Technical Manual

Appendices
Z-100 Series Computers

593-0052-02
CONSISTS OF

MANUAL
595-2960-02

FLYSHEET
597-2922-02

TAB SET
597-2931

TM-100

ZENITH data systems

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In Appendix A, you are furnished with the IEEE Task 696.1/D2, S-100 Bus Standards.

In Appendices B and C, you are furnished the architecture and instruction sets for the Intel 8085 microprocessor.

The 8085 microprocessor is an 8-bit general purpose microprocessor that is capable of accessing up to 64K bytes of memory and has status lines for controlling large systems.

Contained in the 8085 microprocessor are the functions of clock generation, system bus control, and interrupt priority selection, in addition to execution of the instruction set.

The 8085 microprocessor implements a group of instructions that move data between registers, between a register and memory, and between a register and an I/O port. It also has arithmetic and logic instructions, and machine control instruction. The CPU recognizes these instructions only when they are coded in binary form.

The architecture and instruction set for the 8088 microprocessor are located in the iAPX 88 Book, which is included as part of this Appendix.

The 8088 microprocessor is an 8-bit microprocessor. It combines a 16-bit microprocessor internal architecture with an easy to use 8-bit bus interface. Most of the bus lines are identical in function to the 8085A.

The 8088 is totally software compatable with the 16-bit 8086 CPU. All the power of the 8086 16-bit instruction set is available in the 8-bit 8088.

With the 16-bit internal architecture, the 8088 provides 16-bit wide registers, data paths, a 16-bit ALU, and a set of powerful 16-bit instructions identical to the ones found in the 8086 microprocessor. It also provides a 20-bit memory address range and a 16-bit input/output port address range for I/O cycles. This gives the 8088 a full megabyte of memory addressability and 64K bytes of I/O addressability.

The instruction set for the 8088 includes a full complement of arithmetic operations including addition, subtraction, multiplication, and division, on 8-bit or 16-bit quantities. If also has a complete set of string manipulation operations for performance and flexibility in application where large amounts of data are involved.

Appendix D provides you with the data sheets and programming instruction for the major IC's.

APPENDIX A

S100 Bus Specifications

The following pages provide you 1EEE
Task 696.1/D2, S-100 Bus Standards.

APPENDIX B
8085 Architecture

The following pages are reprinted with
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8085A ARCHITECTURE

2.1 WHAT THE 8085A IS

The 8085A is an 8-bit general-purpose microprocessor that is very cost-effective in small systems because of its extraordinarily low hardware overhead requirements. At the same time it is capable of accessing up to 64K bytes of memory and has status lines for controlling large systems.

2.2 WHAT'S IN THE 8085A

In the 8085A microprocessor are contained the functions of clock generation, system bus control, and interrupt priority selection, in addition to execution of the instruction set. (See Figure 2-1.) The 8085A transfers data on an 8-bit, bidirectional 3-state bus (AD_{0-7}) which is time-multiplexed so as to also transmit the eight lower-order address bits. An additional eight lines (A_{8-15}) expand the MCS-85 system memory addressing capability to 16 bits, thereby allowing 64K bytes of memory to be accessed directly by the CPU. The 8085A CPU (central processing unit) generates control signals that can be used to select appropriate external devices and functions to perform READ and WRITE operations and also to select memory or I/O ports. The 8085A can address up to 256 different I/O locations. These addresses have the same numerical values (00 through FFH) as the first 256 memory addresses; they are distinguished by means of the IO/$\overline{M}$ output from the CPU. You may also choose to address I/O ports as memory locations (i.e., memory-map the I/O, Section 3.2).

2.2.1 Registers

The 8085A, like the 8080, is provided with internal 8-bit registers and 16-bit registers. The 8085A has eight addressable 8-bit registers. Six of them can be used either as 8-bit registers or as 16-bit register pairs. Register pairs are treated as though they were single, 16-bit registers; the high-order byte of a pair is located in the first register and the low-order byte is located in the second. In addition to the register pairs, the 8085A contains two more 16-bit registers.

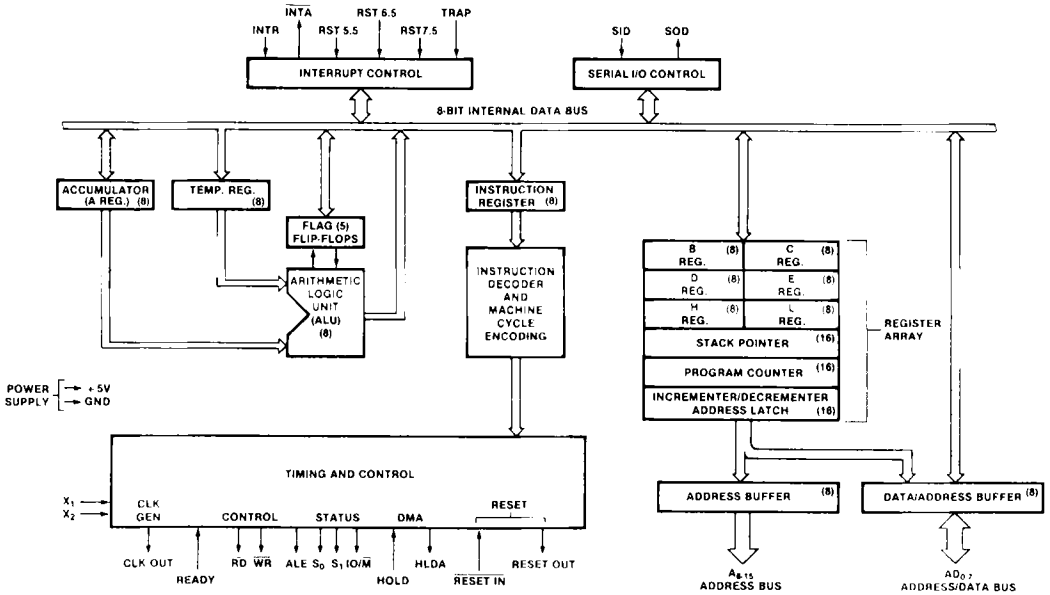


FIGURE 2-1 8085A CPU FUNCTIONAL BLOCK DIAGRAM

FUNCTIONAL DESCRIPTION

The 8085A's CPU registers are distinguished as follows:

- The **accumulator** (ACC or A Register) is the focus of all of the accumulator instructions (Table 4-1), which include arithmetic, logic, load and store, and I/O instructions. It is an 8-bit register only. (However, see **Flags,** in this list.)
- The **program counter** (PC) always points to the memory location of the next instruction to be executed. It always contains a 16-bit address.
- **General-purpose registers** BC, DE, and HL may be used as six 8-bit registers or as three 16-bit registers, interchangeably, depending on the instruction being performed. HL functions as a **data pointer** to reference memory addresses that are either the sources or the destinations in a number of instructions. A smaller number of instructions can use BC or DE for indirect addressing.
- The **stack pointer** (SP) is a special data pointer that always points to the stack top (next available stack address). It is an indivisible 16-bit register.
- The **flag register** contains five one-bit flags, each of which records processor status information and may also control processor operation. (See following paragraph.)

2.2.2 Flags

The five flags in the 8085A CPU are shown below:

D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0
S	Z		AC		P		CY

The **carry flag** (CY) is set and reset by arithmetic operations. Its status can be directly tested by a program. For example, the addition of two one-byte numbers can produce an answer that does not fit into one byte:

HEXIDECIMAL	BINARY
AEH	1 0 1 0 1 1 1 0
+74H	0 1 1 1 0 1 0 0
122H	1 0 0 1 0 0 0 1 0

Carry bit sets carry flag to 1

An addition operation that results in an overflow out of the high-order bit of the accumulator sets the carry flag. An addition operation that does not result in an overflow clears the carry flag. (See 8080/8085 Assembly Language Programming Manual for further details.) The carry flag also acts as a "borrow" flag for subtract operations.

The **auxiliary carry flag** (AC) indicates overflow out of bit 3 of the accumulator in the same way that the carry flag indicates overflow out of bit 7. This flag is commonly used in BCD (binary coded decimal) arithmetic.

The **sign flag** is set to the condition of the most significant bit of the accumulator following the execution of arithmetic or logic instructions. These instructions use bit 7 of data to represent the sign of the number contained in the accumulator. This permits the manipulation of numbers in the range from −128 to +127.

The **zero flag** is set if the result generated by certain instructions is zero. The zero flag is cleared if the result is not zero. A result that has a carry but has a zero answer byte in the accumulator will set both the carry flag and the zero flag. For example,

HEXADECIMAL	BINARY
A7H	1 0 1 0 0 1 1 1
+59H	+ 0 1 0 1 1 0 0 1
100H	1 0 0 0 0 0 0 0 0

Carry bit

Eight zero bits set zero flag to 1

Incrementing or decrementing certain CPU registers with a zero result will also set the zero flag.

The **parity flag** (P) is set to 1 if the parity (number of 1-bits) of the accumulator is even. If odd, it is cleared.

2.2.3 Stack

The stack pointer maintains the address of the last byte entered into the stack. The stack pointer can be initialized to use any portion of read-write memory as a stack. The stack pointer is decremented each time data is pushed onto the stack and is incremented each time data is popped off the stack (i.e., the stack grows downward in terms of memory address, and the stack "top" is the lowest numerical address represented in the stack currently in use). Note that the stack pointer is always incremented or decremented by two bytes since all stack operations apply to register pairs.

2.2.4 Arithmetic-Logic Unit (ALU)

The ALU contains the accumulator and the flag register (described in Sections 2.2.1 and 2.2.2) and some temporary registers that are inaccessible to the programmer.

Arithmetic, logic, and rotate operations are performed by the ALU. The results of these operations can be deposited in the accumulator, or they can be transferred to the internal data bus for use elsewhere.

2.2.5 Instruction Register and Decoder

During an instruction fetch, the first byte of an instruction (containing the opcode) is transferred from the internal bus to the 8-bit instruction register. (See Figure 2-1.) The contents of the instruction register are, in turn, available to the instruction decoder. The output of the decoder, gated by timing signals, controls the registers, ALU, and data and address buffers. The outputs of the instruction decoder and internal clock generator generate the state and machine cycle timing signals.

2.2.6 Internal Clock Generator

The 8085A CPU incorporates a complete clock generator on its chip, so it requires only the addition of a quartz crystal to establish timing for its operation. (It will accept an external clock input at its X_1 input instead, however.) A suitable crystal for the standard 8085A must be parallel-resonant at a fundamental of 6.25 MHz or less, twice the desired internal clock frequency. The 8085A-2 will operate with crystal of up to 10 MHz. The functions of the 8085A internal clock generator are shown in Figure 2-2. A Schmitt trigger is used interchangeably as oscillator or as input conditioner, depending upon whether a crystal or an external source is used. The clock circuitry generates two nonoverlapping internal clock signals, ϕ_1 and ϕ_2 (see Figure 2-2). ϕ_1 and ϕ_2 control the internal timing of the 8085A and are not directly available on the outside of the chip. The external pin CLK is a buffered, inverted version of ϕ_1. CLK is half the frequency of the crystal input signal and may be used for clocking other devices in the system.

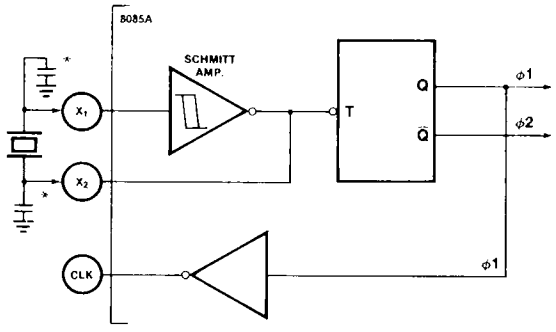


FIGURE 2-2 8085A CLOCK LOGIC

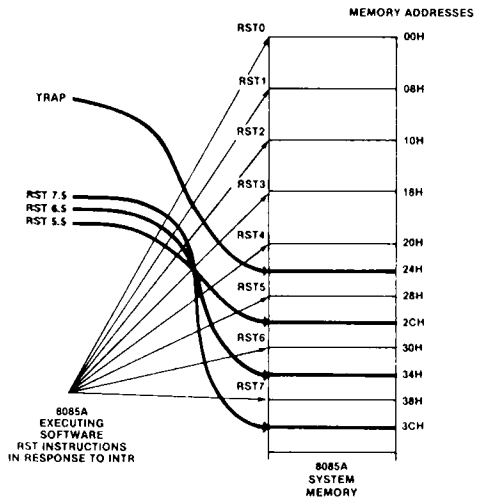


FIGURE 2-3 8085A HARDWARE AND SOFTWARE RST BRANCH LOCATIONS

2.2.7 Interrupts

The five hardware interrupt inputs provided in the 8085A are of three types. INTR is identical with the 8080A INT line in function; i.e., it is maskable (can be enabled or disabled by EI or DI software instructions), and causes the CPU to fetch in an RST instruction, externally placed on the data bus, which vectors a branch to any one of eight fixed memory locations (Restart addresses). (See Figure 2-3.) INTR can also be controlled by the 8259 programmable interrupt controller, which generates CALL instructions instead of RSTs, and can thus vector operation of the CPU to a preprogrammed subroutine located anywhere in your system's memory map. The RST 5.5, RST 6.5, and RST 7.5 hardware interrupts are different in function in that they are maskable through the use of the SIM

FUNCTIONAL DESCRIPTION

instruction, which enables or disables these interrupts by clearing or setting corresponding mask flags based on data in the accumulator. (See Figure 2-4.) You may read the status of the interrupt mask previously set by peforming a RIM instruction. Its execution loads into the accumulator the following information. (See Figure 2-5.)

- Current interrupt mask status for the RST 5.5, 6.5, and 7.5 hardware status.
- Current interrupt enable flag status (except that immediately following TRAP, the IE flag status **preceding** that interrupt is loaded).
- RST 5.5, 6.5, and 7.5 interrupts pending.

RST 5.5, 6.5, and 7.5 are also subject to being enabled or disabled by the EI and DI instructions, respectively. INTR, RST 5.5, and RST 6.5 are level-sensitive, meaning that these inputs may be acknowledged by the processor when they are held at a high level. RST 7.5 is edge-sensitive, meaning that an internal flip-flop in the 8085A registers the occurrence of an interrupt the instant a rising edge appears on the RST 7.5 input line. This input need not be held high; the flip-flop will remain set until it is cleared by one of three possible actions:

- The 8085A responds to the interrupt, and sends an internal reset signal to the RST 7.5 flip-flop. (See Figure 2-6A.)

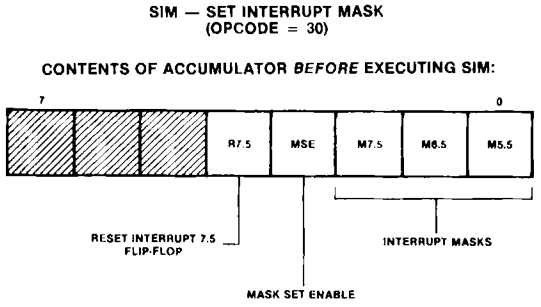


FIGURE 2-4 INTERRUPT MASKS SET USING SIM INSTRUCTION

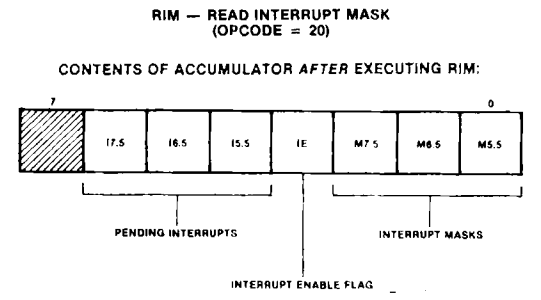


FIGURE 2-5 RIM — READ INTERRUPT MASK

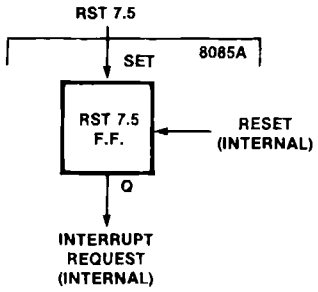


FIGURE 2-6A RST 7.5 FLIP FLOP

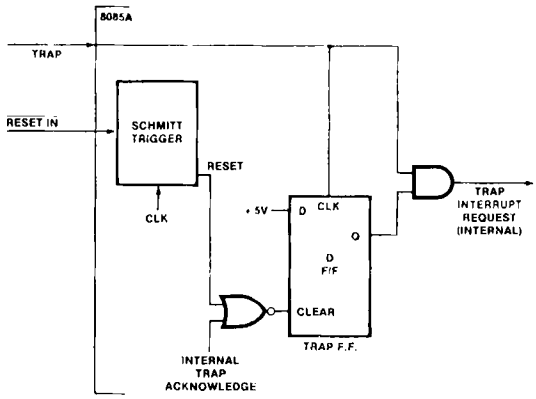


FIGURE 2-6B TRAP INTERRUPT INPUTS

FIGURE 2-6 RST 7.5 AND TRAP INTERRUPT INPUTS

- The 8085A, before responding to the RST 7.5 interrupt, receives a RESET IN signal from an external source; this also activates the internal reset.
- The 8085A executes a SIM instruction, with accumulator bit 4 previously set to 1. (See Figure 2-4.)

The third type of hardware interrupt is TRAP. This input is not subject to any mask or interrupt enable/disable instruction. The receipt of a positive-going edge on the TRAP input triggers the processor's hardware interrupt sequence, but the pulse must be held high until acknowledged internally (see Figure 2-6B).

The sampling of all interrupts occurs on the descending edge of CLK, one cycle before the end of the instruction in which the interrupt input is activated. To be recognized, a valid interrupt must occur at least 160 ns before sampling time in the 8085A, or 150 ns in the 8085A-2. This means that to guarantee being recognized, RST 5.5 and 6.5 and TRAP need to be held on for at least 17 clock states plus 160 ns (150 for 8085A-2), assuming that the interrupt might arrive just barely too late to be acknowledged during a particular instruction, and that the following instruction might be an 18-state CALL. This timing assumes no WAIT or HOLD cycles are used.

The way interrupt masks are set and read is described in Chapter 4 under the RIM (read interrupt mask) and SIM (set interrupt mask) instruction listings. Interrupt functions and their priorities are shown in the table that follows.

Name	Priority	Address (1) Branched to when interrupt occurs	Type Trigger
TRAP	1	24H	Rising edge AND high level until sampled
RST 7.5	2	3CH	Rising edge (latched)
RST 6.5	3	34H	High level until sampled
RST 5.5	4	2CH	High level until sampled
INTR	5	(2)	High level until sampled

NOTES:
(1) In the case of TRAP and RST 5.5-7.5, the contents of the Program Counter are pushed onto the stack before the branch occurs.
(2) Depends on the instruction that is provided to the 8085A by the 8259 or other circuitry when the interrupt is acknowledged.

2.2.8 Serial Input and Output

The SID and SOD pins help to minimize chip count in small systems by providing for easy interface to a serial port using software for timing and for coding and decoding of the data. Each time a RIM instruction is executed, the status of the SID pin is read into bit 7 of the accumulator. RIM is thus a dual-purpose instruction. (See Chapter 4.) In similar fashion, SIM is used to latch bit 7 of the accumulator out to the SOD output via an internal flip-flop, providing that bit 6 of the accumulator is set to 1. (See Figure 2-7.) Section 2.3.8 describes SID and SOD timing.

SID can also be used as a general purpose TEST input and SOD can serve as a one-bit control output.

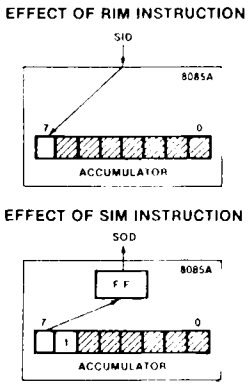


FIGURE 2-7 EFFECT OF RIM AND SIM INSTRUCTIONS ON SERIAL DATA LINES

2.3 HOW THE MCS-85 SYSTEM WORKS

The 8085A CPU generates signals that tell peripheral devices what type of information is on the multiplexed Address/Data bus and from that point on the operation is almost identical to the MCS-80™ CPU Group. A multiplexed bus structure was chosen because it freed device pins so that more functions could be integrated on the 8085A and other components of the family. The multiplexed bus is designed to allow complete compatibility to existing peripheral components with improved timing margins and access requirements. (See Figure 2-8.)

To enhance the system integration of MCS-85, several special components with combined memory and I/O were designed. These new devices directly interface to the multiplexed bus of the 8085A. The pin locations of the 8085A and the special peripheral components are assigned to minimize PC board area and to allow for efficient layout. The details on peripheral components are contained in subsequent paragraphs of this chapter and in Chapters 5 and 6.

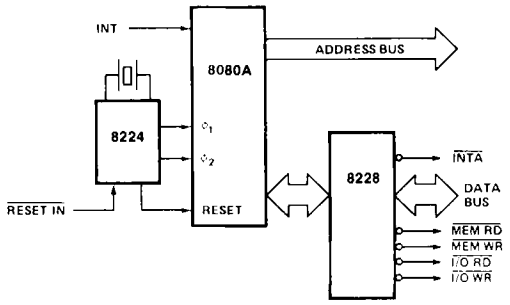


FIGURE 2-8A MCS-80™ CPU GROUP

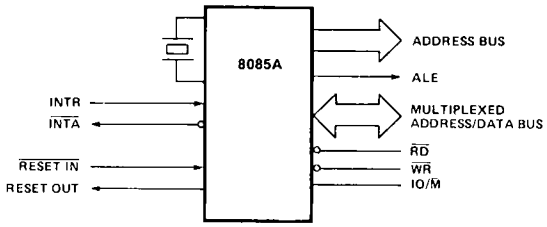


FIGURE 2-8B MCS-85™ CPU/8085A (MCS-80 COMPATIBLE FUNCTIONS)

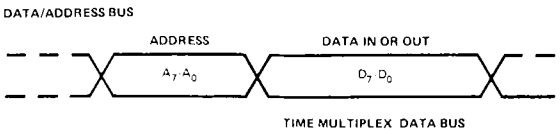


FIGURE 2-8C MULTIPLEXED BUS TIMING

FIGURE 2-8 BASIC CPU FUNCTIONS

2.3.1 Multiplexed Bus Cycle Timing

The execution of any 8085A program consists of a sequence of READ and WRITE operations, of which each transfers a byte of data between the 8085A and a particular memory or I/O address. These READ and WRITE operations are the only communication between the processor and the other components, and are all that is necessary to execute any instruction or program.

Each READ or WRITE operation of the 8085A is referred to as a machine cycle. The execution of each instruction by the 8085A consists of a sequence of from one to five machine cycles, and each machine cycle consists of a minimum of from three to six clock cycles (also referred to as T states). Consider the case of the Store Accumulator Direct (STA) instruction, shown in Figure 2-9. The STA instruction causes the contents of the accumulator to be stored at the direct address specified in the second and third bytes of the instruction. During the first machine cycle (M_1), the CPU puts the contents of the program counter (PC) on the address bus and performs a MEMORY READ cycle to read from memory the opcode of the next instruction (STA). The M_1 machine cycle is also referred to as the OPCODE FETCH cycle, since it fetches the operation code of the next instruction. In the fourth clock cycle (T_4) of M_1, the CPU interprets the data read in and recognizes it as the opcode of the STA instruction. At this point the CPU knows that it must do three more machine cycles (two MEMORY READs and one MEMORY WRITE) to complete the instruction.

The 8085A then increments the program counter so that it points to the next byte of the instruction and performs a MEMORY READ machine cycle (M_2) at address (PC + 1). The accessed memory places the addressed data on the data bus for the CPU. The 8085A temporarily stores this data (which is the low-order byte of the direct address) internally in the CPU. The 8085A again increments the program counter to location (PC + 2) and reads from memory (M_3) the next byte of data, which is the high-order byte of the direct address.

At this point, the 8085A has accessed all three bytes of the STA instruction, which it must now execute. The execution consists of placing the data accessed in M_2 and M_3 on the address bus, then placing the contents of the accumulator on the data bus, and then performing a MEMORY WRITE machine cycle (M_4). When M_4 is finished, the CPU will fetch (M_1) the first byte of the next instruction and continue from there.

State Transition Sequence

As the preceding example shows, the execution of an instruction consists of a series of machine cycles whose nature and sequence is determined by the opcode accessed in the M_1

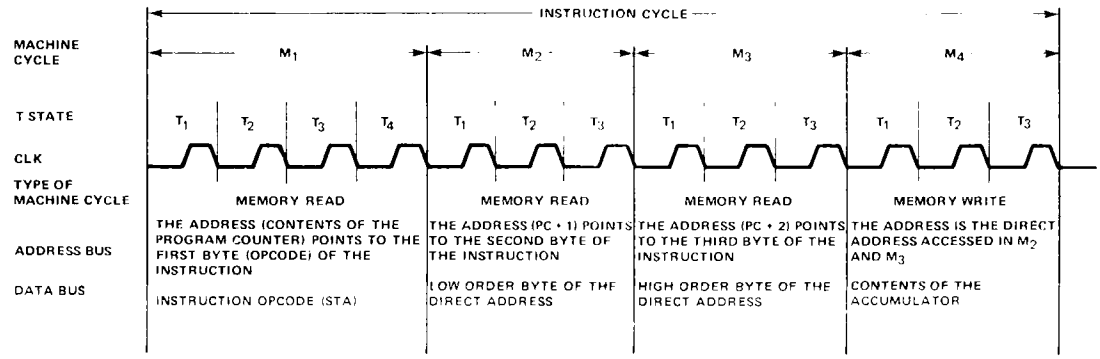


FIGURE 2-9 CPU TIMING FOR STORE ACCUMULATOR DIRECT (STA) INSTRUCTION

MACHINE CYCLE			STATUS			CONTROL		
			IO/M	S1	S0	RD	WR	INTA
OPCODE FETCH	(OF)		0	1	1	0	1	1
MEMORY READ	(MR)		0	1	0	0	1	1
MEMORY WRITE	(MW)		0	0	1	1	0	1
I/O READ	(IOR)		1	1	0	0	1	1
I/O WRITE	(IOW)		1	0	1	1	0	1
INTR ACKNOWLEDGE	(INA)		1	1	1	1	1	0
BUS IDLE	(BI)	DAD	0	1	0	1	1	1
		INA(RST/TRAP)	1	1	1	1	1	1
		HALT	TS	0	0	TS	TS	1

0 = Logic "0" 1 = Logic "1" TS = High Impedance X = Unspecified

FIGURE 2-10 8085A MACHINE CYCLE CHART

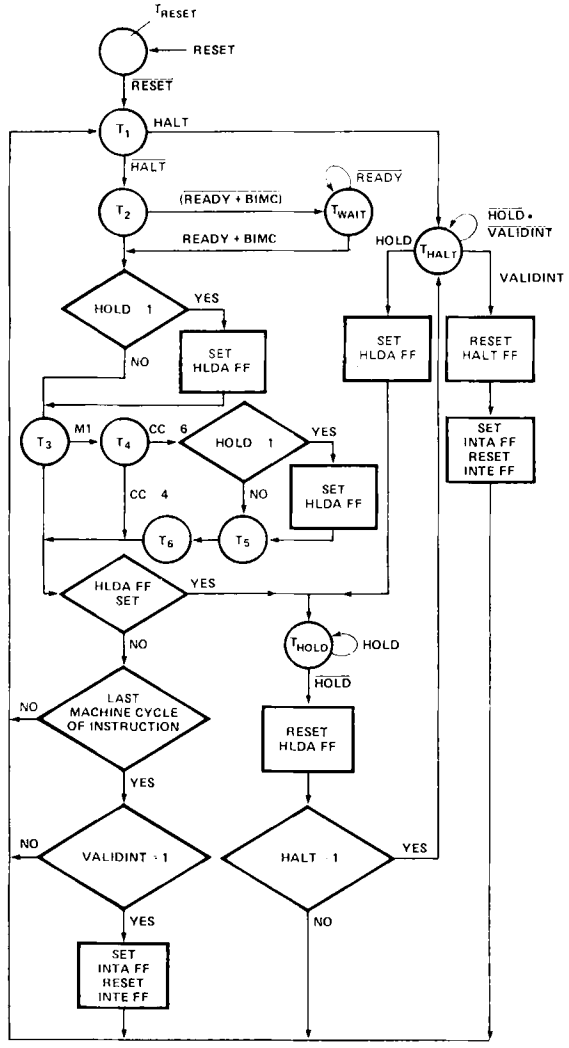
machine cycle. While no one instruction cycle will consist of more than five machine cycles, every machine cycle will be one of the seven types listed in Figure 2-10. These seven types of machine cycles can be differentiated by the state of the three status lines (IO/$\overline{M}$, S_0, and S_1) and the three control signals ($\overline{RD}$, $\overline{WR}$, and $\overline{INTA}$).

Most machine cycles consist of three T states, (cycles of the CLK output) with the exception of OPCODE FETCH, which normally has either four or six T states. The actual number of states required to perform any instruction depends on the instruction being executed, the particular machine cycle within the instruction cycle, and the number of WAIT and HOLD states inserted into each machine cycle through the use of the READY and HOLD inputs of the 8085A. The state transition diagram in Figure 2-11 illustrates how the 8085A proceeds in the course of a machine cycle. The state of various status and control signals, as well as the system buses, is shown in Figure 2-12 for each of the ten possible T states that the processor can be in.

Figure 2-11 also shows when the READY, HOLD, and interrupt signals are sampled, and how they modify the basic instruction sequence (T_1-T_6 and T_{WAIT}). As we shall see, the timings for each of the seven types of machine cycles are almost identical.

OPCODE FETCH (OF):

The OPCODE FETCH (OF) machine cycle is unique in that it has more than three clock cycles. This is because the CPU must interpret the opcode accessed in T_1, T_2, and T_3 before it can decide what to do next.



NOTE: SYMBOL DEFINITION

- T_x - CPU STATE T_x. ALL CPU STATE TRANSITIONS OCCUR ON THE FALLING EDGE OF CLK.
- X - A DECISION (X) THAT DETERMINES WHICH OF SEVERAL ALTERNATIVE PATHS TO FOLLOW.
- X - PERFORM THE ACTION X.
- → - FLOWLINE THAT INDICATES THE SEQUENCE OF EVENTS.
- X → - FLOWLINE THAT INDICATES THE SEQUENCE OF EVENTS IF CONDITION X IS TRUE.
- CC - NUMBER OF CLOCK CYCLES IN THE CURRENT MACHINE CYCLE.
- BIMC - "BUS IDLE MACHINE CYCLE" = MACHINE CYCLE WHICH DOESN'T USE THE SYSTEM BUS.
- VALIDINT - "VALID INTERRUPT" = AN INTERRUPT IS PENDING THAT IS BOTH ENABLED AND UNMASKED (MASKING ONLY APPLIES FOR RST 5.5, 6.5, AND 7.5 INPUTS).
- HLDA FF - INTERNAL HOLD ACKNOWLEDGE FLIP FLOP. NOTE THAT THE 8085A SYSTEM BUSES ARE 3-STATED ONE CLOCK CYCLE AFTER THE HLDA FLIP FLOP IS SET.

FIGURE 2-11 8085A CPU STATE TRANSITION

Machine State	Status & Buses				Control		
	S1,S0	IO/$\overline{M}$	A_8-A_{15}	AD_0-AD_7	$\overline{RD}$,$\overline{WR}$	$\overline{INTA}$	ALE
T_1	X	X	X	X	1	1	1†
T_2	X	X	X	X	X	X	0
T_{WAIT}	X	X	X	X	X	X	0
T_3	X	X	X	X	X	X	0
T_4	1	0*	X	TS	1	1	0
T_5	1	0*	X	TS	1	1	0
T_6	1	0*	X	TS	1	1	0
T_{RESET}	X	TS	TS	TS	TS	1	0
T_{HALT}	0	TS	TS	TS	TS	1	0
T_{HOLD}	X	TS	TS	TS	TS	1	0

0 = Logic "0" 1 = Logic "1" TS = High Impedance X = Unspecified

†ALE not generated during 2nd and 3rd machine cycles of DAD instruction.

*IO/$\overline{M}$ = 1 during T_4-T_6 states of RST and INA cycles.

FIGURE 2-12 8085A MACHINE STATE CHART

Figure 2-13 shows the timing relationships for an OF machine cycle. The particular instruction illustrated is DCX, whose timing for OF differs from other instructions in that it has six T states, while some instructions require only four T states for OF. In this discussion, as well as the following discussions, only the relative timing of the signals will be discussed; for the actual timings, refer to the data sheets of the individual parts in Chapters 5 and 6.

The first thing that the 8085A does at the beginning of every machine cycle is to send out three status signals (IO/$\overline{M}$, S1, S0) that define what type of machine cycle is about to take place. The IO/$\overline{M}$ signal identifies the machine cycle as being either a memory reference or input/output operation. The S1 status signal identifies whether the cycle is a READ or WRITE operation. The S0 and S1 status signals can be used together (see Figure 2-10) to identify READ, WRITE, or OPCODE FETCH machine cycles as well as the HALT state. Referring to Figure 2-13, the 8085A will send out IO/$\overline{M}$ = 0, S1 = 1, S0 = 1 at the beginning of the machine cycle to identify it as a READ from a memory location to obtain an opcode; in other words, it identifies the machine cycle as an OPCODE FETCH cycle.

The 8085A also sends out a 16-bit address at the beginning of every machine cycle to identify the particular memory location or I/O port that the machine cycle applies to. In the case of an OF cycle, the contents of the program counter is placed on the address bus. The high order byte (PCH) is placed on the A_8-A_{15} lines, where it will stay until at least T_4. The low order byte (PCL) is placed on the AD_0-AD_7 lines, whose three-state drivers are enabled if not found already on. Unlike the upper address lines, however, the information on the lower address lines will remain there for only one clock cycle, after which the drivers will go to their high impedance state, indicated by a dashed line in Figure 2-13. This is necessary because the AD_0-AD_7 lines are time mulitplexed between the address and data buses. During T_1 of every machine cycle, AD_0-AD_7 output the lower 8-bits of address after which AD_0-AD_7 will either output the desired data for a WRITE operation or the drivers will float (as is the case for the OF cycle), allowing the external device to drive the lines for a READ operation.

Since the address information on AD_0-AD_7 is of a transitory nature, it must be latched either internally in special multiplexed-bus components like the 8155 or externally in parts like the 8212 8-bit latch. (See Chapter 3.) The 8085A provides a special timing signal, ADDRESS LATCH ENABLE (ALE), to facilitate the latching of A_0-A_7; ALE is present during T_1 of every machine cycle.

After the status signals and address have been sent out and the AD_0-AD_7 drivers have been disabled, the 8085A provides a low level on $\overline{RD}$ to enable the addressed memory device. The device will then start driving the AD_0-AD_7 lines; this is indicated by the dashed line turning into a solid line in Figure 2-13. After a period of time (which is the access time of the memory) valid data will be present on AD_0-AD_7. The 8085A during T_3 will load the memory data on AD_0-AD_7 into its instruction register and then raise $\overline{RD}$ to the high level, disabling the addressed memory device. At this point, the 8085A will have finished accessing the opcode of the instruction. Since this is the first machine cycle (M_1) of the instruction, the CPU will automatically step to T_4, as shown in Figure 2-11.

During T_4, the CPU will decode the opcode in the instruction register and decide whether to enter T_5 on the next clock or to start a new machine cycle and enter T_1. In the case of the DCX instruction shown in Figure 2-13, it will enter T_5 and then T_6 before going to T_1.

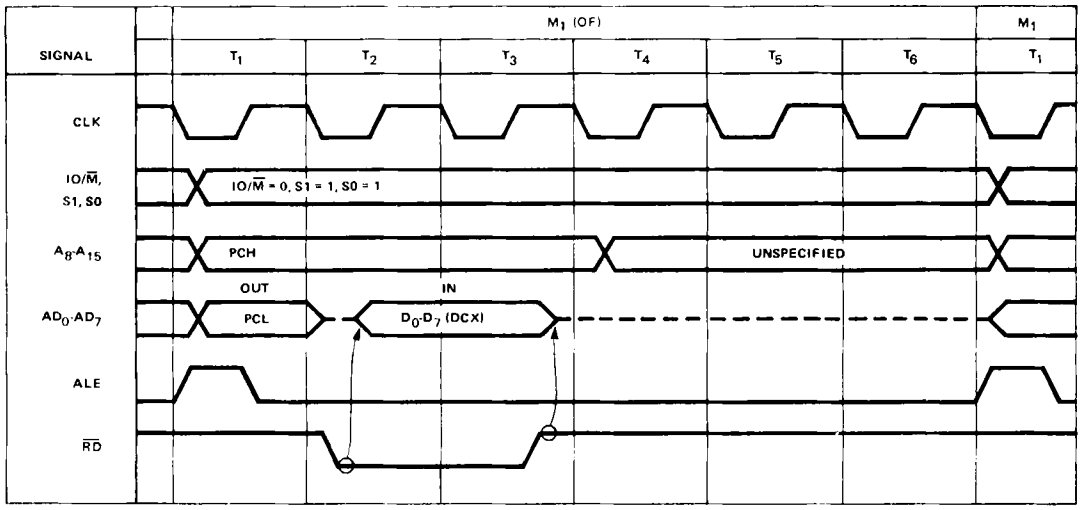


FIGURE 2-13 OPCODE FETCH MACHINE CYCLE (OF DCX INSTRUCTION)

During T_5 and T_6, of DCX, the CPU will decrement the designated register. Since the A_8-A_{15} lines are driven by the address latch circuits, which are part of the incrementer/decrementer logic, the A_8-A_{15} lines may change during T_5 and T_6. Because the value of A_8-A_{15} can vary during T_4-T_6, it is most important that all memory and I/O devices on the system bus qualify their selection with $\overline{RD}$. If they don't use $\overline{RD}$, they may be spuriously selected. Moreover, with a linear selection technique (Chapter 3), two or more devices could be simultaneously enabled, which could be potentially damaging. The generation of spurious addresses can also occur momentarily at address bus transitional periods in T_1. Therefore, the selection of all memory and I/O devices must be qualified with $\overline{RD}$ or $\overline{WR}$. Many new memory devices like the 8155 and 8355 have the $\overline{RD}$ input that internally is used to enable the data bus outputs, removing the need for externally qualifying the chip enable input with $\overline{RD}$.

Figure 2-14 is identical to Figure 2-13 with one exception, which is the use of the READY line. As we can see in Figure 2-11, when the CPU is in T_2, it examines the state of the READY line. If the READY line is high, the CPU will proceed to T_3 and finish executing the instruction. If the READY line is low, however, the CPU will enter T_{WAIT} and stay there indefinitely until READY goes high. When the READY line does go high, the CPU will exit T_{WAIT} and enter T_3, in order to complete the machine cycle. As shown in Figure 2-14, the external effect of using the READY line is to preserve the exact state of the processor signals at the end of T_2 for an integral number of clock periods, before finishing the machine cycle. This "stretching" of the system timing has the further effect of increasing the allowable access time for memory or I/O devices. By inserting T_{WAIT} states, the 8085A can accommodate even the slowest of memories. Another common use of the READY line is to singe-step the processor with a manual switch.

2.3.2 Read Cycle Timing

MEMORY READ (MR):

Figure 2-15 shows the timing of two successive MEMORY READ (MR) machine cycles, the first without a T_{WAIT} state and the second with one T_{WAIT} state. The timing during T_1-T_3 is absolutely identical to the OPCODE FETCH machine cycle, with the exception that the status sent out during T_1 is IO/$\overline{M}$ = 0, S1 = 1, S0 = 0, identifying the cycles as a READ from a memory location. This differs from Figure 2-13 only in that S0 = 1 for an OF cycle, identifying that cycle as an OPCODE FETCH operation. Otherwise, the two cycles are identical during T_1-T_3.

A second difference occurs at the end of T_3. As shown in Figure 2-11, the CPU always goes to T_4 from T_3 during M_1, which is always an OF cycle. During all other machine cycles, the CPU will always go from T_3 to T_1 of the next machine cycle.

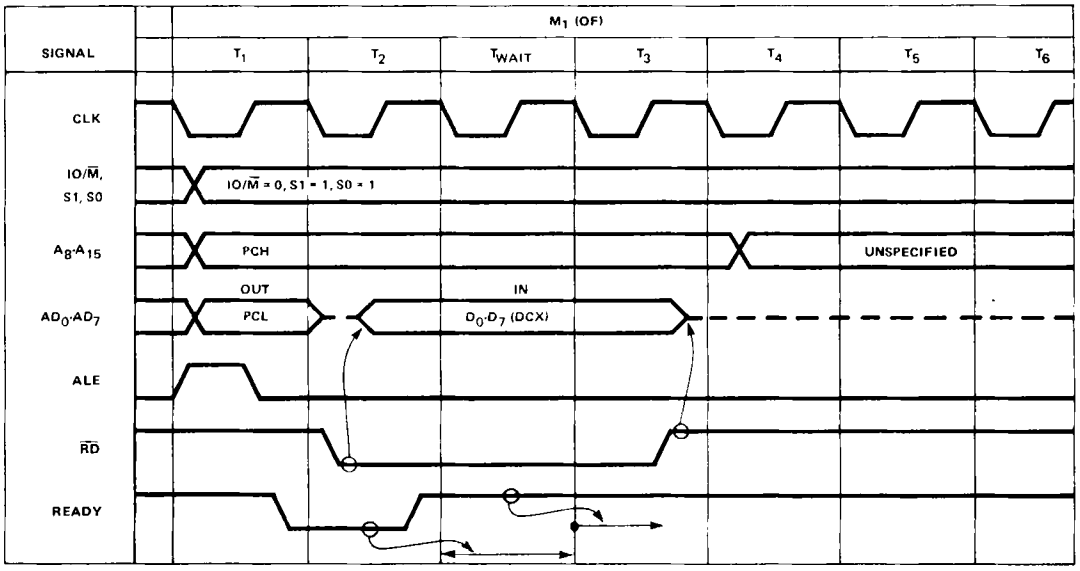


FIGURE 2-14 OPCODE FETCH MACHINE CYCLE WITH ONE WAIT STATE

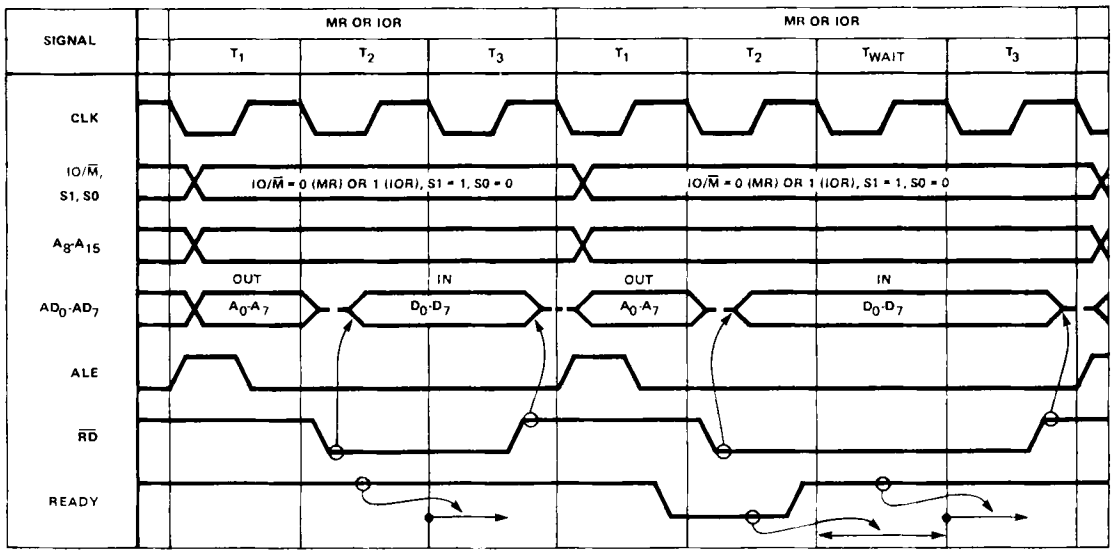


FIGURE 2-15 MEMORY READ (OR I/O READ) MACHINE CYCLES (WITH AND WITHOUT WAIT STATES)

The memory address used in the OF cycle is always the contents of the program counter, which points to the current instruction, while the address used in the MR cycle can have several possible origins. Also, the data read in during an MR cycle is placed in the appropriate register, not the instruction register.

I/O READ (IOR):

Figure 2-15 also shows the timing of two successive I/O READ (IOR) machine cycles, the first without a T_{WAIT} state. As is readily apparent, the timing of an IOR cycle is identical to the timing of an MR cycle, with the exception of IO/$\overline{M}$ = 0 for MR and IO/$\overline{M}$ = 1 for IOR; recall that IO/$\overline{M}$ status signal identifies the address of the current machine cycle as selecting either a memory location or an I/O port. The address used in the IOR cycle comes from the second byte (Port No.) of an INPUT instruction. Note that the I/O port address is duplicated onto both AD_0-AD_7 and A_8-A_{15}. The IOR cycle can occur only as the third machine cycle of an INPUT instruction.

Note that the READY signal can be used to generate T_{WAIT} states for I/O devices as well as memory devices. By gating the READY signal with the proper status lines, one could generate T_{WAIT} states for memory devices only or for I/O devices only. By gating in the address lines, one can further qualify T_{WAIT} state generation by the particular devices being accessed.

2.3.3 WRITE Cycle Timing

MEMORY WRITE (MW):

Figure 2-16 shows the timing for two successive MEMORY WRITE (MW) machine cycles, the first without a T_{WAIT} state, and the second with one T_{WAIT} state. The 8085A sends out the status during T_1 in a similar fashion to the OF, MR and IOR cycles, except that IO/$\overline{M}$ = 0, S1 = 0, and S0 = 1, identifying the current machine cycle as being a WRITE operation to a memory location.

The address is sent out during T_1 in an identical manner to MR. However, at the end of T_1, there is a difference. While the AD_0-AD_7 drivers were disabled during T_2-T_3 of MR in expectation of the addressed memory device driving the AD_0-AD_7 lines, the drivers are not disabled for MW. This is because the CPU must provide the data to be written into the addressed memory location. The data is placed on AD_0-AD_7 at the start of T_2. The $\overline{WR}$ signal is also lowered at this time to enable the writing of the addressed memory device. During T_2, the READY line is checked to see if a T_{WAIT} state is required. If READY is low, T_{WAIT} states are inserted until READY goes high. During T_3, the $\overline{WR}$ line is raised, disabling the addressed memory device and thereby terminating the WRITE operation. The contents of the address and data lines are not changed until the next T_1, which directly follows.

Note that the data on AD_0-AD_7 is not guaranteed to be stable before the falling edge

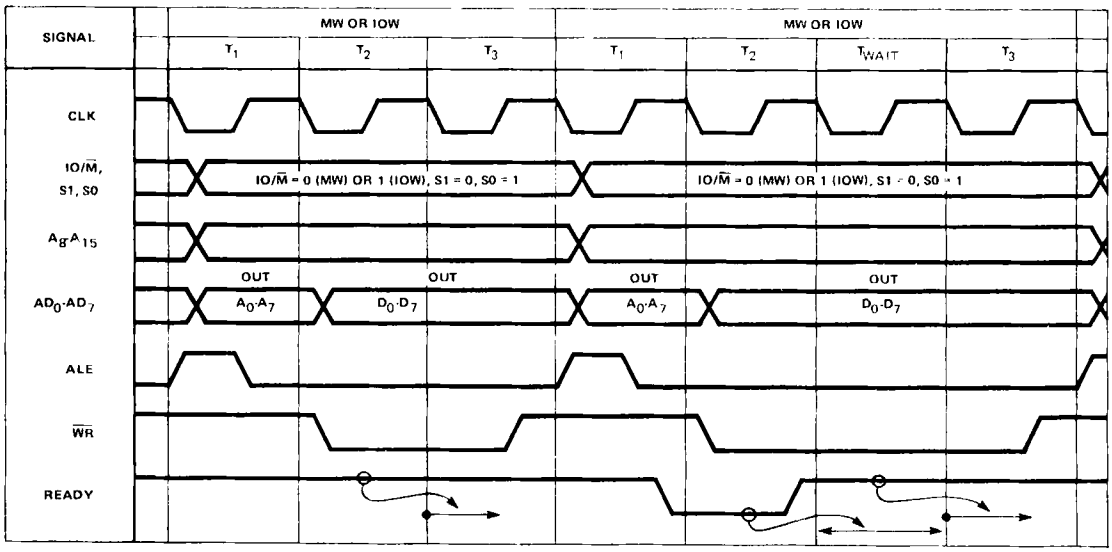


FIGURE 2-16 MEMORY WRITE (OR I/O WRITE) MACHINE CYCLES (WITH AND WITHOUT WAIT STATES)

of $\overline{WR}$. The AD_0-AD_7 lines are guaranteed to be stable both before and after the rising edge of $\overline{WR}$.

I/O WRITE (IOW):

As Figure 2-16 shows, the timing for an I/O WRITE (IOW) machine cycle is the same as an MW machine cycle except that IO/$\overline{M}$ = 0 during the MW cycle and IO/$\overline{M}$ = during the IOW cycle.

As with the IOR cycle discussed previously, the address used in an IOW cycle is the I/O port number which is duplicated on both the high and low bytes of the address bus. In the case of IOW, the port number comes from the second byte of an OUTPUT instruction as the instruction is executed.

2.3.4 Interrupt Acknowledge (INA) Timing

Figures 2-17 and 2-18 (a continuation of 2-17) depict the course of action the CPU takes in response to a high level on the INTR line if the INTE FF (interrupt enable flip-flop) has been set by the EI instruction. The status of the TRAP and RST pins as well as INTR is sampled during the second clock cycle before $M_1 \cdot T_1$. If INTR was the only valid interrupt and if INTE FF is set, then the CPU will reset INTE FF and then enter an INTERRUPT ACKNOWLEDGE (INA) machine cycle. The INA cycle is identical to an OF cycle with two exceptions. $\overline{INTA}$ is sent out instead of $\overline{RD}$. Also, IO/$\overline{M}$ = 1 during INA, whereas IO/$\overline{M}$ = 0 for OF. Although the contents of the program counter are sent out on the address lines, the address lines can be ignored.

When $\overline{INTA}$ is sent out, the external interrupt logic must provide the opcode of an instruction to execute. The opcode is placed on the data bus and read in by the processor. If the opcode is the first byte of a multiple-byte instruction, additional $\overline{INTA}$ pulses will be provided by the 8085A to clock in the remaining bytes. RESTART and CALL instructions are the most

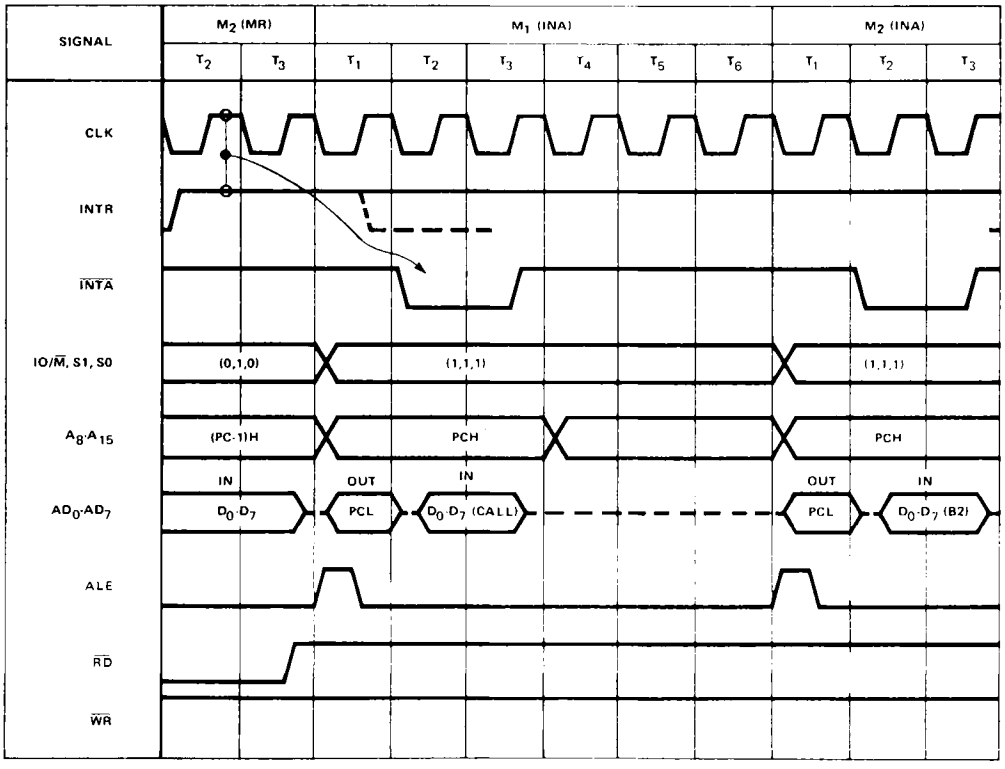


FIGURE 2-17 INTERRUPT ACKNOWLEDGE MACHINE CYCLES (WITH CALL INSTRUCTION IN RESPONSE TO INTR)

logical choices, since they both force the processor to push the contents of the program counter onto the stack before jumping to a new location. In Figure 2-17 it is assumed that a CALL opcode is sent to the CPU during M_1. The CALL opcode could have been placed there by a device like the 8259 programmable interrupt controller.

After receiving the opcode, the processor then decodes it and determines, in this case, that the CALL instruction requires two more bytes. The CPU therefore performs a second INA cycle (M_2) to access the second byte of the instruction from the 8259. The timing of this cycle is identical to M_1, except that it has only three T states. M_2 is followed by another INA cycle (M_3) to access the third byte of the CALL instruction from the 8259.

Now that the CPU has accessed the entire instruction used to acknowledge the interrupt, it will execute that instruction. Note that any instruction could be used (except EI or DI, the instructions which enable or disable interrupts), but the RESTART and CALL instructions are the most logical choices. Also notice that the CPU inhibited the incrementing of the program counter (PC) during the three INA cycles, so that the correct PC value can be pushed onto the stack during M_4 and M_5.

During M_4 and M_5, the CPU performs MEMORY WRITE machine cycles to write the upper and then lower bytes of the PC onto the top of the stack. The CPU then places the two bytes accessed in M_2 and M_3 into the lower and upper bytes of the PC. This has the effect of jumping the execution of the program to the location specified by the CALL instruction.

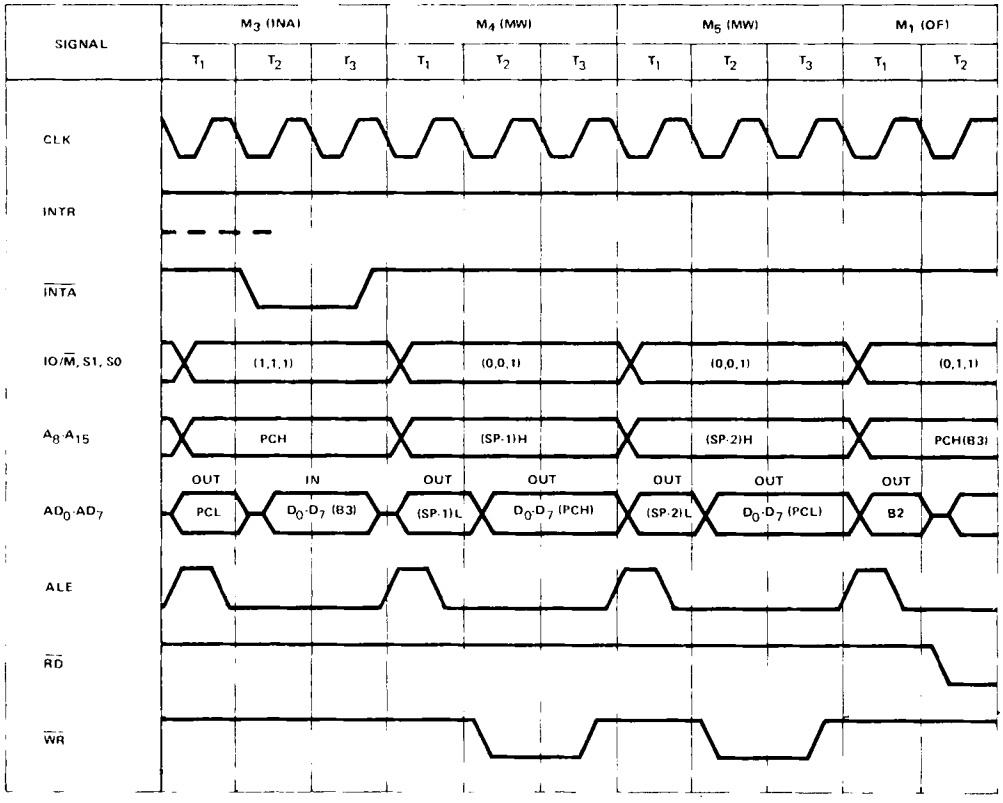


FIGURE 2-18 INTERRUPT ACKNOWLEDGE MACHINE CYCLES (WITH CALL INSTRUCTION IN RESPONSE TO INTR)

2.3.5 Bus Idle (BI) and HALT State

Most machine cycles of the 8085A are associated with either a READ or WRITE operation. There are two exceptions to this rule. The first exception takes place during M_2 and M_3 of the DAD instruction. The 8085A requires six internal T states to execute a DAD instruciton, but it is not desirable to have M_1 be ten (four normal plus six extra) states long. Therefore, the CPU generates two extra machine cycles that do not access either the memory or the I/O. These cycles are referred to as BUS IDLE (BI) machine cycles. In the case of DAD, they are identical to MR cycles except that RD remains high and ALE is not generated. Note that READY is ignored during M_2 and M_3 of DAD.

The other time when the BUS IDLE machine cycle occurs is during the internal opcode generation for the RST or TRAP interrupts. Figure 2-19 illustrates the BI cycle generated in response to RST 7.5. Since this interrupt is rising-edge-triggered, it sets an internal latch; that latch is sampled at the falling edge of the next to the last T-state of the previous instruction. At this point the CPU must generate its own internal RESTART instruction which will (in subsequent machine cycles) cause the processor to push the program counter on the stack and to vector to location 3CH. To do this, it executes an OF machine cycle without issuing RD, generating the RESTART opcode instead. After M_1, the CPU continues execution normally in all respects except that the state of the READY line is ignored during the BI cycle.

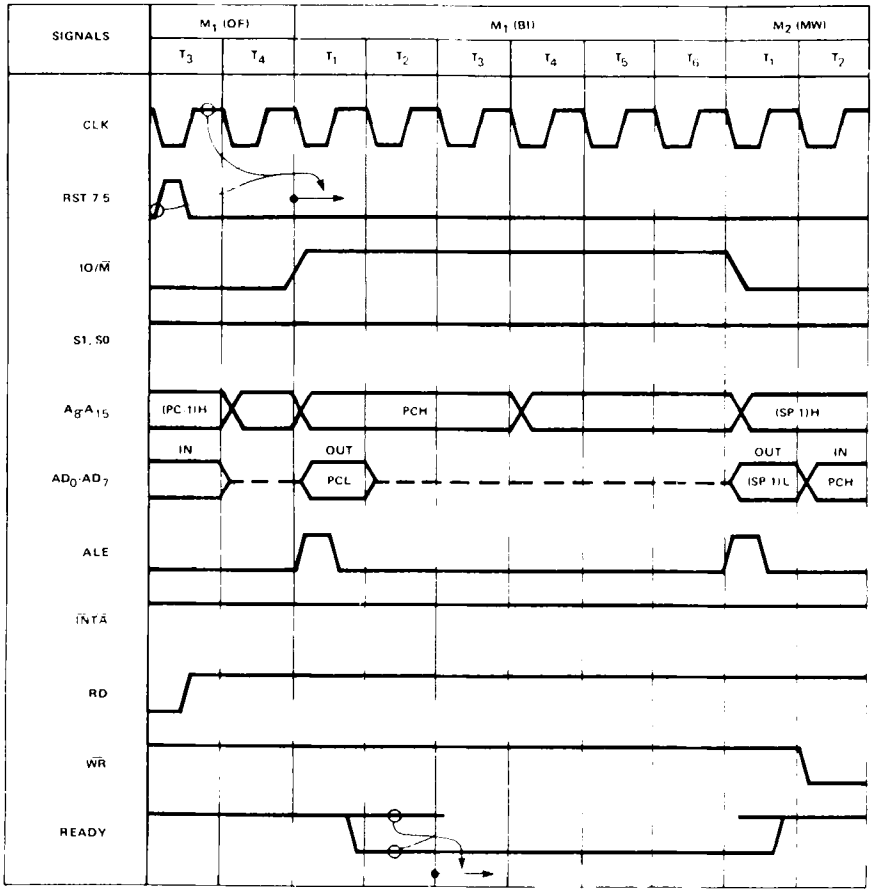


FIGURE 2-19 RST 7.5 BUS IDLE MACHINE CYCLE

FUNCTIONAL DESCRIPTION

Figure 2-20 illustrates the BI cycle generated in response to RST 7.5 when a HALT instruction has just been executed and the CPU is in the T_{HALT} state, with its various signals floating. There are only two ways the processor can completely exit the T_{HALT} state, as shown in Figure 2-11. The first way is for RESET to occur, which always forces the 8085A to T_{RESET}. The second way to exit T_{HALT} permanently is for a valid interrupt to occur, which will cause the CPU to disable further interrupts by resetting INTE FF, and to then proceed to $M_1 \cdot T_1$ of the next instruction. When the HOLD input is activated, the CPU will exit T_{HALT} for the duration of T_{HOLD} and then return to T_{HALT}.

In Figure 2-20 the RST 7.5 line is pulsed during T_{HALT}. Since RST 7.5 is a rising-edge-triggered interrupt, it will set an internal latch which is sampled during CLK = "1" of every T_{HALT} state (as well as during CLK = "1" two T states before any $M_1 \cdot T_1$.) The fact that the latched interrupt was high (assuming that INTE FF = 1 and the RST 7.5 mask = 0) will force the CPU to exit the T_{HALT} state at the end of the next CLK period, and to enter $M_1 \cdot T_1$.

This completes our analysis of the timing of each of the seven types of machine cycles.

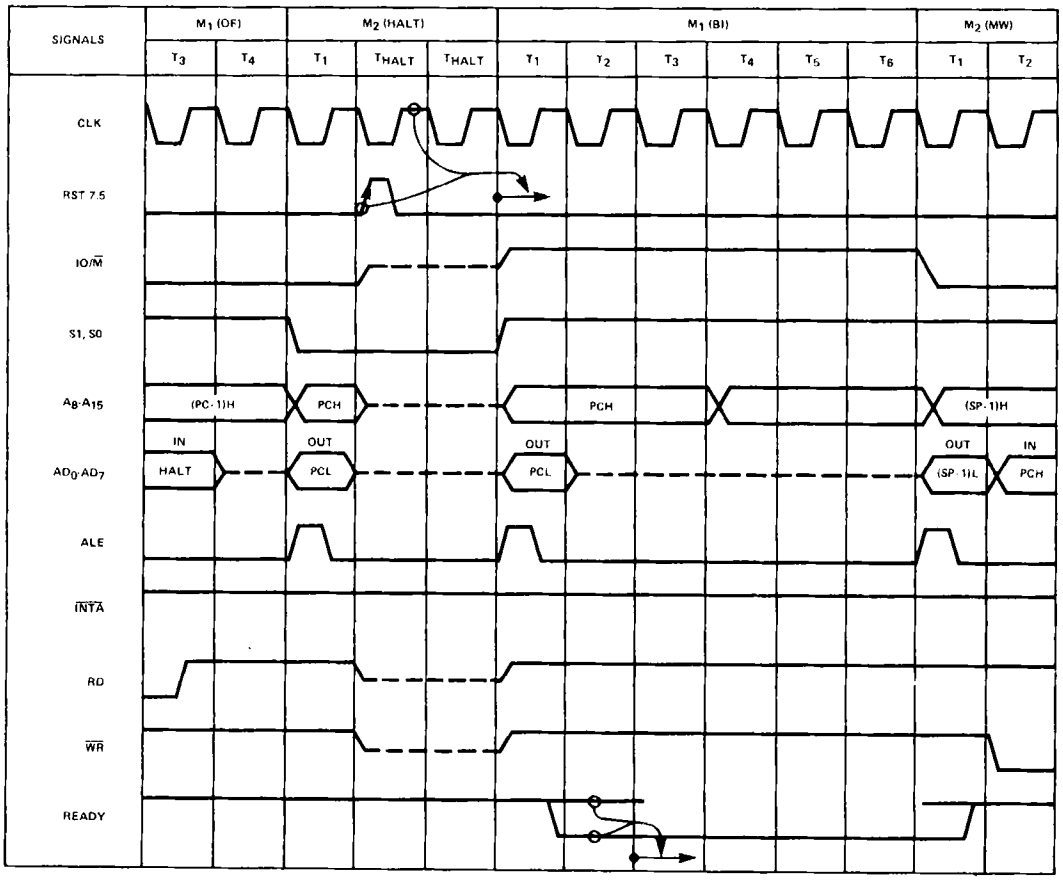


FIGURE 2-20 HALT STATE AND BUS IDLE MACHINE CYCLE
RST 7.5 TERMINATES T_{HALT} STATE

2.3.6 HOLD and HALT States

The 8085A uses the T_{HOLD} state to momentarily cease executing machine cycles, allowing external devices to gain control of the bus and peform DMA cycles. The processor internally latches the state of the HOLD line and the unmasked interrupts during CLK = "1" of every T_{HALT} state. If the internal latched HOLD signal is high during CLK = "1" of any T_{HALT} state, the CPU will exit T_{HALT} and enter T_{HOLD} on the following CLK = "1". As shown in Figure 2-21 this will occur even if a valid interrupt occurs simultaneously with the HOLD signal.

The state of the HOLD and the unmasked interrupt lines is latched internally during CLK = 1 of each T_{HOLD} state as well as during T_{HALT} states. If the internal latched HOLD signal is low during CLK = 1, the CPU will exit T_{HOLD} and enter T_{HALT} on the following CLK = 1.

The 8085A accepts the first unmasked, enabled interrupt sampled; thereafter, all interrupt sampling is inhibited. The interrupt thus accepted will inevitably be executed when the CPU exits the HOLD state, even at the expense of holding off higher-priority interrupts (including TRAP). (See Figure 2-22.)

When the CPU is not in T_{HALT} or T_{HOLD}, it internally latches the HOLD line only during CLK = 1 of the last state before T_3 (T_2 or T_{WAIT}) and during CLK = 1 of the last state before T_5 (T_4 of a six T-state M_1). If the internal latched HOLD signal is high during the next CLK = 1, the CPU will enter T_{HOLD} after the following clock. When the CPU is not in T_{HALT} or T_{HOLD}, it will internally latch the state of the unmasked interupts only during CLK of the next to the last state before each $M_1 \cdot T_1$.

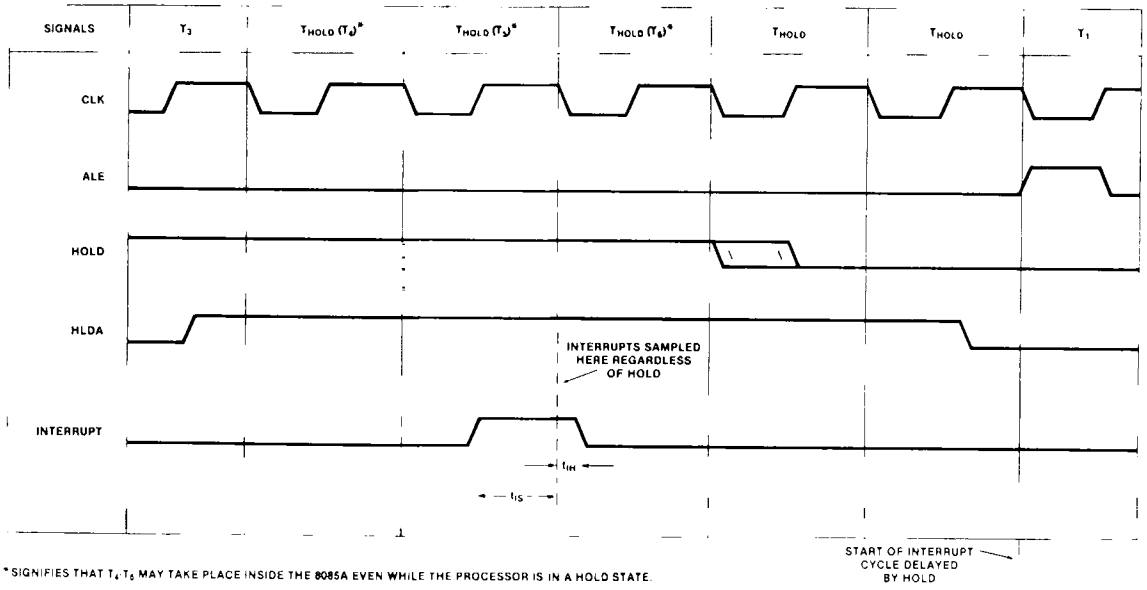


FIGURE 2-21 HOLD VS INTERRUPT — NON HALT

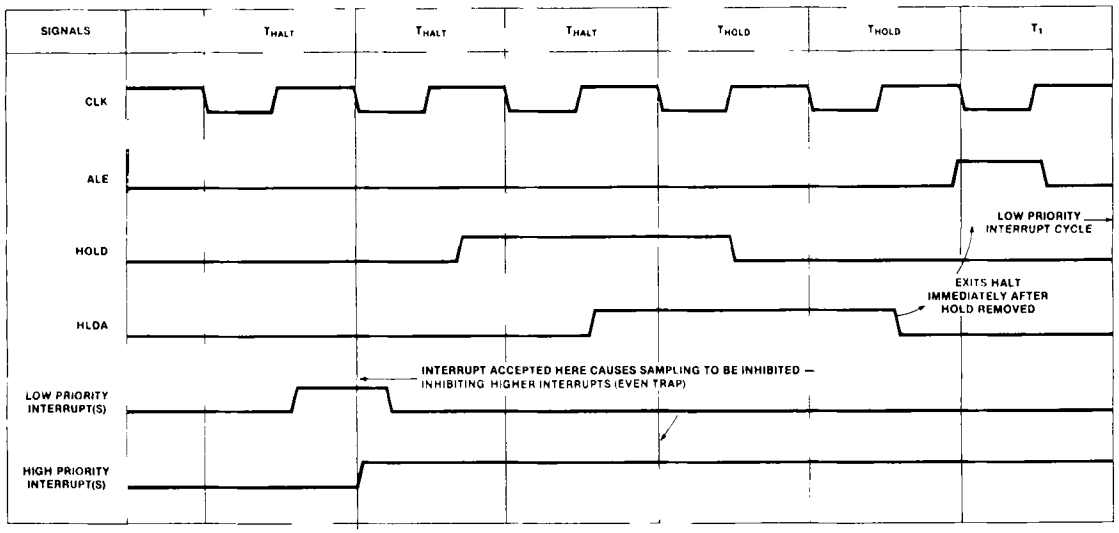


FIGURE 2-22 8085A HOLD VS INTERRUPTS — HALT MODE

2.3.7 Power On and $\overline{\text{RESET IN}}$

The 8085A employs a special internal circuit to increase its speed. This circuit, which is called a substrate bias generator, creates a negative voltage which is used to negatively bias the substrate. The circuit employs an oscillator and a charge pump which require a certain amount of time after POWER ON to stabilize. (See Figure 2-23.)

Taking this circuit into account, the 8085A is not guaranteed to work until 10 ms after V_{CC} reaches 4.75V. For this reason, it is suggested that $\overline{\text{RESET IN}}$ be kept low during this period. Note that the 10 ms period does not include the time it takes for the power supply to reach its 4.75V level — which may be milliseconds in some systems. A simple RC network (Figure 3-6) can satisfy this requirement.

The $\overline{\text{RESET IN}}$ line is latched every CLK = 1. This latched signal is recognized by the CPU during CLK = 1 of the next T state. (See Figure 2-24.) If it is low, the CPU will issue $\overline{\text{RESET OUT}}$ and enter T_{HALT} for the next T state. $\overline{\text{RESET IN}}$ should be kept low for a minimum of three clock periods to ensure proper synchronization of the CPU. When the $\overline{\text{RESET IN}}$ signal goes high, the CPU will enter $M_1 \cdot T_1$ for the next T state. Note that the various signals and buses are floated in T_{RESET} as well as T_{HALT} and T_{HOLD}. For this reason, it is desirable to provide pull-up resistors for the main control signals (particularly $\overline{\text{WR}}$).

Specifically, the $\overline{\text{RESET IN}}$ signal causes the following actions:

RESETS	SETS
PROGRAM COUNTER	RST 5.5 MASK
INSTRUCTION REGISTER	RST 6.5 MASK
INTE FF	RST 7.5 MASK
RST 7.5 FF	
TRAP FF	
SOD FF	
MACHINE STATE FF's	
MACHINE CYCLE FF's	
INTERNALLY LATCHED FF's for HOLD, INTR, and READY	

$\overline{\text{RESET IN}}$ does not explicitly change the contents of the 8085A registers (A, B, C, D, E, H, L) and the condition flags, but due to $\overline{\text{RESET IN}}$ occurring at a random time during instruction execution, the results are indeterminate.

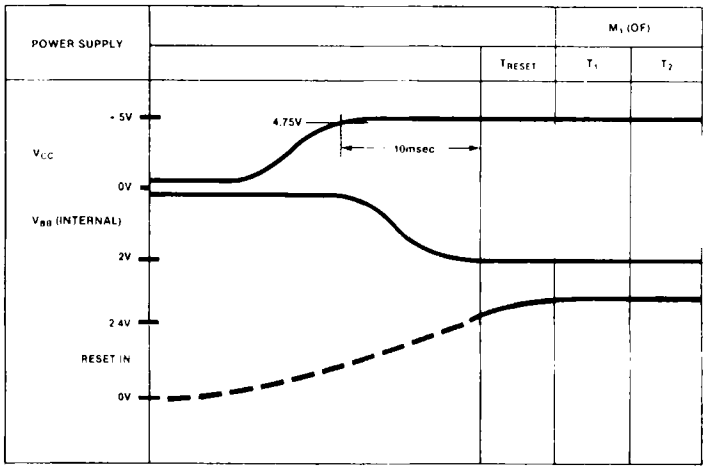


FIGURE 2-23 POWER-ON TIMING

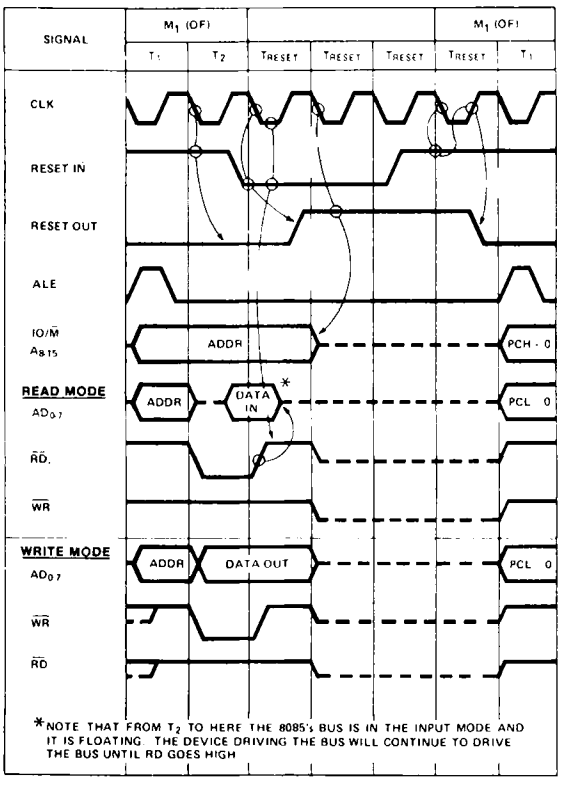


FIGURE 2-24 $\overline{\text{RESET IN}}$ TIMING

Following RESET, the 8085A will start executing instructions at location 0 with the interrupt system disabled, as shown in Figure 2-24.

Figure 2-24 also shows READ and WRITE operations being terminated by a RESET signal. Note that a RESET may prematurely terminate any READ or WRITE operation in process when the RESET occurs.

2.3.8 SID and SOD Signals:

Figure 2-25 shows the timing relationship of the SID and SOD signals to the RIM and SIM instructions. The 8085A has the ability to read the SID line into the accumulator bit 7 using RIM instructions. The state of the SID line is latched internally during $T_3 \cdot CLK = 0$ of the RIM instruction. Following this, the state of the interrupt pins and masks are also transferred directly to the accumulator.

The 8085A can set the SOD flip-flop from bit 7 of the accumulator using the SIM instruction. (See Figure 2-26.) The data is transferred from the accumulator bit 7 to SOD during $M_1 \cdot T_2 \cdot CLK = 0$ of the instruction following SIM, assuming that accumulator bit 6 is a 1. Accumulator bit 6 is a "serial output enable" bit.

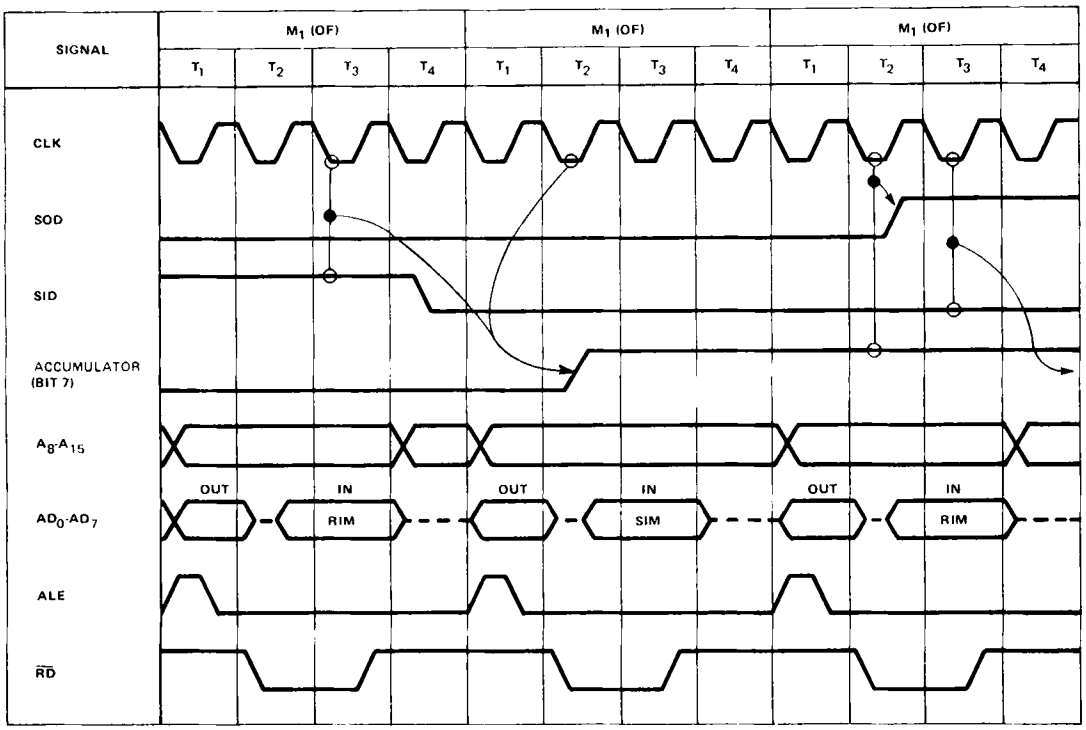
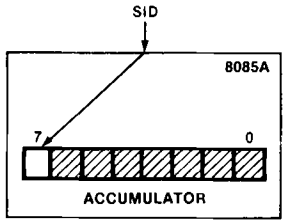


FIGURE 2-25 RELATIONSHIP OF SID AND SOD SIGNALS TO RIM AND SIM INSTRUCTIONS

EFFECT OF RIM INSTRUCTION



EFFECT OF SIM INSTRUCTION

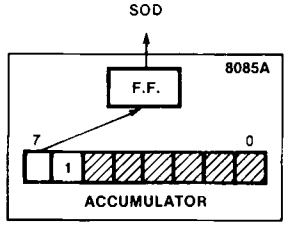


FIGURE 2-26 EFFECT OF RIM AND SIM INSTRUCTIONS

2.4 COMPARISON OF MCS-80 AND MCS-85 SYSTEM BUSES

This section compares the MCS-80 bus with the MCS-85 bus. Figure 2-28 details the signals and general timing of the two buses; the timing diagrams are drawn to the same scale (8080A clock cycle = 480 ns and 8085A clock cycle = 320 ns) to facilitate comparison.

FUNCTIONAL DESCRIPTION

MCS-80™ System Bus

The MCS-80 bus is terminated on one end by the CPU-GROUP (consisting of the 8080A, 8224, 8228) and on the other end by the various memory and I/O circuits. The following figure shows the major signals of the MCS-80 bus.

MCS-85™ System Bus

The MCS-85 bus is terminated on one end by the 8085A and the other end by various memory and I/O devices. The MCS-85 bus may be optionally de-multiplexed with an 8212 eight bit latch to provide an MCS-80 type bus. The following figure shows the major signals of the MCS-85 bus.

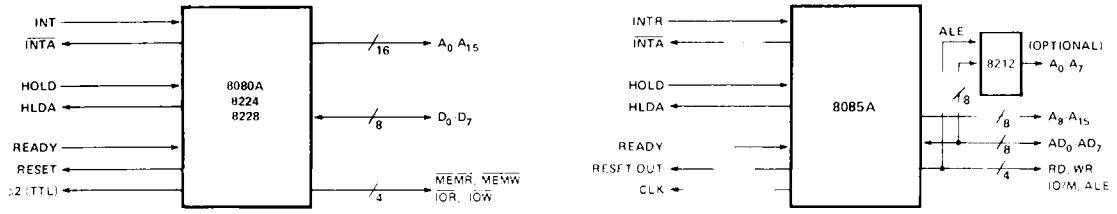


FIGURE 2-27 COMPARISON OF SYSTEM BUSES

MCS-80™ System Bus

SIGNAL(S)	FUNCTION
A_0-A_{15}	The 16 lines of the address bus identify a memory or I/O location for a data transfer operation.
D_0-D_7	The 8 lines of the data bus are used for the parallel transfer of data between two devices.
$\overline{MEMR}$, $\overline{MEMW}$, $\overline{IOR}$, $\overline{IOW}$, $\overline{INTA}$	These five control lines (MEMORY READ, MEMORY WRITE, I/O READ, I/O WRITE, and INTERRUPT ACKNOWLEDGE) identify the type and timing of a data transfer operation.
READY, RESET, HOLD, HLDA ϕ2 (TTL), INT	These signals are used for the synchronization of slow speed memories, system reset, DMA, sytem timing, and CPU interrupt.

MCS-85™ System Bus

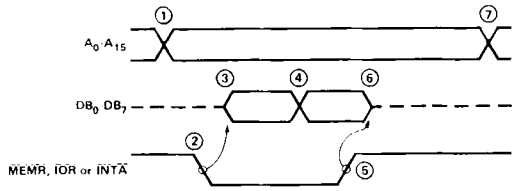
SIGNAL(S)	FUNCTION
A_8-A_{15}	These are the high order eight bits of the address, and are used to identify a memory or I/O location for a data transfer cycle.
AD_0-AD_7	These eight lines serve a dual function. During the beginning of a data transfer operation, these lines carry the low order eight bits of the address bus. During the remainder of the cycle, these lines are used for the parallel transfer of data between two devices.
$\overline{RD}$, $\overline{WR}$, $\overline{INTA}$	These signals identify the type and timing of a data transfer cycle.
IO/$\overline{M}$	The I/O/$\overline{MEMORY}$ line identifies a data transfer as being in the I/O address space or the memory address space.
ALE	ADDRESS LATCH ENABLE enables the latching of the A_0-A_7 signals.
READY, RESET OUT, HOLD, HLDA, CLK, INTR	These signals are used for the synchronization of slow speed memories, system reset, DMA, system timing and CPU interrupt.

FIGURE 2-28 COMPARISON OF SYSTEM BUSES

FUNCTIONAL DESCRIPTION

MCS-80™ System Bus for READ CYCLE

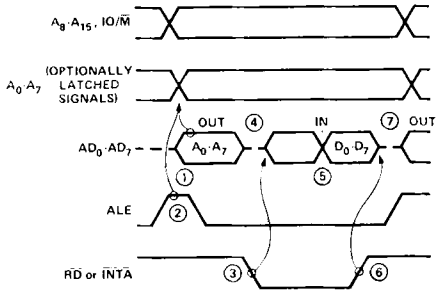
The basic timing of the MCS-80 BUS for a READ CYCLE is as follows:



The MCS-80 first presents the address ① and shortly thereafter the control signal ②. The data bus, which was in the high impedance state, is driven by the selected device ③. The selected device eventually presents the valid data to the processor ④. The processor raises the control signal ⑤, which causes the selected device to put the data bus in the high impedance state ⑥. The processor then changes the address ⑦ for the start of the next data transfer.

MCS-85™ System Bus for READ CYCLE

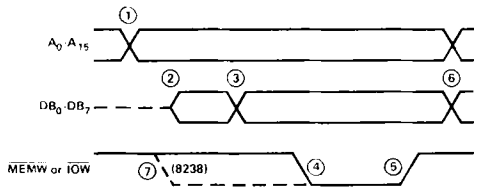
The basic timing of the MCS-85 BUS for a READ CYCLE is as follows:



At the beginning of the READ cycle, the 8085A sends out all 16 bits of address ①. This is followed by ALE ② which causes the lower eight bits of address to be latched in either the 8155/56, 8355, 8755A, or in an external 8212. $\overline{RD}$ is then dropped ③ by the 8085A. The data bus is then tri-stated by the 8085A in preparation for the selected device driving the bus ④; the selected device will continue to drive the bus with valid data ⑤, until $\overline{RD}$ is raised ⑥ by the 8085A. At the end of the READ CYCLE ⑦, the address and data lines are changed in preparation for the next cycle.

MCS-80™ System Bus for WRITE CYCLE

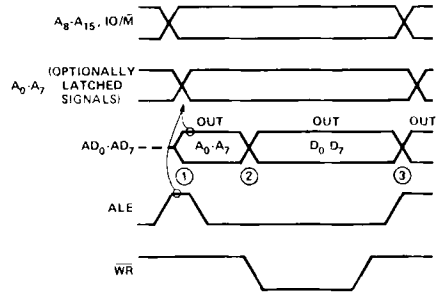
The basic timing of the MCS-80 BUS for a WRITE CYCLE is as follows:



The MCS-80 first presents the address ①, then enables the data bus driver ②, and later presents the data ③. Shortly thereafter, the MCS-80 drops the control signal ④ for an interval of time and then raises the signal ⑤. The MCS-80 then changes the address ⑥ in preparation for the next data transfer. The advance write signal of the 8238 is also shown ⑦.

MCS-85™ System Bus for WRITE CYCLE

The basic timing of the MCS-85 BUS for a WRITE CYCLE is as follows:



The timing of the WRITE CYCLE is identical to the MCS-85 READ CYCLE with the exception of the AD_0-AD_7 lines. At the beginning of the cycle ①, the low order eight bits of address are on AD_0-AD_7. After ALE drops, the eight bits of data ② are put on AD_0-AD_7. They are removed ③ at the end of the WRITE CYCLE, in anticipation of the next data transfer.

FIGURE 2-28 (Continued) COMPARISON OF SYSTEM BUSES

FUNCTIONAL DESCRIPTION

The following observations of the two buses can be made:

1. The access times from address leaving the processor to returning data are almost identical, even though the 8085A is operating 50% faster than the 8080.
2. With the addition of an 8212 latch to the 8085A, the basic timings of the two systems are very similar.
3. The 8085A has more time for address setup to $\overline{RD}$ than the 8080.
4. The MCS-80 has a wider $\overline{RD}$ signal, but a narrower $\overline{WR}$ signal than the 8085A.
5. The MCS-80 provides stable data setup to the leading and trailing edges of $\overline{WR}$, while the 8085 provides stable data setup to only the trailing edge of $\overline{WR}$.
6. The MCS-80 control signals have different widths and occur at different points in the machine cycle, while the 8085A control signals have identical timing.
7. While not shown on the chart, the MCS-80 data and address hold times are adversely affected by the processor preparing to enter the HOLD state. The 8085A has identical timing regardless of entering HOLD.
8. Also not shown on the chart is the fact that all output signals of the 8085A have $-400\mu a$ of source current and 2.0 ma of sink current. The 8085A also has input voltage levels of $V_{IL} = 0.8V$ and $V_{IH} = 2.0V$.

CONCLUSION:

The preceding discussion has clearly shown that the MCS-85 bus satisfies the two restrictions of COMPATIBILITY and SPEED. It is compatible because it requires only an 8212 latch to generate an MCS-80 type bus. If the four control signals $\overline{MEMR}$, $\overline{MEMW}$, $\overline{IOR}$ and $\overline{IOW}$ are desired, they can be generated from $\overline{RD}$, $\overline{WR}$, and IO/$\overline{M}$ with a decoder or a few gates. The MCS-85 bus is also fast. While running at 3MHz, the 8085A generates better timing signals than the MCS-80 does at 2MHz. Furthermore, the multiplexed bus structure doesn't slow the 8085A down, because it is using the internal states to overlap the fetch and execution portions of different machine cycles. Finally, the MCS-85 can be slowed down or sped up considerably, while still providing reasonable timing.

TO USE. The $\overline{RD}$, $\overline{WR}$, and $\overline{INTA}$ control signals all have identical timing, which isn't affected by the CPU preparing to enter the HOLD state. Furthermore, the address and data bus have good setup and hold times relative to the control signals. The voltage and current levels for the interface signals will all drive buses of up to 40 MOS devices, or 1 schottky TTL device.

The MCS-85 system bus is also EFFICIENT. Efficiency is the reason that the lower eight address lines are multiplexed with the data bus. Every chip that needs to use both A_0-A_7 and D_0-D_7 saves 7 pins (the eighth pin is used for ALE) on the interface to the processor. That means that 7 more pins per part are available to either add features to the part or to use a smaller package in some cases. In the three chip system shown in Figure 3-6, the use of the MCS-85 bus saves 3 x 7 = 21 pins, which are used for extra I/O and interrupt lines. A further advantage of the MCS-85 bus is apparent in Figure 3-7, which shows a printed circuit layout of the circuit in Figure 3-6. The reduced number of pins and the fact that compatible pinouts were used, provides for an extremely compact, simple, and efficient printed circuit. Notice that great care was taken when the pinouts were assigned to ensure that the signals would flow easily from chip to chip to chip.

APPENDIX C

8085 Instruction Set

The following pages are reprinted with
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8085A INSTRUCTION SET

5.1 WHAT THE INSTRUCTION SET IS

A computer, no matter how sophisticated, can do only what it is instructed to do. A program is a sequence of instructions, each of which is recognized by the computer and causes it to perform an operation. Once a program is placed in memory space that is accessible to your CPU, you may run that same sequence of instructions as often as you wish to solve the same problem or to do the same function. The set of instructions to which the 8085A CPU will respond is permanently fixed in the design of the chip.

Each computer instruction allows you to initiate the performance of a specific operation. The 8085A implements a group of instructions that move data between registers, between a register and memory, and between a register and an I/O port. It also has arithmetic and logic instructions, conditional and unconditional branch instructions, and machine control instructions. The CPU recognizes these instructions only when they are coded in binary form.

5.2 SYMBOLS AND ABBREVIATIONS:

The following symbols and abbreviations are used in the subsequent description of the 8085A instructions:

SYMBOLS	MEANING
accumulator	Register A
addr	16-bit address quantity
data	8-bit quantity
data 16	16-bit data quantity
byte 2	The second byte of the instruction
byte 3	The third byte of the instruction
port	8-bit address of an I/O device
r,r1,r2	One of the registers A,B,C, D,E,H,L

DDD,SSS — The bit pattern designating one of the registers A,B,C,D, E,H,L (DDD = destination, SSS = source):

DDD or SSS	REGISTER NAME
111	A
000	B
001	C
010	D
011	E
100	H
101	L

rp — One of the register pairs:

B represents the B,C pair with B as the high-order register and C as the low-order register;

D represents the D,E pair with D as the high-order register and E as the low-order register;

H represents the H,L pair with H as the high-order register and L as the low-order register;

SP represents the 16-bit stack pointer register.

RP — The bit pattern designating one of the register pairs B,D,H,SP:

RP	REGISTER PAIR
00	B-C
01	D-E
10	H-L
11	SP

rh — The first (high-order) register of a designated register pair.

rl — The second (low-order) register of a designated register pair.

PC	16-bit program counter register (PCH and PCL are used to refer to the high-order and low-order 8 bits respectively).
SP	16-bit stack pointer register (SPH and SPL are used to refer to the high-order and low-order 8 bits respectively).
r_m	Bit m of the register r (bits are number 7 through 0 from left to right).
LABEL	16-bit address of subroutine.
	The condition flags:
Z	Zero
S	Sign
P	Parity
CY	Carry
AC	Auxiliary Carry
( )	The contents of the memory location or registers enclosed in the parentheses.
←	"Is transferred to"
∧	Logical AND
∀	Exclusive OR
∧	Inclusive OR
+	Addition
−	Two's complement subtraction
*	Multiplication
↔	"Is exchanged with"
——	The one's complement (e.g., $\overline{(A)}$)
n	The restart number 0 through 7
NNN	The binary representation 000 through 111 for restart number 0 through 7 respectively.

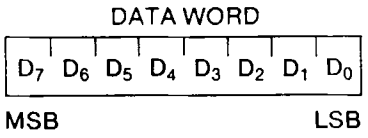
The instruction set encyclopedia is a detailed description of the 8085A instruction set. Each instruction is described in the following manner:

1. The MCS-85 macro assembler format, consisting of the instruction mnemonic and operand fields, is printed in **BOLDFACE** on the first line.
2. The name of the instruction is enclosed in parentheses following the mnemonic.
3. The next lines contain a symbolic description of what the instruction does.
4. This is followed by a narrative description of the operation of the instruction.
5. The boxes describe the binary codes that comprise the machine instruction.
6. The last four lines contain information about the execution of the instruction. The number of machine cycles and states required to execute the instruction are listed first. If the instruction has two possible execution times, as in a conditional jump, both times are listed, separated by a slash. Next, data addressing modes are listed if applicable. The last line lists any of the five flags that are affected by the execution of the instruction.

5.3 INSTRUCTION AND DATA FORMATS

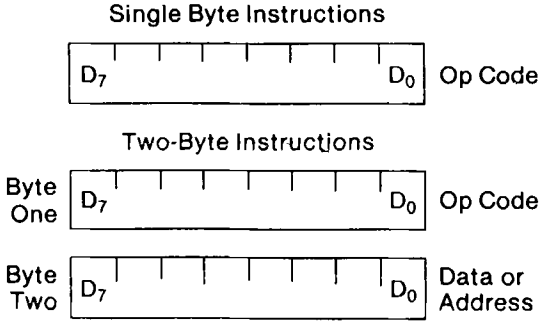
Memory used in the MCS-85 system is organized in 8-bit bytes. Each byte has a unique location in physical memory. That location is described by one of a sequence of 16-bit binary addresses. The 8085A can address up to 64K (K = 1024, or 2^{10}; hence, 64K represents the decimal number 65,536) bytes of memory, which may consist of both random-access, read-write memory (RAM) and read-only memory (ROM), which is also random-access.

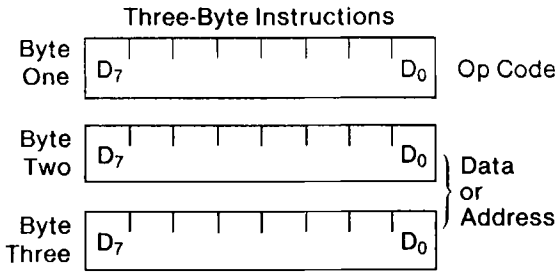
Data in the 8085A is stored in the form of 8-bit binary integers:



When a register or data word contains a binary number, it is necessary to establish the order in which the bits of the number are written. In the Intel 8085A, BIT 0 is referred to as the **Least Significant Bit (LSB),** and BIT 7 (of an 8-bit number) is referred to as the **Most Significant Bit (MSB).**

An 8085A program instruction may be one, two or three bytes in length. Multiple-byte instructions must be stored in successive memory locations; the address of the first byte is always used as the address of the instruction. The exact instruction format will depend on the particular operation to be executed.





5.4 ADDRESSING MODES:

Often the data that is to be operated on is stored in memory. When multi-byte numeric data is used, the data, like instructions, is stored in successive memory locations, with the least significant byte first, followed by increasingly significant bytes. The 8085A has four different modes for addressing data stored in memory or in registers:

- Direct — Bytes 2 and 3 of the instruction contain the exact memory address of the data item (the low-order bits of the address are in byte 2, the high-order bits in byte 3).
- Register — The instruction specifies the register or register pair in which the data is located.
- Register Indirect — The instruction specifies a register pair which contains the memory address where the data is located (the high-order bits of the address are in the first register of the pair the low-order bits in the second).
- Immediate — The instruction contains the data itself. This is either an 8-bit quantity or a 16-bit quantity (least significant byte first, most significant byte second).

Unless directed by an interrupt or branch institution, the execution of instructions proceeds through consecutively increasing memory locations. A branch instruction can specify the address of the next instruction to be executed in one of two ways:

- Direct — The branch instruction contains the address of the next instruction to be executed. (Except for the 'RST' instruction, byte 2 contains the low-order address and byte 3 the high-order address.)
- Register Indirect — The branch instruction indicates a register-pair which contains the address of the next instruction to be executed. (The high-order bits of the address are in the first register of the pair, the low-order bits in the second.)

The RST instruction is a special one-byte call instruction (usually used during interrupt sequences). RST includes a three-bit field; program control is transferred to the instruction whose address is eight times the contents of this three-bit field.

5.5 CONDITION FLAGS:

There are five condition flags associated with the execution of instructions on the 8085A. They are Zero, Sign, Parity, Carry, and Auxiliary Carry. Each is represented by a 1-bit register (or flip-flop) in the CPU. A flag is set by forcing the bit to 1; it is reset by forcing the bit to 0.

Unless indicated otherwise, when an instruction affects a flag, it affects it in the following manner:

Zero: If the result of an instruction has the value 0, this flag is set; otherwise it is reset.

Sign: If the most significant bit of the result of the operation has the value 1, this flag is set; otherwise it is reset.

Parity: If the modulo 2 sum of the bits of the result of the operation is 0, (i.e., if the result has even parity), this flag is set; otherwise it is reset (i.e., if the result has odd parity).

Carry: If the instruction resulted in a carry (from addition), or a borrow (from subtraction or a comparison) out of the high-order bit, this flag is set; otherwise it is reset.

Auxiliary Carry: If the instruction caused a carry out of bit 3 and into bit 4 of the resulting value, the auxiliary carry is set; otherwise it is reset. This flag is affected by single-precision additions, subtractions, increments, decrements, comparisons, and logical operations, but is principally used with additions and increments preceding a DAA (Decimal Adjust Accumulator) instruction.

5.6 INSTRUCTION SET ENCYCLOPEDIA

In the ensuing dozen pages, the complete 8085A instruction set is described, grouped in order under five different functional headings, as follows:

1. **Data Transfer Group** — Moves data between registers or between memory locations and registers. Includes moves, loads, stores, and exchanges. (See below.)
2. **Arithmetic Group** — Adds, subtracts, increments, or decrements data in registers or memory. (See page 5-13.)
3. **Logic Group** — ANDs, ORs, XORs, compares, rotates, or complements data in registers or between memory and a register. (See page 5-16.)
4. **Branch Group** — Initiates conditional or unconditional jumps, calls, returns, and restarts. (See page 5-20.)
5. **Stack, I/O, and Machine Control Group** — Includes instructions for maintaining the stack, reading from input ports, writing to output ports, setting and reading interrupt masks, and setting and clearing flags. (See page 5-22.)

The formats described in the encyclopedia reflect the assembly language processed by Intel-supplied assembler, used with the Intellec® development systems.

5.6.1 Data Transfer Group

This group of instructions transfers data to and from registers and memory. **Condition flags are not affected by any instruction in this group.**

MOV r1, r2 (Move Register)
(r1) ← (r2)
The content of register r2 is moved to register r1.

0	1	D	D	D	S	S	S

Cycles: 1
States: 4 (8085), 5 (8080)
Addressing: register
Flags: none

MOV r, M (Move from memory)
(r) ← ((H) (L))
The content of the memory location, whose address is in registers H and L, is moved to register r.

0	1	D	D	D	1	1	0

Cycles: 2
States: 7
Addressing: reg. indirect
Flags: none

MOV M, r (Move to memory)
((H)) (L)) ← (r)
The content of register r is moved to the memory location whose address is in registers H and L.

0	1	1	1	0	S	S	S

Cycles: 2
States: 7
Addressing: reg. indirect
Flags: none

MVI r, data (Move Immediate)
(r) ← (byte 2)
The content of byte 2 of the instruction is moved to register r.

0	0	D	D	D	1	1	0
data							

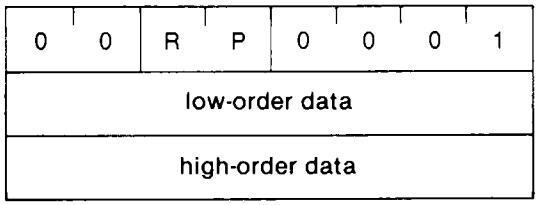
Cycles: 2
States: 7
Addressing: immediate
Flags: none

MVI M, data (Move to memory immediate)
((H) (L)) ← (byte 2)
The content of byte 2 of the instruction is moved to the memory location whose address is in registers H and L.

0	0	1	1	0	1	1	0
data							

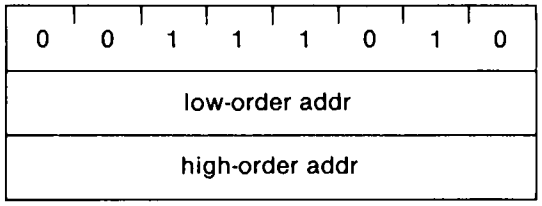
Cycles: 3
States: 10
Addressing: immed./reg. indirect
Flags: none

LXI rp, data 16 (Load register pair immediate)
(rh) ← (byte 3),
(rl) ← (byte 2)
Byte 3 of the instruction is moved into the high-order register (rh) of the register pair rp. Byte 2 of the instruction is moved into the low-order register (rl) of the register pair rp.



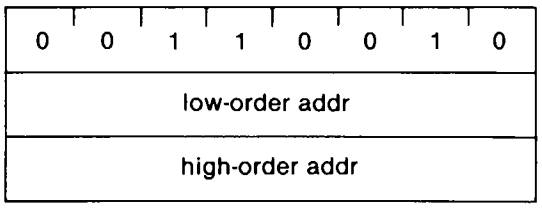
Cycles: 3
States: 10
Addressing: immediate
Flags: none

LDA addr (Load Accumulator direct)
(A) ← ((byte 3)(byte 2))
The content of the memory location, whose address is specified in byte 2 and byte 3 of the instruction, is moved to register A.



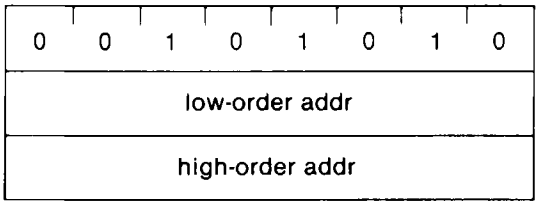
Cycles: 4
States: 13
Addressing: direct
Flags: none

STA addr (Store Accumulator direct)
((byte 3)(byte 2)) ← (A)
The content of the accumulator is moved to the memory location whose address is specified in byte 2 and byte 3 of the instruction.



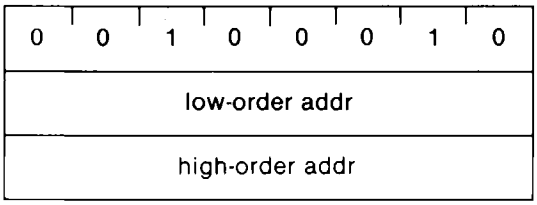
Cycles: 4
States: 13
Addressing: direct
Flags: none

LHLD addr (Load H and L direct)
(L)←((byte 3)(byte 2))
(H)←((byte 3)(byte 2)+1)
The content of the memory location, whose address is specified in byte 2 and byte 3 of the instruction, is moved to register L. The content of the memory location at the succeeding address is moved to register H.



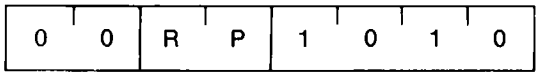
Cycles: 5
States: 16
Addressing: direct
Flags: none

SHLD addr (Store H and L direct)
((byte 3)(byte 2))←(L)
((byte 3)(byte 2)+1)←(H)
The content of register L is moved to the memory location whose address is specified in byte 2 and byte 3. The content of register H is moved to the succeeding memory location.



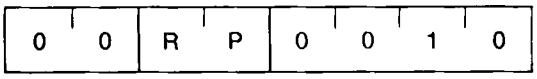
Cycles: 5
States: 16
Addressing: direct
Flags: none

LDAX rp (Load accumulator indirect)
(A) ← ((rp))
The content of the memory location, whose address is in the register pair rp, is moved to register A. Note: only register pairs rp = B (registers B and C) or rp = D (registers D and E) may be specified.



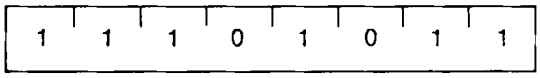
Cycles: 2
States: 7
Addressing: reg. indirect
Flags: none

STAX rp (Store accumulator indirect)
((rp)) ← (A)
The content of register A is moved to the memory location whose address is in the register pair rp. Note: only register pairs rp = B (registers B and C) or rp = D (registers D and E) may be specified.



Cycles: 2
States: 7
Addressing: reg. indirect
Flags: none

XCHG (Exchange H and L with D and E)
(H) ↔ (D)
(L) ↔ (E)
The contents of registers H and L are exchanged with the contents of registers D and E.



Cycles: 1
States: 4
Addressing: register
Flags: none

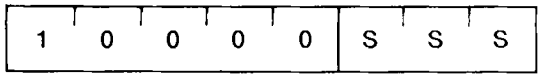
5.6.2 Arithmetic Group

This group of instructions performs arithmetic operations on data in registers and memory.

Unless indicated otherwise, all instructions in this group affect the Zero, Sign, Parity, Carry, and Auxiliary Carry flags according to the standard rules.

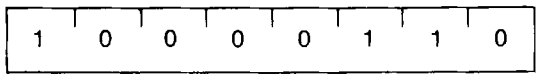
All subtraction operations are performed via two's complement arithmetic and set the carry flag to one to indicate a borrow and clear it to indicate no borrow.

ADD r (Add Register)
(A) ← (A) + (r)
The content of register r is added to the content of the accumulator. The result is placed in the accumulator.



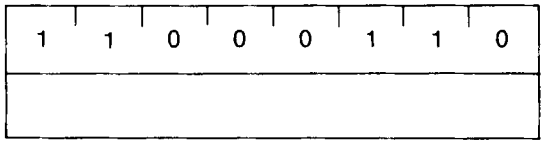
Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

ADD M (Add memory)
(A) ← (A) + ((H) (L))
The content of the memory location whose address is contained in the H and L registers is added to the content of the accumulator. The result is placed in the accumulator.



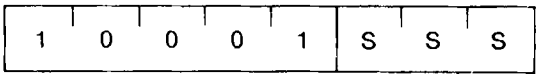
Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

ADI data (Add immediate)
(A) ← (A) + (byte 2)
The content of the second byte of the instruction is added to the content of the accumulator. The result is placed in the accumulator.



Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

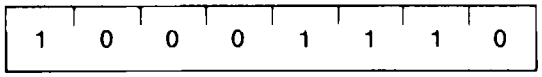
ADC r (Add Register with carry)
(A) ← (A) + (r) + (CY)
The content of register r and the content of the carry bit are added to the content of the accumulator. The result is placed in the accumulator.



Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

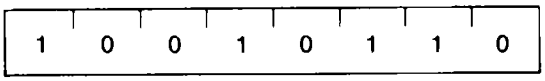
THE INSTRUCTION SET

ADC M (Add memory with carry)
(A) ← (A) + ((H) (L)) + (CY)
The content of the memory location whose address is contained in the H and L registers and the content of the CY flag are added to the accumulator. The result is placed in the accumulator.



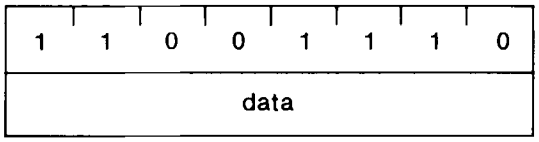
Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

SUB M (Subtract memory)
(A) ← (A) − ((H) (L))
The content of the memory location whose address is contained in the H and L registers is subtracted from the content of the accumulator. The result is placed in the accumulator.



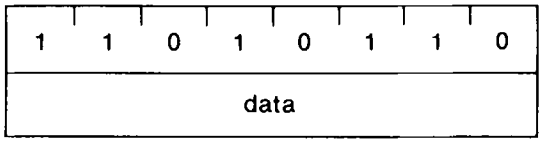
Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

ACI data (Add immediate with carry)
(A) ← (A) + (byte 2) + (CY)
The content of the second byte of the instruction and the content of the CY flag are added to the contents of the accumulator. The result is placed in the accumulator.



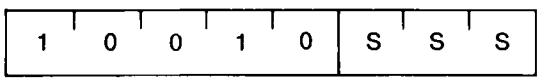
Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

SUI data (Subtract immediate)
(A) ← (A) − (byte 2)
The content of the second byte of the instruction is subtracted from the content of the accumulator. The result is placed in the accumulator.



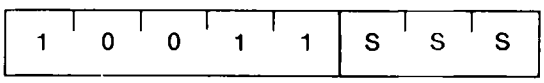
Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

SUB r (Subtract Register)
(A) ← (A) − (r)
The content of register r is subtracted from the content of the accumulator. The result is placed in the accumulator.



Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

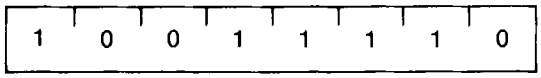
SBB r (Subtract Register with borrow)
(A) ← (A) − (r) − (CY)
The content of register r and the content of the CY flag are both subtracted from the accumulator. The result is placed in the accumulator.



Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

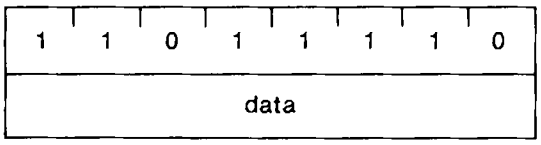
THE INSTRUCTION SET

SBB M (Subtract memory with borrow)
(A) ← (A) − ((H) (L)) − (CY)
The content of the memory location whose address is contained in the H and L registers and the content of the CY flag are both subtracted from the accumulator. The result is placed in the accumulator.



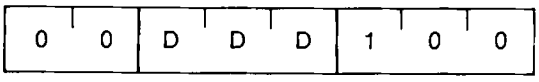
Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

SBI data (Subtract immediate with borrow)
(A) ← (A) − (byte 2) − (CY)
The contents of the second byte of the instruction and the contents of the CY flag are both subtracted from the accumulator. The result is placed in the accumulator.



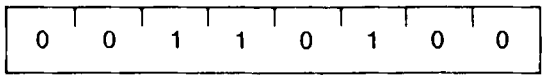
Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

INR r (Increment Register)
(r) ← (r) + 1
The content of register r is incremented by one. Note: All condition flags **except CY** are affected.



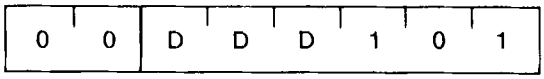
Cycles: 1
States: 4 (8085), 5 (8080)
Addressing: register
Flags: Z,S,P,AC

INR M (Increment memory)
((H) (L) ← ((H) (L)) + 1
The content of the memory location whose address is contained in the H and L registers is incremented by one. Note: All condition flags **except CY** are affected.



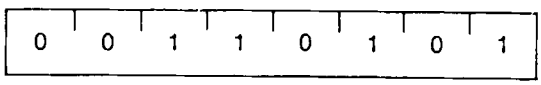
Cycles: 3
States: 10
Addressing: reg. indirect
Flags: Z,S,P,AC

DCR r (Decrement Register)
(r) ← (r) − 1
The content of register r is decremented by one. Note: All condition flags **except CY** are affected.



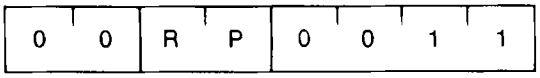
Cycles: 1
States: 4 (8085), 5 (8080)
Addressing: register
Flags: Z,S,P,AC

DCR M (Decrement memory)
((H) (L)) ← ((H) (L)) − 1
The content of the memory location whose address is contained in the H and L registers is decremented by one. Note: All condition flags **except CY** are affected.



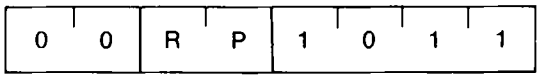
Cycles: 3
States: 10
Addressing: reg. indirect
Flags: Z,S,P,AC

INX rp (Increment register pair)
(rh) (rl) ← (rh) (rl) + 1
The content of the register pair rp is incremented by one. Note: **No condition flags are affected.**



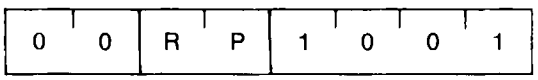
Cycles: 1
States: 6 (8085), 5 (8080)
Addressing: register
Flags: none

DCX rp (Decrement register pair)
(rh) (rl) ← (rh) (rl) − 1
The content of the register pair rp is decremented by one. Note: **No condition flags are affected.**



Cycles: 1
States: 6 (8085), 5 (8080)
Addressing: register
Flags: none

DAD rp (Add register pair to H and L)
(H) (L) ← (H) (L) + (rh) (rl)
The content of the register pair rp is added to the content of the register pair H and L. The result is placed in the register pair H and L. Note: **Only the CY flag is affected.** It is set if there is a carry out of the double precision add; otherwise it is reset.

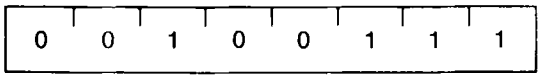


Cycles: 3
States: 10
Addressing: register
Flags: CY

DAA (Decimal Adjust Accumulator)
The eight-bit number in the accumulator is adjusted to form two four-bit Binary-Coded-Decimal digits by the following process:

1. If the value of the lease significant 4 bits of the accumulator is greater than 9 **or** if the AC flag is set, 6 is added to the accumulator.
2. If the value of the most significant 4 bits of the accumulator is now greater than 9, **or** if the CY flag is set, 6 is added to the most significant 4 bits of the accumulator.

NOTE: All flags are affected.



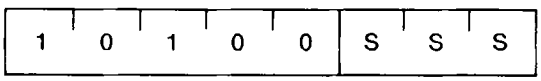
Cycles: 1
States: 4
Flags: Z,S,P,CY,AC

5.6.3 Logical Group

This group of instructions performs logical (Boolean) operations on data in registers and memory and on condition flags.

Unless indicated otherwise, all instructions in this group affect the Zero, Sign, Parity, Auxiliary Carry, and Carry flags according to the standard rules.

ANA r (AND Register)
(A) ← (A) ∧ (r)
The content of register r is logically ANDed with the content of the accumulator. The result is placed in the accumulator. **The CY flag is cleared and AC is set (8085). The CY flag is cleared and AC is set to the OR'ing of bits 3 of the operands (8080).**



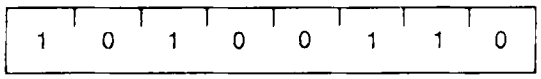
Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

THE INSTRUCTION SET

ANA M (AND memory)

(A) ← (A) ∧ ((H) (L))

The contents of the memory location whose address is contained in the H and L registers is logically ANDed with the content of the accumulator. The result is placed in the accumulator. **The CY flag is cleared and AC is set (8085). The CY flag is cleared and AC is set to the OR'ing of bits 3 of the operands (8080).**

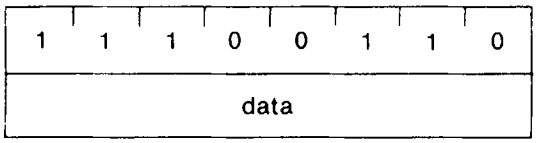


Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

ANI data (AND immediate)

(A) ← (A) ∧ (byte 2)

The content of the second byte of the instruction is logically ANDed with the contents of the accumulator. The result is placed in the accumulator. **The CY flag is cleared and AC is set (8085). The CY flag is cleared and AC is set to the OR'ing of bits 3 of the operands (8080).**

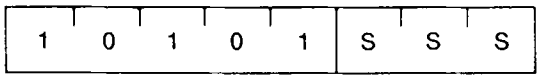


Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

XRA r (Exclusive OR Register)

(A) ← (A) ⊻ (r)

The content of register r is exclusive-OR'd with the content of the accumulator. The result is placed in the accumulator. **The CY and AC flags are cleared.**

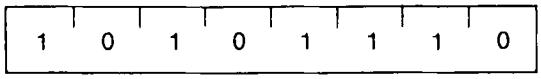


Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

XRA M (Exclusive OR Memory)

(A) ← (A) ⊻ ((H) (L))

The content of the memory location whose address is contained in the H and L registers is exclusive-OR'd with the content of the accumulator. The result is placed in the accumulator. **The CY and AC flags are cleared.**

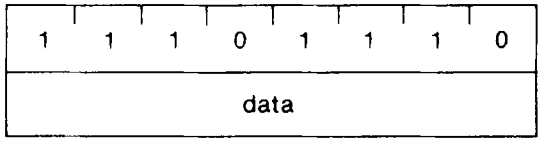


Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

XRI data (Exclusive OR immediate)

(A) ← (A) ⊻ (byte 2)

The content of the second byte of the instruction is exclusive-OR'd with the content of the accumulator. The result is placed in the accumulator. **The CY and AC flags are cleared.**

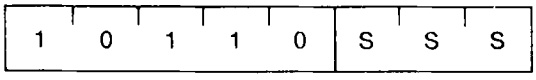


Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

ORA r (OR Register)

(A) ← (A) V (r)

The content of register r is inclusive-OR'd with the content of the accumulator. The result is placed in the accumulator. **The CY and AC flags are cleared.**

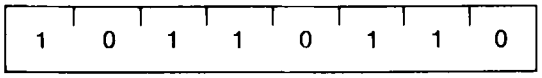


Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

ORA M (OR memory)

(A) ← (A) V ((H) (L))

The content of the memory location whose address is contained in the H and L registers is inclusive-OR'd with the content of the accumulator. The result is placed in the accumulator. **The CY and AC flags are cleared.**

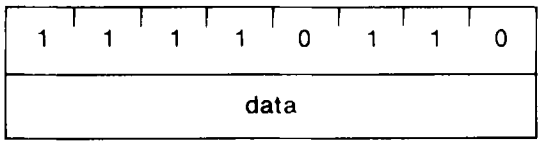


Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

ORI data (OR Immediate)

(A) ← (A) V (byte 2)

The content of the second byte of the instruction is inclusive-OR'd with the content of the accumulator. The result is placed in the accumulator. **The CY and AC flags are cleared..**

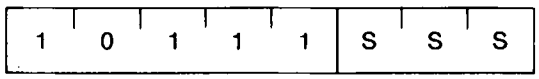


Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

CMP r (Compare Register)

(A) – (r)

The content of register r is subtracted from the accumulator. The accumulator remains unchanged. The condition flags are set as a result of the subtraction. **The Z flag is set to 1 if (A) = (r). The CY flag is set to 1 if (A) < (r).**

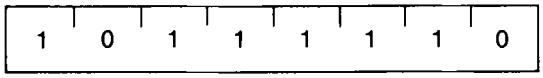


Cycles: 1
States: 4
Addressing: register
Flags: Z,S,P,CY,AC

CMP M (Compare memory)

(A) – ((H) (L))

The content of the memory location whose address is contained in the H and L registers is subtracted from the accumulator. The accumulator remains unchanged. The condition flags are set as a result of the subtraction. **The Z flag is set to 1 if (A) = ((H) (L)). The CY flag is set to 1 if (A) < ((H) (L)).**

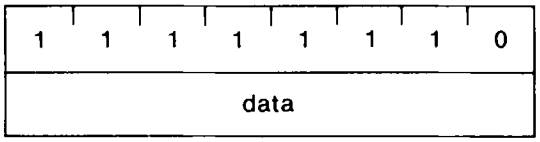


Cycles: 2
States: 7
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

CPI data (Compare immediate)

(A) – (byte 2)

The content of the second byte of the instruction is subtracted from the accumulator. The condition flags are set by the result of the subtraction. **The Z flag is set to 1 if (A) = (byte 2). The CY flag is set to 1 if (A) < (byte 2).**



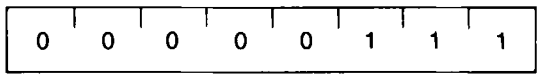
Cycles: 2
States: 7
Addressing: immediate
Flags: Z,S,P,CY,AC

RLC (Rotate left)

$(A_{n+1}) \leftarrow (A_n)$;$(A_0) \leftarrow (A_7)$

(CY) ← (A_7)

The content of the accumulator is rotated left one position. The low order bit and the CY flag are both set to the value shifted out of the high order bit position. **Only the CY flag is affected.**



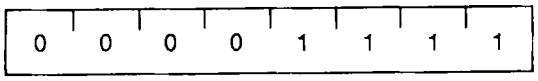
Cycles: 1
States: 4
Flags: CY

THE INSTRUCTION SET

RRC (Rotate right)

$(A_n) \leftarrow (A_{n+1})$; $(A_7) \leftarrow (A_0)$
$(CY) \leftarrow (A_0)$

The content of the accumulator is rotated right one position. The high order bit and the CY flag are both set to the value shifted out of the low order bit position. **Only the CY flag is affected.**

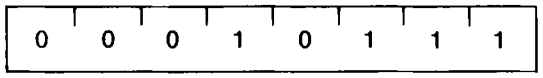


Cycles: 1
States: 4
Flags: CY

RAL (Rotate left through carry)

$(A_{n+1}) \leftarrow (A_n)$; $(CY) \leftarrow (A_7)$
$(A_0) \leftarrow (CY)$

The content of the accumulator is rotated left one position through the CY flag. The low order bit is set equal to the CY flag and the CY flag is set to the value shifted out of the high order bit. **Only the CY flag is affected.**

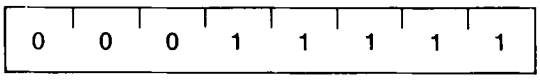


Cycles: 1
States: 4
Flags: CY

RAR (Rotate right through carry)

$(A_n) \leftarrow (A_{n+1})$;$(CY) \leftarrow (A_0)$
$(A_7) \leftarrow (CY)$

The content of the accumulator is rotated right one position through the CY flag. The high order bit is set to the CY flag and the CY flag is set to the value shifted out of the low order bit. **Only the CY flag is affected.**

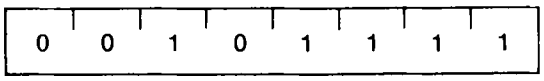


Cycles: 1
States: 4
Flags: CY

CMA (Complement accumulator)

$(A) \leftarrow (\overline{A})$

The contents of the accumulator are complemented (zero bits become 1, one bits become 0). **No flags are affected.**

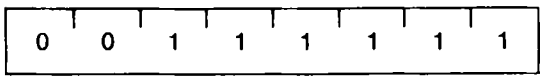


Cycles: 1
States: 4
Flags: none

CMC (Complement carry)

$(CY) \leftarrow (\overline{CY})$

The CY flag is complemented. **No other flags are affected.**

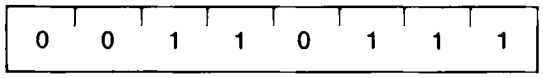


Cycles: 1
States: 4
Flags: CY

STC (Set carry)

$(CY) \leftarrow 1$

The CY flag is set to 1. **No other flags are affected.**



Cycles: 1
States: 4
Flags: CY

5.6.4 Branch Group

This group of instructions alter normal sequential program flow.

Condition flags are not affected by any instruction in this group.

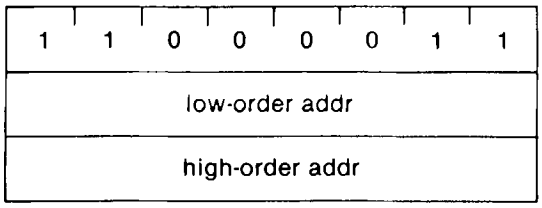
The two types of branch instructions are unconditional and conditional. Unconditional transfers simply perform the specified operation on register PC (the program counter). Conditional transfers examine the status of one of the four processor flags to determine if the specified branch is to be executed. The conditions that may be specified are as follows:

CONDITION	CCC
NZ — not zero (Z = 0)	000
Z — zero (Z = 1)	001
NC — no carry (CY = 0)	010
C — carry (CY = 1)	011
PO — parity odd (P = 0)	100
PE — parity even (P = 1)	101
P — plus (S = 0)	110
M — minus (S = 1)	111

JMP addr (Jump)

(PC) ← (byte 3) (byte 2)

Control is transferred to the instruction whose address is specified in byte 3 and byte 2 of the current instruction.



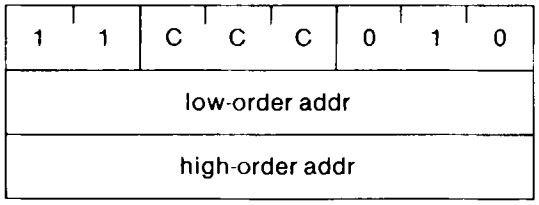
Cycles: 3
States: 10
Addressing: immediate
Flags: none

Jcondition addr (Conditional jump)

If (CCC),

(PC) ← (byte 3) (byte 2)

If the specified condition is true, control is transferred to the instruction whose address is specified in byte 3 and byte 2 of the current instruciton; otherwise, control continues sequentially.



Cycles: 2/3 (8085), 3 (8080)
States: 7/10 (8085), 10 (8080)
Addressing: immediate
Flags: none

CALL addr (Call)

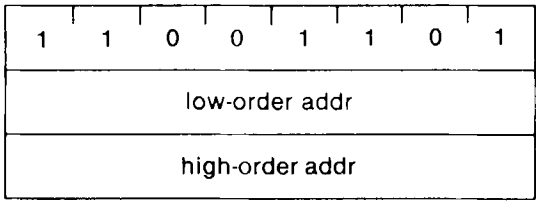
((SP) − 1) ← (PCH)

((SP) − 2) ← (PCL)

(SP) ← (SP) − 2

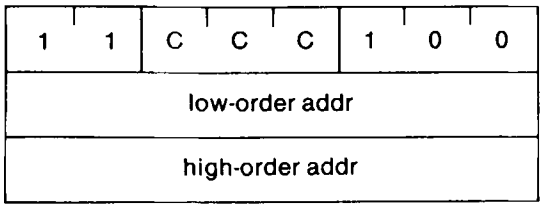
(PC) ← (byte 3) (byte 2)

The high-order eight bits of the next instruction address are moved to the memory location whose address is one less than the content of register SP. The low-order eight bits of the next instruction address are moved to the memory location whose address is two less than the content of register SP. The content of register SP is decremented by 2. Control is transferred to the instruction whose address is specified in byte 3 and byte 2 of the current instruction.



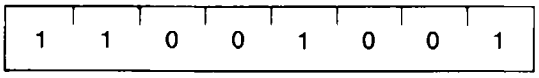
Cycles: 5
States: 18 (8085), 17 (8080)
Addressing: immediate/ reg. indirect
Flags: none

Ccondition addr (Condition call)
If (CCC),
((SP) − 1) ← (PCH)
((SP) − 2) ← (PCL)
(SP) ← (SP) − 2
(PC) ← (byte 3) (byte 2)
If the specified condition is true, the actions specified in the CALL instruction (see above) are performed; otherwise, control continues sequentially.



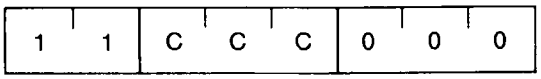
Cycles: 2/5 (8085), 3/5 (8080)
States: 9/18 (8085), 11/17 (8080)
Addressing: immediate/ reg. indirect
Flags: none

RET (Return)
(PCL) ← ((SP));
(PCH) ← ((SP) + 1);
(SP) ← (SP) + 2;
The content of the memory location whose address is specified in register SP is moved to the low-order eight bits of register PC. The content of the memory location whose address is one more than the content of register SP is moved to the high-order eight bits of register PC. The content of register SP is incremented by 2.



Cycles: 3
States: 10
Addressing: reg. indirect
Flags: none

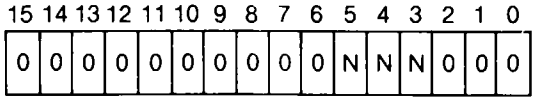
Rcondition (Conditional return)
If (CCC),
(PCL) ← ((SP))
(PCH) ← ((SP) + 1)
(SP) ← (SP) + 2
If the specified condition is true, the actions specified in the RET instruction (see above) are performed; otherwise, control continues sequentially.



Cycles: 1/3
States: 6/12 (8085), 5/11 (8080)
Addressing: reg. indirect
Flags: none

RST n (Restart)
((SP) − 1) ← (PCH)
((SP) − 2) ← (PCL)
(SP) ← (SP) − 2
(PC) ← 8 * (NNN)
The high-order eight bits of the next instruction address are moved to the memory location whose address is one less than the content of register SP. The low-order eight bits of the next instruction address are moved to the memory location whose address is two less than the content of register SP. The content of register SP is decremented by two. Control is transferred to the instruction whose address is eight times the content of NNN.

Cycles: 3
States: 12 (8085), 11 (8080)
Addressing: reg. indirect
Flags: none

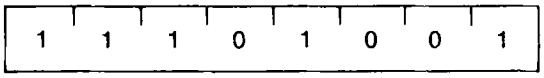


Program Counter After Restart

PCHL (Jump H and L indirect — move H and L to PC)

(PCH) ← (H)
(PCL) ← (L)

The content of register H is moved to the high-order eight bits of register PC. The content of register L is moved to the low-order eight bits of register PC.



Cycles: 1
States: 6 (8085), 5 (8080)
Addressing: register
Flags: none

5.6.5 Stack, I/O, and Machine Control Group

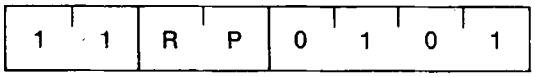
This group of instructions performs I/O, manipulates the Stack, and alters internal control flags.

Unless otherwise specified, **condition flags are not affected by any instructions in this group.**

PUSH rp (Push)

((SP) − 1) ← (rh)
((SP) − 2) ← (rl)
((SP) ← (SP) − 2

The content of the high-order register of register pair rp is moved to the memory location whose address is one less than the content of register SP. The content of the low-order register of register pair rp is moved to the memory location whose address is two less than the content of register SP. The content of register SP is decremented by 2. **Note: Register pair rp = SP may not be specified.**

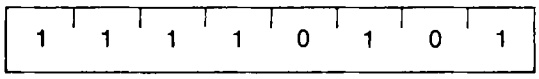


Cycles: 3
States: 12 (8085), 11 (8080)
Addressing: reg. indirect
Flags: none

PUSH PSW (Push processor status word)

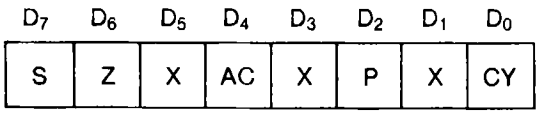
((SP) − 1) ← (A)
((SP) − 2)$_0$ ← (CY), ((SP) − 2)$_1$ ← X
((SP) − 2)$_2$ ← (P), ((SP) − 2)$_3$ ← X
((SP) − 2)$_4$ ← (AC), ((SP) − 2)$_5$ ← X
((SP) − 2)$_6$ ← (Z), ((SP) − 2)$_7$ ← (S)
(SP) ← (SP) − 2 X: Undefined.

The content of register A is moved to the memory location whose address is one less than register SP. The contents of the condition flags are assembled into a processor status word and the word is moved to the memory location whose address is two less than the content of register SP. The content of register SP is decremented by two.



Cycles: 3
States: 12 (8085), 11 (8080)
Addressing: reg. indirect
Flags: none

FLAG WORD

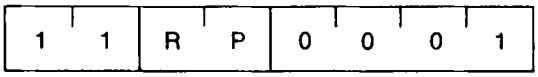


X: undefined

POP rp (Pop)

(rl) ← ((SP))
(rh) ← ((SP) + 1)
(SP) ← (SP) + 2

The content of the memory location, whose address is specified by the content of register SP, is moved to the low-order register of register pair rp. The content of the memory location, whose address is one more than the content of register SP, is moved to the high-order register of register rp. The content of register SP is incremented by 2. **Note: Register pair rp = SP may not be specified.**

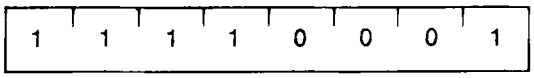


Cycles: 3
States: 10
Addressing: reg.indirect
Flags: none

POP PSW (Pop processor status word)

(CY) ← ((SP))$_0$
(P)← ((SP))$_2$
(AC)← ((SP))$_4$
(Z) ← ((SP))$_6$
(S) ← ((SP))$_7$
(A) ← ((SP) + 1)
(SP) ← (SP) + 2

The content of the memory location whose address is specified by the content of register SP is used to restore the condition flags. The content of the memory location whose address is one more than the content of register SP is moved to register A. The content of register SP is incremented by 2.

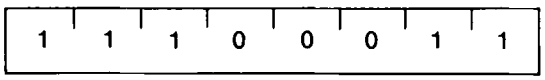


Cycles: 3
States: 10
Addressing: reg. indirect
Flags: Z,S,P,CY,AC

XTHL (Exchange stack top with H and L)

(L) ↔ ((SP))
(H) ↔ ((SP) + 1)

The content of the L register is exchanged with the content of the memory location whose address is specified by the content of register SP. The content of the H register is exchanged with the content of the memory location whose address is one more than the content of register SP.

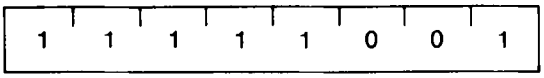


Cycles: 5
States: 16 (8085), 18 (8080)
Addressing: reg. indirect
Flags: none

SPHL (Move HL to SP)

(SP) ← (H) (L)

The contents of registers H and L (16 bits) are moved to register SP.

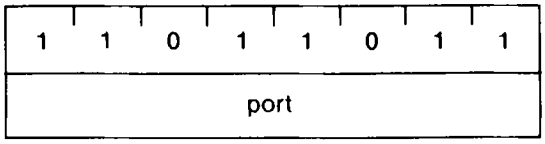


Cycles: 1
States: 6 (8085), 5 (8080)
Addressing: register
Flags: none

IN port (Input)

(A)←(data)

The data placed on the eight bit bi-directional data bus by the specified port is moved to register A.

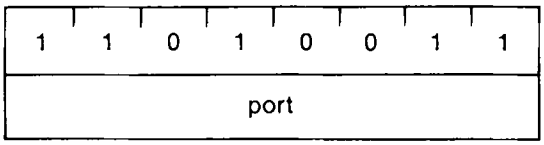


Cycles: 3
States: 10
Addressing: direct
Flags: none

OUT port (Output)

(data) ← (A)

The content of register A is placed on the eight bit bi-directional data bus for transmission to the specified port.



Cycles: 3
States: 10
Addressing: direct
Flags: none

EI (Enable interrupts)

The interrupt system is enabled **following the execution of the next instruction. Interrupts are not recognized during the EI instruction.**

1	1	1	1	1	0	1	1

Cycles: 1
States: 4
Flags: none

NOTE: Placing an EI instruction on the bus in response to $\overline{INTA}$ during an INA cycle is prohibited. (8085)

DI (Disable interrupts)

The interrupt system is disabled **immediately following the execution of the DI instruction. Interrupts are not recognized during the DI instruction.**

1	1	1	1	0	0	1	1

Cycles: 1
States: 4
Flags: none

NOTE: Placing a DI instruction on the bus in response to $\overline{INTA}$ during an INA cycle is prohibited. (8085)

HLT (Halt)

The processor is stopped. The registers and flags are unaffected. (8080) A second ALE is generated during the execution of HLT to strobe out the Halt cycle status information. (8085)

0	1	1	1	0	1	1	0

Cycles: 1+ (8085), 1 (8080)
States: 5 (8085), 7 (8080)
Flags: none

NOP (No op)

No operation is performed. The registers and flags are unaffected.

0	0	0	0	0	0	0	0

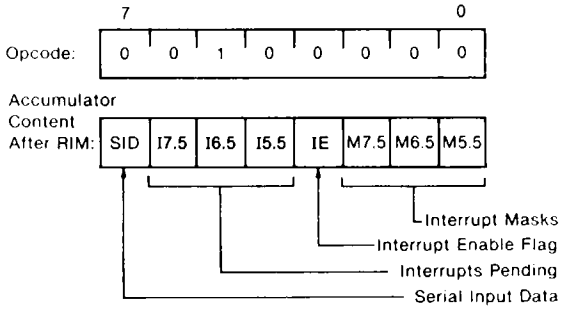
Cycles: 1
States: 4
Flags: none

RIM (Read Interrupt Masks) (8085 only)

The RIM instruction loads data into the accumulator relating to interrupts and the serial input. This data contains the following information:

- Current interrupt mask status for the RST 5.5, 6.5, and 7.5 hardware interrupts (1 = mask disabled)
- Current interrupt enable flag status (1 = interrupts enabled) except immediately following a TRAP interrupt. (See below.)
- Hardware interrupts pending (i.e., signal received but not yet serviced), on the RST 5.5, 6.5, and 7.5 lines.
- Serial input data.

Immediately following a TRAP interrupt, the RIM instruction must be executed as a part of the service routine if you need to retrieve current interrupt status later. Bit 3 of the accumulator is (in this special case only) loaded with the interrupt enable (IE) flag status that existed prior to the TRAP interrupt. Following an RST 5.5, 6.5, 7.5, or INTR interrupt, the interrupt flag flip-flop reflects the current interrupt enable status. Bit 6 of the accumulator (I7.5) is loaded with the status of the RST 7.5 flip-flop, which is always set (edge-triggered) by an input on the RST 7.5 input line, even when that interrupt has been previously masked. (See SIM Instruction.)



Cycles: 1
States: 4
Flags: none

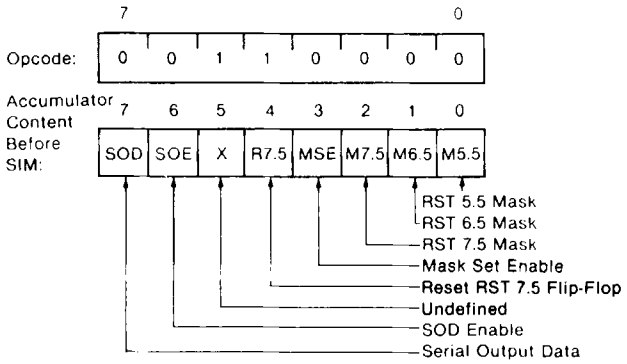
SIM (Set Interrupt Masks) (8085 only)

The execution of the SIM instruction uses the contents of the accumulator (which must be previously loaded) to perform the following functions:

- Program the interrupt mask for the RST 5.5, 6.5, and 7.5 hardware interrupts.
- Reset the edge-triggered RST 7.5 input latch.
- Load the SOD output latch.

To program the interrupt masks, first set accumulator bit 3 to 1 and set to 1 any bits 0, 1, and 2, which disable interrupts RST 5.5, 6.5, and 7.5, respectively. Then do a SIM instruction. If accumulator bit 3 is 0 when the SIM instruction is executed, the interrupt mask register will not change. If accumulator bit 4 is 1 when the SIM instruction is executed, the RST 7.5 latch is then reset. RST 7.5 is distinguished by the fact that its latch is always set by a rising edge on the RST 7.5 input pin, even if the jump to service routine is inhibited by masking. This latch remains high until cleared by a $\overline{\text{RESET IN}}$, by a SIM Instruction with accumulator bit 4 high, or by an internal processor acknowledge to an RST 7.5 interrupt subsequent to the removal of the mask (by a SIM instruction). The $\overline{\text{RESET IN}}$ signal always sets all three RST mask bits.

If accumulator bit 6 is at the 1 level when the SIM instruction is executed, the state of accumulator bit 7 is loaded into the SOD latch and thus becomes available for interface to an external device. The SOD latch is unaffected by the SIM instruction if bit 6 is 0. SOD is always reset by the $\overline{\text{RESET IN}}$ signal.



Cycles: 1
States: 4
Flags: none

8080A/8085A INSTRUCTION SET INDEX
Table 5-1

Instruction		Code	Bytes	T States		Machine Cycles
				8085A	8080A	
ACI	DATA	CE data	2	7	7	F R
ADC	REG	1000 1SSS	1	4	4	F
ADC	M	8E	1	7	7	F R
ADD	REG	1000 0SSS	1	4	4	F
ADD	M	86	1	7	7	F R
ADI	DATA	C6 data	2	7	7	F R
ANA	REG	1010 0SSS	1	4	4	F
ANA	M	A6	1	7	7	F R
ANI	DATA	E6 data	2	7	7	F R
CALL	LABEL	CD addr	3	18	17	S R R W W*
CC	LABEL	DC addr	3	9/18	11/17	S R•/S R R W W*
CM	LABEL	FC addr	3	9/18	11/17	S R•/S R R W W*
CMA		2F	1	4	4	F
CMC		3F	1	4	4	F
CMP	REG	1011 1SSS	1	4	4	F
CMP	M	BE	1	7	7	F R
CNC	LABEL	D4 addr	3	9/18	11/17	S R•/S R R W W*
CNZ	LABEL	C4 addr	3	9/18	11/17	S R•/S R R W W*
CP	LABEL	F4 addr	3	9/18	11/17	S R•/S R R W W*
CPE	LABEL	EC addr	3	9/18	11/17	S R•/S R R W W*
CPI	DATA	FE data	2	7	7	F R
CPO	LABEL	E4 addr	3	9/18	11/17	S R•/S R R W W*
CZ	LABEL	CC addr	3	9/18	11/17	S R•/S R R W W*
DAA		27	1	4	4	F
DAD	RP	00RP 1001	1	10	10	F 8 B
DCR	REG	00SS S101	1	4	5	F*
DCR	M	35	1	10	10	F R W
DCX	RP	00RP 1011	1	6	5	S*
DI		F3	1	4	4	F
EI		FB	1	4	4	F
HLT		76	1	5	7	F B
IN	PORT	DB data	2	10	10	F R I
INR	REG	00SS S100	1	4	5	F*
INR	M	34	1	10	10	F R W
INX	RP	00RP 0011	1	6	5	S*
JC	LABEL	DA addr	3	7/10	10	F R/F R R†
JM	LABEL	FA addr	3	7/10	10	F R/F R R†
JMP	LABEL	C3 addr	3	10	10	F R R
JNC	LABEL	D2 addr	3	7/10	10	F R/F R R†
JNZ	LABEL	C2 addr	3	7/10	10	F R/F R R†
JP	LABEL	F2 addr	3	7/10	10	F R/F R R†
JPE	LABEL	EA addr	3	7/10	10	F R/F R R†
JPO	LABEL	E2 addr	3	7/10	10	F R/F R R†
JZ	LABEL	CA addr	3	7/10	10	F R/F R R†
LDA	ADDR	3A addr	3	13	13	F R R R
LDAX	RP	000X 1010	1	7	7	F R
LHLD	ADDR	2A addr	3	16	16	F R R R

Instruction		Code	Bytes	T States		Machine Cycles
				8085A	8080A	
LXI	RP,DATA16	00RP 0001 data16	3	10	10	F R R
MOV	REG,REG	01DD DSSS	1	4	5	F*
MOV	M,REG	0111 0SSS	1	7	7	F W
MOV	REG,M	01DD D110	1	7	7	F R
MVI	REG,DATA	00DD D110 data	2	7	7	F R
MVI	M,DATA	36 data	2	10	10	F R W
NOP		00	1	4	4	F
ORA	REG	1011 0SSS	1	4	4	F
ORA	M	B6	1	7	7	F R
ORI	DATA	F6 data	2	7	7	F R
OUT	PORT	D3 data	2	10	10	F R O
PCHL		E9	1	6	5	S*
POP	RP	11RP 0001	1	10	10	F R R
PUSH	RP	11RP 0101	1	12	11	S W W*
RAL		17	1	4	4	F
RAR		1F	1	4	4	F
RC		D8	1	6/12	5/11	S/S R R*
RET		C9	1	10	10	F R R
RIM (8085A only)		20	1	4	–	F
RLC		07	1	4	4	F
RM		F8	1	6/12	5/11	S/S R R*
RNC		D0	1	6/12	5/11	S/S R R*
RNZ		C0	1	6/12	5/11	S/S R R*
RP		F0	1	6/12	5/11	S/S R R*
RPE		E8	1	6/12	5/11	S/S R R*
RPO		E0	1	6/12	5/11	S/S R R*
RRC		0F	1	4	4	F
RST	N	11XX X111	1	12	11	S W W*
RZ		C8	1	6/12	5/11	S/S R R*
SBB	REG	1001 1SSS	1	4	4	F
SBB	M	9E	1	7	7	F R
SBI	DATA	DE data	2	7	7	F R
SHLD	ADDR	22 addr	3	16	16	F R R W W
SIM (8085A only)		30	1	4	–	F
SPHL		F9	1	6	5	S*
STA	ADDR	32 addr	3	13	13	F R R W
STAX	RP	000X 0010	1	7	7	F W
STC		37	1	4	4	F
SUB	REG	1001 0SSS	1	4	4	F
SUB	M	96	1	7	7	F R
SUI	DATA	D6 data	2	7	7	F R
XCHG		EB	1	4	4	F
XRA	REG	1010 1SSS	1	4	4	F
XRA	M	AE	1	7	7	F R
XRI	DATA	EE data	2	7	7	F R
XTHL		E3	1	16	18	F R R W W

Machine cycle types:

F	Four clock period instr fetch
S	Six clock period instr fetch
R	Memory read
I	I/O read
W	Memory write
O	I/O write
B	Bus idle
X	Variable or optional binary digit
DDD	Binary digits identifying a destination register: B = 000, C = 001, D = 010, Memory = 110
SSS	Binary digits identifying a source register: E = 011, H = 100, L = 101, A = 111
RP	Register Pair: BC = 00, HL = 10; DE = 01, SP = 11

*Five clock period instruction fetch with 8080A.

†The longer machine cycle sequence applies regardless of condition evaluation with 8080A.

•An extra READ cycle (R) will occur for this condition with 8080A.

8085A CPU INSTRUCTIONS IN OPERATION CODE SEQUENCE
Table 5-2

OP CODE	MNEMONIC	OP CODE	MNEMONIC	OP CODE	MNEMONIC	OP CODE	MNEMONIC	OP CODE	MNEMONIC	OP CODE	MNEMONIC
00	NOP	2B	DCX H	56	MOV D,M	81	ADD C	AC	XRA H	D7	RST 2
01	LXI B,D16	2C	INR L	57	MOV D,A	82	ADD D	AD	XRA L	D8	RC
02	STAX B	2D	DCR L	58	MOV E,B	83	ADD E	AE	XRA M	D9	–
03	INX B	2E	MVI L,D8	59	MOV E,C	84	ADD H	AF	XRA A	DA	JC Adr
04	INR B	2F	CMA	5A	MOV E,D	85	ADD L	B0	ORA B	DB	IN D8
05	DCR B	30	SIM	5B	MOV E,E	86	ADD M	B1	ORA C	DC	CC Adr
06	MVI B,D8	31	LXI SP,D16	5C	MOV E,H	87	ADD A	B2	ORA D	DD	–
07	RLC	32	STA Adr	5D	MOV E,L	88	ADC B	B3	ORA E	DE	SBI D8
08	–	33	INX SP	5E	MOV E,M	89	ADC C	B4	ORA H	DF	RST 3
09	DAD B	34	INR M	5F	MOV E,A	8A	ADC D	B5	ORA L	E0	RPO
0A	LDAX B	35	DCR M	60	MOV H,B	8B	ADC E	B6	ORA M	E1	POP H
0B	DCX B	36	MVI M,D8	61	MOV H,C	8C	ADC H	B7	ORA A	E2	JPO Adr
0C	INR C	37	STC	62	MOV H,D	8D	ADC L	B8	CMP B	E3	XTHL
0D	DCR C	38	–	63	MOV H,E	8E	ADC M	B9	CMP C	E4	CPO Adr
0E	MVI C,D8	39	DAD SP	64	MOV H,H	8F	ADC A	BA	CMP D	E5	PUSH H
0F	RRC	3A	LDA Adr	65	MOV H,L	90	SUB B	BB	CMP E	E6	ANI D8
10	–	3B	DCX SP	66	MOV H,M	91	SUB C	BC	CMP H	E7	RST 4
11	LXI D,D16	3C	INR A	67	MOV H,A	92	SUB D	BD	CMP L	E8	RPE
12	STAX D	3D	DCR A	68	MOV L,B	93	SUB E	BE	CMP M	E9	PCHL
13	INX D	3E	MVI A,D8	69	MOV L,C	94	SUB H	BF	CMP A	EA	JPE Adr
14	INR D	3F	CMC	6A	MOV L,D	95	SUB L	C0	RNZ	EB	XCHG
15	DCR D	40	MOV B,B	6B	MOV L,E	96	SUB M	C1	POP B	EC	CPE Adr
16	MVI D,D8	41	MOV B,C	6C	MOV L,H	97	SUB A	C2	JNZ Adr	ED	–
17	RAL	42	MOV B,D	6D	MOV L,L	98	SBB B	C3	JMP Adr	EE	XRI D8
18	–	43	MOV B,E	6E	MOV L,M	99	SBB C	C4	CNZ Adr	EF	RST 5
19	DAD D	44	MOV B,H	6F	MOV L,A	9A	SBB D	C5	PUSH B	F0	RP
1A	LDAX D	45	MOV B,L	70	MOV M,B	9B	SBB E	C6	ADI D8	F1	POP PSW
1B	DCX D	46	MOV B,M	71	MOV M,C	9C	SBB H	C7	RST 0	F2	JP Adr
1C	INR E	47	MOV B,A	72	MOV M,D	9D	SBB L	C8	RZ	F3	DI
1D	DCR E	48	MOV C,B	73	MOV M,E	9E	SBB M	C9	RET Adr	F4	CP Adr
1E	MVI E,D8	49	MOV C,C	74	MOV M,H	9F	SBB A	CA	JZ	F5	PUSH PSW
1F	RAR	4A	MOV C,D	75	MOV M,L	A0	ANA B	CB	–	F6	ORI D8
20	RIM	4B	MOV C,E	76	HLT	A1	ANA C	CC	CZ Adr	F7	RST 6
21	LXI H,D16	4C	MOV C,H	77	MOV M,A	A2	ANA D	CD	CALL Adr	F8	RM
22	SHLD Adr	4D	MOV C,L	78	MOV A,B	A3	ANA E	CE	ACI D8	F9	SPHL
23	INX H	4E	MOV C,M	79	MOV A,C	A4	ANA H	CF	RST 1	FA	JM Adr
24	INR H	4F	MOV C,A	7A	MOV A,D	A5	ANA L	D0	RNC	FB	EI
25	DCR H	50	MOV D,B	7B	MOV A,E	A6	ANA M	D1	POP D	FC	CM Adr
26	MVI H,D8	51	MOV D,C	7C	MOV A,H	A7	ANA A	D2	JNC Adr	FD	–
27	DAA	52	MOV D,D	7D	MOV A,L	A8	XRA B	D3	OUT D8	FE	CPI D8
28	–	53	MOV D,E	7E	MOV A,M	A9	XRA C	D4	CNC Adr	FF	RST 7
29	DAD H	54	MOV D,H	7F	MOV A,A	AA	XRA D	D5	PUSH D		
2A	LHLD Adr	55	MOV D,L	80	ADD B	AB	XRA E	D6	SUI D8		

D8 = constant, or logical/arithmetic expression that evaluates to an 8-bit data quantity.

D16 = constant, or logical/arithmetic expression that evaluates to a 16-bit data quantity.

Adr = 16-bit address.

8085A INSTRUCTION SET SUMMARY BY FUNCTIONAL GROUPING
Table 5-3

Mnemonic	Description	Instruction Code (1) D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0	Page
MOVE, LOAD, AND STORE										
MOV r1 r2	Move register to register	0	1	D	D	D	S	S	S	5-4
MOV M r	Move register to memory	0	1	1	1	0	S	S	S	5-4
MOV r M	Move memory to register	0	1	D	D	D	1	1	0	5-4
MVI r	Move immediate register	0	0	D	D	D	1	1	0	5-4
MVI M	Move immediate memory	0	0	1	1	0	1	1	0	5-4
LXI B	Load immediate register Pair B & C	0	0	0	0	0	0	0	1	5-5
LXI D	Load immediate register Pair D & E	0	0	0	1	0	0	0	1	5-5
LXI H	Load immediate register Pair H & L	0	0	1	0	0	0	0	1	5-5
STAX B	Store A indirect	0	0	0	0	0	0	1	0	5-6
STAX D	Store A indirect	0	0	0	1	0	0	1	0	5-6
LDAX B	Load A indirect	0	0	0	0	1	0	1	0	5-5
LDAX D	Load A indirect	0	0	0	1	1	0	1	0	5-5
STA	Store A direct	0	0	1	1	0	0	1	0	5-5
LDA	Load A direct	0	0	1	1	1	0	1	0	5-5
SHLD	Store H & L direct	0	0	1	0	0	0	1	0	5-5
LHLD	Load H & L direct	0	0	1	0	1	0	1	0	5-5
XCHG	Exchange D & E, H & L Registers	1	1	1	0	1	0	1	1	5-6
STACK OPS										
PUSH B	Push register Pair B & C on stack	1	1	0	0	0	1	0	1	5-15
PUSH D	Push register Pair D & E on stack	1	1	0	1	0	1	0	1	5-15
PUSH H	Push register Pair H & L on stack	1	1	1	0	0	1	0	1	5-15
PUSH PSW	Push A and Flags on stack	1	1	1	1	0	1	0	1	5-15
POP B	Pop register Pair B & C off stack	1	1	0	0	0	0	0	1	5-15
POP D	Pop register Pair D & E off stack	1	1	0	1	0	0	0	1	5-15
POP H	Pop register Pair H & L off stack	1	1	1	0	0	0	0	1	5-15
POP PSW	Pop A and Flags off stack	1	1	1	1	0	0	0	1	5-15
XTHL	Exchange top of stack, H & L	1	1	1	0	0	0	1	1	5-16
SPHL	H & L to stack pointer	1	1	1	1	1	0	0	1	5-16
LXI SP	Load immediate stack pointer	0	0	1	1	0	0	0	1	5-5
INX SP	Increment stack pointer	0	0	1	1	0	0	1	1	5-9
DCX SP	Decrement stack pointer	0	0	1	1	1	0	1	1	5-9
JUMP										
JMP	Jump unconditional	1	1	0	0	0	0	1	1	5-13
JC	Jump on carry	1	1	0	1	1	0	1	0	5-13
JNC	Jump on no carry	1	1	0	1	0	0	1	0	5-13
JZ	Jump on zero	1	1	0	0	1	0	1	0	5-13
JNZ	Jump on no zero	1	1	0	0	0	0	1	0	5-13
JP	Jump on positive	1	1	1	1	0	0	1	0	5-13
JM	Jump on minus	1	1	1	1	1	0	1	0	5-13
JPE	Jump on parity even	1	1	1	0	1	0	1	0	5-13
JPO	Jump on parity odd	1	1	1	0	0	0	1	0	5-13
PCHL	H & L to program counter	1	1	1	0	1	0	0	1	5-15
CALL										
CALL	Call unconditional	1	1	0	0	1	1	0	1	5-13
CC	Call on carry	1	1	0	1	1	1	0	0	5-14
CNC	Call on no carry	1	1	0	1	0	1	0	0	5-14
CZ	Call on zero	1	1	0	0	1	1	0	0	5-14
CNZ	Call on no zero	1	1	0	0	0	1	0	0	5-14
CP	Call on positive	1	1	1	1	0	1	0	0	5-14
CM	Call on minus	1	1	1	1	1	1	0	0	5-14
CPE	Call on parity even	1	1	1	0	1	1	0	0	5-14
CPO	Call on parity odd	1	1	1	0	0	1	0	0	5-14
RETURN										
RET	Return	1	1	0	0	1	0	0	1	5-14
RC	Return on carry	1	1	0	1	1	0	0	0	5-14
RNC	Return on no carry	1	1	0	1	0	0	0	0	5-14
RZ	Return on zero	1	1	0	0	1	0	0	0	5-14
RNZ	Return on no zero	1	1	0	0	0	0	0	0	5-14
RP	Return on positive	1	1	1	1	0	0	0	0	5-14
RM	Return on minus	1	1	1	1	1	0	0	0	5-14
RPE	Return on parity even	1	1	1	0	1	0	0	0	5-14
RPO	Return on parity odd	1	1	1	0	0	0	0	0	5-14
RESTART										
RST	Restart	1	1	A	A	A	1	1	1	5-14
INPUT/OUTPUT										
IN	Input	1	1	0	1	1	0	1	1	5-16
OUT	Output	1	1	0	1	0	0	1	1	5-16
INCREMENT AND DECREMENT										
INR r	Increment register	0	0	D	D	D	1	0	0	5-8
DCR r	Decrement register	0	0	D	D	D	1	0	1	5-8
INR M	Increment memory	0	0	1	1	0	1	0	0	5-8
DCR M	Decrement memory	0	0	1	1	0	1	0	1	5-8
INX B	Increment B & C registers	0	0	0	0	0	0	1	1	5-9
INX D	Increment D & E registers	0	0	0	1	0	0	1	1	5-9
INX H	Increment H & L registers	0	0	1	0	0	0	1	1	5-9
DCX B	Decrement B & C	0	0	0	0	1	0	1	1	5-9
DCX D	Decrement D & E	0	0	0	1	1	0	1	1	5-9
DCX H	Decrement H & L	0	0	1	0	1	0	1	1	5-9
ADD										
ADD r	Add register to A	1	0	0	0	0	S	S	S	5-6
ADC r	Add register to A with carry	1	0	0	0	1	S	S	S	5-6
ADD M	Add memory to A	1	0	0	0	0	1	1	0	5-6
ADC M	Add memory to A with carry	1	0	0	0	1	1	1	0	5-7
ADI	Add immediate to A	1	1	0	0	0	1	1	0	5-6
ACI	Add immediate to A with carry	1	1	0	0	1	1	1	0	5-7
DAD B	Add B & C to H & L	0	0	0	0	1	0	0	1	5-9
DAD D	Add D & E to H & L	0	0	0	1	1	0	0	1	5-9
DAD H	Add H & L to H & L	0	0	1	0	1	0	0	1	5-9
DAD SP	Add stack pointer to H & L	0	0	1	1	1	0	0	1	5-9
SUBTRACT										
SUB r	Subtract register from A	1	0	0	1	0	S	S	S	5-7
SBB r	Subtract register from A with borrow	1	0	0	1	1	S	S	S	5-7
SUB M	Subtract memory from A	1	0	0	1	0	1	1	0	5-7
SBB M	Subtract memory from A with borrow	1	0	0	1	1	1	1	0	5-8
SUI	Subtract immediate from A	1	1	0	1	0	1	1	0	5-7

8085A INSTRUCTION SET SUMMARY (Cont'd)
Table 5-3

Mnemonic	Description	Instruction Code (1) D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0	Page
SBI	Subtract immediate from A with borrow	1	1	0	1	1	1	1	0	5-8
LOGICAL										
ANA r	And register with A	1	0	1	0	0	S	S	S	5-9
XRA r	Exclusive OR register with A	1	0	1	0	1	S	S	S	5-10
ORA r	OR register with A	1	0	1	1	0	S	S	S	5-10
CMP r	Compare register with A	1	0	1	1	1	S	S	S	5-11
ANA M	And memory with A	1	0	1	0	0	1	1	0	5-10
XRA M	Exclusive OR memory with A	1	0	1	0	1	1	1	0	5-10
ORA M	OR memory with A	1	0	1	1	0	1	1	0	5-11
CMP M	Compare memory with A	1	0	1	1	1	1	1	0	5-11
ANI	And immediate with A	1	1	1	0	0	1	1	0	5-10
XRI	Exclusive OR immediate with A	1	1	1	0	1	1	1	0	5-10
ORI	OR immediate with A	1	1	1	1	0	1	1	0	5-11
CPI	Compare immediate with A	1	1	1	1	1	1	1	0	5-11
ROTATE										
RLC	Rotate A left	0	0	0	0	0	1	1	1	5-11
RRC	Rotate A right	0	0	0	0	1	1	1	1	5-12
RAL	Rotate A left through carry	0	0	0	1	0	1	1	1	5-12
RAR	Rotate A right through carry	0	0	0	1	1	1	1	1	5-12
SPECIALS										
CMA	Complement A	0	0	1	0	1	1	1	1	5-12
STC	Set carry	0	0	1	1	0	1	1	1	5-12
CMC	Complement carry	0	0	1	1	1	1	1	1	5-12
DAA	Decimal adjust A	0	0	1	0	0	1	1	1	5-9
CONTROL										
EI	Enable interrupts	1	1	1	1	1	0	1	1	5-17
DI	Disable Interrupt	1	1	1	1	0	0	1	1	5-17
NOP	No-operation	0	0	0	0	0	0	0	0	5-17
HLT	Halt	0	1	1	1	0	1	1	0	5-17
NEW 8085A INSTRUCTIONS										
RIM	Read Interrupt Mask	0	0	1	0	0	0	0	0	5-17
SIM	Set Interrupt Mask	0	0	1	1	0	0	0	0	5-18

NOTES: 1. DDS or SSS: B 000, C 001, D 010, E011, H 100, L 101, Memory 110, A 111.

2. Two possible cycle times, (6/12) indicate instruction cycles dependent on condition flags.

APPENDIX D

Data Sheets

The following pages are reprinted with the permission of Motorola, Intel, Monolithic Memories, Texas Instruments, Western Digital Corporation, Advanced Micro Devices, Fairchild, and Hitachi.

Data Sheet Index

MAIN BOARD

VIDEO LOGIC BOARD

FLOPPY DISK CONTROLLER BOARD (Z-207)

Main Board

MOTOROLA
SEMICONDUCTORS
3501 ED BLUESTEIN BLVD., AUSTIN, TEXAS 78721

MCM6665A

MOS
(N-CHANNEL, SILICON-GATE)

65,536-BIT DYNAMIC RANDOM ACCESS MEMORY

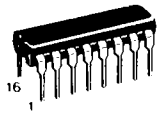
64K BIT DYNAMIC RAM

The MCM6665A is a 65,536 bit, high-speed, dynamic Random-Access Memory. Organized as 65,536 one bit words and fabricated using HMOS high-performance N-channel silicon-gate technology, this new breed of 5 volt only dynamic RAM combines high performance with low cost and improved reliability.

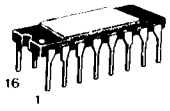
By multiplexing row- and column-address inputs, the MCM6665A requires only eight address lines and permits packaging in standard 16-pin dual-in line packages. Complete address decoding is done on chip with address latches incorporated. Data out is controlled by $\overline{CAS}$ allowing for greater system flexibility.

All inputs and outputs, including clocks, are fully TTL compatible. The MCM6665A incorporates a one transistor cell design and dynamic storage techniques.

- Organized as 65,536 Words of 1 Bit
- Single +5 V Operation (±10%)
- Full Power Supply Range Capabilities
- Maximum Access Time
  MCM6665A-12 = 120 ns
  MCM6665A-15 = 150 ns
  MCM6665A-20 = 200 ns
- Low Power Dissipation
  302.5 mW Maximum (Active) (MCM6665A-15)
  22 mW Maximum (Standby)
- Three-State Data Output
- Internal Latches for Address and Data Input
- Early-Write Common I/O Capability
- 16K Compatible 128 Cycle, 2 ms Refresh
- $\overline{RAS}$-only Refresh Mode
- $\overline{CAS}$ Controlled Output
- Upward Pin Compatible from the 16K RAM (MCM4116, MCM4517)
- Fast Page Mode Cycle Time
- Low Soft Error Rate <0.1% per 1000 Hours (See Soft Error Testing)

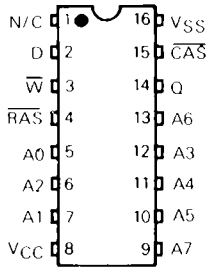


P SUFFIX
PLASTIC PACKAGE
CASE 648



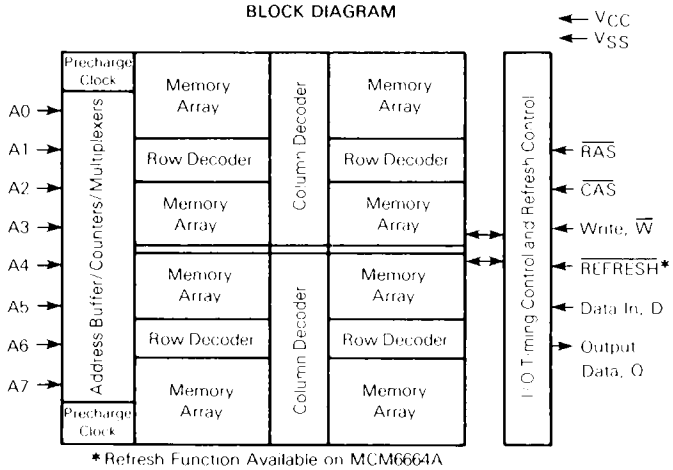
L SUFFIX
CERAMIC PACKAGE
CASE 690

PIN ASSIGNMENT



PIN NAMES	
A0-A7	Address Input
D	Data In
Q	Data Out
$\overline{W}$	Read/Write Input
$\overline{RAS}$	Row Address Strobe
$\overline{CAS}$	Column Address Strobe
V_{CC}	Power (+5 V)
V_{SS}	Ground

BLOCK DIAGRAM



*Refresh Function Available on MCM6664A

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

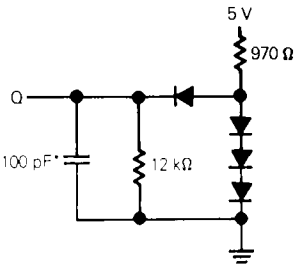
DS 9863
(Replaces ADI 876)

ABSOLUTE MAXIMUM RATINGS (See Note)

Rating	Symbol	Value	Unit
Voltage on Any Pin Relative to V_{SS} (except V_{CC})	V_{in}, V_{out}	−2 to +7	V
Voltage on V_{CC} Supply Relative to V_{SS}	V_{CC}	−1 to +7	V
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	−65 to +150	°C
Power Dissipation	P_D	1.0	W
Data Out Current	I_{out}	50	mA

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

FIGURE 1 — OUTPUT LOAD



*Includes Jig Capacitance

DC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED OPERATING CONDITIONS

Parameter		Symbol	Min	Typ	Max	Unit	Notes
Supply Voltage	MCM6665A-12, -15, -20	V_{CC}	4.5	5.0	5.5	V	1
		V_{SS}	0	0	0	V	1
Logic 1 Voltage, All Inputs		V_{IH}	2.4	–	V_{CC}+1	V	1
Logic 0 Voltage, All Inputs		V_{IL}	−1.0*	–	0.8	V	1

*The device will withstand undershoots to the −2 volt level with a maximum pulse width of 20 ns at the −1.5 volt level. This is periodically sampled rather than 100% tested.

DC CHARACTERISTICS

Characteristic	Symbol	Min	Max	Units	Notes
V_{CC} Power Supply Current (Standby)	I_{CC2}	–	4.0	mA	5
V_{CC} Power Supply Current					
6665A-12, t_{RC} = 250 ns	I_{CC1}	–	60	mA	4
6665A-15, t_{RC} = 270 ns		–	55		
6665A-20, t_{RC} = 330 ns		–	50		
V_{CC} Power Supply Current During $\overline{RAS}$ only Refresh Cycles					
6665A-12, t_{RC} = 250 ns	I_{CC3}	–	50	mA	4
6665A-15, t_{RC} = 270 ns		–	45		
6665A-20, t_{RC} = 330 ns		–	40		
V_{CC} Power Supply Current During Page Mode Cycle for t_{RAS} = 10 μsec					
6665A-12, $t_{PC} = t_{RP}$ = 120 ns	I_{CC4}	–	45	mA	4
6665A-15, $t_{PC} = t_{RP}$ = 145 ns		–	40		
6665A-20, $t_{PC} = t_{RP}$ = 200 ns		–	35		
Input Leakage Current ($V_{SS} \le V_{in} \le V_{CC}$)	$I_{I(L)}$	–	10	μA	–
Output Leakage Current ($\overline{CAS}$ at logic 1, $V_{SS} \le V_{out} \le V_{CC}$)	$I_{O(L)}$	–	10	μA	–
Output Logic 1 Voltage @ I_{out} = −4 mA	V_{OH}	2.4	–	V	–
Output Logic 0 Voltage @ I_{out} = 4 mA	V_{OL}	–	0.4	V	–

CAPACITANCE (f = 1.0 MHz, T_A = 25°C, V_{CC} = 5 V Periodically Sampled Rather Than 100% Tested)

Parameter	Symbol	Typ	Max	Unit	Notes
Input Capacitance (A0-A7), D	C_{I1}	3	5	pF	7
Input Capacitance $\overline{RAS}$, $\overline{CAS}$, $\overline{WRITE}$	C_{I2}	6	8	pF	7
Output Capacitance (Q), ($\overline{CAS}$ = V_{IH} to disable output)	C_O	5	7	pF	7

NOTES:
1. All voltages referenced to V_{SS}.
2. V_{IH} min and V_{IL} max are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} and V_{IL}.
3. An initial pause of 100 μs is required after power-up followed by any 8 $\overline{RAS}$ cycles before proper device operation is guaranteed.
4. Current is a function of cycle rate and output loading, maximum current is measured at the fastest cycle rate with the output open.
5. $\overline{RAS}$ and $\overline{CAS}$ are both at a logic 1.
6. The transition time specification applies for all inputs signals. In addition to meeting the transition rate specification, all input signals must transmit between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) in a monotonic manner.
7. Capacitance measured with a Boonton Meter or effective capacitance calculated from the equation: $C = \frac{I\Delta t}{\Delta V}$

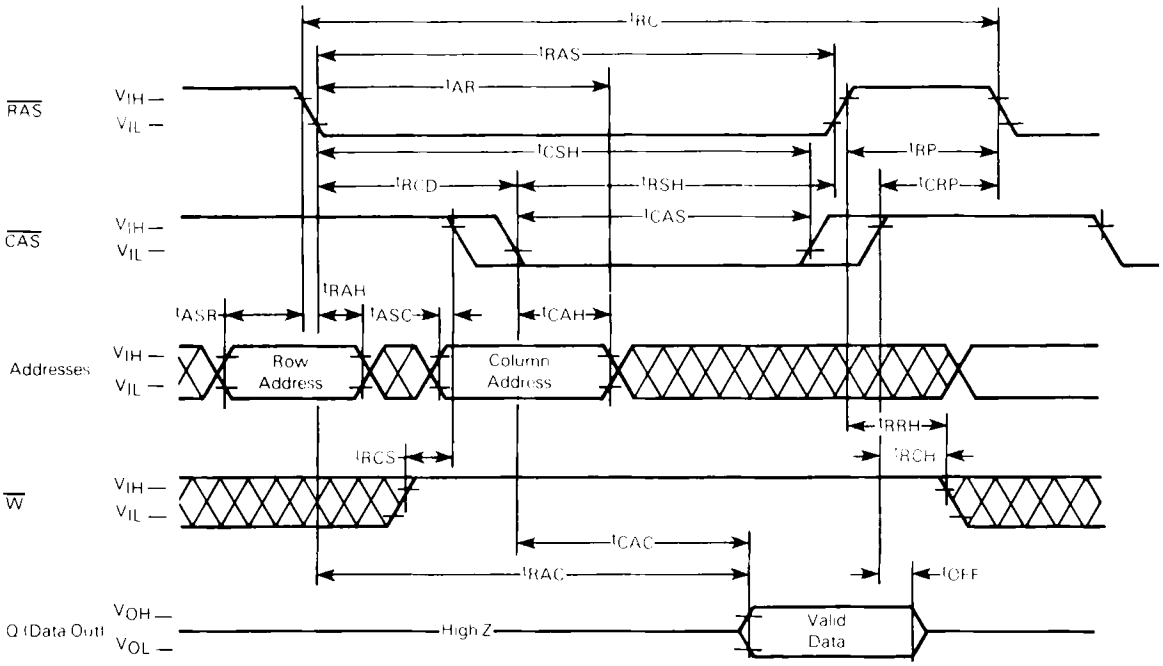
AC OPERATING CONDITIONS AND CHARACTERISTICS (Read, Write, and Read Modify-Write Cycles)

(Full Operating Voltage and Temperature Range Unless Otherwise Noted. See Notes 2, 3, 6, and Figure 1)

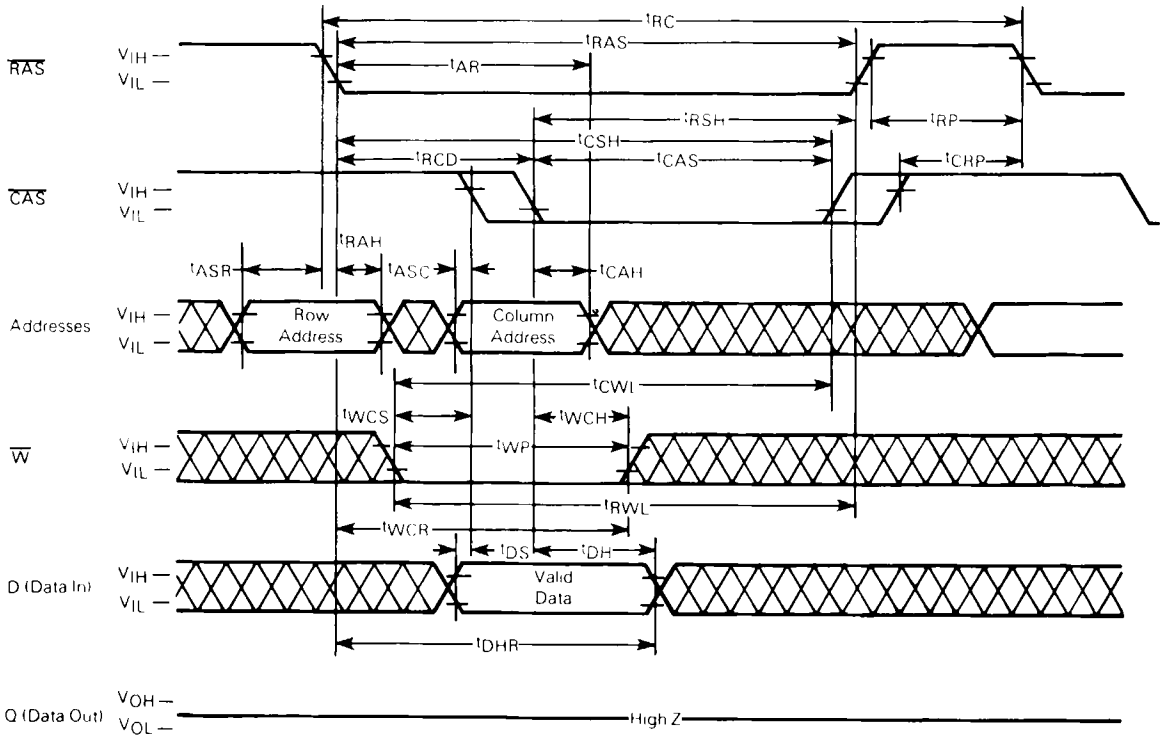
Parameter	Symbol	6665A-12		6665A-15		6665A-20		Units	Notes
		Min	Max	Min	Max	Min	Max		
Random Read or Write Cycle Time	t_{RC}	250		270		330		ns	8, 9
Read Write Cycle Time	t_{RWC}	255		280		345		ns	8, 9
Access Time from Row Address Strobe	t_{RAC}		120		150		200	ns	10, 12
Access Time from Column Address Strobe	t_{CAC}		60		75		100	ns	11, 12
Output Buffer and Turn-Off Delay	t_{OFF}	0	30	0	30	0	40	ns	18
Row Address Strobe Precharge Time	t_{RP}	100		100		120		ns	
Row Address Strobe Pulse Width	t_{RAS}	120	10000	150	10000	200	10000	ns	
Column Address Strobe Pulse Width	t_{CAS}	60	10000	75	10000	100	10000	ns	
Row to Column Strobe Lead Time	t_{RCD}	25	60	30	75	35	100	ns	13
Row Address Setup Time	t_{ASR}	0		0		0		ns	
Row Address Hold Time	t_{RAH}	15		20		25		ns	
Column Address Setup Time	t_{ASC}	0		0		0		ns	
Column Address Hold Time	t_{CAH}	25		35		45		ns	
Column Address Hold Time Referenced to $\overline{RAS}$	t_{AR}	85		95		120		ns	17
Transition Time (Rise and Fall)	t_T	3	50	3	50	3	50	ns	6
Read Command Setup Time	t_{RCS}	0		0		0		ns	
Read Command Hold Time	t_{RCH}	0		0		0		ns	14
Read Command Hold Time Referenced to $\overline{RAS}$	t_{RRH}	0		0		0		ns	14
Write Command Hold Time	t_{WCH}	25		35		45		ns	
Write Command Hold Time Referenced to $\overline{RAS}$	t_{WCR}	85		95		120		ns	17
Write Command Pulse Width	t_{WP}	25		35		45		ns	
Write Command to Row Strobe Lead Time	t_{RWL}	40		45		55		ns	
Write Command to Column Strobe Lead Time	t_{CWL}	40		45		55		ns	
Data in Setup Time	t_{DS}	0		0		0		ns	15
Data in Hold Time	t_{DH}	25		35		45		ns	15
Data in Hold Time Referenced to $\overline{RAS}$	t_{DHR}	85		95		120		ns	17
Column to Row Strobe Precharge Time	t_{CRP}	10		-10		-10		ns	
$\overline{RAS}$ Hold Time	t_{RSH}	60		75		100		ns	
Refresh Period	t_{REFH}		2.0		2.0		2.0	ms	
$\overline{WRITE}$ Command Setup Time	t_{WCS}	10		-10		-10		ns	16
$\overline{CAS}$ to $\overline{WRITE}$ Delay	t_{CWD}	40		45		55		ns	16
$\overline{RAS}$ to $\overline{WRITE}$ Delay	t_{RWD}	100		120		155		ns	16
$\overline{CAS}$ Hold Time	t_{CSH}	120		150		200		ns	
$\overline{CAS}$ Precharge Time (Page Mode Cycle Only)	t_{CP}	50		60		80		ns	
Page Mode Cycle Time	t_{PC}	120		145		200		ns	

8. The specifications for t_{RC} (min), and t_{RWC} (min) are used only to indicate cycle time at which proper operation over the full temperature range ($0°C \le T_A \le 70°C$) is assured.
9. AC measurements $t_T = 5.0$ ns.
10. Assumes that $t_{RCD} \le t_{RCD}$ (max)
11. Assumes that $t_{RCD} \ge t_{RCD}$ (max)
12. Measured with a current load equivalent to 2 TTL (−200 μA, +4 mA) loads and 100 pF with the data output trip points set at $V_{OH} = 2.0$ V and $V_{OL} = 0.8$ V.
13. Operation within the t_{RCD} (max) limit ensures that t_{RAC} (max) can be met. t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD}(max) limit, then access time is controlled exclusively by t_{CAC}.
14. Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.
15. These parameters are referenced to $\overline{CAS}$ leading edge in random write cycles and to $\overline{WRITE}$ leading edge in delayed write or read-modify-write cycles.
16. t_{WCS}, t_{CWD} and t_{RWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if $t_{WCS} \ge t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{CWD} \ge t_{CWD}$ (min) and $t_{RWD} \ge t_{RWD}$ (min), the cycle is read-write cycle and the data out will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
17. t_{AR} min $\le t_{AR} = t_{RCD} + t_{CAH}$
    t_{DHR} min $\le t_{DHR} = t_{RCD} + t_{DH}$
    t_{WCR} min $\le t_{WCR} = t_{RCD} + t_{WCH}$
18. t_{off} (max) defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.

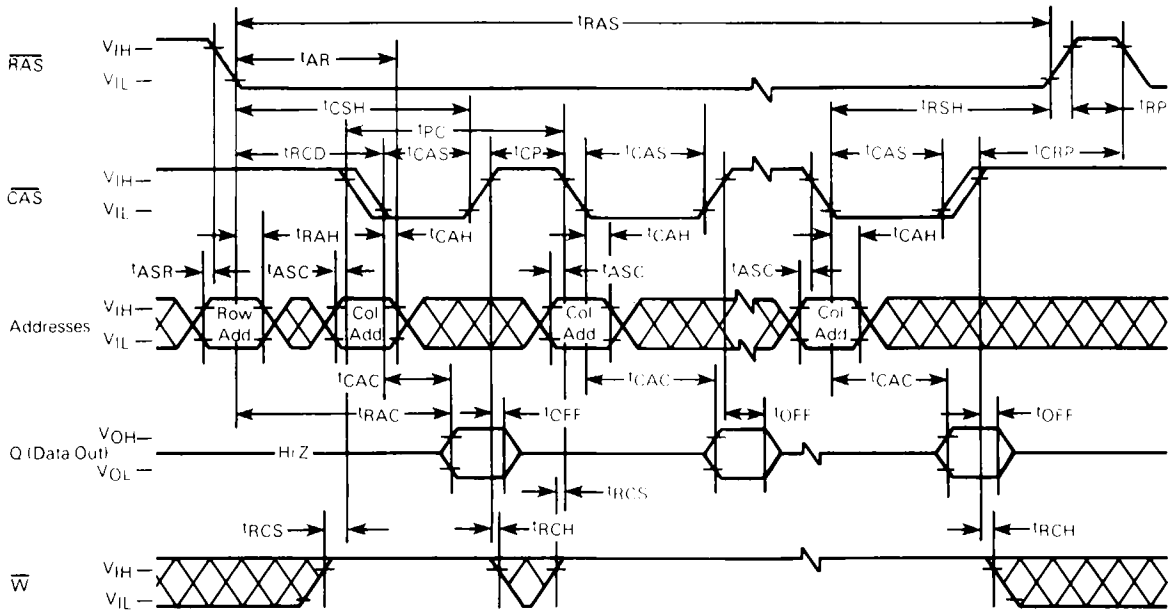
READ CYCLE TIMING



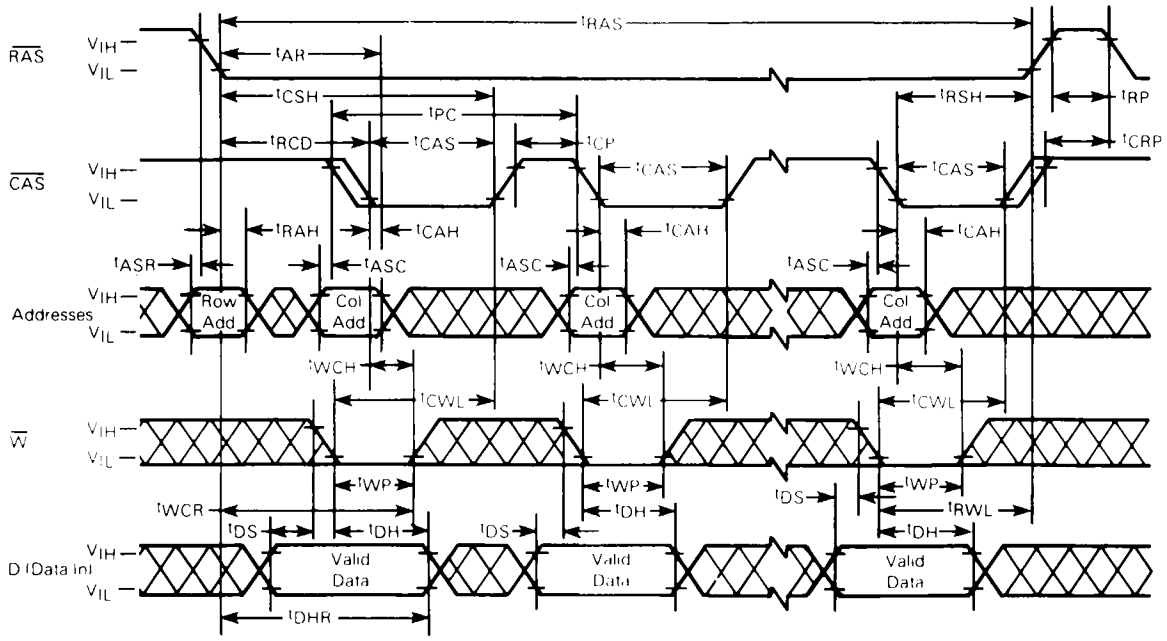
WRITE CYCLE TIMING



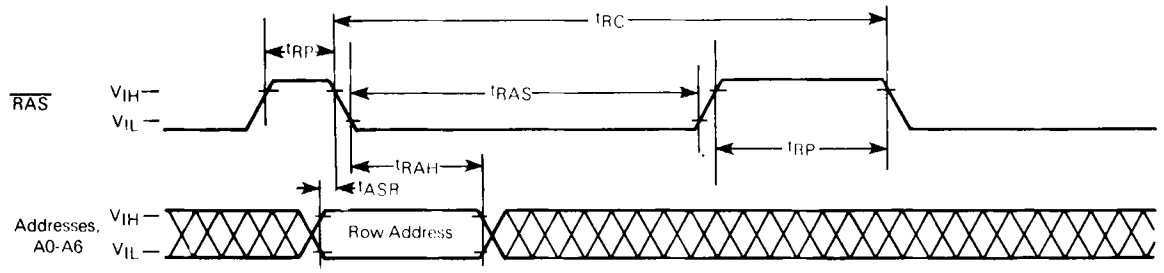
PAGE MODE READ CYCLE



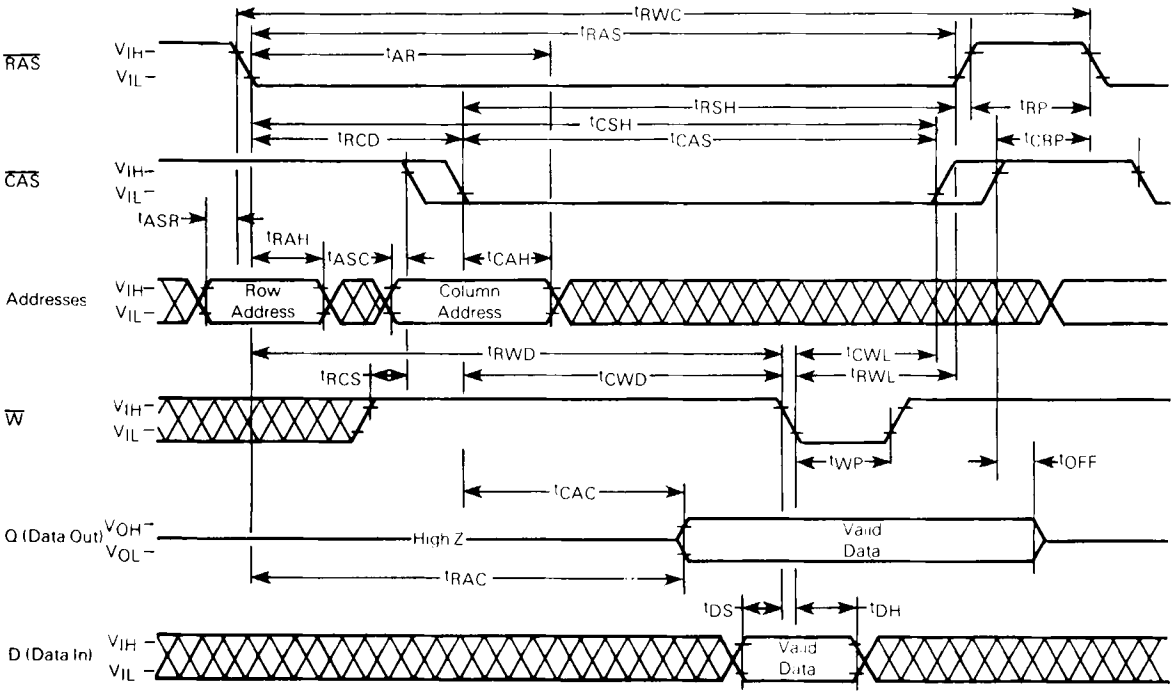
PAGE MODE WRITE CYCLE



RAS-ONLY REFRESH CYCLE
(Data-in and Write are Don't Care, CAS is HIGH)



READ-WRITE/READ-MODIFY-WRITE CYCLE



TYPICAL CHARACTERISTICS

FIGURE 2 – $\overline{RAS}$ ACCESS TIME versus SUPPLY VOLTAGE

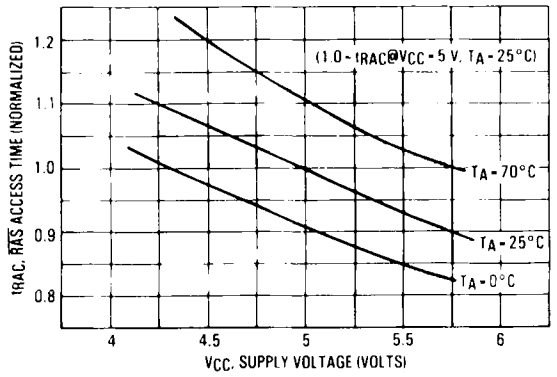


FIGURE 3 – $\overline{CAS}$ ACCESS TIME versus SUPPLY VOLTAGE

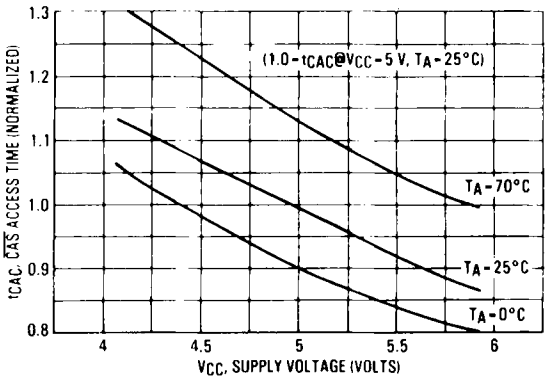


FIGURE 4 – $\overline{RAS}$ ACCESS TIME versus AMBIENT TEMPERATURE

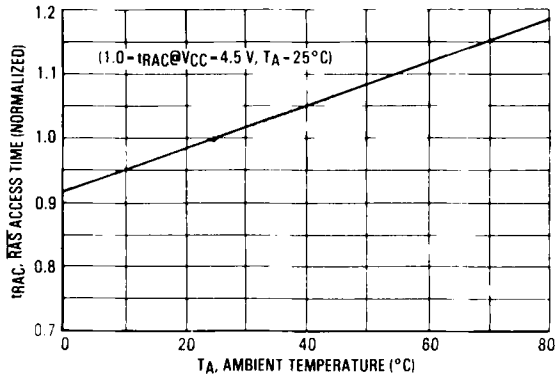


FIGURE 5 – $\overline{CAS}$ ACCESS TIME versus AMBIENT TEMPERATURE

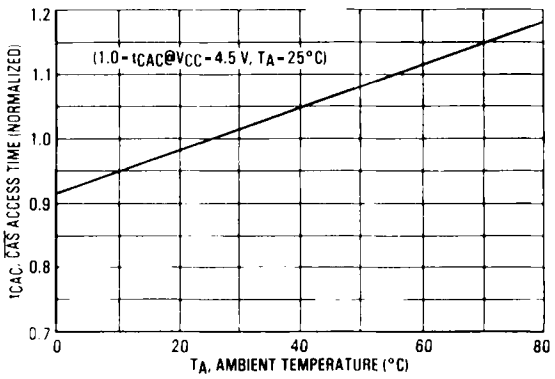


FIGURE 6 – $\overline{RAS}$, $\overline{W}$ INPUT LEVEL versus SUPPLY VOLTAGE

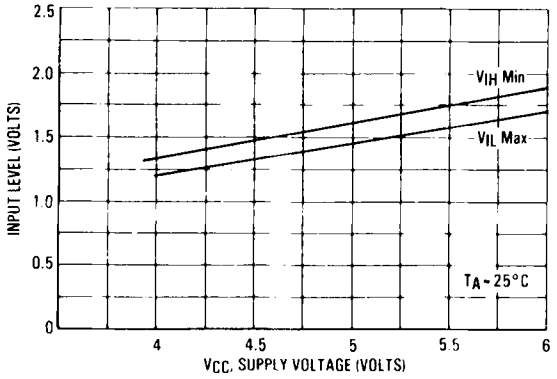
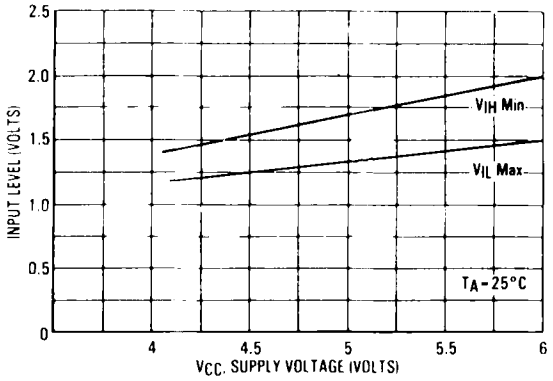


FIGURE 7 – $\overline{CAS}$, $\overline{W}$ INPUT LEVEL versus SUPPLY VOLTAGE



TYPICAL CHARACTERISTICS (continued)

FIGURE 8 – I_{CC1} SUPPLY CURRENT versus CYCLE RATE

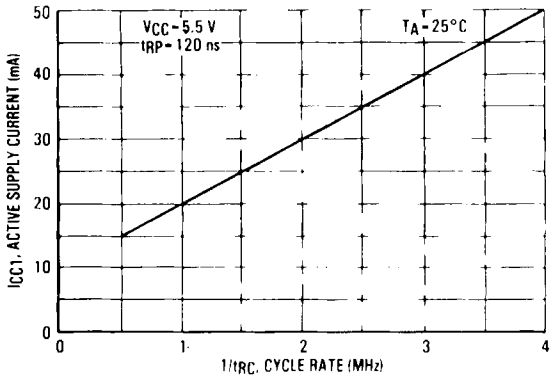


FIGURE 9 – I_{CC1} SUPPLY CURRENT versus SUPPLY VOLTAGE

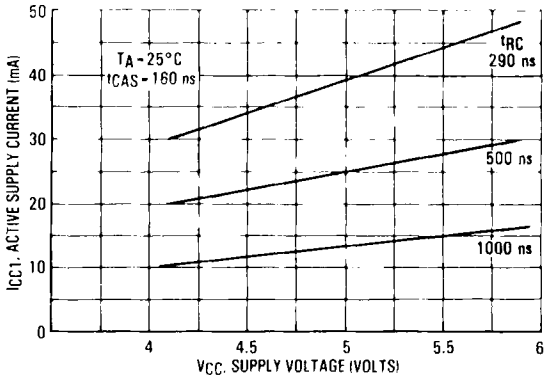


FIGURE 10 – I_{CC1} SUPPLY CURRENT versus SUPPLY VOLTAGE

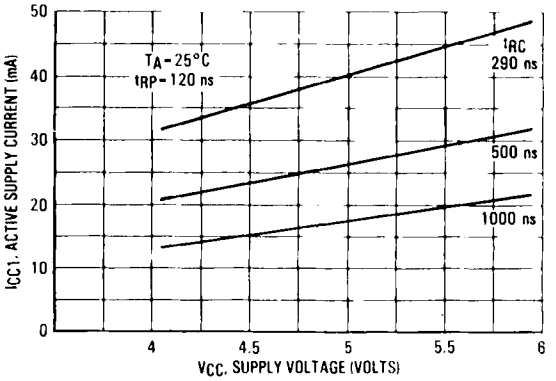


FIGURE 11 – I_{CC1} SUPPLY CURRENT versus AMBIENT TEMPERATURE (min t_{RP})

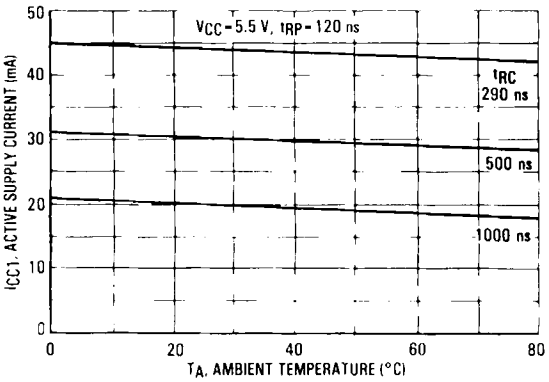


FIGURE 12 – I_{CC1} SUPPLY CURRENT versus AMBIENT TEMPERATURE (min $\overline{RAS}$)

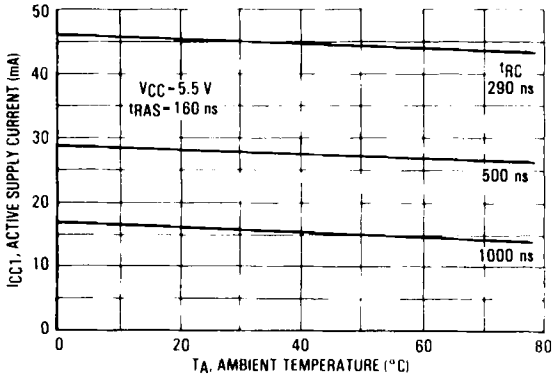
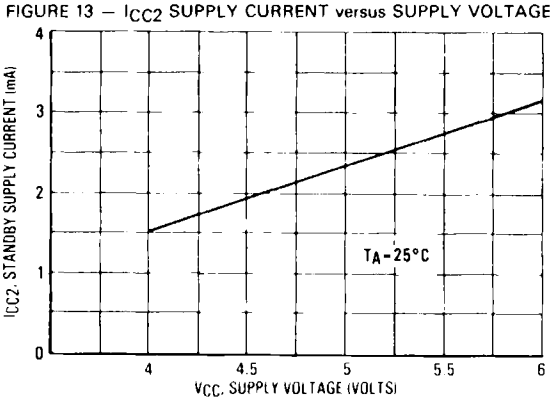


FIGURE 13 – I_{CC2} SUPPLY CURRENT versus SUPPLY VOLTAGE



TYPICAL CHARACTERISTICS (continued)

FIGURE 14 – I_{CC2} STANDBY CURRENT versus AMBIENT TEMPERATURE

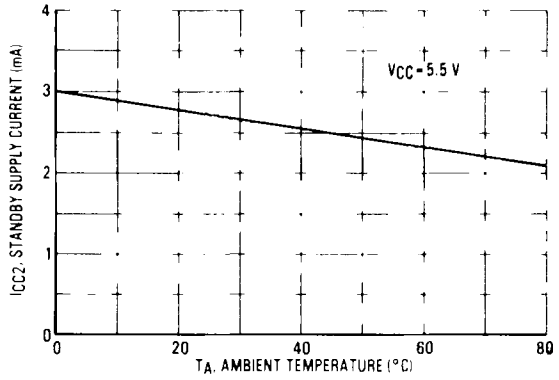


FIGURE 15 – I_{CC3} SUPPLY CURRENT versus CYCLE RATE

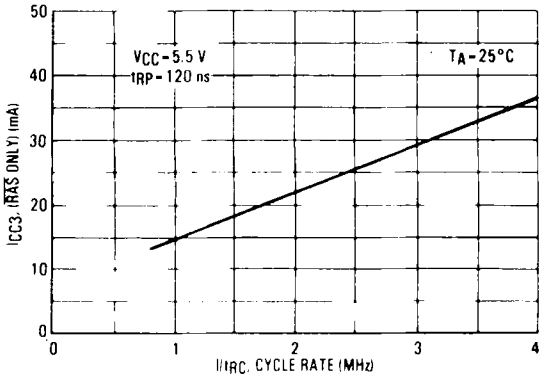


FIGURE 16 – ADDRESS INPUT LEVEL versus SUPPLY VOLTAGE

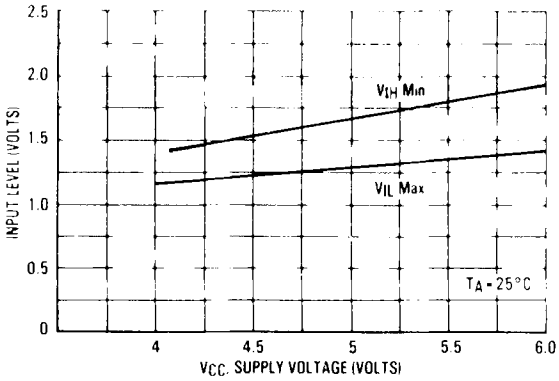
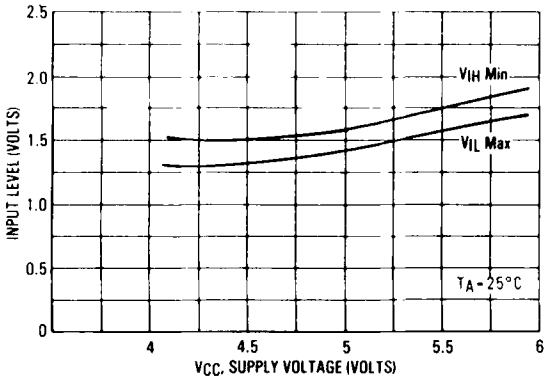


FIGURE 17 – DATA INPUT LEVEL versus SUPPLY VOLTAGE



SOFT ERROR TESTING

The storage cell depletion regions as well as the sense amplifier and its associated bit lines are susceptible to charge collection of electrons from an alpha "hit." However, the susceptibility of these vulnerable regions varies. Depleted storage cells are vulnerable at all times, whereas the sense amplifiers and associated bit lines are susceptible only during the small portion of the memory cycle just prior to sensing. Hence, an increase in the frequency of dynamic RAM access will cause a corresponding increase in the soft error rate.

To take this memory access dependency into account, the total soft error rate profile includes a cycle time component. The soft error rate due to bit line hits at the system's memory cycle rate is added to the soft error rate due to storage cell hits which are not frequency dependent. Figure 18 illustrates the impact that frequency of access has on the MCM6664A/MCM6665A overall soft error rate.

Under normal operating conditions, the die will be exposed to radiation levels of less than 0.01 alpha/cm^2/hr. Accelerated soft error testing data is generated from at least three high-intensity sources having an Alpha Flux Density range of 1×10^5 to 6×10^5 (alpha/cm^{2}hr) placed over uncoated die. Figure 19 shows the soft error rate for a given alpha flux density at a cycle rate of 100 kHz. The accelerated data of Figures 18 and 19 project that the soft error rate for package level radiation will be less than 0.1%/1000 hours.

SYSTEM LIFE OPERATING TEST CONDITIONS

1) Cycle time: 1 microsecond for read, write and refresh cycles
2) Refresh Rate: 1 millisecond
3) Voltage: 5.0 V
4) Temperature: 30° C ±2° C (ambient temperature inside enclosure)
5) Elevation: Approximately 620 feet above mean sea level
6) Data Patterns: Write the entire memory space sequentially with all "1"s and then perform continuous sequential reads for 6 hours. Next, write the entire memory space with all "0"s sequentially and then perform continuous sequential reads for 6 hours. Next, go back to the all "1"s pattern and repeat the sequences all over again.

FIGURE 18 – ACCELERATED SOFT ERROR versus CYCLE TIME

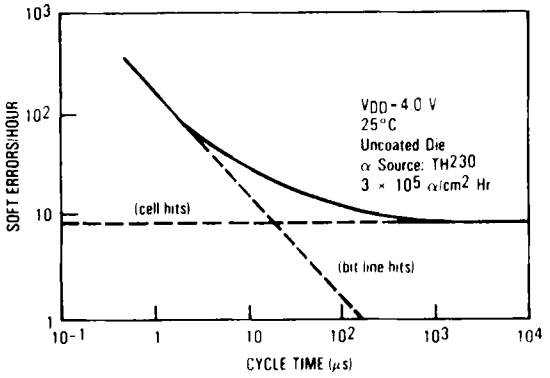
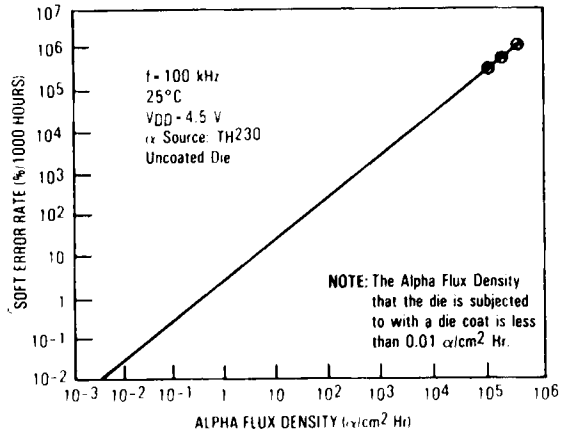


FIGURE 19 – SOFT ERROR RATE versus ALPHA FLUX DENSITY



CURRENT WAVEFORMS

FIGURE 20 – $\overline{RAS}/\overline{CAS}$ CYCLE

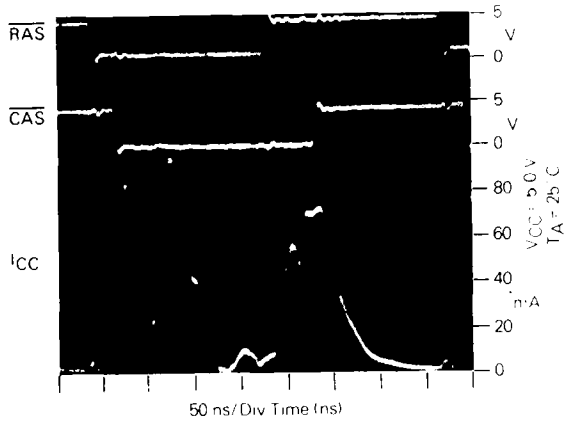


FIGURE 21 – LONG $\overline{RAS}/\overline{CAS}$ CYCLE

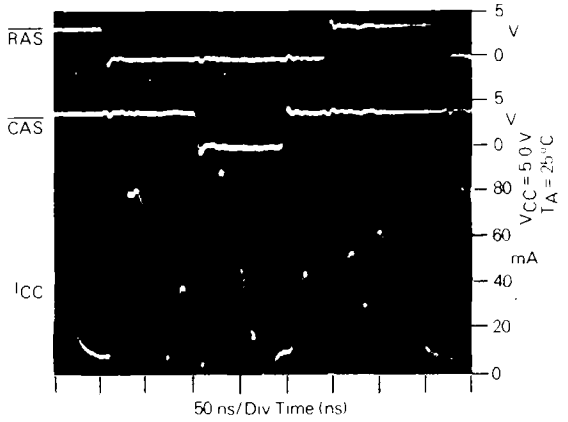


FIGURE 22 – $\overline{RAS}$ ONLY CYCLE

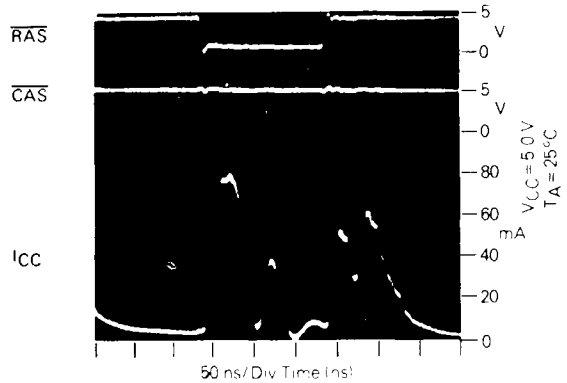


FIGURE 23 – PAGE MODE CYCLE

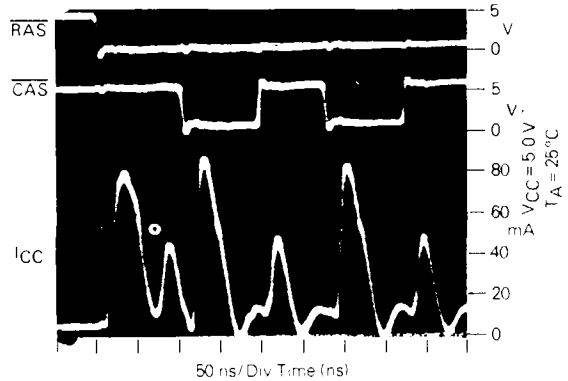
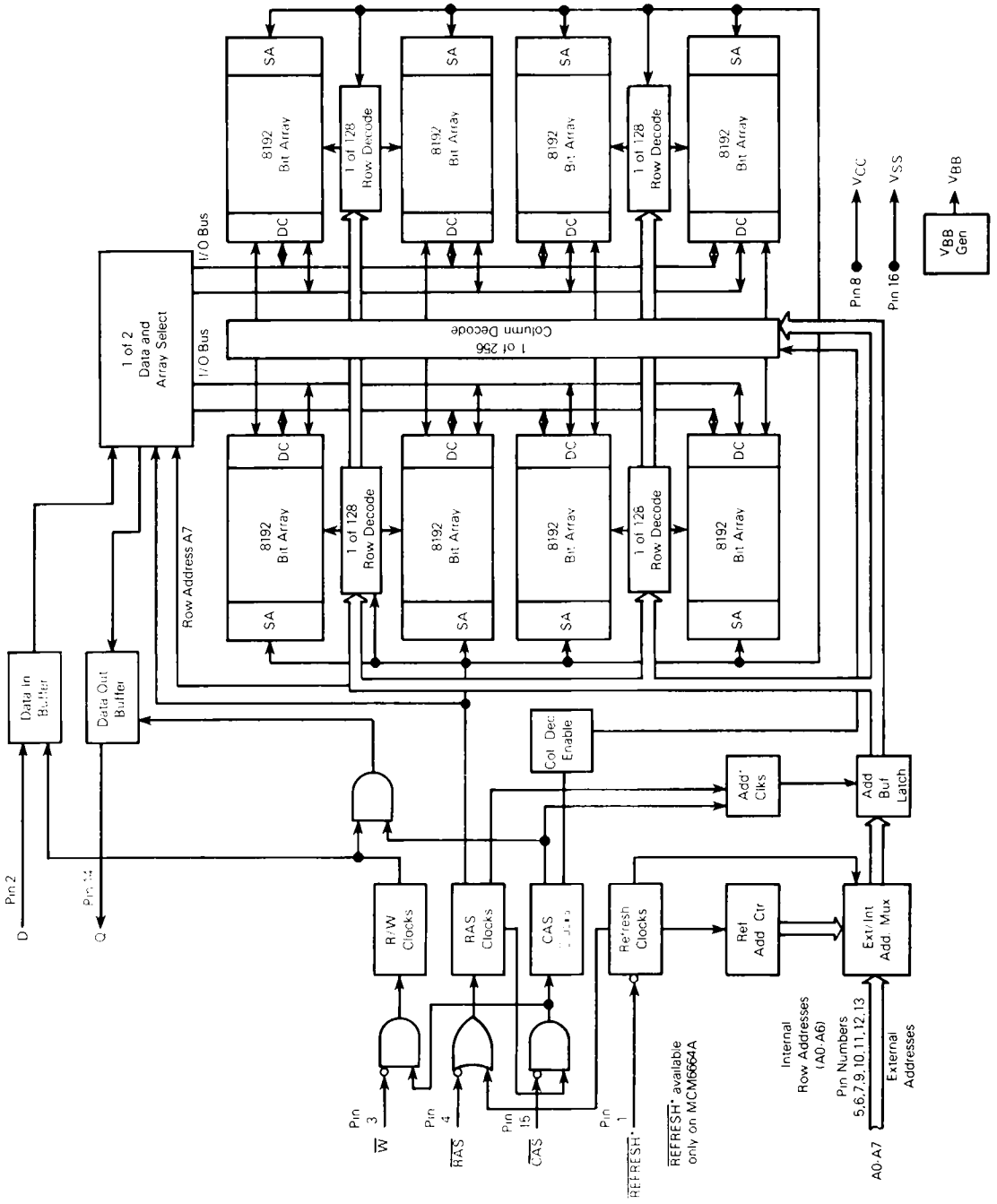


FIGURE 24 — FUNCTIONAL BLOCK DIAGRAM



DEVICE INITIALIZATION

Since the 64K dynamic RAM is a single supply 5 V only device, the need for power supply sequencing is no longer required as was the case in older generation dynamic RAMs. On power-up an initial pause of 100 microseconds is required for the internal substrate generator pump to establish the correct bias voltage. This is to be followed by a minimum of eight active cycles of the row address strobe (clock) to initialize the various dynamic nodes internal to the device. During an extended inactive state of the device (greater than 2 ms with device powered up) the wake up sequence (8 active cycles) will be necessary to assure proper device operation. See Figures 25, 26 for power on characteristics of the RAM for two conditions (clocks active, clocks inactive).

The row address strobe is the primary "clock" that activates the device and maintains the data when the RAM is in the standby mode. This is the main feature that distinguishes it as a dynamic RAM as opposed to a static RAM. A dynamic RAM is placed in a low power standby mode when the device receives a positive-going row address strobe. The variation in the power dissipation of a dynamic RAM from the active to the standby state is an order of magnitude or more for NMOS devices. This feature is used to its fullest advantage with high density mainframe memory systems, where only a very small percentage of the devices are in the active mode at any one time and the rest of the devices are in the standby mode. Thus, large memory systems can be assembled that dissipate very low power per bit compared to a system where all devices are active continuously.

ADDRESSING THE RAM

The eight address pins on the device are time multiplexed with two separate 8-bit address fields that are strobed at the beginning of the memory cycle by two clocks (active negative) called the row address strobe and the column address strobe. A total of sixteen address bits will decode one of the 65,536 cell locations in the device. The column address strobe follows the row address strobe by a specified minimum and maximum time called "t_{RCD}," which is the row to column strobe delay. This time interval is also referred to as the multiplex window which gives flexibility to a system designer to set up his external addresses into the RAM. These conditions have to be met for normal read or write cycles. This initial portion of the cycle accomplishes the normal addressing of the device. There are, however, two other variations in addressing the 64K RAM: one is called the page mode cycle (described later) where an 8-bit column address field is presented on the input pins and latched by the $\overline{CAS}$ clock, and the other is the $\overline{RAS}$ only refresh cycle (described later) where a 7-bit row address field is presented on the input pins and latched by the $\overline{RAS}$ clock. In the latter case, the most significant bit on Row Address A7 (pin 9) is not required for refresh. See bit address map for the topology of the cells and their address selection.

NORMAL READ CYCLE

A read cycle is referred to as normal read cycle to differentiate it from a page-mode-read cycle, a read-while-write cycle, and read-modify-write cycle which are covered in a later section.

The memory read cycle begins with the row addresses valid and the $\overline{RAS}$ clock transitioning from V_{IH} to the V_{IL} level. The $\overline{CAS}$ clock must also make a transition from V_{IH} to the V_{IL} level at the specified t_{RCD} timing limits when the column addresses are latched. Both the $\overline{RAS}$ and $\overline{CAS}$ clocks trigger a sequence of events which are controlled by several delayed internal clocks. Also, these clocks are linked in such a manner that the access time of the device is independent of the address multiplex window. The only stipulation is that the $\overline{CAS}$ clock must be active before or at

CURRENT WAVEFORMS

FIGURE 25 — SUPPLY CURRENT versus SUPPLY VOLTAGE DURING POWER UP, $\overline{RAS}$, $\overline{CAS}$ = V_{CC}

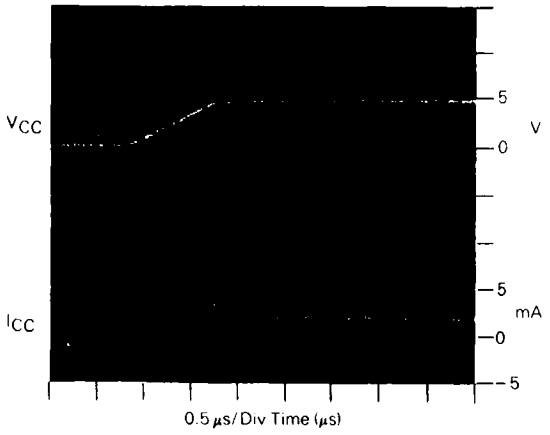
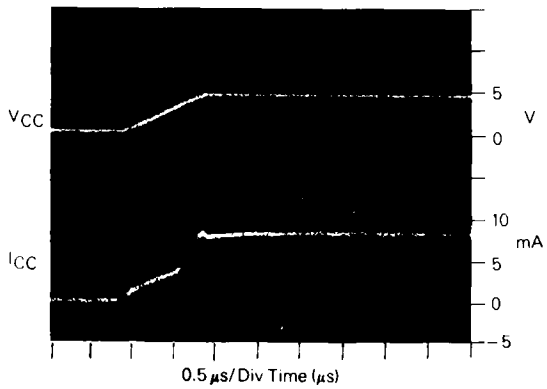


FIGURE 26 — SUPPLY CURRENT versus SUPPLY VOLTAGE DURING POWER UP, $\overline{RAS}$, $\overline{CAS}$ = V_{SS}



the t_{RCD} maximum specification for an access (data valid) from the $\overline{RAS}$ clock edge to be guaranteed (t_{RAC}). If the t_{RCD} maximum condition is not met, the access (t_{CAC}) from the $\overline{CAS}$ clock active transition will determine read access time. The external $\overline{CAS}$ signal is ignored until an internal $\overline{RAS}$ signal is available, as noted in the functional block diagram, Figure 24. This gating feature on the $\overline{CAS}$ clock will allow the external $\overline{CAS}$ signal to become active as soon as the row address hold time (t_{RAH}) specification has been met and defines the t_{RCD} minimum specification. The time difference between t_{RCD} minimum and t_{RCD} maximum can be used to absorb skew delays in switching the address bus from row to column addresses and in generating the $\overline{CAS}$ clock.

Once the clocks have become active, they must stay active for the minimum (t_{RAS}) period for the $\overline{RAS}$ clock and the minimum (t_{CAS}) period for the $\overline{CAS}$ clock. The $\overline{RAS}$ clock must stay inactive for the minimum (t_{RP}) time. The former is for the completion of the cycle in progress, and the latter is for the device internal circuitry to be precharged for the next active cycle.

Data out is not latched and is valid as long as the $\overline{CAS}$ clock is active; the output will switch to the three-state mode when the $\overline{CAS}$ clock goes inactive. The $\overline{CAS}$ clock can remain active for a maximum of 10 ns (t_{CRP}) into the next cycle. To perform a read cycle, the write ($\overline{W}$) input must be held at the V_{IH} level from the time the $\overline{CAS}$ clock makes its active transition (t_{RCS}) to the time when it transitions into the inactive (t_{RCH}) mode.

WRITE CYCLE

A write cycle is similar to a read cycle except that the Write ($\overline{W}$) clock must go active (V_{IL} level) at or before the $\overline{CAS}$ clock goes active at a minimum t_{WCS} time. If the above condition is met, then the cycle in progress is referred to as a early write cycle. In an early write cycle, the write clock and the data in is referenced to the active transition of the $\overline{CAS}$ clock edge. There are two important parameters with respect to the write cycle: the column strobe to write lead time (t_{CWL}) and the row strobe to write lead time (t_{RWL}). These define the minimum time that $\overline{RAS}$ and $\overline{CAS}$ clocks need to be active after the write operation has started ($\overline{W}$ clock at V_{IL} level).

It is also possible to perform a late write cycle. For this cycle the write clock is activated after the $\overline{CAS}$ goes low which is beyond t_{WCS} minimum time. Thus the parameters t_{CWL} and t_{RWL} must be satisifed before terminating this cycle. The difference between an early write cycle and a late write cycle is that in a late write cycle the write ($\overline{W}$) clock can occur much later in time with respect to the active transition of the $\overline{CAS}$ clock. This time could be as long as 10 microseconds $- [t_{RWL} + t_{RP} + 2T_t]$.

At the start of a write cycle, the data out is in a three-state condition and remains inactive throughout the cycle. The data out remains three-state because the active transition of the write ($\overline{W}$) clock prevents the $\overline{CAS}$ clock from enabling the data out buffers as noted in Functional Block Diagram. The three-state condition (high impedance) of the Data Out Pin during a write cycle can be effectively utilized in a system that has a common input/output bus. The only stipulation is that the system use only early write mode operations for all write cycles to avoid bus contention.

READ-MODIFY-WRITE AND READ-WHILE-WRITE CYLES

As the name implies, both a read and a write cycle is accomplished at a selected bit during a single access. The read-modify write cycle is similar to the late write cycle discussed above.

For the read-modify-write cycle a normal read cycle is initiated with the write ($\overline{W}$) clock at the V_{IH} level until the read data occurs at the device access time (t_{RAC}). At this time the write ($\overline{W}$) clock is asserted. The data in is setup and held with respect to the active edge of the write clock. The cycle described assumes a zero modify time between read and write.

Another variation of the read-modify-write cycle is the read-while-write cycle. For this cycle, the following parameters (t_{RWD}, t_{CWD}) play an important role. A read-while write cycle starts as a normal read cycle with the write ($\overline{W}$) clock being asserted at minimum t_{RWD} or minimum t_{CWD} time, depending upon the application. This results in starting a write operation to the selected cell even before data out occurs. The minimum specification on t_{RWD} and t_{CWD} assures that data out does occur. In this case, the data in is set up with respect to write ($\overline{W}$) clock active edge.

PAGE-MODE CYCLES

Page mode operation allows faster successive data operations at the 256 column locations. Page access (t_{CAC}) is typically half the regular $\overline{RAS}$ clock access (t_{RAC}) on the Motorola 64K dynamic RAM. Page mode operation consists of holding the $\overline{RAS}$ clock active while cycling the $\overline{CAS}$ clock to access the column locations determined by the 8-bit column address field. There are two controlling factors that limit the access to all 256 column locations in one $\overline{RAS}$ clock active operation. These are the refresh interval of the device (2 ms/128 = 15.6 microseconds) and the maximum active time specification for the $\overline{RAS}$ clock (10 microseconds). Since 10 microseconds is the smaller value, the maximum specification of the $\overline{RAS}$ clock on time is the limiting factor of the number of sequential page accesses possible. Ten microseconds will provide approximately (10 microseconds/page mode cycle time) 50 successive page accesses for every row address selected before the $\overline{RAS}$ clock is reset.

The page cycle is always initiated with a row address being provided and latched by the $\overline{RAS}$ clock, followed by the column address and $\overline{CAS}$ clock. From the timing illustrated, the initial cycle is a normal read or write cycle, that has been previously described, followed by the shorter $\overline{CAS}$ cycles (t_{PC}). The $\overline{CAS}$ cycle time (t_{PC}) consists of the $\overline{CAS}$ clock active time (t_{CAS}), and $\overline{CAS}$ clock precharge time (t_{CP}) and two transitions. In addition to read and write cycles, a read-modify-write cycle can also be performed in a page mode operation. For a read-modify write or read while-write type cycle, the conditions normal to that mode of operation will apply in the page mode also. The page mode cycles illustrated show a series of sequential reads separated by a series of sequential writes. This is just one mode of operation. In practice, any combination of read, write and read-modify-write cycles can be performed to suit a particular application.

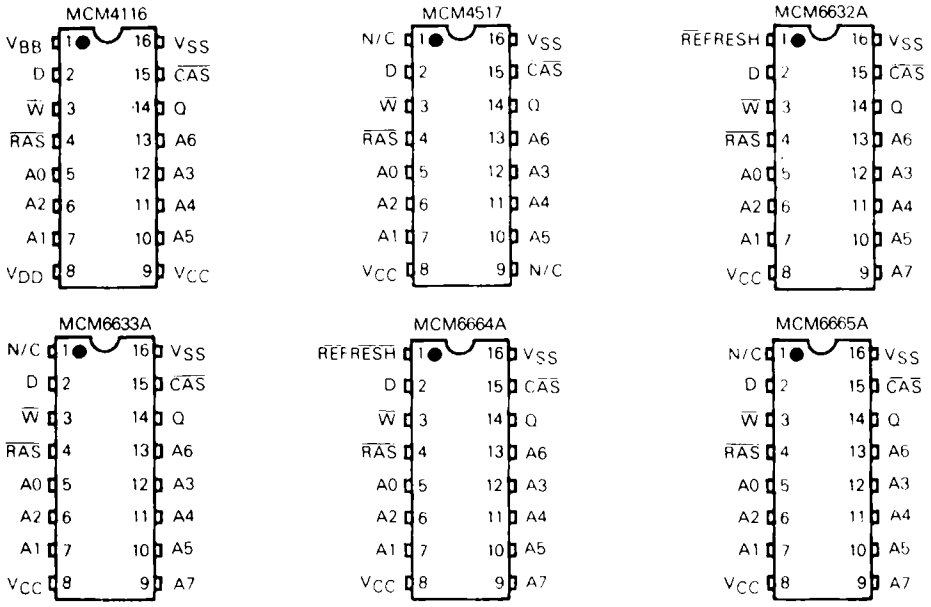
REFRESH CYCLES

The dynamic RAM design is based on capacitor charge storage for each bit in the array. This charge will tend to

degrade with time and temperature. Therefore, to retain the correct information, the bits need to be refreshed at least once every 2 ms. This is accomplished by sequentially cycling through the 128 row address locations every 2 ms, or at least one row every 15.6 microseconds. A normal read or write operation to the RAM will serve to refresh all the bits (256) associated with that particular row decoded.

$\overline{RAS}$ Only Refresh – When the memory component is in standby the $\overline{RAS}$ only refresh scheme is employed. This refresh method performs a $\overline{RAS}$ only cycle on all 128 row addresses every 2 ms. The row addresses are latched in with the $\overline{RAS}$ clock, and the associated internal row locations are refreshed. As the heading implies, the $\overline{CAS}$ clock is not required and should be inactive or at a V_{IH} level to conserve power.

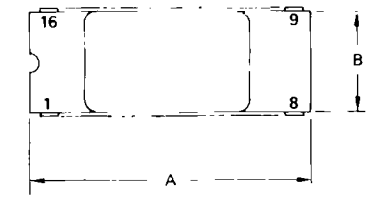
PIN ASSIGNMENT COMPARISON



PIN VARIATIONS

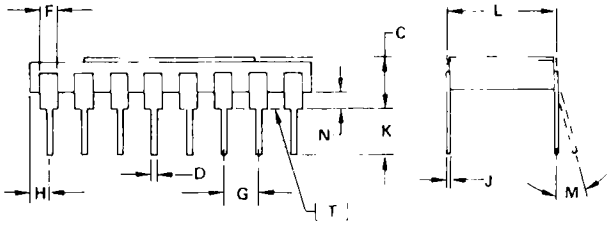
PIN NUMBER	MCM4116	MCM4517	MCM6632A	MCM6663A	MCM6664A	MCM6665A
1	V_{BB} (−5 V)	N/C	REFRESH	N/C	REFRESH	N/C
8	V_{DD} (+12 V)	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
9	V_{CC} (+5 V)	N/C	A7	A7	A7	A7

PACKAGE DIMENSIONS

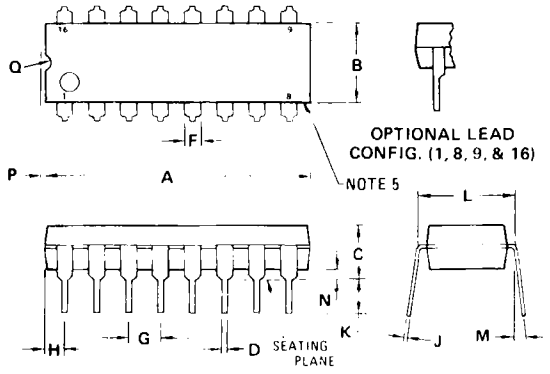


L SUFFIX
CERAMIC PACKAGE
CASE 690-13

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	20.07	20.57	0.790	0.810
B	7.11	7.62	0.280	0.300
C	2.67	4.19	0.105	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.52	0.030	0.060
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.30	0.008	0.012
K	3.18	5.08	0.125	0.200
L	7.62 BSC		0.300 BSC	
M	--	10°	--	10°
N	0.38	1.52	0.015	0.060



NOTES:
1. -A- AND -B- ARE DATUMS.
2. -T- IS SEATING PLANE
3. POSITIONAL TOLERANCE FOR LEADS (D).
   ⌖ | Ø 0.25 (0.010) Ⓜ | T | A Ⓜ | B Ⓜ
4. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.

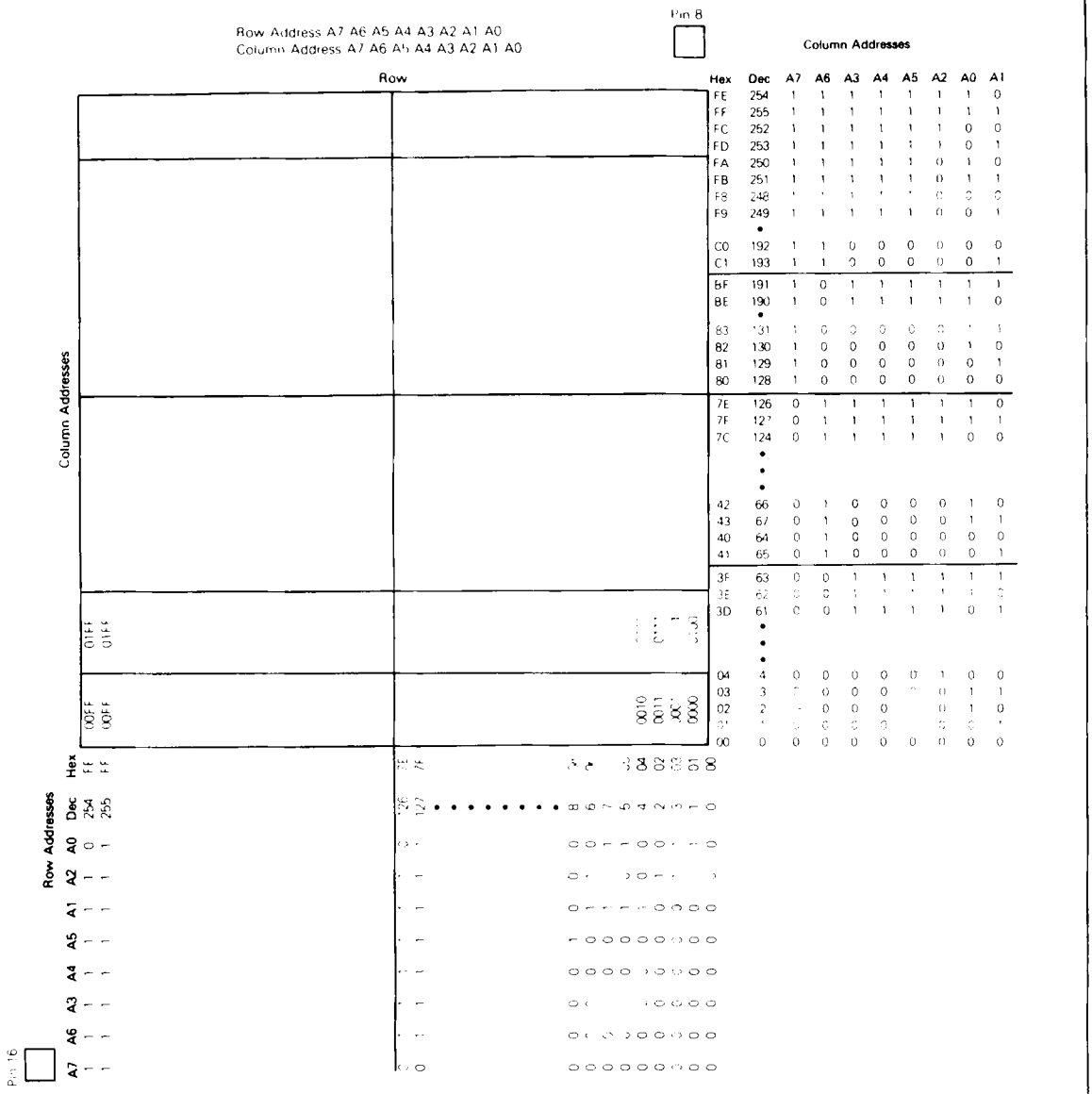


P SUFFIX
PLASTIC PACKAGE
CASE 648-05

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	18.80	21.34	0.740	0.840
B	6.10	6.60	0.240	0.260
C	4.06	5.08	0.160	0.200
D	0.38	0.53	0.015	0.021
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.38	2.41	0.015	0.095
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	10°	0°	10°
N	0.51	1.02	0.020	0.040

NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
4. "F" DIMENSION IS FOR FULL LEADS. "HALF" LEADS ARE OPTIONAL AT LEAD POSITIONS 1, 8, 9, and 16).
5. ROUNDED CORNERS OPTIONAL.

MCM6665A BIT ADDRESS MAP



Data Stored = $D_{in} \oplus A_{0X} \oplus A_{1Y}$

Column Address A1	Row Address A0	Data Stored
0	0	True
0	1	Inverted
1	0	Inverted
1	1	True

intel®

8085A/8085A-2
SINGLE CHIP 8-BIT N-CHANNEL MICROPROCESSORS

- **Single +5V Power Supply**
- **100% Software Compatible with 8080A**
- **1.3 μs Instruction Cycle (8085A); 0.8 μs (8085A-2)**
- **On-Chip Clock Generator (with External Crystal, LC or RC Network)**
- **On-Chip System Controller; Advanced Cycle Status Information Available for Large System Control**
- **Four Vectored Interrupt Inputs (One is non-Maskable) Plus an 8080A-compatible interrupt**
- **Serial In/Serial Out Port**
- **Decimal, Binary and Double Precision Arithmetic**
- **Direct Addressing Capability to 64k Bytes of Memory**

The Intel® 8085A is a complete 8 bit parallel Central Processing Unit (CPU). Its instruction set is 100% software compatible with the 8080A microprocessor, and it is designed to improve the present 8080A's performance by higher system speed. Its high level of system integration allows a minimum system of three IC's [8085A (CPU), 8156 (RAM/IO) and 8355/8755A (ROM/PROM/IO)] while maintaining total system expandability. The 8085A-2 is a faster version of the 8085A.

The 8085A incorporates all of the features that the 8224 (clock generator) and 8228 (system controller) provided for the 8080A, thereby offering a high level of system integration.

The 8085A uses a multiplexed data bus. The address is split between the 8 bit address bus and the 8 bit data bus. The on-chip address latches of 8155/8156/8355/8755A memory products allow a direct interface with the 8085A.

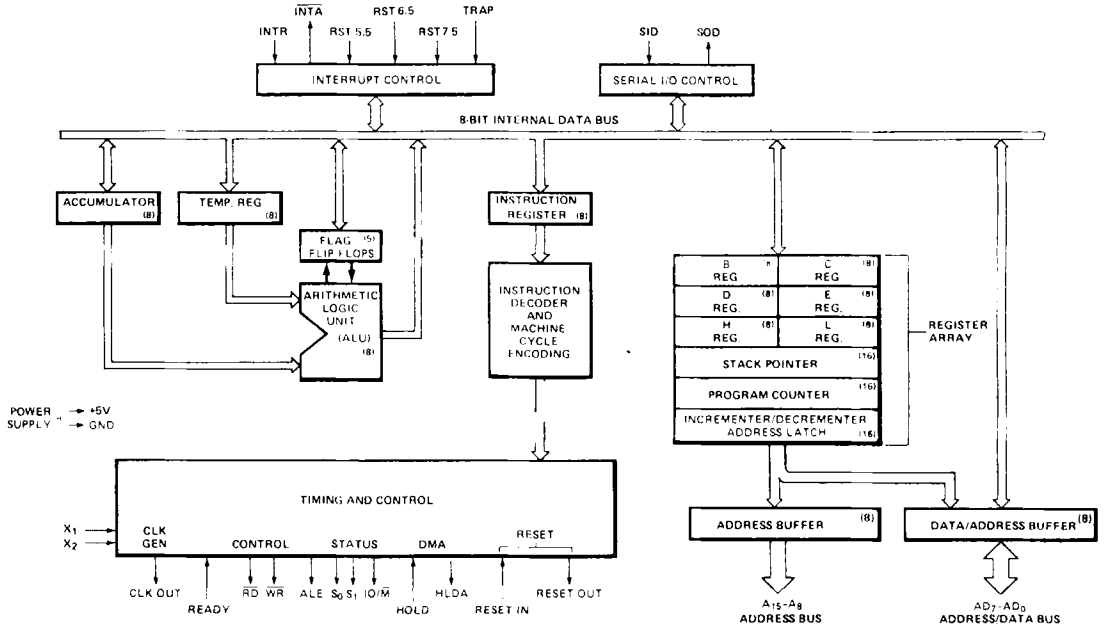


Figure 1. 8085A CPU Functional Block Diagram

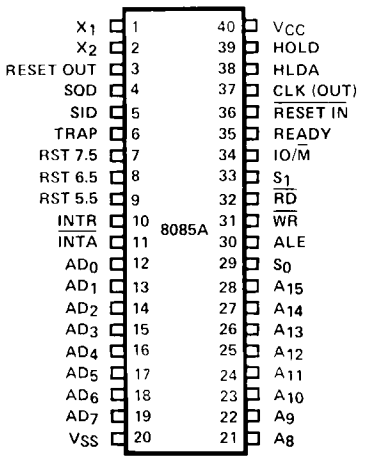


Figure 2. 8085A Pinout Diagram

8085A FUNCTIONAL PIN DEFINITION

The following describes the function of each pin:

Symbol	Function
A_8–A_{15} (Output, 3-state)	Address Bus: The most significant 8 bits of the memory address or the 8 bits of the I/O address, 3-stated during Hold and Halt modes and during RESET.
AD_{0-7} (Input/Output, 3-state)	Multiplexed Address/Data Bus: Lower 8 bits of the memory address (or I/O address) appear on the bus during the first clock cycle (T state) of a machine cycle. It then becomes the data bus during the second and third clock cycles.
ALE (Output)	Address Latch Enable: It occurs during the first clock state of a machine cycle and enables the address to get latched into the on-chip latch of peripherals. The falling edge of ALE is set to guarantee setup and hold times for the address information. The falling edge of ALE can also be used to strobe the status information. ALE is never 3-stated.
S_0, S_1, and IO/$\overline{M}$ (Output)	Machine cycle status:

IO/$\overline{M}$	S_1	S_0	Status
0	0	1	Memory write
0	1	0	Memory read
1	0	1	I/O write
1	1	0	I/O read
0	1	1	Opcode fetch
1	1	1	Interrupt Acknowledge
*	0	0	Halt
*	X	X	Hold
*	X	X	Reset

* = 3-state (high impedance)
X = unspecified

Symbol	Function
	S_1 can be used as an advanced R/$\overline{W}$ status. IO/$\overline{M}$,S_0 and S_1 become valid at the beginning of a machine cycle and remain stable throughout the cycle. The falling edge of ALE may be used to latch the state of these lines.
$\overline{RD}$ (Output, 3-state)	READ control: A low level on $\overline{RD}$ indicates the selected memory or I/O device is to be read and that the Data Bus is available for the data transfer, 3-stated during Hold and Halt modes and during RESET.
$\overline{WR}$ (Output, 3-state)	WRITE control: A low level on $\overline{WR}$ indicates the data on the Data Bus is to be written into the selected memory or I/O location. Data is set up at the trailing edge of $\overline{WR}$. 3-stated during Hold and Halt modes and during RESET.
READY (Input)	If READY is high during a read or write cycle, it indicates that the memory or peripheral is ready to send or receive data. If READY is low, the cpu will wait an integral number of clock cycles for READY to go high before completing the read or write cycle.
HOLD (Input)	HOLD indicates that another master is requesting the use of the address and data buses. The cpu, upon receiving the hold request, will relinquish the use of the bus as soon as the completion of the current bus transfer. Internal processing can continue. The processor can regain the bus only after the HOLD is removed. When the HOLD is acknowledged, the Address, Data, $\overline{RD}$, $\overline{WR}$, and IO/$\overline{M}$ lines are 3-stated.
HLDA (Output)	HOLD ACKNOWLEDGE: Indicates that the cpu has received the HOLD request and that it will relinquish the bus in the next clock cycle. HLDA goes low after the Hold request is removed. The cpu takes the bus one half clock cycle after HLDA goes low.
INTR (Input)	INTERRUPT REQUEST: is used as a general purpose interrupt. It is sampled only during the next to the last clock cycle of an instruction and during Hold and Halt states. If it is active, the Program Counter (PC) will be inhibited from incrementing and an $\overline{INTA}$ will be issued. During this cycle a RESTART or CALL instruction can be inserted to jump to the interrupt service routine. The INTR is enabled and disabled by software. It is disabled by Reset and immediately after an interrupt is accepted.

8085A FUNCTIONAL PIN DESCRIPTION (Continued)

Symbol	Function
$\overline{\text{INTA}}$ (Output)	INTERRUPT ACKNOWLEDGE: Is used instead of (and has the same timing as) $\overline{\text{RD}}$ during the Instruction cycle after an INTR is accepted. It can be used to activate the 8259 Interrupt chip or some other interrupt port.
RST 5.5 RST 6.5 RST 7.5 (Inputs)	RESTART INTERRUPTS: These three inputs have the same timing as INTR except they cause an internal RESTART to be automatically inserted. The priority of these interrupts is ordered as shown in Table 1. These interrupts have a higher priority than INTR. In addition, they may be individually masked out using the SIM instruction.
TRAP (Input)	Trap interrupt is a nonmaskable RESTART interrupt. It is recognized at the same time as INTR or RST 5.5-7.5. It is unaffected by any mask or Interrupt Enable. It has the highest priority of any interrupt. (See Table 1.)
$\overline{\text{RESET IN}}$ (Input)	Sets the Program Counter to zero and resets the Interrupt Enable and HLDA flip-flops. The data and address buses and the control lines are 3-stated during RESET and because of the asynchronous nature of RESET, the processor's internal registers and flags may be altered by RESET with unpredictable results. $\overline{\text{RESET IN}}$ is a Schmitt-triggered input, allowing connection to an R-C network for power-on RESET delay. The cpu is held in the reset condition as long as $\overline{\text{RESET IN}}$ is applied.
RESET OUT (Output)	Indicates cpu is being reset. Can be used as a system reset. The signal is synchronized to the processor clock and lasts an integral number of clock periods.
X_1, X_2 (Input)	X_1 and X_2 are connected to a crystal, LC, or RC network to drive the internal clock generator. X_1 can also be an external clock input from a logic gate. The input frequency is divided by 2 to give the processor's internal operating frequency.
CLK (Output)	Clock Output for use as a system clock. The period of CLK is twice the X_1, X_2 input period.
SID (Input)	Serial input data line. The data on this line is loaded into accumulator bit 7 whenever a RIM instruction is executed.
SOD (Output)	Serial output data line. The output SOD is set or reset as specified by the SIM instruction.
V_{CC}	+5 volt supply.
V_{SS}	Ground Reference.

TABLE 1. INTERRUPT PRIORITY, RESTART ADDRESS, AND SENSITIVITY

Name	Priority	Address Branched To (1) When Interrupt Occurs	Type Trigger
TRAP	1	24H	Rising edge AND high level until sampled.
RST 7.5	2	3CH	Rising edge (latched).
RST 6.5	3	34H	High level until sampled.
RST 5.5	4	2CH	High level until sampled.
INTR	5	See Note (2).	High level until sampled.

NOTES:

(1) The processor pushes the PC on the stack before branching to the indicated address.
(2) The address branched to depends on the instruction provided to the cpu when the interrupt is acknowledged.

FUNCTIONAL DESCRIPTION

The 8085A is a complete 8-bit parallel central processor. It is designed with N-channel depletion loads and requires a single +5 volt supply. Its basic clock speed is 3 MHz (8085A) or 5 MHz (8085A-2), thus improving on the present 8080A's performance with higher system speed. Also it is designed to fit into a minimum system of three IC's: The cpu (8085A), a RAM/IO (8156), and a ROM or EPROM/IO chip (8355 or 8755A).

The 8085A has twelve addressable 8-bit registers. Four of them can function only as two 16-bit register pairs. Six others can be used interchangeably as 8-bit registers or as 16-bit register pairs. The 8085A register set is as follows:

Mnemonic	Register	Contents
ACC or A	Accumulator	8 bits
PC	Program Counter	16-bit address
BC,DE,HL	General-Purpose Registers; data pointer (HL)	8 bits x 6 or 16 bits x 3
SP	Stack Pointer	16-bit address
Flags or F	Flag Register	5 flags (8-bit space)

The 8085A uses a multiplexed Data Bus. The address is split between the higher 8-bit Address Bus and the lower 8-bit Address/Data Bus. During the first T state (clock cycle) of a machine cycle the low order address is sent out on the Address/Data bus. These lower 8 bits may be latched externally by the Address Latch Enable signal (ALE). During the rest of the machine cycle the data bus is used for memory or I/O data.

The 8085A provides $\overline{RD}$, $\overline{WR}$, S_0, S_1, and IO/$\overline{M}$ signals for bus control. An Interrupt Acknowledge signal ($\overline{INTA}$) is also provided. HOLD and all Interrupts are synchronized with the processor's internal clock. The 8085A also provides Serial Input Data (SID) and Serial Output Data (SOD) lines for simple serial interface.

In addition to these features, the 8085A has three maskable, vector interrupt pins and one nonmaskable TRAP interrupt.

INTERRUPT AND SERIAL I/O

The 8085A has 5 interrupt inputs: INTR, RST 5.5, RST 6.5, RST 7.5, and TRAP. INTR is identical in function to the 8080A INT. Each of the three RESTART inputs, 5.5, 6.5, and 7.5, has a programmable mask. TRAP is also a RESTART interrupt but it is nonmaskable.

The three maskable interrupts cause the internal execution of RESTART (saving the program counter in the stack and branching to the RESTART address) if the interrupts are enabled and if the interrupt mask is not set. The nonmaskable TRAP causes the internal execution of a RESTART vector independent of the state of the interrupt enable or masks. (See Table 1.)

There are two different types of inputs in the restart interrupts. RST 5.5 and RST 6.5 are *high level-sensitive* like INTR (and INT on the 8080) and are recognized with the same timing as INTR. RST 7.5 is *rising edge-sensitive*.

For RST 7.5, only a pulse is required to set an internal flip-flop which generates the internal interrupt request. (See Section 5.2.7.) The RST 7.5 request flip-flop remains set until the request is serviced. Then it is reset automatically. This flip-flop may also be reset by using the SIM instruction or by issuing a $\overline{RESET\ IN}$ to the 8085A. The RST 7.5 internal flip-flop will be set by a pulse on the RST 7.5 pin even when the RST 7.5 interrupt is masked out.

The status of the three RST interrupt masks can only be affected by the SIM instruction and $\overline{RESET\ IN}$. (See SIM, Chapter 5.

The interrupts are arranged in a fixed priority that determines which interrupt is to be recognized if more than one is pending as follows: TRAP — highest priority, RST 7.5, RST 6.5, RST 5.5, INTR — lowest priority. This priority scheme does not take into account the priority of a routine that was started by a higher priority interrupt. RST 5.5 can interrupt an RST 7.5 routine if the interrupts are re-enabled before the end of the RST 7.5 routine.

The TRAP interrupt is useful for catastrophic events such as power failure or bus error. The TRAP input is recognized just as any other interrupt but has the highest priority. It is not affected by any flag or mask. The TRAP input is both *edge and level sensitive*. The TRAP input must go high and remain high until it is acknowledged. It will not be recognized again until it goes low, then high again. This avoids any false triggering due to noise or logic glitches. Figure 3 illustrates the TRAP interrupt request circuitry within the 8085A. Note that the servicing of any interrupt (TRAP, RST 7.5, RST 6.5, RST 5.5, INTR) disables all future interrupts (except TRAPs) until an EI instruction is executed.

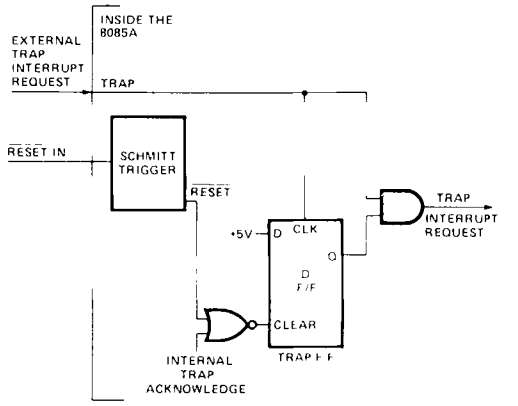


Figure 3. TRAP and $\overline{RESET\ IN}$ Circuit

The TRAP interrupt is special in that it disables interrupts, but preserves the previous interrupt enable status. Performing the first RIM instruction following a TRAP interrupt allows you to determine whether interrupts were enabled or disabled prior to the TRAP. All subsequent RIM instructions provide current interrupt enable status. Performing a RIM instruction following INTR, or RST 5.5-7.5 will provide current Interrupt Enable status, revealing that Interrupts are disabled. See the description of the RIM instruction in Chapter 5.

The serial I/O system is also controlled by the RIM and SIM instructions. SID is read by RIM, and SIM sets the SOD data.

DRIVING THE X_1 AND X_2 INPUTS

You may drive the clock inputs of the 8085A or 8085A-2 with a crystal, an LC tuned circuit, an RC network, or an external clock source. The driving frequency must be at least 1 MHz, and must be twice the desired internal clock frequency; hence, the 8085A is operated with a 6 MHz crystal (for 3 MHz clock), and the 8085A-2 can be operated with a 10 MHz crystal (for 5 MHz clock). If a crystal is used, it must have the following characteristics:

Parallel resonance at twice the clock frequency desired
C_L (load capacitance) ≤ 30 pf
C_S (shunt capacitance) ≤ 7 pf
R_S (equivalent shunt resistance) ≤ 75 Ohms
Drive level: 10 mW
Frequency tolerance: ±.005% (suggested)

Note the use of the 20pF capacitor between X_2 and ground. This capacitor is required with crystal frequencies below 4 MHz to assure oscillator startup at the correct frequency. A parallel-resonant LC circuit may be used as the frequency-determining network for the 8085A, providing that its frequency tolerance of approximately ±10% is acceptable. The components are chosen from the formula:

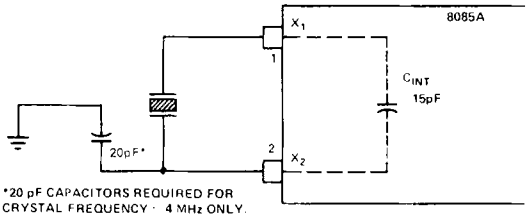
$$f = \frac{1}{2\pi\sqrt{L(C_{ext} + C_{int})}}$$

To minimize variations in frequency, it is recommended that you choose a value for C_{ext} that is at least twice that of C_{int}, or 30 pF. The use of an LC circuit is not recommended for frequencies higher than approximately 5 MHz.

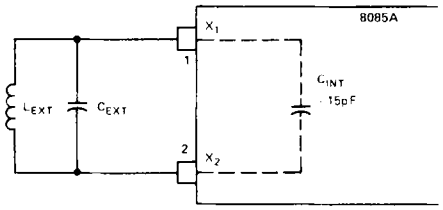
An RC circuit may be used as the frequency-determining network for the 8085A if maintaining a precise clock frequency is of no importance. Variations in the on-chip timing generation can cause a wide variation in frequency when using the RC mode. Its advantage is its low component cost. The driving frequency generated by the circuit shown is approximately 3 MHz. It is not recommended that frequencies greatly higher or lower than this be attempted.

Figure 4 shows the recommended clock driver circuits. Note in D and E that pullup resistors are required to assure that the high level voltage of the input is at least 4 V.

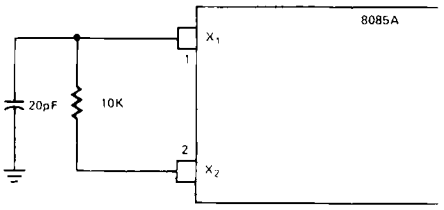
For driving frequencies up to and including 6 MHz you may supply the driving signal to X_1 and leave X_2 open-circuited (Figue 4D). If the driving frequency is from 6 MHz to 10 MHz, stability of the clock generator will be improved by driving both X_1 and X_2 with a push-pull source (Figure 4E). To prevent self-oscillation of the 8085A, be sure that X_2 is not coupled back to X_1 through the driving circuit.



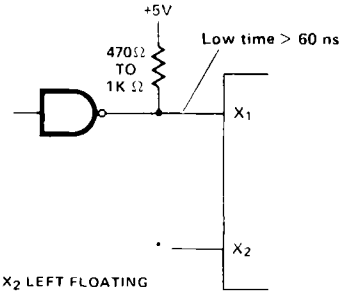
A. Quartz Crystal Clock Driver



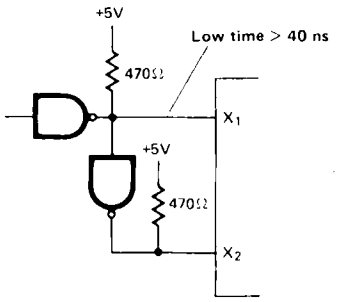
B. LC Tuned Circuit Clock Driver



C. RC Circuit Clock Driver



D. 1-6 MHz Input Frequency External Clock Driver Circuit



E. 1-10 MHz Input Frequency External Clock Driver Circuit

Figure 4. Clock Driver Circuits

GENERATING AN 8085A WAIT STATE

If your system requirements are such that slow memories or peripheral devices are being used, the circuit shown in Figure 5 may be used to insert one WAIT state in each 8085A machine cycle

The D flip-flops should be chosen so that

- CLK is rising edge-triggered
- CLEAR is low-level active.

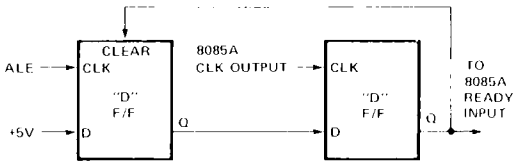


Figure 5. Generation of a Wait State for 8085A CPU

As in the 8080, the READY line is used to extend the read and write pulse lengths so that the 8085A can be used with slow memory. HOLD causes the cpu to relinquish the bus when it is through with it by floating the Address and Data Buses.

SYSTEM INTERFACE

The 8085A family includes memory components, which are directly compatible to the 8085A cpu. For example, a system consisting of the three chips, 8085A, 8156, and 8355 will have the following features:

- 2K Bytes ROM
- 256 Bytes RAM
- 1 Timer/Counter
- 4 8-bit I/O Ports
- 1 6-bit I/O Port
- 4 Interrupt Levels
- Serial In/Serial Out Ports

This minimum system, using the standard I/O technique is as shown in Figure 6.

In addition to standard I/O, the memory mapped I/O offers an efficient I/O addressing technique. With this technique, an area of memory address space is assigned for I/O address, thereby, using the memory address for I/O manipulation. Figure 7 shows the system configuration of Memory Mapped I/O using 8085A.

The 8085A cpu can also interface with the standard memory that does *not* have the multiplexed address/data bus. It will require a simple 8212 (8-bit latch) as shown in Figure 8.

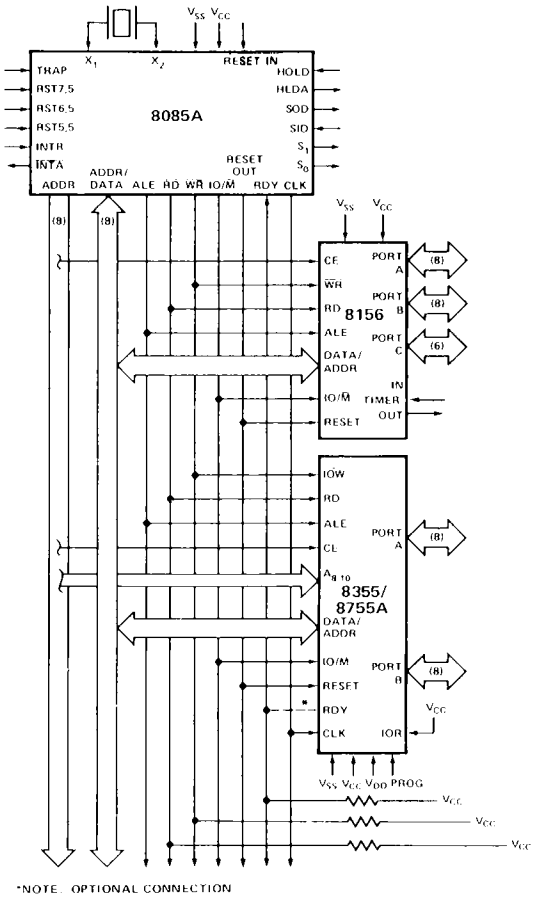


Figure 6. 8085A Minimum System (Standard I/O Technique)

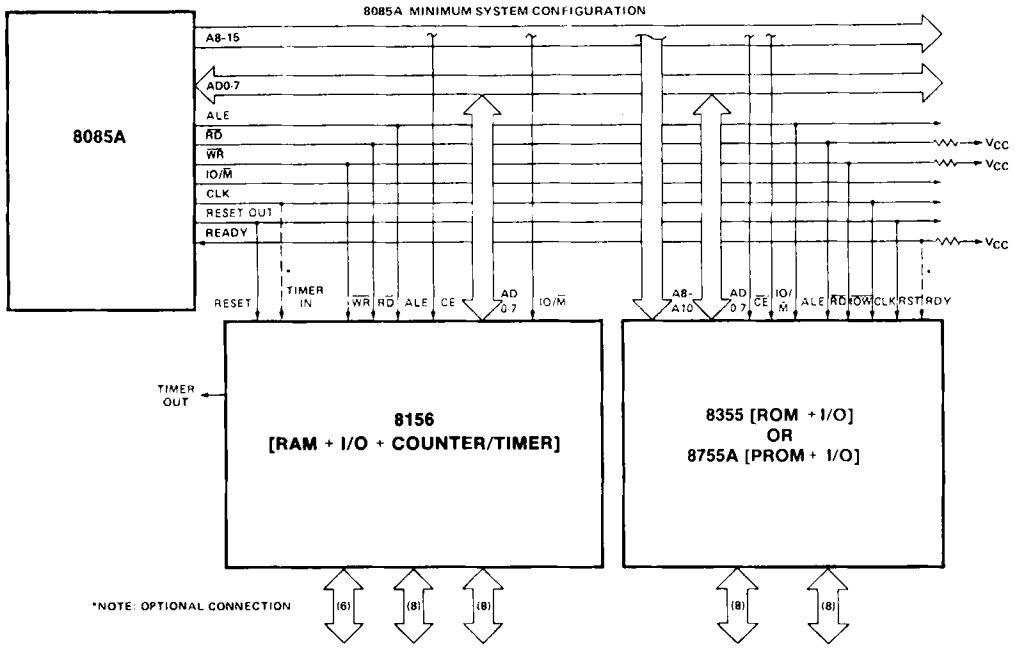


Figure 7. MCS-85™ Minimum System (Memory Mapped I/O)

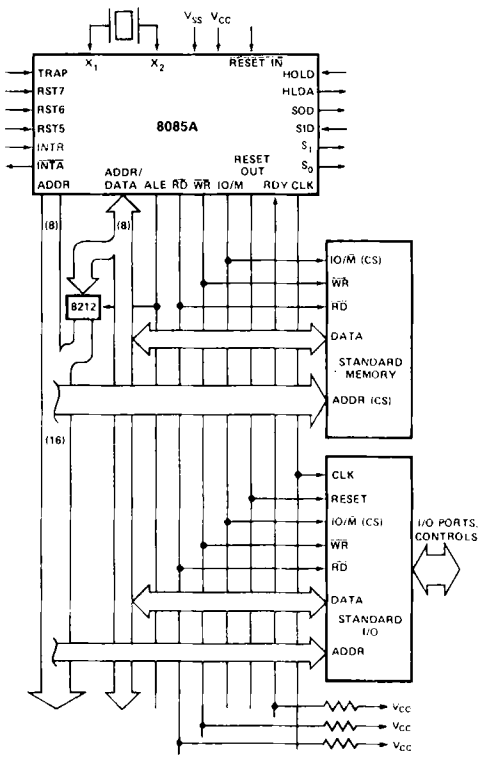


Figure 8. MCS-85™ System (Using Standard Memories)

BASIC SYSTEM TIMING

The 8085A has a multiplexed Data Bus. ALE is used as a strobe to sample the lower 8-bits of address on the Data Bus. Figure 9 shows an instruction fetch, memory read and I/O write cycle (as would occur during processing of the OUT instruction). Note that during the I/O write and read cycle that the I/O port address is copied on both the upper and lower half of the address.

There are seven possible types of machine cycles. Which of these seven takes place is defined by the status of the three status lines ($IO/\overline{M}$, S_1, S_0) and the three control signals ($\overline{RD}$, $\overline{WR}$, and $\overline{INTA}$). (See Table 2.) The status lines can be used as advanced controls (for device selection, for example), since they become active at the T_1 state, at the outset of each machine cycle. Control lines $\overline{RD}$ and $\overline{WR}$ become active later, at the time when the transfer of data is to take place, so are used as command lines.

A machine cycle normally consists of three T states, with the exception of OPCODE FETCH, which normally has either four or six T states (unless WAIT or HOLD states are forced by the receipt of $\overline{READY}$ or HOLD inputs). Any T state must be one of ten possible states, shown in Table 3.

TABLE 2. 8085A MACHINE CYCLE CHART

MACHINE CYCLE			STATUS			CONTROL		
			$IO/\overline{M}$	S1	S0	$\overline{RD}$	$\overline{WR}$	$\overline{INTA}$
OPCODE FETCH	(OF)		0	1	1	0	*	1
MEMORY READ	(MR)		0	1	0	0	1	1
MEMORY WRITE	(MW)		0	0	1	1	0	1
I/O READ	(IOR)		1	1	0	0	1	1
I/O WRITE	(IOW)		1	0	1	1	0	1
ACKNOWLEDGE OF INTR	(INA)		1	1	1	1	1	0
BUS IDLE	(BI):	DAD	0	1	0	1	1	1
		ACK. OF RST,TRAP	1	1	1	1	1	1
		HALT	TS	0	0	TS	TS	1

TABLE 3. 8085A MACHINE STATE CHART

Machine State	Status & Buses				Control		
	S1,S0	$IO/\overline{M}$	A_8-A_{15}	AD_0-AD_7	$\overline{RD}$,$\overline{WR}$	$\overline{INTA}$	ALE
T_1	X	X	X	X	1	1	1*
T_2	X	X	X	X	X	X	0
T_{WAIT}	X	X	X	X	X	X	0
T_3	X	X	X	X	X	X	0
T_4	1	0†	X	TS	1	1	0
T_5	1	0†	X	TS	1	1	0
T_6	1	0†	X	TS	1	1	0
T_{RESET}	X	TS	TS	TS	TS	1	0
T_{HALT}	0	TS	TS	TS	TS	1	0
T_{HOLD}	X	TS	TS	TS	TS	1	0

0 = Logic "0" TS = High Impedance
1 = Logic "1" X = Unspecified

* ALE not generated during 2nd and 3rd machine cycles of DAD instruction
† IO/M = 1 during T_4-T_6 of INA machine cycle

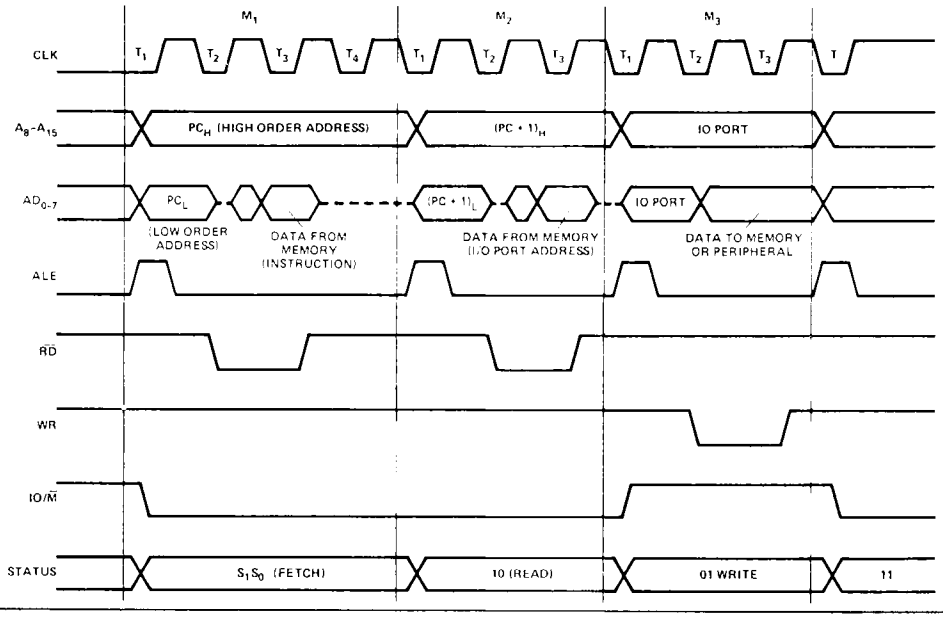


Figure 9. 8085A Basic System Timing

TABLE 4. ABSOLUTE MAXIMUM RATINGS*

Ambient Temperature Under Bias. . . . . 0°C to 70°C
Storage Temperature . . . . . –65°C to +150°C
Voltage on Any Pin
With Respect to Ground . . . . . –0.5V to +7V
Power Dissipation . . . . . 1.5 Watt

*COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TABLE 5. D.C. CHARACTERISTICS

(T_A = 0°C to 70°C; V_{CC} = 5V ±5%; V_{SS} = 0V; unless otherwise specified)

Symbol	Parameter	Min.	Max.	Units	Test Conditions
V_{IL}	Input Low Voltage	-0.5	+0.8	V	
V_{IH}	Input High Voltage	2.0	V_{CC}+0.5	V	
V_{OL}	Output Low Voltage		0.45	V	I_{OL} = 2mA
V_{OH}	Output High Voltage	2.4		V	I_{OH} = -400μA
I_{CC}	Power Supply Current		170	mA	
I_{IL}	Input Leakage		±10	μA	V_{in} = V_{CC}
I_{LO}	Output Leakage		±10	μA	0.45V ≤ V_{out} ≤ V_{CC}
V_{ILR}	Input Low Level, RESET	-0.5	+0.8	V	
V_{IHR}	Input High Level, RESET	2.4	V_{CC} +0.5	V	
V_{HY}	Hysteresis, RESET	0.25		V	

TABLE 6. A.C. CHARACTERISTICS

$T_A = 0°C$ to $70°C$; $V_{CC} = 5V \pm 5\%$; $V_{SS} = 0V$

Symbol	Parameter	8085A[2]		8085A-2[2] (Preliminary)		Units
		Min.	Max.	Min.	Max.	
t_{CYC}	CLK Cycle Period	320	2000	200	2000	ns
t_1	CLK Low Time (Standard CLK Loading)	80		40		ns
t_2	CLK High Time (Standard CLK Loading)	120		70		ns
t_r, t_f	CLK Rise and Fall Time		30		30	ns
t_{XKR}	X_1 Rising to CLK Rising	30	120	30	100	ns
t_{XKF}	X_1 Rising to CLK Falling	30	150	30	110	ns
t_{AC}	A_{8-15} Valid to Leading Edge of Control[1]	270		115		ns
t_{ACL}	A_{0-7} Valid to Leading Edge of Control	240		115		ns
t_{AD}	A_{0-15} Valid to Valid Data In		575		350	ns
t_{AFR}	Address Float After Leading Edge of $\overline{READ}$ ($\overline{INTA}$)		0		0	ns
t_{AL}	A_{8-15} Valid Before Trailing Edge of ALE[1]	115		50		ns
t_{ALL}	A_{0-7} Valid Before Trailing Edge of ALE	90		50		ns
t_{ARY}	READY Valid from Address Valid		220		100	ns
t_{CA}	Address (A_{8-15}) Valid After Control	120		60		ns
t_{CC}	Width of Control Low ($\overline{RD}$, $\overline{WR}$, $\overline{INTA}$) Edge of ALE	400		230		ns
t_{CL}	Trailing Edge of Control to Leading Edge of ALE	50		25		ns
t_{DW}	Data Valid to Trailing Edge of $\overline{WRITE}$	420		230		ns
t_{HABE}	HLDA to Bus Enable		210		150	ns
t_{HABF}	Bus Float After HLDA		210		150	ns
t_{HACK}	HLDA Valid to Trailing Edge of CLK	110		40		ns
t_{HDH}	HOLD Hold Time	0		0		ns
t_{HDS}	HOLD Setup Time to Trailing Edge of CLK	170		120		ns
t_{INH}	INTR Hold Time	0		0		ns
t_{INS}	INTR, RST, and TRAP Setup Time to Falling Edge of CLK	160		150		ns
t_{LA}	Address Hold Time After ALE	100		50		ns
t_{LC}	Trailing Edge of ALE to Leading Edge of Control	130		60		ns
t_{LCK}	ALE Low During CLK High	100		50		ns
t_{LDR}	ALE to Valid Data During Read		460		270	ns
t_{LDW}	ALE to Valid Data During Write		200		120	ns
t_{LL}	ALE Width	140		80		ns
t_{LRY}	ALE to READY Stable		110		30	ns

Table 6. A.C. Characteristics (Cont.)

Symbol	Parameter	8085A[2]		8085A-2[2] (Preliminary)		Units
		Min.	Max.	Min.	Max.	
t_{RAE}	Trailing Edge of $\overline{READ}$ to Re-Enabling of Address	150		90		ns
t_{RD}	$\overline{READ}$ (or $\overline{INTA}$) to Valid Data		300		150	ns
t_{RV}	Control Trailing Edge to Leading Edge of Next Control	400		220		ns
t_{RDH}	Data Hold Time After $\overline{READ}$ $\overline{INTA}$[7]	0		0		ns
t_{RYH}	READY Hold Time	0		0		ns
t_{RYS}	READY Setup Time to Leading Edge of CLK	110		100		ns
t_{WD}	Data Valid After Trailing Edge of $\overline{WRITE}$	100		60		ns
t_{WDL}	LEADING Edge of WRITE to Data Valid		40		20	ns

Notes:
1. A_8-A_{15} address Specs apply to IO/$\overline{M}$, S_0, and S_1 except A_8-A_{15} are undefined during T_4-T_6 of OF cycle whereas IO/$\overline{M}$, S_0, and S_1 are stable.
2. Test conditions: t_{CYC} = 320 ns (8085A)/200 ns (8085A-2); C_L = 150 pF.
3. For all output timing where C_L = 150 pF use the following correction factors:
   25 pF ≤ C_L < 150 pF: −0.10 ns/pF
   150 pF < C_L ≤ 300 pF: +0.30 ns/pF
4. Output timings are measured with purely capacitive load.
5. All timings are measured at output votage V_L = 0.8V, V_H = 2.0V, and 1.5V with 20 ns rise and fall time on inputs.
6. To calculate timing specifications at other values of t_{CYC} use Table 7.
7. Data hold time is guaranteed under all loading conditions.

Input Waveform for A.C. Tests:

TABLE 7. BUS TIMING SPECIFICATION AS A T_{CYC} DEPENDENT

8085A			
t_{AL}	–	(1/2) T - 45	MIN
t_{LA}	–	(1/2) T - 60	MIN
t_{LL}	–	(1/2) T - 20	MIN
t_{LCK}	–	(1/2) T - 60	MIN
t_{LC}	–	(1/2) T - 30	MIN
t_{AD}	–	(5/2 + N) T - 225	MAX
t_{RD}	–	(3/2 + N) T - 180	MAX
t_{RAE}	–	(1/2) T - 10	MIN
t_{CA}	–	(1/2) T - 40	MIN
t_{DW}	–	(3/2 + N) T - 60	MIN
t_{WD}	–	(1/2) T - 60	MIN
t_{CC}	–	(3/2 + N) T - 80	MIN
t_{CL}	–	(1/2) T - 110	MIN
t_{ARY}	–	(3/2) T - 260	MAX
t_{HACK}	–	(1/2) T - 50	MIN
t_{HABF}	–	(1/2) T + 50	MAX
t_{HABE}	–	(1/2) T + 50	MAX
t_{AC}	–	(2/2) T - 50	MIN
t_1	–	(1/2) T - 80	MIN
t_2	–	(1/2) T - 40	MIN
t_{RV}	–	(3/2) T - 80	MIN
t_{LDR}	–	(4/2) T - 180	MAX

NOTE: N is equal to the total WAIT states.
T = t_{CYC}.

8085A-2 (Preliminary)			
t_{AL}	–	(1/2) T - 50	MIN
t_{LA}	–	(1/2) T - 50	MIN
t_{LL}	–	(1/2) T - 20	MIN
t_{LCK}	–	(1/2) T - 50	MIN
t_{LC}	–	(1/2) T - 40	MIN
t_{AD}	–	(5/2 + N) T - 150	MAX
t_{RD}	–	(3/2 + N) T - 150	MAX
t_{RAE}	–	(1/2) T - 10	MIN
t_{CA}	–	(1/2) T - 40	MIN
t_{DW}	–	(3/2 + N) T - 70	MIN
t_{WD}	–	(1/2) T - 40	MIN
t_{CC}	–	(3/2 + N) T - 70	MIN
t_{CL}	–	(1/2) T - 75	MIN
t_{ARY}	–	(3/2) T - 200	MAX
t_{HACK}	–	(1/2) T - 60	MIN
t_{HABF}	–	(1/2) T + 50	MAX
t_{HABE}	–	(1/2) T + 50	MAX
t_{AC}	–	(2/2) T - 85	MIN
t_1	–	(1/2) T - 60	MIN
t_2	–	(1/2) T - 30	MIN
t_{RV}	–	(3/2) T - 80	MIN
t_{LDR}	–	(4/2) T - 130	MAX

NOTE: N is equal to the total WAIT states.
T = t_{CYC}.

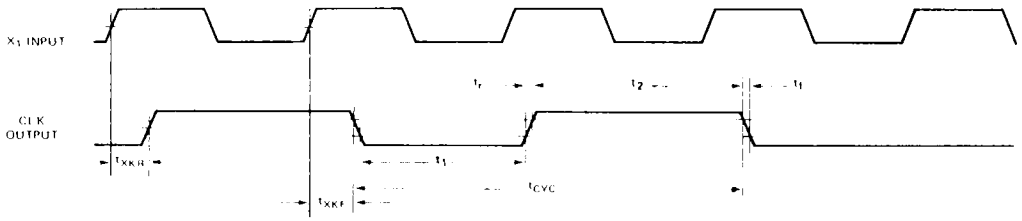
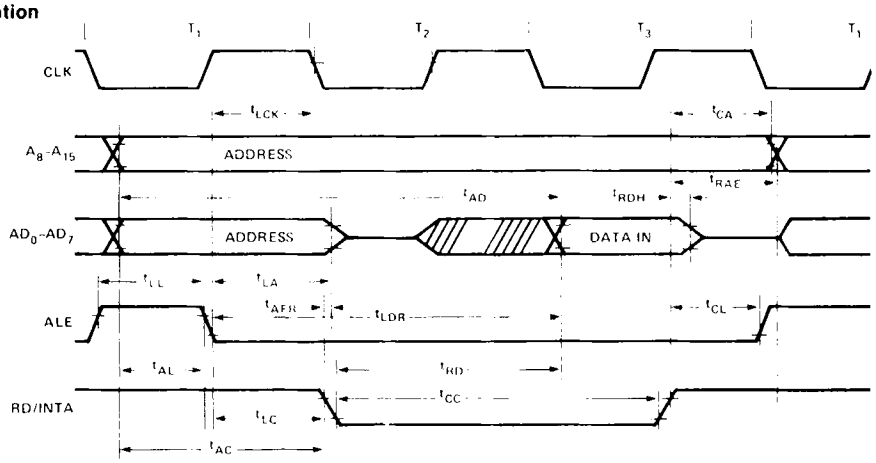
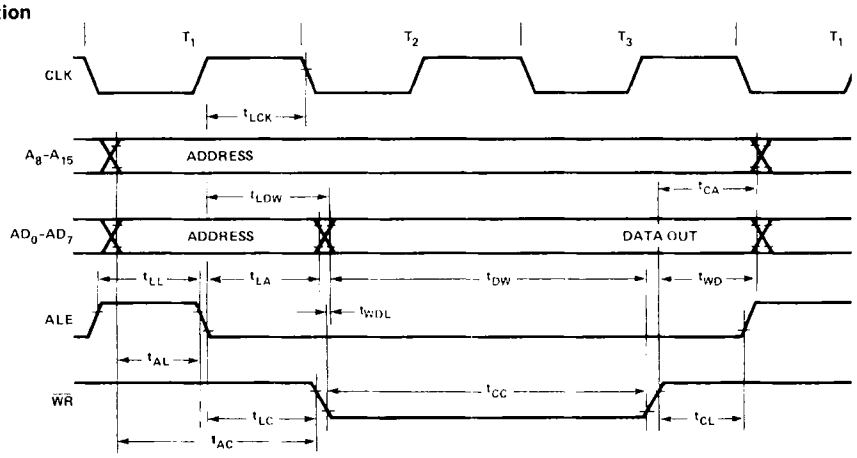


Figure 10. Clock Timing Waveform

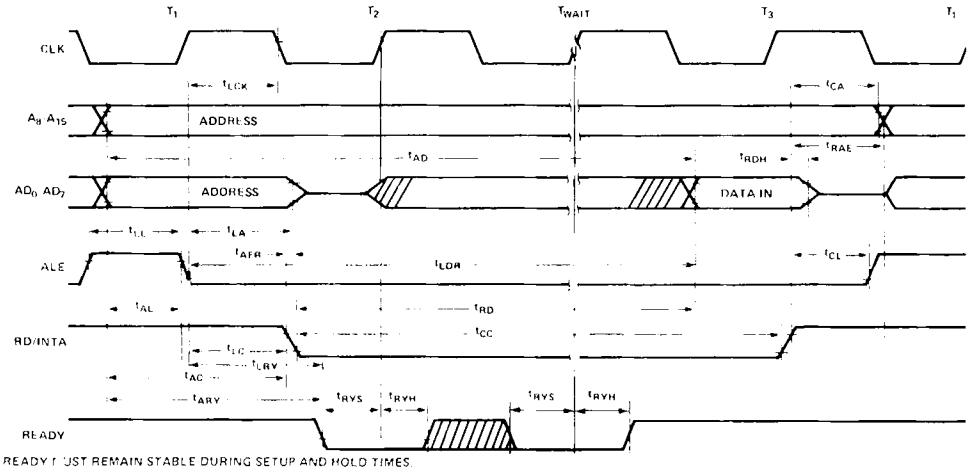
Read Operation



Write Operation



Read operation with Wait Cycle (Typical) — same READY timing applies to WRITE operation.



NOTE 1: READY MUST REMAIN STABLE DURING SETUP AND HOLD TIMES.

Figure 11. 8085A Bus Timing, With and Without Wait

Hold Operation

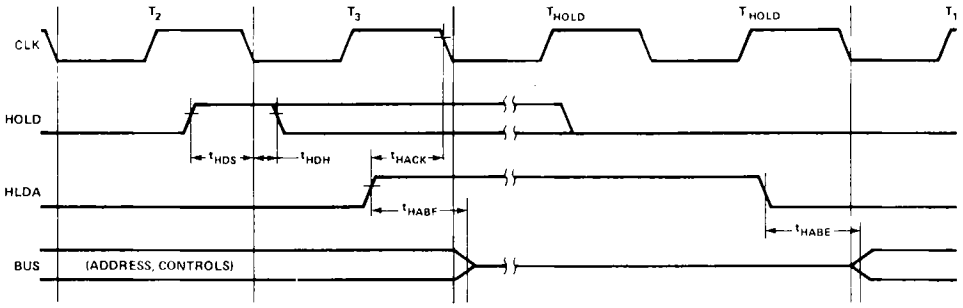


Figure 12. 8085A Hold Timing.

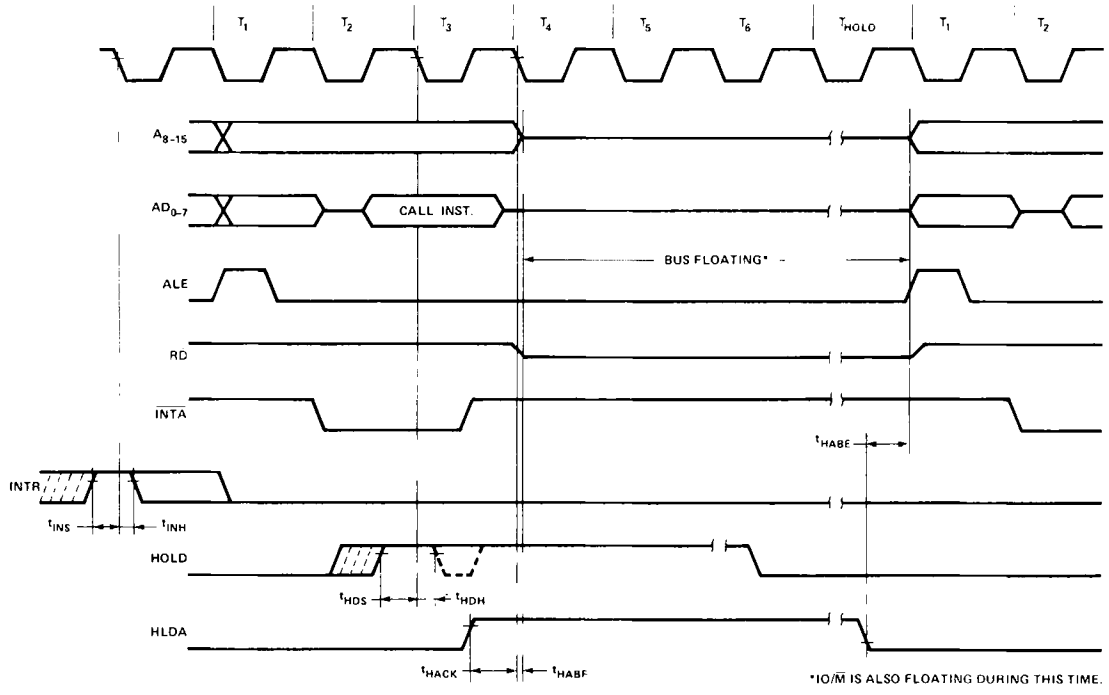


Figure 13. 8085A Interrupt and Hold Timing

8085A INSTRUCTION SET SUMMARY BY FUNCTIONAL GROUPING

Table 6-1

Mnemonic	Description	Instruction Code (1) D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0	Page
MOVE, LOAD, AND STORE										
MOVr1 r2	Move register to register	0	1	D	D	D	S	S	S	5-4
MOV M,r	Move register to memory	0	1	1	1	0	S	S	S	5-4
MOV r,M	Move memory to register	0	1	D	D	D	1	1	0	5-4
MVI r	Move immediate register	0	0	D	D	D	1	1	0	5-4
MVI M	Move immediate memory	0	0	1	1	0	1	1	0	5-4
LXI B	Load immediate register Pair B & C	0	0	0	0	0	0	0	1	5-5
LXI D	Load immediate register Pair D & E	0	0	0	1	0	0	0	1	5-5
LXI H	Load immediate register Pair H & L	0	0	1	0	0	0	0	1	5-5
STAX B	Store A indirect	0	0	0	0	0	0	1	0	5-6
STAX D	Store A indirect	0	0	0	1	0	0	1	0	5-6
LDAX B	Load A indirect	0	0	0	0	1	0	1	0	5-5
LDAX D	Load A indirect	0	0	0	1	1	0	1	0	5-5
STA	Store A direct	0	0	1	1	0	0	1	0	5-5
LDA	Load A direct	0	0	1	1	1	0	1	0	5-5
SHLD	Store H & L direct	0	0	1	0	0	0	1	0	5-5
LHLD	Load H & L direct	0	0	1	0	1	0	1	0	5-5
XCHG	Exchange D & E, H & L Registers	1	1	1	0	1	0	1	1	5-6
STACK OPS										
PUSH B	Push register Pair B & C on stack	1	1	0	0	0	1	0	1	5-15
PUSH D	Push register Pair D & E on stack	1	1	0	1	0	1	0	1	5-15
PUSH H	Push register Pair H & L on stack	1	1	1	0	0	1	0	1	5-15
PUSH PSW	Push A and Flags on stack	1	1	1	1	0	1	0	1	5-15
POP B	Pop register Pair B & C off stack	1	1	0	0	0	0	0	1	5-15
POP D	Pop register Pair D & E off stack	1	1	0	1	0	0	0	1	5-15
POP H	Pop register Pair H & L off stack	1	1	1	0	0	0	0	1	5-15
POP PSW	Pop A and Flags off stack	1	1	1	1	0	0	0	1	5-15
XTHL	Exchange top of stack, H & L	1	1	1	0	0	0	1	1	5-16
SPHL	H & L to stack pointer	1	1	1	1	1	0	0	1	5-16
LXI SP	Load immediate stack pointer	0	0	1	1	0	0	0	1	5-5
INX SP	Increment stack pointer	0	0	1	1	0	0	1	1	5-9
DCX SP	Decrement stack pointer	0	0	1	1	1	0	1	1	5-9
JUMP										
JMP	Jump unconditional	1	1	0	0	0	0	1	1	5-13
JC	Jump on carry	1	1	0	1	1	0	1	0	5-13
JNC	Jump on no carry	1	1	0	1	0	0	1	0	5-13
JZ	Jump on zero	1	1	0	0	1	0	1	0	5-13
JNZ	Jump on no zero	1	1	0	0	0	0	1	0	5-13
JP	Jump on positive	1	1	1	1	0	0	1	0	5-13
JM	Jump on minus	1	1	1	1	1	0	1	0	5-13
JPE	Jump on parity even	1	1	1	0	1	0	1	0	5-13
JPO	Jump on parity odd	1	1	1	0	0	0	1	0	5-13
PCHL	H & L to program counter	1	1	1	0	1	0	0	1	5-15
CALL										
CALL	Call unconditional	1	1	0	0	1	1	0	1	5-13
CC	Call on carry	1	1	0	1	1	1	0	0	5-14
CNC	Call on no carry	1	1	0	1	0	1	0	0	5-14
CZ	Call on zero	1	1	0	0	1	1	0	0	5-14
CNZ	Call on no zero	1	1	0	0	0	1	0	0	5-14
CP	Call on positive	1	1	1	1	0	1	0	0	5-14
CM	Call on minus	1	1	1	1	1	1	0	0	5-14
CPE	Call on parity even	1	1	1	0	1	1	0	0	5-14
CPO	Call on parity odd	1	1	1	0	0	1	0	0	5-14
RETURN										
RET	Return	1	1	0	0	1	0	0	1	5-14
RC	Return on carry	1	1	0	1	1	0	0	0	5-14
RNC	Return on no carry	1	1	0	1	0	0	0	0	5-14
RZ	Return on zero	1	1	0	0	1	0	0	0	5-14
RNZ	Return on no zero	1	1	0	0	0	0	0	0	5-14
RP	Return on positive	1	1	1	1	0	0	0	0	5-14
RM	Return on minus	1	1	1	1	1	0	0	0	5-14
RPE	Return on parity even	1	1	1	0	1	0	0	0	5-14
RPO	Return on parity odd	1	1	1	0	0	0	0	0	5-14
RESTART										
RST	Restart	1	1	A	A	A	1	1	1	5-14
INPUT/OUTPUT										
IN	Input	1	1	0	1	1	0	1	1	5-16
OUT	Output	1	1	0	1	0	0	1	1	5-16
INCREMENT AND DECREMENT										
INR r	Increment register	0	0	D	D	D	1	0	0	5-8
DCR r	Decrement register	0	0	D	D	D	1	0	1	5-8
INR M	Increment memory	0	0	1	1	0	1	0	0	5-8
DCR M	Decrement memory	0	0	1	1	0	1	0	1	5-8
INX B	Increment B & C registers	0	0	0	0	0	0	1	1	5-9
INX D	Increment D & E registers	0	0	0	1	0	0	1	1	5-9
INX H	Increment H & L registers	0	0	1	0	0	0	1	1	5-9
DCX B	Decrement B & C	0	0	0	0	1	0	1	1	5-9
DCX D	Decrement D & E	0	0	0	1	1	0	1	1	5-9
DCX H	Decrement H & L	0	0	1	0	1	0	1	1	5-9
ADD										
ADD r	Add register to A	1	0	0	0	0	S	S	S	5-6
ADC r	Add register to A with carry	1	0	0	0	1	S	S	S	5-6
ADD M	Add memory to A	1	0	0	0	0	1	1	0	5-6
ADC M	Add memory to A with carry	1	0	0	0	1	1	1	0	5-7
ADI	Add immediate to A	1	1	0	0	0	1	1	0	5-6
ACI	Add immediate to A with carry	1	1	0	0	1	1	1	0	5-7
DAD B	Add B & C to H & L	0	0	0	0	1	0	0	1	5-9
DAD D	Add D & E to H & L	0	0	0	1	1	0	0	1	5-9
DAD H	Add H & L to H & L	0	0	1	0	1	0	0	1	5-9
DAD SP	Add stack pointer to H & L	0	0	1	1	1	0	0	1	5-9
SUBTRACT										
SUB r	Subtract register from A	1	0	0	1	0	S	S	S	5-7
SBB r	Subtract register from A with borrow	1	0	0	1	1	S	S	S	5-7
SUB M	Subtract memory from A	1	0	0	1	0	1	1	0	5-7
SBB M	Subtract memory from A with borrow	1	0	0	1	1	1	1	0	5-8
SUI	Subtract immediate from A	1	1	0	1	0	1	1	0	5-7

8085A INSTRUCTION SET SUMMARY (Cont'd)

Table 6-1

Mnemonic	Description	Instruction Code (1) D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0	Page
SBI	Subtract immediate from A with borrow	1	1	0	1	1	1	1	0	5-8
LOGICAL										
ANA r	And register with A	1	0	1	0	0	S	S	S	5-9
XRA r	Exclusive OR register with A	1	0	1	0	1	S	S	S	5-10
ORA r	OR register with A	1	0	1	1	0	S	S	S	5-10
CMP r	Compare register with A	1	0	1	1	1	S	S	S	5-11
ANA M	And memory with A	1	0	1	0	0	1	1	0	5-10
XRA M	Exclusive OR memory with A	1	0	1	0	1	1	1	0	5-10
ORA M	OR memory with A	1	0	1	1	0	1	1	0	5-11
CMP M	Compare memory with A	1	0	1	1	1	1	1	0	5-11
ANI	And immediate with A	1	1	1	0	0	1	1	0	5-10
XRI	Exclusive OR immediate with A	1	1	1	0	1	1	1	0	5-10
ORI	OR immediate with A	1	1	1	1	0	1	1	0	5-11
CPI	Compare immediate with A	1	1	1	1	1	1	1	0	5-11
ROTATE										
RLC	Rotate A left	0	0	0	0	0	1	1	1	5-11
RRC	Rotate A right	0	0	0	0	1	1	1	1	5-12
RAL	Rotate A left through carry	0	0	0	1	0	1	1	1	5-12
RAR	Rotate A right through carry	0	0	0	1	1	1	1	1	5-12
SPECIALS										
CMA	Complement A	0	0	1	0	1	1	1	1	5-12
STC	Set carry	0	0	1	1	0	1	1	1	5-12
CMC	Complement carry	0	0	1	1	1	1	1	1	5-12
DAA	Decimal adjust A	0	0	1	0	0	1	1	1	5-9
CONTROL										
EI	Enable Interrupts	1	1	1	1	1	0	1	1	5-17
DI	Disable Interrupt	1	1	1	1	0	0	1	1	5-17
NOP	No-operation	0	0	0	0	0	0	0	0	5-17
HLT	Halt	0	1	1	1	0	1	1	0	5-17
NEW 8085A INSTRUCTIONS										
RIM	Read Interrupt Mask	0	0	1	0	0	0	0	0	5-17
SIM	Set Interrupt Mask	0	0	1	1	0	0	0	0	5-18

NOTES: 1. DDS or SSS: B 000, C 001, D 010, E011, H 100, L 101, Memory 110, A 111.

2. Two possible cycle times, (6/12) indicate instruction cycles dependent on condition flags.

8259A
PROGRAMMABLE INTERRUPT CONTROLLER

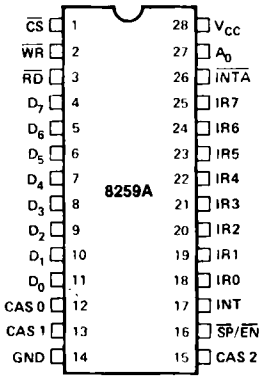
- **MCS-86™ Compatible**
- **MCS-80/85™ Compatible**
- **Eight-Level Priority Controller**
- **Expandable to 64 Levels**
- **Programmable Interrupt Modes**
- **Individual Request Mask Capability**
- **Single +5V Supply (No Clocks)**
- **28-Pin Dual-In-Line Package**

The Intel® 8259A Programmable Interrupt Controller handles up to eight vectored priority interrupts for the CPU. It is cascadable for up to 64 vectored priority interrupts without additional circuitry. It is packaged in a 28-pin DIP, uses NMOS technology and requires a single +5V supply. Circuitry is static, requiring no clock input.

The 8259A is designed to minimize the software and real time overhead in handling multi-level priority interrupts. It has several modes, permitting optimization for a variety of system requirements.

The 8259A is fully upward compatible with the Intel® 8259. Software originally written for the 8259 will operate the 8259A in all 8259 equivalent modes (MCS-80/85, Non-Buffered, Edge Triggered).

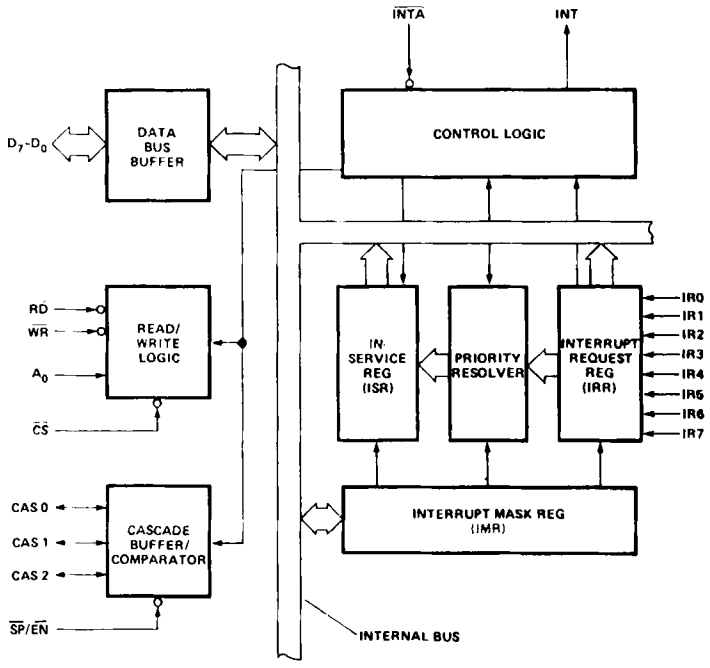
PIN CONFIGURATION



PIN NAMES

D_7-D_0	DATA BUS (BI-DIRECTIONAL)
$\overline{RD}$	READ INPUT
$\overline{WR}$	WRITE INPUT
A_0	COMMAND SELECT ADDRESS
$\overline{CS}$	CHIP SELECT
CAS2-CAS0	CASCADE LINES
$\overline{SP}/\overline{EN}$	SLAVE PROGRAM INPUT/ENABLE
INT	INTERRUPT OUTPUT
$\overline{INTA}$	INTERRUPT ACKNOWLEDGE INPUT
IR0-IR7	INTERRUPT REQUEST INPUTS

BLOCK DIAGRAM



INTERRUPTS IN MICROCOMPUTER SYSTEMS

Microcomputer system design requires that I/O devices such as keyboards, displays, sensors and other components receive servicing in an efficient manner so that large amounts of the total system tasks can be assumed by the microcomputer with little or no effect on throughput.

The most common method of servicing such devices is the *Polled* approach. This is where the processor must test each device in sequence and in effect "ask" each one if it needs servicing. It is easy to see that a large portion of the main program is looping through this continuous polling cycle and that such a method would have a serious, detrimental effect on system throughput, thus limiting the tasks that could be assumed by the microcomputer and reducing the cost effectiveness of using such devices.

A more desirable method would be one that would allow the microprocessor to be executing its main program and only stop to service peripheral devices when it is told to do so by the device itself. In effect, the method would provide an external asynchronous input that would inform the processor that it should complete whatever instruction that is currently being executed and fetch a new routine that will service the requesting device. Once this servicing is complete, however, the processor would resume exactly where it left off.

This method is called *Interrupt*. It is easy to see that system throughput would drastically increase, and thus more tasks could be assumed by the microcomputer to further enhance its cost effectiveness.

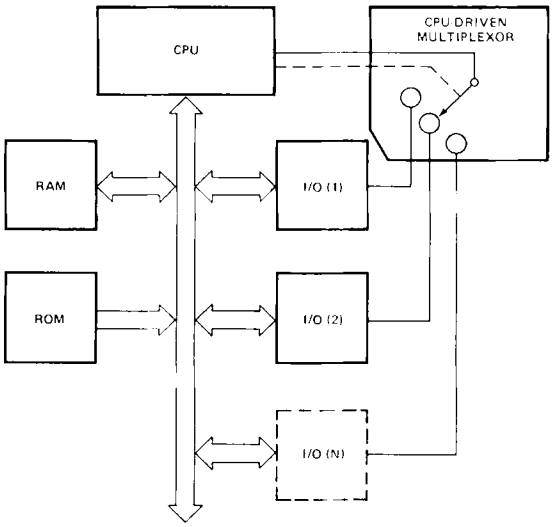
The Programmable Interrupt Controller (PIC) functions as an overall manager in an Interrupt-Driven system environment. It accepts requests from the peripheral equipment, determines which of the incoming requests is of the highest importance (priority), ascertains whether the incoming request has a higher priority value than the level currently being serviced, and issues an interrupt to the CPU based on this determination.

Each peripheral device or structure usually has a special program or "routine" that is associated with its specific functional or operational requirements; this is referred to as a "service routine". The PIC, after issuing an Interrupt to the CPU, must somehow input information into the CPU that can "point" the Program Counter to the service routine associated with the requesting device. This "pointer" is an address in a vectoring table and will often be referred to, in this document, as vectoring data.

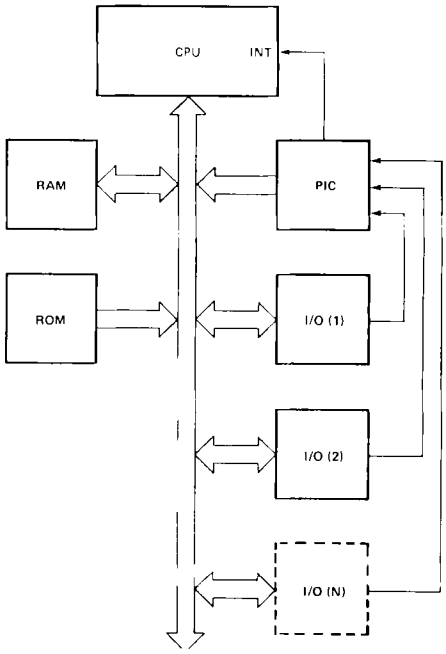
8259A BASIC FUNCTIONAL DESCRIPTION

GENERAL

The 8259A is a device specifically designed for use in real time, interrupt driven microcomputer systems. It manages eight levels or requests and has built-in features for expandability to other 8259A's (up to 64 levels). It is programmed by the system's software as an I/O peripheral. A selection of priority modes is available to the programmer so that the manner in which the requests are processed by the 8259A can be configured to match his system requirements. The priority modes can be changed or reconfigured dynamically at any time during the main program. This means that the complete interrupt structure can be defined as required, based on the total system environment.



Polled Method



Interrupt Method

INTERRUPT REQUEST REGISTER (IRR) AND IN-SERVICE REGISTER (ISR)

The interrupts at the IR input lines are handled by two registers in cascade, the Interrupt Request Register (IRR) and the In-Service Register (ISR). The IRR is used to store all the interrupt levels which are requesting service; and the ISR is used to store all the interrupt levels which are being serviced.

PRIORITY RESOLVER

This logic block determines the priorities of the bits set in the IRR. The highest priority is selected and strobed into the corresponding bit of the ISR during $\overline{INTA}$ pulse.

INTERRUPT MASK REGISTER (IMR)

The IMR stores the bits which mask the interrupt lines to be masked. The IMR operates on the IRR. Masking of a higher priority input will not affect the interrupt request lines of lower priority.

INT (INTERRUPT)

This output goes directly to the CPU interrupt input. The V_{OH} level on this line is designed to be fully compatible with the 8080A, 8085A and 8086 input levels.

$\overline{INTA}$ (INTERRUPT ACKNOWLEDGE)

$\overline{INTA}$ pulses will cause the 8259A to release vectoring information onto the data bus. The format of this data depends on the system mode (μPM) of the 8259A.

DATA BUS BUFFER

This 3-state, bidirectional 8-bit buffer is used to interface the 8259A to the system Data Bus. Control words and status information are transferred through the Data Bus Buffer.

READ/WRITE CONTROL LOGIC

The function of this block is to accept OUTput commands from the CPU. It contains the Initialization Command Word (ICW) registers and Operation Command Word (OCW) registers which store the various control formats for device operation. This function block also allows the status of the 8259A to be transferred onto the Data Bus.

$\overline{CS}$ (CHIP SELECT)

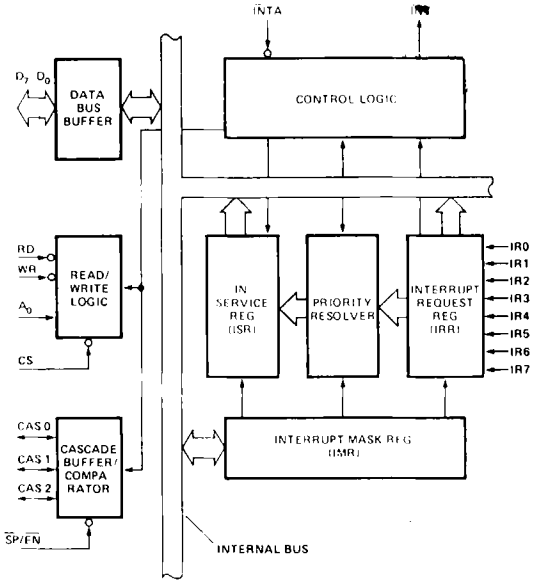
A LOW on this input enables the 8259A. No reading or writing of the chip will occur unless the device is selected.

$\overline{WR}$ (WRITE)

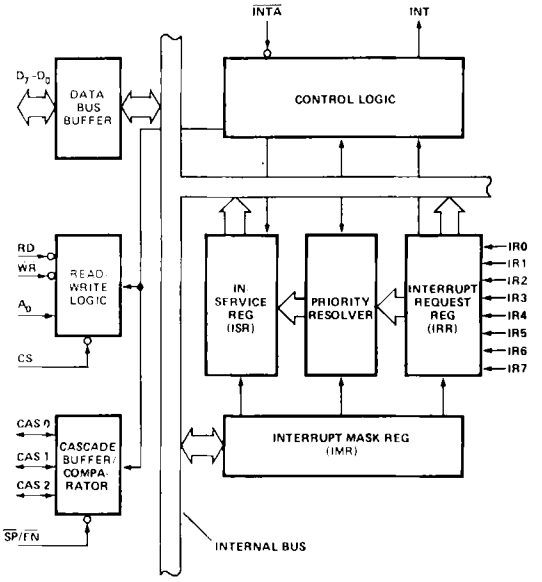
A LOW on this input enables the CPU to write control words (ICWs and OCWs) to the 8259A.

$\overline{RD}$ (READ)

A LOW on this input enables the 8259A to send the status of the Interrupt Request Register (IRR), In Service Register (ISR), the Interrupt Mask Register (IMR), or the Interrupt level onto the Data Bus.



8259A Block Diagram



8259A Block Diagram

A_0

This input signal is used in conjunction with $\overline{WR}$ and $\overline{RD}$ signals to write commands into the various command registers, as well as reading the various status registers of the chip. This line can be tied directly to one of the address lines.

THE CASCADE BUFFER/COMPARATOR

This function block stores and compares the IDs of all 8259A's used in the system. The associated three I/O pins (CAS0-2) are outputs when the 8259A is used as a master and are inputs when the 8259A is used as a slave. As a master, the 8259A sends the ID of the interrupting slave device onto the CAS0-2 lines. The slave thus selected will send its preprogrammed subroutine address onto the Data Bus during the next one or two consecutive $\overline{INTA}$ pulses. (See section "Cascading the 8259A".)

INTERRUPT SEQUENCE

The powerful features of the 8259A in a microcomputer system are its programmability and the interrupt routine addressing capability. The latter allows direct or indirect jumping to the specific interrupt routine requested without any polling of the interrupting devices. The normal sequence of events during an interrupt depends on the type of CPU being used.

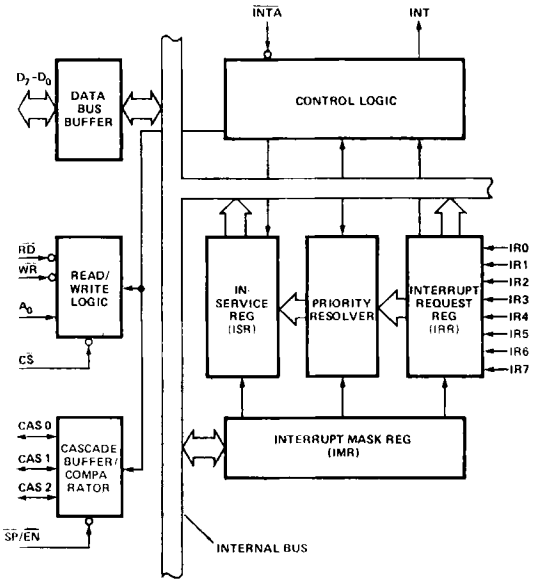
The events occur as follows in an MCS-80/85 system:

1. One or more of the INTERRUPT REQUEST lines (IR7-0) are raised high, setting the corresponding IRR bit(s).
2. The 8259A evaluates these requests, and sends an INT to the CPU, if appropriate.
3. The CPU acknowledges the INT and responds with an $\overline{INTA}$ pulse.
4. Upon receiving an $\overline{INTA}$ from the CPU group, the highest priority ISR bit is set, and the corresponding IRR bit is reset. The 8259A will also release a CALL instruction code (11001101) onto the 8-bit Data Bus through its D7-0 pins.
5. This CALL instruction will initiate two more $\overline{INTA}$ pulses to be sent to the 8259A from the CPU group.
6. These two $\overline{INTA}$ pulses allow the 8259A to release its preprogrammed subroutine address onto the Data Bus. The lower 8-bit address is released at the first $\overline{INTA}$ pulse and and the higher 8-bit address is released at the second $\overline{INTA}$ pulse.
7. This completes the 3-byte CALL instruction released by the 8259A. In the AEOI mode the ISR bit is reset at the end of the third $\overline{INTA}$ pulse. Otherwise, the ISR bit remains set until an appropriate EOI command is issued at the end of the interrupt sequence.

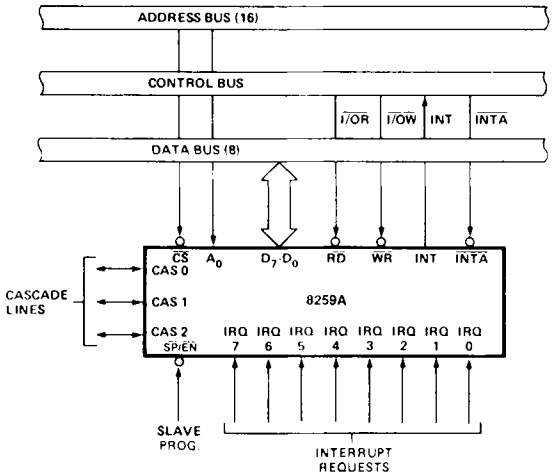
The events occurring in an MCS-86 system are the same until step 4.

4. Upon receiving an $\overline{INTA}$ from the CPU group, the highest priority ISR bit is set and the corresponding IRR bit is reset. The 8259A does not drive the Data Bus during this cycle.
5. The MCS-86 CPU will initiate a second $\overline{INTA}$ pulse. During this pulse, the 8259A releases an 8-bit pointer onto the Data Bus where it is read by the CPU.
6. This completes the interrupt cycle. In the AEOI mode the ISR bit is reset at the end of the second $\overline{INTA}$ pulse. Otherwise, the ISR bit remains set until an appropriate EOI command is issued at the end of the interrupt subroutine.

If no interrupt request is present at step 4 of either sequence (i.e., the request was too short in duration) the 8259A will issue an interrupt level 7. Both the vectoring bytes and the CAS lines will look like an interrupt level 7 was requested.



8259A Block Diagram



8259A Interface to Standard System Bus

INTERRUPT SEQUENCE OUTPUTS

MCS-80/85 SYSTEM

This sequence is timed by three $\overline{INTA}$ pulses. During the first $\overline{INTA}$ pulse the CALL opcode is enabled onto the data bus.

Content of First Interrupt Vector Byte

	D7	D6	D5	D4	D3	D2	D1	D0
CALL CODE	1	1	0	0	1	1	0	1

During the second $\overline{INTA}$ pulse the lower address of the appropriate service routine is enabled onto the data bus. When Interval = 4 bits A_5-A_7 are programmed, while A_0-A_4 are automatically inserted by the 8259A. When Interval = 8 only A_6 and A_7 are programmed, while A_0-A_5 are automatically inserted.

Content of Second Interrupt Vector Byte

IR	Interval = 4							
	D7	D6	D5	D4	D3	D2	D1	D0
7	A7	A6	A5	1	1	1	0	0
6	A7	A6	A5	1	1	0	0	0
5	A7	A6	A5	1	0	1	0	0
4	A7	A6	A5	1	0	0	0	0
3	A7	A6	A5	0	1	1	0	0
2	A7	A6	A5	0	1	0	0	0
1	A7	A6	A5	0	0	1	0	0
0	A7	A6	A5	0	0	0	0	0

IR	Interval = 8							
	D7	D6	D5	D4	D3	D2	D1	D0
7	A7	A6	1	1	1	0	0	0
6	A7	A6	1	1	0	0	0	0
5	A7	A6	1	0	1	0	0	0
4	A7	A6	1	0	0	0	0	0
3	A7	A6	0	1	1	0	0	0
2	A7	A6	0	1	0	0	0	0
1	A7	A6	0	0	1	0	0	0
0	A7	A6	0	0	0	0	0	0

During the third $\overline{INTA}$ pulse the higher address of the appropriate service routine, which was programmed as byte 2 of the initialization sequence (A_8-A_{15}), is enabled onto the bus.

Content of Third Interrupt Vector Byte

D7	D6	D5	D4	D3	D2	D1	D0
A15	A14	A13	A12	A11	A10	A9	A8

MCS-86 SYSTEM

MCS-86 mode is similar to MCS-80 mode except that only two Interrupt Acknowledge cycles are issued by the processor and no CALL opcode is sent to the processor. The first interrupt acknowledge cycle is similar to that of MCS-80/85 systems in that the 8259A uses it to internally freeze the state of the interrupts for priority resolution and as a master it issues the interrupt code on the cascade lines at the end of the $\overline{INTA}$ pulse. On this first cycle it does not issue any data to the processor and leaves its data bus buffers disabled. On the second interrupt acknowledge cycle in MCS-86 mode the master (or slave if so programmed) will send a byte of data to the processor with the acknowledged interrupt code composed as follows (note the state of the ADI mode control is ignored and A_5-A_{11} are unused in MCS-86 mode):

Content of Interrupt Vector Byte for MCS-86 System Mode

	D7	D6	D5	D4	D3	D2	D1	D0
IR7	A15	A14	A13	A12	A11	1	1	1
IR6	A15	A14	A13	A12	A11	1	1	0
IR5	A15	A14	A13	A12	A11	1	0	1
IR4	A15	A14	A13	A12	A11	1	0	0
IR3	A15	A14	A13	A12	A11	0	1	1
IR2	A15	A14	A13	A12	A11	0	1	0
IR1	A15	A14	A13	A12	A11	0	0	1
IR0	A15	A14	A13	A12	A11	0	0	0

PROGRAMMING THE 8259A

The 8259A accepts two types of command words generated by the CPU:

1. *Initialization Command Words (ICWs):* Before normal operation can begin, each 8259A in the system must be brought to a starting point — by a sequence of 2 to 4 bytes timed by $\overline{WR}$ pulses. This sequence is described in Figure 1.

2. *Operation Command Words (OCWs):* These are the command words which command the 8259A to operate in various interrupt modes. These modes are:
   a. Fully nested mode
   b. Rotating priority mode
   c. Special mask mode
   d. Polled mode

The OCWs can be written into the 8259A anytime after initialization.

INITIALIZATION

GENERAL

Whenever a command is issued with A0 = 0 and D4 = 1, this is interpreted as Initialization Command Word 1 (ICW1). ICW1 starts the initialization sequence during which the following automatically occur.

a. The edge sense circuit is reset, which means that following initialization, an interrupt request (IR) input must make a low-to-high transition to generate an interrupt.
b. The Interrupt Mask Register is cleared.
c. IR 7 input is assigned priority 7.
d. The slave mode address is set to 7.
e. Special Mask Mode is cleared and Status Read is set to IRR.
f. If IC4 = 0, then all functions selected in ICW4 are set to zero. (Non-Buffered mode*, no Auto-EOI, MCS-80/85 system).

*Note: Master/Slave in ICW4 is only used in the buffered mode.

A_0	D_4	D_3	$\overline{RD}$	$\overline{WR}$	$\overline{CS}$	INPUT OPERATION (READ)
0			0	1	0	IRR, ISR or Interrupting Level → DATA BUS (Note 1)
1			0	1	0	IMR → DATA BUS
						OUTPUT OPERATION (WRITE)
0	0	0	1	0	0	DATA BUS → OCW2
0	0	1	1	0	0	DATA BUS → OCW3
0	1	X	1	0	0	DATA BUS → ICW1
1	X	X	1	0	0	DATA BUS → OCW1, ICW2, ICW3, ICW4 (Note 2)
						DISABLE FUNCTION
X	X	X	1	1	0	DATA BUS → 3-STATE
X	X	X	X	X	1	DATA BUS → 3-STATE

Notes: 1. Selection of IRR, ISR or Interrupting Level is based on the content of OCW3 written before the READ operation.
2. On-chip sequencer logic queues these commands into proper sequence.

8259A Basic Operation

INITIALIZATION COMMAND WORDS 1 AND 2 (ICW1, ICW2)

A_5-A_{15}: *Page starting address of service routines.* In an MCS 80/85 system, the 8 request levels will generate CALLs to 8 locations equally spaced in memory. These can be programmed to be spaced at intervals of 4 or 8 memory locations, thus the 8 routines will occupy a page of 32 or 64 bytes, respectively.

The address format is 2 bytes long (A_0-A_{15}). When the routine interval is 4, A_0-A_4 are automatically inserted by the 8259A, while A_5-A_{15} are programmed externally. When the routine interval is 8, A_0-A_5 are automatically inserted by the 8259A, while A_6-A_{15} are programmed externally.

The 8-byte interval will maintain compatibility with current software, while the 4-byte interval is best for a compact jump table.

In an MCS-86 system A_{15}-A_{11} are inserted in the five most significant bits of the vectoring byte and the 8259A sets the three least significant bits according to the interrupt level. A_{10}-A_5 are ignored and ADI (Address interval) has no effect.

LTIM: If LTIM = 1, then the 8259A will operate in the level interrupt mode. Edge detect logic on the interrupt inputs will be disabled.

ADI: CALL address interval. ADI = 1 then interval = 4; ADI = 0 then interval = 8.

SNGL: Single. Means that this is the only 8259A in the system. If SNGL = 1 no ICW3 will be issued.

IC4: If this bit is set — ICW4 has to be read. If ICW4 is not needed, set IC4 = 0.

INITIALIZATION COMMAND WORD 3 (ICW3)

This word is read only when there is more than one 8259A in the system and cascading is used, in which case SNGL = 0. It will load the 8-bit slave register. The functions of this register are:

a. In the master mode (either when $\overline{SP}$ = 1, or in buffered mode when M/S = 1 in ICW4) a "1" is set for each slave in the system. The master then will release byte 1 of the call sequence (for MCS-80/85 system) and will enable the corresponding slave to release bytes 2 and 3 (for MCS-86 only byte 2) through the cascade lines.

b. In the slave mode (either when $\overline{SP}$ = 0, or if BUF = 1 and M/S = 0 in ICW4) bits 2-0 identify the slave. The slave compares its cascade input with these bits and, if they are equal, bytes 2 and 3 of the call sequence (or just byte 2 for MCS-86) are released by it on the Data Bus.

INITIALIZATION COMMAND WORD 4 (ICW4)

FNM: If FNM = 1 the fully nested mode is programmed.

BUF: If BUF = 1 the buffered mode is programmed. In buffered mode $\overline{SP}/\overline{EN}$ becomes an enable output and the master/slave determination is by M/S.

M/S: If buffered mode is selected: M/S = 1 means the 8259A is programmed to be a master, M/S = 0 means the 8259A is programmed to be a slave. If BUF = 0, M/S has no function.

AEOI: If AEOI = 1 the automatic end of interrupt mode is programmed.

μPM: Microprocessor mode: μPM = 0 sets the 8259A for MCS-80/85 system operation, μPM = 1 sets the 8259A for MCS-86 system operation.

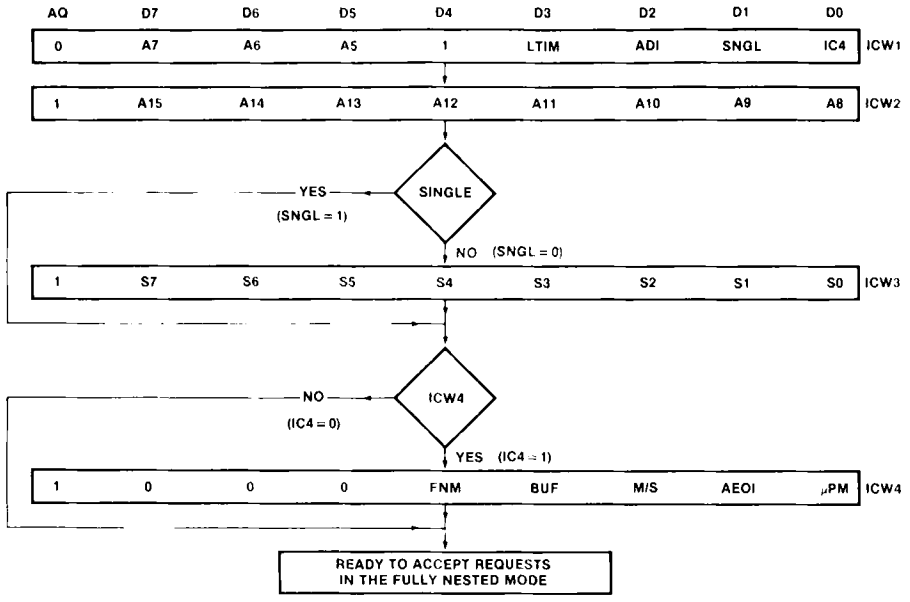
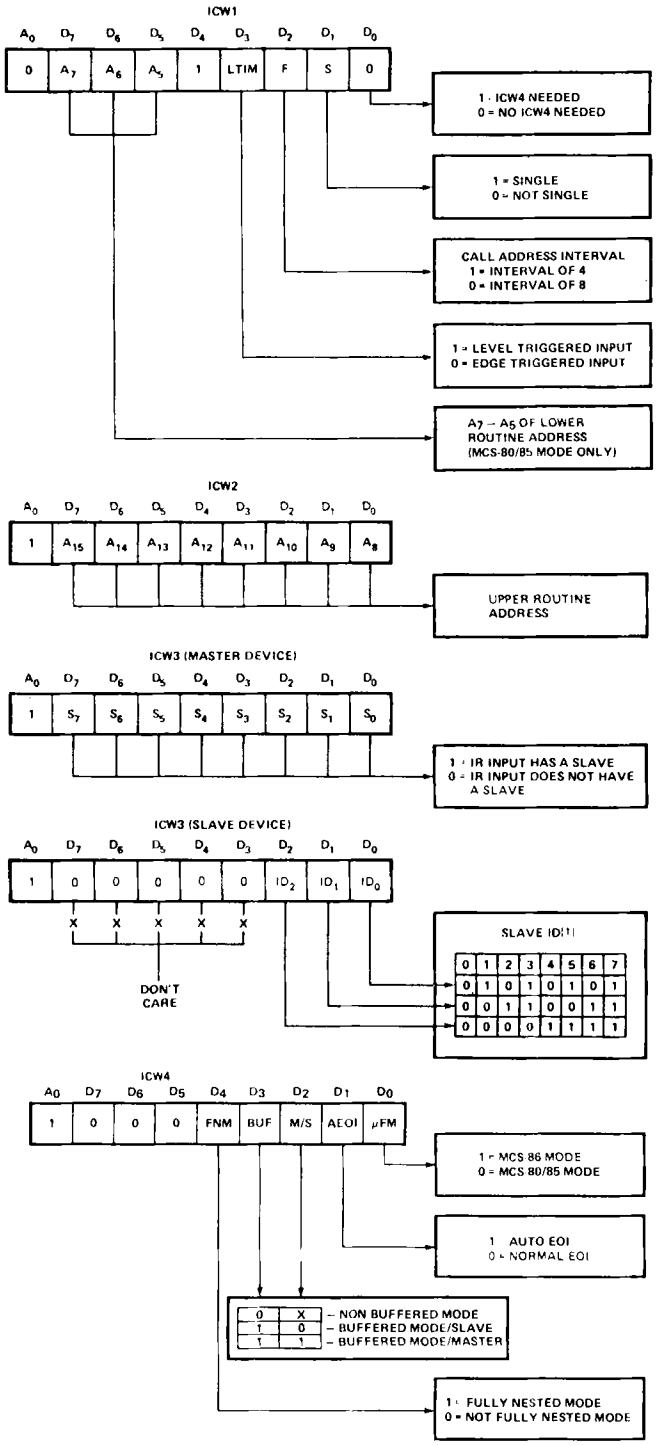


Figure 1. Initialization Sequence



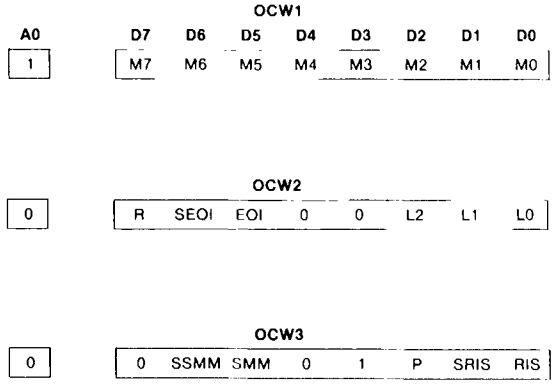
NOTE 1: SLAVED ID IS EQUAL TO THE CORRESPONDING MASTER IR INPUT.
NOTE 2: X INDICATED "DON'T CARE".

Initialization Command Word Format

OPERATION COMMAND WORDS (OCWs)

After the Initialization Command Words (ICWs) are programmed into the 8259A, the chip is ready to accept interrupt requests at its input lines. However, during the 8259A operation, a selection of algorithms can command the 8259A to operate in various modes through the Operation Command Words (OCWs).

OPERATION CONTROL WORDS (OCWs)



OPERATION CONTROL WORD 1 (OCW1)

OCW1 sets and clears the mask bits in the Interrupt Mask Register (IMR). M_7-M_0 represent the eight mask bits. M = 1 indicates the channel is masked (inhibited). M = 0 indicates the channel is enabled.

OPERATION CONTROL WORD 2 (OCW2)

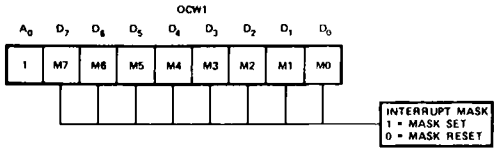
R, SEOI, EOI — These three bits control the Rotate and End of Interrupt modes and combinations of the two. A chart of these combinations can be found on the Operation Command Word Format.

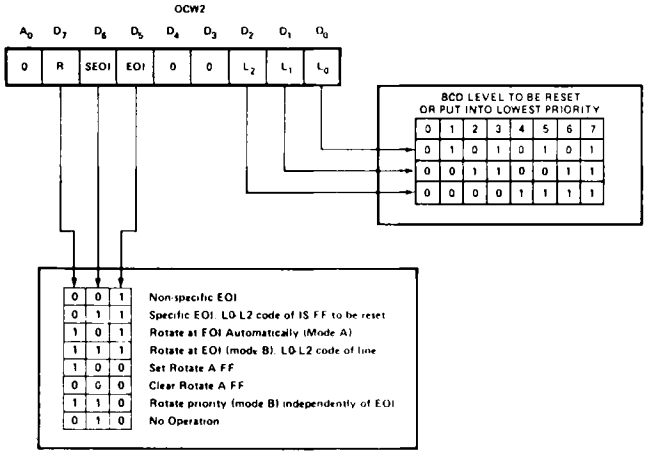
L_2, L_1, L_0 — These bits determine the interrupt level acted upon when the SEOI bit is active.

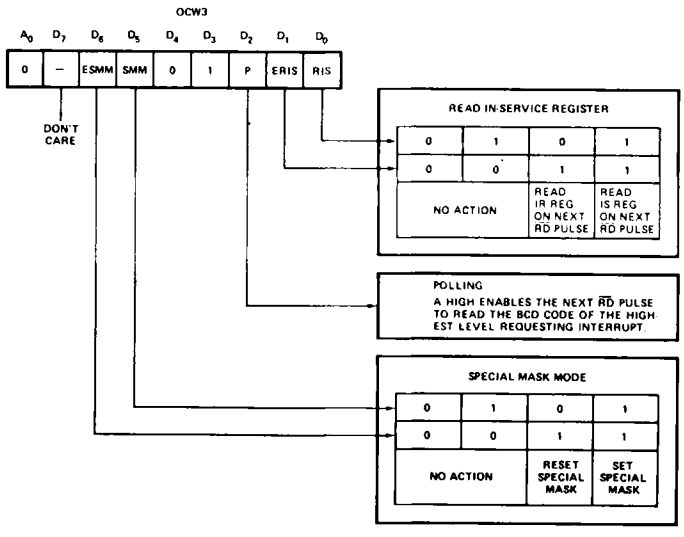
OPERATION CONTROL WORD 3 (OCW3)

ESMM — Enable Special Mask Mode. When this bit is set to 1 it enables the SMM bit to set or reset the Special Mask Mode. When ESMM = 0 the SMM bit becomes a "don't care".

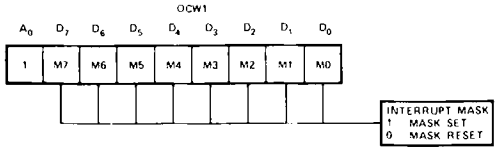
SMM — Special Mask Mode. If ESMM = 1 and SMM = 1 the 8259A will enter Special Mask Mode. If ESMM = 1 and SMM = 0 the 8259A will revert to normal mask mode. When ESMM = 0, SMM has no effect.

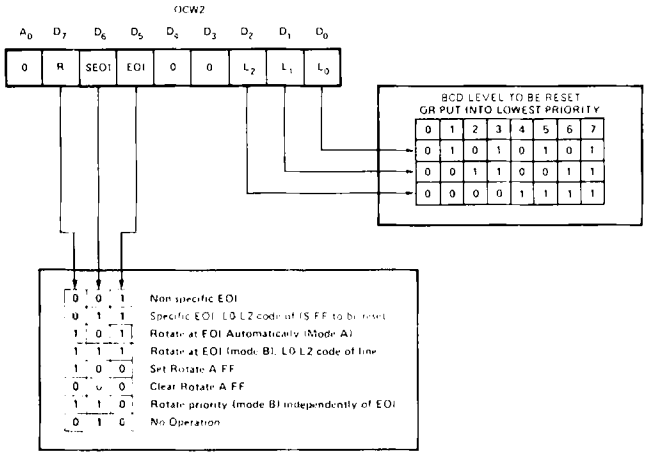


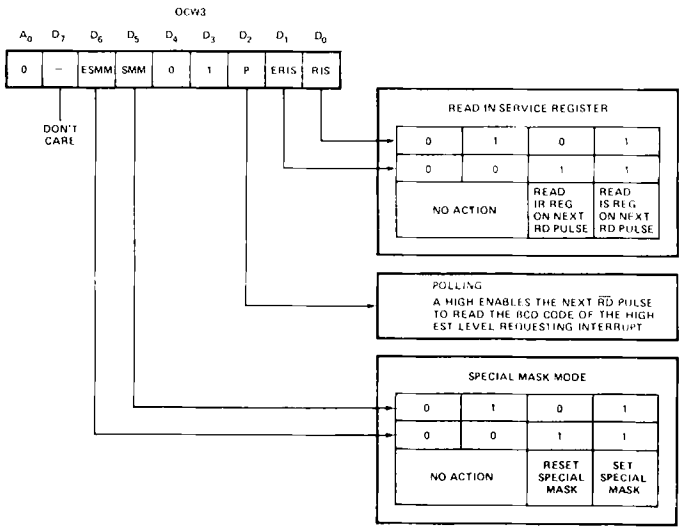




Operation Command Word Format







Operation Command Word Format

INTERRUPT MASKS

Each Interrupt Request input can be masked individually by the Interrupt Mask Register (IMR) programmed through OCW1. Each bit in the IMR masks one interrupt channel if it is set (1). Bit 0 masks IR0, Bit 1 masks IR1 and so forth. Masking an IR channel does not affect the other channels operation.

SPECIAL MASK MODE

Some applications may require an interrupt service routine to dynamically alter the system priority structure during its execution under software control. For example, the routine may wish to inhibit lower priority requests for a portion of its execution but enable some of them for another portion.

The difficulty here is that if an Interrupt Request is acknowledged and an End of Interrupt command did not reset its IS bit (i.e., while executing a service routine), the 8259A would have inhibited all lower priority requests with no easy way for the routine to enable them

That is where the Special Mask Mode comes in. In the special Mask Mode, when a mask bit is set in OCW1, it inhibits further interrupts at that level *and enables* interrupts from *all other* levels (lower as well as higher) that are not masked.

Thus, any interrupts may be selectively enabled by loading the mask register.

The special Mask Mode is set by OCW3 where: SSMM = 1, SMM = 1, and cleared where SSMM = 1, SMM = 0.

BUFFERED MODE

When the 8259A is used in a large system where bus driving buffers are required on the data bus and the cascading mode is used, there exists the problem of enabling buffers.

The buffered mode will structure the 8259A to send an enable signal on $\overline{SP}/\overline{EN}$ to enable the buffers. In this mode, whenever the 8259A's data bus outputs are enabled, the $\overline{SP}/\overline{EN}$ output becomes active.

This modification forces the use of software programming to determine whether the 8259A is a master or a slave. Bit 3 in ICW4 programs the buffered mode, and bit 2 in ICW4 determines whether it is a master or a slave.

NESTED MODE

This mode is entered after initialization unless another mode is programmed. The interrupt requests are ordered in priority from 0 through 7 (0 highest). When an interrupt is acknowledged the highest priority request is determined and its vector placed on the bus. Additionally, a bit of the Interrupt Service register (IS0-7) is set. This bit remains set until the microprocessor issues an

End of Interrupt (EOI) command immediately before returning from the service routine, or if AEOI (Automatic End of Interrupt) bit is set, until the trailing edge of the last $\overline{INTA}$. While the IS bit is set, all further interrupts of the same or lower priority are inhibited, while higher levels will generate an interrupt (which will be acknowledged only if the microprocessor internal Interrupt enable flip-flop has been re-enabled through software).

After the initialization sequence, IR0 has the highest priority and IR7 the lowest. Priorities can be changed, as will be explained, in the rotating priority mode.

THE SPECIAL FULLY NESTED MODE

This mode will be used in the case of a big system where cascading is used, and the priority has to be conserved within each slave. In this case the fully nested mode will be programmed to the master (using ICW4). This mode is similar to the normal nested mode with the following exceptions:

a. When an interrupt request from a certain slave is in service this slave is not locked out from the master's priority logic and further interrupt requests from higher priority IR's within the slave will be recognized by the master and will initiate interrupts to the processor. (In the normal nested mode a slave is masked out when its request is in service and no higher requests from the same slave can be serviced.)

b. When exiting the Interrupt Service routine the software has to check whether the interrupt serviced was the only one from that slave. This is done by sending a non-specific End of Interrupt (EOI) command to the slave and then reading its In-Service register and checking for zero. If it is empty, a non-specific EOI can be sent to the master too. If not, no EOI should be sent.

POLL

In this mode the microprocessor internal Interrupt Enable flip-flop is reset, disabling its interrupt input. Service to devices is achieved by programmer initiative using a Poll command.

The Poll command is issued by setting P = "1" in OCW3. The 8259A treats the next $\overline{RD}$ pulse to the 8259A (i.e., $\overline{RD} = 0$, $\overline{CS} = 0$) as an interrupt acknowledge, sets the appropriate IS bit if there is a request, and reads the priority level. Interrupt is frozen from $\overline{WR}$ to $\overline{RD}$.

The word enabled onto the data bus during $\overline{RD}$ is:

D7	D6	D5	D4	D3	D2	D1	D0
I	–	–	–	–	W2	W1	W0

W0-W2: Binary code of the highest priority level requesting service.

I: Equal to a "1" if there is an interrupt.

This mode is useful if there is a routine command common to several levels so that the $\overline{INTA}$ sequence is not needed (saves ROM space). Another application is to use the poll mode to expand the number of priority levels to more than 64.

END OF INTERRUPT (EOI)

The In Service (IS) bit can be reset either automatically following the trailing edge of the last in sequence $\overline{INTA}$ pulse (when AEOI bit in ICW1 is set) or by a command word that must be issued to the 8259A before returning from a service routine (EOI command). An EOI command must be issued twice, once for the master and once for the corresponding slave if slaves are in use.

There are two forms of EOI command: Specific and Non-Specific. When the 8259A is operated in modes which preserve the fully nested structure, it can determine which IS bit to reset on EOI. When a Non-Specific EOI command is issued the 8259A will automatically reset the highest IS bit of those that are set, since in the nested mode the highest IS level was necessarily the last level acknowledged and serviced.

However, when a mode is used which may disturb the fully nested structure, the 8259A may no longer be able to determine the last level acknowledged. In this case a Specific End of Interrupt (SEOI) must be issued which includes as part of the command the IS level to be reset. EOI is issued whenever E = 1, in OCW2, where L0-L2 is the binary level of the IS bit to be reset. Note that although the Rotate command can be issued together with an EOI where E = 1, it is not necessarily tied to it.

It should be noted that an IS bit that is masked by an IMR bit will not be cleared by a non-specific EOI if the 8259A is in the Special Mask Mode.

AUTOMATIC END OF INTERRUPT (AEOI) MODE

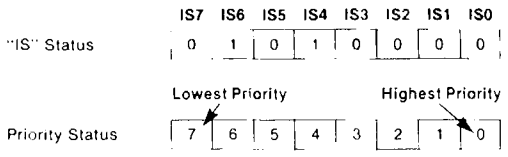
If AEOI = 1 in ICW4, then the 8259A will operate in AEOI mode continuously until reprogrammed by ICW4. In this mode the 8259A will automatically perform a non-specific EOI operation at the trailing edge of the last interrupt acknowledge pulse (third pulse in MCS-80/85, second in MCS-86). Note that from a system standpoint, this mode should be used only when a nested multilevel interrupt structure is not required within a single 8259A.

To achieve automatic rotation (Rotate Mode A) within AEOI, there is a special rotate flip-flop. It is set by OCW2 with R = 1, SEOI = *0*, E = 0, and cleared with R = 0, SEOI = 0, E = 0.

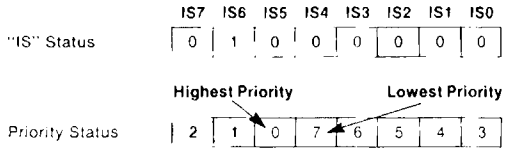
ROTATING PRIORITY MODE A (AUTOMATIC ROTATION) FOR EQUAL PRIORITY DEVICES

In some applications there are a number of interrupting devices of equal priority. In this mode a device, after being serviced, receives the lowest priority, so a device requesting an interrupt will have to wait, in the worst case until each of 7 other devices are serviced at most *once*. For example, if the priority and "in service" status is:

Before Rotate (IR4 the highest priority requiring service)



After Rotate (IR4 was serviced, all other priorities rotated correspondingly)



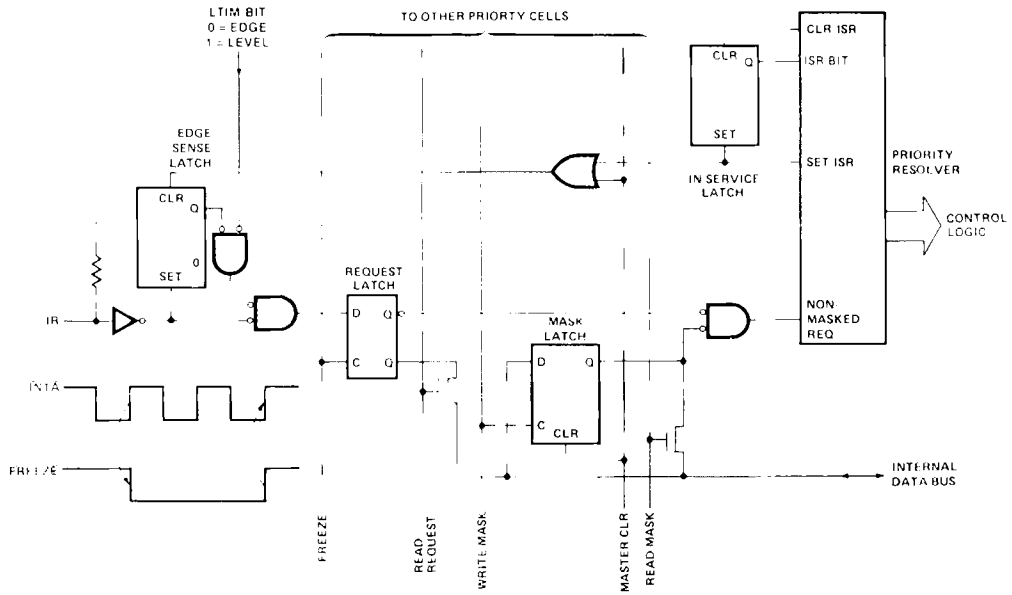
The Rotate command mode A is issued in OCW2 where: R = 1, E = 1, SEOI = 0. Internal status is updated by an End of Interrupt (EOI or AEOI) command. If R = 1, E = 0, SEOI = 0, a "Rotate-A" flip-flop is set. This is useful in AEOI, and described under Automatic End of Interrupt.

ROTATING PRIORITY MODE B (ROTATION BY SOFTWARE)

The programmer can change priorities by programming the bottom priority and thus fixing all other priorities; i.e., if IR5 is programmed as the bottom priority device, then IR6 will have the highest one.

The Rotate command is issued in OCW2 where: R = 1, SEOI = 1; L0-L2 is the binary priority level code of the bottom priority device.

Observe that in this mode internal status is updated by software control during OCW2. However, it is independent of the End of Interrupt (EOI) command (also executed by OCW2). Priority changes can be executed during an EOI command or independently.



NOTES

1. MASTER CLEAR ACTIVE ONLY DURING ICW1
2. FREEZE/ IS ACTIVE DURING $\overline{INTA}$/ AND POLL SEQUENCES ONLY
3. TRUTH TABLE FOR D LATCH

C	D	Q	OPERATION
1	D_i	D_i	FOLLOW
0	X	Q_{n-1}	HOLD

Priority Cell

LEVEL TRIGGERED MODE

This mode is programmed using bit 3 in ICW1.

If LTM = '1', an interrupt request will be recognized by a 'high' level on IR Input, and there is no need for an edge detection. The interrupt request must be removed before the EOI command is issued or the CPU interrupt is enabled to prevent a second interrupt from occurring.

The above figure shows a conceptual circuit to give the reader an understanding of the level sensitive and edge sensitive input circuitry of the 8259A. Be sure to note that the request latch is a transparent D type latch.

READING THE 8259A STATUS

The input status of several internal registers can be read to update the user information on the system. The following registers can be read by issuing a suitable OCW3 and reading with $\overline{RD}$.

Interrupt Mask Register: 8-bit register whose content specifies the interrupt request lines being masked. acknowledged. The highest request level is reset from the IRR when an interrupt is acknowledged. (Not affected by IMR.)

In-Service Register (ISR): 8-bit register which contains the priority levels that are being serviced. The ISR is updated when an End of Interrupt command is issued.

Interrupt Mask Register: 8-bit register which contains the interrupt request lines which are masked.

The IRR can be read when, prior to the $\overline{RD}$ pulse, a $\overline{WR}$ pulse is issued with OCW3 (ERIS = 1, RIS = 0.)

The ISR can be read in a similar mode when ERIS = 1, RIS = 1 in the OCW3.

There is no need to write an OCW3 before every status read operation, as long as the status read corresponds with the previous one; i.e., the 8259A "remembers" whether the IRR or ISR has been previously selected by the OCW3.

After initialization the 8259A is set to IRR.

For reading the IMR, no OCW3 is needed. The output data bus will contain the IMR whenever $\overline{RD}$ is active and A0 = 1.

Polling overrides status read when P = 1, ERIS = 1 in OCW3.

SUMMARY OF 8259A INSTRUCTION SET

Inst. #	Mnemonic		A0	D7	D6	D5	D4	D3	D2	D1	D0	Operation Description	
1	ICW1	A	0	A7	A6	A5	1	0	1	1	0		Format = 4, single, edge triggered
2	ICW1	B	0	A7	A6	A5	1	1	1	1	0		Format = 4, single, level triggered
3	ICW1	C	0	A7	A6	A5	1	0	1	0	0	Byte 1 Initialization	Format = 4, not single, edge triggered
4	ICW1	D	0	A7	A6	A5	1	1	1	0	0		Format = 4, not single, level triggered
5	ICW1	E	0	A7	A6	0	1	0	0	1	0	No ICW4 Required	Format = 8, single, edge triggered
6	ICW1	F	0	A7	A6	0	1	1	0	1	0		Format = 8, single, level triggered
7	ICW1	G	0	A7	A6	0	1	0	0	0	0		Format = 8, not single, edge triggered
8	ICW1	H	0	A7	A6	0	1	1	0	0	0		Format = 8, not single, level triggered
9	ICW1	I	0	A7	A6	A5	1	0	1	1	1		Format = 4, single, edge triggered
10	ICW1	J	0	A7	A6	A5	1	1	1	1	1		Format = 4, single, level triggered
11	ICW1	K	0	A7	A6	A5	1	0	1	0	1	Byte 1 Initialization	Format = 4, not single, edge triggered
12	ICW1	L	0	A7	A6	A5	1	1	1	0	1		Format = 4, not single, level triggered
13	ICW1	M	0	A7	A6	0	1	0	0	1	1	ICW4 Required	Format = 8, single, edge triggered
14	ICW1	N	0	A7	A6	0	1	1	0	1	1		Format = 8, single, level triggered
15	ICW1	O	0	A7	A6	0	1	0	0	0	1		Format = 8, not single, edge triggered
16	ICW1	P	0	A7	A6	0	1	1	0	0	1		Format = 8, not single, level triggered
17	ICW2		1	A15	A14	A13	A12	A11	A10	A9	A8	Byte 2 initialization	
18	ICW3	M	1	S7	S6	S5	S4	S3	S2	S1	S0	Byte 3 initialization — master	
19	ICW3	S	1	0	0	0	0	0	S2	S1	S0	Byte 3 initialization — slave	
20	ICW4	A	1	0	0	0	0	0	0	0	0	No action, redundant	
21	ICW4	B	1	0	0	0	0	0	0	0	1	Non-buffered mode, no AEOI, MCS-86	
22	ICW4	C	1	0	0	0	0	0	0	1	0	Non-buffered mode, AEOI, MCS-80/85	
23	ICW4	D	1	0	0	0	0	0	0	1	1	Non-buffered mode, AEOI, MCS-86	
24	ICW4	E	1	0	0	0	0	0	1	0	0	No action, redundant	
25	ICW4	F	1	0	0	0	0	0	1	0	1	Non-buffered mode, no AEOI, MCS-86	
26	ICW4	G	1	0	0	0	0	0	1	1	0	Non-buffered mode, AEOI, MCS-80/85	
27	ICW4	H	1	0	0	0	0	0	1	1	1	Non-buffered mode, AEOI, MCS-86	
28	ICW4	I	1	0	0	0	0	1	0	0	0	Buffered mode, slave, no AEOI, MCS-80/85	
29	ICW4	J	1	0	0	0	0	1	0	0	1	Buffered mode, slave, no AEOI, MCS-86	
30	ICW4	K	1	0	0	0	0	1	0	1	0	Buffered mode, slave, AEOI, MCS-80/85	
31	ICW4	L	1	0	0	0	0	1	0	1	1	Buffered mode, slave, AEOI, MCS-86	
32	ICW4	M	1	0	0	0	0	1	1	0	0	Buffered mode, master, no AEOI, MCS-80/85	
33	ICW4	N	1	0	0	0	0	1	1	0	1	Buffered mode, master, no AEOI, MCS-86	
34	ICW4	O	1	0	0	0	0	1	1	1	0	Buffered mode, master, AEOI, MCS-80/85	
35	ICW4	P	1	0	0	0	0	1	1	1	1	Buffered mode, master, AEOI, MCS-86	
36	ICW4	NA	1	0	0	0	1	0	0	0	0	Fully nested mode, MCS-80, non-buffered, no AEOI	
37	ICW4	NB	1	0	0	0	1	0	0	0	1	ICW4 NB through ICW4 ND are identical to ICW4 B through ICW4 D with the addition of Fully Nested Mode	
38	ICW4	NC	1	0	0	0	1	0	0	1	0		
39	ICW4	ND	1	0	0	0	1	0	0	1	1		
40	ICW4	NE	1	0	0	0	1	0	1	0	0	Fully Nested Mode, MCS-80/85, non-buffered, no AEOI	
41	ICW4	NF	1	0	0	0	1	0	1	0	1	ICW4 NF through ICW4 NP are identical to ICW4 F through ICW4 P with the addition of Fully Nested Mode	
42	ICW4	NG	1	0	0	0	1	0	1	1	0		
43	ICW4	NH	1	0	0	0	1	0	1	1	1		
44	ICW4	NI	1	0	0	0	1	1	0	0	0		
45	ICW4	NJ	1	0	0	0	1	1	0	0	1		
46	ICW4	NK	1	0	0	0	1	1	0	1	0		
47	ICW4	NL	1	0	0	0	1	1	0	1	1		
48	ICW4	NM	1	0	0	0	1	1	1	0	0		
49	ICW4	NN	1	0	0	0	1	1	1	0	1		
50	ICW4	NO	1	0	0	0	1	1	1	1	0		
51	ICW4	NP	1	0	0	0	1	1	1	1	1		
36	OCW1		1	M7	M6	M5	M4	M3	M2	M1	M0	Load mask register, read mask register	
37	OCW2	E	0	0	0	1	0	0	0	0	0	Non-specific EOI	
38	OCW2	SE	0	0	1	1	0	0	L2	L1	L0	Specific EOI, L0–L2 code of IS FF to be reset	
39	OCW2	RE	0	1	0	1	0	0	0	0	0	Rotate at EOI Automatically (Mode A)	
40	OCW2	RSE	0	1	1	1	0	0	L2	L1	L0	Rotate at EOI (mode B). L0–L2 code of line	
41	OCW2	R	0	1	0	0	0	0	0	0	0	Set Rotate A FF	
42	OCW2	CR	0	0	0	0	0	0	0	0	0	Clear Rotate A FF	
43	OCW2	RS	0	1	1	0	0	0	L2	L1	L0	Rotate priority (mode B) independently of EOI	
44	OCW3	P	0	0	0	0	0	1	1	0	0	Poll mode	
45	OCW3	RIS	0	0	0	0	0	1	0	1	1	Read IS register	

SUMMARY OF 8259A INSTRUCTION SET (Cont.)

Inst. #	Mnemonic	A0	D7	D6	D5	D4	D3	D2	D1	D0	Operation Description
46	OCW3 RR	0	0	0	0	0	1	0	1	0	Read request register
47	OCW3 SM	0	0	1	1	0	1	0	0	0	Set special mask mode
48	OCW3 RSM	0	0	1	0	0	1	0	0	0	Reset special mask mode

Note: 1. In the master mode SP pin = 1, in slave mode SP = 0

Cascading

The 8259A can be easily interconnected in a system of one master with up to eight slaves to handle up to 64 priority levels.

A typical MCS-80/85 system is shown in Figure 2. The master controls, through the 3 line cascade bus, which one of the slaves will release the corresponding address.

As shown in Figure 2, the slave interrupt outputs are connected to the master interrupt request inputs. When a slave request line is activated and afterwards acknowledged, the master will enable the corresponding slave to release the device routine address during bytes 2 and 3 of $\overline{INTA}$. (Byte 2 only for MCS-86).

The cascade bus lines are normally low and will contain the slave address code from the trailing edge of the first $\overline{INTA}$ pulse to the trailing edge of the third pulse. It is obvious that each 8259A in the system must follow a separate initialization sequence and can be programmed to work in a different mode. An EOI command must be issued twice: once for the master and once for the corresponding slave. An address decoder is required to activate the Chip Select ($\overline{CS}$) input of each 8259A.

The cascade lines of the Master 8259A are activated for any interrupt input, even if no slave is connected to that input.

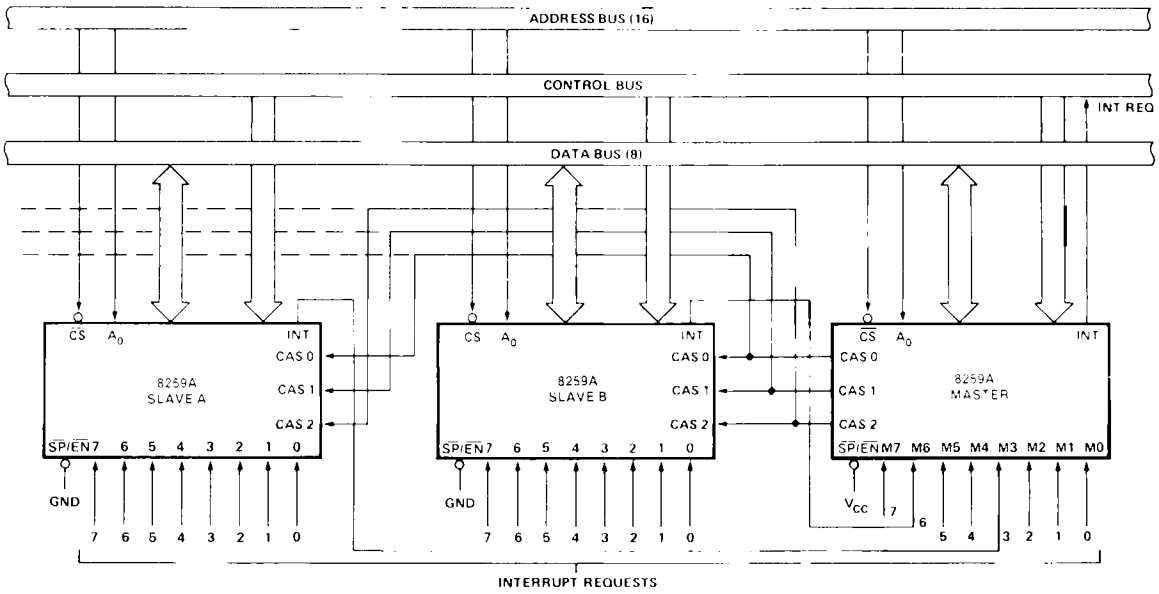


Figure 2. Cascading the 8259A

PIN FUNCTIONS

Name	I/O	Pin #	Function
V_{CC}		28	+5V supply.
GND		14	Ground.
D_{0-7}	I/O	11-4	Bidirectional data bus, used for: a) programming the mode of the 8259A (programming is done by software); b) the microprocessor can read the status of the 8259A; c) the 8259A will send vectoring data to the microprocessor when an interrupt is acknowledged.
IR_{0-7}	I	18-25	Interrupt Requests: These are asynchronous inputs. A positive-going edge will generate an interrupt request. Thus a request can be generated by raising the line and holding it high until acknowledged, or by a negative pulse. In level triggered mode, no edge is required. These lines are active HIGH.
$\overline{RD}$	I	3	Read (generally from 8228 in MCS-80 system or from 8086 in MCS-86 system).
$\overline{WR}$	I	2	Write (generally from 8228 in MCS-80 sytem or from 8086 in MCS-86 system).
$\overline{INTA}$	I	26	Interrupt Acknowledge (generally from 8228 in MCS-80 system, 8086 in MCS-86 system). The 8288 generates three distinct $\overline{INTA}$ pulses when a CALL is inserted, the 8086 produces two distinct $\overline{INTA}$ pulses during an interrupt cycle.
$\overline{CS}$	I	1	Chip Select: $\overline{RD}$ and $\overline{WR}$ are enabled by Chip Select, whereas Interrupt Acknowledge is independent of Chip Select.
A0	I	27	Usually the least significant bit of the microprocessor address output. When A0 = 1 the Interrupt Mask Register can be loaded or read. When A0 = 0 the 8259A mode can be programmed or its status can be read. $\overline{CS}$ is active LOW.
INT	O	17	Goes directly to the microprocessor interrrupt input. This output will have high V_{OH} to match the 8080 3.3V V_{IH}. INT is active HIGH.
C0-C2	I/O	12 13 15	Three cascade lines, outputs in master mode and inputs in slave mode. The master issues the binary code of the acknowledged interrupt level on these lines. Each slave compares this code with its own.
$\overline{SP}/\overline{EN}$	I/O	16	$\overline{SP}/\overline{EN}$ is a dual function pin. In the buffered mode $\overline{SP}/\overline{EN}$ is used to enable bus transceivers ($\overline{EN}$). In the non-buffered mode $\overline{SP}/\overline{EN}$ determines if this 8259A is a master or a slave. If $\overline{SP}$ = 1 the 8259A is master; $\overline{SP}$ = 0 indicates a slave.

ABSOLUTE MAXIMUM RATINGS*

Ambient Temperature Under Bias ..... −40°C to 85°C
Storage Temperature ..... −65°C to +150°C
Voltage On Any Pin
With Respect to Ground ..... −0.5V to +7V
Power Dissipation ..... 1 Watt

COMMENT
Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

D.C. CHARACTERISTICS

T_A = 0°C to 70°C V_{CC} = 5V ± 5% (8259A-8) V_{CC} = 5V ± 10% (8259A)

Symbol	Parameter	Min.	Max.	Units	Test Conditions
V_{IL}	Input Low Voltage	−.5	.8	V	
V_{IH}	Input High Voltage	2.0	V_{CC} + .5V	V	
V_{OL}	Output Low Voltage		.45	V	I_{OL} = 2.2 mA
V_{OH}	Output High Voltage	2.4		V	I_{OH} = −400 μA
$V_{OH(INT)}$	Interrupt Output High Voltage	3.5 2.4		V V	I_{OH} = −100 μA I_{OH} = −400 μA
I_{LI}	Input Load Current		10	μA	V_{IN} = V_{CC} to 0V
I_{LOL}	Output Leakage Current		−10	μA	V_{OUT} = 0.45V
I_{LOH}	Output Leakage Current		10	μA	V_{OUT} = V_{CC}
I_{CC}	V_{CC} Supply Current		85	mA	

8259A A.C. CHARACTERISTICS

$T_A = 0°C$ to $70°C$ $V_{CC} = 5V \pm 5\%$ (8259A-8) $V_{CC} = 5V \pm 10\%$ (8259A)

TIMING REQUIREMENTS

Symbol	Parameter	8259A-8 Min.	8259A-8 Max.	8259A Min.	8259A Max.	Units	Test Conditions
TAHRL	A0/$\overline{CS}$ Setup to $\overline{RD}$/$\overline{INTA}$↓	50		0		ns	
TRHAX	A0/$\overline{CS}$ Hold after $\overline{RD}$/$\overline{INTA}$↑	5		0		ns	
TRLRH	$\overline{RD}$ Pulse Width	420		235		ns	
TAHWL	A0/$\overline{CS}$ Setup to$\overline{WR}$↓	50		0		ns	
TWHAX	A0/$\overline{CS}$ Hold after $\overline{WR}$↑	20		0		ns	
TWLWH	$\overline{WR}$ Pulse Width	400		290		ns	
TDVWH	Data Setup to $\overline{WR}$↑	300		240		ns	
TWHDX	Data Hold after $\overline{WR}$↑	40		0		ns	
TJLJH	Interrupt Request Width (Low)	100		100		ns	See Note 1
TCVIAH	Cascade Setup to Second or Third $\overline{INTA}$↓ (Slave Only)	55		55		ns	
TRHRL	End of $\overline{RD}$ to Next Command	160		160		ns	
TWHRL	End of $\overline{WR}$ to Next Command	190		190		ns	

Note: 1. This is the low time required to clear the input latch in the edge triggered mode.

TIMING RESPONSES

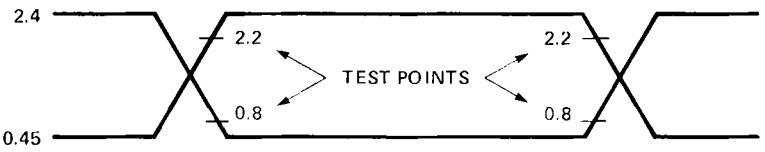
Symbol	Parameter	8259A-8 Min.	8259A-8 Max.	8259A Min.	8259A Max.	Units	Test Conditions
TRLDV	Data Valid from $\overline{RD}$/$\overline{INTA}$↓		300		200	ns	C of Data Bus = 100 pF
TRHDZ	Data Float after $\overline{RD}$/$\overline{INTA}$↑	20	200		100	ns	C of Data Bus
TJHIH	Interrupt Output Delay		400		350	ns	Max. test C = 100 pF Min. test C = 15 pF
TIAHCV	Cascade Valid from First $\overline{INTA}$↓ (Master Only)		565		565	ns	C_{INT} = 100 pF
TRLEL	Enable Active from $\overline{RD}$↓ or $\overline{INTA}$↓		160		125	ns	$C_{CASCADE}$ = 100 pF
TRHEH	Enable Inactive from $\overline{RD}$↑ or $\overline{INTA}$↑		325		150	ns	
TAHDV	Data Valid from Stable Address		350		200	ns	
TCVDV	Cascade Valid to Valid Data		300		300	ns	

CAPACITANCE

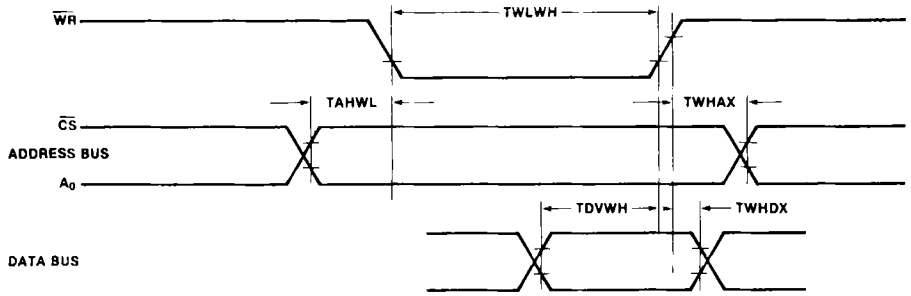
$T_A = 25°C$; $V_{CC} = GND = 0V$

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
C_{IN}	Input Capacitance			10	pF	fc = 1 MHz
$C_{I/O}$	I/O Capacitance			20	pF	Unmeasured pins returned to V_{SS}

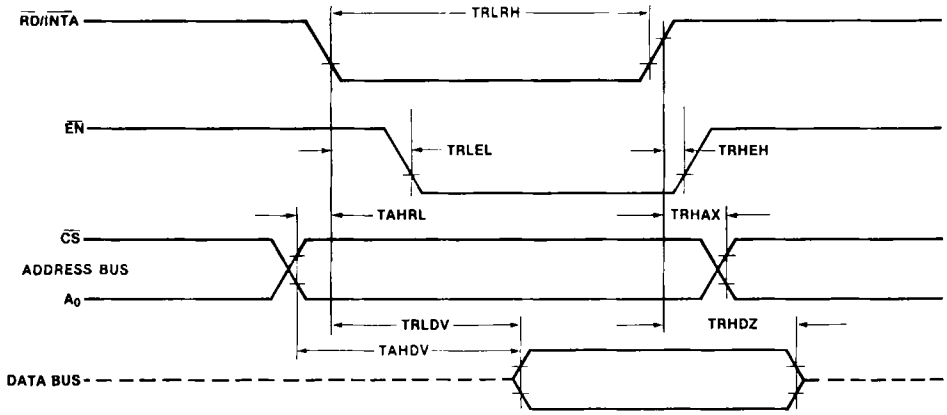
Input Waveforms for A.C. Tests



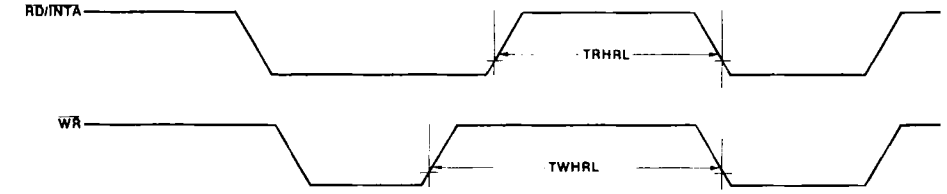
WRITE MODE



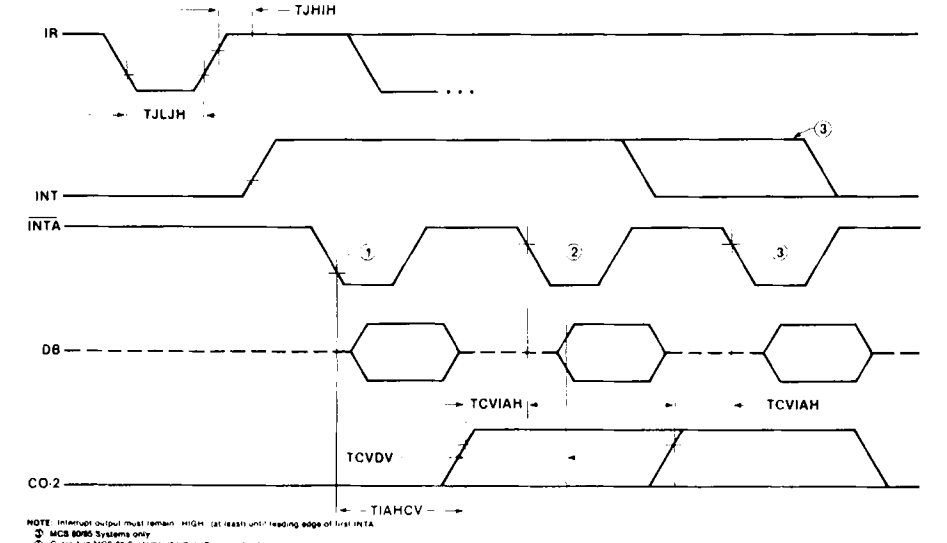
READ/INTA MODE



OTHER TIMING



INTA SEQUENCE



NOTE: Interrupt output must remain HIGH (at least until leading edge of first INTA
① MCS 80/85 Systems only
② Cycle 1 in MCS 86 Systems the Data Bus is not active

MOTOROLA

MC6821
(1.0 MHz)
MC68A21
(1.5 MHz)
MC68B21
(2.0 MHz)

MOS

(N-CHANNEL, SILICON-GATE, DEPLETION LOAD)

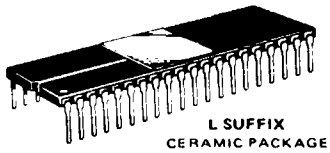
PERIPHERAL INTERFACE ADAPTER

PERIPHERAL INTERFACE ADAPTER (PIA)

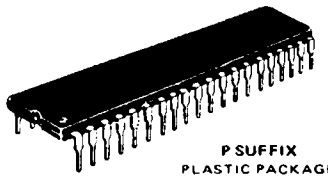
The MC6821 Peripheral Interface Adapter provides the universal means of interfacing peripheral equipment to the MC6800 Microprocessing Unit (MPU). This device is capable of interfacing the MPU to peripherals through two 8-bit bidirectional peripheral data buses and four control lines. No external logic is required for interfacing to most peripheral devices.

The functional configuration of the PIA is programmed by the MPU during system initialization. Each of the peripheral data lines can be programmed to act as an input or output, and each of the four control/interrupt lines may be programmed for one of several control modes. This allows a high degree of flexibility in the over-all operation of the interface.

- 8-Bit Bidirectional Data Bus for Communication with the MPU
- Two Bidirectional 8-Bit Buses for Interface to Peripherals
- Two Programmable Control Registers
- Two Programmable Data Direction Registers
- Four Individually-Controlled Interrupt Input Lines; Two Usable as Peripheral Control Outputs
- Handshake Control Logic for Input and Output Peripheral Operation
- High-Impedance 3-State and Direct Transistor Drive Peripheral Lines
- Program Controlled Interrupt and Interrupt Disable Capability
- CMOS Drive Capability on Side A Peripheral Lines
- Two TTL Drive Capability on All A and B Side Buffers
- TTL-Compatible
- Static Operation

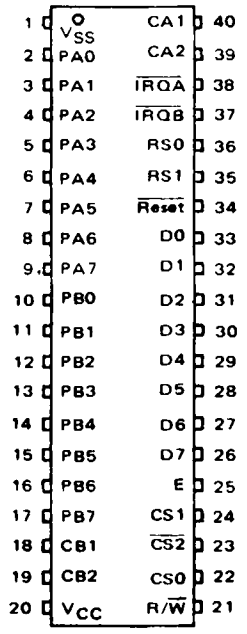


L SUFFIX
CERAMIC PACKAGE
CASE 715



P SUFFIX
PLASTIC PACKAGE
CASE 711

PIN ASSIGNMENT



ORDERING INFORMATION

Speed	Device	Temperature Range
1.0 MHz	MC6821P, L	0 to +70°C
	MC6821CP, CL	-40 to +85°C
MIL-STD-883B MIL-STD-883C	MC6821BQCS MC6821CQCS	- 55 to +125°C
1.5 MHz	MC68A21P, L	0 to +70°C
	MC68A21CP, CL	-40 to +85°C
2.0 MHz	MC68B21P, L	0 to +70°C

MC6821

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Supply Voltage	V_{CC}	-0.3 to +7.0	Vdc
Input Voltage	V_{in}	-0.3 to +7.0	Vdc
Operating Temperature Range MC6821, MC68A21, MC68B21 MC6821C, MC68A21C MC6821CQCS, MC6821BQCS	T_A	T_L to T_H 0 to 70 -40 to 85 -55 to 125	 °C °C °C
Storage Temperature Range	T_{stg}	-55 to +150	°C
Thermal Resistance	θ_{JA}	82.5	°C/W

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance.

ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 V ±5%, V_{SS} = 0, T_A = T_L to T_H unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
BUS CONTROL INPUTS (R/$\overline{W}$, Enable, $\overline{Reset}$, RS0, RS1, CS0, CS1, $\overline{CS2}$)					
Input High Voltage	V_{IH}	V_{SS} + 2.0	–	V_{CC}	Vdc
Input Low Voltage	V_{IL}	V_{SS} - 0.3	–	V_{SS} + 0.8	Vdc
Input Leakage Current (V_{in} = 0 to 5.25 Vdc)	I_{in}	–	1.0	2.5	μAdc
Capacitance (V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	C_{in}	–	–	7.5	pF
INTERRUPT OUTPUTS ($\overline{IRQA}$, $\overline{IRQB}$)					
Output Low Voltage (I_{Load} = 3.2 mAdc)	V_{OL}	–	–	V_{SS} + 0.4	Vdc
Output Leakage Current (Off State) (V_{OH} = 2.4 Vdc)	I_{LOH}	–	1.0	10	μAdc
Capacitance (V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	C_{out}	–	–	5.0	pF
DATA BUS (D0-D7)					
Input High Voltage	V_{IH}	V_{SS} + 2.0	–	V_{CC}	Vdc
Input Low Voltage	V_{IL}	V_{SS} - 0.3	–	V_{SS} + 0.8	Vdc
Three-State (Off State) Input Current (V_{in} = 0.4 to 2.4 Vdc)	I_{TSI}	–	2.0	10	μAdc
Output High Voltage (I_{Load} = -205 μAdc)	V_{OH}	V_{SS} + 2.4	–	–	Vdc
Output Low Voltage (I_{Load} = 1.6 mAdc)	V_{OL}	–	–	V_{SS} + 0.4	Vdc
Capacitance (V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	C_{in}	–	–	12.5	pF
PERIPHERAL BUS (PA0-PA7, PB0-PB7, CA1, CA2, CB1, CB2)					
Input Leakage Current (V_{in} = 0 to 5.25 Vdc) R/$\overline{W}$, $\overline{Reset}$, RS0, RS1, CS0, CS1, $\overline{CS2}$, CA1, CB1, Enable	I_{in}	–	1.0	2.5	μAdc
Three-State (Off State) Input Current (V_{in} = 0.4 to 2.4 Vdc) PB0-PB7, CB2	I_{TSI}	–	2.0	10	μAdc
Input High Current (V_{IH} = 2.4 Vdc) PA0-PA7, CA2	I_{IH}	-200	-400	–	μAdc
Darlington Drive Current V_O = 1.5 Vdc PB0-PB7,CB2	I_{OH}	-1.0	–	-10	mAdc
Input Low Current (V_{IL} = 0.4 Vdc) PA0-PA7, CA2	I_{IL}	–	-1.3	-2.4	mAdc
Output High Voltage (I_{Load} = -200 μAdc) PA0-P7, PB0-PB7, CA2, CB2 (I_{Load} = -10 μAdc) PA0-PA7, CA2	V_{OH}	 V_{SS} + 2.4 V_{CC} - 1.0	 – –	 – –	Vdc
Output Low Voltage (I_{Load} = 3.2 mAdc)	V_{OL}	–	–	V_{SS} + 0.4	Vdc
Capacitance (V_{in} = 0, T_A = 25°C, f = 1.0 MHz)	C_{in}	–	–	10	pF
POWER REQUIREMENTS					
Power Dissipation	P_D	–	–	550	mW

MC6821

BUS TIMING CHARACTERISTICS (V_{CC} = 5.0 V ±5%, V_{SS} = 0, T_A = T_L to T_H unless otherwise specified.)

Characteristic	Symbol	MC6821		MC68A21		MC68B21		Unit	Ref. Fig. No.
		Min	Max	Min	Max	Min	Max		
Enable Cycle Time	t_{cycE}	1000	–	666	–	500	–	ns	1
Enable Pulse Width, High	PW_{EH}	450	–	280	–	220	–	ns	1
Enable Pulse Width, Low	PW_{EL}	430	–	280	–	210	–	ns	1
Enable Pulse Rise and Fall Times	t_{Er}, t_{Ef}	–	25	–	25	–	25	ns	1
Setup Time, Address and R/W valid to Enable positive transition	t_{AS}	160	–	140	–	70	–	ns	2, 3
Address Hold Time	t_{AH}	10	–	10	–	10	–	ns	2, 3
Data Delay Time, Read	t_{DDR}	–	320	–	220	–	180	ns	2, 4
Data Hold Time, Read	t_{DHR}	10	–	10	–	10	–	ns	2, 4
Data Setup Time, Write	t_{DSW}	195	–	80	–	60	–	ns	3, 4
Data Hold Time, Write	t_{DHW}	10	–	10	–	10	–	ns	3, 4

FIGURE 1 – ENABLE SIGNAL CHARACTERISTICS

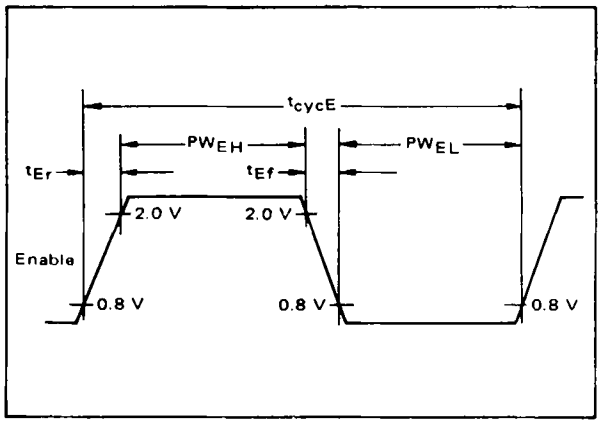


FIGURE 2 – BUS READ TIMING CHARACTERISTICS
(Read Information from PIA)

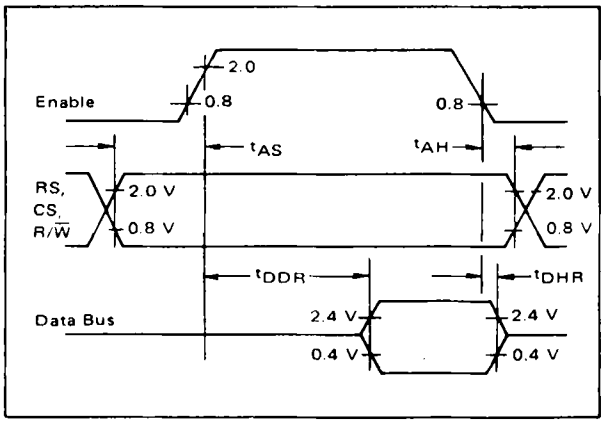


FIGURE 3 – BUS WRITE TIMING CHARACTERISTICS
(Write Information into PIA)

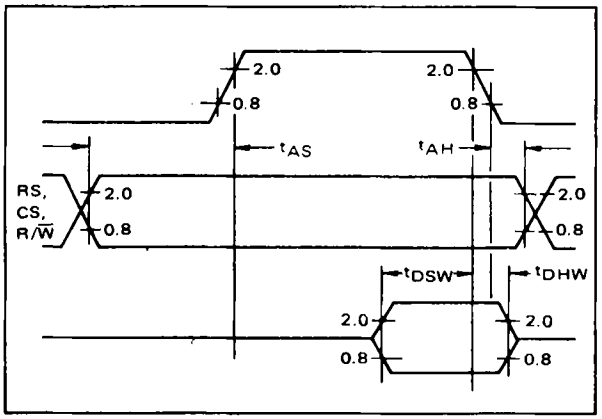
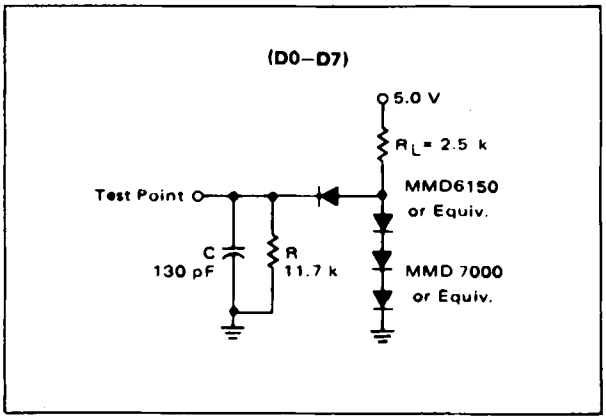


FIGURE 4 – BUS TIMING TEST LOADS



MC6821

PERIPHERAL TIMING CHARACTERISTICS (V_{CC} = 5.0 V ±5%, V_{SS} = 0 V, $T_A = T_L$ to T_H unless otherwise specified.)

Characteristic	Symbol	MC6821		MC68A21		MC68B21		Unit	Reference Fig. No.
		Min	Max	Min	Max	Min	Max		
Peripheral Data Setup Time	t_{PDSU}	200	–	135	–	100	–	ns	8
Peripheral Data Hold Time	t_{PDH}	0	–	0	–	0	–	ns	8
Delay Time, Enable negative transition to CA2 negative transition	t_{CA2}	–	1.0	–	0.670	–	0.500	µs	5, 9, 10
Delay Time, Enable negative transition to CA2 positive transition	t_{RS1}	–	1.0	–	0.670	–	0.500	µs	5, 9
Rise and Fall Times for CA1 and CA2 input signals	t_r, t_f	–	1.0	–	1.0	–	1.0	µs	5, 10
Delay Time from CA1 active transition to CA2 positive transition	t_{RS2}	–	2.0	–	1.35	–	1.0	µs	5, 10
Delay Time, Enable negative transition to Peripheral Data Valid	t_{PDW}	–	1.0	–	0.670	–	0.5	µs	5, 11, 12
Delay Time, Enable negative transition to Peripheral CMOS Data Valid PA0-PA7, CA2	t_{CMOS}	–	2.0	–	1.35	–	1.0	µs	6, 11
Delay Time, Enable positive transition to CB2 negative transition	t_{CB2}	–	1.0	–	0.670	–	0.5	µs	5, 13, 14
Delay Time, Peripheral Data Valid to CB2 negative transition	t_{DC}	20	–	20	–	20	–	ns	5, 12
Delay Time, Enable positive transition to CB2 positive transition	t_{RS1}	–	1.0	–	0.670	–	0.5	µs	5, 13
Peripheral Control Output Pulse Width, CA2/CB2	PW_{CT}	550	–	550	–	500	–	ns	5, 13
Rise and Fall Time for CB1 and CB2 input signals	t_r, t_f	–	1.0	–	1.0	–	1.0	µs	14
Delay Time, CB1 active transition to CB2 positive transition	t_{RS2}	–	2.0	–	1.35	–	1.0	µs	5, 14
Interrupt Release Time, $\overline{IRQA}$ and $\overline{IRQB}$	t_{IR}	–	1.60	–	1.10	–	0.85	µs	7, 16
Interrupt Response Time	t_{RS3}	–	1.0	–	1.0	–	1.0	µs	7, 15
Interrupt Input Pulse Width	PW_I	500	–	500	–	500	–	ns	15
Reset Low Time*	t_{RL}	1.0	–	0.66	–	0.5	–	µs	17

*The Reset line must be high a minimum of 1.0 µs before addressing the PIA.

FIGURE 5 – TTL EQUIV. TEST LOAD

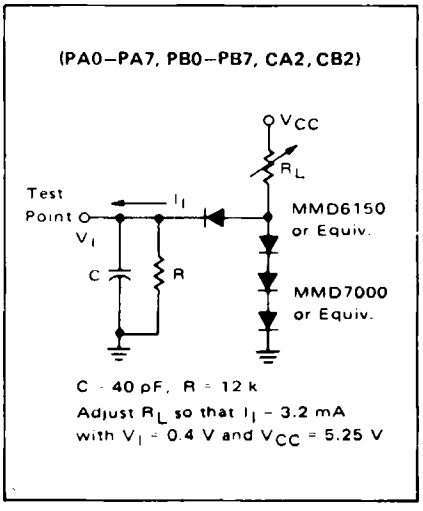


FIGURE 6 – CMOS EQUIV. TEST LOAD

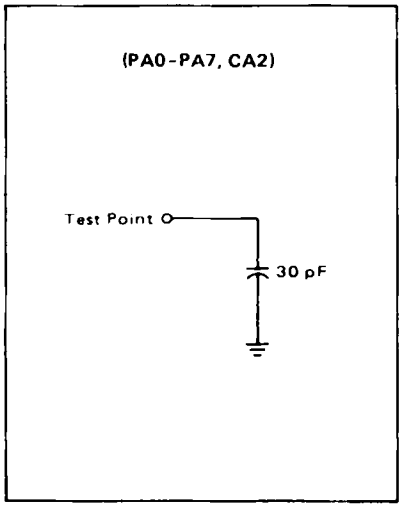


FIGURE 7 – NMOS EQUIV. TEST LOAD

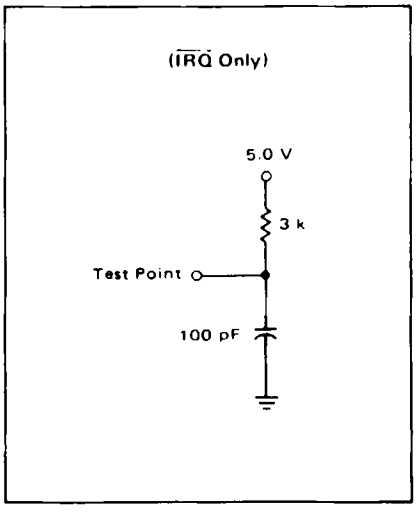


FIGURE 8 – PERIPHERAL DATA SETUP AND HOLD TIMES
(Read Mode)

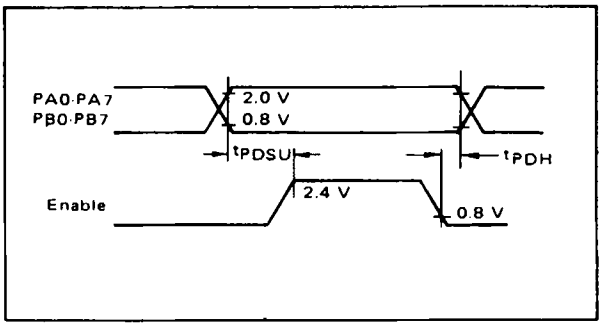


FIGURE 9 – CA2 DELAY TIME
(Read Mode; CRA-5 = CRA-3 = 1, CRA-4 = 0)

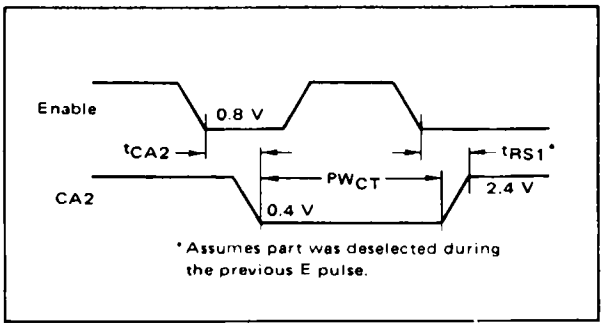


FIGURE 10 – CA2 DELAY TIME
(Read Mode; CRA-5 = 1, CRA-3 = CRA-4 = 0)

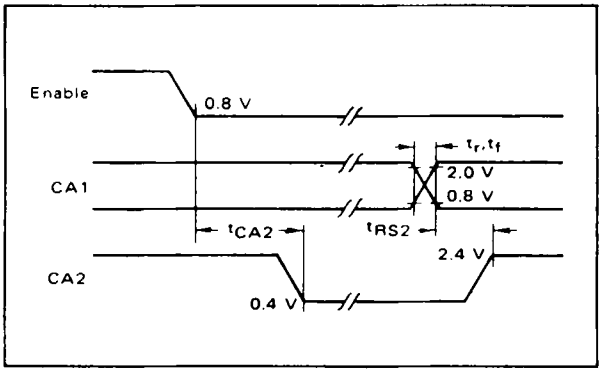


FIGURE 11 – PERIPHERAL CMOS DATA DELAY TIMES
(Write Mode; CRA-5 = CRA-3 = 1, CRA-4 = 0)

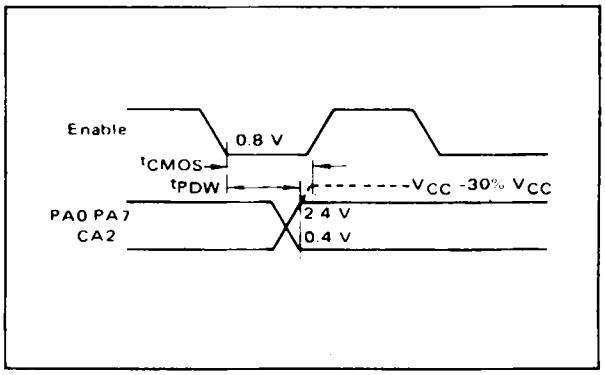


FIGURE 12 – PERIPHERAL DATA AND CB2 DELAY TIMES
(Write Mode; CRB-5 = CRB-3 = 1, CRB-4 = 0)

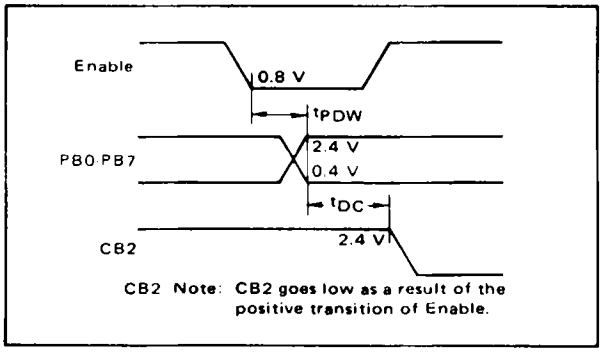


FIGURE 13 – CB2 DELAY TIME
(Write Mode; CRB-5 = CRB-3 = 1, CRB-4 = 0)

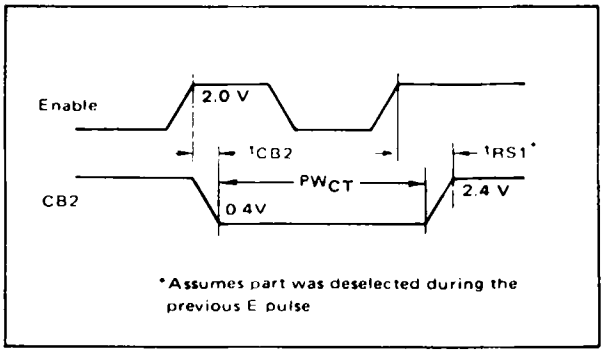


FIGURE 14 – CB2 DELAY TIME
(Write Mode; CRB-5 = 1, CRB-3 = CRB-4 = 0)

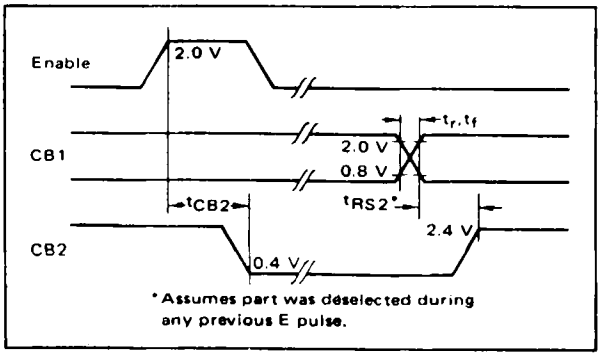


FIGURE 15 – INTERRUPT PULSE WIDTH AND $\overline{IRQ}$ RESPONSE

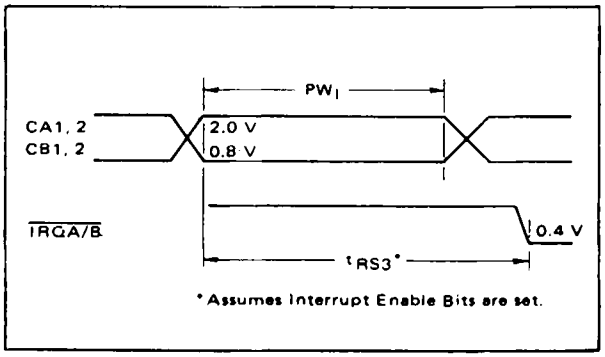


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FIGURE 16 – $\overline{IRQ}$ RELEASE TIME

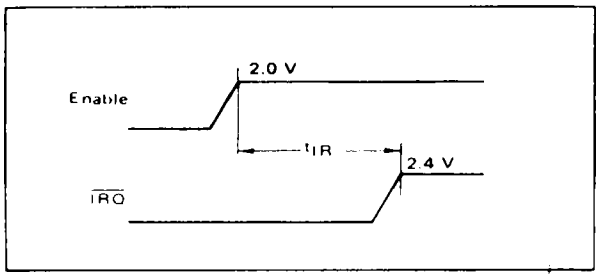
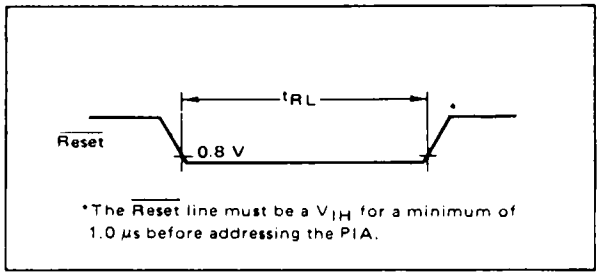
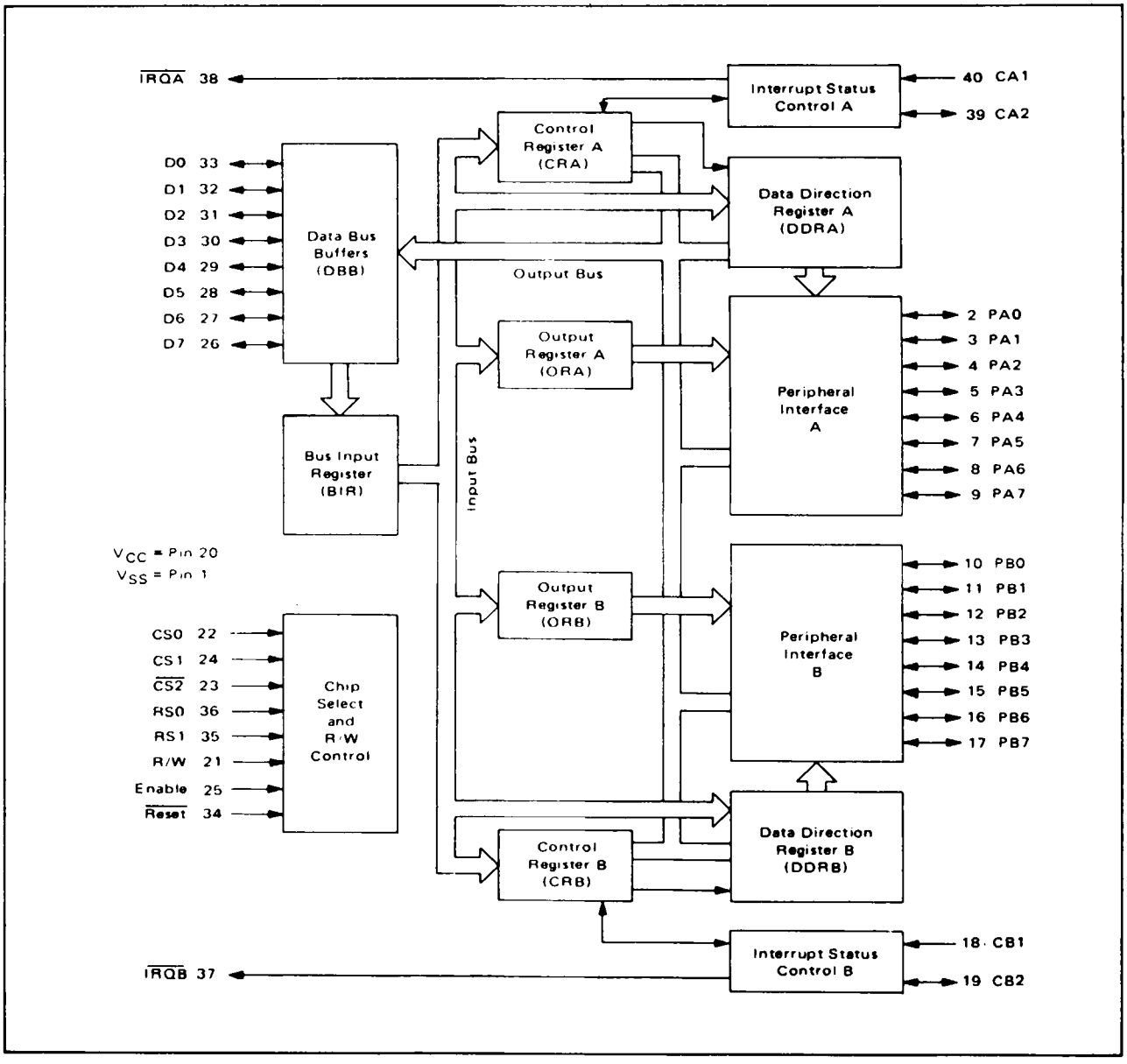


FIGURE 17 – $\overline{RESET}$ LOW TIME



*The $\overline{Reset}$ line must be a V_{IH} for a minimum of 1.0 µs before addressing the PIA.

EXPANDED BLOCK DIAGRAM



MC6821

PIA INTERFACE SIGNALS FOR MPU

The PIA interfaces to the MC6800 MPU with an eight-bit bi-directional data bus, three chip select lines, two register select lines, two interrupt request lines, read/write line, enable line and reset line. These signals, in conjunction with the MC6800 VMA output, permit the MPU to have complete control over the PIA. VMA should be utilized in conjunction with an MPU address line into a chip select of the PIA.

PIA Bi-Directional Data (D0-D7) The bi-directional data lines (D0-D7) allow the transfer of data between the MPU and the PIA. The data bus output drivers are three-state devices that remain in the high-impedance (off) state except when the MPU performs a PIA read operation. The Read/Write line is in the Read (high) state when the PIA is selected for a Read operation.

PIA Enable (E) - The enable pulse, E, is the only timing signal that is supplied to the PIA. Timing of all other signals is referenced to the leading and trailing edges of the E pulse. This signal will normally be a derivative of the MC6800 $\phi 2$ Clock.

PIA Read/Write (R/W) - This signal is generated by the MPU to control the direction of data transfers on the Data Bus. A low state on the PIA Read/Write line enables the input buffers and data is transferred from the MPU to the PIA on the E signal if the device has been selected. A high on the Read/Write line sets up the PIA for a transfer of data to the bus. The PIA output buffers are enabled when the proper address and the enable pulse E are present.

$\overline{\text{Reset}}$ – The active low $\overline{\text{Reset}}$ line is used to reset all register bits in the PIA to a logical zero (low). This line can be used as a power-on reset and as a master reset during system operation.

PIA Chip Select (CS0, CS1 and $\overline{\text{CS2}}$) - These three input signals are used to select the PIA. CS0 and CS1 must be high and $\overline{\text{CS2}}$ must be low for selection of the device. Data transfers are then performed under the control of the Enable and Read/Write signals. The chip select lines must be stable for the duration of the E pulse. The device is deselected when any of the chip selects are in the inactive state.

PIA Register Select (RS0 and RS1) – The two register select lines are used to select the various registers inside the PIA. These two lines are used in conjunction with internal Control Registers to select a particular register that is to be written or read.

The register and chip select lines should be stable for the duration of the E pulse while in the read or write cycle.

Interrupt Request ($\overline{\text{IRQA}}$ and $\overline{\text{IRQB}}$) The active low Interrupt Request lines ($\overline{\text{IRQA}}$ and $\overline{\text{IRQB}}$) act to interrupt the MPU either directly or through interrupt priority circuitry. These lines are "open drain" (no load device on the chip). This permits all interrupt request lines to be tied together in a wire-OR configuration.

Each Interrupt Request line has two internal interrupt flag bits that can cause the Interrupt Request line to go low. Each flag bit is associated with a particular peripheral interrupt line. Also four interrupt enable bits are provided in the PIA which may be used to inhibit a particular interrupt from a peripheral device.

Servicing an interrupt by the MPU may be accomplished by a software routine that, on a prioritized basis, sequentially reads and tests the two control registers in each PIA for interrupt flag bits that are set.

The interrupt flags are cleared (zeroed) as a result of an MPU Read Peripheral Data Operation of the corresponding data register. After being cleared, the interrupt flag bit cannot be enabled to be set until the PIA is deselected during an E pulse. The E pulse is used to condition the interrupt control lines (CA1, CA2, CB1, CB2). When these lines are used as interrupt inputs at least one E pulse must occur from the inactive edge to the active edge of the interrupt input signal to condition the edge sense network. If the interrupt flag has been enabled and the edge sense circuit has been properly conditioned, the interrupt flag will be set on the next active transition of the interrupt input pin.

PIA PERIPHERAL INTERFACE LINES

The PIA provides two 8-bit bi-directional data buses and four interrupt/control lines for interfacing to peripheral devices.

Section A Peripheral Data (PA0-PA7) – Each of the peripheral data lines can be programmed to act as an input or output. This is accomplished by setting a "1" in the corresponding Data Direction Register bit for those lines which are to be outputs. A "0" in a bit of the Data Direction Register causes the corresponding peripheral data line to act as an input. During an MPU Read Peripheral Data Operation, the data on peripheral lines programmed to act as inputs appears directly on the corresponding MPU Data Bus lines. In the input mode the internal pullup resistor on these lines represents a maximum of 1.5 standard TTL loads.

The data in Output Register A will appear on the data lines that are programmed to be outputs. A logical "1" written into the register will cause a "high" on the corresponding data line while a "0" results in a "low". Data in Output Register A may be read by an MPU "Read Peripheral Data A" operation when the corresponding lines are programmed as outputs. This data will be read properly if the voltage on the peripheral data lines is greater than 2.0 volts for a logic "1" output and less than 0.8 volt for a logic "0" output. Loading the output lines such that the voltage on these lines does not reach full voltage causes the data transferred into the MPU on a Read operation to differ from that contained in the respective bit of Output Register A.

Section B Peripheral Data (PB0-PB7) – The peripheral data lines in the B Section of the PIA can be programmed to act as either inputs or outputs in a similar manner to PA0-PA7. However, the output buffers driving these lines differ from those driving lines PA0-PA7. They have three-state capability, allowing them to enter a high impedance state when the peripheral data line is used as an input. In addition, data on the peripheral data lines PB0-PB7 will be read properly from those lines programmed as outputs even if the voltages are below 2.0 volts for a "high". As outputs, these lines are compatible with standard TTL and may also be used as a source of up to 1 milliampere at 1.5 volts to directly drive the base of a transistor switch.

Interrupt Input (CA1 and CB1) – Peripheral Input lines CA1 and CB1 are input only lines that set the interrupt flags of the control registers. The active transition for these signals is also programmed by the two control registers.

Peripheral Control (CA2) – The peripheral control line CA2 can be programmed to act as an interrupt input or as a peripheral control output. As an output, this line is compatible with standard TTL, as an input the internal pullup resistor on this line represents 1.5 standard TTL loads. The function of this signal line is programmed with Control Register A.

Peripheral Control (CB2) – Peripheral Control line CB2 may also be programmed to act as an interrupt input or peripheral control output. As an input, this line has high input impedance and is compatible with standard TTL. As an output it is compatible with standard TTL and may also be used as a source of up to 1 milliampere at 1.5 volts to directly drive the base of a transistor switch. This line is programmed by Control Register B.

INTERNAL CONTROLS

There are six locations within the PIA accessible to the MPU data bus: two Peripheral Registers, two Data Direction Registers, and two Control Registers. Selection of these locations is controlled by the RS0 and RS1 inputs together with bit 2 in the Control Register, as shown in Table 1.

TABLE 1 – INTERNAL ADDRESSING

		Control Register Bit		
RS1	RS0	CRA-2	CRB-2	Location Selected
0	0	1	X	Peripheral Register A
0	0	0	X	Data Direction Register A
0	1	X	X	Control Register A
1	0	X	1	Peripheral Register B
1	0	X	0	Data Direction Register B
1	1	X	X	Control Register B

X = Don't Care

INITIALIZATION

A low reset line has the effect of zeroing all PIA registers. This will set PA0-PA7, PB0-PB7, CA2 and CB2 as inputs, and all interrupts disabled. The PIA must be configured during the restart program which follows the reset.

Details of possible configurations of the Data Direction and Control Register are as follows.

DATA DIRECTION REGISTERS (DDRA and DDRB)

The two Data Direction Registers allow the MPU to control the direction of data through each corresponding peripheral data line. A Data Direction Register bit set at "0" configures the corresponding peripheral data line as an input; a "1" results in an output.

CONTROL REGISTERS (CRA and CRB)

The two Control Registers (CRA and CRB) allow the MPU to control the operation of the four peripheral control lines CA1, CA2, CB1 and CB2. In addition they allow the MPU to enable the interrupt lines and monitor the status of the interrupt flags. Bits 0 through 5 of the two registers may be written or read by the MPU when the proper chip select and register select signals are applied. Bits 6 and 7 of the two registers are read only and are modified by external interrupts occurring on control lines CA1, CA2, CB1 or CB2. The format of the control words is shown in Table 2.

TABLE 2 – CONTROL WORD FORMAT

	7	6	5	4	3	2	1	0
CRA	IRQA1	IRQA2	CA2 Control			DDRA Access	CA1 Control	
CRB	IRQB1	IRQB2	CB2 Control			DDRB Access	CB1 Control	

Data Direction Access Control Bit (CRA-2 and CRB-2) – Bit 2 in each Control register (CRA and CRB) allows selection of either a Peripheral Interface Register or the Data Direction Register when the proper register select signals are applied to RS0 and RS1.

Interrupt Flags (CRA-6, CRA-7, CRB-6, and CRB-7) – The four interrupt flag bits are set by active transitions of signals on the four Interrupt and Peripheral Control lines when those lines are programmed to be inputs. These bits cannot be set directly from the MPU Data Bus and are reset indirectly by a Read Peripheral Data Operation on the appropriate section.

TABLE 3 – CONTROL OF INTERRUPT INPUTS CA1 AND CB1

CRA-1 (CRB-1)	CRA-0 (CRB-0)	Interrupt Input CA1 (CB1)	Interrupt Flag CRA-7 (CRB-7)	MPU Interrupt Request $\overline{IRQA}$ ($\overline{IRQB}$)
0	0	↓ Active	Set high on ↓ of CA1 (CB1)	Disabled — $\overline{IRQ}$ remains high
0	1	↓ Active	Set high on ↓ of CA1 (CB1)	Goes low when the interrupt flag bit CRA-7 (CRB-7) goes high
1	0	↑ Active	Set high on ↑ of CA1 (CB1)	Disabled — $\overline{IRQ}$ remains high
1	1	↑ Active	Set high on ↑ of CA1 (CB1)	Goes low when the interrupt flag bit CRA-7 (CRB-7) goes high

Notes 1 ↑ indicates positive transition (low to high)

2 ↓ indicates negative transition (high to low)

3 The interrupt flag bit CRA-7 is cleared by an MPU Read of the A Data Register, and CRB-7 is cleared by an MPU Read of the B Data Register.

4 If CRA-0 (CRB-0) is low when an interrupt occurs (Interrupt disabled) and is later brought high, $\overline{IRQA}$ ($\overline{IRQB}$) occurs after CRA-0 (CRB-0) is written to a "one".

Control of CA1 and CB1 Interrupt Input Lines (CRA-0, CRB-0, CRA-1, and CRB-1) – The two lowest order bits of the control registers are used to control the interrupt input lines CA1 and CB1. Bits CRA-0 and CRB-0 are used to enable the MPU interrupt signals $\overline{IRQA}$ and $\overline{IRQB}$, respectively. Bits CRA-1 and CRB-1 determine the active transition of the interrupt input signals CA1 and CB1 (Table 3).

TABLE 4 – CONTROL OF CA2 AND CB2 AS INTERRUPT INPUTS
CRA5 (CRB5) is low

CRA-5 (CRB-5)	CRA-4 (CRB-4)	CRA-3 (CRB-3)	Interrupt Input CA2 (CB2)	Interrupt Flag CRA-6 (CRB-6)	MPU Interrupt Request $\overline{IRQA}$ ($\overline{IRQB}$)
0	0	0	↓ Active	Set high on ↓ of CA2 (CB2)	Disabled — $\overline{IRQ}$ remains high
0	0	1	↓ Active	Set high on ↓ of CA2 (CB2)	Goes low when the interrupt flag bit CRA-6 (CRB-6) goes high
0	1	0	↑ Active	Set high on ↑ of CA2 (CB2)	Disabled — $\overline{IRQ}$ remains high
0	1	1	↑ Active	Set high on ↑ of CA2 (CB2)	Goes low when the interrupt flag bit CRA-6 (CRB-6) goes high

Notes: 1. ↑ indicates positive transition (low to high)

2. ↓ indicates negative transition (high to low)

3. The interrupt flag bit CRA-6 is cleared by an MPU Read of the A Data Register and CRB-6 is cleared by an MPU Read of the B Data Register

4. If CRA-3 (CRB-3) is low when an interrupt occurs (Interrupt disabled) and is later brought high, $\overline{IRQA}$ ($\overline{IRQB}$) occurs after CRA-3 (CRB-3) is written to a "one".

TABLE 5 – CONTROL OF CB2 AS AN OUTPUT
CRB-5 is high

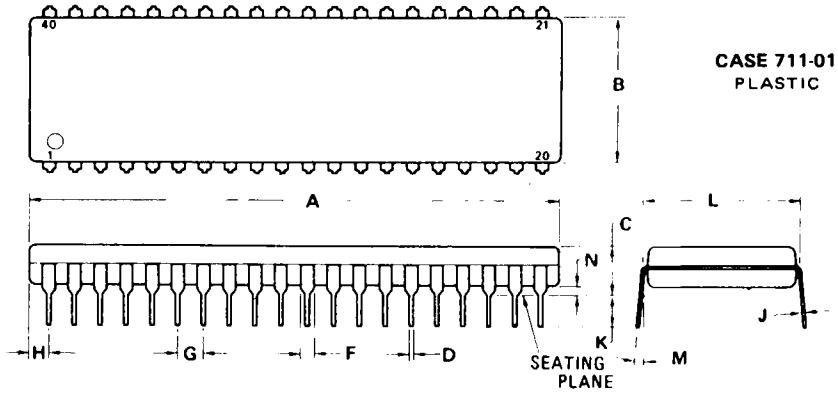
CRB-5	CRB-4	CRB-3	CB2	
			Cleared	Set
1	0	0	Low on the positive transition of the first E pulse following an MPU Write "B" Data Register operation	High when the interrupt flag bit CRB-7 is set by an active transition of the CB1 signal
1	0	1	Low on the positive transition of the first E pulse after an MPU Write "B" Data Register operation.	High on the positive edge of the first "E" pulse following an "E" pulse which occurred while the part was deselected
1	1	0	Low when CRB-3 goes low as a result of an MPU Write in Control Register B.	Always low as long as CRB-3 is low. Will go high on an MPU Write in Control Register B that changes CRB-3 to one.
1	1	1	Always high as long as CRB-3 is high. Will be cleared when an MPU Write Control Register "B" results in clearing CRB-3 to zero.	High when CRB-3 goes high as a result of an MPU Write into Control Register "B".

Control of CA2 and CB2 Peripheral Control Lines (CRA-3, CRA-4, CRA-5, CRB-3, CRB-4, and CRB-5) – Bits 3, 4, and 5 of the two control registers are used to control the CA2 and CB2 Peripheral Control lines. These bits determine if the control lines will be an interrupt input or an output control signal. If bit CRA-5 (CRB-5) is low, CA2 (CB2) is an interrupt input line similar to CA1 (CB1) (Table 4). When CRA-5 (CRB-5) is high, CA2 (CB2) becomes an output signal that may be used to control peripheral data transfers. When in the output mode, CA2 and CB2 have slightly different characteristics (Tables 5 and 6).

TABLE 6 – CONTROL OF CA-2 AS AN OUTPUT
CRA-5 is high

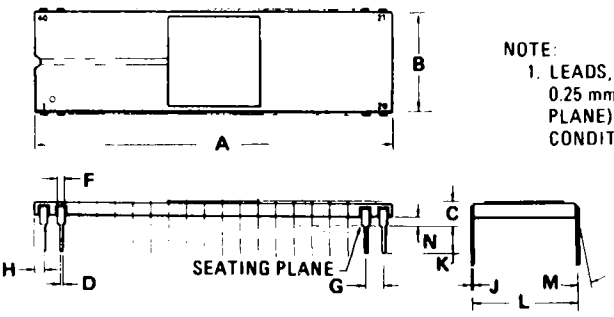
CRA-5	CRA-4	CRA-3	CA2 Cleared	CA2 Set
1	0	0	Low on negative transition of E after an MPU Read "A" Data operation.	High when the interrupt flag bit CRA-7 is set by an active transition of the CA1 signal.
1	0	1	Low on negative transition of E after an MPU Read "A" Data operation.	High on the negative edge of the first "E" pulse which occurs during a deselect.
1	1	0	Low when CRA-3 goes low as a result of an MPU Write to Control Register "A".	Always low as long as CRA-3 is low. Will go high on an MPU Write to Control Register "A" that changes CRA-3 to "one".
1	1	1	Always high as long as CRA-3 is high. Will be cleared on an MPU Write to Control Register "A" that clears CRA-3 to a "zero".	High when CRA-3 goes high as a result of an MPU Write to Control Register "A".

PACKAGE DIMENSIONS



CASE 711-01
PLASTIC

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	51.82	52.32	2.040	2.060
B	13.72	14.22	0.540	0.560
C	4.57	5.08	0.180	0.200
D	0.36	0.51	0.014	0.020
F	1.02	1.52	0.040	0.060
G	2.41	2.67	0.095	0.105
H	1.65	2.16	0.065	0.085
J	0.20	0.30	0.008	0.012
K	3.68	4.19	0.145	0.165
L	14.99	15.49	0.590	0.610
M	0°	10°	0°	10°
N	0.51	1.02	0.020	0.040



NOTE:
1. LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA (AT SEATING PLANE), AT MAX. MAT'L CONDITION.

CASE 715-02
CERAMIC

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	50.29	51.31	1.980	2.020
B	14.86	15.62	0.585	0.615
C	2.54	4.19	0.100	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.33	0.008	0.013
K	2.54	4.19	0.100	0.165
L	14.60	15.37	0.575	0.605
M	–	10°	–	10°
N	0.51	1.52	0.020	0.060

96S02 • 96LS02

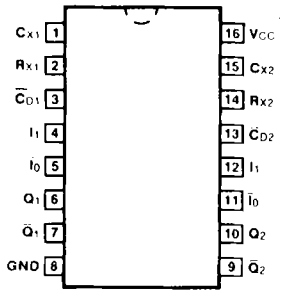
96S02
96LS02

DUAL RETRIGGERABLE RESETTABLE MONOSTABLE MULTIVIBRATOR

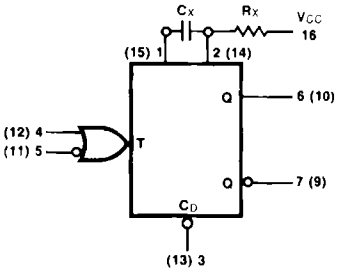
DESCRIPTION — The 96S02 and 96LS02 are dual retriggerable and resettable monostable multivibrators. These one-shots provide exceptionally wide delay range, pulse width stability, predictable accuracy and immunity to noise. The pulse width is set by an external resistor and capacitor. Resistor values up to 1.0 MΩ for the 96LS02 and 2.0 MΩ for the 96S02 reduce required capacitor values. Hysteresis is provided on both trigger inputs of the 96LS02 and on the positive trigger input of the 96S02 for increased noise immunity.

- **REQUIRED TIMING CAPACITANCE REDUCED BY FACTORS OF 10 TO 100 OVER CONVENTIONAL DESIGNS**
- **BROAD TIMING RESISTOR RANGE — 1.0 kΩ to 2.0 MΩ**
- **OUTPUT PULSE WIDTH IS VARIABLE OVER A 2000:1 RANGE BY RESISTOR CONTROL**
- **PROPAGATION DELAY OF 35 ns 96LS02, 12 ns 96S02**
- **0.3 V HYSTERESIS ON TRIGGER INPUTS**
- **OUTPUT PULSE WIDTH INDEPENDENT OF DUTY CYCLE**
- **35 ns TO ∞ OUTPUT PULSE WIDTH RANGE**

CONNECTION DIAGRAM
PINOUT A



LOGIC SYMBOL



V_{CC} = Pin 16
GND = Pin 8

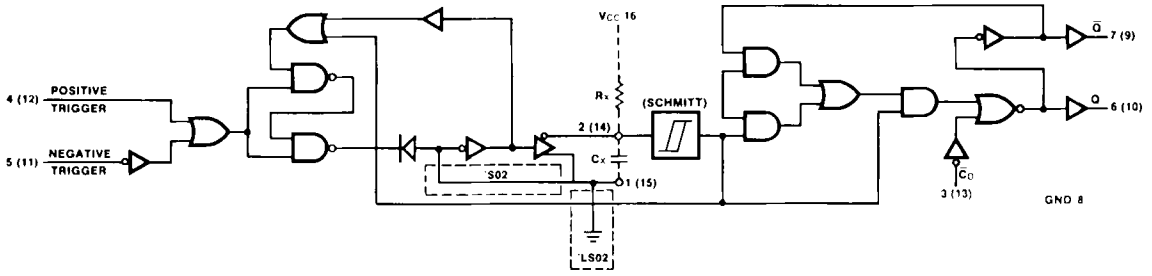
ORDERING CODE: See Section 9

PKGS	PIN OUT	COMMERCIAL GRADE V_{CC} = +5.0 V ±5%, T_A = 0°C to +70°C	MILITARY GRADE V_{CC} = +5.0 V ±10%, T_A = -55°C to +125°C	PKG TYPE
Plastic DIP (P)	A	96S02PC, 96LS02PC		9B
Ceramic DIP (D)	A	96S02DC, 96LS02DC	96S02DM, 96LS02DM	6B
Flatpak (F)	A	96S02FC, 96LS02FC	96S02FM, 96LS02FM	4L

INPUT LOADING/FAN-OUT: See Section 3 for U.L. definitions

PIN NAMES	DESCRIPTION	96S (U.L.) HIGH/LOW	96LS (U.L.) HIGH/LOW
$\overline{I}_0$	Trigger Input (Active Falling Edge)	0.5/0.625	
$\overline{I}_0$	Schmitt Trigger Input (Active Falling Edge)		0.5/0.25
I_1	Schmitt Trigger Input (Active Rising Edge)	0.5/0.625	0.5/0.25
$\overline{C}_D$	Direct Clear Input (Active LOW)	0.5/0.625	0.5/0.25
Q	True Pulse Output	25/12.5	10/5.0 (2.5)
$\overline{Q}$	Complementary Pulse Output	25/12.5	10/5.0 (2.5)

LOGIC DIAGRAM

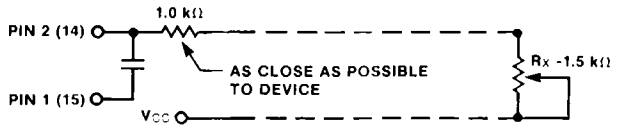


FUNCTIONAL DESCRIPTION — The 96S02 and 96LS02 dual retriggerable resettable monostable multivibrators have two dc coupled trigger inputs per function, one active LOW ($\overline{I}_0$) and one active HIGH (I_1). The I_1 input of both circuit types and the $\overline{I}_0$ input of the 96LS02 utilize an internal Schmitt trigger with hysteresis of 0.3 V to provide increased noise immunity. The use of active HIGH and LOW inputs allows either rising or falling edge triggering and optional non-retriggerable operation. The inputs are dc coupled making triggering independent of input transition times. When input conditions for triggering are met the Q output goes HIGH and the external capacitor is rapidly discharged and then allowed to recharge. An input trigger which occurs during the timing cycle will retrigger the circuit and result in Q remaining HIGH. The output pulse may be terminated (Q to the LOW state) at any time by setting the Direct Clear input LOW. Retriggering may be inhibited by tying the $\overline{Q}$ output to $\overline{I}_0$ or the Q output to I_1. Differential sensing techniques are used to obtain excellent stability over temperature and power supply variations and a feedback Darlington capacitor discharge circuit minimizes pulse width variation from unit to unit. Schottky TTL output stages provide high switching speeds and output compatibility with all TTL logic families.

Operation Notes

TIMING

1. An external resistor (R_X) and an external capacitor (C_X) are required as shown in the Logic Diagram. The value of R_X may vary from 1.0 kΩ to 1.0 MΩ (96LS02) or 2.0 MΩ (96S02).
2. The value of C_X may vary from 0 to any necessary value available. If, however, the capacitor has significant leakage relative to V_{CC}/R_X the timing equations may not represent the pulse width obtained.
3. Polarized capacitors may be used directly. The (+) terminal of a polarized capacitor is connected to pin 1 (15), the (-) terminal to pin 2 (14) and R_X. Pin 1 (15) will remain positive with respect to pin 2 (14) during the timing cycle. In the 96S02, however, during quiescent (non-triggered) conditions, pin 1 (15) may go negative with respect to pin 2 (14) depending on values of R_X and V_{CC}. For values of $R_X \geq 10$ kΩ the maximum amount of capacitor reverse polarity, pin 1 (15) negative with respect to pin 2 (14) is 500 mV. Most tantalum electrolytic capacitors are rated for safe reverse bias operation up to 5% of their working forward voltage rating; therefore, capacitors having a rating of 10 WVdc or higher should be used with the 96S02 when $R_X \geq 10$ kΩ.
4. The output pulse width t_w for $R_X \geq 10$ kΩ and $C_X \geq 1000$ pF is determined as follows:
   (96S02) $t_w = 0.55\ R_X C_X$
   (96LS02) $t_w = 0.43\ R_X C_X$
   Where R_X is in kΩ, C_X is in pF, t is in ns *or* R_X is in kΩ, C_X is in μF, t is in ms.
5. The output pulse width for $R_X < 10$ kΩ or $C_X < 1000$ pF should be determined from pulse width versus C_X or R_X graphs.
6. To obtain variable pulse width by remote trimming, the following circuit is recommended:



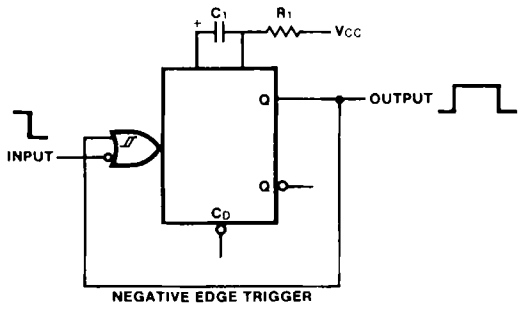
96S02 • 96LS02

Operation Notes (Cont'd)

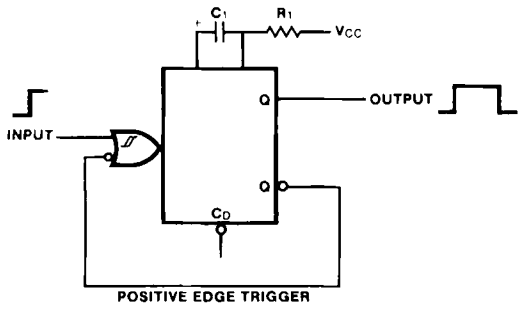
7. Under any operating condition, C_X and R_X (Min) must be kept as close to the circuit as possible to minimize stray capacitance and reduce noise pickup.
8. V_{CC} and ground wiring should conform to good high frequency standards so that switching transients on V_{CC} and ground leads do not cause interaction between one shots. Use of a 0.01 μF to 0.1 μF bypass capacitor between V_{CC} and ground located near the circuit is recommended.

TRIGGERING

1. The minimum negative pulse width into $\overline{I}_0$ is 8.0 ns; the minimum positive pulse width into I_1 is 12 ns.
2. Input signals to the 96S02 exhibiting slow or noisy transitions should use the positive trigger input I_1 which contains a Schmitt trigger. Input signals to the 96LS02 exhibiting slow or noisy transitions can use either trigger as both are Schmitt triggers.
3. When non-retriggerable operation is required, i.e., when input triggers are to be ignored during quasi-stable state, input latching is used to inhibit retriggering.



NEGATIVE EDGE TRIGGER



POSITIVE EDGE TRIGGER

4. An overriding active LOW level direct clear is provided on each multivibrator. By applying a LOW to the clear, any timing cycle can be terminated or any new cycle inhibited until the LOW reset input is removed. Trigger inputs will not produce spikes in the output when the reset is held LOW. A LOW-to-HIGH transition on $\overline{C}_D$ will not trigger the 96S02 or 96LS02. If the $\overline{C}_D$ input goes HIGH coincident with a trigger transition, the circuit will respond to the trigger.

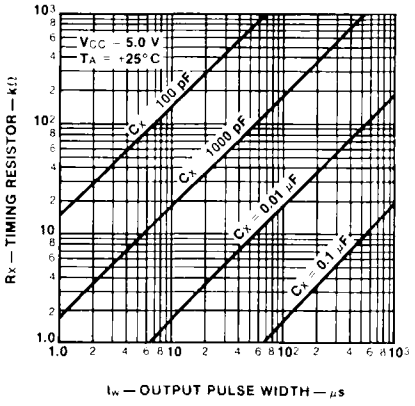
TRIGGERING TRUTH TABLE

PIN NO'S. 5 (11)	4 (12)	3 (13)	OPERATION
H→L	L	H	Trigger
H	L→H	H	Trigger
X	X	L	Reset

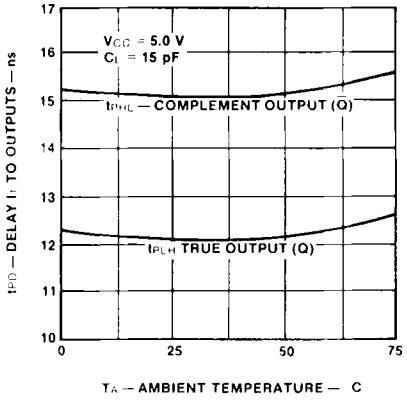
H = HIGH Voltage Level ≥ V_{IH}
L = LOW Voltage Level ≤ V_{IL}
X = Immaterial (either H or L)
H→L = HIGH to LOW Voltage Level transition
L→H = LOW to HIGH Voltage Level transition

TYPICAL CHARACTERISTICS
96S02

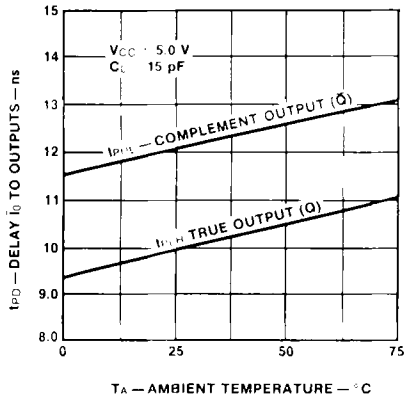
OUTPUT t_w vs R_X and C_X



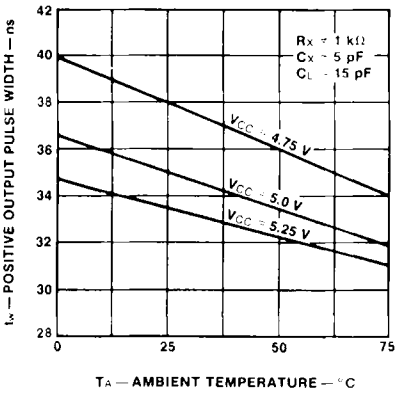
$\overline{I}_1$ DELAY TIME vs T_A



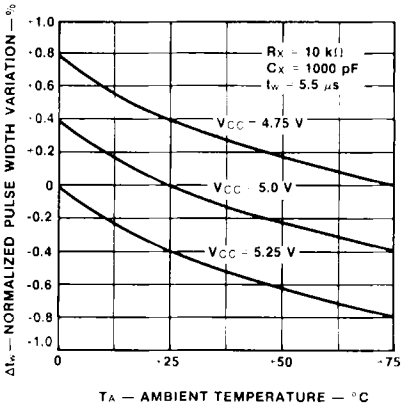
$\overline{I}_0$ DELAY TIME vs T_A



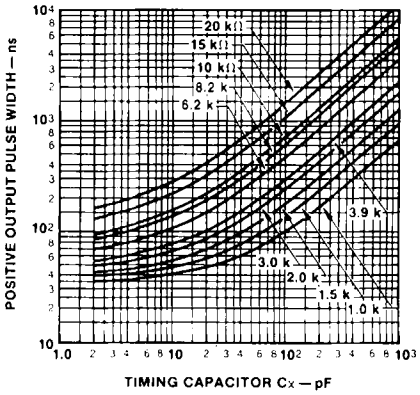
OUTPUT t_w vs T_A



NORMALIZED Δt_w vs T_A



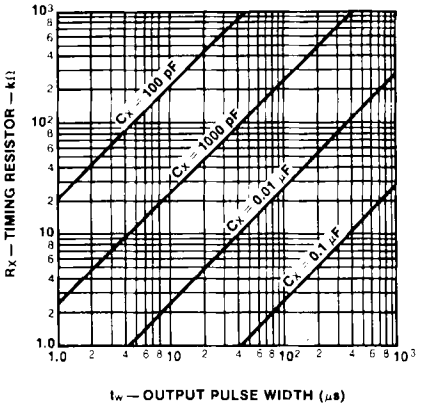
PULSE WIDTH vs R_XC_X



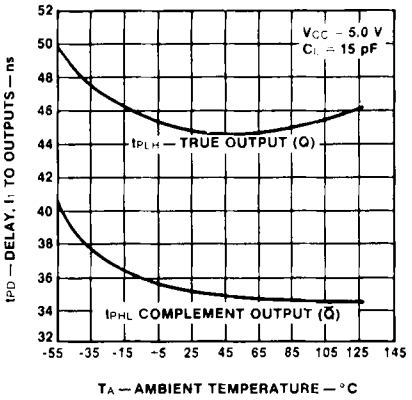
96S02 • 96LS02

TYPICAL CHARACTERISTICS
96LS02

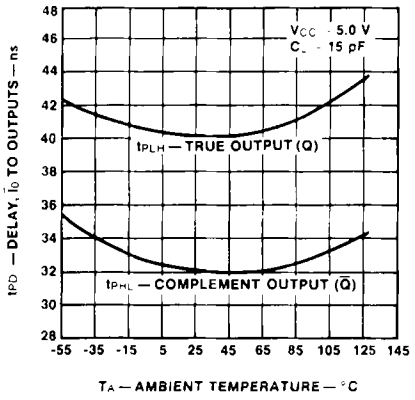
OUTPUT t_W vs R_X and C_X



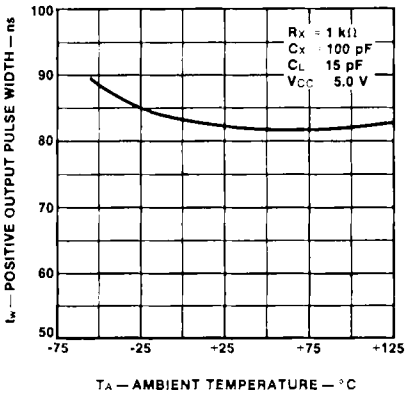
I_1 DELAY TIME vs T_A



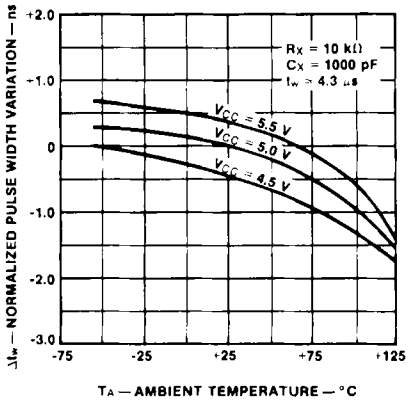
$\bar{I}_0$ DELAY TIME vs T_A



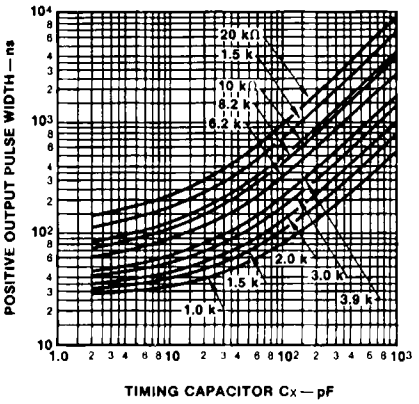
OUTPUT t_W vs T_A



NORMALIZED Δt_W vs T_A



PULSE WIDTH vs R_XC_X



DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

SYMBOL	PARAMETER		96S Min	96S Max	96LS Min	96LS Max	UNITS	CONDITIONS
V_{T+}	Positive-going Threshold Voltage, $\overline{I_0}$, I_1 (96LS02) I_1 (96S02)			2.0		2.0	V	V_{CC} = 5.0 V
V_{T-}	Negative-going Threshold Voltage $\overline{I_0}$, I_1 (96LS02) I_1 (96S02)	XM	0.8		0.7		V	V_{CC} = 5.0 V
		XC	0.8		0.8			
V_{OH}	Output HIGH Voltage	XM	2.7		2.5		V	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL} I_{OH} = -400 μA ('LS02) I_{OH} = -1.0 mA ('S02)
		XC	2.7		2.7			
V_{OL}	Output LOW Voltage	XM		0.5		0.5	V	V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}
		XC		0.5		0.4		
V_{CX}	Capacitor Voltage Pin 1 (15) Referenced to Pin 2 (14)		-0.85 -0.5 -0.4	3.0 3.0 3.0	0 0 0	3.0 3.0 3.0	V	R_X = 1.0 kΩ R_X = > 10 kΩ R_X > 1.0 MΩ V_{CC} = 4.75 V to 5.25 V
I_{IH}	Input HIGH Current			20 0.1		20 0.1	μA mA	V_{IN} = 2.7 V V_{IN} = 5.5 V ('S02) V_{IN} = 10 V ('LS02) V_{CC} = Max
I_{IL}	Input LOW Current			-1.0		-0.4	mA	V_{IN} = 0.4 V, V_{CC} = Max
I_{OS}	Output Short Circuit Current		-40	-100	-20	-100	mA	V_{CC} = Max, V_{OUT} = 0 V
I_{CC}	Power Supply Current			75		36	mA	V_{IN} = Open, V_{CC} = Max

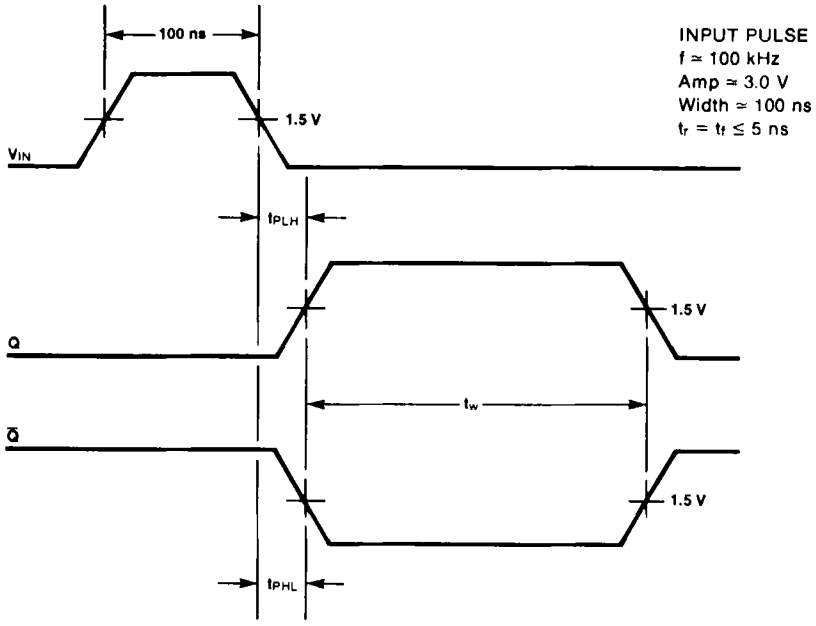


Fig. a

96S02 • 96LS02

AC CHARACTERISTICS: V_{CC} = +5.0 V, T_A = +25°C (See Section 3 for waveforms and load configurations)

SYMBOL	PARAMETER		96S C_L = 15 pF Min	96S C_L = 15 pF Max	96LS C_L = 15 pF Min	96LS C_L = 15 pF Max	UNITS	CONDITIONS
t_{PLH}	Propagation Delay $\overline{I_0}$ to Q			15		55	ns	Fig. a
t_{PHL}	Propagation Delay $\overline{I_0}$ to $\overline{Q}$			19		50	ns	
t_{PLH}	Propagation Delay I_1 to Q			19		60	ns	
t_{PHL}	Propagation Delay I_1 to $\overline{Q}$			20		55	ns	
t_{PHL}	Propagation Delay $\overline{C_D}$ to Q			20		30	ns	
t_{PLH}	Propagation Delay $\overline{C_D}$ to $\overline{Q}$			14		35	ns	
t_w (L)	$\overline{I_0}$ Pulse Width LOW		8.0		15		ns	
t_w (H)	I_1 Pulse Width HIGH		12		30		ns	
t_w (L)	$\overline{C_D}$ Pulse Width LOW		7.0		22		ns	
t_w (H)	Minimum Q Pulse Width HIGH		30	45	25	55	ns	R_X = 1.0 kΩ, C_X = 10 pF including jig and stray
t_w	Q Pulse Width		5.2	5.8	4.1	4.5	μs	R_X = 10 kΩ, C_X = 1000 pF
R_X	Timing Resistor Range*		1.0	2000	1.0	1000	kΩ	T_A = -55°C to +125°C, V_{CC} = 4.5 V to 5.5 V
t	Change in Q Pulse Width over Temperature	XM				3.0	%	R_X = 10 kΩ, C_X = 1000 pF
		XC		1.0		1.0		
t	Change in Q Pulse Width over V_{CC} Range			1.0		0.8	%	T_A = 25°C, V_{CC} = 4.75 V to 5.25 V, R_X = 10 kΩ, C_X = 1000 pF
						1.5		T_A = 25°C, V_{CC} = 4.5 V to 5.5 V, R_X = 10 kΩ, C_X = 1000 pF

*Applies only over commercial V_{CC} and T_A range for 96S02.

MOTOROLA
SEMICONDUCTORS
3501 ED BLUESTEIN BLVD., AUSTIN, TEXAS 78721

MC2661A/MC68661A
(Baud Rate Set A)
MC2661B/MC68661B
(Baud Rate Set B)
MC2661C/MC68661C
(Baud Rate Set C)

Advance Information

MOS
(N-CHANNEL, SILICON-GATE)

ENHANCED PROGRAMMABLE COMMUNICATIONS INTERFACE (EPCI)

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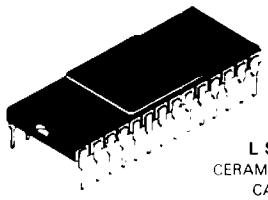
The MC2661/MC68661, Enhanced Programmable Communications Interface (EPCI), is a universal synchronous/asychronous data communications controller chip that is an enhanced version of the Signetics 2651. The EPCI directly interfaces to most 8-bit MPUs and easily to the MC68000 MPU and other 16-bit MPUs. It may be used in either a polled or interrupt driven system. Programmed instructions can be accepted from the host MPU while supporting many synchronous or asynchronous serial-data communication protocols in a full or half-duplex mode. Special support for BISYNC is provided.

The EPCI converts parallel data characters, accepted from the microprocessor data bus, into transmit-serial data. Simultaneously, the EPCI can convert receive-serial data to parallel data characters for input to the microprocessor.

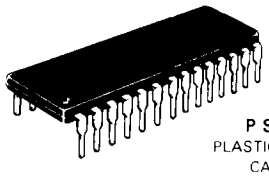
A baud rate generator in the EPCI can be programmed to either accept an external clock, or to generate internal transmit or receive clocks. Sixteen different baud rates can be selected under program control when operating in the internal clock mode. Each version of the EPCI (A, B, C) has a different set of baud rates.

FEATURES

- **Synchronous Operation**
  - Single or Double SYN Operation
  - Internal or External Character Synchronization
  - Transparent or Non-transparent Mode
  - Transparent Mode DLE Stuffing (Tx) and Detection (Rx)
  - Automatic SYN or DLE-SYN Insertion
  - SYN, DLE, and DLE-SYN Stripping
  - Baud Rate: dc to 1M bps (1X Clock)
- **Asynchronous Operation**
  - 1, 1½, or 2 Stop Bits Transmitted
  - Parity, Overrun, and Framing Error Detection
  - Line Break Detection and Generation
  - False Start Bit Detection
  - Automatic Serial Echo Mode (Echoplex)
  - Baud Rate: dc 1M bps (1X Clock)
    dc to 62.5k bps (16X Clock)
    dc to 15.625k bps (64X Clock)
- **Common Features**
  - Internal or External Baud Rate Clock; No System Clock Required
  - 3 Baud Rate Sets (A, B, C); 16 Internal Rates for Each Set
  - 5- to 8-Bit Characters plus parity; Odd, Even, or No Parity
  - Double Buffered Transmitter and Receiver
  - Dynamic Character Length Switching
  - Full- or Half-Duplex Operation
  - Local or Remote Maintenance Loop-Back Mode
  - TTL-Compatible Inputs and Outputs
  - RxC and TxC Pins and Short Circuit Protected
  - 3 Open-Drain MOS Outputs can be Wire ORed
  - Single 5 V Power Supply
- **Applications**
  - Intelligent Terminals
  - Network Processors
  - Front End Processors
  - Remote Data Concentrators
  - Computer-to-Computer Links
  - Serial Peripherals
  - BISYNC Adaptors



L SUFFIX
CERAMIC PACKAGE
CASE 719



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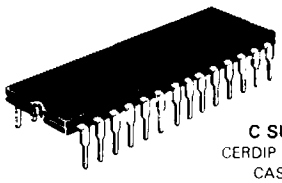
CASE 710



C SUFFIX
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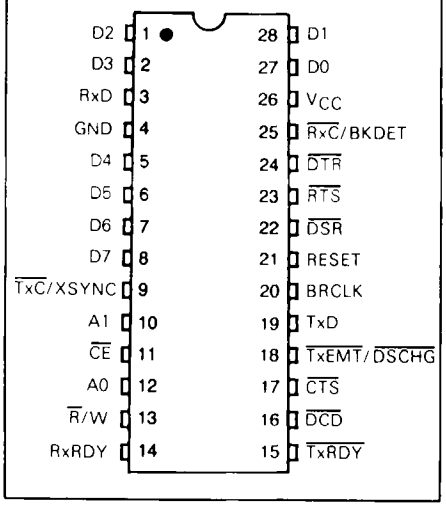
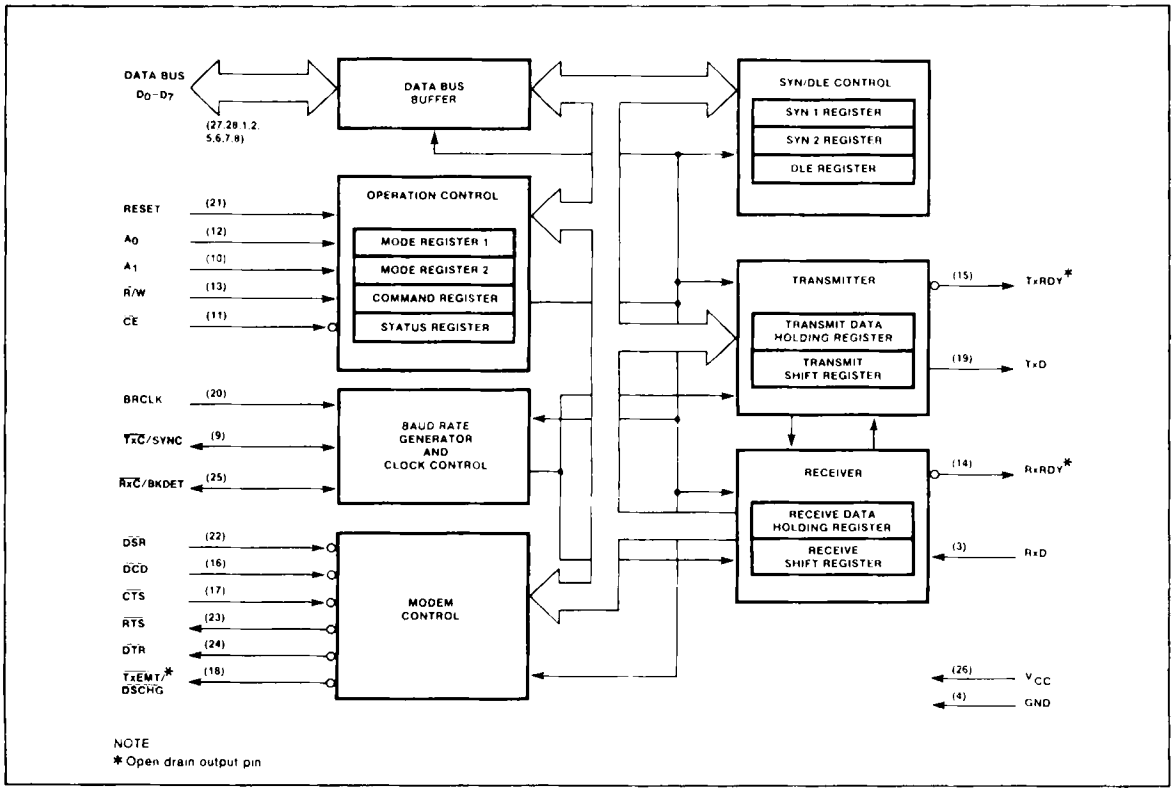
CASE 733

PIN ASSIGNMENT



BLOCK DIAGRAM



NOTE
* Open drain output pin

BLOCK DIAGRAM

The EPCI consists of six major sections. These are the transmitter, receiver, timing, operation control, modem control and SYN/DLE control. These sections communicate with each other via an internal data bus and an internal control bus. The internal data bus interfaces to the microprocessor data bus via a data bus buffer.

Operation Control

This functional block stores configuration and operation commands from the CPU and generates appropriate signals to various internal sections to control the overall device operation. It contains read and write circuits to permit communications with the microprocessor via the data bus and contains mode registers 1 and 2, the command register, and the status register. Details of register addressing and protocol are presented in the EPCI programming section of this data sheet.

Table 1 BAUD RATE GENERATOR CHARACTERISTICS
Set A (BRCLK = 4.9152MHz)

MR23–20	BAUD RATE	ACTUAL FREQUENCY 16X CLOCK	PERCENT ERROR	DIVISOR
0000	50	0.8kHz	-	6144
0001	75	1.2	-	4096
0010	110	1.7598	−0.01	2793
0011	134.5	2.152	-	2284
0100	150	2.4	-	2048
0101	200	3.2	-	1536
0110	300	4.8	-	1024
0111	600	9.6	-	512
1000	1050	16.8329	0.196	292
1001	1200	19.2	-	256
1010	1800	28.7438	−0.19	171
1011	2000	31.9168	−0.26	154
1100	2400	38.4	-	128
1101	4800	76.8	-	64
1110	9600	153.6	-	32
1111	19200	307.2	-	16

Timing
The EPCI contains a baud rate generator (BRG) which is programmable to accept external transmit or receive clocks or to divide an external clock to perform data communications. The unit can generate 16 commonly used baud rates, any one of which can be selected for full duplex operation. See table 1.

Receiver
The receiver accepts serial data on the RxD pin, converts this serial input to parallel format, checks for bits or characters that are unique to the communication technique and sends an "assembled" character to the CPU.

Transmitter
The transmitter accepts parallel data from the CPU, converts it to a serial bit stream, inserts the appropriate characters or bits (based on the communication technique) and outputs a composite serial stream of data on the TxD output pin.

Modem Control
The modem control section provides interfacing for three input signals and three output signals used for "handshaking" and status indication between the CPU and a modem.

SYN/DLE Control
This section contains control circuitry and three 8-bit registers storing the SYN1, SYN2, and DLE characters provided by the CPU. These registers are used in the synchronous mode of operation to provide the characters required for synchronization, idle fill and data transparency.

Table 1 BAUD RATE GENERATOR CHARACTERISTICS (Cont'd)

Set B (BRCLK = 4.9152MHz)

MR23-20	BAUD RATE	ACTUAL FREQUENCY 16X CLOCK	PERCENT ERROR	DIVISOR
0000	45.5	0.7279kHz	0.005	6752
0001	50	0.8	-	6144
0010	75	1.2	-	4096
0011	110	1.7598	−0.01	2793
0100	134.5	2.152	-	2284
0101	150	2.4	-	2048
0110	300	4.8	-	1024
0111	600	9.6	-	512
1000	1200	19.2	-	256
1001	1800	28.7438	−0.19	171
1010	2000	31.9168	−0.26	154
1011	2400	38.4	-	128
1100	4800	76.8	-	64
1101	9600	153.6	-	32
1110	19200	307.2	-	16
1111	38400	614.4	-	8

Set C (BRCLK = 5.0688MHz)

MR23-20	BAUD RATE	ACTUAL FREQUENCY 16X CLOCK	PERCENT ERROR	DIVISOR
0000	50	0.8kHz	-	6336
0001	75	1.2	-	4224
0010	110	1.76	-	2880
0011	134.5	2.1523	0.016	2355
0100	150	2.4	-	2112
0101	300	4.8	-	1056
0110	600	9.6	-	528
0111	1200	19.2	-	264
1000	1800	28.8	-	176
1001	2000	32.081	0.253	158
1010	2400	38.4	-	132
1011	3600	57.6	-	88
1100	4800	76.8	-	66
1101	7200	115.2	-	44
1110	9600	153.6	-	33
1111	19200	316.8	3.125	16

NOTE
16X clock is used in asynchronous mode. In synchronous mode, clock multiplier is 1X and BRG can be used only for TxC.

ORDERING CODE

PACKAGES	COMMERCIAL RANGES V_{CC} = 5V ±5%, T_A = 0°C to 70°C	
Ceramic DIP	MC2661A/MC68661A MC2661B/MC68661B MC2661C/MC68661C	See table 1 for baud rates
Plastic DIP	MC2661A/MC68661A MC2661B/MC68661B MC2661C/MC68661C	See table 1 for baud rates

Table 2 CPU-RELATED SIGNALS

PIN NAME	PIN NO.	INPUT/ OUTPUT	FUNCTION
V_{CC}	26	I	+5V supply input
GND	4	I	Ground
RESET	21	I	A high on this input performs a master reset on the 2661. This signal asynchronously terminates any device activity and clears the mode, command and status registers. The device assumes the idle state and remains there until initialized with the appropriate control words.
A_1-A_0	10,12	I	Address lines used to select internal EPCI registers.
$\overline{R}/W$	13	I	Read command when low, write command when high.
$\overline{CE}$	11	I	Chip enable command. When low, indicates that control and data lines to the EPCI are valid and that the operation specified by the $\overline{R}/W$, A_1 and A_0 inputs should be performed. When high, places the D_0-D_7 lines in the three-state condition.
D_7-D_0	8,7,6,5, 2,1,28,17	I/O	8-bit, three-state data bus used to transfer commands, data and status between EPCI and the CPU. D_0 is the least significant bit; D_7 the most significant bit.
$\overline{TxRDY}$	15	O	This output is the complement of status register bit SR0. When low, it indicates that the transmit data holding register (THR) is ready to accept a data character from the CPU. It goes high when the data character is loaded. This output is valid only when the transmitter is enabled. It is an open drain output which can be used as an interrupt to the CPU.
$\overline{RxRDY}$	14	O	This output is the complement of status register bit SR1. When low, it indicates that the receive data holding register (RHR) has a character ready for input to the CPU. It goes high when the RHR is read by the CPU, and also when the receiver is disabled. It is an open drain output which can be used as an interrupt to the CPU.
$\overline{TxEMT}$/ $\overline{DSCHG}$	18	O	This output is the complement of status register bit SR2. When low, it indicates that the transmitter has completed serialization of the last character loaded by the CPU, or that a change of state of the $\overline{DSR}$ or $\overline{DCD}$ inputs has occurred. This output goes high when the status register is read by the CPU, if the TxEMT condition does not exist. Otherwise, the THR must be loaded by the CPU for this line to go high. It is an open drain output which can be used as an interrupt to the CPU.

OPERATION

The functional operation of the 2661 is programmed by a set of control words supplied by the CPU. These control words specify items such as synchronous or asynchronous mode, baud rate, number of bits per character, etc. The programming procedure is described in the EPCI programming section of the data sheet.

After programming, the EPCI is ready to perform the desired communications functions. The receiver performs serial to parallel conversion of data received from a modem or equivalent device. The transmitter converts parallel data received from the CPU to a serial bit stream. These actions are accomplished within the framework specified by the control words.

Receiver

The 2661 is conditioned to receive data when the $\overline{DCD}$ input is low and the RxEN bit in the command register is true. In the asynchronous mode, the receiver looks for a high to low (mark to space) transition of the start bit on the RxD input line. If a transition is detected, the state of the RxD line is sampled again after a delay of one-half of a bit time. If RxD is now high, the search for a valid start bit is begun again. If RxD is still low, a valid start bit is assumed and the receiver continues to sample the input line at one bit time intervals until the proper number of data bits, the parity bit, and one stop bit have been assembled. The data are then transferred to the receive data holding register, the RxRDY bit in the status register is set, and the $\overline{RxRDY}$ output is asserted. If the character length is less than 8 bits, the high order unused bits in the holding register are set to zero. The parity error, framing error, and overrun error status bits are strobed into the status register on the positive going edge of $\overline{RxC}$ corresponding to the received character boundary. If the stop bit is present, the receiver will immediately begin its search for the next start bit. If the stop bit is absent (framing error), the receiver will interpret a space as a start bit if it persists into the next bit time interval. If a break condition is detected (RxD is low for the entire character as well as the stop bit), only one character consisting of all zeros (with the FE status bit SR5 set) will be transferred to the holding register. The RxD input must return to a high condition before a search for the next start bit begins.

Pin 25 can be programmed to be a break detect output by appropriate setting of MR27-MR24. If so, a detected break will cause that pin to go high. When RxD returns to mark for one RxC time, pin 25 will go low. Refer to the break detection timing diagram.

Table 3 DEVICE-RELATED SIGNALS

PIN NAME	PIN NO.	INPUT/ OUTPUT	FUNCTION
BRCLK	20	I	Clock input to the internal baud rate generator (see table 1). Not required if external receiver and transmitter clocks are used
*$\overline{RxC}$/BKDET	25	I/O	Receiver clock. If external receiver clock is programmed, this input controls the rate at which the character is to be received. Its frequency is 1X, 16X or 64X the baud rate, as programmed by mode register 1. Data are sampled on the rising edge of the clock. If internal receiver clock is programmed, this pin can be a 1X/16X clock or a break detect output pin.
*$\overline{TxC}$/XSYNC	9	I/O	Transmitter clock. If external transmitter clock is programmed, this input controls the rate at which the character is transmitted. Its frequency is 1X, 16X or 64X the baud rate, as programmed by mode register 1. The transmitted data changes on the falling edge of the clock. If internal transmitter clock is programmed, this pin can be a 1X/16X clock output or an external jam synchronization input.
RxD	3	I	Serial data input to the receiver. "Mark" is high, "space" is low.
TxD	19	O	Serial data output from the transmitter. "Mark" is high, "space" is low. Held in mark condition when the transmitter is disabled.
$\overline{DSR}$	22	I	General purpose input which can be used for data set ready or ring indicator condition. Its complement appears as status register bit SR7. Causes a low output on $\overline{TxEMT}/\overline{DSCHG}$ when its state changes if CR2 or CR0 = 1.
$\overline{DCD}$	16	I	Data carrier detect input. Must be low in order for the receiver to operate. Its complement appears as status register bit SR6. Causes a low output on $\overline{TxEMT}/\overline{DSCHG}$ when its state changes if CR2 or CR0 = 1. If $\overline{DCD}$ goes high while receiving, the RxC is internally inhibited.
$\overline{CTS}$	17	I	Clear to send input. Must be low in order for the transmitter to operate. If it goes high during transmission, the character in the transmit shift register will be transmitted before termination.
$\overline{DTR}$	24	O	General purpose output which is the complement of command register bit CR1. Normally used to indicate data terminal ready.
$\overline{RTS}$	23	O	General purpose output which is the complement of command register bit CR5. Normally used to indicate request to send. If the transmit shift register is not empty when CR5 is reset (1 to 0), then $\overline{RTS}$ will go high one TxC time after the last serial bit is transmitted.

NOTE
*$\overline{RxC}$ and $\overline{TxC}$ outputs have short circuit protection max C_L = 100pF. Outputs become open circuited upon detection of a zero pulled high or a one pulled low

When the EPCI is initialized into the synchronous mode, the receiver first enters the hunt mode on a 0 to 1 transition of RxEN(CR2). In this mode, as data are shifted into the receiver shift register a bit at a time, the contents of the register are compared to the contents of the SYN1 register. If the two are not equal, the next bit is shifted in and the comparison is repeated. When the two registers match, the hunt mode is terminated and character assembly mode begins. If single SYN operation is programmed, the SYN DETECT status bit is set. If double SYN operation is programmed, the first character assembled after SYN1 must be SYN2 in order for the SYN DETECT bit to be set. Otherwise, the EPCI returns to the hunt mode. (Note that the sequence SYN1-SYN1-SYN2 will not achieve synchronization.) When synchronization has been achieved, the EPCI continues to assemble characters and transfer them to the holding register, setting the RxRDY status bit and asserting the $\overline{RxRDY}$ output each time a character is transferred. The PE and OE status bits are set as appropriate. Further receipt of the appropriate SYN sequence sets the SYN DETECT status bit. If the SYN stripping mode is commanded, SYN characters are not transferred to the holding register. Note that the SYN characters used to establish initial synchronization are not transferred to the holding register in any case.

External jam synchronization can be achieved via pin 9 by appropriate setting of MR27-MR24. When pin 9 is an XSYNC input, the internal SYN1, SYN1-SYN2, and DLE-SYN1 detection is disabled. Each positive going signal on XSYNC will cause the receiver to establish synchronization on the rising edge of the next RxC pulse. Character assembly will start with the RxD input at this edge. XSYNC may be lowered on the next rising edge of RxC. This external synchronization will cause the SYN DETECT status bit to be set until the status register is read. Refer to XSYNC timing diagram.

Transmitter

The EPCI is conditioned to transmit data when the $\overline{CTS}$ input is low and the TxEN command register bit is set. The 2661 indicates to the CPU that it can accept a character for transmission by setting the TxRDY status bit and asserting the $\overline{TxRDY}$ output. When the CPU writes a character into the transmit data holding register, these conditions are negated. Data are transferred from the holding register to the transmit shift register when it is idle or has completed transmission of the previous character. The TxRDY conditions are then asserted again. Thus, one full character time of buffering is provided.

In the asynchronous mode, the transmitter automatically sends a start bit followed by the programmed number of data bits, the least significant bit being sent first. It then appends an optional odd or even parity bit and the programmed number of stop bits. If, following transmission of the data bits, a new character is not available in the transmit holding register, the TxD output remains in the marking (high) condition and the $\overline{TxEMT}/\overline{DSCHG}$ output and its corresponding status bit are asserted. Transmission resumes when the CPU loads a new character into the holding register. The transmitter can be forced to output a continuous low (BREAK) condition by setting the send break command bit (CR3) high.

In the synchronous mode, when the 2661 is initially conditioned to transmit, the TxD output remains high and the TxRDY condition is asserted until the first character to be transmitted (usually a SYN character) is loaded by the CPU. Subsequent to this, a continuous stream of characters is transmitted. No extra bits (other than parity, if commanded) are generated by the EPCI unless the CPU fails to send a new character to the EPCI by the time the transmitter has completed sending the previous character. Since synchronous communication does not allow gaps between characters, the EPCI asserts TxEMT and automatically "fills" the gap by transmitting SYN1s, SYN1-SYN2 doublets, or DLE-SYN1 doublets, depending on the state of MR16 and MR17. Normal transmission of the message resumes when a new character is available in the transmit data holding register. If the SEND DLE bit in the command register is true, the DLE character is automatically transmitted prior to transmission of the message character in the THR.

EPCI PROGRAMMING

Prior to initiating data communications, the 2661 operational mode must be programmed by performing write operations to the mode and command registers. In addition, if synchronous operation is programmed, the appropriate SYN/DLE registers must be loaded. The EPCI can be reconfigured at any time during program execution. A flowchart of the intialization process appears in figure 1.

The internal registers of the EPCI are accessed by applying specific signals to the $\overline{CE}$, $\overline{R}/W$, A_1 and A_0 inputs. The conditions necessary to address each register are shown in table 4.

The SYN1, SYN2, and DLE registers are accessed by performing write operations with the conditions $A_1 = 0$, $A_0 = 1$, and

Table 4 MC2661/MC68661 REGISTER ADDRESSING

$\overline{CE}$	A_1	A_0	$\overline{R}/W$	FUNCTION
1	X	X	X	Three-state data bus
0	0	0	0	Read receive holding register
0	0	0	1	Write transmit holding register
0	0	1	0	Read status register
0	0	1	1	Write SYN1/SYN2/DLE registers
0	1	0	0	Read mode registers ½
0	1	0	1	Write mode registers ½
0	1	1	0	Read command register
0	1	1	1	Write command register

NOTE
See AC characteristics section for timing requirements

MC2661/MC68661 INITIALIZATION FLOW CHART

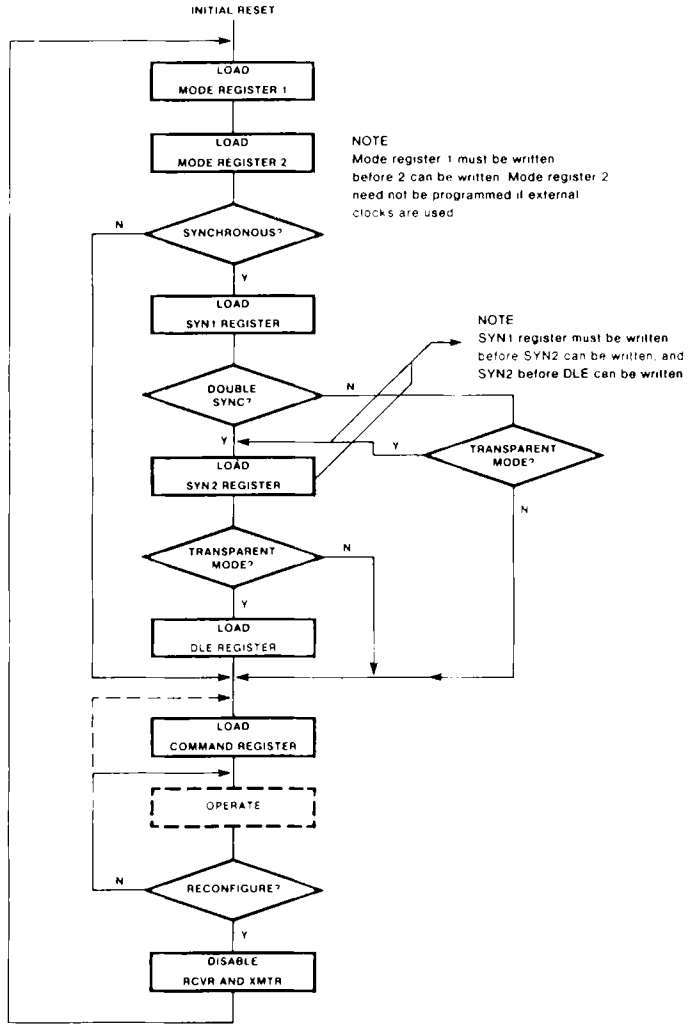


Figure 1

$\overline{R}/W$ = 1. The first operation loads the SYN1 register. The next loads the SYN2 register, and the third loads the DLE register. Reading or loading the mode registers is done in a similar manner. The first write (or read) operation addresses mode register 1, and a subsequent operation addresses mode register 2. If more than the required number of accesses are made, the internal sequencer recycles to point at the first register. The pointers are reset to SYN1 register and mode register 1 by a RESET input or by performing a read command register operation, but are unaffected by any other read or write operation.

The 2661 register formats are summarized in tables 5, 6, 7 and 8. Mode registers 1 and 2 define the general operational characteristics of the EPCI, while the command register controls the operation within this basic framework. The EPCI indicates its status in the status register. These registers are cleared when a RESET input is applied.

Mode Register 1 (MR1)

Table 5 illustrates Mode Register 1. Bits MR11 and MR10 select the communication format and baud rate multiplier. 00 specifies synchronous mode and 1X multiplier. 1X, 16X, and 64X multipliers are programmable for asynchronous format. However, the multiplier in asynchronous format applies only if the external clock input option is selected by MR24 or MR25.

MR13 and MR12 select a character length of 5, 6, 7 or 8 bits. The character length does not include the parity bit, if programmed, and does not include the start and stop bits in asynchronous mode.

MR14 controls parity generation. If enabled, a parity bit is added to the transmitted character and the receiver performs a parity check on incoming data. MR15 selects odd or even parity when parity is enabled by MR14.

In asynchronous mode, MR17 and MR16 select character framing of 1, 1.5, or 2 stop bits. (If 1X baud rate is programmed, 1.5 stop bits defaults to 1 stop bits on transmit.) In synchronous mode, MR17 controls the number of SYN characters used to establish synchronization and for character fill when the transmitter is idle. SYN1 alone is used if MR17 = 1, and SYN1-SYN2 is used when MR17 = 0. If the transparent mode is specified by MR16, DLE-SYN1 is used for character fill and SYN detect, but the normal synchronization sequence is used to establish character sync. When transmitting, a DLE character in the transmit holding register will cause a second DLE character to be transmitted. This DLE stuffing eliminates the software DLE compare and stuff on each transparent mode data character. If the send DLE command (CR3) is active when a DLE is loaded into THR, only one additional DLE will be transmitted. Also, DLE stripping and DLE detect (with MR14 = 0) are enabled.

The bits in the mode register affecting character assembly and disassembly (MR12-MR16) can be changed dynamically (during active receive/transmit operation). The character mode register affects both the transmitter and receiver; therefore in synchronous mode, changes should be made only in half duplex mode (RxEN = 1 or TxEN = 1, but not both simultaneously = 1). In asynchronous mode, character changes should be made when RxEN and TxEN=0 or when TxEN = 1 and the transmitter is marking in half duplex mode (RxEN = 0).

To effect assembly/disassembly of the next received/transmitted character, MR12-15 must be changed within n bit times of the active going state of $\overline{RxRDY}$/TxRDY. Transparent and non-transparent mode changes (MR16) must occur within n-1 bit times of the character to be affected when the receiver or transmitter is active. (n = smaller of the new and old character lengths.)

Mode Register 2 (MR2)

Table 6 illustrates mode register 2. MR23, MR22, MR21 and MR20 control the frequency of the internal baud rate generator (BRG). Sixteen rates are selectable for each EPCI version (A, B, C). Versions A and B specify a 4.9152 MHz TTL input at BRCLK (pin 20); version C specifies a 5.0688 MHz input which is identical to the Signetics 2651. MR23-20 are don't cares if external clocks are selected (MR25-MR24 = 0). The individual rates are given in table 1.

MR24-MR27 select the receive and transmit clock source (either the BRG or an external input) and the function at pins 9 and 25. Refer to table 6.

Command Register (CR)

Table 7 illustrates the command register. Bits CR0 (TxEN) and CR2 (RxEN) enable or disable the transmitter and receiver respectively. A 0 to 1 transition of CR2 forces start bit search (async mode) or hunt mode (sync mode) on the second $\overline{RxC}$ rising edge. Disabling the receiver causes $\overline{RxRDY}$ to go high (inactive). If the transmitter is disabled, it will complete the transmission of the character in the transmit shift register (if any) prior to terminating operation. The TxD output will then remain in the marking state

Table 5 MODE REGISTER 1 (MR 1)

MR17 MR16		MR15	MR14	MR13 MR12	MR11 MR10
Sync/Async		Parity Type	Parity Control	Character Length	Mode and Baud Rate Factor
Async: Stop Bit Length 00 = Invalid 01 = 1 stop bit 10 = 1½ stop bits 11 = 2 stop bits		0 = Odd 1 = Even	0 = Disabled 1 = Enabled	00 = 5 bits 01 = 6 bits 10 = 7 bits 11 = 8 bits	00 = Synchronous 1X rate 01 = Asynchronous 1X rate 10 = Asynchronous 16X rate 11 = Asynchronous 64X rate
Sync: Number of SYN char 0 = Double SYN 1 = Single SYN	**Sync: Transparency Control** 0 = Normal 1 = Transparent				

NOTE
Baud rate factor in asynchronous applies only if external clock is selected. Factor is 16X if internal clock is selected. Mode must be selected (MR11, MR10) in any case.

Table 6 MODE REGISTER 2 (MR2)

MR27–MR24											MR23–MR20
	TxC	RxC	Pin 9	Pin 25		TxC	RxC	Pin 9	Pin 25	Mode	Baud Rate Selection
0000	E	E	TxC	RxC	1000	E	E	XSYNC[1]	RxC/TxC	sync	
0001	E	I	TxC	1X	1001	E	I	TxC	BKDET	async	
0010	I	E	1X	RxC	1010	I	E	XSYNC[1]	RxC	sync	
0011	I	I	1X	1X	1011	I	I	1X	BKDET	async	See baud rates in table 1
0100	E	E	TxC	RxC	1100	E	E	XSYNC[1]	RxC/TxC	sync	
0101	E	I	TxC	16X	1101	E	I	TxC	BKDET	async	
0110	I	E	16X	RxC	1110	I	E	XSYNC[1]	RxC	sync	
0111	I	I	16X	16X	1111	I	I	16X	BKDET	async	

NOTES
1. When pin 9 is programmed as XSYNC input, SYN1, SYN1-SYN2, and DLE-SYN1 detection is disabled.
E = External clock
I = Internal clock (BRG)
1X and 16X are clock outputs

Table 7 COMMAND REGISTER (CR)

CR7 CR6	CR5	CR4	CR3	CR2	CR1	CR0
Operating Mode	**Request To Send**	**Reset Error**	**Sync/Async**	**Receive Control (RxEN)**	**Data Terminal Ready**	**Transmit Control (TxEN)**
00 = Normal operation 01 = Async: Automatic echo mode Sync: SYN and/or DLE stripping mode 10 = Local loop back 11 = Remote loop back	0 = Force $\overline{RTS}$ output high one clock time after TxSR serialization 1 = Force $\overline{RTS}$ output low	0 = Normal 1 = Reset error flags in status register (FE, OE, PE/DLE detect)	**Async:** **Force break** 0 = Normal 1 = Force break	0 = Disable 1 = Enable	0 = Force $\overline{DTR}$ output high 1 = Force $\overline{DTR}$ output low	0 = Disable 1 = Enable
			Sync: **Send DLE** 0 = Normal 1 = Send DLE			

Table 8 STATUS REGISTER (SR)

SR7	SR6	SR5	SR4	SR3	SR2	SR1	SR0
Data Set Ready	Data Carrier Detect	FE/SYN Detect	Overrun	PE/DLE Detect	TxEMT DSCHG	RxRDY	TxRDY
0 = $\overline{DSR}$ input is high 1 = $\overline{DSR}$ input is low	0 = $\overline{DCD}$ input is high 1 = $\overline{DCD}$ input is low	**Async:** 0 = Normal 1 = Framing Error	0 = Normal 1 = Overrun Error	**Async:** 0 = Normal 1 = Parity error	0 = Normal 1 = Change in $\overline{DSR}$, or $\overline{DCD}$, or transmit shift register is empty	0 = Receive holding register empty 1 = Receive holding register has data	0 = Transmit holding register busy 1 = Transmit holding register empty
		Sync: 0 = Normal 1 = SYN detected		**Sync:** 0 = Normal 1 = Parity error or DLE received			

(high) while $\overline{TxRDY}$ and $\overline{TxEMT}$ will go high (inactive). If the receiver is disabled, it will terminate operation immediately. Any character being assembled will be neglected. A 0 to 1 transition of CR2 will initiate start bit search (async) or hunt mode (sync).

Bits CR1 (DTR) and CR5 (RTS) control the $\overline{DTR}$ and $\overline{RTS}$ outputs. Data at the outputs are the logical complement of the register data.

In asynchronous mode, setting CR3 will force and hold the TxD output low (spacing condition) at the end of the current transmitted character. Normal operation resumes when CR3 is cleared. The TxD line will go high for at least one bit time before beginning transmission of the next character in the transmit data holding register. In synchronous mode, setting CR3 causes the transmission of the DLE register contents prior to sending the character in the transmit data holding register. Since this is a one time command, CR3 does not have to be reset by software. CR3 should be set when entering and exiting transparent mode and for all DLE—non-DLE character sequences.

Setting CR4 causes the error flags in the status register (SR3, SR4, and SR5) to be cleared. This is a one time command. There is no internal latch for this bit.

Table 9 MC2661/MC68661 EPCI vs SIGNETICS 2651 PCI

FEATURE	EPCI	PCI
1. MR2 Bit 6, 7	Control pin 9, 25	Not used
2. DLE detect-SR3	SR3 = 0 for DLE-DLE, DLE-SYNC1	SR3 = 1 for DLE-DLE, DLE-SYNC1
3. Reset of SR3, DLE detect	Second character after DLE, or receiver disable, or CR4 = 1	Receiver disable, or CR4 = 1
4. Send DLE-CR3	One time command	Reset via CR3 on next $\overline{\text{TxRDY}}$
5. DLE stuffing in transparent mode	Automatic DLE stuffing when DLE is loaded except if CR3 = 1	None
6. SYNC1 stripping in double sync non-transparent mode	All SYNC1	First SYNC1 of pair
7. Baud rate versions	Three	One
8. Terminate ASYNC transmission (drop RTS)	Reset CR5 in response to $\overline{\text{TxRDY}}$ changing from 0 to 1	Reset CR0 when $\overline{\text{TxEMT}}$ goes from 1 to 0. Then reset CR5 when $\overline{\text{TxEMT}}$ goes from 0 to 1
9. Break detect	Pin 25[1]	FE and null character
10. Stop bit searched	One	Two
11. External jam sync	Pin 9[2]	No
12. Data bus timing	Improved over 2651	—
13. Data bus drivers	Sink 2.2mA	Sink 1.6mA
	Source 400μA	Source 100μA

NOTES
1. Internal BRG used for RxC
2. Internal BRG used for TxC

When CR5 (RTS) is set, the $\overline{\text{RTS}}$ pin is forced low and the transmit serial logic is enabled. A 1 to 0 transition of CR5 will cause $\overline{\text{RTS}}$ to go high (inactive) one TxC time after the last serial bit has been transmitted (if the transmit shift register was not empty).

The EPCI can operate in one of four sub-modes within each major mode (synchronous or asynchronous). The operational sub-mode is determined by CR7 and CR6. CR7-CR6 = 00 is the normal mode, with the transmitter and receiver operating independently in accordance with the mode and status register instructions.

In asynchronous mode, CR7-CR6 = 01 places the EPCI in the automatic echo mode. Clocked, regenerated received data are automatically directed to the TxD line while normal receiver operation continues. The receiver must be enabled (CR2 = 1), but the transmitter need not be enabled. CPU to receiver communications continues normally, but the CPU to transmitter link is disabled. Only the first character of a break condition is echoed. The TxD output will go high until the next valid start is detected. The following conditions are true while in automatic echo mode:

1. Data assembled by the receiver are automatically placed in the transmit holding register and retransmitted by the transmitter on the TxD output.
2. The transmitter is clocked by the receive clock.
3. $\overline{\text{TxRDY}}$ output = 1.
4. The $\overline{\text{TxEMT}}/\overline{\text{DSCHG}}$ pin will reflect only the data set change condition.
5. The TxEN command (CR0) is ignored.

In synchronous mode, CR7-CR6 = 01 places the EPCI in the automatic SYN/DLE stripping mode. The exact action taken depends on the setting of bits MR17 and MR16:

1. In the non-transparent, single SYN mode (MR17-MR16 = 10), characters in the data stream matching SYN1 are not transferred to the receive data holding register (RHR).
2. In the non-transparent, double SYN mode (MR17-MR16 = 00), characters in the data stream matching SYN1, or SYN2 if immediately preceded by SYN1, are not transferred to the RHR.
3. In transparent mode (MR16 = 1), characters in the data stream matching DLE, or SYN1 if immediately preceded by DLE, are not transferred to the RHR. However, only the first DLE of a DLE-DLE pair is stripped.

Note that automatic stripping mode does not affect the setting of the DLE detect and SYN detect status bits (SR3 and SR5).

Two diagnostic sub-modes can also be configured. In local loop back mode (CR7-CR6 = 10), the following loops are connected internally:

1. The transmitter output is connected to the receiver input.
2. $\overline{\text{DTR}}$ is connected to $\overline{\text{DCD}}$ and $\overline{\text{RTS}}$ is connected to $\overline{\text{CTS}}$.
3. The receiver is clocked by the transmit clock.
4. The $\overline{\text{DTR}}$, $\overline{\text{RTS}}$ and $\overline{\text{TxD}}$ outputs are held high.
5. The $\overline{\text{CTS}}$, $\overline{\text{DCD}}$, $\overline{\text{DSR}}$ and RxD inputs are ignored.

Additional requirements to operate in the local loop back mode are that CR0 (TxEN), CR1 (DTR), and CR5 (RTS) must be set to 1. CR2 (RxEN) is ignored by the EPCI.

The second diagnostic mode is the remote loop back mode (CR7-CR6 = 11). In this mode:

1. Data assembled by the receiver are automatically placed in the transmit holding register and retransmitted by the transmitter on the TxD output.
2. The transmitter is clocked by the receive clock.
3. No data are sent to the local CPU, but the error status conditions (PE, OE, FE) are set.
4. The $\overline{\text{RxRDY}}$, $\overline{\text{TxRDY}}$, and $\overline{\text{TxEMT}}/\overline{\text{DSCHG}}$ outputs are held high.
5. CR1 (TxEN) is ignored.
6. All other signals operate normally.

Status Register

The data contained in the status register (as shown in table 8) indicate receiver and transmitter conditions and modem/data set status.

SR0 is the transmitter ready (TxRDY) status bit. It, and its corresponding output, are valid only when the transmitter is enabled. If equal to 0, it indicates that the transmit data holding register has been loaded by the CPU and the data has not been transferred to the transmit shift register. If set equal to 1, it indicates that the holding register is ready to accept data from the CPU. This bit is initially set when the transmitter is enabled by CR0, unless a character has previously been loaded into the holding register. It is not set when the automatic echo or remote loopback modes are programmed. When this bit is set, the $\overline{\text{TxRDY}}$ output pin is low. In

the automatic echo and remote loop back modes, the output is held high.

SR1, the receiver ready (RxRDY) status bit, indicates the condition of the receive data holding register. If set, it indicates that a character has been loaded into the holding register from the receive shift register and is ready to be read by the CPU. If equal to zero, there is no new character in the holding register. This bit is cleared when the CPU reads the receive data holding register or when the receiver is disabled by CR2. When set, the $\overline{RxRDY}$ output is low.

The TxEMT/DSCHG bit, SR2, when set, indicates either a change of state of the $\overline{DSR}$ or $\overline{DCD}$ inputs (when CR2 or CR0 = 1) or that the transmit shift register has completed transmission of a character and no new character has been loaded into the transmit data holding register. Note that in synchronous mode this bit will be set even though the appropriate "fill" character is transmitted. TxEMT will not go active until at least one character has been transmitted. It is cleared by loading the transmit data holding register. The DSCHG condition is enabled when TxEN = 1 or RxEN = 1. It is cleared when the status register is read by the CPU. If the status register is read twice and SR2 = 1 while SR6 and SR7 remain unchanged, then a TxEMT condition exists. When SR2 is set, the $\overline{TxEMT}/\overline{DSCHG}$ output is low.

SR3, when set, indicates a received parity error when parity is enabled by MR14. In synchronous transparent mode (MR16 = 1), with parity disabled, it indicates that a character matching DLE register was received and the present character is neither SYN1 nor DLE. This bit is cleared when the next character following the above sequence is loaded into RHR, when the receiver is disabled, or by a reset error command, CR4.

The overrun error status bit, SR4, indicates that the previous character loaded into the receive holding register was not read by the CPU at the time a new received character was transferred into it. This bit is cleared when the receiver is disabled or by the reset error command, CR4.

In asynchronous mode, bit SR5 signifies that the received character was not framed by a stop bit, i.e., only the first stop bit is checked. If RHR = 0 when SR5 = 1, a break condition is present. In synchronous non-transparent mode (MR16 = 0), it indicates receipt of the SYN1 character in single SYN mode or the SYN1-SYN2 pair in double SYN mode. In synchronous transparent mode (MR16 = 1), this bit is set upon detection of the initial synchronizing characters (SYN1 or SYN1-SYN2) and, after synchronization has been achieved, when a DLE-SYN1 pair is received. The bit is reset when the receiver is disabled, when the reset error command is given in asynchronous mode, or when the status register is read by the CPU in the synchronous mode.

SR6 and SR7 reflect the conditions of the $\overline{DCD}$ and $\overline{DSR}$ inputs respectively. A low input sets its corresponding status bit, and a high input clears it.

ABSOLUTE MAXIMUM RATINGS[1]

PARAMETER	RATING	UNIT
Operating ambient temperature[2]	0 to +70	°C
Storage temperature	−55 to +150	°C
All voltages with respect to ground[3]	−0.3 to +7.0	V

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	VALUE	UNIT
Thermal Resistance			
Ceramic		50	
Plastic	θ_{JA}	100	°C/W
Cerdip		60	

DC ELECTRICAL CHARACTERISTICS T_A = 0°C to +70°C, V_{CC} = 5.0V ±5%[4,5,6]

PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
	Input voltage					V
V_{IL}	Low		−0.3		0.8	
V_{IH}	High		2.0		V_{CC}	
	Output voltage					V
V_{OL}	Low	I_{OL} = 2.2mA			0.4	
V_{OH}[7]	High	I_{OH} = −400μA	2.4			
I_{IL}	Input leakage current	V_{IN} = 0 to 5.5 V			10	μA
	3-state output leakage current					μA
I_{LH}	Data bus high	V_{OUT} = 0 to 5.25 V			10	
I_{LL}	Data bus low				10	
I_{CC}	Power supply current				150	mA

CAPACITANCE T_A = 25°C, V_{CC} = 0V

PARAMETER		TEST CONDITIONS	LIMITS			UNIT
			Min	Typ	Max	
	Capacitance	V_{IN} = V_{OUT} = 0 V				pF
C_{IN}	Input				20	
C_{OUT}	Output	fc = 1MHz			20	
$C_{I/O}$	Input/Output	Unmeasured pins tied to ground			20	

Notes on following page

AC ELECTRICAL CHARACTERISTICS T_A = 0°C to +70°C, V_{CC} = 5.0V ± 5% [4,5,6]

	PARAMETER	TEST CONDITIONS	Min	Typ	Max	UNIT
	Pulse width					ns
t_{RES}	Reset		1000			
t_{CE}	Chip enable		250			
	Setup and hold time					ns
t_{AS}	Address setup		10			
t_{AH}	Address hold		10			
t_{CS}	R/W control setup		10			
t_{CH}	R/W control hold		10			
t_{DS}	Data setup for write		150			
t_{DH}	Data hold for write		0			
t_{RXS}	Rx data setup		300			
t_{RXH}	Rx data hold		350			
t_{DD}	Data delay time for read	C_L = 150pF			200	ns
t_{DF}	Data bus floating time for read	C_L = 150pF			100	
t_{CED}	CE to CE delay		600			
	Input clock frequency					MHz
f_{BRG}	Baud rate generator (MC2661A,B/MC68661A,B)		1.0	4.9152	4.9202	
f_{BRG}	Baud rate generator (MC2661C/MC68661C)		1.0	5.0688	5.0738	
$f_{R/T}$	TxC or RxC		dc		1.0	
	Clock width					ns
t_{BRH} [9]	Baud rate high (MC2661A,B/MC68661A,B)		75			
t_{BRH} [9]	Baud rate high (MC2661C/MC68661C)		70			
t_{BRL} [9]	Baud rate low (MC2661A,B/MC68661A,B)		75			
t_{BRL} [9]	Baud rate low (MC2661C/MC68661C)		70			
$t_{R/TH}$	TxC or RxC high		480			
$t_{R/TL}$	TxC or RxC low		480			
t_{TXD}	TxD delay from falling edge of TxC	C_L = 150pF			650	ns
t_{TCS}	Skew between TxD changing and falling edge of TxC output [8]	C_L = 150pF	TBD		TBD	

NOTES

1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or at any other condition above those indicated in the operation section of this specification is not implied.
2. For operating at elevated temperatures, the device must be derated based on +150°C maximum junction temperature and thermal resistance of 60°C/W junction to ambient (IQ ceramic package).
3. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying any voltages larger than the rated maxima.
4. Parameters are valid over operating temperature range unless otherwise specified.
5. All voltage measurements are referenced to ground. All time measurements are at the 50% level for inputs (except t_{BRH} and t_{BRL}) and at 0.8 V and 2.0 V for outputs. Input levels swing between 0.4 V and 2.4 V, with a transition time of 20ns maximum.
6. Typical values are at +25°C, typical supply voltages and typical processing parameters.
7. TxRDY, RxRDY and TxEMT/DSCHG outputs are open drain.
8. Parameter applies when internal transmitter clock is used.
9. Under test conditions of 5.0688 MHz f_{BRG} (MC2661C/MC68661C) and 4.9152 MHz f_{BRG} (MC2661A,B/MC68661A,B), f_{BRH} and t_{BRL} measured at V_{IH} and V_{IL} respectively.

POWER CONSIDERATIONS

The average chip-junction temperature, T_J, in °C can be obtained from:

$$T_J = T_A + (P_D \bullet \theta_{JA}) \quad (1)$$

Where:

T_A = Ambient Temperature, °C

θ_{JA} = Package Thermal Resistance, Junction-to-Ambient, °C/W

$P_D = P_{INT} + P_{PORT}$

$P_{INT} = I_{CC} \times V_{CC}$, Watts – Chip Internal Power

P_{PORT} = Port Power Dissipation, Watts – User Determined

For most applications $P_{PORT} \ll P_{INT}$ and can be neglected. P_{PORT} may become significant if the device is configured to drive Darlington bases or sink LED loads.

An approximate relationship between P_D and T_J (if P_{PORT} is neglected) is:

$$P_D = K \div (T_J + 273°C) \quad (2)$$

Solving equations 1 and 2 for K gives:

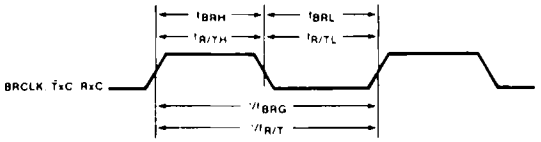
$$K = P_D \bullet (T_A + 273°C) + \theta_{JA} \bullet P_D^2 \quad (3)$$

Where K is a constant pertaining to the particular part. K can be determined from equation 3 by measuring P_D (at equilibrium) for a known T_A. Using this value of K the values of P_D and T_J can be obtained by solving equations (1) and (2) iteratively for any value of T_A.

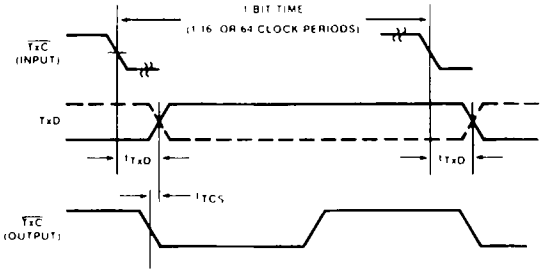
TIMING DIAGRAMS

RESET

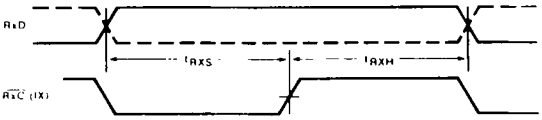
CLOCK



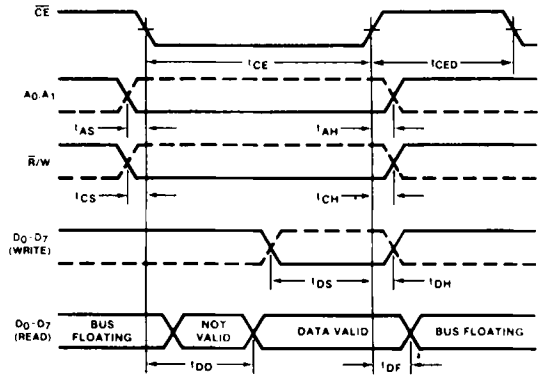
TRANSMIT



RECEIVE

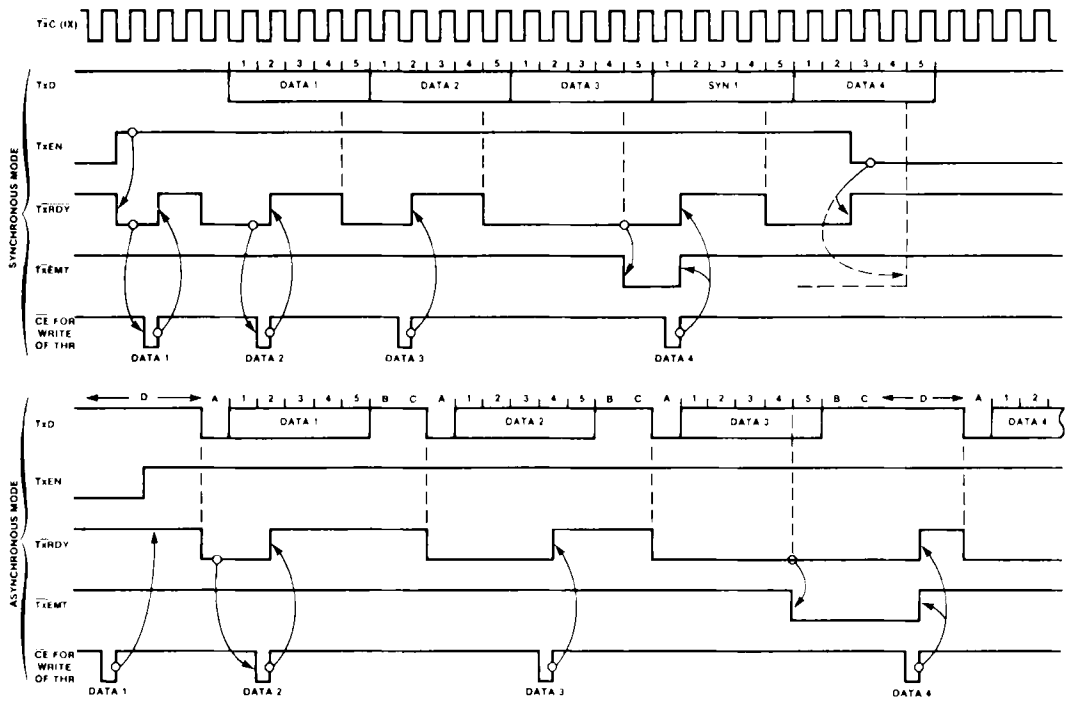


READ AND WRITE



TIMING DIAGRAMS (Cont'd)

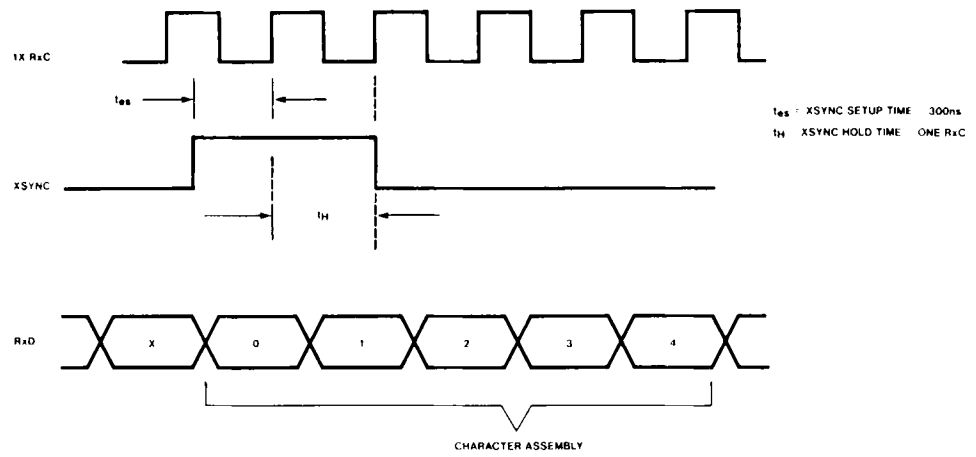
TxRDY, TxEMT (Shown for 5-bit characters, no parity, 2 stop bits (in asynchronous mode))



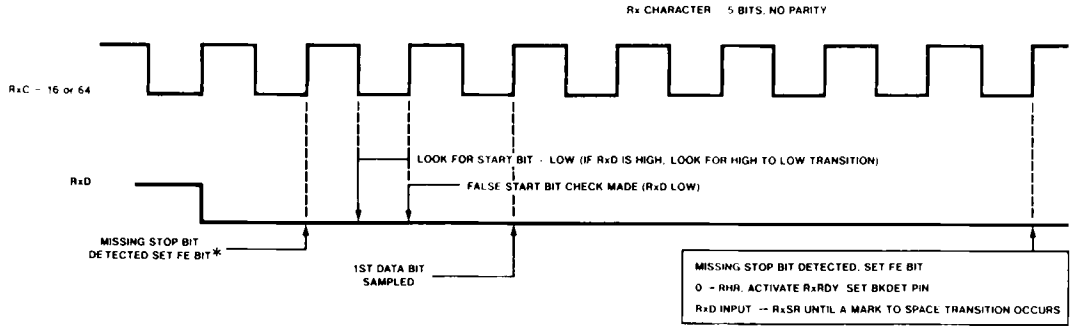
NOTES
A = Start bit
B = Stop bit 1
C = Stop bit 2
D = TxD marking condition
TxEMT goes low at the beginning of the last data bit, or, if parity is enabled, at the beginning of the parity bit

TIMING DIAGRAMS (Cont'd)

EXTERNAL SYNCHRONIZATION WITH XSYNC



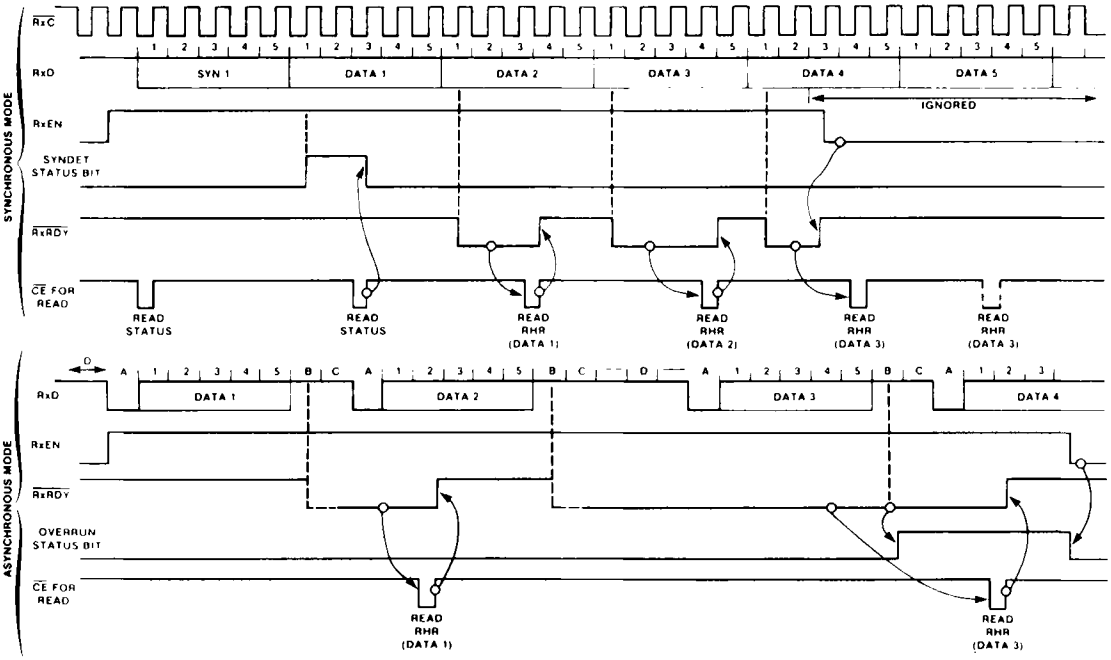
BREAK DETECTION TIMING



NOTE
* If the stop bit is present, the start bit search will commence immediately

TIMING DIAGRAMS (Cont'd)

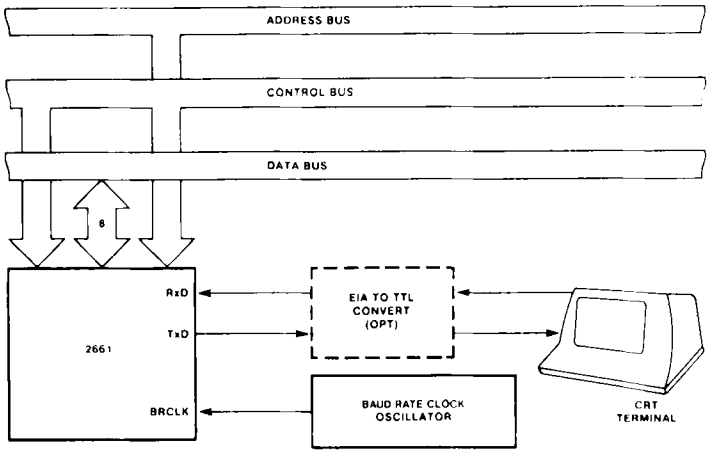
RxRDY (Shown for 5-bit characters, no parity, 2 stops bits [in asynchronous mode])



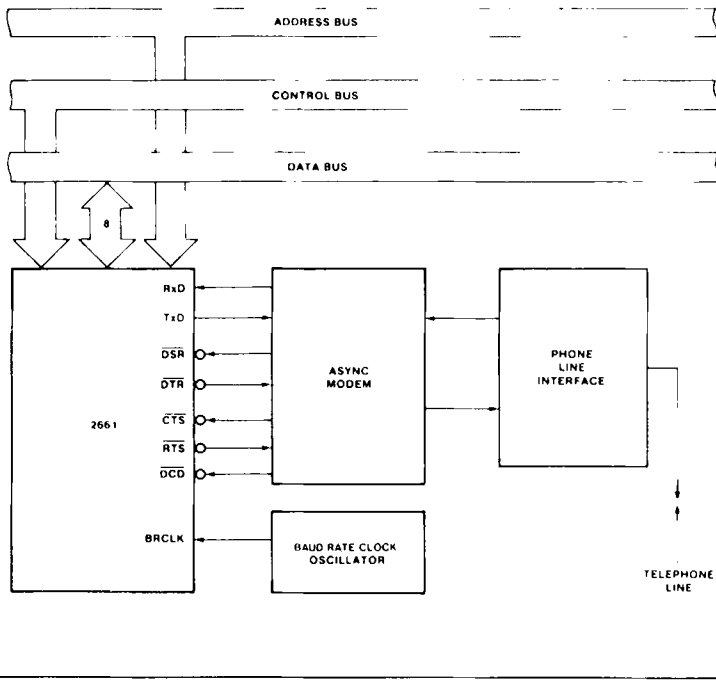
NOTES
A = Start bit
B = Stop bit 1
C = Stop bit 2
D = TxD marking condition
Only one stop bit is detected

TYPICAL APPLICATIONS

ASYNCHRONOUS INTERFACE TO CRT TERMINAL

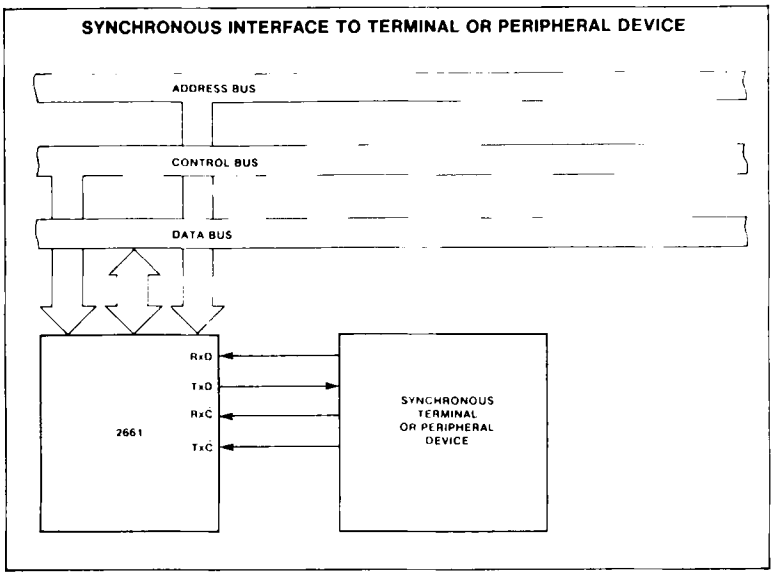


ASYNCHRONOUS INTERFACE TO TELEPHONE LINES

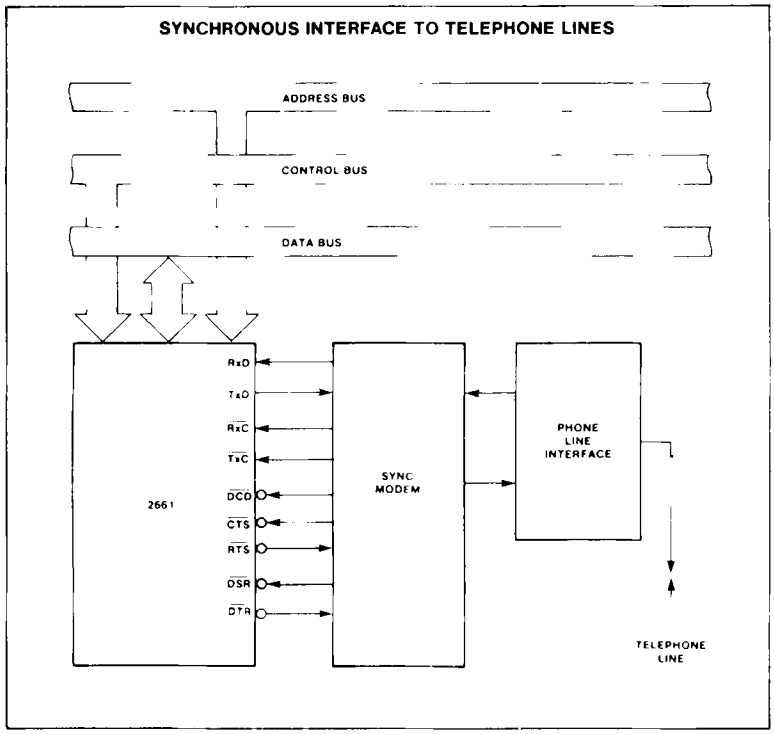


TYPICAL APPLICATIONS (Cont'd)

SYNCHRONOUS INTERFACE TO TERMINAL OR PERIPHERAL DEVICE



SYNCHRONOUS INTERFACE TO TELEPHONE LINES



MC68000 MPU-TO-EPCI INTERFACE REQUIREMENTS

The circuit shown in Figure 2 interfaces the EPCI to the MC68000 MPU. The 8-bit data bus of the EPCI is connected to the low order 8 bits of the MPU data bus (D0-D7). Due to this, the EPCI's registers are addressed on word (even byte) boundaries and so address line A1 of the MPU is connected to the A0 address line of the EPCI. Similarly, A2 of the MPU is connected to A1 of the EPCI. R/$\overline{W}$ on the MC68000 is inverted and connected to $\overline{R}$/W of the EPCI.

The $\overline{CE}$ signal must be generated for the EPCI and the $\overline{DTACK}$ signal must be supplied to the MPU. To allow for the data setup time on a read of the EPCI, $\overline{CE}$ must be delayed one-half clock cycle and $\overline{DTACK}$ generated on the next rising edge of the system clock. This causes the processor to insert one wait state in the bus cycle. In addition to this, $\overline{CE}$ must not be reasserted until the chip enable period t_{CE} has expired. Since some instructions on the MC68000 can cause access to consecutive addresses on consecutive bus cycles (e.g., MOVEP), an INHIBIT signal must be generated to hold-off an access during this period. A state machine consisting of a 74LS161 binary counter and a 74LS74 D flip-flop is configured as a digital "one shot." The rising edge of $\overline{CE}$ starts the counter which times out after given number of clock cycles. Since t_{CE} is 600 ns, a minimum of 5 clock cycles at 8 MHz (625 ns) is required. The timing for two consecutive read bus cycles is shown in Figure 3. The INHIBIT signal prevents $\overline{CE}$ from being generated and $\overline{DTACK}$ from being asserted, causing the processor to generate wait states until INHIBIT is negated.

M6809 FAMILY MPU-TO-EPCI INTERFACE REQUIREMENTS

The M6809 family of microprocessors can be easily interfaced to the EPCI as shown in Figure 4.

FIGURE 2 — MC68000-TO-EPCI INTERFACE — EXAMPLE CIRCUIT

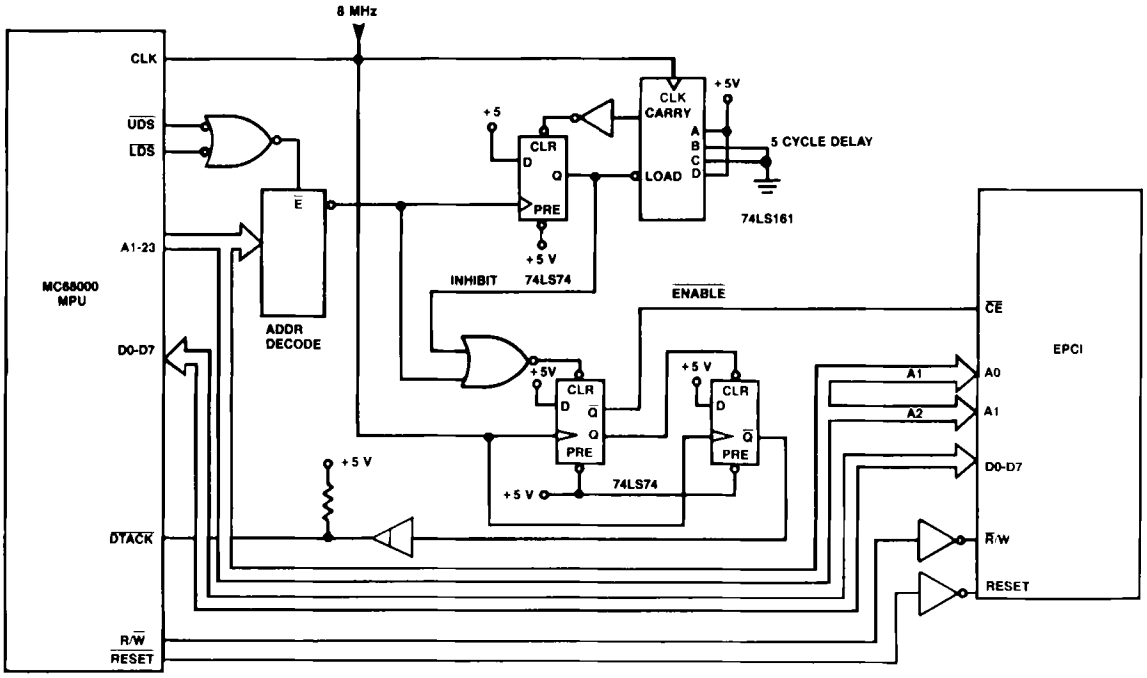
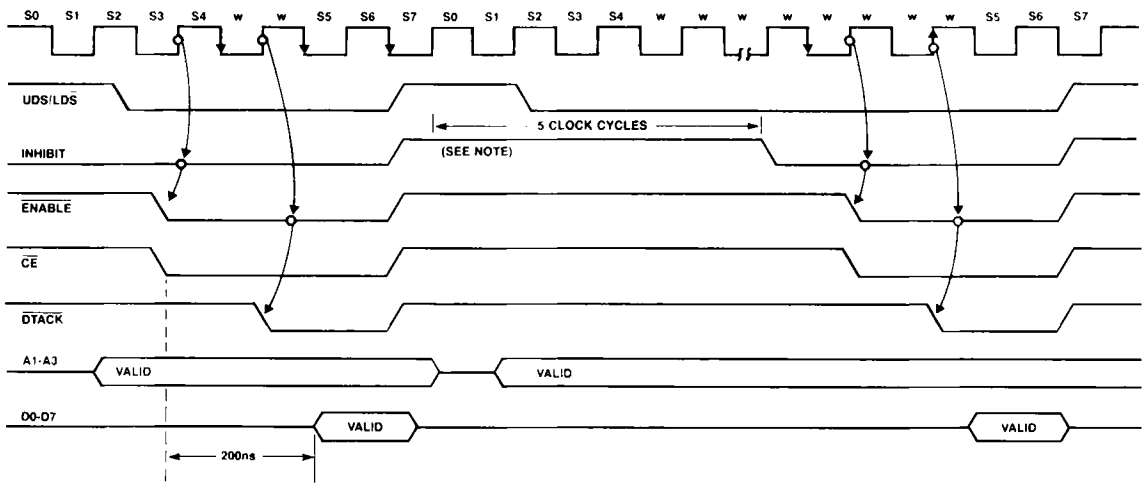
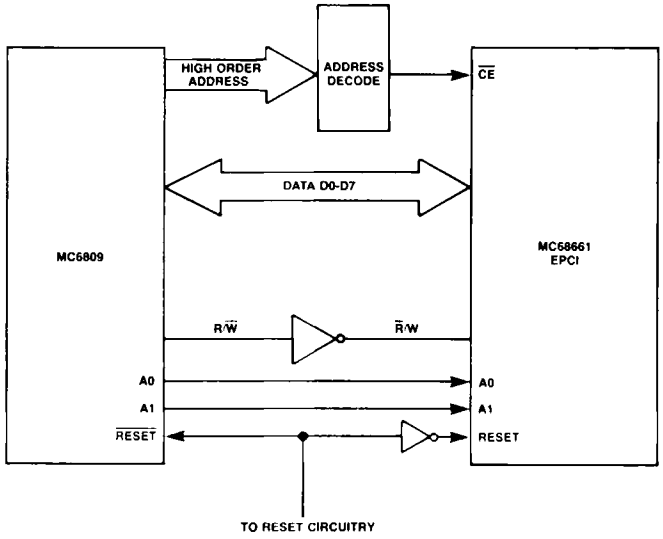


FIGURE 3 — MC68000-TO-EPCI READ BUS CYCLE TIMING

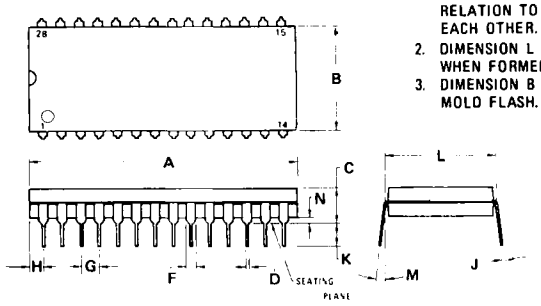


NOTE: INSERTION OF INHIBIT PERIOD DELAYS NEXT READ CYCLE FOR 5 CLOCK CYCLES

FIGURE 4 — INTERFACE CONNECTIONS TO MC6809

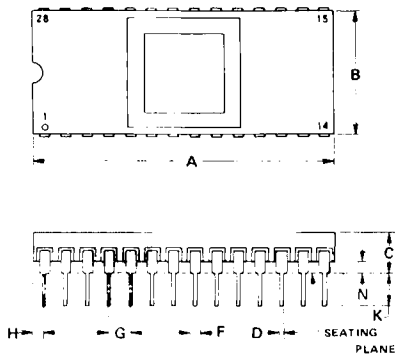


NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25mm(0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.



	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	36.45	37.21	1.435	1.465
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

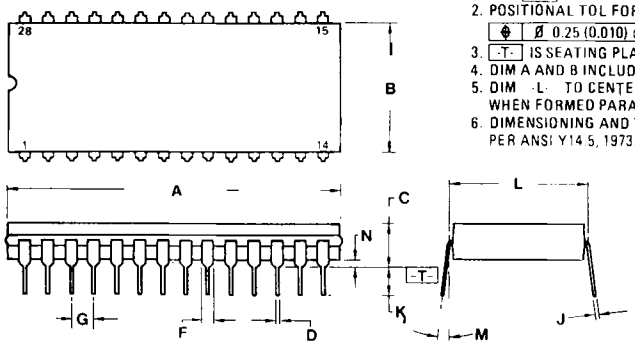
CASE 710



NOTES:
1. LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIAMETER (AT SEATING PLANE) AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	35.20	35.92	1.386	1.414
B	14.73	15.34	0.580	0.604
C	3.05	4.19	0.120	0.165
D	0.38	0.53	0.015	0.021
F	0.76	1.40	0.030	0.055
G	2.54 BSC		0.100 BSC	
H	0.76	1.78	0.030	0.070
J	0.20	0.30	0.008	0.012
K	2.54	4.19	0.100	0.165
L	14.99	15.49	0.590	0.610
M	–	10°	–	10°
N	0.51	1.52	0.020	0.060

CASE 719



NOTES:
1. DIM -A- IS DATUM.
2. POSITIONAL TOL FOR LEADS: ⌖ Ø 0.25 (0.010) Ⓜ T A Ⓜ
3. -T- IS SEATING PLANE.
4. DIM A AND B INCLUDES MENISCUS.
5. DIM -L- TO CENTER OF LEADS WHEN FORMED PARALLEL.
6. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	36.45	37.85	1.435	1.490
B	12.70	15.37	0.500	0.605
C	4.06	5.84	0.160	0.230
D	0.38	0.56	0.015	0.022
F	1.27	1.65	0.050	0.065
G	2.54 BSC		0.100 BSC	
J	0.20	0.30	0.008	0.012
K	2.54	4.06	0.100	0.160
L	15.24 BSC		0.600 BSC	
M	5°	15°	5°	15°
N	0.51	1.27	0.020	0.050

CASE 733

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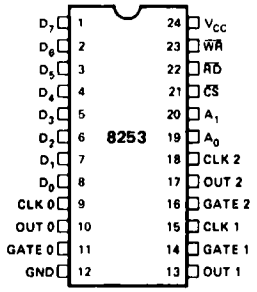
8253/8253-5
PROGRAMMABLE INTERVAL TIMER

- MCS-85™ Compatible 8253-5
- 3 Independent 16-Bit Counters
- DC to 2 MHz
- Programmable Counter Modes
- Count Binary or BCD
- Single +5V Supply
- 24-Pin Dual In-Line Package

The Intel® 8253 is a programmable counter/timer chip designed for use as an Intel microcomputer peripheral. It uses nMOS technology with a single +5V supply and is packaged in a 24-pin plastic DIP.

It is organized as 3 independent 16-bit counters, each with a count rate of up to 2 MHz. All modes of operation are software programmable.

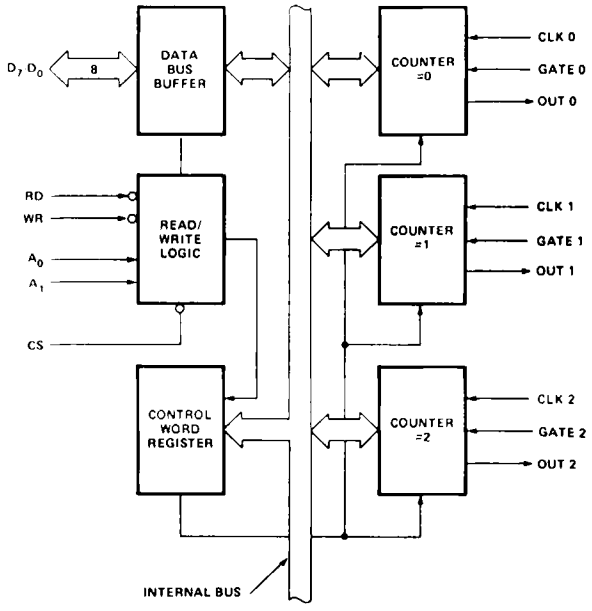
PIN CONFIGURATION



PIN NAMES

D_7 D_0	DATA BUS (8-BIT)
CLK N	COUNTER CLOCK INPUTS
GATE N	COUNTER GATE INPUTS
OUT N	COUNTER OUTPUTS
$\overline{RD}$	READ COUNTER
$\overline{WR}$	WRITE COMMAND OR DATA
$\overline{CS}$	CHIP SELECT
A_0 A_1	COUNTER SELECT
V_{CC}	+5 VOLTS
GND	GROUND

BLOCK DIAGRAM



FUNCTIONAL DESCRIPTION

General

The 8253 is a programmable interval timer/counter specifically designed for use with the Intel™ Microcomputer systems. Its function is that of a general purpose, multi-timing element that can be treated as an array of I/O ports in the system software.

The 8253 solves one of the most common problems in any microcomputer system, the generation of accurate time delays under software control. Instead of setting up timing loops in systems software, the programmer configures the 8253 to match his requirements, initializes one of the counters of the 8253 with the desired quantity, then upon command the 8253 will count out the delay and interrupt the CPU when it has completed its tasks. It is easy to see that the software overhead is minimal and that multiple delays can easily be maintained by assignment of priority levels.

Other counter/timer functions that are non-delay in nature but also common to most microcomputers can be implemented with the 8253.

- Programmable Rate Generator
- Event Counter
- Binary Rate Multiplier
- Real Time Clock
- Digital One-Shot
- Complex Motor Controller

Data Bus Buffer

This 3-state, bi-directional, 8-bit buffer is used to interface the 8253 to the system data bus. Data is transmitted or received by the buffer upon execution of INput or OUTput CPU instructions. The Data Bus Buffer has three basic functions.

1. Programming the MODES of the 8253.
2. Loading the count registers.
3. Reading the count values.

Read/Write Logic

The Read/Write Logic accepts inputs from the system bus and in turn generates control signals for overall device operation. It is enabled or disabled by CS so that no operation can occur to change the function unless the device has been selected by the system logic.

$\overline{RD}$ (Read)

A "low" on this input informs the 8253 that the CPU is inputting data in the form of a counters value.

$\overline{WR}$ (Write)

A "low" on this input informs the 8253 that the CPU is outputting data in the form of mode information or loading counters.

A0, A1

These inputs are normally connected to the address bus. Their function is to select one of the three counters to be operated on and to address the control word register for mode selection.

$\overline{CS}$ (Chip Select)

A "low" on this input enables the 8253. No reading or writing will occur unless the device is selected. The $\overline{CS}$ input has no effect upon the actual operation of the counters.

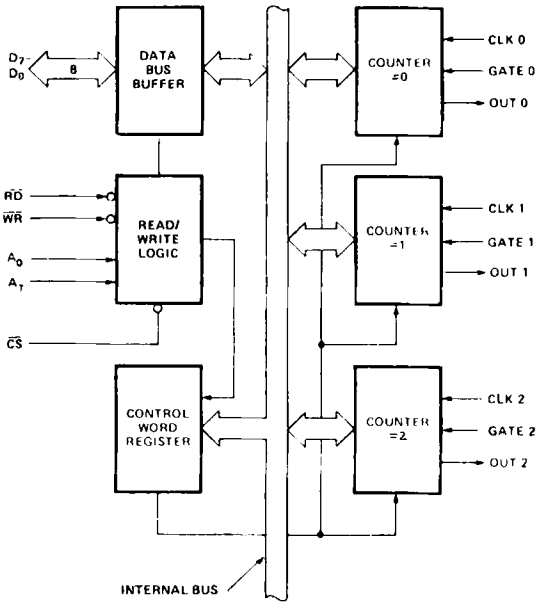


Figure 1. Block Diagram Showing Data Bus Buffer and Read/Write Logic Functions

$\overline{CS}$	$\overline{RD}$	$\overline{WR}$	A_1	A_0	
0	1	0	0	0	Load Counter No. 0
0	1	0	0	1	Load Counter No. 1
0	1	0	1	0	Load Counter No. 2
0	1	0	1	1	Write Mode Word
0	0	1	0	0	Read Counter No. 0
0	0	1	0	1	Read Counter No. 1
0	0	1	1	0	Read Counter No. 2
0	0	1	1	1	No-Operation 3-State
1	X	X	X	X	Disable 3-State
0	1	1	X	X	No-Operation 3-State

Control Word Register

The Control Word Register is selected when A0, A1 are 11. It then accepts information from the data bus buffer and stores it in a register. The information stored in this register controls the operational MODE of each counter, selection of binary or BCD counting and the loading of each count register.

The Control Word Register can only be written into; no read operation of its contents is available.

Counter #0, Counter #1, Counter #2

These three functional blocks are identical in operation so only a single Counter will be described. Each Counter consists of a single, 16-bit, pre-settable, DOWN counter. The counter can operate in either binary or BCD and its input, gate and output are configured by the selection of MODES stored in the Control Word Register.

The counters are fully independent and each can have separate Mode configuration and counting operation, binary or BCD. Also, there are special features in the control word that handle the loading of the count value so that software overhead can be minimized for these functions.

The reading of the contents of each counter is available to the programmer with simple READ operations for event counting applications and special commands and logic are included in the 8253 so that the contents of each counter can be read "on the fly" without having to inhibit the clock input.

8253 SYSTEM INTERFACE

The 8253 is a component of the Intel™ Microcomputer Systems and interfaces in the same manner as all other peripherals of the family. It is treated by the systems software as an array of peripheral I/O ports; three are counters and the fourth is a control register for MODE programming.

Basically, the select inputs A0, A1 connect to the A0, A1 address bus signals of the CPU. The $\overline{CS}$ can be derived directly from the address bus using a linear select method. Or it can be connected to the output of a decoder, such as an Intel® 8205 for larger systems.

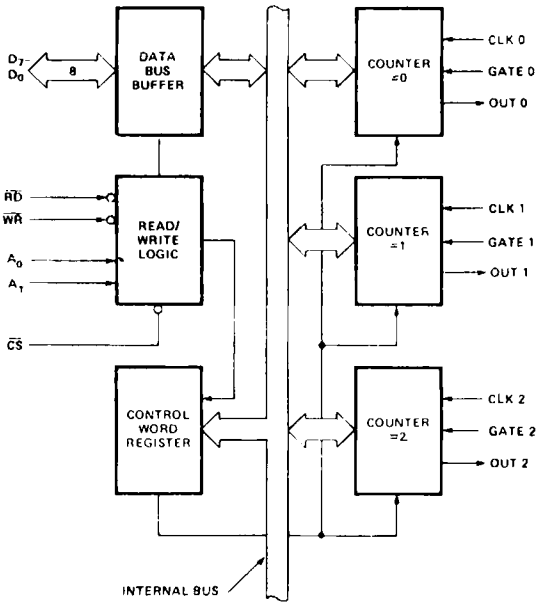


Figure 2. Block Diagram Showing Control Word Register and Counter Functions

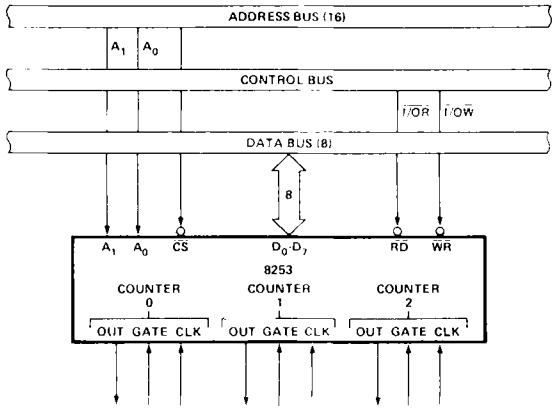


Figure 3. 8253 System Interface

OPERATIONAL DESCRIPTION

General

The complete functional definition of the 8253 is programmed by the systems software. A set of control words must be sent out by the CPU to initialize each counter of the 8253 with the desired MODE and quantity information. Prior to initialization, the MODE, count, and output of all counters is undefined. These control words program the MODE, Loading sequence and selection of binary or BCD counting.

Once programmed, the 8253 is ready to perform whatever timing tasks it is assigned to accomplish.

The actual counting operation of each counter is completely independent and additional logic is provided on-chip so that the usual problems associated with efficient monitoring and management of external, asynchronous events or rates to the microcomputer system have been eliminated.

Programming the 8253

All of the MODES for each counter are programmed by the systems software by simple I/O operations.

Each counter of the 8253 is individually programmed by writing a control word into the Control Word Register. (A0, A1 = 11)

Control Word Format

D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0
SC1	SC0	RL1	RL0	M2	M1	M0	BCD

Definition of Control

SC — Select Counter:

SC1	SC0	
0	0	Select Counter 0
0	1	Select Counter 1
1	0	Select Counter 2
1	1	Illegal

RL — Read/Load:

RL1	RL0	
0	0	Counter Latching operation (see READ/WRITE Procedure Section)
1	0	Read/Load most significant byte only.
0	1	Read/Load least significant byte only.
1	1	Read/Load least significant byte first, then most significant byte.

M — MODE:

M2	M1	M0	
0	0	0	Mode 0
0	0	1	Mode 1
X	1	0	Mode 2
X	1	1	Mode 3
1	0	0	Mode 4
1	0	1	Mode 5

BCD:

0	Binary Counter 16-bits
1	Binary Coded Decimal (BCD) Counter (4 Decades)

Counter Loading

The count register is not loaded until the count value is written (one or two bytes, depending on the mode selected by the RL bits), followed by a rising edge and a falling edge of the clock. Any read of the counter prior to that falling clock edge may yield invalid data.

MODE Definition

MODE 0: Interrupt on Terminal Count. The output will be initially low after the mode set operation. After the count is loaded into the selected count register, the output will remain low and the counter will count. When terminal count is reached the output will go high and remain high until the selected count register is reloaded with the mode or a new count is loaded. The counter continues to decrement after terminal count has been reached.

Rewriting a counter register during counting results in the following:

(1) Write 1st byte stops the current counting.
(2) Write 2nd byte starts the new count.

MODE 1: Programmable One-Shot. The output will go low on the count following the rising edge of the gate input.

The output will go high on the terminal count. If a new count value is loaded while the output is low it will not affect the duration of the one-shot pulse until the succeeding trigger. The current count can be read at any time without affecting the one-shot pulse.

The one-shot is retriggerable, hence the output will remain low for the full count after any rising edge of the gate input.

MODE 2: Rate Generator. Divide by N counter. The output will be low for one period of the input clock. The period from one output pulse to the next equals the number of input counts in the count register. If the count register is reloaded between output pulses the present period will not be affected, but the subsequent period will reflect the new value.

The gate input, when low, will force the output high. When the gate input goes high, the counter will start from the initial count. Thus, the gate input can be used to synchronize the counter.

When this mode is set, the output will remain high until after the count register is loaded. The output then can also be synchronized by software.

MODE 3: Square Wave Rate Generator. Similar to MODE 2 except that the output will remain high until one half the count has been completed (for even numbers) and go low for the other half of the count. This is accomplished by decrementing the counter by two on the falling edge of each clock pulse. When the counter reaches terminal count, the state of the output is changed and the counter is reloaded with the full count and the whole process is repeated.

If the count is odd and the output is high, the first clock pulse (after the count is loaded) decrements the count by 1. Subsequent clock pulses decrement the clock by 2. After timeout, the output goes low and the full count is reloaded. The first clock pulse (following the reload) decrements the counter by 3. Subsequent clock pulses decrement the count by 2 until timeout. Then the whole process is repeated. In this way, if the count is odd, the output will be high for (N + 1)/2 counts and low for (N – 1)/2 counts.

MODE 4: Software Triggered Strobe. After the mode is set, the output will be high. When the count is loaded, the counter will begin counting. On terminal count, the output will go low for one input clock period, then will go high again.

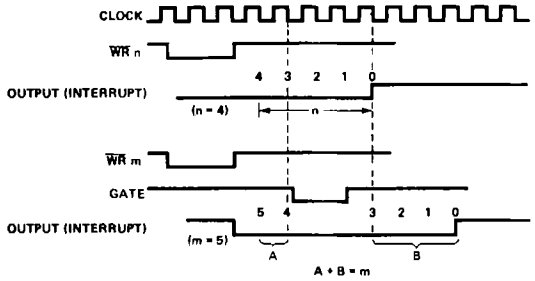
If the count register is reloaded between output pulses, counting will continue from the new value. The count will be inhibited while the gate input is low. Reloading the counter register will restart counting beginning with the new number.

MODE 5: Hardware Triggered Strobe. The counter will start counting after the rising edge of the trigger input and will go low for one clock period when the terminal count is reached. The counter is retriggerable. The output will not go low until the full count after the rising edge of any trigger.

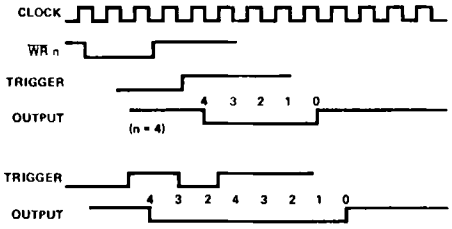
Modes \ Signal Status	Low Or Going Low	Rising	High
0	Disables counting	— —	Enables counting
1	— —	1) Initiates counting 2) Resets output after next clock	— —
2	1) Disables counting 2) Sets output immediately high	**1) Reloads counter** **2) Initiates counting**	Enables counting
3	1) Disables counting 2) Sets output immediately high	Initiates counting	Enables counting
4	Disables counting	— —	Enables counting
5	— —	Initiates counting	— —

Figure 4. Gate Pin Operations Summary

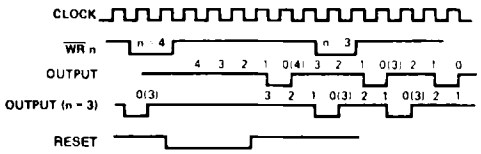
MODE 0: Interrupt on Terminal Count



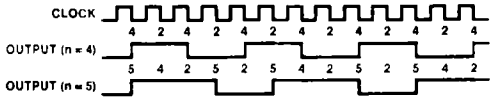
MODE 1: Programmable One-Shot



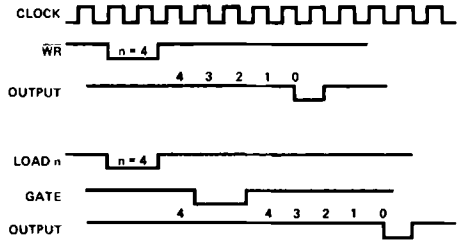
MODE 2: Rate Generator



MODE 3: Square Wave Generator



MODE 4: Software Triggered Strobe



MODE 5: Hardware Triggered Strobe

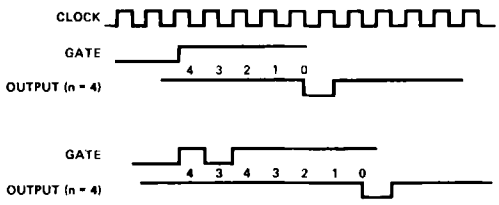


Figure 5. 8253 Timing Diagrams

8253 READ/WRITE PROCEDURE

Write Operations

The systems software must program each counter of the 8253 with the mode and quantity desired. The programmer must write out to the 8253 a MODE control word and the programmed number of count register bytes (1 or 2) prior to actually using the selected counter.

The actual order of the programming is quite flexible. Writing out of the MODE control word can be in any sequence of counter selection, e.g., counter #0 does not have to be first or counter #2 last. Each counter's MODE control word register has a separate address so that its loading is completely sequence independent. (SC0, SC1)

The loading of the Count Register with the actual count value, however, must be done in exactly the sequence programmed in the MODE control word (RL0, RL1). This loading of the counter's count register is still sequence independent like the MODE control word loading, but when a selected count register is to be loaded it must be loaded with the number of bytes programmed in the MODE control word (RL0, RL1). The one or two bytes to be loaded in the count register do not have to follow the associated MODE control word. They can be programmed at any time following the MODE control word loading as long as the correct number of bytes is loaded in order.

All counters are down counters. Thus, the value loaded into the count register will actually be decremented. Loading all zeroes into a count register will result in the maximum count (2^{16} for Binary or 10^4 for BCD). In MODE 0 the new count will not restart until the load has been completed. It will accept one of two bytes depending on how the MODE control words (RL0, RL1) are programmed. Then proceed with the restart operation.

	MODE Control Word Counter n
LSB	Count Register byte Counter n
MSB	Count Register byte Counter n

Note: Format shown is a simple example of loading the 8253 and does not imply that it is the only format that can be used.

Figure 6. Programming Format

			A1	A0
No. 1		MODE Control Word Counter 0	1	1
No. 2		MODE Control Word Counter 1	1	1
No. 3		MODE Control Word Counter 2	1	1
No. 4	LSB	Count Register Byte Counter 1	0	1
No. 5	MSB	Count Register Byte Counter 1	0	1
No. 6	LSB	Count Register Byte Counter 2	1	0
No. 7	MSB	Count Register Byte Counter 2	1	0
No. 8	LSB	Count Register Byte Counter 0	0	0
No. 9	MSB	Count Register Byte Counter 0	0	0

Note: The exclusive addresses of each counter's count register make the task of programming the 8253 a very simple matter, and maximum effective use of the device will result if this feature is fully utilized.

Figure 7. Alternate Programming Formats

Read Operations

In most counter applications it becomes necessary to read the value of the count in progress and make a computational decision based on this quantity. Event counters are probably the most common application that uses this function. The 8253 contains logic that will allow the programmer to easily read the contents of any of the three counters without disturbing the actual count in progress.

There are two methods that the programmer can use to read the value of the counters. The first method involves the use of simple I/O read operations of the selected counter. By controlling the A0, A1 inputs to the 8253 the programmer can select the counter to be read (remember that no read operation of the mode register is allowed A0, A1-11). The only requirement with this method is that in order to assure a stable count reading the actual operation of the selected counter must be inhibited either by controlling the Gate input or by external logic that inhibits the clock input. The contents of the counter selected will be available as follows:

first I/O Read contains the least significant byte (LSB).

second I/O Read contains the most significant byte (MSB).

Due to the internal logic of the 8253 it is absolutely necessary to complete the entire reading procedure. If two bytes are programmed to be read then two bytes must be read before any loading WR command can be sent to the same counter.

Read Operation Chart

A1	A0	RD	
0	0	0	Read Counter No. 0
0	1	0	Read Counter No. 1
1	0	0	Read Counter No. 2
1	1	0	Illegal

Reading While Counting

In order for the programmer to read the contents of any counter without effecting or disturbing the counting operation the 8253 has special internal logic that can be accessed using simple WR commands to the MODE register. Basically, when the programmer wishes to read the contents of a selected counter "on the fly" he loads the MODE register with a special code which latches the present count value into a storage register so that its contents contain an accurate, stable quantity. The programmer then issues a normal read command to the selected counter and the contents of the latched register is available.

MODE Register for Latching Count

A0, A1 = 11

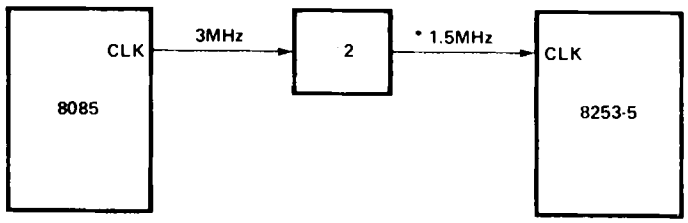
D7	D6	D5	D4	D3	D2	D1	D0
SC1	SC0	0	0	X	X	X	X

SC1,SC0 — specify counter to be latched.

D5,D4 — 00 designates counter latching operation.

X — don't care.

The same limitation applies to this mode of reading the counter as the previous method. That is, it is mandatory to complete the entire read operation as programmed. This command has no effect on the counter's mode.



*If an 8085 clock output is to drive an 8253-5 clock input, it must be reduced to 2 MHz or less.

Figure 8. MCS-85™ Clock Interface*

ABSOLUTE MAXIMUM RATINGS*

Ambient Temperature Under Bias ..... 0°C to 70°C
Storage Temperature ..... −65°C to +150°C
Voltage On Any Pin
With Respect to Ground ..... −0.5 V to +7 V
Power Dissipation ..... 1 Watt

COMMENT: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

D.C. CHARACTERISTICS (T_A = 0°C to 70°C; V_{CC} = 5V ±10%)

SYMBOL	PARAMETER	MIN.	MAX.	UNITS	TEST CONDITIONS
V_{IL}	Input Low Voltage	-0.5	0.8	V	
V_{IH}	Input High Voltage	2.2	V_{CC}+.5V	V	
V_{OL}	Output Low Voltage		0.45	V	Note 1
V_{OH}	Output High Voltage	2.4		V	Note 2
I_{IL}	Input Load Current		±10	μA	V_{IN} = V_{CC} to 0V
I_{OFL}	Output Float Leakage		±10	μA	V_{OUT} = V_{CC} to 0V
I_{CC}	V_{CC} Supply Current		140	mA	

Note 1: I_{OL} = 2.2 mA.
Note 2: I_{OH} = -400 μA.

CAPACITANCE T_A = 25°C; V_{CC} = GND = 0V

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
C_{IN}	Input Capacitance			10	pF	fc = 1 MHz
$C_{I/O}$	I/O Capacitance			20	pF	Unmeasured pins returned to V_{SS}

A.C. CHARACTERISTICS T_A = 0°C to 70°C; V_{CC} = 5.0V ±5%; GND = 0V

Bus Parameters (Note 1)

Read Cycle:

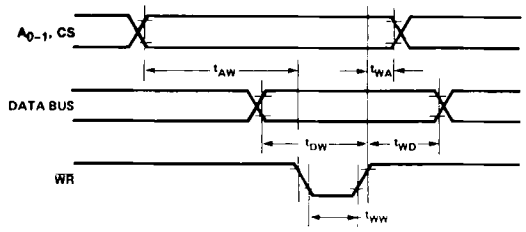
SYMBOL	PARAMETER	8253 MIN.	8253 MAX.	8253-5 MIN.	8253-5 MAX.	UNIT
t_{AR}	Address Stable Before $\overline{READ}$	50		30		ns
t_{RA}	Address Hold Time for $\overline{READ}$	5		5		ns
t_{RR}	$\overline{READ}$ Pulse Width	400		300		ns
t_{RD}	Data Delay From $\overline{READ}$[2]		300		200	ns
t_{DF}	$\overline{READ}$ to Data Floating	25	125	25	100	ns
t_{RV}	Recovery Time Between READ and Any Other Control Signal	1		1		μs

Write Cycle:

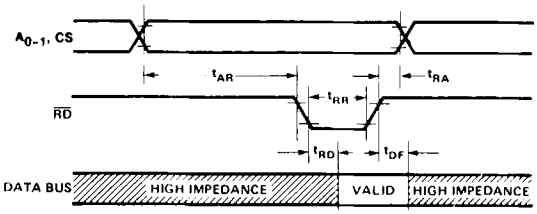
SYMBOL	PARAMETER	8253 MIN.	8253 MAX.	8253-5 MIN.	8253-5 MAX.	UNIT
t_{AW}	Address Stable Before $\overline{WRITE}$	50		30		ns
t_{WA}	Address Hold Time for $\overline{WRITE}$	30		30		ns
t_{WW}	$\overline{WRITE}$ Pulse Width	400		300		ns
t_{DW}	Data Set Up Time for $\overline{WRITE}$	300		250		ns
t_{WD}	Data Hold Time for $\overline{WRITE}$	40		30		ns
t_{RV}	Recovery Time Between $\overline{WRITE}$ and Any Other Control Signal	1		1		μs

Notes: 1. AC timings measured at V_{OH} = 2.2, V_{OL} = 0.8
2. C_L = 150pF.

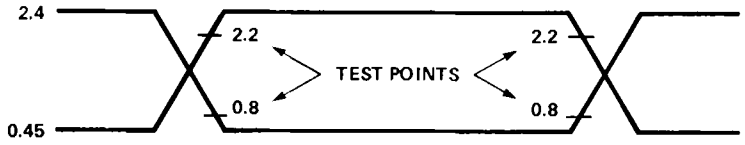
Write Timing:



Read Timing:



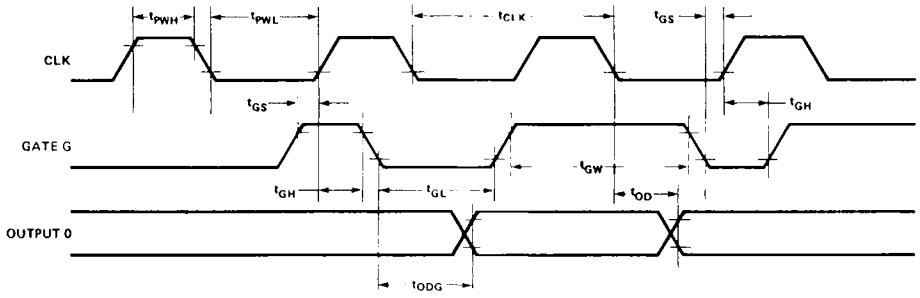
Input Waveforms for A.C. Tests:



Clock and Gate Timing:

SYMBOL	PARAMETER	8253		8253-5		UNIT
		MIN.	MAX.	MIN.	MAX.	
t_{CLK}	Clock Period	380	dc	380	dc	ns
t_{PWH}	High Pulse Width	230		230		ns
t_{PWL}	Low Pulse Width	150		150		ns
t_{GW}	Gate Width High	150		150		ns
t_{GL}	Gate Width Low	100		100		ns
t_{GS}	Gate Set Up Time to CLK↑	100		100		ns
t_{GH}	Gate Hold Time After CLK↑	50		50		ns
t_{OD}	Output Delay From CLK↓[1]		400		400	ns
t_{ODG}	Output Delay From Gate↓[1]		300		300	ns

Note 1: $C_L = 150pF$.



Programmable Array Logic Family

PAL® Series 20

U.S. Patent 4124899

March 1981

Features/Benefits

- Programmable replacement for conventional TTL logic.
- Reduces IC inventories substantially and simplifies their control.
- Reduces chip count by 4 to 1.
- Expedites and simplifies prototyping and board layout.
- Saves space with 20-pin SKINNY DIP® packages.
- High speed: 25ns typical propagation delay.
- Programmed on standard PROM programmers.
- Programmable three-state outputs.
- Special feature reduces possibility of copying by competitors.

Description

The PAL family utilizes an advanced Schottky TTL process and the Bipolar PROM fusible link technology to provide user programmable logic for replacing conventional SSI/MSI gates and flip-flops at reduced chip count.

The family lets the systems engineer "design his own chip" by blowing fusible links to configure AND and OR gates to perform his desired logic function. Complex interconnections which previously required time-consuming layout are thus "lifted" from PC board etch and placed on silicon where they can be easily modified during prototype check-out or production.

The PAL transfer function is the familiar sum of products. Like the PROM, the PAL has a single array of fusible links. Unlike the PROM, the PAL is a programmable AND array driving a fixed OR array (the PROM is a fixed AND array driving a programmable OR array). In addition the PAL provides these options:

- Variable input/output pin ratio
- Programmable three-state outputs
- Registers with feedback
- Arithmetic capability

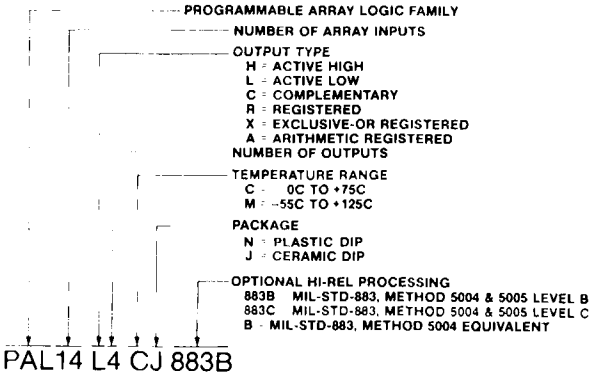
PAL® is a registered trademark of Monolithic Memories

PART NUMBER	DESCRIPTION
PAL10H8	OCTAL 10 INPUT AND-OR GATE ARRAY
PAL12H6	HEX 12 INPUT AND-OR GATE ARRAY
PAL14H4	QUAD 14 INPUT AND-OR GATE ARRAY
PAL16H2	DUAL 16 INPUT AND-OR GATE ARRAY
PAL16C1	16 INPUT AND-OR/AND-OR-INVERT GATE ARRAY
PAL10L8	OCTAL 10 INPUT AND-OR-INVERT GATE ARRAY
PAL12L6	HEX 12 INPUT AND-OR-INVERT GATE ARRAY
PAL14L4	QUAD 14 INPUT AND-OR-INVERT GATE ARRAY
PAL16L2	DUAL 16 INPUT AND-OR-INVERT GATE ARRAY
PAL16L8	OCTAL 16 INPUT AND-OR-INVERT GATE ARRAY
PAL16R8	OCTAL 16 INPUT REGISTERED AND-OR GATE ARRAY
PAL16R6	HEX 16 INPUT REGISTERED AND-OR GATE ARRAY
PAL16R4	QUAD 16 INPUT REGISTERED AND-OR GATE ARRAY
PAL16X4	QUAD 16 INPUT REGISTERED AND-OR-XOR GATE ARRAY
PAL16A4	QUAD 16 INPUT REGISTERED AND-CARRY-OR-XOR GATE ARRAY

Unused inputs are tied directly to V_{CC} or GND. Product terms with all fuses blown assume the logical high state, and product terms connected to both true and complement of any single input assume the logical low state. Registers consist of D type flip-flops which are loaded on the low to high transition of the clock. PAL Logic Diagrams are shown with all fuses blown, enabling the designer use of the diagrams as coding sheets.

The entire PAL family is programmed on inexpensive conventional PROM programmers with appropriate personality and socket adapter cards. Once the PAL is programmed and verified, two additional fuses may be blown to defeat verification. This feature gives the user a proprietary circuit which is very difficult to copy.

Ordering Information

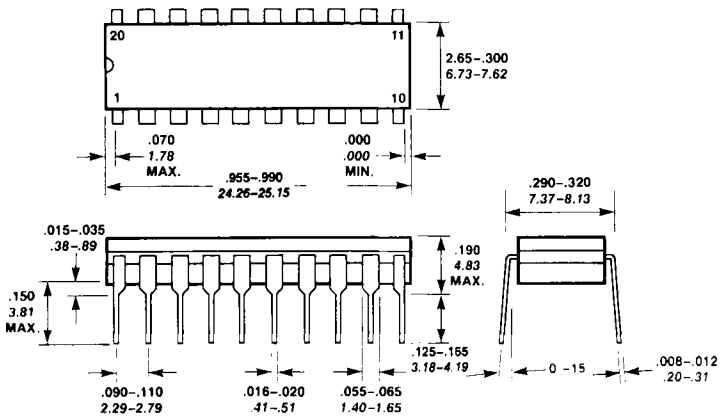


1165 East Arques Avenue, Sunnyvale, CA 94086 Tel: (408) 739-3535 TWX: 910-339-9229

Monolithic Memories

J20 Ceramic DIP

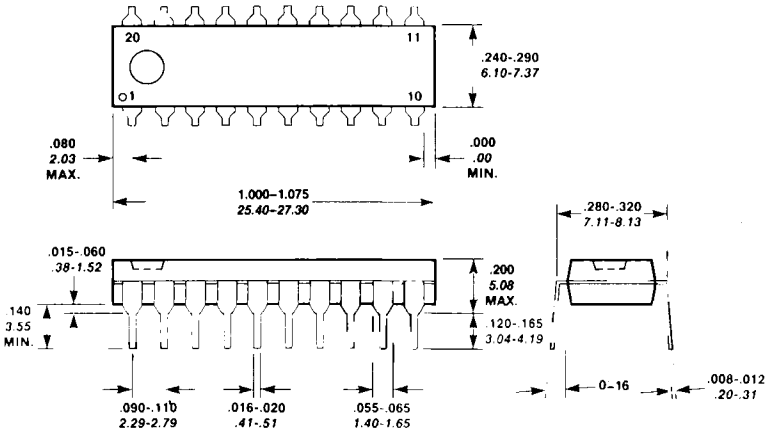
θ_{JA} = 75° C/W
θ_{JC} = 35° C/W



UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS.

N20 Plastic Kool Dip™

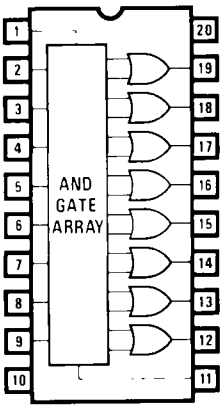
θ_{JA} = 75° C/W
θ_{JC} = 35° C/W



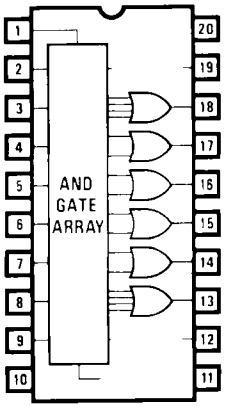
UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS.

PAL Series 20

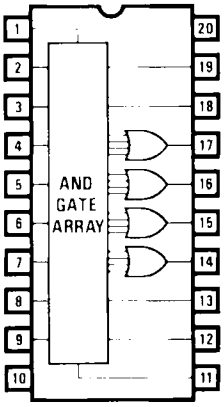
PAL10H8



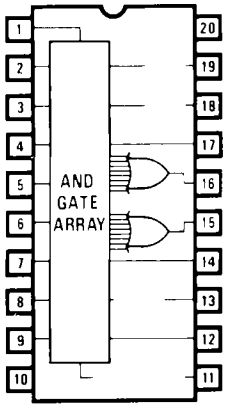
PAL12H6



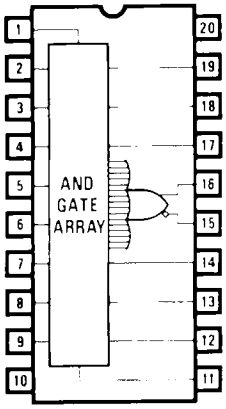
PAL14H4



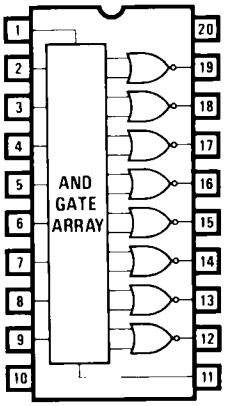
PAL16H2



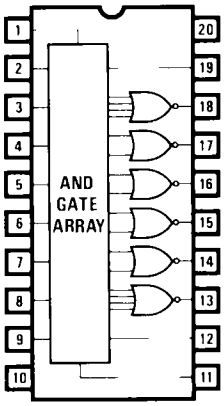
PAL16C1



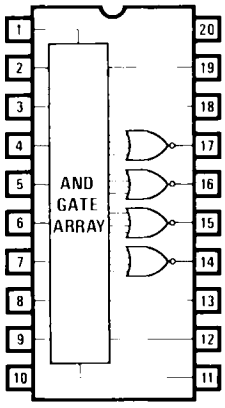
PAL10L8



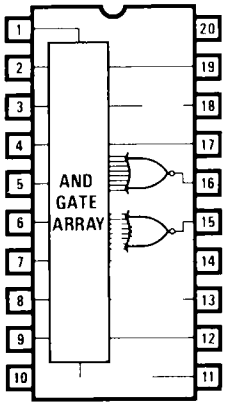
PAL12L6



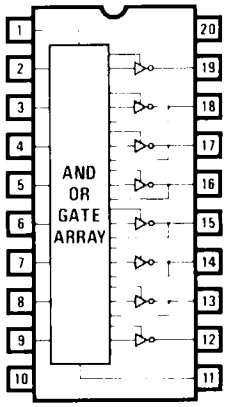
PAL14L4



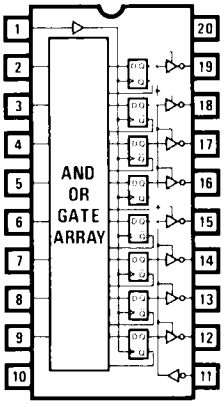
PAL16L2



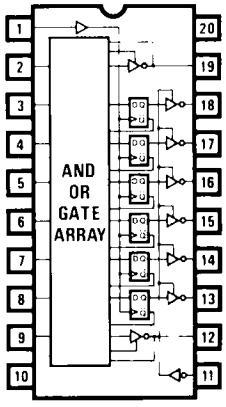
PAL16L8



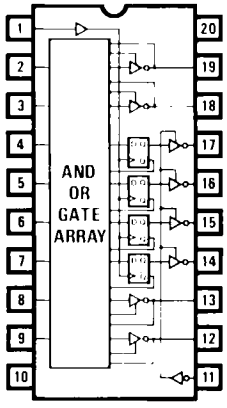
PAL16R8



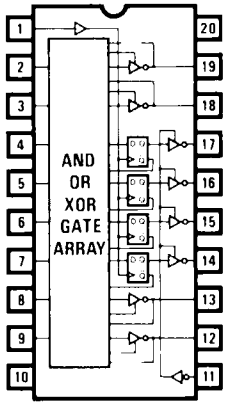
PAL16R6



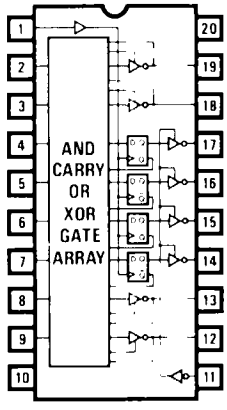
PAL16R4



PAL16X4



PAL16A4



Absolute Maximum Ratings

	Operating	Programming
Supply Voltage, V_{CC}	7	12V
Input Voltage	5.5V	12V *
Off-state output Voltage	5.5V	12V
Storage temperature	−65° to +150°C	

Operating Conditions

SYMBOL	PARAMETER	MILITARY MIN	MILITARY NOM	MILITARY MAX	COMMERCIAL MIN	COMMERCIAL NOM	COMMERCIAL MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature				0		75	°C
T_C	Operating case temperature	−55		125				°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS				MIN	TYP	MAX	UNIT
V_{IL}	Low-level input voltage							0.8	V
V_{IH}	High-level input voltage					2			V
V_{IC}	Input clamp voltage	V_{CC} = MIN	I_I = −18mA					−1.5	V
I_{IL}	Low-level input current †	V_{CC} = MAX	V_I = 0.4V					−0.25	mA
I_{IH}	High-level input current †	V_{CC} = MAX	V_I = 2.4V					25	μA
I_I	Maximum input current	V_{CC} = MAX	V_I = 5.5V					1	mA
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = 0.8V, V_{IH} = 2V	10H8, 12H6, 14H4, 16H2, 16C1, 10L8, 12L6, 14L4, 16L2	MIL COM	I_{OL} = 8mA			0.5	V
			16L8 16R8 16R6 16R4 16X4 16A4	MIL	I_{OL} = 12mA				
				COM	I_{OL} = 24mA				
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = 0.8V, V_{IH} = 2V	MIL		I_{OH} = −2mA	2.4			V
			COM		I_{OH} = −3.2mA				
I_{OZL}	Off-state output current †	V_{CC} = MAX, V_{IL} = 0.8V, V_{IH} = 2V	16L8 16R8 16R6 16R4 16X4 16A4		V_O = 0.4V			−100	μA
I_{OZH}					V_O = 2.4V			100	μA
I_{OS}	Output short-circuit current **	V_{CC} = 5V			V_O = 0V	−30		−130	mA
I_{CC}	Supply current	V_{CC} = MAX	10H8, 12H6, 14H4, 16H2, 16C1, 10L8, 12L6, 14L4, 16L2				55	90	mA
			16R4, 16R6, 16R8, 16L8	COM			120	180	
			16L8	MIL			140	210	
			16R4, 16R6, 16R8	MIL			150	225	
			16X4				160	225	
			16A4				170	240	

† I/O pin leakage is the worst case of I_{OZX} or I_{IX} (e.g. I_{IL} and I_{OZH})

* Pins 1 and 11 may be raised to 22V max

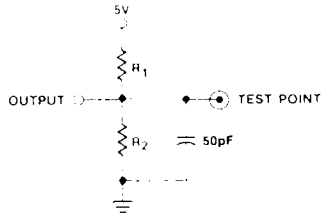
** Only one output shorted at a time

Switching Characteristics

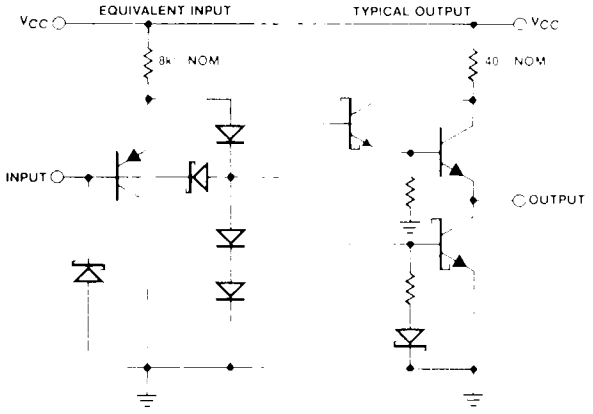
Over Operating Conditions

SYMBOL	PARAMETER		TEST CONDITIONS	MILITARY MIN	MILITARY TYP	MILITARY MAX	COMMERCIAL MIN	COMMERCIAL TYP	COMMERCIAL MAX	UNIT
t_{PD}	Input to output	10H8 12H6 14H4 16H2 10L8 12L6 14L4 16L2	R_1 = 560Ω, R_2 = 1.1kΩ		25	45		25	35	ns
		16C1			25	45		25	40	
t_{PD}	Input or feedback to output		16R8 16R6 16R4 16L8 16X4 16A4		25	45		25	35	ns
t_{CLK}	Clock to output or feedback				15	25		15	25	ns
t_{PZX}	Pin 11 to output enable				15	25		15	25	ns
t_{PXZ}	Pin 11 to output disable				15	25		15	25	ns
t_{PZX}	Input to output enable				25	45		25	35	ns
t_{PXZ}	Input to output disable				25	45		25	35	ns
t_W	Width of clock	Low	R_1 = 200Ω, R_2 = 390Ω	25			25			ns
		High		25			25			
t_{SU}	Setup time from input or feedback	16R8 16R6 16R4		45			35			ns
		16X4 16A4		55			45			
t_H	Hold time			0		−15	0		−15	ns
f_{MAX}	Maximum frequency	16R8 16R6 16R4		14			16			MHz
		16X4 16A4		12			14			

Test Load



Schematic of Inputs and Outputs



Available Programmers

MANUFACTURER	PERSONALITY CARD SET	SOCKET ADAPTER CONFIGURATION
Cybernetic Programming Systems, Inc	CYMPC-1	
Data I/O Corporation	909-1427	715 1428-1 715 1428-2 715 1428-3
Pro-Log Corporation	PM9068	
Stag Systems	PM202	AM10H8 AM10L8 AM12H6 AM12L6 AM14H4 AM14L4 AM16H2 AM16L2 AM16C1
Structured Design	SD20/24	

Programming

PAL fuses are programmed using a low-voltage linear-select procedure which is common to all 15 PAL types. The array is divided into two groups, products 0 thru 31 and products 32 thru 63, for which pin identifications are shown in Pin Configurations below. To program a particular fuse, both an input line and a product line are selected according to the following procedure:

Step 1 Raise Output Disable, OD, to V_{IHH}

Step 2 Select an input line by specifying I_0, I_1, I_2, I_3, I_4, I_5, I_6, I_7 and L/R as shown in Table 1.

Step 3 Select a product line by specifying A_0, A_1 and A_2 one-of-eight select as shown in Table 2.

Step 4 Raise V_{CC} (pin 20) to V_{IHH}

Step 5 Program the fuse by pulsing the output pins, O, of the selected product group to V_{IHH} as shown in Programming Waveform.

Step 6 Lower V_{CC} (pin 20) to 6.0 V

Step 7 Pulse the CLOCK pin and verify the output pin, O, to be Low for active Low PAL types or High for active High PAL types.

Step 8 Lower V_{CC} (pin 20) to 4.5 V and repeat step 7.

Step 9 Should the output not verify, repeat steps 1 thru 8 up to five (5) times.

This procedure is repeated for all fuses to be blown (see Programming Waveforms).

To prevent further verification, two last fuses may be blown by raising pin 1 and pin 11 to V_P. V_{CC} is not required during this operation.

Voltage Legend

L = Low-level input voltage, V_{IL}
H = High-level input voltage, V_{IH}
HH = High-level program voltage, V_{IHH}
Z = High impedance (e.g., 10kΩ to 5.0V)

INPUT LINE NUMBER	PIN IDENTIFICATION								
	I_7	I_6	I_5	I_4	I_3	I_2	I_1	I_0	L/R
0	HH	HH	HH	HH	HH	HH	HH	L	Z
1	HH	HH	HH	HH	HH	HH	HH	H	Z
2	HH	HH	HH	HH	HH	HH	HH	L	HH
3	HH	HH	HH	HH	HH	HH	HH	H	HH
4	HH	HH	HH	HH	HH	HH	L	HH	Z
5	HH	HH	HH	HH	HH	HH	H	HH	Z
6	HH	HH	HH	HH	HH	HH	L	HH	HH
7	HH	HH	HH	HH	HH	HH	H	HH	HH
8	HH	HH	HH	HH	HH	L	HH	HH	Z
9	HH	HH	HH	HH	HH	H	HH	HH	Z
10	HH	HH	HH	HH	HH	L	HH	HH	HH
11	HH	HH	HH	HH	HH	H	HH	HH	HH
12	HH	HH	HH	HH	L	HH	HH	HH	Z
13	HH	HH	HH	HH	H	HH	HH	HH	Z
14	HH	HH	HH	HH	L	HH	HH	HH	HH
15	HH	HH	HH	HH	H	HH	HH	HH	HH
16	HH	HH	HH	L	HH	HH	HH	HH	Z
17	HH	HH	HH	H	HH	HH	HH	HH	Z
18	HH	HH	HH	L	HH	HH	HH	HH	HH
19	HH	HH	HH	H	HH	HH	HH	HH	HH
20	HH	HH	L	HH	HH	HH	HH	HH	Z
21	HH	HH	H	HH	HH	HH	HH	HH	Z
22	HH	HH	L	HH	HH	HH	HH	HH	HH
23	HH	HH	H	HH	HH	HH	HH	HH	HH
24	HH	L	HH	HH	HH	HH	HH	HH	Z
25	HH	H	HH	HH	HH	HH	HH	HH	Z
26	HH	L	HH	HH	HH	HH	HH	HH	HH
27	HH	H	HH	HH	HH	HH	HH	HH	HH
28	L	HH	HH	HH	HH	HH	HH	HH	Z
29	H	HH	HH	HH	HH	HH	HH	HH	Z
30	L	HH	HH	HH	HH	HH	HH	HH	HH
31	H	HH	HH	HH	HH	HH	HH	HH	HH

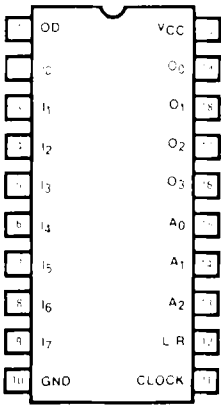
Table 1 Input Line Select

PRODUCT LINE NUMBER	PIN IDENTIFICATION						
	O_3	O_2	O_1	O_0	A_2	A_1	A_0
0, 32	Z	Z	Z	HH	Z	Z	Z
1, 33	Z	Z	Z	HH	Z	Z	HH
2, 34	Z	Z	Z	HH	Z	HH	Z
3, 35	Z	Z	Z	HH	Z	HH	HH
4, 36	Z	Z	Z	HH	HH	Z	Z
5, 37	Z	Z	Z	HH	HH	Z	HH
6, 38	Z	Z	Z	HH	HH	HH	Z
7, 39	Z	Z	Z	HH	HH	HH	HH
8, 40	Z	Z	HH	Z	Z	Z	Z
9, 41	Z	Z	HH	Z	Z	Z	HH
10, 42	Z	Z	HH	Z	Z	HH	Z
11, 43	Z	Z	HH	Z	Z	HH	HH
12, 44	Z	Z	HH	Z	HH	Z	Z
13, 45	Z	Z	HH	Z	HH	Z	HH
14, 46	Z	Z	HH	Z	HH	HH	Z
15, 47	Z	Z	HH	Z	HH	HH	HH
16, 48	Z	HH	Z	Z	Z	Z	Z
17, 49	Z	HH	Z	Z	Z	Z	HH
18, 50	Z	HH	Z	Z	Z	HH	Z
19, 51	Z	HH	Z	Z	Z	HH	HH
20, 52	Z	HH	Z	Z	HH	Z	Z
21, 53	Z	HH	Z	Z	HH	Z	HH
22, 54	Z	HH	Z	Z	HH	HH	Z
23, 55	Z	HH	Z	Z	HH	HH	HH
24, 56	HH	Z	Z	Z	Z	Z	Z
25, 57	HH	Z	Z	Z	Z	Z	HH
26, 58	HH	Z	Z	Z	Z	HH	Z
27, 59	HH	Z	Z	Z	Z	HH	HH
28, 60	HH	Z	Z	Z	HH	Z	Z
29, 61	HH	Z	Z	Z	HH	Z	HH
30, 62	HH	Z	Z	Z	HH	HH	Z
31, 63	HH	Z	Z	Z	HH	HH	HH

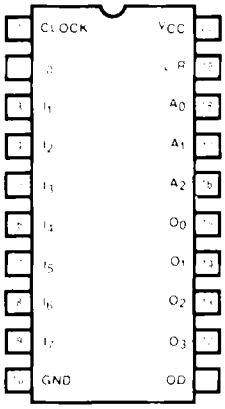
Table 2 Product Line Select

Pin Configurations

PRODUCTS 0 THRU 31



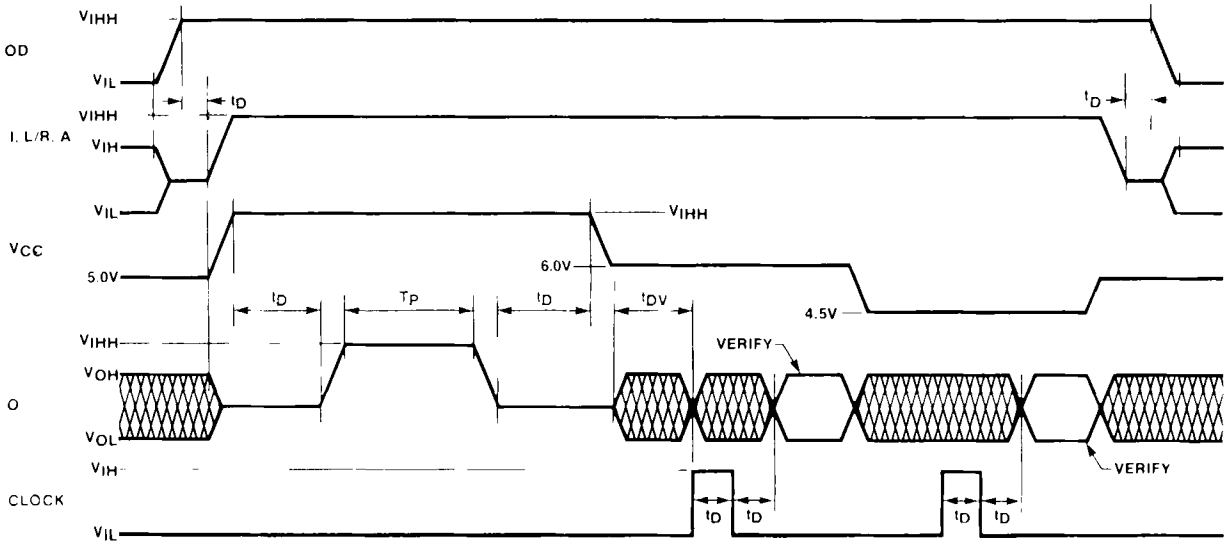
PRODUCTS 32 THRU 63



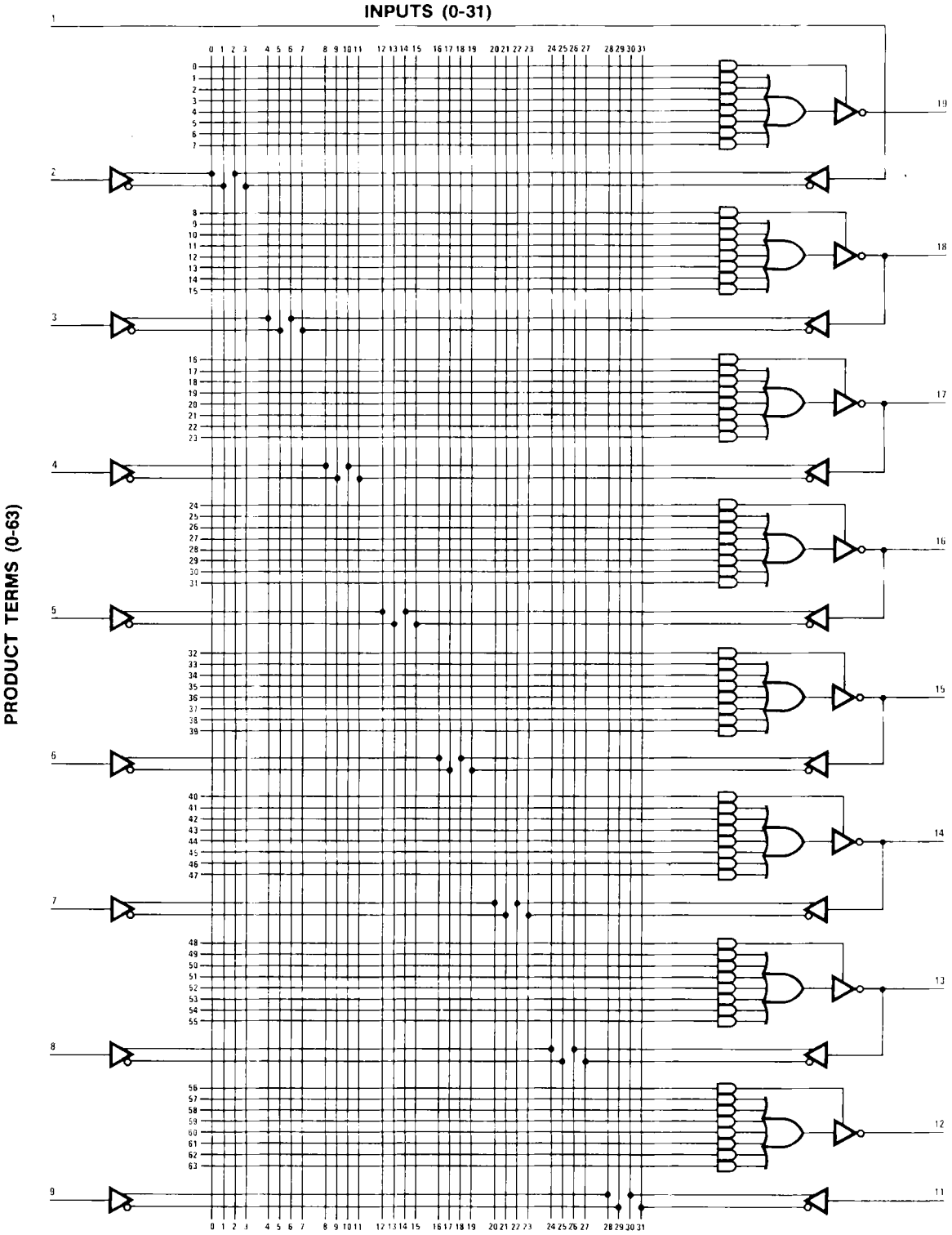
Programming Parameters T_A = 25°C

SYMBOL	PARAMETER		LIMITS MIN	TYP	MAX	UNIT
V_{IHH}	Program-level input voltage		11	11.5	12	V
I_{IHH}	Program-level input current	Output Program Pulse			50	mA
		OD, L/R			25	
		All Other Inputs			5	
I_{CCH}	Program Supply Current				400	mA
T_P	Program Pulse Width		10		50	μs
t_D	Delay time		100			ns
t_{DV}	Delay Time to Verify		100			μs
	Program Pulse duty cycle				25	%
V_P	Verify-Protect-input voltage		20	21	22	V
I_P	Verify-Protect-input current				400	mA
T_{PP}	Verify-Protect Pulse Width		20		50	msec

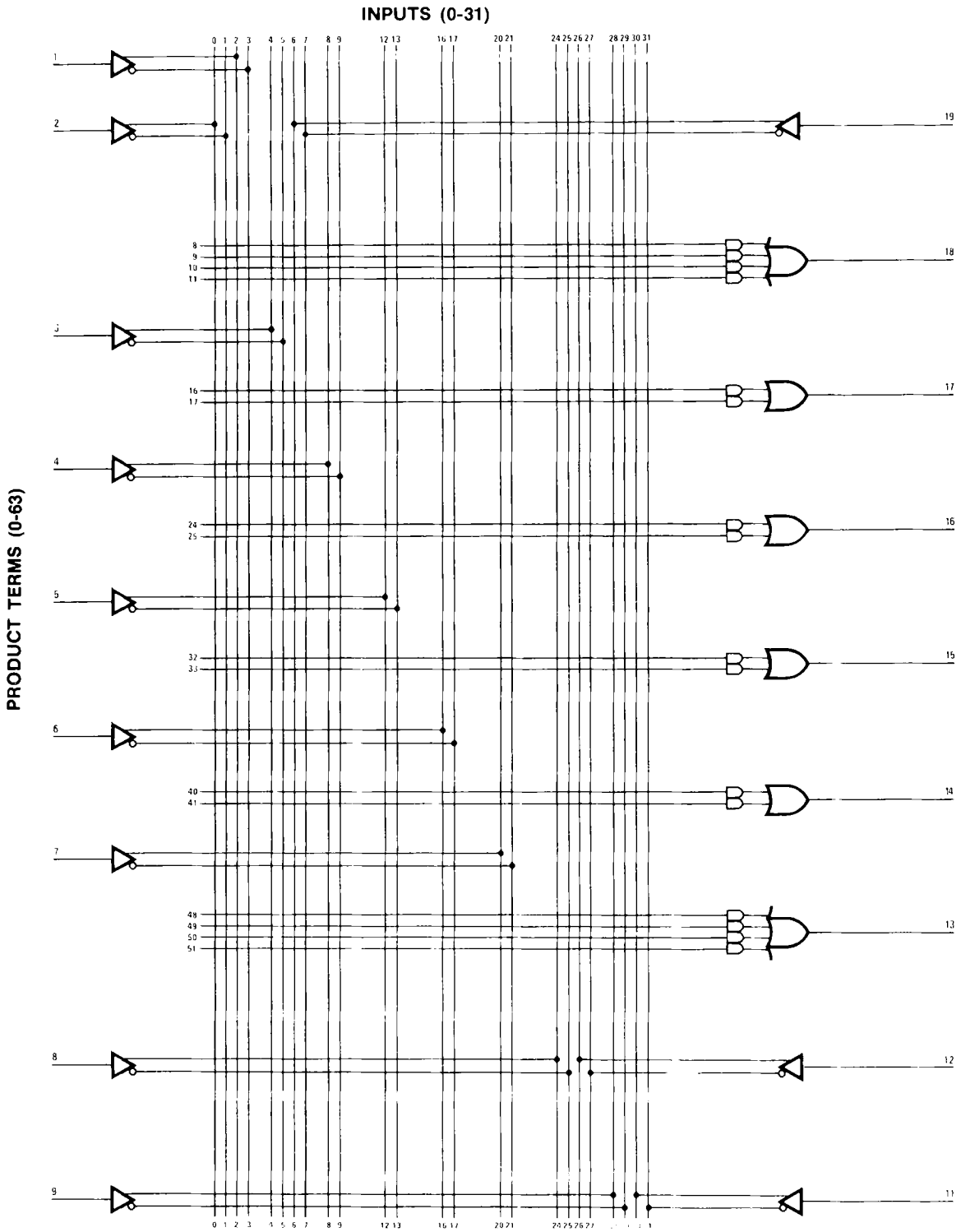
Programming Waveforms



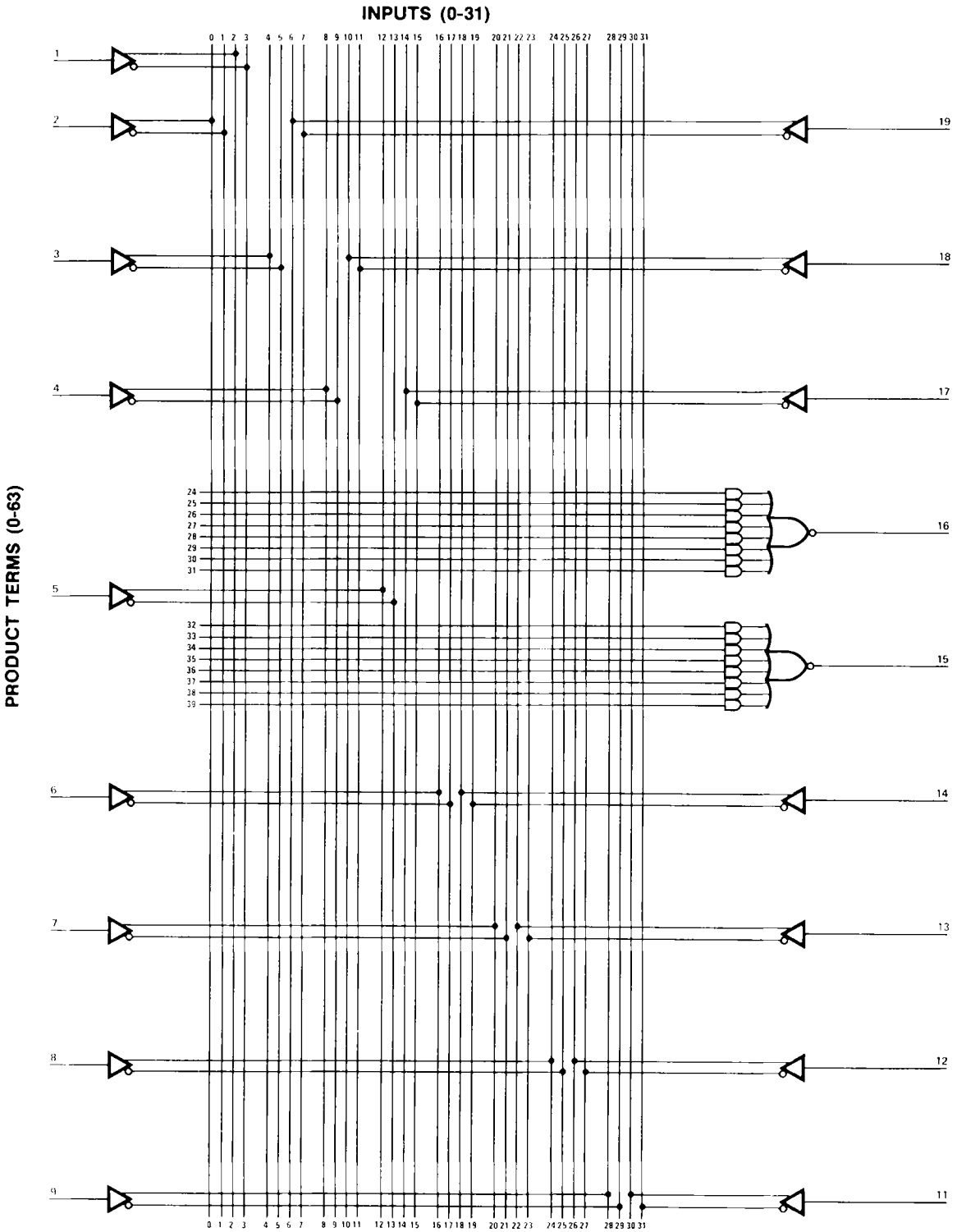
Logic Diagram PAL16L8



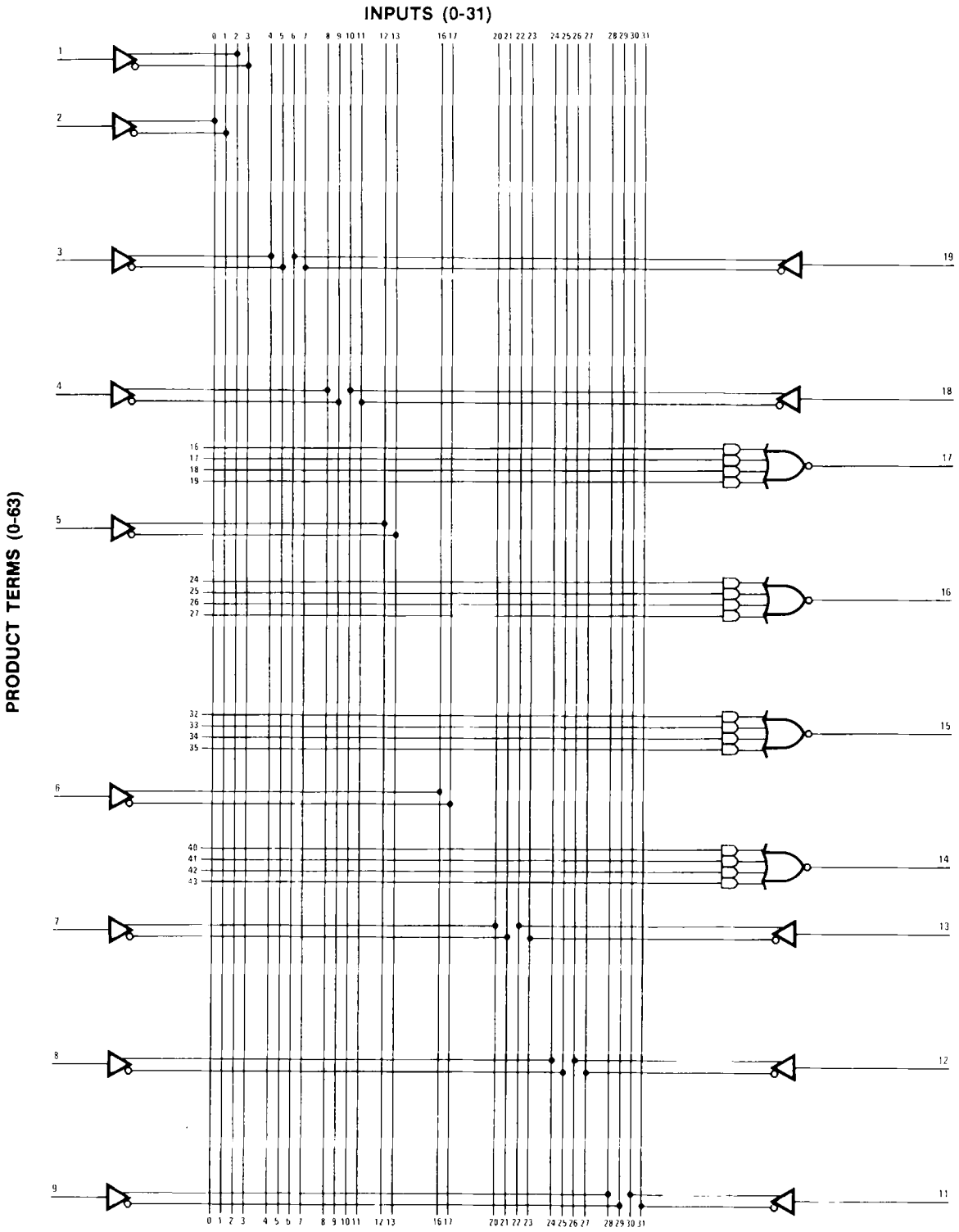
Logic Diagram PAL12H6



Logic Diagram PAL16L2



Logic Diagram PAL14L4



Am27S20 • Am27S21

1024-Bit Generic Series Bipolar PROM

DISTINCTIVE CHARACTERISTICS

- High Speed – 45ns max commercial range access time
- Excellent performance over full MIL and commercial ranges
- Highly reliable, ultra-fast programming Platinum-Silicide fuses
- High programming yield
- Low current PNP inputs
- High current open collector and three-state outputs
- Fast chip select
- Access time tested with N^2 patterns
- Pin for pin replacements for industry standard products
- Common Generic PROM series electrical characteristics and simple programming procedures.

GENERIC SERIES CHARACTERISTICS

The Am27S20 and Am27S21 are members of an Advanced PROM series incorporating common electrical characteristics and programming procedures. All parts in this series are produced with a fusible link at each memory location storing a logic LOW and can be selectively programmed to a logic HIGH by applying appropriate voltages to the circuit.

All parts are fabricated with AMD's fast programming highly reliable Platinum-Silicide Fuse technology. Utilizing easily implemented programming (and common programming personality card sets) these products can be rapidly programmed to any customized pattern. Extra test words are pre-programmed during manufacturing to insure extremely high field programming yields, and produce excellent parametric correlation.

Platinum-Silicide was selected as the fuse link material to achieve a well controlled melt rate resulting in large non-conductive gaps that ensure very stable long term reliabilty. Extensive operating testing has proven that this low-field, large-gap technology offers the best reliability for fusible link PROMs.

Common design features include active loading of all critical AC paths regulated by a built-in temperature and voltage compensated bias network to provide excellent parametric performance over MIL supply and temperature ranges. Selective feedback techniques have been employed to minimize delays through all critical paths producing the fastest speeds possible from Schottky processed PROMs.

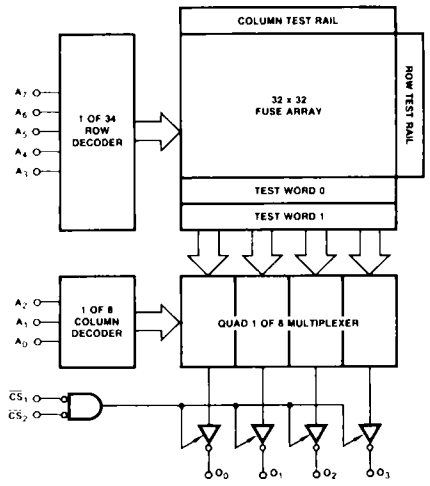
ORDERING INFORMATION

Package Type	Temperature Range	Order Number
	Open Collectors	
Hermetic DIP	0°C to +75°C	AM27S20DC
Hermetic DIP	−55°C to +125°C	AM27S20DM
Hermetic Flat Pak	−55°C to +125°C	AM27S20FM
	Three-State Outputs	
Hermetic DIP	0°C to +75°C	AM27S21DC
Hermetic DIP	−55°C to +125°C	AM27S21DM
Hermetic Flat Pak	−55°C to +125°C	AM27S21FM

FUNCTIONAL DESCRIPTION

The Am27S20 and Am27S21 are high speed electrically programmable Schottky read only memories. Organized in the industry standard 256 x 4 configuration, they are available in both open collector Am27S20 and three-state Am27S21 output versions. After programming, stored information is read on outputs O_0-O_3 by applying unique binary addresses to A_0-A_7 and holding the chip select inputs, $\overline{CS}_1$ and $\overline{CS}_2$, at a logic LOW. If either chip select input goes to a logic HIGH, O_0-O_3 go to the off or high impedance state.

BLOCK DIAGRAM



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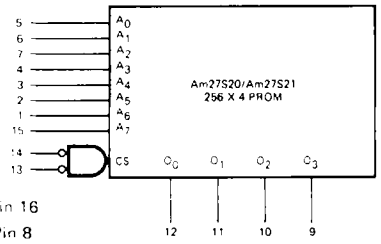
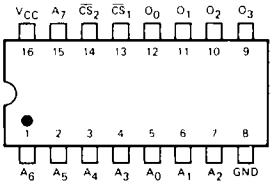
LOGIC SYMBOL



BPM-028

CONNECTION DIAGRAM
Top View



Note: Pin 1 is marked for orientation.

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Am27S20 • Am27S21

MAXIMUM RATINGS (Above which the useful life may be impaired)

Storage Temperature	−65°C to +150°C
Temperature (Ambient) Under Bias	−55°C to +125°C
Supply Voltage to Ground Potential (Pin 16 to Pin 8) Continuous	−0.5V to +7.0V
DC Voltage Applied to Outputs (Except During Programming)	−0.5V to +V_{CC} max.
DC Voltage Applied to Outputs During Programming	21V
Output Current into Outputs During Programming (Max. Duration of 1 sec.)	200mA
DC Input Voltage	−0.5V to +5.5V
DC Input Current	−30mA to +5mA

OPERATING RANGE

COM'L	Am27S20XC, Am27S21XC	T_A = 0°C to +75°C	V_{CC} = 5.0V ±5%
MIL	Am27S20XM, Am27S21XM	T_A = −55°C to +125°C	V_{CC} = 5.0V ±10%

ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE (Unless Otherwise Noted)

PRELIMINARY DATA

Parameters	Description	Test Conditions			Min.	Typ. (Note 1)	Max.	Units
V_{OH} (Am27S21 only)	Output HIGH Voltage	V_{CC} = MIN., I_{OH} = −2.0mA V_{IN} = V_{IH} or V_{IL}			2.4			Volts
V_{OL}	Output LOW Voltage	V_{CC} = MIN., I_{OL} = 16mA V_{IN} = V_{IH} or V_{IL}					0.45	Volts
V_{IH}	Input HIGH Level	Guaranteed input logical HIGH voltage for all inputs			2.0			Volts
V_{IL}	Input LOW Level	Guaranteed input logical LOW voltage for all inputs					0.8	Volts
I_{IL}	Input LOW Current	V_{CC} = MAX., V_{IN} = 0.45V				−0.010	−0.250	mA
I_{IH}	Input HIGH Current	V_{CC} = MAX., V_{IN} = 2.7V					25	µA
I_I	Input HIGH Current	V_{CC} = MAX., V_{IN} = 5.5V					1.0	mA
I_{SC} (Am27S21 only)	Output Short Circuit Current	V_{CC} = MAX., V_{OUT} = 0.0V (Note 2)			−20	−40	−90	mA
I_{CC}	Power Supply Current	All inputs = GND V_{CC} = MAX.				95	130	mA
V_I	Input Clamp Voltage	V_{CC} = MIN., I_{IN} = −18mA					−1.2	Volts
I_{CEX}	Output Leakage Current	V_{CC} = MAX. $V_{\overline{CS1}}$ = 2.4V	Am27S21 only	V_O = 4.5V			40	µA
				V_O = 2.4V			40	
				V_O = 0.4V			−40	
C_{IN}	Input Capacitance	V_{IN} = 2.0V @ f = 1 MHz (Note 3)				4		pF
C_{OUT}	Output Capacitance	V_{OUT} = 2.0V @ f = 1 MHz (Note 3)				8		pF

Note 1. Typical limits are at V_{CC} = 5.0V and T_A = 25°C

2. Not more than one output should be shorted at a time. Duration of the short circuit should not be more than one second.

3. These parameters are not 100% tested, but are periodically sampled.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

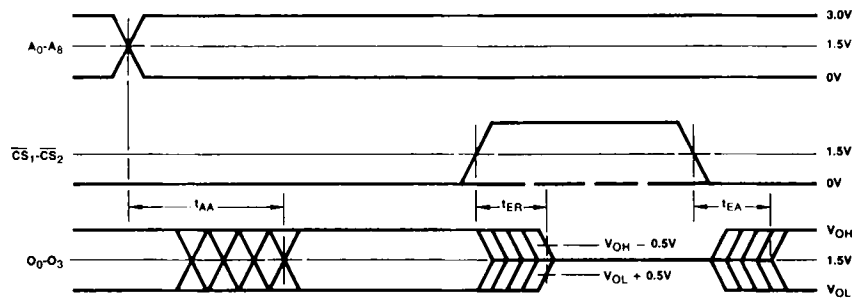
Am27S20 • Am27S21

PRELIMINARY DATA

Parameter	Description	Test Conditions	Typ 5V 25°C	Max COM'L	Max MIL	Units
t_{AA}	Address Access Time	AC Test Load (See Notes 1-3)	25	45	60	ns
t_{EA}	Enable Access Time		15	20	30	ns
t_{ER}	Enable Recovery Time		15	20	30	ns

Notes: 1. t_{AA} is tested with switch S_1 closed and C_L = 30pF.
2. For open collector outputs, t_{EA} and t_{ER} are tested with S_1 closed to the 1.5V output level. C_L = 30pF.
3. For three state outputs, t_{EA} is tested with C_L = 30pF to the 1.5V level; S_1 is open for high impedance to HIGH tests and closed for high impedance to LOW tests. t_{ER} is tested with C_L = 5pF. HIGH to high impedance tests are made with S_1 open to an output voltage of V_{OH} − 0.5V; LOW to high impedance tests are made with S_1 closed to the V_{OL} + 0.5V level.

SWITCHING WAVEFORMS



Note: Level on output while either $\overline{CS}$ is HIGH is determined externally.

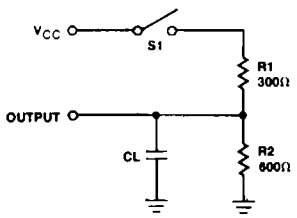
BPM-030

KEY TO TIMING DIAGRAM

WAVEFORM	INPUTS	OUTPUTS
——— / ———	MUST BE STEADY	WILL BE STEADY
⟋⟋⟋	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
⟍⟍⟍	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H

WAVEFORM	INPUTS	OUTPUTS
⋈⋈⋈	DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
⋈	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

AC TEST LOAD



BPM-031

PROGRAMMING

The Am27S20 and Am27S21 are manufactured with a conductive Platinum-Silicide link at each bit location. The output of the memory with the link in place is LOW. To program the device, the fusible links are selectively opened.

The fusible links are opened one at a time by passing current through them from a 20 volt supply which is applied to one memory output after the $\overline{CS}_1$ input is at a logic HIGH. Current is gated through the addressed fuse by raising the $\overline{CS}_1$ input from a logic HIGH to 15 volts. After 50 μsec, the 20 volt supply is removed, the chip enabled, and the output level sensed to determine if the link has opened. Most links will open within 50 μsec. Occasionally a link will be stronger and require additional programming cycles. The recommended duration of additional programming periods is 5 msec. If a link has not opened after a total elapsed programming time of 400 msec, further programming of the device should not be attempted. Successive links are programmed in the same manner until all desired bit locations have been programmed to the HIGH level.

Typical current into an output during programming will be approximately 140mA until the fuse link is opened, after which the current drops to approximately 40mA. Current into the $\overline{CS}_1$ pin when it is raised to 15 volts is typically 1.5mA.

The memories may become hot during programming due to the large currents being passed. Programming cycles should not be applied to one device more than 5 seconds to avoid heat damage. If this programming time is exceeded, all power to the chip including V_{CC} should be removed for a period of 5 seconds after which programming may be resumed.

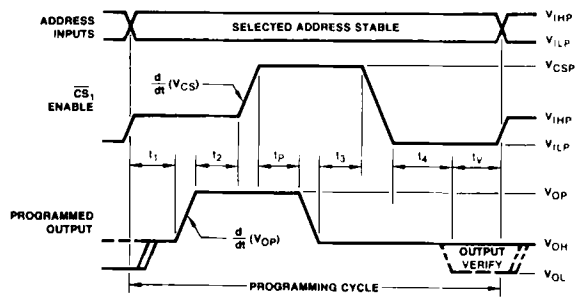
When all programming has been completed, the data content of the memory should be verified by sequentially reading all words. Occasionally this verification will show that an extra undesired link has been fused. Should this occur, immediately check the programming equipment to make sure that all device pins are firmly contacting the programming socket, that the input signal levels exhibit sufficient noise margins, and that the programming voltages are within the specified limits. All of these conditions must be maintained during programming. AMD PROMs are thoroughly tested to minimize unwanted fusing; fusing extra bits is generally related to programming equipment problems.

PROGRAMMING PARAMETERS

Parameter	Description	Min.	Max.	Units
V_{CCP}	V_{CC} During Programming	5.0	5.5	Volts
V_{IHP}	Input HIGH Level During Programming	2.4	5.5	Volts
V_{ILP}	Input LOW Level During Programming	0.0	0.45	Volts
V_{CSP}	$\overline{CS}_1$ Voltage During Programming	14.5	15.5	Volts
V_{OP}	Output Voltage During Programming	19.5	20.5	Volts
V_{ONP}	Voltage on Outputs Not to be Programmed	0	V_{CCP}+0.3	Volts
I_{ONP}	Current into Outputs Not to be Programmed		20	mA
$d(V_{OP})/dt$	Rate of Output Voltage Change	20	250	V/μsec
$d(V_{CS})/dt$	Rate of $\overline{CS}_1$, Voltage Change	100	1000	V/μsec
t_P	Programming Period – First Attempt	50	100	μsec
	Programming Period – Subsequent Attempts	5.0	15	msec

Notes:
1. All delays between edges are specified from completion of the first edge to beginning of the second edge; i.e., not to the midpoints.
2. Delays t_1, t_2, t_3 and t_4 must be greater than 100 ns; maximum delays of 1 μsec are recommended to minimize heating during programming.
3. During t_V, a user defined period, the output being programmed is switched to the load R and read to determine if additional pulses are required.
4. Outputs not being programmed are connected to V_{ONP} through resistor R which provides output current limiting.

PROGRAMMING WAVEFORMS



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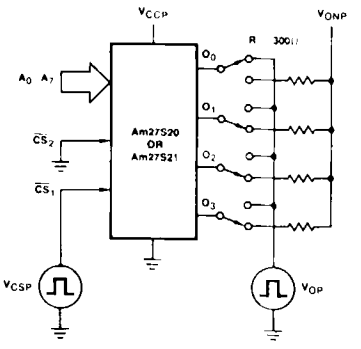
SIMPLIFIED PROGRAMMING DIAGRAM



BPM-033

PROGRAMMING EQUIPMENT

Generic programming boards and device adapters are available from the sources listed below. In each case, the programming boards are used in these manufacturer's automatic programmers to program all AMD generic series bipolar PROMs; individual adapters are required for each basic part type in the series.

SOURCE AND LOCATION	Data I/O Corp P.O. Box 308 Issaquah, Wash. 98027	Pro-Log Corp 2411 Garden Road Monterey, Ca. 93940
PROGRAMMER MODEL(S)	Model 5, 7 and 9	M900 and M920
AMD GENERIC BIPOLAR PROM PERSONALITY BOARD	909-1286-1	PM9058
Am27S20 • Am27S21 ADAPTERS AND CONFIGURATOR	715-1408-1	PA16-5 and 256 x 4 (L)

OBTAINING PROGRAMMED UNITS

Programmed devices may be purchased from your distributor or Advanced Micro Devices. The program data should be submitted in the form of a punched paper tape and must be accompanied by a written truth table. The punched tape can be delivered with your order or may be transmitted over a TWX machine or time-sharing terminal. ASCII BPNF is our preferred paper tape format.

Truth tables are also acceptable, but are much less desirable especially for larger density PROMs. Submission of a truth table requires the generation of a punched paper tape at the distributor or factory resulting in longer lead times, greater possibility of error, and higher cost.

ASCII BPNF

An example of an ASCII tape in the BPNF format is shown below. They can be punched on any Teletype® or on a TWX or Telex machine. The format chosen provides relatively good error detection. Paper tapes must consist of:

1. A leader of at least 25 rubouts.
2. The data patterns for all 256 words, starting with word 0, in the following format:
   a. Any characters, including carriage return and line feed, except "B".
   b. The letter "B", indicating the beginning of the data word.
   c. A sequence of four Ps or Ns, starting with output O_3.
   d. The letter "F", indicating the finish of the data word.
   e. Any text, including carriage return and line feed, except the letter "B".
3. A trailer of at least 25 rubouts.

A P is a HIGH logic level = 2.4 volts.
An N is a LOW logic level = 0.4 volts.

A convenient pattern to use for the data words is to prefix the word (or every few words with the word number, then type the data word, then a comment, then carriage return and line feed as shown below. There must be no characters between the B and the F except for the four Ps and Ns. If an error is made in a word, the entire word must be cancelled with rubouts back to the letter B, then the word re-typed beginning with the B.

When TWXing your tape, be sure the tape is in even parity. Parity is not necessary if the tape is mailed.

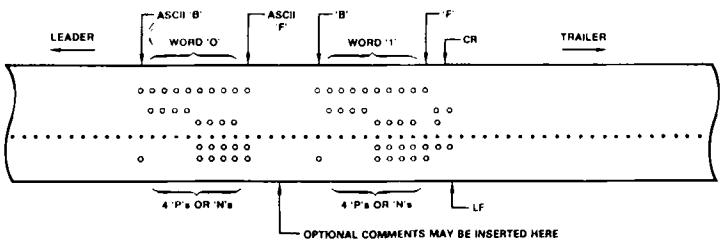
TYPICAL PAPER TAPE FORMAT

ØØØ	BNNNPF	WORD ZERO (R) (L)
	BPPNNF	COMMENT FIELD (R) (L)
ØØ2	BPPPNF	ANY (R) (L)
	BNNNNF	TEXT (R) (L)
ØØ4	BNNNPF	CAN (R) (L)
	BPPNNF	GO (R) (L)
ØØ6	BPPNNF	HERE (R) (L)
⋮	⋮⋮⋮⋮⋮	⋮
255	BPPPNF	END (R) (L)

RESULTING DEVICE TRUTH TABLE ($\overline{CS}_1$ & $\overline{CS}_2$ = LOW)

A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0	O_3	O_2	O_1	O_0
L	L	L	L	L	L	L	L	L	L	L	H
L	L	L	L	L	L	L	H	H	H	L	L
L	L	L	L	L	L	H	L	H	H	H	L
L	L	L	L	L	L	H	H	L	L	L	L
L	L	L	L	L	H	L	L	L	L	L	H
L	L	L	L	L	H	L	H	H	H	L	L
L	L	L	L	L	H	H	L	H	H	L	L
				⋮						⋮	
H	H	H	H	H	H	H	H	H	H	H	L

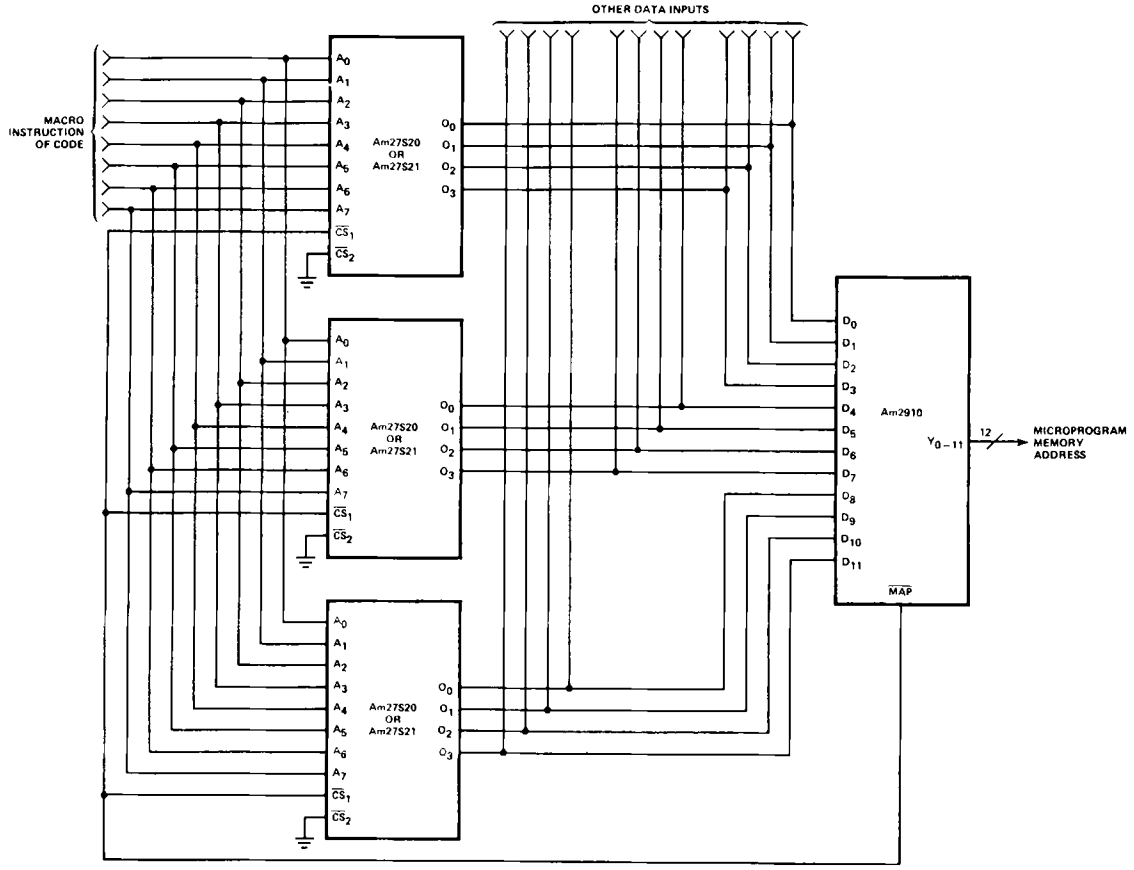
ASCII PAPER TAPE



BPM-034

APPLYING THE Am27S20/21

Typical application of the Am27S20/21 is shown below. The Am27S20/21's are employed as mapping ROMs in a microprogram computer control unit. The eight-bit macroinstruction from main memory is brought into the A_{0-7} inputs of the mapping ROM array. The instruction is mapped into a 12-bit address space with each PROM output supplying 4 bits. The 12 bits of address are then supplied to the "D" inputs of the Am2910 as a possible next address source for microprogram memory. The $\overline{MAP}$ output of the Am2910 is connected to the $\overline{CS}_1$ input of the Am27S20/21 such that when the $\overline{CS}_1$ input is HIGH, the outputs of the PROMs are either HIGH in the case of the Am27S20 or in the three-state mode in the case of the Am27S21. In both cases the $\overline{CS}_2$ input is grounded, thus data from other sources are free to drive the D inputs of the Am2910 when $\overline{MAP}$ is HIGH.

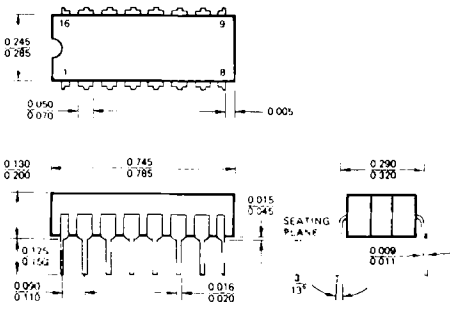


MICROPROGRAMMING INSTRUCTION MAPPING

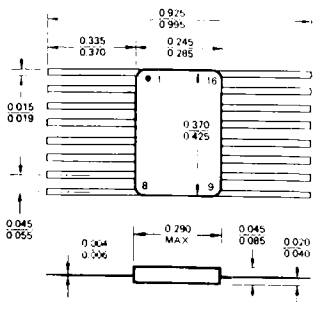
BPM-035

PHYSICAL DIMENSIONS
Dual-In-Line

16-Pin Ceramic



16-Pin Flat Package



Am27S18 • Am27S19

256-Bit Generic Series Bipolar PROM

DISTINCTIVE CHARACTERISTICS

- High Speed – 40ns max commercial range access time
- Excellent performance over full MIL and commercial ranges
- Highly reliable, ultra-fast programming Platinum-Silicide fuses
- High programming yield
- Low current PNP inputs
- High current open collector and three-state outputs
- Fast chip select
- Access time tested with N^2 patterns
- Pin for pin replacements for industry standard products
- Common Generic PROM series electrical characteristics and simple programming procedures.

FUNCTIONAL DESCRIPTION

The Am27S18 and Am27S19 are high speed electrically programmable Schottky read only memories. Organized in the industry standard 32 x 8 configuration, they are available in both open collector Am27S18 and three-state Am27S19 output versions. After programming, stored information is read on outputs O_0-O_7 by applying unique binary addresses to A_0-A_4 and holding the chip select input, $\overline{CS}$, at a logic LOW. If the chip select input goes to a logic HIGH, O_0-O_7 go to the off or high impedance state.

GENERIC SERIES CHARACTERISTICS

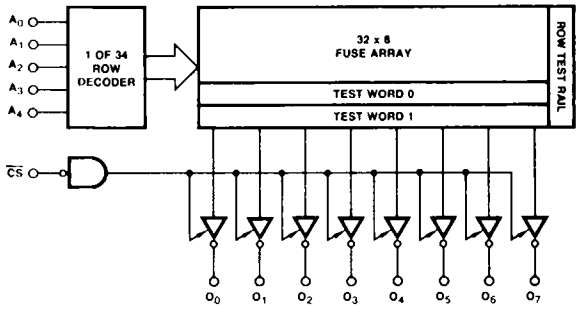
The Am27S18 and Am27S19 are members of an Advanced PROM series incorporating common electrical characteristics and programming procedures. All parts in this series are produced with a fusible link at each memory location storing a logic LOW and can be selectively programmed to a logic HIGH by applying appropriate voltages to the circuit.

All parts are fabricated with AMD's fast programming highly reliable Platinum-Silicide Fuse technology. Utilizing easily implemented programming (and common programming personality card sets) these products can be rapidly programmed to any customized pattern. Extra test words are pre-programmed during manufacturing to insure extremely high field programming yields, and produce excellent parametric correlation.

Platinum-Silicide was selected as the fuse link material to achieve a well controlled melt rate resulting in large non-conductive gaps that ensure very stable long term reliabilty. Extensive operating testing has proven that this low-field, large-gap technology offers the best reliability for fusible link PROMs.

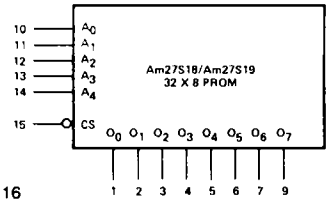
Common design features include active loading of all critical AC paths regulated by a built-in temperature and voltage compensated bias network to provide excellent parametric performance over MIL supply and temperature ranges. Selective feedback techniques have been employed to minimize delays through all critical paths producing the fastest speeds possible from Schottky processed PROMs.

BLOCK DIAGRAM



BPM-018

LOGIC SYMBOL



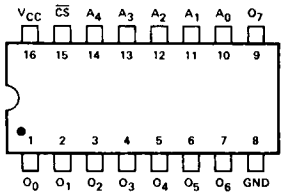
V_{CC} = Pin 16
GND = Pin 8

BPM-019

ORDERING INFORMATION

Package Type	Temperature Range	Order Number
Open Collectors		
Hermetic DIP	0°C to +75°C	AM27S18DC
Hermetic DIP	−55°C to +125°C	AM27S18DM
Hermetic Flat Pak	−55°C to +125°C	AM27S18FM
Three-State Outputs		
Hermetic DIP	0°C to +75°C	AM27S19DC
Hermetic DIP	−55°C to +125°C	AM27S19DM
Hermetic Flat Pak	−55°C to +125°C	AM27S19FM

CONNECTION DIAGRAM
Top View



Note: Pin 1 is marked for orientation.

BPM-020

MAXIMUM RATINGS (Above which the useful life may be impaired)

Storage Temperature	−65°C to +150°C
Temperature (Ambient) Under Bias	−55°C to +125°C
Supply Voltage to Ground Potential (Pin 16 to Pin 8) Continuous	−0.5V to +7.0V
DC Voltage Applied to Outputs (Except During Programming)	−0.5V to +V_{CC} max.
DC Voltage Applied to Outputs During Programming	21V
Output Current into Outputs During Programming (Max. Duration of 1 sec.)	200mA
DC Input Voltage	−0.5V to +5.5V
DC Input Current	−30mA to +5mA

OPERATING RANGE

COM'L	Am27S18XC, Am27S19XC	T_A = 0°C to +75°C	V_{CC} = 5.0V ±5%
MIL	Am27S18XM, Am27S19XM	T_A = −55°C to +125°C	V_{CC} = 5.0V ±10%

ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE (Unless Otherwise Noted)

PRELIMINARY DATA

Parameters	Description	Test Conditions	Min.	Typ. (Note 1)	Max.	Units
V_{OH} (Am27LS19 only)	Output HIGH Voltage	V_{CC} = MIN., I_{OH} = −2.0mA V_{IN} = V_{IH} or V_{IL}	2.4			Volts
V_{OL}	Output LOW Voltage	V_{CC} = MIN., I_{OL} = 16mA V_{IN} = V_{IH} or V_{IL}			0.45	Volts
V_{IH}	Input HIGH Level	Guaranteed input logical HIGH voltage for all inputs	2.0			Volts
V_{IL}	Input LOW Level	Guaranteed input logical LOW voltage for all inputs			0.8	Volts
I_{IL}	Input LOW Current	V_{CC} = MAX., V_{IN} = 0.45V		−0.010	−0.250	mA
I_{IH}	Input HIGH Current	V_{CC} = MAX., V_{IN} = 2.7V			25	µA
I_I	Input HIGH Current	V_{CC} = MAX., V_{IN} = 5.5V			1.0	mA
I_{SC} (Am27LS19 only)	Output Short Circuit Current	V_{CC} = MAX., V_{OUT} = 0.0V (Note 2)	−20	−40	−90	mA
I_{CC}	Power Supply Current	All inputs = GND V_{CC} = MAX.		90	115	mA
V_I	Input Clamp Voltage	V_{CC} = MIN., I_{IN} = −18mA			−1.2	Volts
I_{CEX}	Output Leakage Current	V_{CC} = MAX., $V_{\overline{CS}}$ = 2.4V; Am27LS19 only; V_O = 4.5V			40	µA
		V_{CC} = MAX., $V_{\overline{CS}}$ = 2.4V; Am27LS19 only; V_O = 2.4V			40	µA
		V_{CC} = MAX., $V_{\overline{CS}}$ = 2.4V; Am27LS19 only; V_O = 0.4V			−40	µA
C_{IN}	Input Capacitance	V_{IN} = 2.0V @ f = 1 MHz (Note 3)		4		pF
C_{OUT}	Output Capacitance	V_{OUT} = 2.0V @ f = 1 MHz (Note 3)		8		pF

Notes: 1. Typical limits are at V_{CC} = 5.0V and T_A = 25°C.
2. Not more than one output should be shorted at a time. Duration of the short circuit should not be more than one second.
3. These parameters are not 100% tested, but periodically sampled.

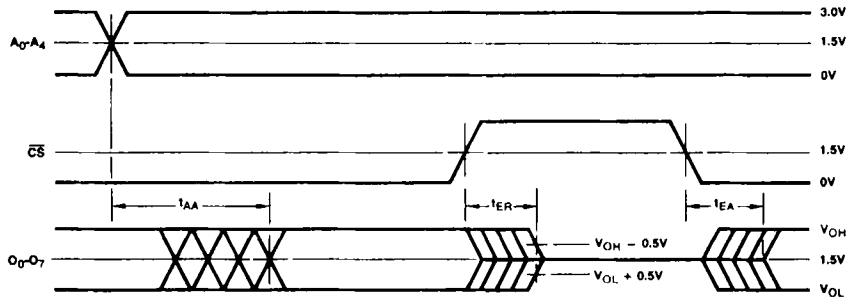
SWITCHING CHARACTERISTICS OVER OPERATING RANGE

PRELIMINARY DATA

Parameter	Description	Test Conditions	Typ 5V 25°C	Max COM'L	Max MIL	Units
t_{AA}	Address Access Time	AC Test Load (See Notes 1-3)	25	40	50	ns
t_{EA}	Enable Access Time		15	25	30	ns
t_{ER}	Enable Recovery Time		15	25	30	ns

Notes: 1. t_{AA} is tested with switch S_1 closed and C_L = 30pF.
2. For open collector outputs, t_{EA} and t_{ER} are tested with S_1 closed to the 1.5V output level. C_L = 30pF.
3. For three state outputs, t_{EA} is tested with C_L = 30pF to the 1.5V level; S_1 is open for high impedance to HIGH tests and closed for high impedance to LOW tests. t_{ER} is tested with C_L = 5pF. HIGH to high impedance tests are made with S_1 open to an output voltage of V_{OH} − 0.5V; LOW to high impedance tests are made with S_1 closed to the V_{OL} + 0.5V level.

SWITCHING WAVEFORMS



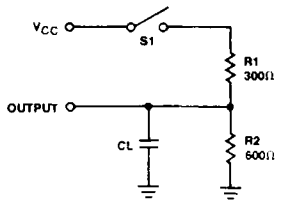
Note: Level on output while $\overline{CS}$ is HIGH is determined externally.

BPM 021

KEY TO TIMING DIAGRAM

WAVEFORM	INPUTS	OUTPUTS	WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY		DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L		DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H			

AC TEST LOAD



BPM-022

PROGRAMMING

The Am27S18 and Am27S19 are manufactured with a conductive Platinum-Silicide link at each bit location. The output of the memory with the link in place is LOW. To program the device, the fusible links are selectively opened.

The fusible links are opened one at a time by passing current through them from a 20 volt supply which is applied to one memory output after the $\overline{CS}$ input is at a logic HIGH. Current is gated through the addressed fuse by raising the $\overline{CS}$ input from a logic HIGH to 15 volts. After 50 μsec, the 20 volt supply is removed, the chip enabled, and the output level sensed to determine if the link has opened. Most links will open within 50 μsec. Occasionally a link will be stronger and require additional programming cycles. The recommended duration of additional programming periods is 5 msec. If a link has not opened after a total elapsed programming time of 400 msec, further programming of the device should not be attempted. Successive links are programmed in the same manner until all desired bit locations have been programmed to the HIGH level.

Typical current into an output during programming will be approximately 140mA until the fuse link is opened, after which the current drops to approximately 40mA. Current into the $\overline{CS}$ pin when it is raised to 15 volts is typically 1.5mA.

The memories may become hot during programming due to the large currents being passed. Programming cycles should not be applied to one device more than 5 seconds to avoid heat damage. If this programming time is exceeded, all power to the chip including V_{CC} should be removed for a period of 5 seconds after which programming may be resumed.

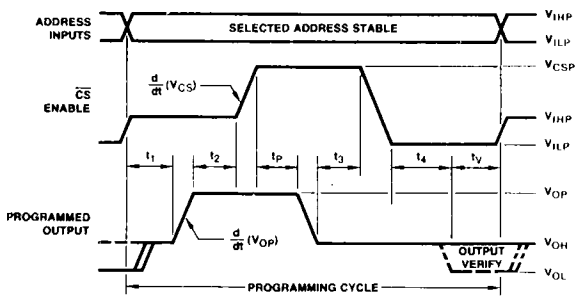
When all programming has been completed, the data content of the memory should be verified by sequentially reading all words. Occasionally this verification will show that an extra undesired link has been fused. Should this occur, immediately check the programming equipment to make sure that all device pins are firmly contacting the programming socket, that the input signal levels exhibit sufficient noise margins, and that the programming voltages are within the specified limits. All of these conditions must be maintained during programming. AMD PROMs are thoroughly tested to minimize unwanted fusing; fusing extra bits is generally related to programming equipment problems.

PROGRAMMING PARAMETERS

Parameter	Description	Min.	Max.	Units
V_{CCP}	V_{CC} During Programming	5.0	5.5	Volts
V_{IHP}	Input HIGH Level During Programming	2.4	5.5	Volts
V_{ILP}	Input LOW Level During Programming	0.0	0.45	Volts
V_{CSP}	$\overline{CS}$ Voltage During Programming	14.5	15.5	Volts
V_{OP}	Output Voltage During Programming	19.5	20.5	Volts
V_{ONP}	Voltage on Outputs Not to be Programmed	0	V_{CCP}+0.3	Volts
I_{ONP}	Current into Outputs Not to be Programmed		20	mA
$d(V_{OP})/dt$	Rate of Output Voltage Change	20	250	V/μsec
$d(V_{CS})/dt$	Rate of $\overline{CS}$ Voltage Change	100	1000	V/μsec
t_P	Programming Period – First Attempt	50	100	μsec
	Programming Period – Subsequent Attempts	5.0	15	msec

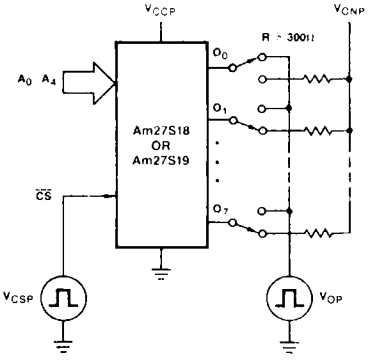
Notes:
1. All delays between edges are specified from completion of the first edge to beginning of the second edge; i.e., not to the midpoints.
2. Delays t_1, t_2, t_3 and t_4 must be greater than 100 ns; maximum delays of 1 μsec are recommended to minimize heating during programming.
3. During t_V, a user defined period, the output being programmed is switched to the load R and read to determine if additional pulses are required.
4. Outputs not being programmed are connected to V_{ONP} through resistor R which provides output current limiting.

PROGRAMMING WAVEFORMS



BPM-023

SIMPLIFIED PROGRAMMING DIAGRAM



BPM-024

PROGRAMMING EQUIPMENT

Generic programming boards and device adapters are available from the sources listed below. In each case, the programming boards are used in these manufacturer's automatic programmers to program all AMD generic series bipolar PROMs; individual adapters are required for each basic part type in the series.

SOURCE AND LOCATION	Data I/O Corp. P.O. Box 308 Issaquah, Wash. 98027	Pro-Log Corp. 2411 Garden Road Monterey, Ca. 93940
PROGRAMMER MODEL(S)	Model 5, 7 and 9	M900 and M920
AMD GENERIC BIPOLAR PROM PERSONALITY BOARD	909-1286-1	PM9058
Am27S18 • Am27S19 ADAPTERS AND CONFIGURATOR	715-1407-1	PA16-6 and 32 x 8 (L)

OBTAINING PROGRAMMED UNITS

Programmed devices may be purchased from your distributor or Advanced Micro Devices. The program data should be submitted in the form of a punched paper tape and must be accompanied by a written truth table. The punched tape can be delivered with your order or may be transmitted over a TWX machine or time-sharing terminal. ASCII BPNF is our preferred paper tape format.

Truth tables are also acceptable, but are much less desirable especially for larger density PROMs. Submission of a truth table requires the generation of a punched paper tape at the distributor or factory resulting in longer lead times, greater possibility of error, and higher cost.

ASCII BPNF

An example of an ASCII tape in the BPNF format is shown below. They can be punched on any Teletype® or on a TWX or Telex machine. The format chosen provides relatively good error detection. Paper tapes must consist of:

1. A leader of at least 25 rubouts.
2. The data patterns for all 32 words, starting with word 0, in the following format:
   a. Any characters, including carriage return and line feed, except "B".
   b. The letter "B", indicating the beginning of the data word.
   c. A sequence of eight Ps or Ns, starting with output O_7.
   d. The letter "F", indicating the finish of the data word.
   e. Any text, including carriage return and line feed, except the letter "B".
3. A trailer of at least 25 rubouts.

A P is a HIGH logic level = 2.4 volts.
An N is a LOW logic level = 0.4 volts.

A convenient pattern to use for the data words is to prefix the word (or every few words with the word number, then type the data word, then a comment, then carriage return and line feed as shown below. There must be no characters between the B and the F except for the eight Ps and Ns. If an error is made in a word, the entire word must be cancelled with rubouts back to the letter B, then the word re-typed beginning with the B.

When TWXing your tape, be sure the tape is in even parity. Parity is not necessary if the tape is mailed.

TYPICAL PAPER TAPE FORMAT

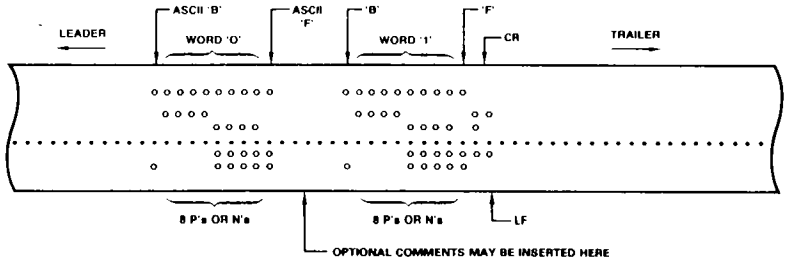
```
ØØØ   BPNPPNNNPF   WORD ZERO (R) (L)
      BPPPPPPNNF   COMMENT FIELD (R) (L)
ØØ2   BNNNPPPPNF   ANY (R) (L)
      BNNNNNNNNF   TEXT (R) (L)
ØØ4   BPNNNNNNPF   CAN (R) (L)
      BNPPNPPNNF   GO (R) (L)
ØØ6   BPNNPPPNNF   HERE (R) (L)
 .          .          .
Ø31   BNNNNPPPNF   END (R) (L)

(R) = CARRIAGE RETURN
(L) = LINE FEED
```

RESULTING DEVICE TRUTH TABLE ($\overline{CS}$ = LOW)

A_4	A_3	A_2	A_1	A_0	O_7	O_6	O_5	O_4	O_3	O_2	O_1	O_0
L	L	L	L	L	H	L	H	H	L	L	L	H
L	L	L	L	H	H	H	H	H	H	H	L	L
L	L	L	H	L	L	L	L	H	H	H	H	L
L	L	L	H	H	L	L	L	L	L	L	L	L
L	L	H	L	L	H	L	L	L	L	L	L	H
L	L	H	L	H	L	H	H	L	H	H	L	L
L	L	H	H	L	H	L	L	H	H	H	L	L
⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
H	H	H	H	H	L	L	L	L	H	H	H	L

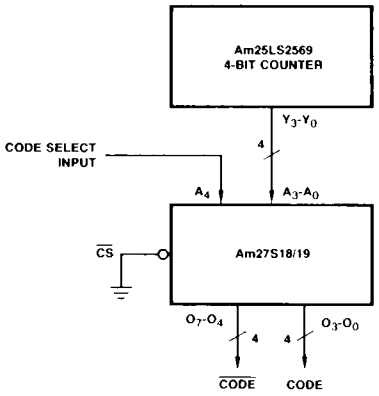
ASCII PAPER TAPE



BPM-025

APPLYING THE Am27S18 AND Am27S19

The Am27S18 and Am27S19 PROMs may be used as code converters. Examples include conversion of hexadecimal, octal or BCD to seven segment display drive format. In many code conversion applications an extra PROM address input is available and may be used as a polarity control, blanking control or code selector input. The use of a single Am27S18 or Am27S19 to convert the outputs of a binary counter to either excess three or gray code format is illustrated below. In this case both codes are generated in true and complemented form simultaneously.



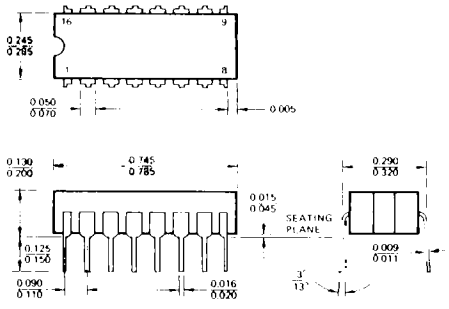
BPM-026

TRUTH TABLE

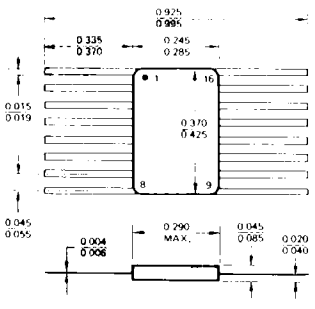
ADDRESS					COMPLEMENT				TRUE				
A_4	A_3	A_2	A_1	A_0	O_7	O_6	O_5	O_4	O_3	O_2	O_1	O_0	
0	0	0	0	0	1	1	0	0	0	0	1	1	EXCESS THREE CODE
0	0	0	0	1	1	0	1	1	0	1	0	0	
0	0	0	1	0	1	0	1	0	0	1	0	1	
0	0	0	1	1	1	0	0	1	0	1	1	0	
0	0	1	0	0	1	0	0	0	0	1	1	1	
0	0	1	0	1	0	1	1	1	1	0	0	0	
0	0	1	1	0	0	1	1	0	1	0	0	1	
0	0	1	1	1	0	1	0	1	1	0	1	0	
0	1	0	0	0	0	1	0	0	1	0	1	1	
0	1	0	0	1	0	0	1	1	1	1	0	0	
0	1	0	1	0	X	X	X	X	X	X	X	X	
0	1	0	1	1	X	X	X	X	X	X	X	X	
0	1	1	0	0	X	X	X	X	X	X	X	X	
0	1	1	0	1	X	X	X	X	X	X	X	X	
0	1	1	1	0	X	X	X	X	X	X	X	X	
0	1	1	1	1	X	X	X	X	X	X	X	X	
1	0	0	0	0	1	1	1	1	0	0	0	0	GRAY CODE
1	0	0	0	1	1	1	1	0	0	0	0	1	
1	0	0	1	0	1	1	0	0	0	0	1	1	
1	0	0	1	1	1	1	0	1	0	0	1	0	
1	0	1	0	0	1	0	0	1	0	1	1	0	
1	0	1	0	1	1	0	0	0	0	1	1	1	
1	0	1	1	0	1	0	1	0	0	1	0	1	
1	0	1	1	1	1	0	1	1	0	1	0	0	
1	1	0	0	0	0	0	1	1	1	1	0	0	
1	1	0	0	1	0	0	1	0	1	1	0	1	
1	1	0	1	0	0	0	0	0	1	1	1	1	
1	1	0	1	1	0	0	0	1	1	1	1	0	
1	1	1	0	0	0	1	0	1	1	0	1	0	
1	1	1	0	1	0	1	0	0	1	0	1	1	
1	1	1	1	0	0	1	1	0	1	0	0	1	
1	1	1	1	1	0	1	1	1	1	0	0	0	

PHYSICAL DIMENSIONS
Dual-In-Line

16-Pin Ceramic



16-Pin Flat Package



intel

2764
(8K x 8) UV ERASABLE PROM

- **200 ns (2764-2) Maximum Access Time . . . HMOS*-E Technology**
- **Compatible to High Speed 8mHz 8086-2 MPU . . . Zero WAIT State**
- **Two Line Control**
- **Pin Compatible to 2732A EPROM**
- **Industry Standard Pinout . . . JEDEC Approved**
- **Low Active Current...100mA Max.**
- **±10% V_{CC} Tolerance Available**

The Intel® 2764 is a 5V only, 65,536-bit ultraviolet erasable and electrically programmable read-only memory (EPROM). The standard 2764 access time is 250ns with speed selection available at 200ns. The access time is compatible to high performance microprocessors, such as Intel's 8mHz 8086-2. In these systems, the 2764 allows the microprocessor to operate without the addition of WAIT states.

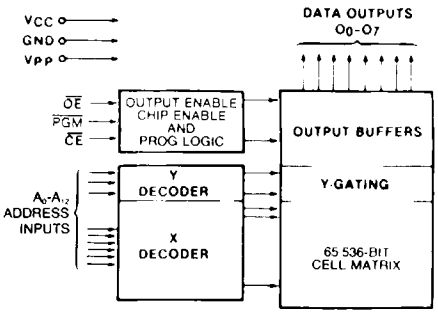
An important 2764 feature is the separate output control, Output Enable ($\overline{OE}$) from the Chip Enable control ($\overline{CE}$). The $\overline{OE}$ control eliminates bus contention in multiple bus microprocessor systems. Intel's Application Note AP-72 describes the microprocessor system implementation of the $\overline{OE}$ and $\overline{CE}$ controls on Intel's EPROMs. AP-72 is available from Intel's Literature Department.

The 2764 has a standby mode which reduces the power dissipation without increasing access time. The active current is 100mA, while the standby current is only 40mA. The standby mode is achieved by applying a TTL-high signal to the $\overline{CE}$ input.

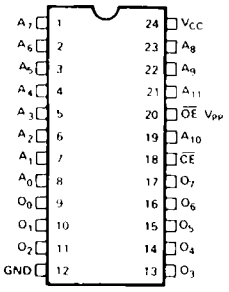
±10% V_{CC} tolerance is available as an alternative to the standard ± 5% V_{CC} tolerance for the 2764. This can allow the system designer more leeway in terms of his power supply requirements and other system parameters.

The 2764 is fabricated with HMOS*-E technology, Intel's high-speed N-channel MOS Silicon Gate Technology.

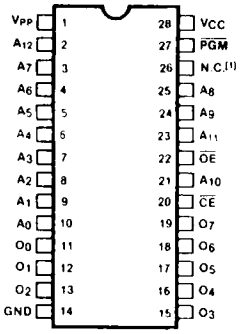
BLOCK DIAGRAM



2732A PIN CONFIGURATION



2764 PIN CONFIGURATION



(1) For upgradability to JEDEC approved 128K EPROMs, provide an address line to pin 26. For compatibility with the 2732A and 32K ROMs, provide a trace from V_{CC} to pin 26.

MODE SELECTION

MODE \ PINS	$\overline{CE}$ (20)	$\overline{OE}$ (22)	$\overline{PGM}$ (27)	V_{PP} (1)	V_{CC} (28)	Outputs (11-13, 15-19)
Read	V_{IL}	V_{IL}	V_{IH}	V_{CC}	V_{CC}	D_{OUT}
Standby	V_{IH}	x	x	V_{CC}	V_{CC}	High Z
Program	V_{IL}	x	V_{IL}	V_{PP}	V_{CC}	D_{IN}
Program Verify	V_{IL}	V_{IL}	V_{IH}	V_{PP}	V_{CC}	D_{OUT}
Program Inhibit	V_{IH}	x	x	V_{PP}	V_{CC}	High Z

x can be either V_{IL} or V_{IH}.

PIN NAMES

A_0-A_{12}	ADDRESSES
$\overline{CE}$	CHIP ENABLE
$\overline{OE}$	OUTPUT ENABLE
O_0-O_7	OUTPUTS
$\overline{PGM}$	PROGRAM
N.C.	NO CONNECT

*HMOS is a patented process of Intel Corporation.

ABSOLUTE MAXIMUM RATINGS*

Temperature Under Bias .....−10°C to +80°C
Storage Temperature .....−65°C to +125°C
All Input or Output Voltages with
Respect to Ground .....+6V to −0.6V
V_{PP} Supply Voltage with Respect to Ground
During Programming .....+22V to −0.6V

*COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

D.C. AND A.C. OPERATING CONDITIONS DURING READ

	2764-2	2764	2764-3	2764-4
Operating Temperature Range	0°C–70°C	0°C–70°C	0°C–70°C	0°C–70°C
V_{CC} Power Supply[1,2]	5V ± 5%	5V ± 5%	5V ± 5%	5V ± 5%
V_{PP} Voltage[2]	$V_{PP} = V_{CC}$	$V_{PP} = V_{CC}$	$V_{PP} = V_{CC}$	$V_{PP} = V_{CC}$

2764-25	2764-30	2764-45
0°C–70°C	0°C–70°C	0°C–70°C
5V + 10%	5V + 10%	5V + 10%
$V_{PP} = V_{CC}$	$V_{PP} = V_{CC}$	$V_{PP} = V_{CC}$

READ OPERATION

D.C. AND OPERATING CHARACTERISTICS

Symbol	Parameter	Limits			Unit	Conditions
		Min	Typ[3]	Max		
I_{LI}	Input Load Current			10	μA	$V_{IN} = 5.5V$
I_{LO}	Output Leakage Current			10	μA	$V_{OUT} = 5.5V$
I_{PP1}[2]	V_{PP} Current Read			5	mA	$V_{PP} = 5.5V$
I_{CC1}[2]	V_{CC} Current Standby			40	mA	$\overline{CE} = V_{IH}$
I_{CC2}[2]	V_{CC} Current Active		70	100	mA	$CE = \overline{OE} = V_{IL}$
V_{IL}	Input Low Voltage	.1		+.8	V	
V_{IH}	Input High Voltage	2.0		V_{CC} + 1	V	
V_{OL}	Output Low Voltage			.45	V	$I_{OL} = 2.1$ mA
V_{OH}	Output High Voltage	2.4			V	$I_{OH} = -400$ μA

A.C. CHARACTERISTICS

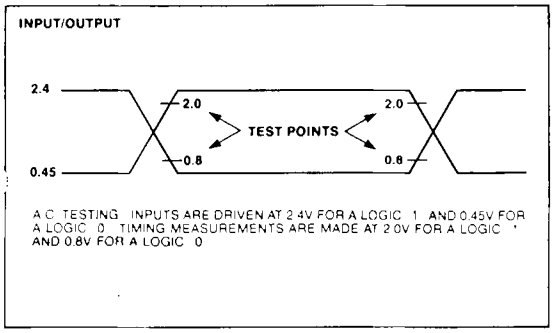
Symbol	Parameter	2764-2 Limits		2764-25 & 2764 Limits		2764-30 & 2764-3 Limits		2764-45 & 2764-4 Limits		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max	Min	Max		
t_{ACC}	Address to Output Delay		200		250		300		450	ns	$\overline{CE}$ $\overline{OE}$ V_{IL}
t_{CE}	$\overline{CE}$ to Output Delay		200		250		300		450	ns	$\overline{OE}$ V_{IL}
t_{OE}	$\overline{OE}$ to Output Delay		75		100		120		150	ns	$\overline{CE}$ V_{IL}
t_{DF}[4]	$\overline{OE}$ High to Output Float	0	60	0	85	0	105	0	130	ns	$\overline{CE}$ V_{IL}
t_{OH}	Output Hold from Addresses, $\overline{CE}$ or $\overline{OE}$ Whichever Occurred First	0		0		0		0		ns	$\overline{CE}$ $\overline{OE}$ V_{IL}

NOTES: 1. V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}.
2. V_{PP} may be connected directly to V_{CC} except during programming. The supply current would then be the sum of I_{CC} and I_{PP1}.
3. Typical values are for $t_A = 25°C$ and nominal supply voltages.
4. This parameter is only sampled and not 100% tested.

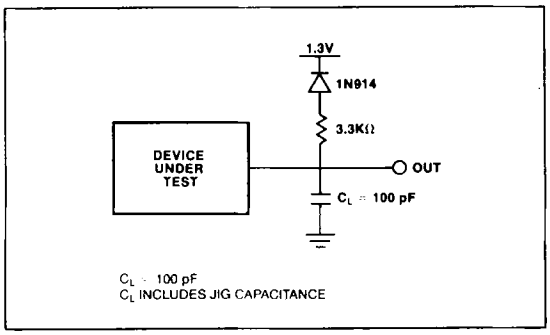
CAPACITANCE $T_A = 25°C$, f = 1MHz

Symbol	Parameter	Typ.[1]	Max.	Unit	Conditions
C_{IN}[2]	Input Capacitance	4	6	pF	$V_{IN}=0V$
C_{OUT}	Output Capacitance	8	12	pF	$V_{OUT}=0V$

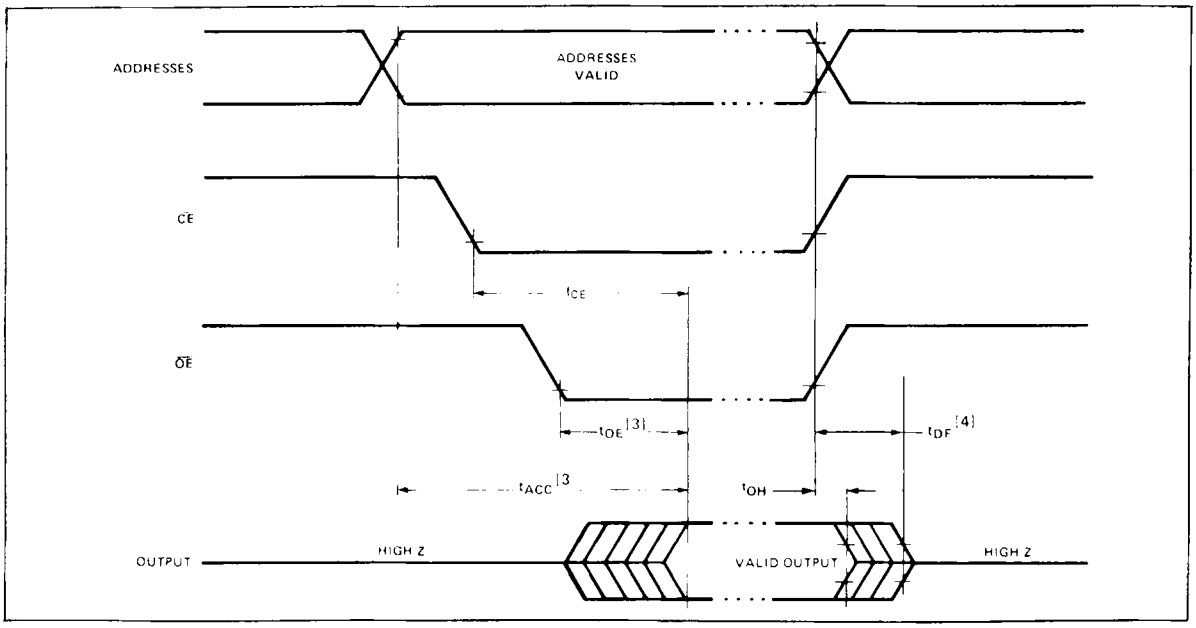
A.C. TESTING INPUT, OUTPUT WAVEFORM



A.C. TESTING LOAD CIRCUIT



A.C. WAVEFORMS



NOTES: 1. Typical values are for T_A = 25°C and nominal supply voltages.
2. This parameter is only sampled and is not 100% tested.
3. $\overline{OE}$ may be delayed up to $t_{ACC} - t_{OE}$ after the falling edge of $\overline{CE}$ without impact on t_{ACC}.
4. t_{DF} is specified from $\overline{OE}$ or $\overline{CE}$, whichever occurs first.

PROGRAMMING

D.C. PROGRAMMING CHARACTERISTICS: T_A = 25 ±5°C, V_{CC} = 5V ±5%, V_{PP} = 21V ±0.5V (see Note 1)

Symbol	Parameter	Limits				Test Conditions
		Min.	Typ.	Max.	Unit	
I_{LI}	Input Current (All Inputs)			10	μA	$V_{IN} = V_{IL}$ or V_{IH}
V_{OL}	Output Low Voltage During Verify			0.45	V	I_{OL} = 2.1 mA
V_{OH}	Output High Voltage During Verify	2.4			V	I_{OH} = −400 μA
I_{CC2}	V_{CC} Supply Current (Active)			100	mA	
V_{IL}	Input Low Level (All Inputs)	−0.1		0.8	V	
V_{IH}	Input High Level	2.0		V_{CC}+1	V	
I_{PP}	V_{PP} Supply Current			30	mA	$\overline{CE} = V_{IL} = \overline{PGM}$

A.C. PROGRAMMING CHARACTERISTICS: T_A = 25 ±5°C, V_{CC} = 5V ±5%, V_{PP} = 21V ±0.5V (see Note 1)

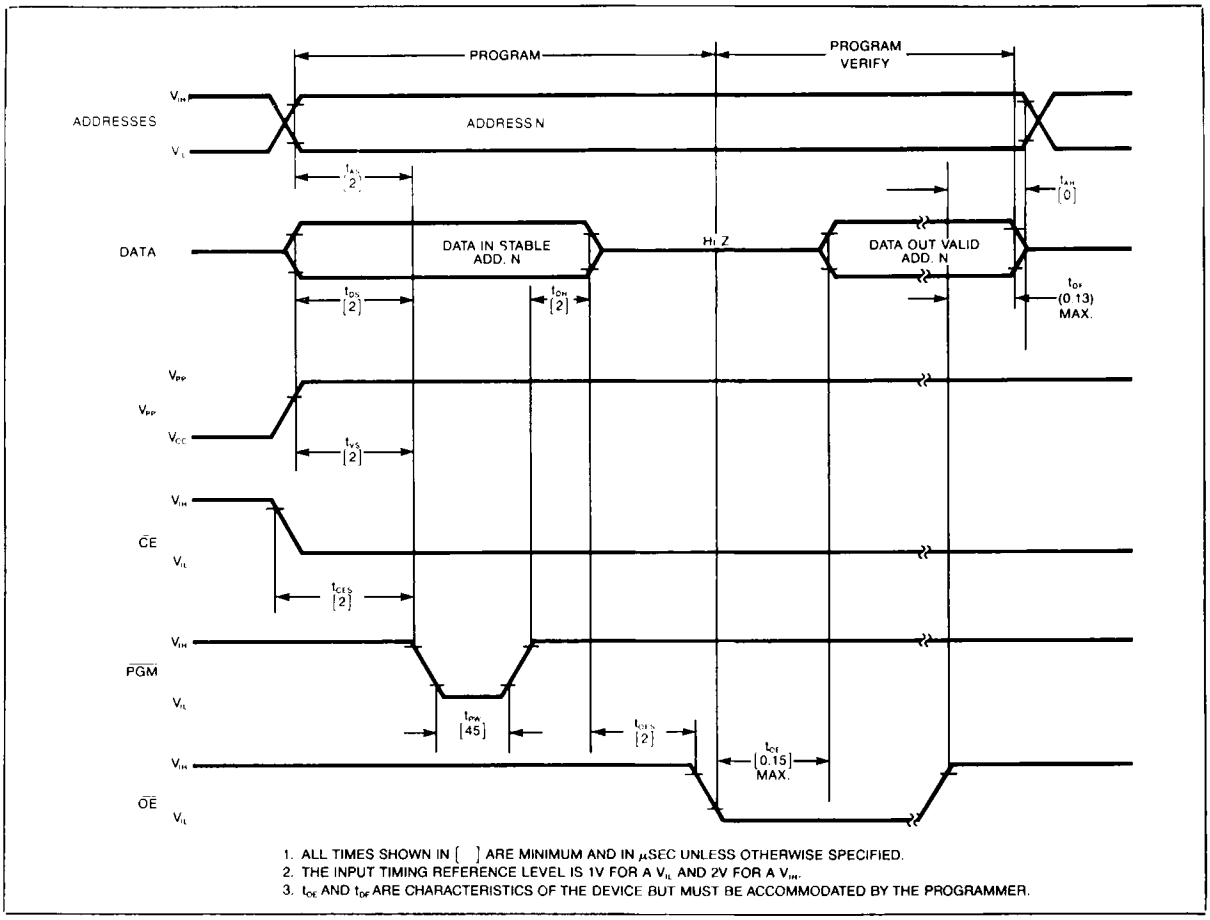
Symbol	Parameter	Limits				Test Conditions*
		Min.	Typ.	Max.	Unit	
t_{AS}	Address Setup Time	2			μs	
t_{OES}	$\overline{OE}$ Setup Time	2			μs	
t_{DS}	Data Setup Time	2			μs	
t_{AH}	Address Hold Time	0			μs	
t_{DH}	Data Hold Time	2			μs	
t_{DF}	Chip Enable to Output Float Delay	0		130	ns	
t_{VS}	V_{PP} Setup Time	2			μs	
t_{PW}	$\overline{PGM}$ Pulse Width During Programming	45	50	55	ms	
t_{CES}	$\overline{CE}$ Setup Time	2			μs	
t_{OE}	Data Valid from $\overline{OE}$			150	ns	

*A.C. CONDITIONS OF TEST

Input Rise and Fall Times (10% to 90%) 20ns
Input Pulse Levels ..... 0.45V to 2.4V
Input Timing Reference Level ..... 1V and 2V
Output Timing Reference Level ..... 0.8V and 2.0V

NOTE:
1. V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}.

PROGRAMMING WAVEFORMS



1. ALL TIMES SHOWN IN [ ] ARE MINIMUM AND IN μSEC UNLESS OTHERWISE SPECIFIED.
2. THE INPUT TIMING REFERENCE LEVEL IS 1V FOR A V_{IL} AND 2V FOR A V_{IH}.
3. t_{OE} AND t_{DF} ARE CHARACTERISTICS OF THE DEVICE BUT MUST BE ACCOMMODATED BY THE PROGRAMMER.

ERASURE CHARACTERISTICS

The erasure characteristics of the 2764 are such that erasure begins to occur when exposed to light with wavelengths shorter than approximately 4000 Angstroms (Å). It should be noted that sunlight and certain types of fluorescent lamps have wavelengths in the 3000–4000 Å range. Data show that constant exposure to room level fluorescent lighting could erase the typical 2764 in approximately 3 years, while it would take approximately 1 week to cause erasure when exposed to direct sunlight. If the 2764 is to be exposed to these types of lighting conditions for extended periods of time, opaque labels are available from Intel which should be placed over the 2764 window to prevent unintentional erasure.

The recommended erasure procedure for the 2764 is exposure to shortwave ultraviolet light which has a wavelength of 2537 Angstroms (Å). The integrated dose (i.e., UV intensity X exposure time) for erasure should be a minimum of 15 W-sec/cm². The erasure time with this dosage is approximately 15 to 20 minutes using an ultraviolet lamp with 12000 μW/cm² power rating. The 2764 should be placed within 1 inch of the lamp tubes during erasure. Some lamps have a filter on their tubes which should be removed before erasure.

DEVICE OPERATION

The five modes of operation of the 2764 are listed in Table 1. A single 5V power supply is required in the read mode. All inputs are TTL levels except for V_{PP}.

TABLE 1. MODE SELECTION

MODE \ PINS	$\overline{CE}$ (20)	$\overline{OE}$ (22)	$\overline{PGM}$ (27)	V_{PP} (1)	V_{CC} (28)	Outputs (11-13, 15-19)
Read	V_{IL}	V_{IL}	V_{IH}	V_{CC}	V_{CC}	D_{OUT}
Standby	V_{IH}	x	x	V_{CC}	V_{CC}	High Z
Program	V_{IL}	x	V_{IL}	V_{PP}	V_{CC}	D_{IN}
Program Verify	V_{IL}	V_{IL}	V_{IH}	V_{PP}	V_{CC}	D_{OUT}
Program Inhibit	V_{IH}	x	x	V_{PP}	V_{CC}	High Z

x can be either V_{IL} or V_{IH}

READ MODE

The 2764 has two control functions, both of which must be logically active in order to obtain data at the outputs. Chip Enable ($\overline{CE}$) is the power control and should be used for device selection. Output Enable ($\overline{OE}$) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t_{ACC}) is equal to the delay from $\overline{CE}$ to output (t_{CE}). Data is available at the outputs after a delay of t_{OE} from the falling edge of $\overline{OE}$, assuming that $\overline{CE}$ has been low and addresses have been stable for at least $t_{ACC}-t_{OE}$.

Standby Mode

The 2764 has a standby mode which reduces the active power current from 100mA to 40mA. The 2764 is placed in the standby mode by applying a TTL high signal to the $\overline{CE}$ input. When in standby mode, the outputs are in a high impedance state, independent of the $\overline{OE}$ input.

Output OR-Tieing

Because EPROMs are usually used in larger memory arrays, Intel has provided 2 control lines which accommodate this multiple memory connection. The two control lines allow for:

a) the lowest possible memory power dissipation, and
b) complete assurance that output bus contention will not occur.

To use these two control lines most efficiently, $\overline{CE}$ (pin 20) should be decoded and used as the primary device selecting function, while $\overline{OE}$ (pin 22) should be made a common connection to all devices in the array and connected to the READ line from the system control bus. This assures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is desired from a particular memory device.

System Consideration

The power switching characteristics of HMOS-E EPROMs require careful decoupling of the devices. The supply current, I_{CC}, has three segments that are of interest to the system designer — the standby current level, the active current level, and the transient current peaks that are produced on the falling and rising edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. The associated transient voltage peaks can be suppressed by complying with Intel's Two-Line Control, as detailed in Intel's Application Note, AP-72, and/or by properly selected decoupling capacitors. It is recommended that a 0.1 μF ceramic capacitor be used on every device between V_{CC} and GND. This should be a high frequency capacitor of low inherent inductance. In addition, a 4.7 μF bulk electrolytic capacitor should be used between V_{CC} and GND for each eight devices. The bulk capacitor should be located near where the power supply is connected to the array. The purpose of the bulk capacitor is to overcome the voltage droop caused by the inductive effects of the PC board-traces.

Programming

Caution: Exceeding 22V on pin 1 (V_{PP}) will damage the 2764.

Initially, and after each erasure, all bits of the 2764 are in the "1" state. Data is introduced by selectively programming "0s" into the desired bit locations. Although only "0s" will be programmed, both "1s" and "0s" can be present in the data word. The only way to change a "0" to a "1" is by ultraviolet light erasure.

The 2764 is in the programming mode when V_{PP} input is at 21V and $\overline{CE}$ and $\overline{PGM}$ are both at TTL low. The data to be programmed is applied 8 bits in parallel to the data output pins. The levels required for the address and data inputs are TTL.

For programming, $\overline{CE}$ should be kept TTL low at all times while V_{PP} is kept at 21V. When the address and data are stable, a 50 msec, active low, TTL program pulse is applied to $\overline{PGM}$ input. A program pulse must be applied at each address location to be programmed. You can program any location at any time—either individually, sequentially, or at random. The program pulse has a maximum width of 55 msec.

Programming of multiple 2764s in parallel with the same data can be easily accomplished due to the simplicity of the programming requirements. Like inputs of the paralleled 2764s may be connected together when they are programmed with the same data. A low level TTL pulse applied to the $\overline{PGM}$ input programs the paralleled 2764s.

Program Inhibit

Programming of multiple 2764s in parallel with different data is also easily accomplished. A high level CE or $\overline{PGM}$ input inhibits the other 2764s from being programmed. Except for $\overline{CE}$ (or $\overline{PGM}$), all like inputs (including $\overline{OE}$) of the parallel 2764s may be common. A TTL low level pulse applied to a 2764 $\overline{CE}$ and $\overline{PGM}$ input with V_{PP} at 21V will program that 2764.

Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify is accomplished with $\overline{CE}$ and $\overline{OE}$ at V_{IL}. However, $\overline{PGM}$ is at V_{IH}.

8041A/8641A/8741A
UNIVERSAL PERIPHERAL INTERFACE
8-BIT MICROCOMPUTER

- **8-Bit CPU plus ROM, RAM, I/O, Timer and Clock in a Single Package**
- **One 8-Bit Status and Two Data Registers for Asynchronous Slave-to-Master Interface**
- **DMA, Interrupt, or Polled Operation Supported**
- **1024 x 8 ROM/EPROM, 64 x 8 RAM, 8-Bit Timer/Counter, 18 Programmable I/O Pins**
- **Fully Compatible with MCS-48™, MCS-80™, MCS-85™, and MCS-86™ Microprocessor Families**
- **Interchangeable ROM and EPROM Versions**
- **3.6 MHz 8741A-8 Available**
- **Expandable I/O**
- **RAM Power-Down Capability**
- **Over 90 Instructions: 70% Single Byte**
- **Single 5V Supply**

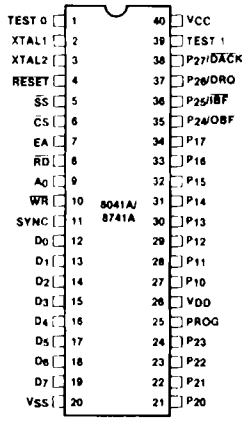
The Intel® 8041A/8741A is a general purpose, programmable interface device designed for use with a variety of 8-bit microprocessor systems. It contains a low cost microcomputer with program memory, data memory, 8-bit CPU, I/O ports, timer/counter, and clock in a single 40-pin package. Interface registers are included to enable the UPI device to function as a peripheral controller in MCS-48™, MCS-80™, MCS-85™, MCS-86™, and other 8-bit systems.

The UPI-41A™ has 1K words of program memory and 64 words of data memory on-chip. To allow full user flexibility the program memory is available as ROM in the 8041A version or as UV-erasable EPROM in the 8741A version. The 8741A and the 8041A are fully pin compatible for easy transition from prototype to production level designs. The 8641A is a one-time programmable (at the factory) 8741A which can be ordered as the first 25 pieces of a new 8041A order. The substitution of 8641A's for 8041A's allows for very fast turnaround for initial code verification and evaluation results.

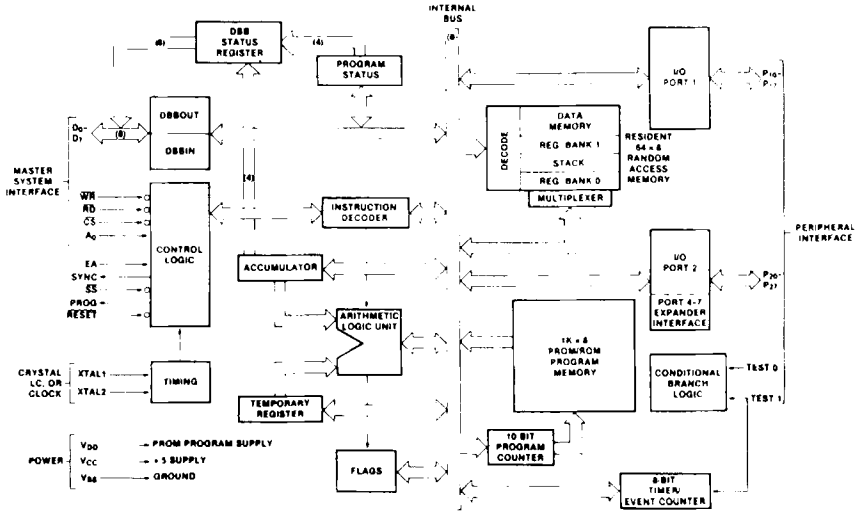
The device has two 8-bit, TTL compatible I/O ports and two test inputs. Individual port lines can function as either inputs or outputs under software control. I/O can be expanded with the 8243 device which is directly compatible and has 16 I/O lines. An 8-bit programmable timer/counter is included in the UPI device for generating timing sequences or counting external inputs. Additional UPI features include: single 5V supply, low power standby mode (in the 8041A), single-step mode for debug (in the 8741A), and dual working register banks.

Because it's a complete microcomputer, the UPI provides more flexibility for the designer than conventional LSI interface devices. It is designed to be an efficient controller as well as an arithmetic processor. Applications include keyboard scanning, printer control, display multiplexing and similar functions which involve interfacing peripheral devices to microprocessor systems.

PIN CONFIGURATION

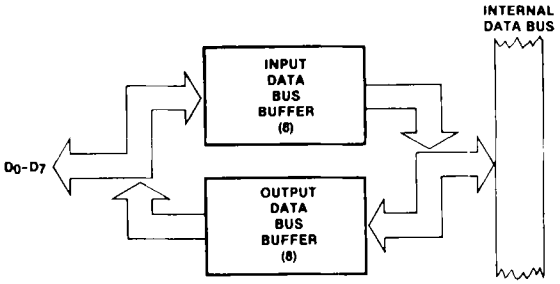


BLOCK DIAGRAM



UPI-41A™ FEATURES AND ENHANCEMENTS

1. Two Data Bus Buffers, one for input and one for output. This allows a much cleaner Master/Slave protocol.



2. 8 Bits of Status

ST_7	ST_6	ST_5	ST_4	F_1	F_0	IBF	OBF
D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0

ST_4-ST_7 are user definable status bits. These bits are defined by the "MOV STS, A" single byte, single cycle instruction. Bits 4-7 of the accumulator are moved to bits 4-7 of the status register. Bits 0-3 of the status register are not affected.

MOV STS, A Op Code: 90H

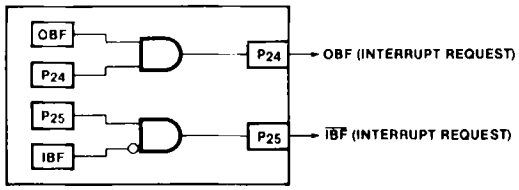
1	0	0	1	0	0	0	0
D_7							D_0

3. $\overline{RD}$ and $\overline{WR}$ are edge triggered. IBF, OBF, F_1 and INT change internally after the trailing edge of $\overline{RD}$ or $\overline{WR}$.

4. P_{24} and P_{25} are port pins or Buffer Flag pins which can be used to interrupt a master processor. These pins default to port pins on Reset.

   If the "EN FLAGS" instruction has been executed, P_{24} becomes the OBF (Output Buffer Full) pin. A "1" written to P_{24} enables the OBF pin (the pin outputs the OBF Status Bit). A "0" written to P_{24} disables the OBF pin (the pin remains low). This pin can be used to indicate that valid data is available from the UPI-41A (in Output Data Bus Buffer).

   If "EN FLAGS" has been executed, P_{25} becomes the $\overline{IBF}$ (Input Buffer Full) pin. A "1" written to P_{25} enables the $\overline{IBF}$ pin (the pin outputs the inverse of the IBF Status Bit). A "0" written to P_{25} disables the $\overline{IBF}$ pin (the pin remains low). This pin can be used to indicate that the UPI-41A is ready for data.



DATA BUS BUFFER INTERRUPT CAPABILITY

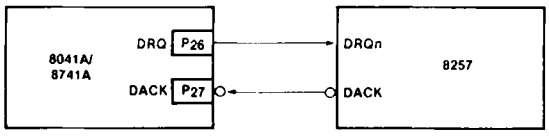
EN FLAGS Op Code: 0F5H

1	1	1	1	0	1	0	1
D_7							D_0

5. P_{26} and P_{27} are port pins or DMA handshake pins for use with a DMA controller. These pins default to port pins on Reset.

   If the "EN DMA" instruction has been executed, P_{26} becomes the DRQ (DMA ReQuest) pin. A "1" written to P_{26} causes a DMA request (DRQ is activated). DRQ is deactivated by DACK·RD, DACK·WR, or execution of the "EN DMA" instruction.

   If "EN DMA" has been executed, P_{27} becomes the $\overline{DACK}$ (DMA ACKnowledge) pin. This pin acts as a chip select input for the Data Bus Buffer registers during DMA transfers.



DMA HANDSHAKE CAPABILITY

EN DMA Op Code: 0E5H

1	1	1	0	0	1	0	1
D_1							D_0

PIN DESCRIPTION

Signal	Description
$D_0 - D_7$ (BUS)	Three-state, bidirectional DATA BUS BUFFER lines used to interface the UPI-41A to an 8-bit master system data bus.
P_{10}-P_{17}	8-bit, PORT 1 quasi-bidirectional I/O lines.
P_{20}-P_{27}	8-bit, PORT 2 quasi-bidirectional I/O lines. The lower 4 bits (P_{20}-P_{23}) interface directly to the 8243 I/O expander device and contain address and data information during PORT 4-7 access. The upper 4 bits (P_{24}-P_{27}) can be programmed to provide Interrupt Request and DMA Handshake capability. Software control can configure P_{24} as OBF (Output Buffer Full), P_{25} as $\overline{IBF}$ (Input Buffer Full), P_{26} as DRQ (DMA Request), and P_{27} as $\overline{DACK}$ (DMA ACKnowledge).
$\overline{WR}$	I/O write input which enables the master CPU to write data and command words to the UPI-41A INPUT DATA BUS BUFFER.
$\overline{RD}$	I/O read input which enables the master CPU to read data and status words from the OUTPUT DATA BUS BUFFER or status register.
$\overline{CS}$	Chip select input used to select one UPI-41A out of several connected to a common data bus.
A_0	Address input used by the master processor to indicate whether byte transfer is data or command.
TEST 0, TEST 1	Input pins which can be directly tested using conditional branch instructions.
	T_1 also functions as the event timer input (under software control). T_0 is used during PROM programming and verification in the 8741A.
XTAL1, XTAL2	Inputs for a crystal, LC or an external timing signal to determine the internal oscillator frequency.
SYNC	Output signal which occurs once per UPI-41A instruction cycle. SYNC can be used as a strobe for external circuitry; it is also used to synchronize single step operation.
EA	External access input which allows emulation, testing and PROM/ROM verification.
PROG	Multifunction pin used as the program pulse input during PROM programming.
	During I/O expander access the PROG pin acts as an address/data strobe to the 8243.
$\overline{RESET}$	Input used to reset status flip-flops and to set the program counter to zero.
	$\overline{RESET}$ is also used during PROM programming and verification.
$\overline{SS}$	Single step input used in the 8741A in conjunction with the SYNC output to step the program through each instruction.
V_{CC}	+5V main power supply pin.
V_{DD}	+5V during normal operation. +25V during programming operation. Low power standby pin in ROM version.
V_{SS}	Circuit ground potential.

UPI™ INSTRUCTION SET

Mnemonic	Description	Bytes	Cycles
ACCUMULATOR			
ADD A,Rr	Add register to A	1	1
ADD A,@Rr	Add data memory to A	1	1
ADD A,#data	Add immediate to A	2	2
ADDC A,Rr	Add register to A with carry	1	1
ADDC A,@Rr	Add data memory to A with carry	1	1
ADDC A,#data	Add immed. to A with carry	2	2
ANL A,Rr	AND register to A	1	1
ANL A,@Rr	AND data memory to A	1	1
ANL A,#data	AND immediate to A	2	2
ORL A,Rr	OR register to A	1	1
ORL A,@Rr	OR data memory to A	1	1
ORL A,#data	OR immediate to A	2	2
XRL A,Rr	Exclusive OR register to A	1	1
XRL A,@Rr	Exclusive OR data memory to A	1	1
XRL A,#data	Exclusive OR immediate to A	2	2
INC A	Increment A	1	1
DEC A	Decrement A	1	1
CLR A	Clear A	1	1
CPL A	Complement A	1	1
DA A	Decimal Adjust A	1	1
SWAP A	Swap nibbles of A	1	1
RL A	Rotate A left	1	1
RLC A	Rotate A left through carry	1	1
RR A	Rotate A right	1	1
RRC A	Rotate A right through carry	1	1
INPUT/OUTPUT			
IN A,Pp	Input port to A	1	2
OUTL Pp,A	Output A to port	1	2
ANL Pp,#data	AND immediate to port	2	2
ORL Pp,#data	OR immediate to port	2	2
IN A,DBB	Input DBB to A, clear IBF	1	1
OUT DBB,A	Output A to DBB, set OBF	1	1
MOV STS,A	A_4-A_7 to Bits 4-7 of Status	1	1
MOVD A,Pp	Input Expander port to A	1	2
MOVD Pp,A	Output A to Expander port	1	2
ANLD Pp,A	AND A to Expander port	1	2
ORLD Pp,A	OR A to Expander port	1	2
DATA MOVES			
MOV A,Rr	Move register to A	1	1
MOV A,@Rr	Move data memory to A	1	1
MOV A,#data	Move immediate to A	2	2
MOV Rr,A	Move A to register	1	1
MOV @Rr,A	Move A to data memory	1	1
MOV Rr,#data	Move immediate to register	2	2
MOV @Rr,#data	Move immediate to data memory	2	2
MOV A,PSW	Move PSW to A	1	1
MOV PSW,A	Move A to PSW	1	1
XCH A,Rr	Exchange A and register	1	1
XCH A,@Rr	Exchange A and data memory	1	1
XCHD A,@Rr	Exchange digit of A and register	1	1
MOVP A,@A	Move to A from current page	1	2
MOVP3, A,@A	Move to A from page 3	1	2
TIMER/COUNTER			
MOV A,T	Read Timer/Counter	1	1
MOV T,A	Load Timer/Counter	1	1
STRT T	Start Timer	1	1
STRT CNT	Start Counter	1	1
STOP TCNT	Stop Timer/Counter	1	1
EN TCNTI	Enable Timer/Counter Interrupt	1	1
DIS TCNTI	Disable Timer/Counter Interrupt	1	1

Mnemonic	Description	Bytes	Cycles
CONTROL			
EN DMA	Enable DMA Handshake Lines	1	1
EN I	Enable IBF Interrupt	1	1
DIS I	Disable IBF Interrupt	1	1
EN FLAGS	Enable Master Interrupts	1	1
SEL RB0	Select register bank 0	1	1
SEL RB1	Select register bank 1	1	1
NOP	No Operation	1	1
REGISTERS			
INC Rr	Increment register	1	1
INC @Rr	Increment data memory	1	1
DEC Rr	Decrement register	1	1
SUBROUTINE			
CALL addr	Jump to subroutine	2	2
RET	Return	1	2
RETR	Return and restore status	1	2
FLAGS			
CLR C	Clear Carry	1	1
CPL C	Complement Carry	1	1
CLR F0	Clear Flag 0	1	1
CPL F0	Complement Flag 0	1	1
CLR F1	Clear F1 Flag	1	1
CPL F1	Complement F1 Flag	1	1
BRANCH			
JMP addr	Jump unconditional	2	2
JMPP @A	Jump indirect	1	2
DJNZ Rr, addr	Decrement register and jump	2	2
JC addr	Jump on Carry = 1	2	2
JNC addr	Jump on Carry = 0	2	2
JZ addr	Jump on A Zero	2	2
JNZ addr	Jump on A not Zero	2	2
JT0 addr	Jump on T0 = 1	2	2
JNT0 addr	Jump on T0 = 0	2	2
JT1 addr	Jump on T1 = 1	2	2
JNT1 addr	Jump on T1 = 0	2	2
JF0 addr	Jump on F0 Flag = 1	2	2
JF1 addr	Jump on F1 Flag = 1	2	2
JTF addr	Jump on Timer Flag = 1, Clear Flag	2	2
JNIBF addr	Jump on IBF Flag = 0	2	2
JOBF addr	Jump on OBF Flag = 1	2	2
JBb addr	Jump on Accumulator Bit	2	2

APPLICATIONS

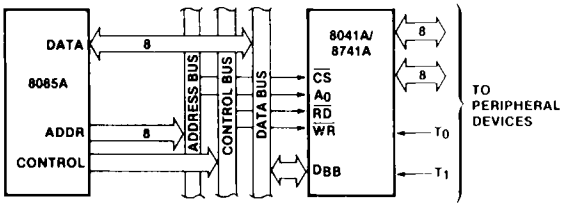


Figure 1. 8085A-8041A Interface

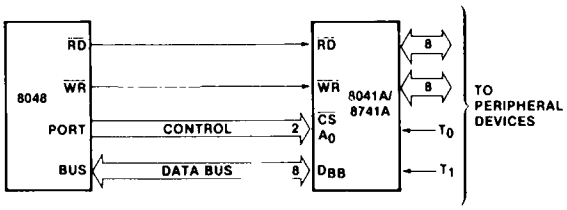


Figure 2. 8048-8041A Interface

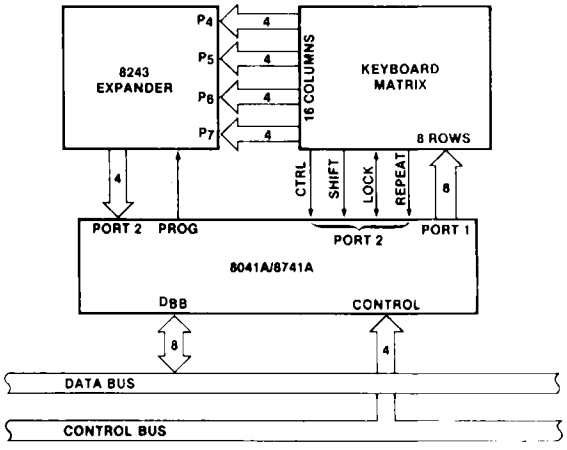


Figure 3. 8041A-8243 Keyboad Scanner

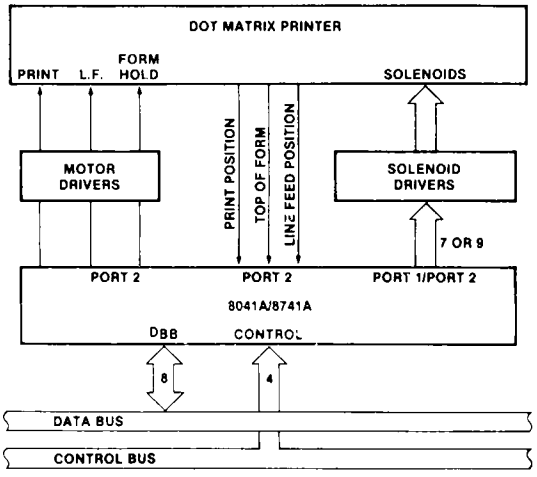


Figure 4. 8041A Matrix Printer Interface

ABSOLUTE MAXIMUM RATINGS*

Ambient Temperature Under Bias . . . . . 0°C to 70°C
Storage Temperature . . . . . – 65°C to + 150°C
Voltage on Any Pin With Respect to Ground . . . . . 0.5V to + 7V
Power Dissipation . . . . . 1.5 Watt

*COMMENT: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

D.C. AND OPERATING CHARACTERISTICS

$T_A = 0°C$ to 70°C, $V_{SS} = 0V$, 8041A: $V_{CC} = V_{DD} = +5V \pm 10\%$, 8741A: $V_{CC} = V_{DD} = +5V \pm 5\%$

Symbol	Parameter	Min.	Max.	Unit	Test Conditions
V_{IL}	Input Low Voltage (Except XTAL1, XTAL2, $\overline{RESET}$)	– 0.5	0.8	V	
V_{IL1}	Input Low Voltage (XTAL1, XTAL2, $\overline{RESET}$)	– 0.5	0.6	V	
V_{IH}	Input High Voltage (Except XTAL1, XTAL2, $\overline{RESET}$)	2.2	V_{CC}		
V_{IH1}	Input High Voltage (XTAL1, XTAL2, $\overline{RESET}$)	3.8	V_{CC}	V	
V_{OL}	Output Low Voltage (D_0-D_7)		0.45	V	$I_{OL} = 2.0$ mA
V_{OL1}	Output Low Voltage ($P_{10}P_{17}$, $P_{20}P_{27}$, Sync)		0.45	V	$I_{OL} = 1.6$ mA
V_{OL2}	Output Low Voltage (Prog)		0.45	V	$I_{OL} = 1.0$ mA
V_{OH}	Output High Voltage (D_0-D_7)	2.4		V	$I_{OH} = -400\ \mu A$
V_{OH1}	Output High Voltage (All Other Outputs)	2.4		V	$I_{OH} = -50\ \mu A$
I_{IL}	Input Leakage Current (T_0, T_1, $\overline{RD}$, $\overline{WR}$, $\overline{CS}$, A_0, EA)		± 10	μA	$V_{SS} \le V_{IN} \le V_{CC}$
I_{OZ}	Output Leakage Current (D_0-D_7, High Z State)		± 10	μA	$V_{SS} + 0.45 \le V_{IN} \le V_{CC}$
I_{LI}	Low Input Load Current ($P_{10}P_{17}$, $P_{20}P_{27}$)		0.5	mA	$V_{IL} = 0.8V$
I_{LI1}	Low Input Load Current ($\overline{RESET}$, $\overline{SS}$)		0.2	mA	$V_{IL} = 0.8V$
I_{DD}	V_{DD} Supply Current		15	mA	Typical = 5 mA
$I_{CC} + I_{DD}$	Total Supply Current		125	mA	Typical = 60 mA

A.C. CHARACTERISTICS

$T_A = 0°C$ to 70°C, $V_{SS} = 0V$, 8041A: $V_{CC} = V_{DD} = +5V \pm 10\%$, 8741A: $V_{CC} = V_{DD} = +5V \pm 5\%$

DBB READ

Symbol	Parameter	Min.	Max.	Unit	Test Conditions
t_{AR}	$\overline{CS}$, A_0 Setup to $\overline{RD}$↓	0		ns	
t_{RA}	$\overline{CS}$, A_0 Hold After $\overline{RD}$↑	0		ns	
t_{RR}	$\overline{RD}$ Pulse Width	250		ns	
t_{AD}	$\overline{CS}$, A_0 to Data Out Delay		225	ns	$C_L = 150$ pF
t_{RD}	$\overline{RD}$↓ to Data Out Delay		225	ns	$C_L = 150$ pF
t_{DF}	$\overline{RD}$↑ to Data Float Delay		100	ns	
t_{CY}	Cycle Time (Except 8741A-8)	2.5	15	μs	6.0 MHz XTAL
t_{CY}	Cycle Time (8741A-8)	4.17	15	μs	3.6 MHz XTAL

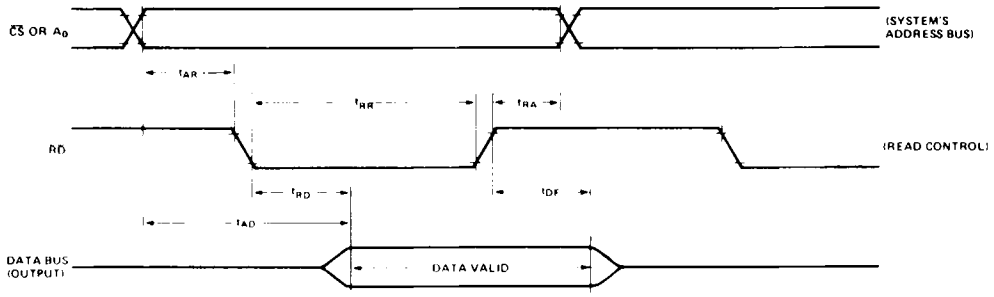
DBB WRITE

Symbol	Parameter	Min.	Max.	Unit	Test Conditions
t_{AW}	$\overline{CS}$, A_0 Setup to $\overline{WR}$↓	0		ns	
t_{WA}	$\overline{CS}$, A_0 Hold After $\overline{WR}$↑	0		ns	
t_{WW}	$\overline{WR}$ Pulse Width	250		ns	
t_{DW}	Data Setup to $\overline{WR}$↑	150		ns	
t_{WD}	Data Hold After $\overline{WR}$↑	0		ns	

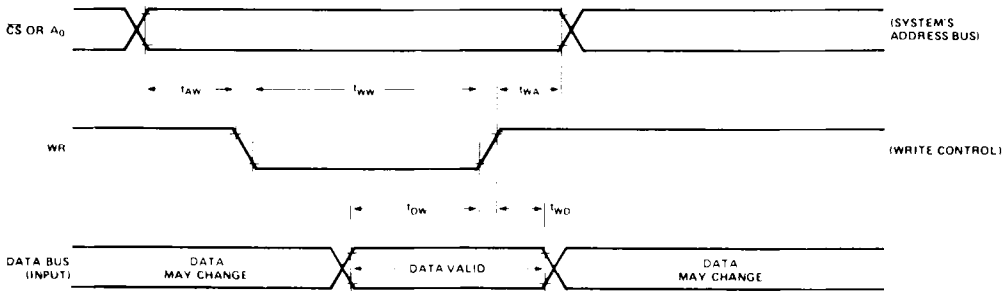
INPUT AND OUTPUT WAVEFORMS FOR A.C. TESTS

WAVEFORMS

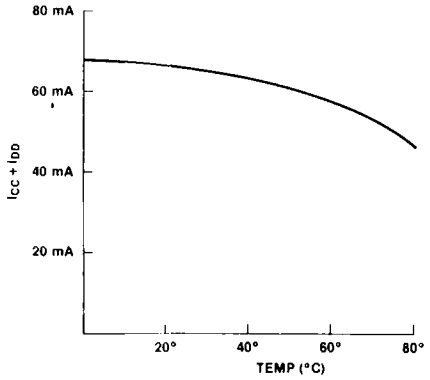
1. READ OPERATION—DATA BUS BUFFER REGISTER.



2. WRITE OPERATION—DATA BUS BUFFER REGISTER.



TYPICAL 8041/8741A CURRENT

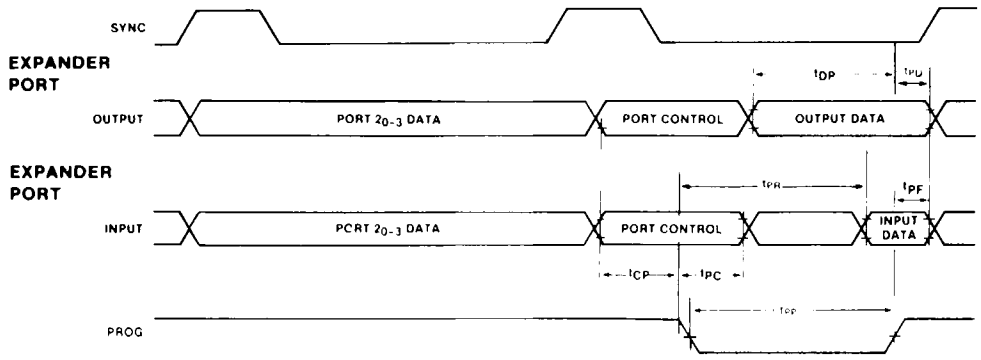


A.C. CHARACTERISTICS—PORT 2

$T_A = 0°C$ to $70°C$, 8041A: $V_{CC} = +5V \pm 10\%$, 8741A: $V_{CC} = +5V \pm 5\%$

Symbol	Parameter	Min.	Max.	Unit	Test Conditions
t_{CP}	Port Control Setup Before Falling Edge of PROG	110		ns	
t_{PC}	Port Control Hold After Falling Edge of PROG	100		ns	
t_{PR}	PROG to Time P2 Input Must Be Valid		810	ns	
t_{PF}	Input Data Hold Time	0	150	ns	
t_{DP}	Output Data Setup Time	250		ns	
t_{PD}	Output Data Hold Time	65		ns	
t_{PP}	PROG Pulse Width	1200		ns	

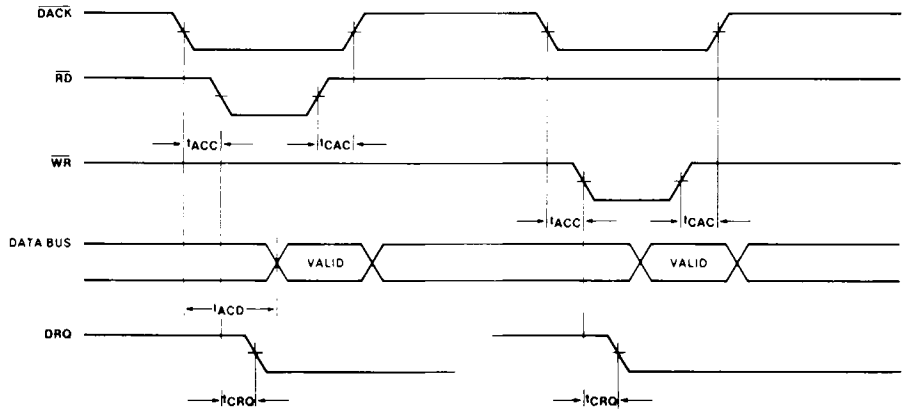
PORT 2 TIMING



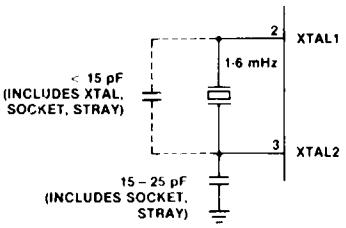
A.C. CHARACTERISTICS—DMA

Symbol	Parameter	Min.	Max.	Unit	Test Conditions
t_{ACC}	$\overline{DACK}$ to $\overline{WR}$ or $\overline{RD}$	0		ns	
t_{CAC}	$\overline{RD}$ or $\overline{WR}$ to $\overline{DACK}$	0		ns	
t_{ACD}	$\overline{DACK}$ to Data Valid		225	ns	$C_L = 150$ pF
t_{CRQ}	$\overline{RD}$ or $\overline{WR}$ to DRQ Cleared		200	ns	

WAVEFORMS—DMA

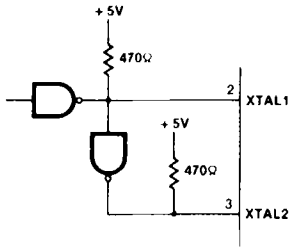


CRYSTAL OSCILLATOR MODE



CRYSTAL SERIES RESISTANCE SHOULD BE <75Ω AT 6 MHz; <180Ω AT 3.6 MHz.

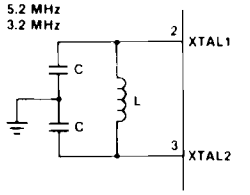
DRIVING FROM EXTERNAL SOURCE



BOTH XTAL1 AND XTAL2 SHOULD BE DRIVEN. RESISTORS TO V_{CC} ARE NEEDED TO ENSURE V_{IH} = 3.8V IF TTL CIRCUITRY IS USED.

LC OSCILLATOR MODE

L	C	NOMINAL f
45 μH	20 pF	5.2 MHz
120 μH	20 pF	3.2 MHz



$$f = \frac{1}{2\pi\sqrt{LC'}}$$

$$C' = \frac{C + 3C_{PP}}{2}$$

C_{PP} = 5 – 10 pF PIN-TO-PIN CAPACITANCE

EACH C SHOULD BE APPROXIMATELY 20 pF, INCLUDING STRAY CAPACITANCE.

PROGRAMMING, VERIFYING, AND ERASING THE 8741A EPROM

Programming Verification

In brief, the programming process consists of: activating the program mode, applying an address, latching the address, applying data, and applying a programming pulse. Each word is programmed completely before moving on to the next and is followed by a verification step. The following is a list of the pins used for programming and a description of their functions:

Pin	Function
XTAL 1	Clock Input (1 to 6MHz)
$\overline{\text{Reset}}$	Initialization and Address Latching
Test 0	Selection of Program or Verify Mode
EA	Activation of Program/Verify Modes
BUS	Address and Data Input Data Output During Verify
P20-1	Address Input
V_{DD}	Programming Power Supply
PROG	Program Pulse Input

WARNING:

An attempt to program a missocketed 8741A will result in severe damage to the part. An indication of a properly socketed part is the appearance of the SYNC clock output. The lack of this clock may be used to disable the programmer.

The Program/Verify sequence is:

1. A_0 = 0V, $\overline{CS}$ = 5V, EA = 5V, $\overline{RESET}$ = 0V, TEST0 = 5V, V_{DD} = 5V, clock applied or internal oscillator operating, BUS and PROG floating.
2. Insert 8741A in programming socket
3. TEST 0 = 0v (select program mode)
4. EA = 23V (activate program mode)
5. Address applied to BUS and P20-1
6. $\overline{RESET}$ = 5v (latch address)
7. Data applied to BUS
8. V_{DD} = 25v (programming power)
9. PROG = 0v followed by one 50ms pulse to 23V
10. V_{DD} = 5v
11. TEST 0 = 5v (verify mode)
12. Read and verify data on BUS
13. TEST 0 = 0v
14. $\overline{RESET}$ = 0v and repeat from step 5
15. Programmer should be at conditions of step 1 when 8741A is removed from socket.

8741A Erasure Characteristics

The erasure characteristics of the 8741A are such that erasure begins to occur when exposed to light with wavelengths shorter than approximately 4000 Angstroms (Å). It should be noted that sunlight and certain types of fluorescent lamps have wavelengths in the 3000–4000Å range. Data show that constant exposure to room level fluorescent lighting could erase the typical 8741A in approximately 3 years while it would take approximately one week to cause erasure when exposed to direct sunlight. If the 8741A is to be exposed to these types of lighting conditions for extended periods of time, opaque labels are available from Intel which should be placed over the 8741A window to prevent unintentional erasure.

The recommended erasure procedure for the 8741A is exposure to shortwave ultraviolet light which has a wavelength of 2537Å. The integrated dose (i.e., UV intensity x exposure time) for erasure should be a minimum of 15 w-sec/cm^2. The erasure time with this dosage is approximately 15 to 20 minutes using an ultraviolet lamp with a 12,000 μW/cm^2 power rating. The 8741A should be placed within one inch of the lamp tubes during erasure. Some lamps have a filter on their tubes which should be removed before erasure.

A.C. TIMING SPECIFICATION FOR PROGRAMMING

T_A = 25°C ±5°C, V_{CC} = 5V ±5%, V_{DD} = 25V ±1V

Symbol	Parameter	Min.	Max.	Unit	Test Conditions
t_{AW}	Address Setup Time to $\overline{\text{RESET}}$ ↑	4t_{CY}			
t_{WA}	Address Hold Time After $\overline{\text{RESET}}$ ↑	4t_{CY}			
t_{DW}	Data in Setup Time to PROG ↑	4t_{CY}			
t_{WD}	Data in Hold Time After PROG ↑	4t_{CY}			
t_{PH}	$\overline{\text{RESET}}$ Hold Time to Verify	4t_{CY}			
t_{VDDW}	V_{DD} Setup Time to PROG ↑	4t_{CY}			
t_{VDDH}	V_{DD} Hold Time After PROG ↑	0			
t_{PW}	Program Pulse Width	50	60	mS	
t_{TW}	Test 0 Setup Time for Program Mode	4t_{CY}			
t_{WT}	Test 0 Hold Time After Program Mode	4t_{CY}			
t_{DO}	Test 0 to Data Out Delay		4t_{CY}		
t_{WW}	$\overline{\text{RESET}}$ Pulse Width to Latch Address	4t_{CY}			
t_r, t_f	V_{DD} and PROG Rise and Fall Times	0.5	2.0	μS	
t_{CY}	CPU Operation Cycle Time	5.0		μS	
t_{RE}	$\overline{\text{RESET}}$ Setup Time Before EA ↑	4t_{CY}			

Note: If TEST 0 is high, t_{DO} can be triggered by $\overline{\text{RESET}}$ ↑.

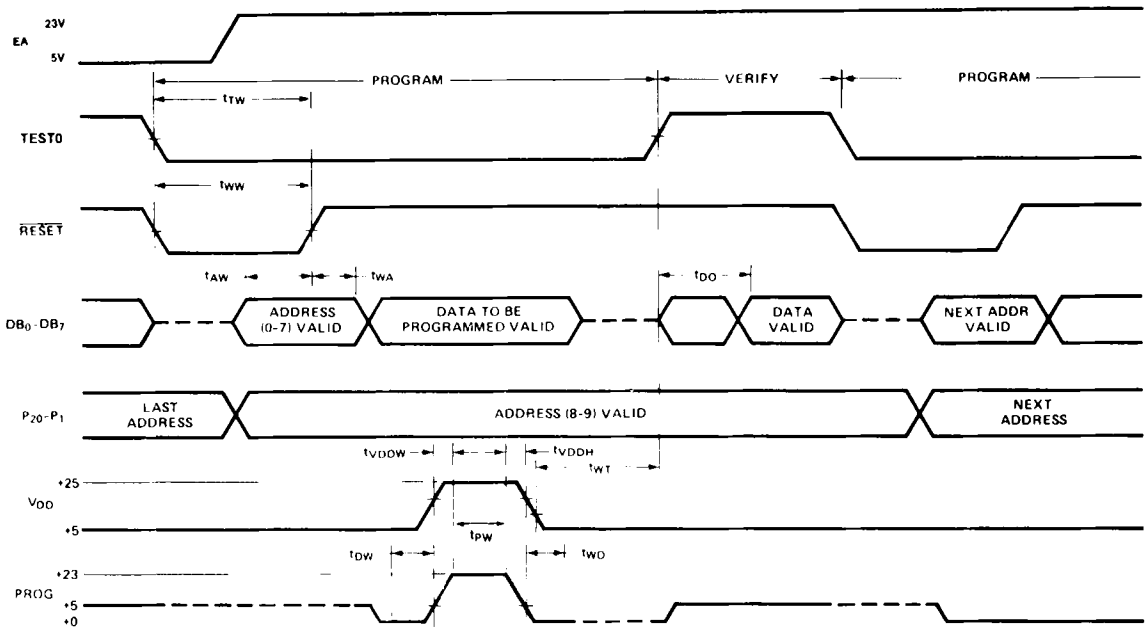
D.C. SPECIFICATION FOR PROGRAMMING

T_A = 25°C ±5°C, V_{CC} = 5V ±5%, V_{DD} = 25V ±1V

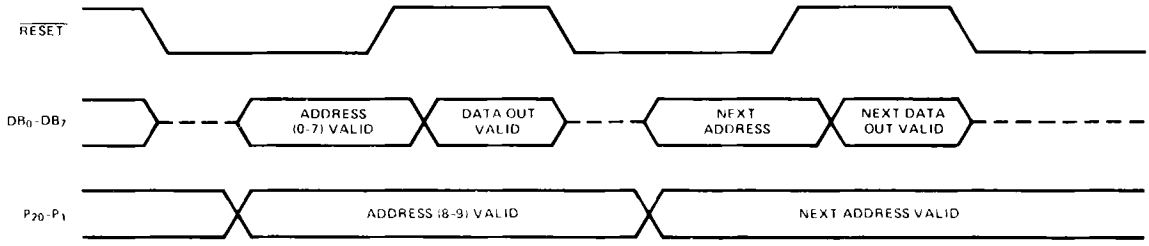
Symbol	Parameter	Min.	Max.	Unit	Test Conditions
V_{DDH}	V_{DD} Program Voltage High Level	24.0	26.0	V	
V_{DDL}	V_{DD} Voltage Low Level	4.75	5.25	V	
V_{PH}	PROG Program Voltage High Level	21.5	24.5	V	
V_{PL}	PROG Voltage Low Level		0.2	V	
V_{EAH}	EA Program or Verify Voltage High Level	21.5	24.5	V	
V_{EAL}	EA Voltage Low Level		5.25	V	
I_{DD}	V_{DD} High Voltage Supply Current		30.0	mA	
I_{PROG}	PROG High Voltage Supply Current		16.0	mA	
I_{EA}	EA High Voltage Supply Current		1.0	mA	

WAVEFORMS FOR PROGRAMMING

COMBINATION PROGRAM/VERIFY MODE (EPROM'S ONLY)



VERIFY MODE (ROM/EPROM)



NOTES:
1. **PROG MUST FLOAT IF EA IS LOW (I.e., ≠ 23V), OR IF T0 = 5V FOR THE 8741A. FOR THE 8041A PROG MUST ALWAYS FLOAT.**
2. **XTAL1 AND XTAL 2 DRIVEN BY 3.6 MHz CLOCK WILL GIVE 4.17 μsec t_{CY}. THIS IS ACCEPTABLE FOR 8741A-8 PARTS AS WELL AS STANDARD PARTS.**
3. **AO MUST BE HELD LOW (I.e., = 0V) DURING PROGRAM/VERIFY MODES.**

The 8741A EPROM can be programmed by either of two Intel products:

1. PROMPT-48 Microcomputer Design Aid, or
2. Universal PROM Programmer (UPP series) peripheral of the Intellec® Development System with a UPP-848 Personality Card.

Video Logic Board

HD6845S, HD68A45S, HD68B45S

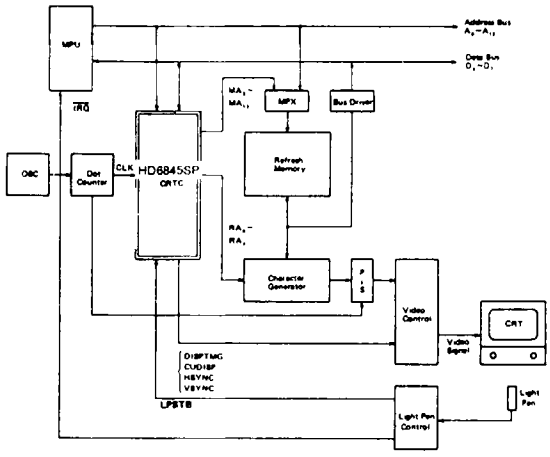
CRTC (CRT Controller)

The CRTC is a LSI controller which is designed to provide an interface for microcomputers to raster scan type CRT displays. The CRTC belongs to the HMCS6800 LSI Family and has full compatibility with MPU in both data lines and control lines. Its primary function is to generate timing signal which is necessary for raster scan type CRT display according to the specification programmed by MPU. The CRTC is also designed as a programmable controller, so applicable to wide-range CRT display from small low-functioning character display up to raster type full graphic display as well as large high-functioning limited graphic display.

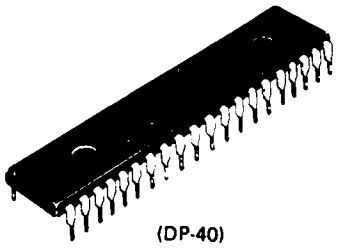
■ FEATURES

- Number of Displayed Characters on the Screen, Vertical Dot Format of One Character, Horizontal and Vertical Sync Signal, Display Timing Signal are Programmable
- 3.7 MHz High Speed Display Operation
- Line Buffer-less Refreshing
- 14-bit Refresh Memory Address Output (16k Words max. Access)
- Programmable Interlace/Non-interlace Scan Mode
- Built-in Cursor Control Function
- Programmable Cursor Height and its Blink
- Built-in Light Pen Detection Function
- Paging and Scrolling Capability
- TTL Compatible
- Single +5V Power Supply
- Upward compatible with MC6845

■ SYSTEM BLOCK DIAGRAM

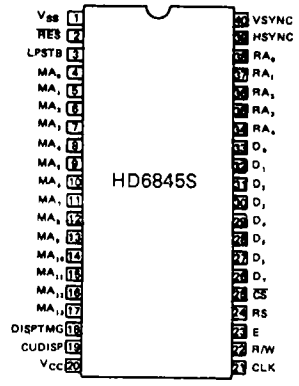


HD6845SP, HD68A45SP, HD68B45SP



(DP-40)

■ PIN ARRANGEMENT



(Top View)

■ ORDERING INFORMATION

CRTC	Bus Timing	CRT Display Timing
HD6845SP	1.0 MHz	3.7 MHz max.
HD68A45SP	1.5 MHz	
HD68B45SP	2.0 MHz	

■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V_{CC} *	-0.3 ~ +7.0	V
Input Voltage	V_{in} *	-0.3 ~ +7.0	V
Operating Temperature	T_{opr}	- 20 ~ + 75	°C
Storage Temperature	T_{stg}	- 55 ~ +150	°C

* With respect to V_{SS} (SYSTEM GND)

[NOTE] Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

■ RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
Supply Voltage	V_{CC} *	4.75	5	5.25	V
Input Voltage	V_{IL} *	-0.3	–	0.8	V
	V_{IH} *	2.0	–	V_{CC}	V
Operating Temperature	T_{opr}	- 20	25	75	°C

* With respect to V_{SS} (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC} = 5V ± 5%, V_{SS} = 0V, Ta = -20~+75°C, unless otherwise noted.)

Item	Symbol	Test Condition		min	typ	max	Unit
Input "High" Voltage	V_{IH}			2.0	–	V_{CC}	V
Input "Low" Voltage	V_{IL}			-0.3	–	0.8	V
Input Leakage Current	I_{in}	V_{in} = 0 ~ 5.25V (Except D_0~D_7)		-2.5	–	2.5	μA
Three-State Input Current (off-state)	I_{TSI}	V_{in} = 0.4 ~ 2.4V V_{CC} = 5.25V (D_0~ D_7)		- 10	–	10	μA
Output "High" Voltage	V_{OH}	I_{LOAD} = -205 μA (D_0~ D_7)		2.4	–	–	V
		I_{LOAD} = -100 μA (Other Outputs)					
Output "Low" Voltage	V_{OL}	I_{LOAD} = 1.6 mA		–	–	0.4	V
Input Capacitance	C_{in}	V_{in} = 0 Ta = 25°C f = 1.0 MHz	D_0 ~ D_7	–	–	12.5	pF
			Other Inputs	–	–	10.0	pF
Output Capacitance	C_{out}	V_{in} = 0V, Ta = 25°C, f = 1.0 MHz		–	–	10.0	pF
Power Dissipation	P_D			–	600	1000	mW

- **AC CHARACTERISTICS (V_{CC} = 5V ±5%, V_{SS} = 0V, Ta = -20~+75°C, unless otherwise noted.)**

1. TIMING OF CRTC SIGNAL

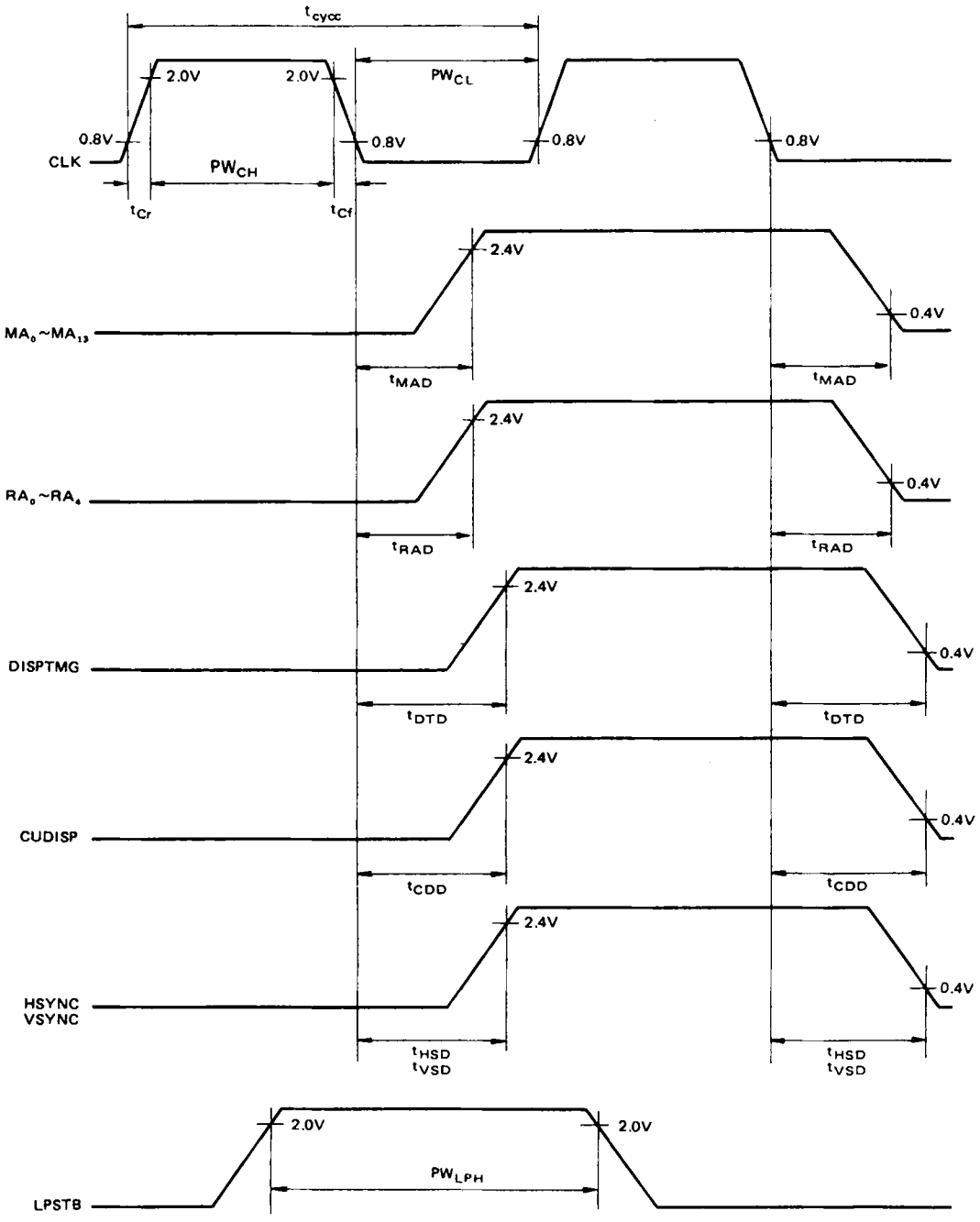
Item	Symbol	Test Condition	min	typ	max	Unit
Clock Cycle Time	t_{cycc}	Fig. 1	270	–	–	ns
Clock "High" Pulse Width	PW_{CH}		130	–	–	ns
Clock "Low" Pulse Width	PW_{CL}		130	–	–	ns
Rise and Fall Time for Clock Input	t_{Cr}, t_{Cf}		–	–	20	ns
Memory Address Delay Time	t_{MAD}		–	–	160	ns
Raster Address Delay Time	t_{RAD}		–	–	160	ns
DISPTMG Delay Time	t_{DTD}		–	–	250	ns
CUDISP Delay Time	t_{CDD}		–	–	250	ns
Horizontal Sync Delay Time	t_{HSD}		–	–	200	ns
Vertical Sync Delay Time	t_{VSD}		–	–	250	ns
Light Pen Strobe Pulse Width	PW_{LPH}		60	–	–	ns
Light Pen Strobe	t_{LPD1}	Fig. 2	–	–	70	ns
Uncertain Time of Acceptance	t_{LPD2}		–	–	0	ns

2. MPU READ TIMING

Item	Symbol	Test Condition	HD6845SP			HD68A45SP			HD68B45SP			Unit
			min	typ	max	min	typ	max	min	typ	max	
Enable Cycle Time	t_{tycE}	Fig. 3	1.0	–	–	0.666	–	–	0.5	–	–	μs
Enable "High" Pulse Width	PW_{EH}		0.45	–	–	0.280	–	–	0.22	–	–	μs
Enable "Low" Pulse Width	PW_{EL}		0.40	–	–	0.280	–	–	0.21	–	–	μs
Enable Rise and Fall Time	t_{Er}, t_{Ef}		–	–	25	–	–	25	–	–	25	ns
Address Set Up Time	t_{AS}		140	–	–	140	–	–	70	–	–	ns
Data Delay Time	t_{DDR}		–	–	320	–	–	220	–	–	180	ns
Data Hold Time	t_{H}		10	–	–	10	–	–	10	–	–	ns
Address Hold Time	t_{AH}		10	–	–	10	–	–	10	–	–	ns
Data Access Time	t_{ACC}		–	–	460	–	–	360	–	–	250	ns

3. MPU WRITE TIMING

Item	Symbol	Test Condition	HD6845SP			HD68A45SP			HD68B45SP			Unit
			min	typ	max	min	typ	max	min	typ	max	
Enable Cycle Time	t_{cycE}	Fig. 4	1.0	–	–	0.666	–	–	0.5	–	–	μs
Enable "High" Pulse Width	PW_{EH}		0.45	–	–	0.280	–	–	0.22	–	–	μs
Enable "Low" Pulse Width	PW_{EL}		0.40	–	–	0.280	–	–	0.21	–	–	μs
Enable Rise and Fall Time	t_{Er}, t_{Ef}		–	–	25	–	–	25	–	–	25	ns
Address Set Up Time	t_{AS}		140	–	–	140	–	–	70	–	–	ns
Data Set Up Time	t_{DSW}		195	–	–	80	–	–	60	–	–	ns
Data Hold Time	t_{H}		10	–	–	10	–	–	10	–	–	ns
Address Hold Time	t_{AH}		10	–	–	10	–	–	10	–	–	ns



This Figure shows the relation in time between CLK signal and each output signals. Output sequence is shown in Figs. 9 ~ 15.

Figure 1 Time Chart of the CRTC

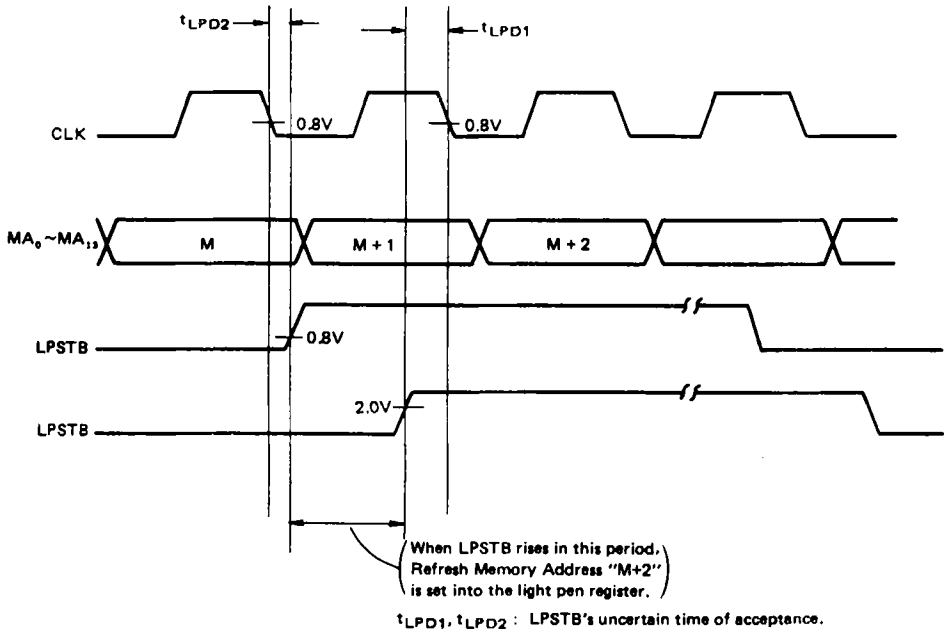


Figure 2 LPSTB Input Timing & Refresh Memory Address that is set into the light pen register.

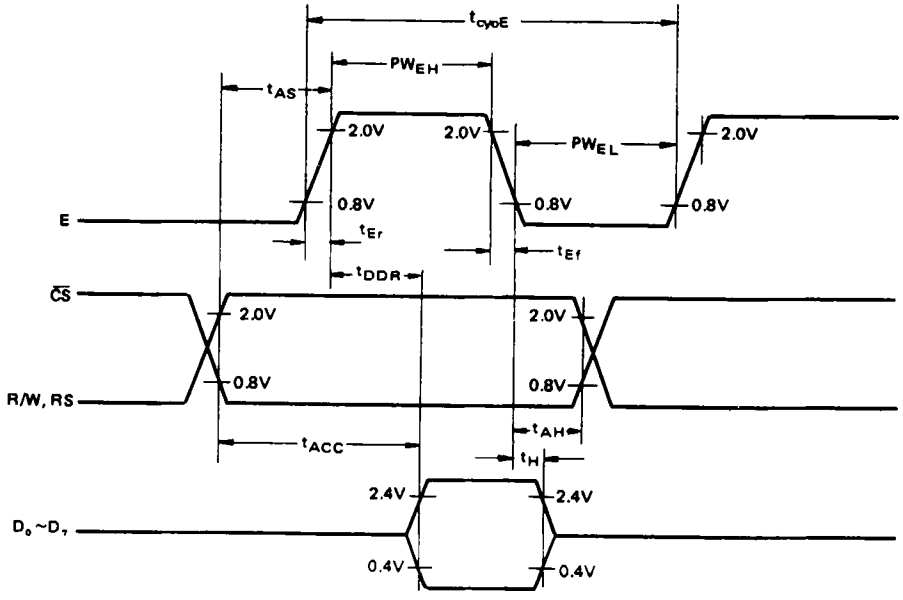


Figure 3 Read Sequence

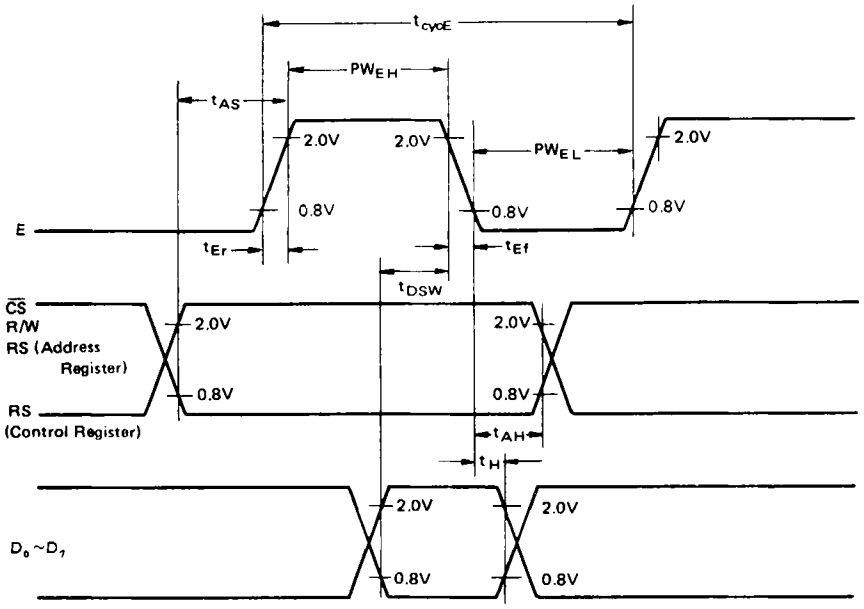


Figure 4 Write Sequence

■ SYSTEM DESCRIPTION

The CRTC is a LSI which is connected with MPU and CRT display device to control CRT display. The CRTC consists of internal register group, horizontal and vertical timing circuits, linear address generator, cursor control circuit, and light pen detection circuit. Horizontal and vertical timing circuit generate $RA_0 \sim RA_4$, DISPTMG, HSYNC, and VSYNC. $RA_0 \sim RA_4$ are raster address signals and used as input signals for Character Generator. DISPTMG, HSYNC, and VSYNC signals are received by video control circuit. This horizontal and vertical timing circuit consists of internal counter and comparator circuit. Linear address generator generates refresh memory address $MA_0 \sim MA_{13}$ to be used for refreshing the screen. By these address signals, refresh memory is accessed periodically. As 14 refresh memory address signals are prepared, 16k words max are accessible. Moreover, the use of start address register enables paging and scrolling. Light pen detection circuit detects light pen position on the screen. When light pen strobe signal is received, light pen register memorizes linear address generated by linear address generator in order to memorize where light pen is on the screen. Cursor control circuit controls the position of cursor, its height, and its blink.

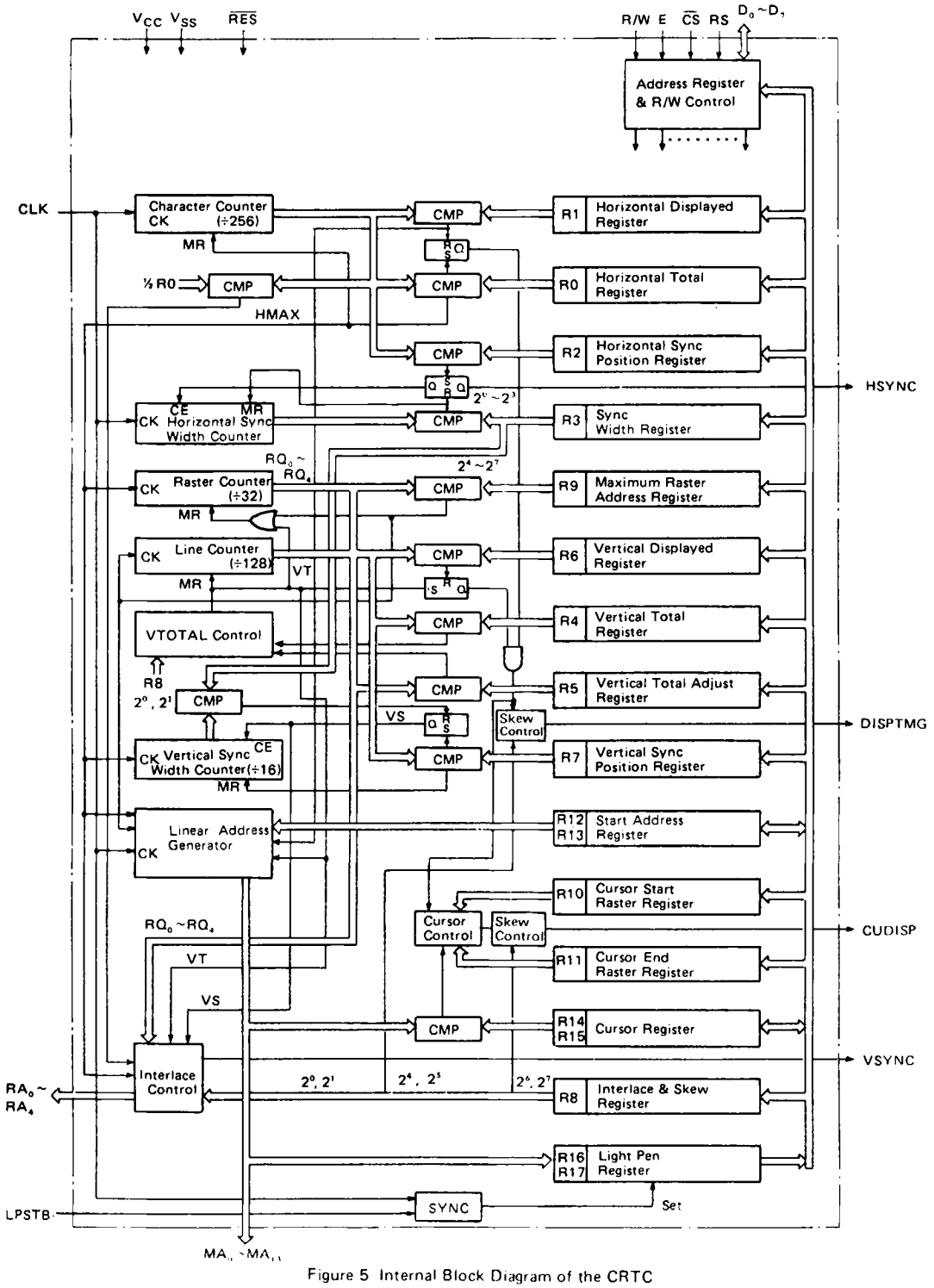


Figure 5 Internal Block Diagram of the CRTC

■ FUNCTION OF SIGNAL LINE

The CRTC provides 13 interface signals to MPU and 25 interface signals to CRT display.

• Interface Signals to MPU

Bi-directional Data Bus (D_0~D_7)

Bi-directional data bus(D_0~D_7) are used for data transfer between the CRTC and MPU. The data bus outputs are 3-state buffers and remain in the high-impedance state except when MPU performs a CRTC read operation.

Read/Write (R/W)

R/W signal controls the direction of data transfer between the CRTC and MPU. When R/W is at "High" level, data of CRTC is transfered to MPU. When R/W is at "Low" level, data of MPU is transfered to CRTC.

Chip Select ($\overline{CS}$)

Chip Select signal ($\overline{CS}$) is used to address the CRTC. When $\overline{CS}$ is at "Low" level, it enables R/W operation to CRTC internal registers. Normally this signal is derived from decoded address signal of MPU under the condition that VMA signal of MPU is at "High" level.

Register Select (RS)

Register Select signal (RS) is used to select the address register and 18 control registers of the CRTC. When RS is at "Low" level, the address register is selected and when RS is at "High" level, control registers are selected. This signal is normally a derivative of the lowest bit (A0) of MPU address bus.

Enable(E)

Enable signal (E) is used as strobe signal in MPU R/W operation with the CRTC internal registers. This signal is normally a derivative of the HMCS6800 System ϕ_2 clock.

Reset ($\overline{RES}$)

Reset signal ($\overline{RES}$) is an input signal used to reset the CRTC.

When $\overline{RES}$ is at "Low" level, it forces the CRTC into the following status.

1) All the counters in the CRTC are cleared and the device stops the display operation.
2) All the outputs go down to "Low" level.
3) Control registers in the CRTC are not affected and remain unchanged.

This signal is different from other HMCS6800 family LSIs in the following functions and has restrictions for usage.

1) $\overline{RES}$ signal has capability of reset function only when LPSTB is at "Low" level.
2) The CRTC starts the display operation immediately after $\overline{RES}$ signal goes "High".

• Interface Signals to CRT Display Device

Character Clock (CLK)

CLK is a standard clock input signal which defines character timing for the CRTC display operation. This signal is normally derived from the external high-speed dot timing logic.

Horizontal Sync (HSYNC)

HSYNC is an active "High" level signal which provides horizontal synchronization for display device.

Vertical Sync (VSYNC)

VSYNC is an active "High" level signal which provides vertical synchronization for display device.

Display Timing (DISPTMG)

DISPTMG is an active "High" level signal which defines the display period in horizontal and vertical raster scanning. It is necessary to enable video signal only when DISPTMG is at "High" level.

Refresh Memory Address (MA_0~MA_{13})

MA_0~MA_{13} are refresh memory address signals which are used to access to refresh memory in order to refresh the CRT screen periodically. These outputs enables 16k words max. refresh memory access. So, for instance, these are applicable up to 2000 characters/screen and 8-page system.

Raster Address (RA_0~RA_4)

RA_0~RA_4 are raster address signals which are used to select the raster of the character generator or graphic pattern generator etc.

Cursor Display (CUDISP)

CUDISP is an active "High" level video signal which is used to display the cursor on the CRT screen. This output is inhibited while DISPTMG is at "Low" level. Normally this output is mixed with video signal and provided to the CRT display device.

Light Pen Strobe (LPSTB)

LPSTB is an active "High" level input signal which accepts strobe pulse detected by the light pen and control circuit. When this signal is activated, the refresh memory address (MA_0~MA_{13}) which are shown in Fig. 2 are stored in the 14-bit light pen register. The stored refresh memory address need to be corrected in software, taking the delay time of the display device, light pen, and light pen control circuits into account.

■ REGISTER DESCRIPTION

Table 1 Internal Registers Assignment

$\overline{CS}$	RS	Address Register 4	3	2	1	0	Register #	Register Name	Program Unit	READ	WRITE	Data Bit 7	6	5	4	3	2	1	0
1	×	×	×	×	×	×			–	–	–								
0	0	×	×	×	×	×	AR	Address Register	–	×	○								
0	1	0	0	0	0	0	R0	Horizontal Total *	Character	×	○								
0	1	0	0	0	0	1	R1	Horizontal Displayed	Character	×	○								
0	1	0	0	0	1	0	R2	Horizontal Sync* Position	Character	×	○								
0	1	0	0	0	1	1	R3	Sync Width	Vertical-Raster, Horizontal-Character	×	○	wv3	wv2	wv1	wv0	wh3	wh2	wh1	wh0
0	1	0	0	1	0	0	R4	Vertical Total *	Line	×	○								
0	1	0	0	1	0	1	R5	Vertical Total Adjust	Raster	×	○								
0	1	0	0	1	1	0	R6	Vertical Displayed	Line	×	○								
0	1	0	0	1	1	1	R7	Vertical Sync * Position	Line	×	○								
0	1	0	1	0	0	0	R8	Interlace & Skew	–	×	○	C1	C0	D1	D0			V	S
0	1	0	1	0	0	1	R9	Maximum Raster Address	Raster	×	○								
0	1	0	1	0	1	0	R10	Cursor Start Raster	Raster	×	○		B	P					
0	1	0	1	0	1	1	R11	Cursor End Raster	Raster	×	○								
0	1	0	1	1	0	0	R12	Start Address(H)	–	○	○								
0	1	0	1	1	0	1	R13	Start Address(L)	–	○	○								
0	1	0	1	1	1	0	R14	Cursor(H)	–	○	○								
0	1	0	1	1	1	1	R15	Cursor (L)	–	○	○								
0	1	1	0	0	0	0	R16	Light Pen(H)	–	○	×								
0	1	1	0	0	0	1	R17	Light Pen(L)	–	○	×								

[NOTE] 1. The Registers marked *: (Written Value) = (Specified Value) – 1
2. Written Value of R9 is mentioned below.
1) Non-interlace Mode, Interlace Sync Mode } (Written Value Nr) = (Specified Value) – 1
2) Interlace Sync & Video Mode
(Written Value Nr) = (Specified Value) – 2
3. C0 and C1 specify skew of CUDISP output signal.
D0 and D1 specify skew of DISPTMG output signal.
When S is "1", V specifies video mode. S specifies the Interlace Sync Mode.
4. B specifies the cursor blink. P specifies the cursor blink period.
5. wv0~wv3 specify the pulse width of Vertical Sync Signal.
wh0~wh3 specify the pulse width of Horizontal Sync Signal.
6. R0 is ordinally programmed to be odd number in interlace mode.
7. ○; Yes, ×; No

- **Address Register (AR)**

This is a 5-bit register used to select 18 internal control registers (R0~R17). Its contents are the address of one of 18 internal control registers. Programming the data from 18 to 31 produces no results. Access to R0~R17 requires, first of all, to write the address of corresponding control register into this register. When RS and $\overline{CS}$ are at "Low" level, this register is selected.

- **Horizontal Total Register (R0)**

This is a register used to program total number of horizontal characters per line including the retrace period. The data is 8-bit and its value should be programmed according to the specification of the CRT. When M is total number of characters, (M-1) shall be programmed to this register. When programming for interlace mode, M must be even.

- **Horizontal Displayed Register (R1)**

This is a register used to program the number of horizontal displayed characters per line. Data is 8-bit and any number that is smaller than that of horizontal total characters can be programmed.

- **Horizontal Sync Position Register (R2)**

This is a register used to program horizontal sync position as multiples of the character clock period. Data is 8-bit and any number that is lower than the horizontal total number can be programmed. When H is character number of horizontal Sync Position, (H-1) shall be programmed to this register. When programmed value of this register is increased, the display position on the CRT screen is shifted to the left. When programmed value is decreased, the position is shifted to the right. Therefore, the optimum horizontal position can be determined by this value.

- **Sync Width Register (R3)**

This is a register used to program the horizontal sync pulse width and the vertical sync pulse width. The horizontal sync pulse width is programmed in the lower 4-bit as multiples of the character clock period. "0" cannot be programmed. The vertical sync pulse width is programmed in higher 4-bit as multiples of the raster period. When "0" is programmed in higher 4-bit, 16 raster period (16H) is specified.

- **Vertical Total Register (R4)**

This is a register used to program total number of lines per frame including vertical retrace period. The data is within 7-bit and its value should be programmed according to the specification of the CRTC. When N is total number of lines, (N-1) shall be programmed to this register.

- **Vertical Total Adjust Register (R5)**

This is a register used to program the optimum number to adjust total number of rasters per field. This register enables to decide the number of vertical deflection frequency more strictly.

- **Vertical Displayed Register (R6)**

This is a register used to program the number of displayed character rows on the CRT screen. Data is 7-bit and any number that is smaller than that of vertical total characters can be programmed.

Table 2 Pulse Width of Vertical Sync Signal

VSW				Pulse Width
2^7	2^6	2^5	2^4	
0	0	0	0	16H
0	0	0	1	1
0	0	1	0	2
0	0	1	1	3
0	1	0	0	4
0	1	0	1	5
0	1	1	0	6
0	1	1	1	7
1	0	0	0	8
1	0	0	1	9
1	0	1	0	10
1	0	1	1	11
1	1	0	0	12
1	1	0	1	13
1	1	1	0	14
1	1	1	1	15

H; Raster period

Table 3 Pulse Width of Horizontal Sync Signal

HSW				Pulse Width
2^3	2^2	2^1	2^0	
0	0	0	0	– (Note)
0	0	0	1	1 CH
0	0	1	0	2
0	0	1	1	3
0	1	0	0	4
0	1	0	1	5
0	1	1	0	6
0	1	1	1	7
1	0	0	0	8
1	0	0	1	9
1	0	1	0	10
1	0	1	1	11
1	1	0	0	12
1	1	0	1	13
1	1	1	0	14
1	1	1	1	15

CH; Character clock period
(Note) HSW = "0" cannot be used.

- **Vertical Sync Position Register (R7)**

This is a register used to program the vertical sync position on the screen as multiples of the horizontal character line period. Data is 7-bit and any number that is equal to or less than vertical total characters can be programmed. When V is character number of vertical sync position, (V-1) shall be programmed to this register. When programmed value of this register is increased, the display position is shifted up. When programmed value is decreased, the position is shifted down. Therefore, the optimum vertical position may be determined by this value.

- **Interlace and Skew Register (R8)**

This is a register used to program raster scan mode and skew (delay) of CUDISP signal and DISPTMG signal.

Interlace Mode Program Bit (V, S)

Raster scan mode is programmed in the V, S bit.

Table 4 Interlace Mode (2^1, 2^0)

V	S	Raster Scan Mode
0	0	Non-interlace Mode
1	0	
0	1	Interlace Sync Mode
1	1	Interlace Sync & Video Mode

In the non-interlace mode, the rasters of even number field and odd number field are scanned duplicatedly. In the interlace sync mode, the rasters of odd number field are scanned in the middle of even number field. Then it is controlled to display the same character pattern in two fields. In the interlace sync and video mode, the raster scan method is the same as the interlace sync mode, but it is controlled to display different character pattern in two field.

Skew Program Bit (C1, C0, D1, D0)

These are used to program the skew (delay) of CUDISP signal and DISPTMG signal.

Skew of these two kinds of signals are programmed separately.

Table 5 DISPTMG Skew Bit (2^7, 2^6)

D1	D0	DISPTMG Signal
0	0	Non-skew
0	1	One-character skew
1	0	Two-character skew
1	1	Non-output

Table 6 Cursor Skew Bit (2^5, 2^4)

C1	C0	Non-skew
0	0	Non-skew
0	1	One-character skew
1	0	Two-character skew
1	1	Non-output

Skew function is used to delay the output timing of CUDISP and DISPTMG signals in LSI for the time to access refresh memory, character generator or pattern generator, and to make the same phase with serial video signal.

- **Maximum Raster Address Register (R9)**

This is a register used to program maximum raster address within 5-bit. This register defines total number of rasters per character including space. This register is programmed as follows.

Non-interlace Mode, Interlace Sync Mode

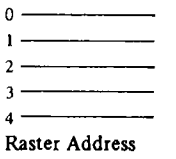
When total number of rasters is RN, (RN-1) shall be programmed.

Interlace Sync & Video Mode

When total number of rasters is RN, (RN-2) shall be programmed.

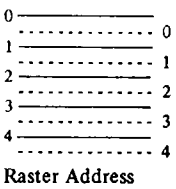
This manual defines total number of rasters in non-interlace mode, interlace sync mode and interlace sync & video mode as follows:

Non-interlace Mode



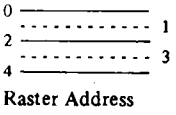
Total Number of Rasters 5
Programmed Value Nr = 4
(The same as displayed total number of rasters)

Interlace Sync Mode



Total Number of Rasters 5
Programmed Value Nr = 4
(In the interlace sync mode, total number of rasters in both the even and odd fields is ten. On programming, the half of it is defined as total number of rasters.)

Interlace Sync & Video Mode



Total Number of Rasters 5
Programmed Value Nr = 3
(Total number of rasters displayed in the even field and the odd field.)

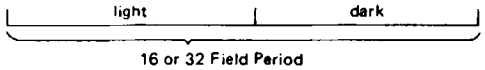
- **Cursor Start Raster Register (R10)**

This is a register used to program the cursor start raster address by lower 5-bit (2^0~2^4) and the cursor display mode by higher 2-bit (2^5, 2^6).

Table 7 Cursor Display Mode (2^6, 2^5)

B	P	Cursor Display Mode
0	0	Non-blink
0	1	Cursor Non-display
1	0	Blink, 16 Field Period
1	1	Blink, 32 Field Period

Blink Period



- **Cursor End Raster Register (R11)**
  This is register used to program the cursor end raster address.

- **Start Address Register (R12, R13)**
  These are used to program the first address of refresh memory to read out.
  Paging and scrolling is easily performed using this register. This register can be read but the higher 2-bit (2^6, 2^7) of R12 are always "0".

- **Cursor Register (R14, R15)**
  These two read/write registers stores the cursor location. The higher 2-bit (2^6, 2^7) of R14 are always "0".

- **Light Pen Register (R16, R17)**
  These read only registers are used to catch the detection address of the light pen. The higher 2-bit (2^6, 2^7) of R16 are always "0". Its value needs to be corrected by software because there is time delay from address output of the CRTC to signal input LPSTB pin of the CRTC in the process that raster is lit after address output and light pen detects it. Moreover, delay time shown in Fig. 2 needs to be taken into account.

Restriction on Programming Internal Register

1) $0 < Nhd < Nht + 1 \leqq 256$
2) $0 < Nvd < Nvt + 1 \leqq 128$
3) $0 \leqq Nhsp \leqq Nht$
4) $0 \leqq Nvsp \leqq Nvt$*
5) $0 \leqq N_{CSTART} \leqq N_{CEND} \leqq Nr$ (Non-interlace, Interlace sync mode)
   $0 \leqq N_{CSTART} \leqq N_{CEND} \leqq Nr + 1$ (Interlace sync & video mode)
6) $2 \leqq Nr \leqq 30$
7) $3 \leqq Nht$ (Except non-interlace mode)
   $5 \leqq Nht$ (Non-interlace mode only)

* In the interlace mode, pulse width is changed ±½ raster time when vertical sync signal extends over two fields.

Notes for Use

The method of directly using the value programmed in the internal register of LSI for controlling the CRT is adopted. Consequently, the display may flicker on the screen when the contents of the registers are changed from bus side asyncronously with the display operation.

Cursor Register

Writing into this register at frequent intervals for moving the cursor should be performed during horizontal and vertical retrace period.

Start Address Register

Writing into the start address register at frequent intervals for scrolling and paging should be performed during horizontal and vertical display period.

It is desirable to avoid programming other registers during display operation.

■ OPERATION OF THE CRTC

- **Time Chart of CRT Interface Signals**
  The following example shows the display operation in which values of Table 8 are programmed to the CRTC internal registers. Fig. 6 shows the CRT screen format. Fig. 9 shows the time chart of signals output from the CRTC.

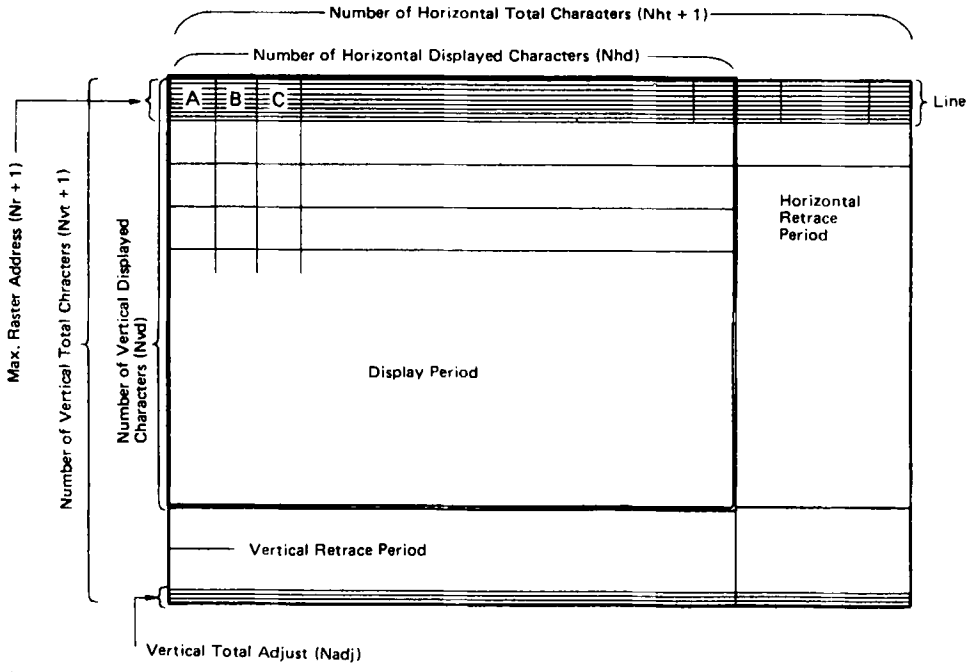


Figure 6 CRT screen Format

Table 8 Programmed Values into the Registers

Register	Register Name	Value	Register	Register Name	Value
R0	Horizontal Total	Nht	R9	Max. Raster Address	Nr
R1	Horizontal Displayed	Nhd	R10	Cursor Start Raster	
R2	Horizontal Sync Position	Nhsp	R11	Cursor End Raster	
R3	Sync Width	Nvsw, Nhsw	R12	Start Address (H)	0
R4	Vertical Total	Nvt	R13	Start Address (L)	0
R5	Vertical Total Adjust	Nadj	R14	Cursor (H)	
R6	Vertical Displayed	Nvd	R15	Cursor (L)	
R7	Vertical Sync Position	Nvsp	R16	Light Pen (H)	
R8	Interlace & Skew		R17	Light Pen (L)	

[NOTE] Nhd<Nht, Nvd<Nvt

The relation between values of Refresh Memory Address ($MA_0 \sim MA_{13}$) and Raster Address ($RA_0 \sim RA_4$) and the display position on the screen is shown in Fig. 15. Fig. 15 shows the case where the value of Start Address is 0.

- **Interlace Control**

Fig. 7 shows an example where the same character is displayed in the non-interlace mode, interlace sync mode, and video mode.

Non-interlace Mode Display

In non-interlace mode, each field is scanned duplicatedly. The values of raster addresses ($RA_0 \sim RA_4$) are counted up one from 0.

Interlace Sync Mode Display

In the interlace sync mode, raster addressed in the even field and the odd field are the same as addressed in the noninterlace mode. One character pattern is displayed mutually and its displayed position in the odd field is set at 1/2 raster space down from that in the even field.

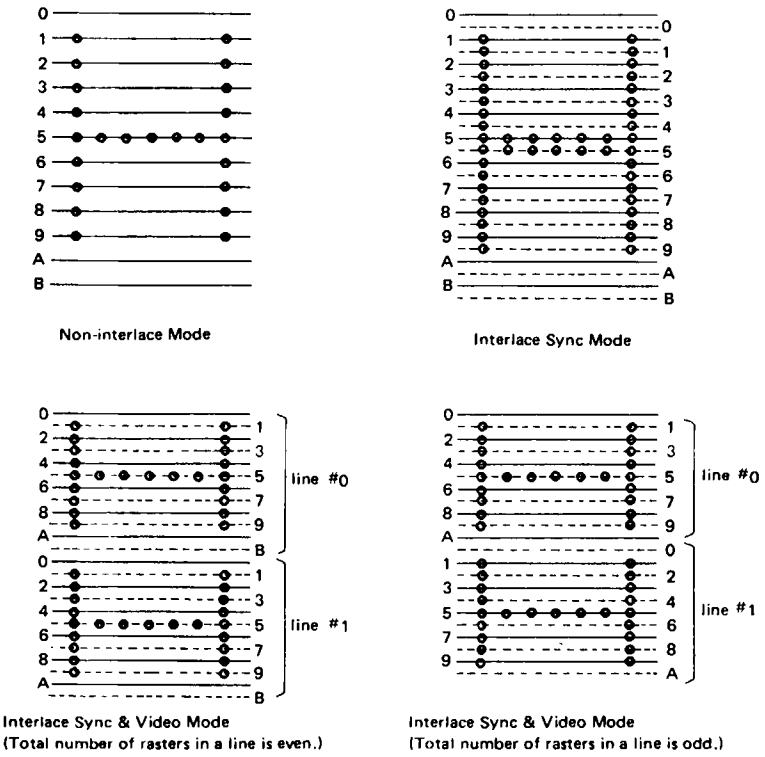


Figure 7 Example of Raster Scan Display

Interlace Sync & Video Mode Display

In interlace sync & video mode, the output raster address when the number of rasters is even is different from that when the number of rasters is odd.

Table 9 The Output of Raster Address in Interlace Sync & Video Mode

Total Number of Rasters in a Line \ Field		Even Field	Odd Field
Even		Even Address	Odd Address
Odd	Even Line*	Even Address	Odd Address
	Odd Line*	Odd Address	Even Address

* Internal line address begins from 0.

1) Total number of rasters in a line is even;

When number of rasters is programmed to be even, even raster address is output in the even field and odd raster address is output in the odd field.

2) Total number of rasters in a line is odd;

When total number of rasters is programmed to be odd, odd and even addresses are reversed according to the odd and even lines in each field. In this case, the difference in numbers of dots displayed between even field and odd field is usually smaller the case of 1). Then interlace can be displayed more stably.

[NOTE] The wide disparity of dots between number of dots between even field and odd field influences beam current of CRT. CRT, which has a stable high-voltage part, can make interlace display normal. On the contrary, CRT, which has unstable high-voltage part, moves deflection angle of beam current and also dots displayed in the even and odd fields may be shifted. Characters appears distroting on a border of the screen. So 2) programming has an effect to decrease such evil influences as mentioned above. Fig. 12 shows fine chart in each mode when interlace is performed.

- **Cursor Control**

Fig. 8 shows the display patterns where each value is programmed to the cursor start raster register and the cursor end raster register. Programmed values to the cursor start raster register and the cursor end raster register need to be under the following condition.

Cursor Start Raster Register $\leqq$ Cursor End Raster Register $\leqq$ Maximum Raster Address Register.

Time chart of CUDISP output signal is shown in Fig. 13 and Fig. 14.

■ INTERFACE TO DISPLAY CONTROL UNIT

Fig. 16 shows the interface between the CRTC and display control unit. Display control unit is mainly composed of Refresh Memory, Character Generator, and Video Control circuit. For refresh memory, 14 Memory Address line (0~16383) max are provided and for character generator, 5 Raster Address line (0~31) max are provided. For video control circuit, DISPTMG, CUDISP, HSYNC, and VSYNC signals are sent out. DISPTMG signal is used to control the blank period of video signal. CUDISP signal is used as video signal to display the cursor on the CRT screen. Moreover, HSYNC and VSYNC signals are used as drive signals respectively for CRT horizontal and vertical deflection circuits.

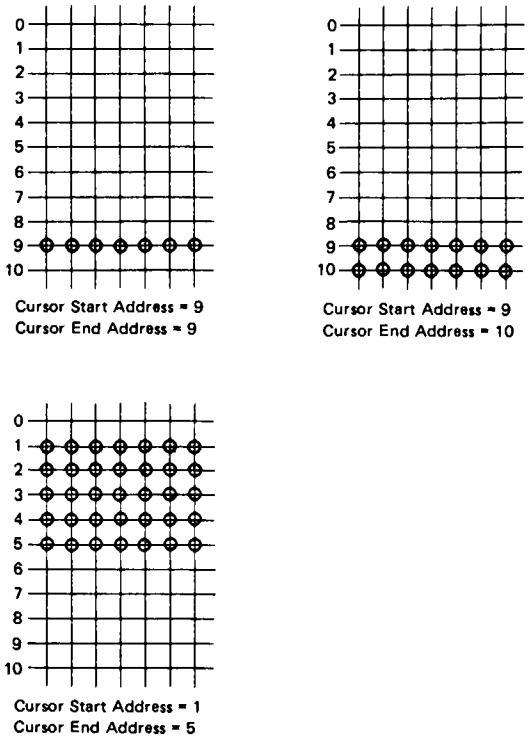


Figure 8 Cursor Control

Outputs from video control circuit, (video signals and sync signals) are provided to CRT display unit to control the deflection and brightness of CRT, thus characters are displayed on the screen.

Fig. 17 shows detailed block diagram of display control unit. This shows how to use CUDISP and DISPTMG signals. CUDISP and DISPTMG signals should be used being latched at least one time at external flip-flop F1 and F2. Flip-flop F1 and F2 function to make one-character delay time so as to synchronize them with video signal from parallel-serial converter. High-speed D type flip-flop as TTL is used for this purpose. After being delayed at F1 and F2 DISPTMG signal is AND-ed with character video signal, and CUDISP signal is OR-ed with output from AND gate. By using this circuitry, blanking of horizontal and vertical retrace time is controlled. And cursor video is mixed with character video signal.

Fig. 17 shows the example in the case that both refresh memory and CG can be accessed for horizontal one character time. Time chart for this case is shown in Fig. 20. This method is used when a few character needed to be displayed in horizontal direction on the screen.

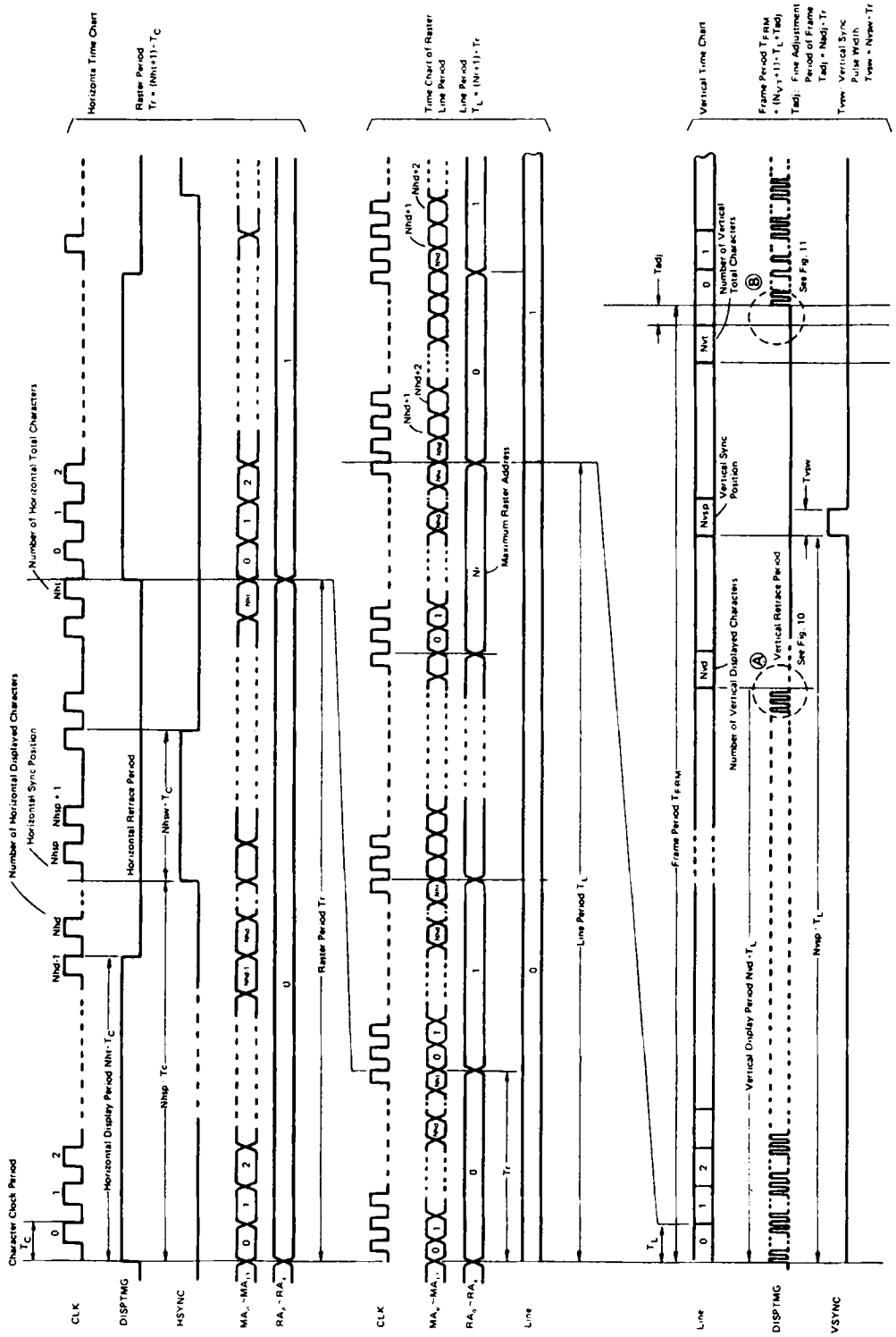


Figure 9 CRTC Time Chart

(Output waveform of horizontal & vertical display in the case where values shown in Table 8 are Programmed to each register.)

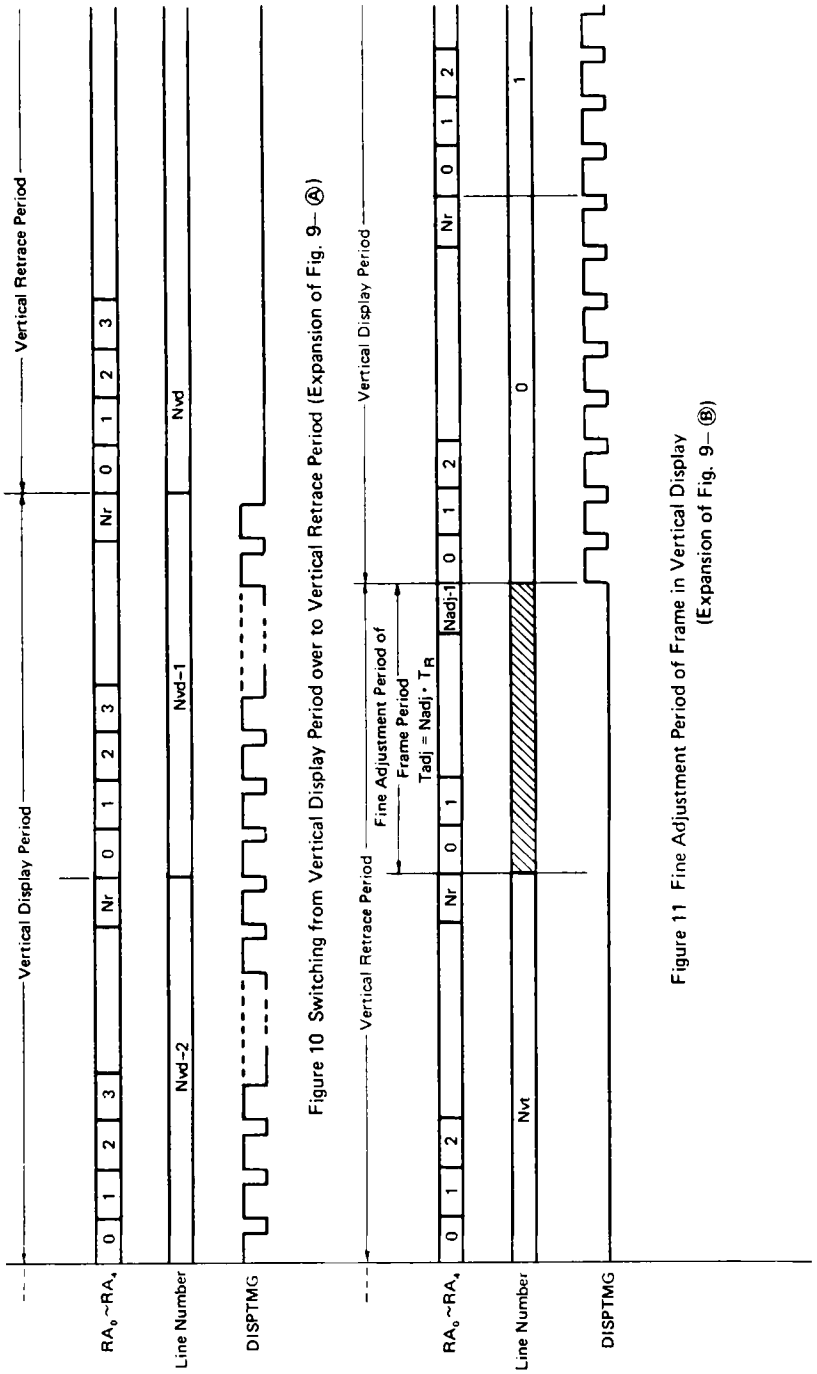


Figure 10 Switching from Vertical Display Period over to Vertical Retrace Period (Expansion of Fig. 9– Ⓐ)

Figure 11 Fine Adjustment Period of Frame in Vertical Display (Expansion of Fig. 9– Ⓑ)

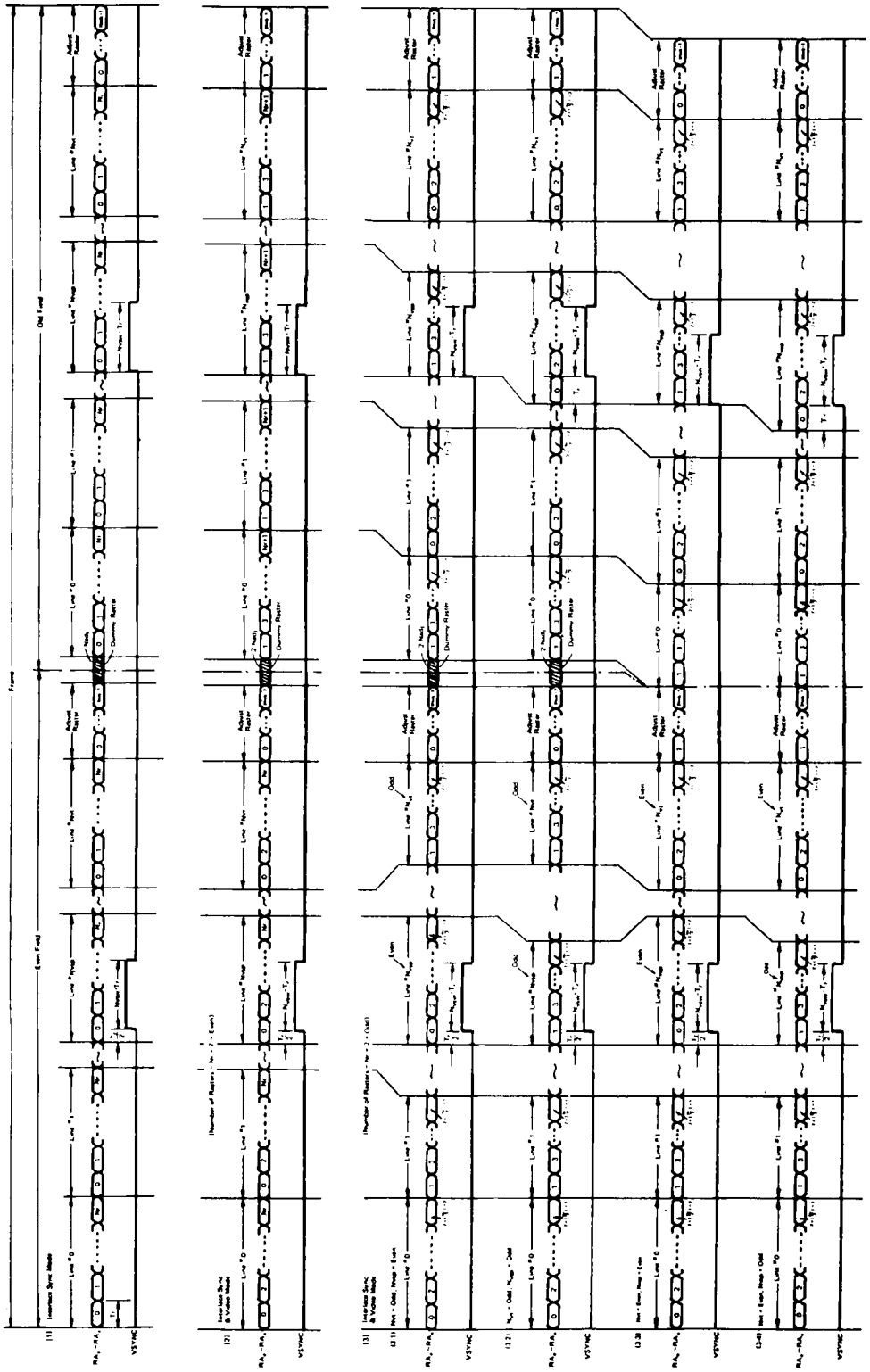


Figure 12 Interlace Control

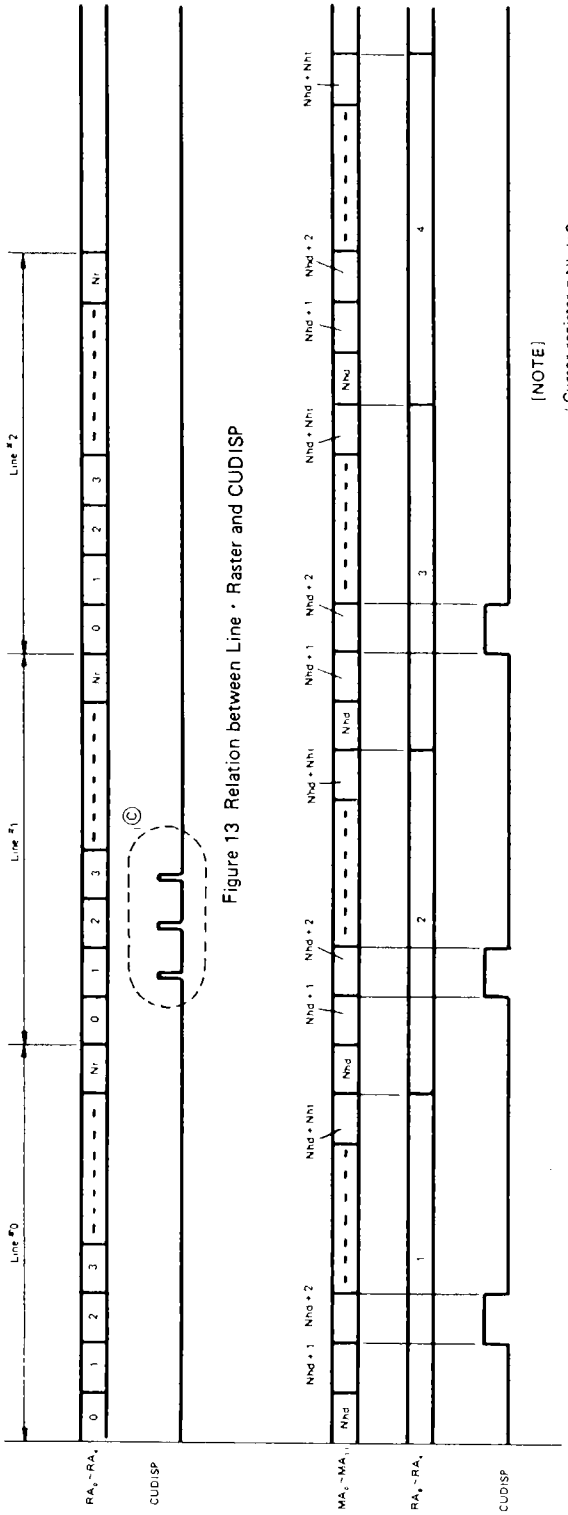


Figure 13 Relation between Line · Raster and CUDISP

[NOTE]
Cursor register = Nhd+2
Cursor Start
Raster Register = 1
Cursor End
Raster Register = 3
are Programmed in cursor display mode.

In blink mode, it is changed into display or non-display mode when field period is 16 or 32-time period.

Figure 14 CUDISP Output Timing (Exapnsion of Fig. 13· ©)

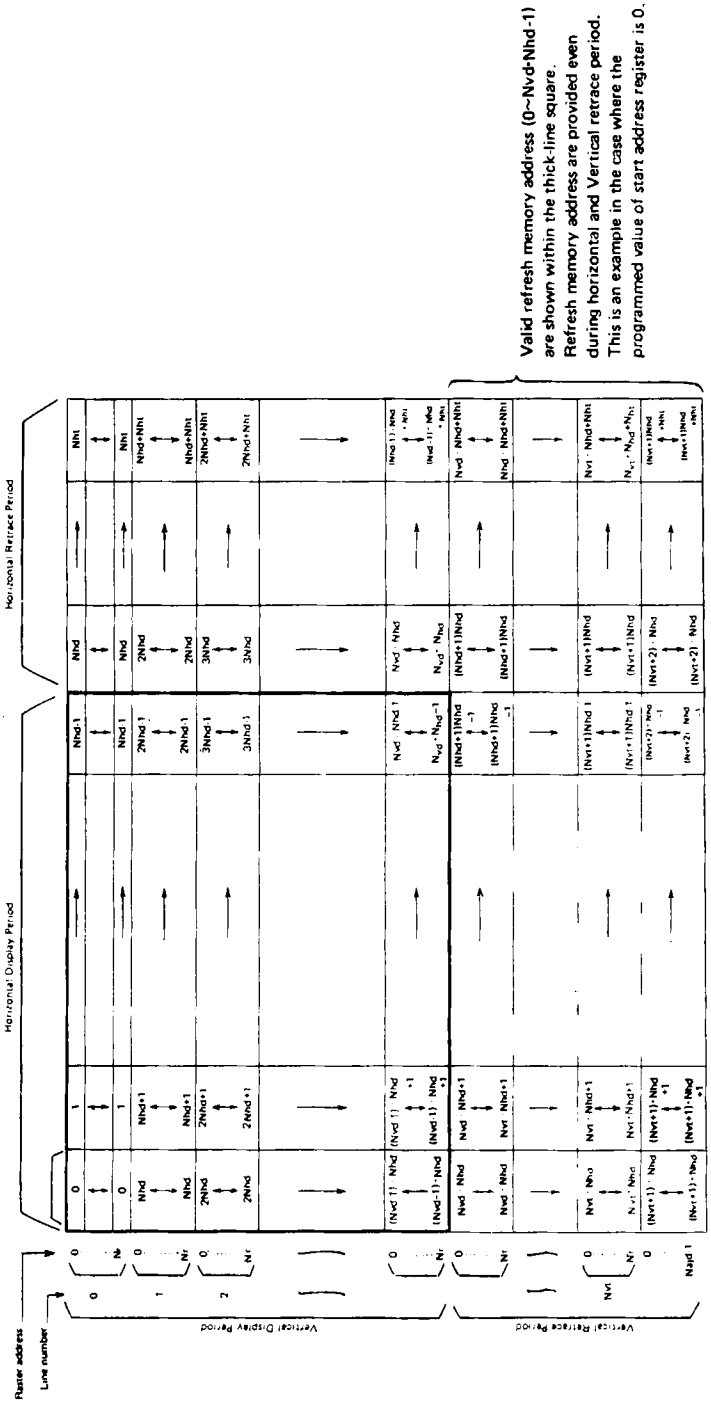


Figure 15 Refresh Memory Address (MA_0~MA_{13})

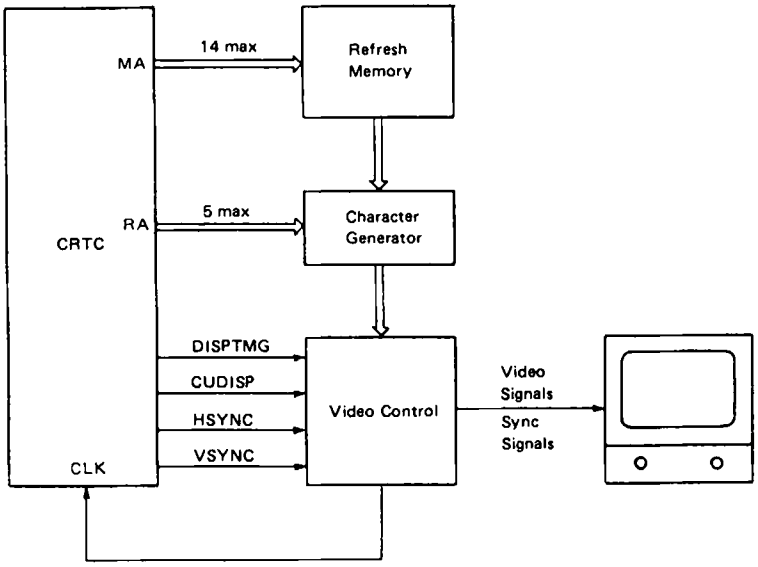


Figure 16 Interface to Display Control Unit

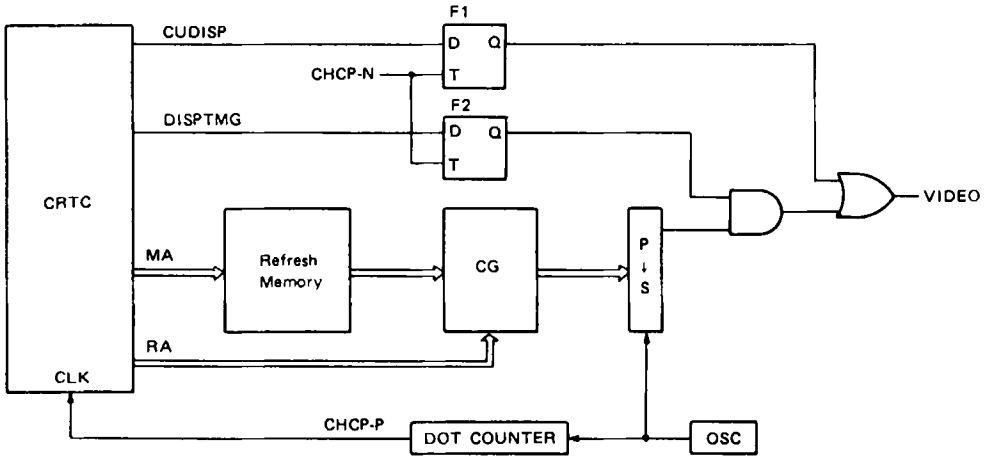


Figure 17 Display Control Unit (1)

When many characters are displayed in horizontal direction on the screen, and horizontal one-character time is so short that both refresh memory and CG cannot be accessed, the circuitry shown in Fig. 18 should be used. In this case refresh memory output shall be latched and CG shall be accessed at the next cycle. The time chart in this case is shown in Fig. 21. CUDISP and DISPTMG signals should be provided after being delayed by one-character time by using skew bit of interlace & skew register (R8). Moreover, when there are some troubles about delay time of MA during horizontal one-character time on high-speed display operation, system shown in Fig.19 is adopted. The time chart in this case is shown in Fig.22. Character video signal is delayed for two-character time because each MA outputs and refresh memory outputs are latched, and they are made to be in phase with CUDISP and DISPTMG signals by delaying for two-character time. Table 10 shows the circuitry selection standard of display units.

Table 10 Circuitry Standard of Display Control Unit

Case	Relation among t_{CH}, RM and CG	Block Diagram	Interlace & Skew Register Bit Programming			
			C1	C0	D1	D0
1	$t_{CH} >$ RM Access + CG Access + t_{MAD}	Fig. 17	0	0	0	0
2	RM Access + CG Access + $t_{MAD} \geqq t_{CH} >$ RM Access + t_{MAD}	Fig. 18	0	1	0	1
3	RM Access + $t_{MAD} \geqq t_{CH} >$ RM Access	Fig. 19	1	0	1	0

t_{CH} : CHCP Period; t_{MAD} : MA Delay

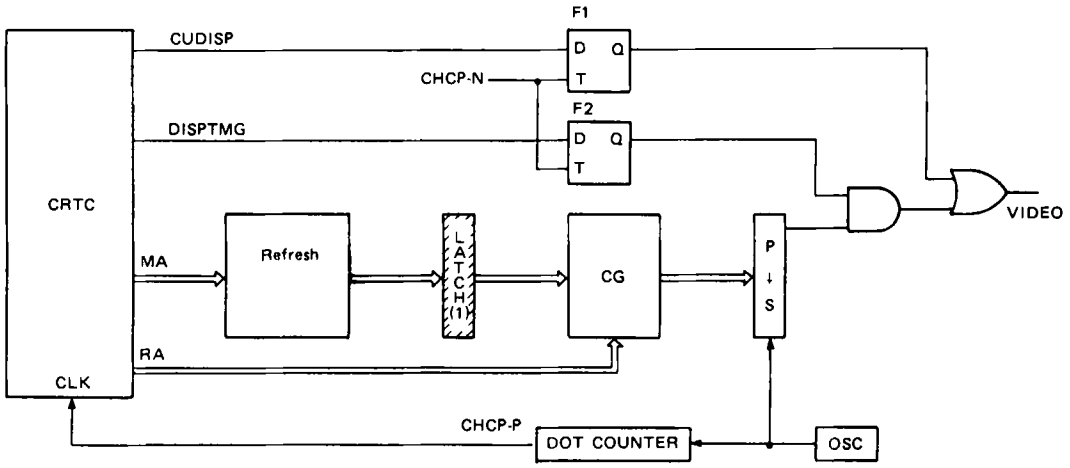


Figure 18 Display Control Unit (2)

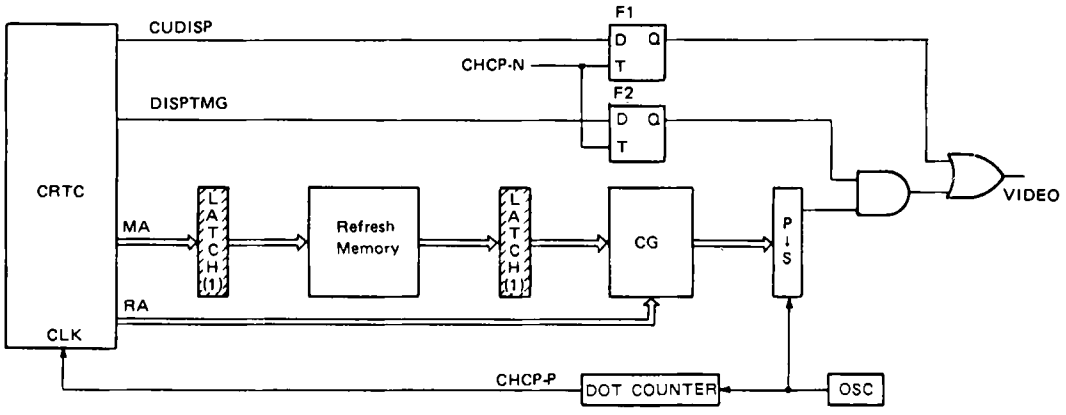


Figure 19 Display Control Unit (For high-speed display operation) (3)

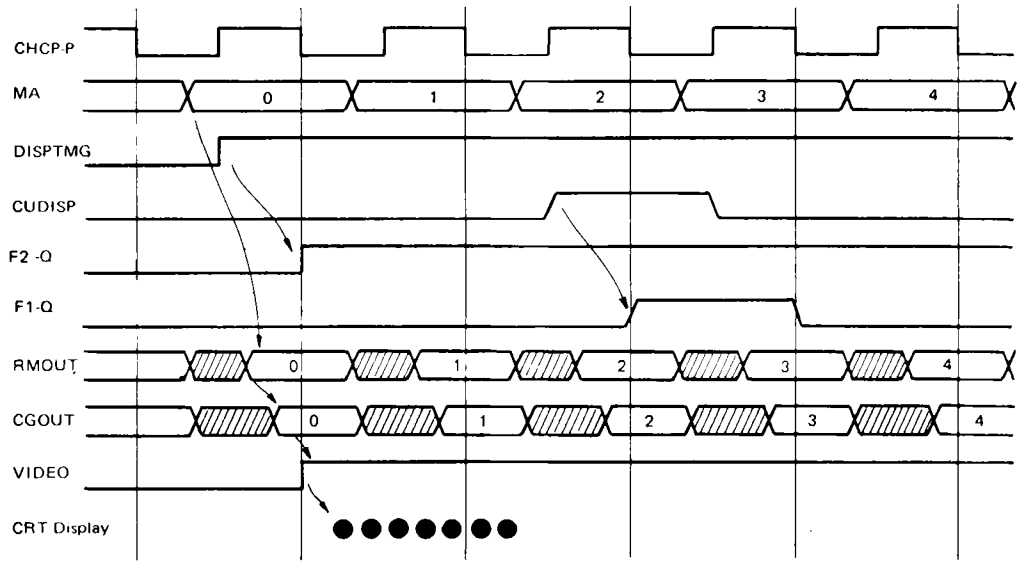


Figure 20 Time Chart of Display Control Unit (1)

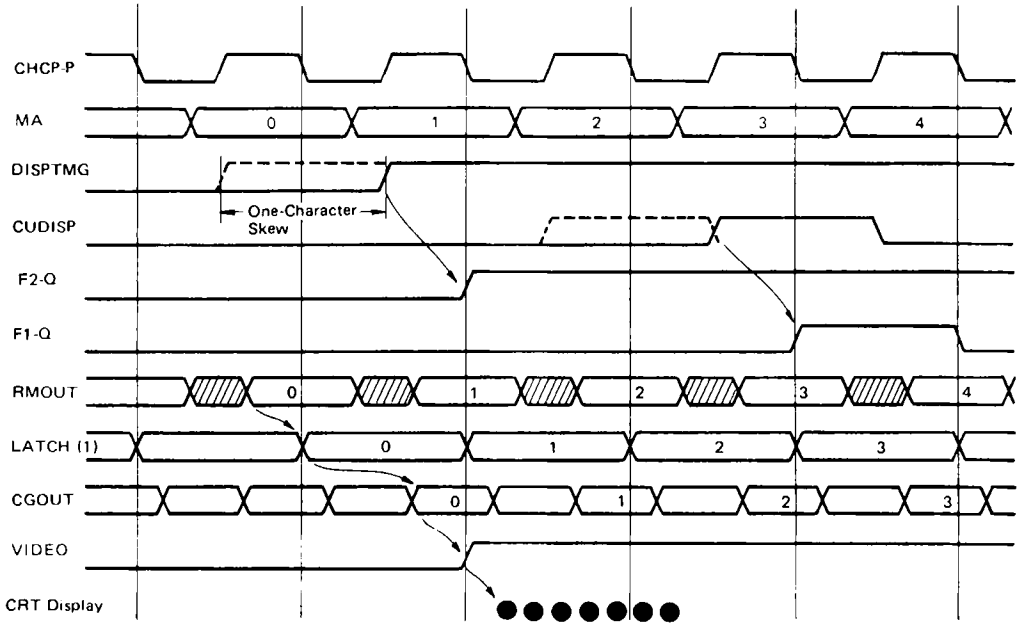


Figure 21 Time Chart of Display Control Unit (2)

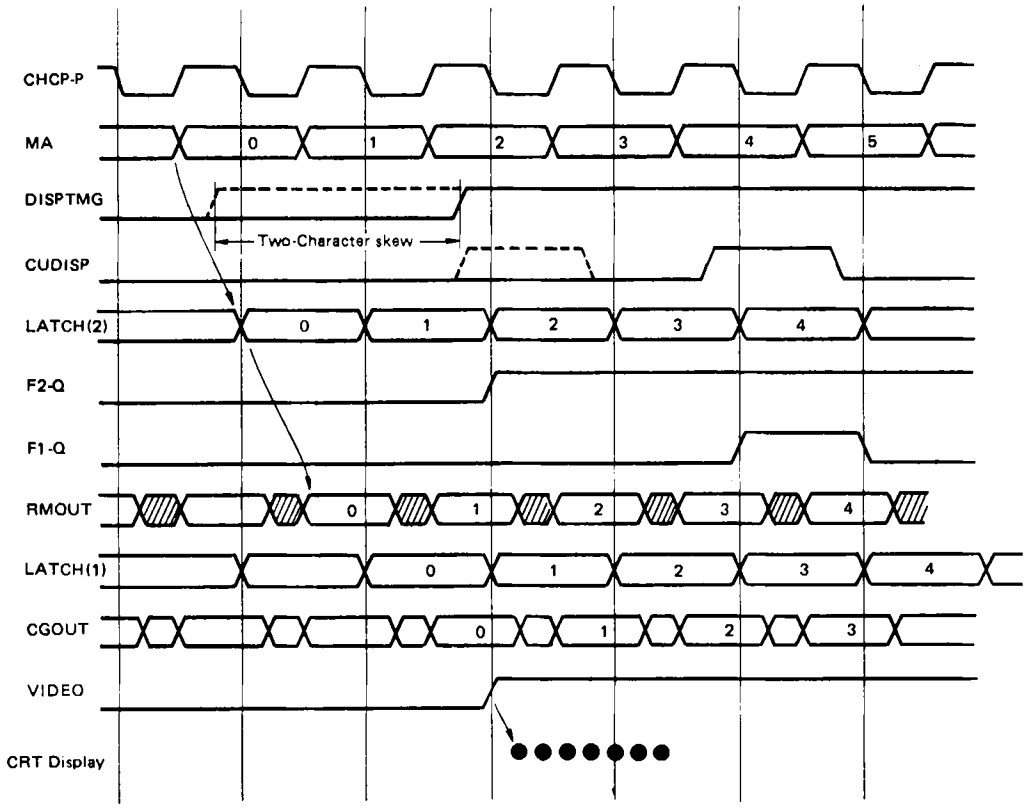


Figure 23 Time Chart of Display Unit (3)

■ HOW TO DECIDE PARAMETERS SET ON THE CRTC

• How to Decide Parameters Based on Specification of CRT Display Unit (Monitor)

Number of Horizontal Total Characters

Horizontal deflection frequency fh is given by specification of CRT display unit. Number of horizontal total characters is determined by the following equation.

$$fh = \frac{1}{tC\ (Nht + 1)}$$

where,

tC : Cycle Time of CLK (Character Clock)
Nht : Programmed Value of Horizontal Total Register (R0)

Number of Vertical Total Characters

Vertical deflection frequency is given by specification of CRT display unit. Number of vertical Total characters is determined by the following equation.

1) Non-interlace Mode
$Rt = (Nvt + 1)(Nr + 1) + Nadj$
2) Interlace Sync Mode
$Rt = (Nvt + 1)(Nr + 1) + Nadj + 0.5$
3) Interlace Sync & Video Mode

$$Rt = \frac{(Nvt + 1)(Nr + 2) + 2Nadj}{2} \quad \ldots\ldots\ldots\ldots \text{(a)}$$

$$Rt = \frac{(Nvt + 1)(Nr + 2) + 2Nadj + 1}{2} \quad \ldots\ldots\ldots\ldots \text{(b)}$$

(a) is applied when both total numbers of vertical characters (Nvt + 1) and that of rasters in a line (Nr + 2) are odd.
(b) is applied when total number of rasters (Nr + 2) is even, or when (Nr + 2) is odd and total number of vertical characters (Nvt + 1) is even.

where,

Rt : Number of Total Rasters per frame (Including retrace period)
Nvt : Programmed Value of Vertical Total Register (R4)
Nr : Programmed Value of Maximum Raster Address Register (R9)
Nadj : Programmed Value of Vertical Total Adjust Register (R5)

Horizontal Sync Pulse Width

Horizontal sync pulse width is programmed to low order 4-bit of horizontal sync width register (R3) in unit of horizontal character time. Programmed value can be selected within from 1 to 15.

Horizontal Sync Position

As shown in Fig. 24, horizontal sync position is normally selected to be in the middle of horizontal blank period. But there are some cases where its optimum sync position is not located in the middle of horizontal blank period according to specification of CRT. Therefore, horizontal sync position should be determined by specification of CRT. Horizontal sync pulse position is programmed in unit of horizontal character time.

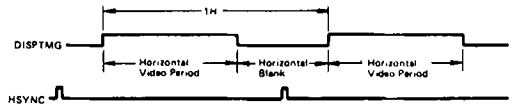


Figure 24 Time Chart of HSYNC

Vertical Sync Pulse Width

Vertical Sync Pulse Width is programmed to high order 4-bit of vertical sync pulse width register (R3) in unit of raster period. Programmed value can be selected within from 1 to 16.

Vertical Sync Position

As shown in Fig. 25, vertical sync position is normally selected to be in the middle of vertical blank period. But there are some cases where its optimum sync position is not located in the middle of vertical blank period according to specification of CRT. Therefore, vertical sync position should be determined by specification of CRT. Vertical sync pulse position is programmed to vertical sync position register (R7) in unit of line period.

- **How to Decide Parameters Based on Screen Format**

Dot Number of Characters (Horizontal)

Dot number of characters (horizontal) is determined by character font and character space. An example is shown in Fig. 26. More strictly, dot number of characters (horizontal) N is determined by external N-counter. Character space is set by means shown in Fig. 27.

Dot Number of Characters (Vertical)

Dot number of characters (vertical) is determined by characters font and line space. An example is shown in Fig. 26. Dot number of characters (vertical) is programmed to maximum raster address (register R9) of CRTC. When N_r is programmed

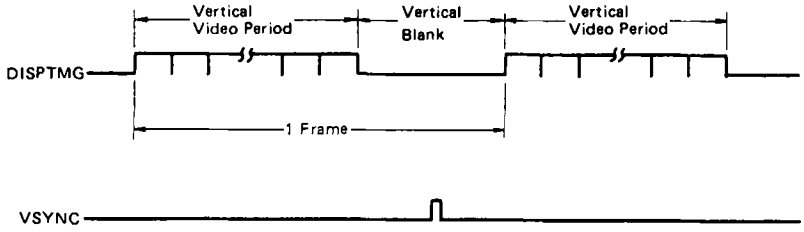


Figure 25 Time Chart of VSYNC

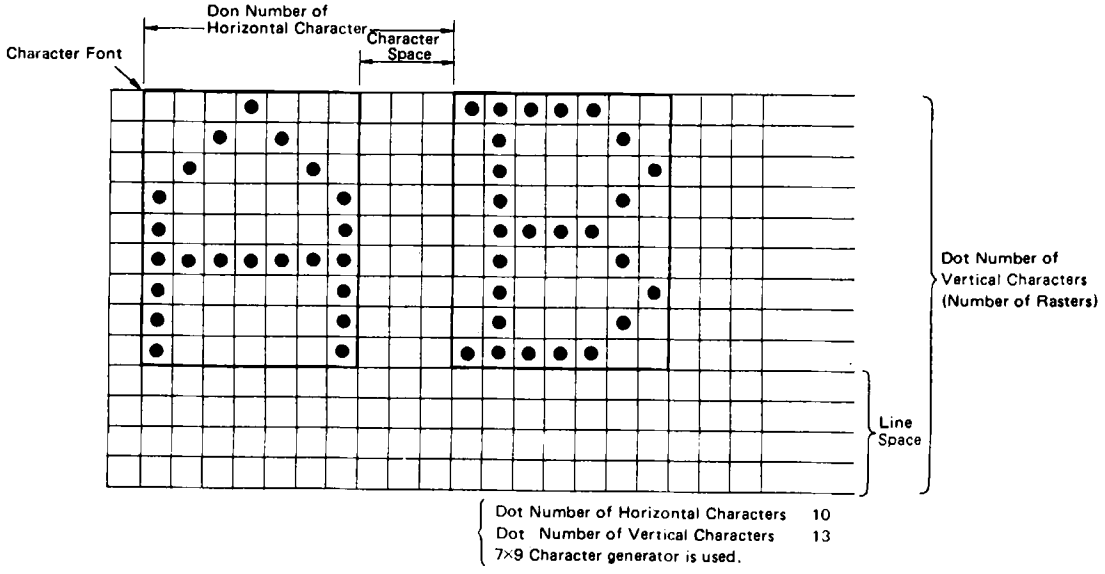


Figure 26 Dot Number of Horizontal and Vertical Characters

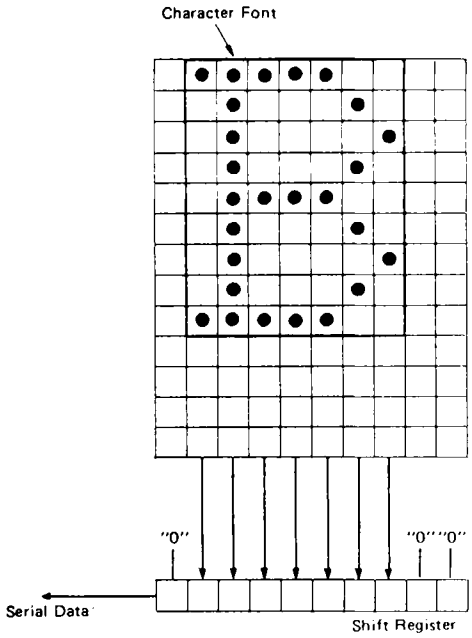


Figure 27 How to Make Character Space

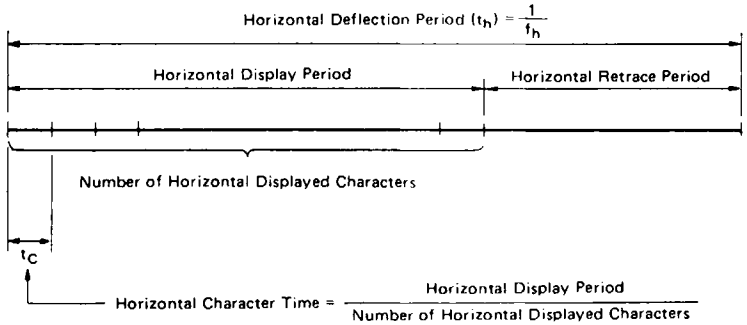


Figure 28 Number of Horizontal Displayed Characters

value of R9, dot number of characters (vertical) is (Nr+1).

Number of Horizontal Displayed Characters

Number of horizontal displayed characters is programmed to horizontal displayed register (R1) of the CRTC. Programmed value is based on screen format. Horizontal display period, which is given by specification of horizontal deflection frequency and horizontal retrace period of CRT display unit, determines horizontal character time, being divided by number of horizontal displayed characters. Moreover, its cycle time and access time which are necessary for CRT display system are determined by horizontal character time.

Number of Vertical Displayed Characters

Number of vertical displayed characters is programmed to vertical displayed register (R6). Programmed value is based on screen format. As specification of vertical deflection frequency of CRT determines number of total rasters (Rt) including vertical retrace period and the relation between number of vertical displayed character and total number of rasters on a screen is as mentioned above, CRT which is suitable for desired screen format should be selected.

For optimum screen format, it is necessary to adjust number of rasters per line, number of vertical displayed characters, and total adjust raster (Nadj) within specification of vertical deflection frequency.

Scan Mode

The CRTC can program three-scan modes shown in Table 11 to interlace mode register (R8). An example of character display in each scan mode is shown in Fig. 7.

Table 11 Program of Scan Mode

2^1	2^0	Scan Mode	Main Usage
0	0	Non-interlace	Normal Display of Characters & Figures
1	0		
0	1	Interlace Sync	Fine Display of Characters & Figures
1	1	Interlace Sync & Video	Display of Many Characters & Figures Without Using High-resolution CRT

[NOTE] In the interlace mode, the number of times per sec. in raster scanning on one spot on the screen is half as many as that in non-interlace mode. Therefore, when persistence of luminescence is short, flickering may happen. It is necessary to select optimum scan mode for the system, taking characteristics of CRT, raster scan speed, and number of displayed characters and figures into account.

Cursor Display Method

Cursor start raster register and cursor end raster register (R10, R11) enable programming the display modes shown in Table 7 and display patterns shown in Fig. 8. Therefore, it is possible to change the method of cursor display dynamically according to the system conditions as well as to realize the cursor display that meets the system requirements.

Start Address

Start address resisters (R12, R13) give an offset to the address of refresh memory to read out. This enables paging and scrolling easily.

Cursor Register

Cursor registers (R14, R15) enable programming the cursor display position on the screen. As for cursor address, it is not X, Y address but linear address that is programmed.

■ EXAMPLES OF APPLIED CIRCUIT OF THE CRTC

Fig. 30 shows an example of application of the CRTC to monochrome character display. Its specification is shown in Table 12. Moreover, specification of CRT display unit is shown in Table 13 and initializing values for the CRTC are shown in Table 14.

Table 12 Specification of Applied Circuit

Item	Specification															
Character Format	5 × 7 Dot															
Character Space	Horizontal : 3 Dot Vertical : 5 Dot															
One Character Time	1 μs															
Number of Displayed Characters	40 characters × 16 lines = 640 characters															
Access Method to Refresh Memory	Snychronous Method (DISPTMG Read)															
Refresh Memory	1 kB															
Address Map		2^{15}	2^{14}	2^{13}	2^{12}	2^{11}	2^{10}	2^9	2^8	2^7	2^6	2^5	2^4	2^3	2^2	2^1	2^0
	Refresh Memory	0	0	0	0	0	0	•	•	•	•	•	•	•	•	•	•
	CRTC Address Register	0	0	0	1	0	0	×	×	×	×	×	×	×	×	×	0
	CRTC Control Register	0	0	0	1	0	0	×	×	×	×	×	×	×	×	×	1
	× · · · don't care, • · · · 0 or 1																
Synchronization Method	HVSYNC Method															

Table 13 Specification of Character Display

Item	Specification
Scan Mode	Non-interlace
Horizontal Deflection Frequency	15.625 kHz
Vertical Deflection Frequency	60.1 Hz
Dot Frequency	8 MHz
Character Dot (Horizontal × Vertical)	8 × 12 (Character Font 5 × 9)
Number of Displayed Characters (Row × Line)	40 × 16
HSYNC Width	4 μs
VSYNC Width	3 H
Cursor Display	Raster 9 ~ 10, Blink 16 Field Period
Paging, Scrolling	Not used

Table 14 Initializing Values for Character Display

Register	Name	Symbol	Initializing Value Hex (Decimal)
R0	Horizontal Total	Nht	3F (63)
R1	Horizontal Displayed	Nhd	28 (40)
R2	Horizontal Sync Position	Nhsp	34 (52)
R3	Sync Width	Nvsw, Nhsw	34
R4	Vertical Total	Nvt	14 (20)
R5	Vertical Total Adjust	Nadj	08 (8)
R6	Vertical Displayed	Nvd	10 (16)
R7	Vertical Sync Position	Nvsp	13 (19)
R8	Interlace & Skew		00
R9	Maximum Raster Address	Nr	0B (11)
R10	Cursor Start Raster	B, P, NCSTART	49
R11	Cursor End Raster	NCEND	0A (10)
R12	Start Address (H)		00 (0)
R13	Start Address (L)		00 (0)
R14	Cursor (H)		00 (0)
R15	Cursor (L)		00 (0)

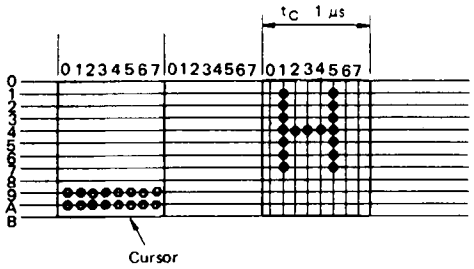


Figure 29 Non-interlace Display (Example)

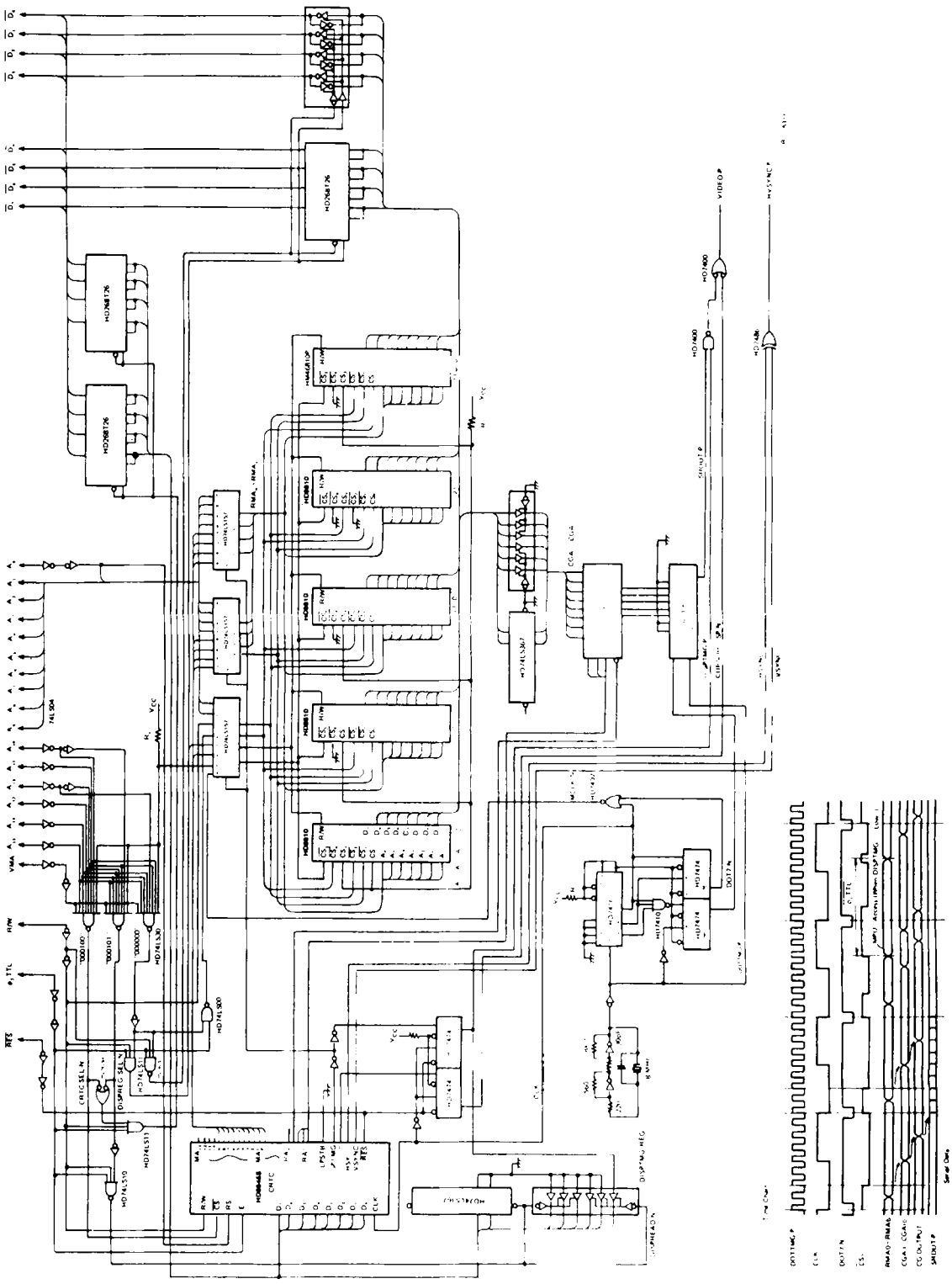
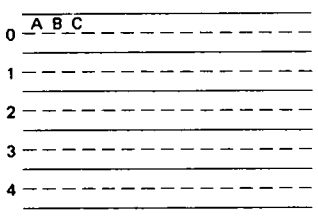
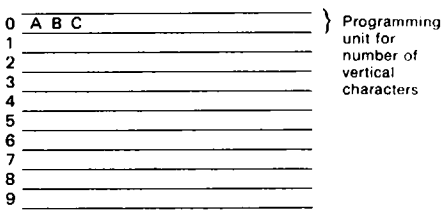
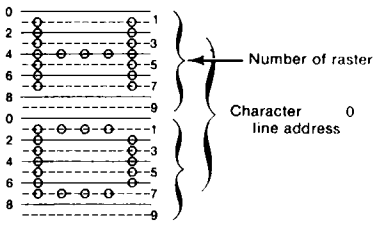
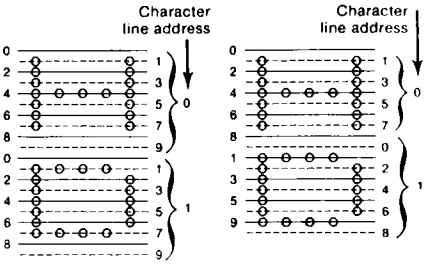
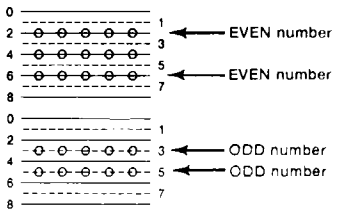
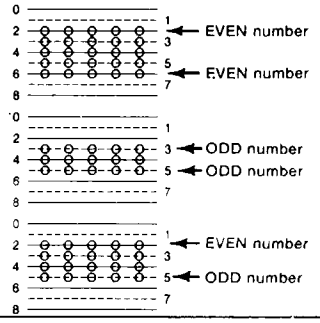
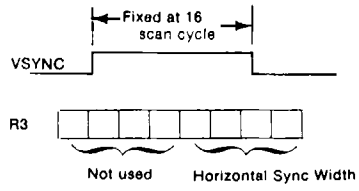
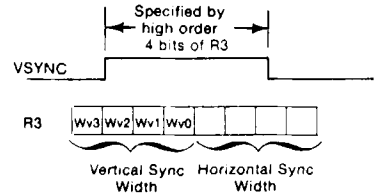
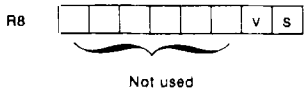
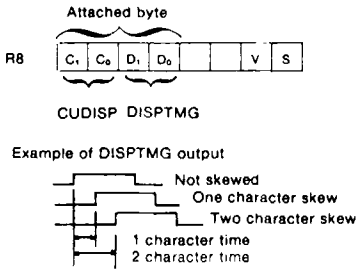


Figure 30 Example of Applied Circuit of the CRTC (Monochrome Character Display)

Differences between the HD6845R (Motorola MC6845 Compatible) and the HD6845S (Enhanced)

No.	Functional Difference		HD6845R	HD6845S
1	Interlace Sync & Video Mode Display	Programming Method of number of vertical characters	Character line address  In HD6845R, number of characters is vertically programmed in units of two lines, as illustrated above. (Number of vertical total characters, Number of vertical displayed characters, Vertical Sync Position) Example of above figure . . . Programmed number into Vertical Displayed Register = 5	Character line address  In HD6845S, number of characters is vertically programmed in unit of one line, as illustrated above. (Number of vertical total characters, Number of vertical displayed characters, Vertical Sync Position) Example of above figure . . . Programmed number into Vertical Displayed Register = 10
		Number of raster per character line	Only even number can be specified.  Number of raster = 10 scanline (specified) However, number which is programmed into register is calculated as follows. Programmed number (Nr) = (Number specified) − 1	Both even number and odd number can be specified.  When number of raster per character line is EVEN Number of raster = 10 scan line (specified) When number of raster per character line is ODD. Number of raster = 9 scan line (specified) However, number which is programmed into register is calculated as follows. Programmed number (NR) = (Number specified) − 2
		Cursor Display	Cursor is displayed in either EVEN field or ODD field. 	Cursor is displayed in both EVEN field and ODD field. 

No.	Functional Difference	HD6845R	HD6845S
2	Vertical Sync Pulse Width (VSYNC output)	Fixed at 16 raster scan cycle (16H) 	Programmable (1 - 16 raster scan cycle) 
3	SKEW Function	Not included 	SKEW capability is included in DISPTMG, CUDISP signals. 
4	Start Address Register	Write Only	Read or Write
5	RESET Signal (RES)	$MA_0 \sim M_{13}$ Output, $RA_0 \sim RA_4$ Output ------Synchronous reset Other Outputs ---------Asynchronous reset Output signals of $MA_0 \sim MA_{13}$, $RA_0 \sim RA_4$, synchronized with CLK "LOW" level, go to "LOW" level, after RES has gone to "LOW." Other outputs go to "LOW" immediately after RES has gone to "LOW" level.	$MA^0 \sim MA_{13}$ Output, $RA_0 \sim RA_4$ Output, Other Outputs ---- Asynchronous reset Output signals of $MA_0 \sim MA_{13}$, $RA_0 \sim RA_4$ and others go to "LOW" level immediately after RES has gone to "LOW" level.

AC Characteristic Differences between HD6845R (Motorola MC6845 Compatible) and HD6845S (Enhanced)

No.	Characteristic Difference	Symbol	HD46505R			HD46505S			Unit
			min.	typ.	max.	min.	typ.	max.	
1	Clock Cycle Time	$tcycc$	330	—	—	270	—	—	ns
2	Clock Pulse Width "High"	PW_{CH}	150	—	—	130	—	—	ns
3	Clock Pulse Width "Low"	PW_{CL}	150	—	—	130	—	—	ns
4	Rise and Fall Time for Clock Input	T_{CR}, T_{CF}	—	—	15	—	—	20	ns
5	Horizontal Sync Delay Time	T_{HSD}	—	—	250	—	—	200	ns
6	Light Pan Strobe Pulse Width	PW_{LPH}	80	—	—	60	—	—	ns
7	Light Pan Strobe, Uncertain Time of Acceptance	T_{LPD1}	—	—	80	—	—	70	ns
		T_{LPD2}	—	—	10	—	—	0	ns

SCHOTTKY † PROMS

SERIES 14 AND 18 PROGRAMMABLE READ-ONLY MEMORIES

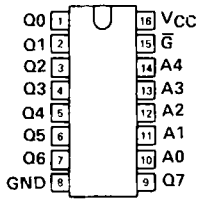
JUNE 1981

- Titanium-Tungsten (Ti-W) Fuse Link For Reliable Low-Voltage Full Family Compatible Programming
- Full Decoding And Fast Chip Select Simplify System Design
- P-N-P Inputs For Reduced Loading On System Buffers/Drivers
- Applications Include:
  Microprogramming/Firmware Loaders
  Code Converters/Character Generators
  Translators/Emulators
  Address Mapping/Look-Up Tables

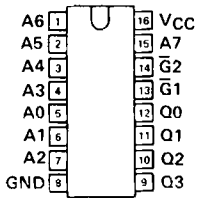
NEW TYPE NUMBER	OLD TYPE NUMBER	BIT SIZE (ORGANIZATION)	OUTPUT CONFIGURATION†	TYPICAL PERFORMANCE	
0°C to 70°C	0°C to 70°C			ADDRESS ACCESS TIME	POWER DISSIPATION
TBP18SA030 (J, N)▲	SN74S188 (J, N)	256 Bits (32W X 8B)	◇	25 ns	400 mW
TBP18S030 (J, N)▲	SN74S288 (J, N)		▽		
TBP14S10 (J, N)▲	SN74S287 (J, N)	1024 Bits (256W X 4B)	▽	42 ns	500 mW
TBP14SA10 (J, N)▲	SN74S387 (J, N)		◇		
TBP18SA22 (J, N)▲	SN74S470 (J, N)	2048 Bits (256W X 8B)	◇	50 ns	550 mW
TBP18S22 (J, N)▲	SN74S471 (J, N)		▽		
TBP18S42 (J, N)▲	SN74S472 (J, N)	4096 Bits (512W X 8B)	▽	55 ns	600 mW
TBP18SA42 (J, N)▲	SN74S473 (J, N)		◇		
TBP18S46 (J, N)▲	SN74S474 (J, N)	4096 Bits (512W X 8B)	▽	55 ns	600 mW
TBP18SA46 (J, N)▲	SN74S475 (J, N)		◇		

▲ For full temperature parts (−55°C to +125°C) use suffix MJ. For devices with MIL-STD 883B processing (−55°C to +125°C) see page 2-3.
† ◇ = open collector, ▽ = three state.

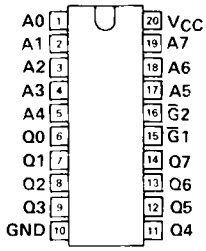
TBP18SA030, TBP18S030
256 BITS
(32 WORDS BY 8 BITS)
(TOP VIEW)



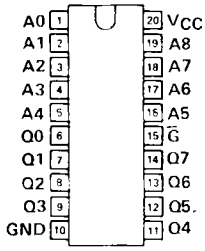
TBP14S10, TBP14SA10
1024 BITS
(256 WORDS BY 4 BITS)
(TOP VIEW)



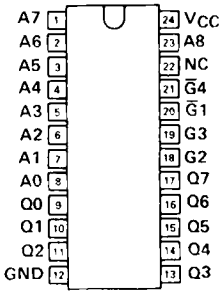
TBP18SA22, TBP18S22
2048 BITS
(256 WORDS BY 8 BITS)
(TOP VIEW)



TBP18S42, TBP18SA42
4096 BITS
(512 WORDS BY 8 BITS)
(TOP VIEW)



TBP18S46, TBP18SA46
4096 BITS
(512 WORDS BY 8 BITS)
(TOP VIEW)



Pin assignments for all of these memories are the same for the J and N packages. See Product Guide, Section 7, for chip carrier pin assignments.

description

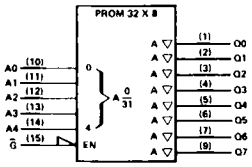
These monolithic TTL programmable read-only memories (PROMs) feature titanium-tungsten (Ti-W) fuse links with each link designed to program in 100 microseconds. The Schottky-clamped versions of these PROMs offer considerable flexibility for upgrading existing designs or improving new designs as they feature full Schottky clamping for improved performance, low-current MOS-compatible p-n-p inputs, choice of bus-driving three-state or open-collector outputs, and improved chip-select access times.

The high-complexity 2048- and 4096-bit PROMs can be used to significantly improve system density for fixed memories as all are offered in the 20-pin dual-in-line package having pin-row spacings of 0.300 inch (7,62 mm).

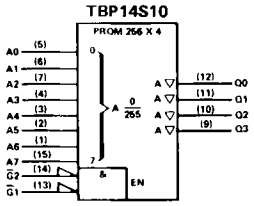
SERIES 14 AND 18
PROGRAMMABLE READ-ONLY MEMORIES

logic symbols

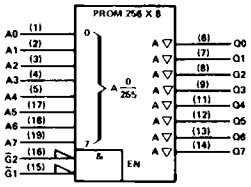
TBP18S030



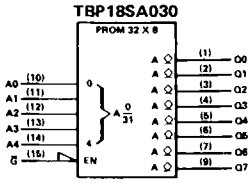
TBP14S10



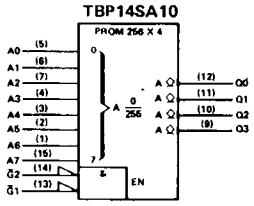
TBP18S22



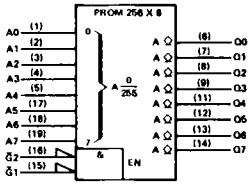
TBP18SA030



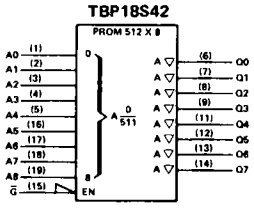
TBP14SA10



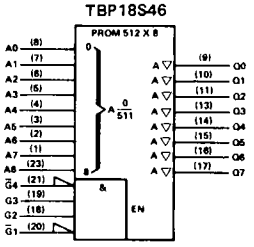
TBP18SA22



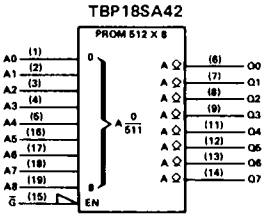
TBP18S42



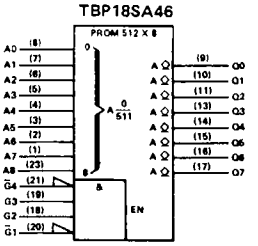
TBP18S46



TBP18SA42



TBP18SA46



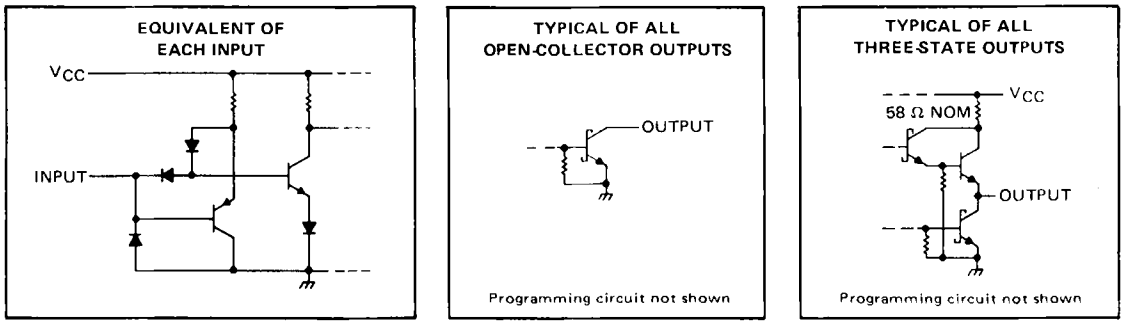
description (continued)

Data can be electronically programmed, as desired, at any bit location in accordance with the programming procedure specified. All PROMs, except the TBP14S10 and TBP14SA10 are supplied with a low-logic-level output condition stored at each bit location. The programming procedure open-circuits Ti-W metal links, which reverses the stored logic level at selected locations. The procedure is irreversible; once altered, the output for that bit location is permanently programmed. Outputs that have never been altered may later be programmed to supply the opposite output level. Operation of the unit within the recommended operating conditions will not alter the memory content.

A low level at the chip-select input(s) enables each PROM. The opposite level at any chip-select input causes the outputs to be off.

The three-state output offers the convenience of an open-collector output with the speed of a totem-pole output; it can be bus-connected to other similar outputs yet it retains the fast rise time characteristic of the TTL totem-pole output. The open-collector output offers the capability of direct interface with a data line having a passive pull-up.

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage (see Note 1) 7V
Input voltage 5.5V
Off-state output voltage 5.5V
Operating free-air temperature range: Full-temperature-range circuits . . . . . −55°C to 125°C
Commercial-temperature-range circuits . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

recommended conditions for programming the TBP18S', TBP18SA', TBP14S', and TBP14SA' PROMs

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC} (see Note 1)	Steady state	4.75	5	5.25	V
	Program pulse	9	9.25	9.5	
Input voltage	High level, V_{IH}	2.4		5	V
	Low level, V_{IL}	0		0.5	
Termination of all outputs except the one to be programmed		See load circuit (Figure 1)			
Voltage applied to output to be programmed, $V_{O(pr)}$ (see Note 2)		0	0.25	0.3	V
Duration of V_{CC} programming pulse X (see Figure 2 and Note 3)		15	25	100	μs
Programming duty cycle for Y pulse			25	35	%
Free-air temperature		20	25	30	°C

† Absolute maximum ratings.

NOTES: 1. Voltage values are with respect to network ground terminal. The supply voltage rating does not apply during programming.
2. The TBP18S030, TBP18SA030, TBP18SA22, TBP18S22, TBP18S42, TBP18SA42, TBP18S46 and TBP18SA46 are supplied with all bit locations containing a low logic level, and programming a bit changes the output of the bit to high logic level. The TBP14S10, TBP14SA10 are supplied with all bit outputs at a high logic level, and programming a bit changes it to a low logic level.
3. Programming is guaranteed if the pulse applied as 98 μs in duration.

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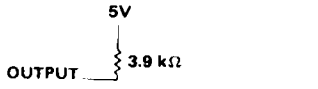
PROGRAMMABLE READ-ONLY MEMORIES

step-by-step programming procedure for the TBP18SA030, TBP18S030, TBP14S10, TBP14SA10, TBP18SA22, TBP18S22, TBP18SA42, TBP18S42, TBP18S46, TBP18SA46

1. Apply steady-state supply voltage (V_{CC} = 5 V) and address the word to be programmed.
2. Verify that the bit location needs to be programmed. If not, proceed to the next bit.
3. If the bit requires programming, disable the outputs by applying a high-logic-level voltage to the chip-select input(s).
4. Only one bit location is programmed at a time. Connect each output not being programmed to 5 V through 3.9 kΩ and apply the voltage specified in the table to the output to be programmed. Maximum current into the programmer output is 150 mA.
5. Step V_{CC} to 9.25 nominal. Maximum supply current required during programming is 750 mA.
6. Apply a low-logic-level voltage to the chip-select input(s). This should occur between 1 μs and 1 ms after V_{CC} has reached its 9.25 level. See programming sequence of Figure 2.
7. After the X pulse time is reached, a high logic level is applied to the chip-select inputs to disable the outputs.
8. Within the range of 1 μs to 1 ms after the chip-select input(s) reach a high logic level, V_{CC} should be stepped down to 5 V at which level verification can be accomplished.
9. The chip-select input(s) may be taken to a low logic level (to permit program verification) 1 μs or more after V_{CC} reaches its steady-state value of 5 V.
10. At a Y pulse duty cycle of 35% or less, repeat steps 1 through 8 for each output where it is desired to program a bit.
11. Verify accurate programming of every word after all words have been programmed using V_{CC} values of 4.5 and 5.5 volts.

NOTE: Only one programming attempt per bit is recommended.



LOAD CIRCUIT FOR EACH OUTPUT NOT BEING PROGRAMMED OR FOR PROGRAM VERIFICATION

FIGURE 1 – LOAD CIRCUIT

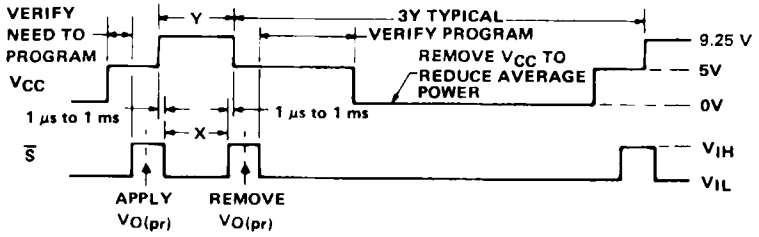


FIGURE 2 – VOLTAGE WAVEFORMS FOR PROGRAMMING

recommended operating conditions

PARAMETER		TBP14S10, TBP18S22			TBP18S030			TBP18S42, TBP18S46			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	MJ	4.5	5	5.5	4.5	5	5.5	4.5	5	5.5	V
	J, N	4.75	5	5.25	4.75	5	5.25	4.75	5	5.25	
High-level output current, I_{OH}	MJ			−2			−2			−2	mA
	J, N			−6.5			−6.5			−6.5	
Low-level output current, I_{OL}				16			20			12	mA
Operating free-air temperature, T_A	MJ	−55		125	−55		125	−55		125	°C
	J, N	0		70	0		70	0		70	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			FULL TEMP (MJ)			COMM. TEMP (J, N)			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage				2			2			V
V_{IL}	Low-level input voltage						0.8			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA				−1.2			1.2	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OH} = MAX		2.4	3.4		2.4	3.2		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OL} = MAX				0.5			0.5	V
I_{OZH}	Off-state output current, high-level voltage applied	V_{CC} = MAX, V_O = 2.4 V	V_{IH} = 2 V,				50			50	μA
I_{OZL}	Off-state output current, low-level voltage applied	V_{CC} = MAX, V_O = 0.5 V	V_{IH} = 2 V,				−50			−50	μA
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V				25			25	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.5 V				−250			−250	μA
I_{OS}	Short-circuit output current§	V_{CC} = MAX			−30		−100	−30		−100	mA
I_{CC}	Supply current	V_{CC} = MAX, Chip select(s) at 0 V, Outputs open, See Note 4		TBP14S10		100	135		100	135	mA
				TBP18S030		80	110		80	110	
				TBP18S22		110	155		110	155	
				TBP18S42, TBP18S46		120	155		120	155	

switching characteristics over recommended ranges of T_A and V_{CC} (unless otherwise noted)

TYPE	TEST CONDITIONS	$t_{a(A)}$ (ns) Access time from address			$t_{a(S)}$ (ns) Access time from chip select (enable time)			t_{PXZ} (ns) Disable time from high or low level			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	MIN	TYP‡	MAX	
TBP14S10MJ	C_L = 30 pF for $t_{a(A)}$ and $t_{a(S)}$, 5 pF for t_{PXZ}, See Page 1-12		42	75		15	40		12	40	ns
TBP14S10			42	65		15	35		12	35	ns
TBP18S030MJ			25	50		12	30		8	30	ns
TBP18S030			25	40		12	25		8	20	ns
TBP18S22MJ			50	80		20	40		15	35	ns
TBP18S22			50	70		20	35		15	30	ns
TBP18S42MJ, TBP18S46MJ			55	85		20	45		15	40	ns
TBP18S42, TBP18S46			55	75		20	40		15	35	ns

NOTE: MJ designates full-temperature-range circuits (formerly 54 Family), J and N designate commercial-temperature-range circuits (formerly 74 Family).

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

NOTE 4: The typical values of I_{CC} are with all outputs low.

SERIES 14 AND 18 PROGRAMMABLE READ-ONLY MEMORIES WITH OPEN-COLLECTOR OUTPUTS

recommended operating conditions

PARAMETER		TBP14SA10, TBP18SA22			TBP18SA030			TBP18SA42, TBP18SA46			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	MJ	4.5	5	5.5	4.5	5	5.5	4.5	5	5.5	V
	J, N	4.75	5	5.25	4.75	5	5.25	4.75	5	5.25	
High-level output voltage, V_{OH}				5.5			5.5			5.5	V
Low-level output current, I_{OL}				16			20			16	mA
Operating free-air temperature, T_A	MJ	−55		125	−55		125	−55		125	°C
	J, N	0		70	0		70	0		70	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IH}	High-level input voltage			2			V
V_{IL}	Low-level input voltage					0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = −18 mA			−1.2	V
I_{OH}	High-level output current	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V	V_{OH} = 2.4 V			50	μA
			V_{OH} = 5.5 V			100	
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IL} = 0.8 V,	V_{IH} = 2 V, I_{OL} = MAX			0.5	V
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 5.5 V			1	mA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V			25	μA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.5 V			−250	μA
I_{CC}	Supply current	V_{CC} = MAX, Chip select(s) at 0 V, Outputs open, See Note 4	TBP18SA030		80	110	mA
			TBP14SA10		100	135	
			TBP18SA22		110	155	
			TBP18SA42, TBP18SA46		120	155	

switching characteristics over recommended ranges of T_A and V_{CC} (unless otherwise noted)

TYPE	TEST CONDITIONS	$t_{a(A)}$ Access time from address			$t_{a(S)}$ Access time from chip select (enable time)			t_{PLH} Propagation delay time, low-to-high-level output from chip select (disable time)			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	MIN	TYP‡	MAX	
TBP18SA030MJ	C_L = 30 pF, R_{L1} = 300 Ω, R_{L2} = 600 Ω, See Page 1-12		25	50		12	30		12	30	ns
TBP18SA030			25	40		12	25		12	25	ns
TBP14SA10MJ			42	75		15	40		15	40	ns
TBP14SA10			42	65		15	35		15	35	ns
TBP18SA22MJ			50	80		20	40		15	35	ns
TBPSA22			50	70		20	35		15	30	ns
TBP18SA42MJ, TBP18SA46MJ			55	85		20	45		15	40	ns
TBP18SA42, TBP18SA46			55	75		20	40		15	35	ns

NOTE: MJ designates full-temperature-range circuits (formerly 54 Family), J and N designate commercial-temperature-range circuits (formerly 74 Family).

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

NOTE 4: The typical values of I_{CC} are with all output low.

SCHOTTKY† PROMS

SERIES 24 AND 28 STANDARD, LOW-POWER, POWER-DOWN, REGISTERED PROGRAMMABLE READ-ONLY MEMORIES

JUNE 1981

- New, Expanded Family of Standard, Low Power, Power Down, And Registered PROMs
- Titanium-Tungsten (Ti-W) Fuse Links for Reliable Low-Voltage Full-Family-Compatible Programming
- Full Decoding And Fast Chip Select Simplify System Design
- P-N-P Inputs for Reduced Loading On System Buffers/Drivers
- Each PROM Supplied With a High Logic Level Stored At Each Bit Location
- Applications Include:
  Microprogramming/Firm Ware Loaders
  Code Converters/Character Generators
  Translators/Emulators
  Address Mapping/Look-Up Tables

STANDARD PROMS

TYPE NUMBER		OUTPUT CONFIGURATION‡	BIT SIZE (ORGANIZATION)	TYPICAL PERFORMANCE		
				ACCESS TIMES		POWER
NEW TYPE NUMBER	OLD TYPE NUMBER			ADDRESS	SELECT	DISSIPATION
TBP24S10 (J, N)▲		▽	1024 Bits (256W X 4B)	35 ns	20 ns	375 mW
TBP24SA10 (J, N)▲		◇				
TBP28S42 (J, N)▲		▽	4096 Bits (512W X 8B)	35 ns	20 ns	500 mW
TBP28SA42		◇				
TBP28S45 (J, N) †▲		▽				
TBP28S46		▽				
TBP28SA46		◇				
TBP24S41 (J, N)▲	SN74S476 (J, N)	▽	4096 Bits (1024W X 4B)	40 ns	20 ns	475 mW
TBP24SA41 (J, N)▲	SN74S477 (J, N)	◇				
TBP24S81 (J, N) ▲	SN74S454 (J, N)	▽	8192 Bits (2048W X 4B)	45 ns	20 ns	625 mW
TBP24SA81 (J, N) ▲	SN74S455 (J, N)	◇				
TBP28S86 (J, N) ▲	SN74S478 (J, N)	▽	8192 Bits (1024W X 8B)	45 ns	20 ns	625 mW
TBP28SA86 (J, N) ▲	SN74S479 (J, N)	◇				
TBP28S2708 (J, N)	SN74S2708 (J, N)	▽				
TBP28S85 (J, N) †▲		▽		35 ns	15 ns	550 mW
TBP28S166 (J, N) ▲		▽	16,384 Bits (2048W X 8B)	35 ns	15 ns	650 mW
TBP28SA166		◇				

LOW POWER PROMS

TYPE NUMBER		OUTPUT CONFIGURATION‡	BIT SIZE (ORGANIZATION)	TYPICAL PERFORMANCE		
				ACCESS TIMES		POWER
NEW TYPE NUMBER	OLD TYPE NUMBER			ADDRESS	SELECT	DISSIPATION
TBP28L22 (J, N)▲		▽	2048 Bits (256W X 8B)	45 ns	20 ns	375 mW
TBP28LA22		◇				
TBP28L42 (J,N) ▲		▽	4096 Bits (512W X 8B)	60 ns	30 ns	250 mW
TBP28L45 (J, N) †▲		▽				
TBP28L46 (J,N) ▲		▽				
TBP28L86 (J, N)▲	SN74LS478 (J, N)	▽	8192 Bits (1024W X 8B)	80 ns	35 ns	350 mW
TBP28L85 (J, N) †▲		▽		65 ns	30 ns	275 mW
TBP28L166 (J, N) †▲		▽	16,384 Bits (2048W X 8B)	65 ns	30 ns	350 mW

All PROMs are also available in chip carriers.

† NOTE — Electrical parameters for these devices are design goals only.

▲ NOTE — These devices available as full-temperature-range and as high-rel processed devices (use suffix MJ or NJ).

‡ ◇ = open collector, ▽ = three state.

Floppy Disk Controller Board (Z-207)

WESTERN DIGITAL
CORPORATION

FD179X-02
FLOPPY DISK FORMATTER/CONTROLLER FAMILY

AUGUST, 1981

FEATURES

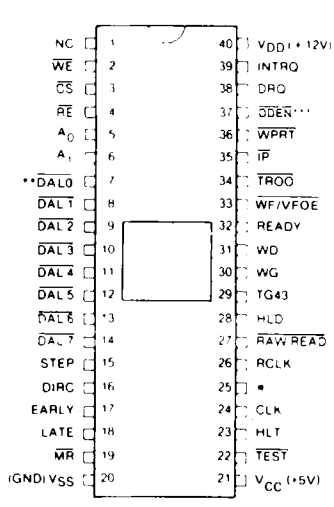
- TWO VFO CONTROL SIGNALS — RG & VFOE
- SOFT SECTOR FORMAT COMPATIBILITY
- AUTOMATIC TRACK SEEK WITH VERIFICATION
- ACCOMMODATES SINGLE AND DOUBLE DENSITY FORMATS
  - IBM 3740 Single Density (FM)
  - IBM System 34 Double Density (MFM)
  - Non IBM Format for Increased Capacity
- READ MODE
  - Single/Multiple Sector Read with Automatic Search or Entire Track Read
  - Selectable 128, 256, 512 or 1024 Byte Sector Lengths
- WRITE MODE
  - Single/Multiple Sector Write with Automatic Sector Search
  - Entire Track Write for Diskette Formatting
- SYSTEM COMPATIBILITY
  - Double Buffering of Data 8 Bit Bi-Directional Bus for Data, Control and Status
  - DMA or Programmed Data Transfers
  - All Inputs and Outputs are TTL Compatible
  - On-Chip Track and Sector Registers/Comprehensive Status Information
- PROGRAMMABLE CONTROLS
  - Selectable Track to Track Stepping Time
  - Side Select Compare
- WRITE PRECOMPENSATION
- WINDOW EXTENSION
- INCORPORATES ENCODING/DECODING AND ADDRESS MARK CIRCUITRY
- FD1792/4 IS SINGLE DENSITY ONLY
- FD1795/7 HAS A SIDE SELECT OUTPUT

179X-02 FAMILY CHARACTERISTICS

FEATURES	1791	1792	1793	1794	1795	1797
Single Density (FM)	X	X	X	X	X	X
Double Density (MFM)	X		X		X	X
True Data Bus			X	X		X
Inverted Data Bus	X	X			X	
Write Precomp	X	X	X	X	X	X
Side Selection Output					X	X

APPLICATIONS

8" FLOPPY AND 5¼" MINI FLOPPY CONTROLLER
SINGLE OR DOUBLE DENSITY
CONTROLLER/FORMATTER



*1791/3 = RG 1795/7 = SSO
**1793/7 TRUE BUS
***1792/4 OPEN

PIN CONNECTIONS

FD179X SYSTEM BLOCK DIAGRAM

PIN OUTS

PIN NUMBER	PIN NAME	SYMBOL	FUNCTION
1	NO CONNECTION	NC	Pin 1 is internally connected to a back bias generator and must be left open by the user.
19	MASTER RESET	$\overline{MR}$	A logic low (50 microseconds min.) on this input resets the device and loads HEX 03 into the command register. The Not Ready (Status Bit 7) is reset during $\overline{MR}$ ACTIVE. When $\overline{MR}$ is brought to a logic high a RESTORE Command is executed, regardless of the state of the Ready signal from the drive. Also, HEX 01 is loaded into sector register.
20	POWER SUPPLIES	V_{SS}	Ground
21		V_{CC}	+5V ±5%
40		V_{DD}	+12V ±5%
COMPUTER INTERFACE:			
2	WRITE ENABLE	$\overline{WE}$	A logic low on this input gates data on the DAL into the selected register when $\overline{CS}$ is low.
3	CHIP SELECT	$\overline{CS}$	A logic low on this input selects the chip and enables computer communication with the device.
4	READ ENABLE	$\overline{RE}$	A logic low on this input controls the placement of data from a selected register on the DAL when $\overline{CS}$ is low.
5,6	REGISTER SELECT LINES	A0, A1	These inputs select the register to receive/transfer data on the DAL lines under $\overline{RE}$ and $\overline{WE}$ control: $\overline{CS}$ A1 A0 $\overline{RE}$ $\overline{WE}$ 0 0 0 Status Reg Command Reg 0 0 1 Track Reg Track Reg 0 1 0 Sector Reg Sector Reg 0 1 1 Data Reg Data Reg
7-14	DATA ACCESS LINES	$\overline{DAL0}$-$\overline{DAL7}$	Eight bit Bidirectional bus used for transfer of data, control, and status. This bus is receiver enabled by $\overline{WE}$ or transmitter enabled by $\overline{RE}$. Each line will drive 1 standard TTL load.
24	CLOCK	CLK	This input requires a free-running 50% duty cycle square wave clock for internal timing reference, 2 MHz ± 1% for 8" drives, 1 MHz ±1% for mini-floppies.
38	DATA REQUEST	DRQ	This open drain output indicates that the DR contains assembled data in Read operations, or the DR is empty in Write operations. This signal is reset when serviced by the computer through reading or loading the DR in Read or Write operations, respectively. Use 10K pull-up resistor to +5.
39	INTERRUPT REQUEST	INTRQ	This open drain output is set at the completion of any command and is reset when the STATUS register is read or the command register is written to. Use 10K pull-up resistor to +5.
FLOPPY DISK INTERFACE:			
15	STEP	STEP	The step output contains a pulse for each step.
16	DIRECTION	DIRC	Direction Output is active high when stepping in, active low when stepping out.
17	EARLY	EARLY	Indicates that the WRITE DATA pulse occuring while Early is active (high) should be shifted early for write precompensation.
18	LATE	LATE	Indicates that the write data pulse occurring while Late is active (high) should be shifted late for write precompensation.

PIN NUMBER	PIN NAME	SYMBOL	FUNCTION
22	$\overline{\text{TEST}}$	$\overline{\text{TEST}}$	This input is used for testing purposes only and should be tied to +5V or left open by the user unless interfacing to voice coil actuated steppers.
23	HEAD LOAD TIMING	HLT	When a logic high is found on the HLT input the head is assumed to be engaged. It is typically derived from a 1 shot triggered by HLD.
25	READ GATE (1791, 1792, 1793, 1794)	RG	This output is used for synchronization of external data separators. The output goes high after two Bytes of zeros in single density, or 4 Bytes of either zeros or ones in double density operation.
25	SIDE SELECT OUTPUT (1795, 1797)	SSO	The logic level of the Side Select Output is directly controlled by the 'S' flag in Type II or III commands. When U = 1, SSO is set to a logic 1. When U = 0, SSO is set to a logic 0. The SSO is compared with the side information in the Sector I.D. Field. If they do not compare Status Bit 4 (RNF) is set. The Side Select Output is only updated at the beginning of a Type II or III command. It is forced to a logic 0 upon a MASTER RESET condition.
26	READ CLOCK	RCLK	A nominal square-wave clock signal derived from the data stream must be provided to this input. Phasing (i.e. RCLK transitions) relative to RAW READ is important but polarity (RCLK high or low) is not.
27	$\overline{\text{RAW READ}}$	$\overline{\text{RAW READ}}$	The data input signal directly from the drive. This input shall be a negative pulse for each recorded flux transition.
28	HEAD LOAD	HLD	The HLD output controls the loading of the Read-Write head against the media.
29	TRACK GREATER THAN 43	TG43	This output informs the drive that the Read/Write head is positioned between tracks 44-76. This output is valid only during Read and Write Commands.
30	WRITE GATE	WG	This output is made valid before writing is to be performed on the diskette.
31	WRITE DATA	WD	A 200 ns (MFM) or 500 ns (FM) output pulse per flux transition. WD contains the unique Address marks as well as data and clock in both FM and MFM formats.
32	READY	READY	This input indicates disk readiness and is sampled for a logic high before Read or Write commands are performed. If Ready is low the Read or Write operation is not performed and an interrupt is generated. Type I operations are performed regardless of the state of Ready. The Ready input appears in inverted format as Status Register bit 7.
33	$\overline{\text{WRITE FAULT}}$ $\overline{\text{VFO ENABLE}}$	$\overline{\text{WF/VFOE}}$	This is a bi-directional signal used to signify writing faults at the drive, and to enable the external PLO data separator. When WG = 1, Pin 33 functions as a WF input. If WF = 0, any write command will immediately be terminated. When WG = 0, Pin 33 functions as a VFOE output. VFOE will go low during a read operation after the head has loaded and settled (HLT = 1). On the 1795/7, it will remain low until the last bit of the second CRC byte in the ID field. VFOE will then go high until 8 bytes (MFM) or 4 bytes (FM) before the Address Mark. It will then go active until the last bit of the second CRC byte of the Data Field. On the 1791/3, VFOE will remain low until the end of the Data Field. This pin has an internal 100K Ohm pull-up resistor.
34	$\overline{\text{TRACK 00}}$	$\overline{\text{TR00}}$	This input informs the FD179X that the Read/Write head is positioned over Track 00.

PIN NUMBER	PIN NAME	SYMBOL	FUNCTION
35	INDEX PULSE	$\overline{IP}$	This input informs the FD179X when the index hole is encountered on the diskette.
36	WRITE PROTECT	$\overline{WPRT}$	This input is sampled whenever a Write Command is received. A logic low terminates the command and sets the Write Protect Status bit.
37	DOUBLE DENSITY	$\overline{DDEN}$	This input pin selects either single or double density operation. When $\overline{DDEN}$ = 0, double density is selected. When $\overline{DDEN}$ = 1, single density is selected. This line must be left open on the 1792/4.

GENERAL DESCRIPTION

The FD179X are N-Channel Silicon Gate MOS LSI devices which perform the functions of a Floppy Disk Formatter/Controller in a single chip implementation. The FD179X, which can be considered the end result of both the FD1771 and FD1781 designs, is IBM 3740 compatible in single density mode (FM) and System 34 compatible in Double Density Mode (MFM). The FD179X contains all the features of its predecessor the FD1771, plus the added features necessary to read/write and format a double density diskette. These include address mark detection, FM and MFM encode and decode logic, window extension, and write precompensation. In order to maintain compatibility, the FD1771, FD1781, and FD179X designs were made as close as possible with the computer interface, instruction set, and I/O registers being identical. Also, head load control is identical. In each case, the actual pin assignments vary by only a few pins from any one to another.

The processor interface consists of an 8-bit bi-directional bus for data, status, and control word transfers. The FD179X is set up to operate on a multiplexed bus with other bus-oriented devices.

The FD179X is TTL compatible on all inputs and outputs. The outputs will drive ONE TTL load or three LS loads. The 1793 is identical to the 1791 except the DAL lines are TRUE for systems that utilize true data busses.

The 1795/7 has a side select output for controlling double sided drives, and the 1792 and 1794 are "Single Density Only" versions of the 1791 and 1793 respectively. On these devices, DDEN must be left open.

ORGANIZATION

The Floppy Disk Formatter block diagram is illustrated on page 5. The primary sections include, the parallel processor interface and the Floppy Disk interface.

Data Shift Register — This 8-bit register assembles serial data from the Read Data input ($\overline{RAW\ READ}$) during Read operations and transfers serial data to the Write Data output during Write operations.

Data Register — This 8-bit register is used as a holding register during Disk Read and Write operations. In Disk Read operations the assembled data byte is transferred in parallel to the Data Register from the Data Shift Register. In Disk Write operations information is transferred in parallel from the Data Register to the Data Shift Register.

When executing the Seek command the Data Register holds the address of the desired Track position. This register is loaded from the DAL and gated onto the DAL under processor control.

Track Register — This 8-bit register holds the track number of the current Read/Write head position. It is incremented by one every time the head is stepped in (towards track 76) and decremented by one when the head is stepped out (towards track 00). The contents of the register are compared with the recorded track number in the ID field during disk Read, Write, and Verify operations. The Track Register can be loaded from or transferred to the DAL. This Register should not be loaded when the device is busy.

Sector Register (SR) — This 8-bit register holds the address of the desired sector position. The contents of the register are compared with the recorded sector number in the ID field during disk Read or Write operations. The Sector Register contents can be loaded from or transferred to the DAL. This register should not be loaded when the device is busy.

Command Register (CR) — This 8-bit register holds the command presently being executed. This register should not be loaded when the device is busy unless the new command is a force interrupt. The command register can be loaded from the DAL, but not read onto the DAL.

Status Register (STR) — This 8-bit register holds device Status information. The meaning of the Status bits is a function of the type of command previously executed. This register can be read onto the DAL, but not loaded from the DAL.

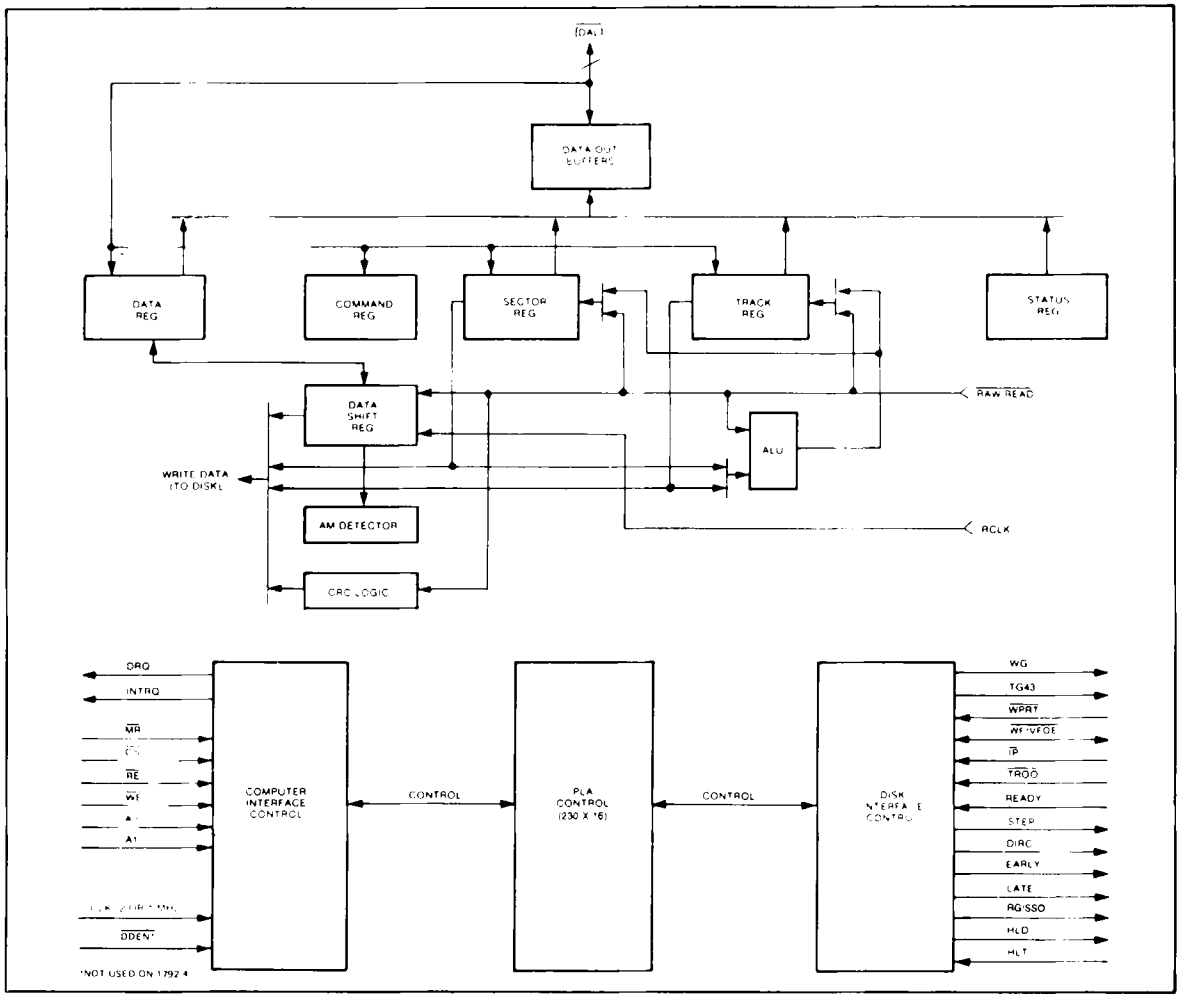
CRC Logic — This logic is used to check or to generate the 16-bit Cyclic Redundancy Check (CRC). The polynomial is: $G(x) = x^{16} + x^{12} + x^5 + 1$.

The CRC includes all information starting with the address mark and up to the CRC characters. The CRC register is preset to ones prior to data being shifted through the circuit.

Arithmetic/Logic Unit (ALU) — The ALU is a serial comparator, incrementer, and decrementer and is used for register modification and comparisons with the disk recorded ID field.

Timing and Control — All computer and Floppy Disk Interface controls are generated through this logic. The internal device timing is generated from an external crystal clock.

The FD179X has two different modes of operation according to the state of $\overline{DDEN}$. When $\overline{DDEN}$ = 0 double density (MFM) is assumed. When $\overline{DDEN}$ = 1, single



FD179X BLOCK DIAGRAM

density (FM) is assumed. 1792 & 1794 are single density only.

AM Detector — The address mark detector detects ID, data and index address marks during read and write operations.

PROCESSOR INTERFACE

The interface to the processor is accomplished through the eight Data Access Lines ($\overline{DAL}$) and associated control signals. The $\overline{DAL}$ are used to transfer Data, Status, and Control words out of, or into the FD179X. The $\overline{DAL}$ are three state buffers that are enabled as output drivers when Chip Select (CS) and Read Enable ($\overline{RE}$) are active (low logic state) or act as input receivers when $\overline{CS}$ and Write Enable ($\overline{WE}$) are active.

When transfer of data with the Floppy Disk Controller is required by the host processor, the device address is decoded and $\overline{CS}$ is made low. The address bits A1 and A0, combined with the signals $\overline{RE}$ during a Read operation or $\overline{WE}$ during a Write operation are interpreted as selecting the following registers:

A1	A0	READ ($\overline{RE}$)	WRITE ($\overline{WE}$)
0	0	Status Register	Command Register
0	1	Track Register	Track Register
1	0	Sector Register	Sector Register
1	1	Data Register	Data Register

During Direct Memory Access (DMA) types of data transfers between the Data Register of the FD179X and the processor, the Data Request (DRQ) output is used in Data Transfer control. This signal also appears as status bit 1 during Read and Write operations.

On Disk Read operations the Data Request is activated (set high) when an assembled serial input byte is transferred in parallel to the Data Register. This bit is cleared when the Data Register is read by the processor. If the Data Register is read after one or more characters are lost, by having new data transferred into the register prior to processor readout, the Lost Data bit is set in the Status Register. The Read operation continues until the end of sector is reached.

On Disk Write operations the data Request is activated when the Data Register transfers its contents to the Data

Shift Register, and requires a new data byte. It is reset when the Data Register is loaded with new data by the processor. If new data is not loaded at the time the next serial byte is required by the Floppy Disk, a byte of zeroes is written on the diskette and the Lost Data bit is set in the Status Register.

At the completion of every command an INTRQ is generated. INTRQ is reset by either reading the status register or by loading the command register with a new command. In addition, INTRQ is generated if a Force Interrupt command condition is met.

The 179X has two modes of operation according to the state of $\overline{DDEN}$ (Pin 37). When $\overline{DDEN}$ = 1, single density is selected. In either case, the CLK input (Pin 24) is at 2 MHz. However, when interfacing with the mini-floppy, the CLK input is set at 1 MHz for both single density and double density.

GENERAL DISK READ OPERATIONS

Sector lengths of 128, 256, 512 or 1024 are obtainable in either FM or MFM formats. For FM, $\overline{DDEN}$ should be placed to logical "1." For MFM formats, $\overline{DDEN}$ should be placed to a logical "0." Sector lengths are determined at format time by the fourth byte in the "ID" field.

Sector Length Table*	
Sector Length Field (hex)	Number of Bytes in Sector (decimal)
00	128
01	256
02	512
03	1024

*1795/97 may vary — see command summary.

The number of sectors per track as far as the FD179X is concerned can be from 1 to 255 sectors. The number of tracks as far as the FD179X is concerned is from 0 to 255 tracks. For IBM 3740 compatibility, sector lengths are 128 bytes with 26 sectors per track. For System 34 compatibility (MFM), sector lengths are 256 bytes/sector with 26 sectors/track; or lengths of 1024 bytes/sector with 8 sectors/track. (See Sector Length Table)

For read operations in 8" double density the FD179X requires $\overline{RAW\ READ}$ Data (Pin 27) signal which is a 200 ns pulse per flux transition and a Read clock (RCLK) signal to indicate flux transition spacings. The RCLK (Pin 26) signal is provided by some drives but if not it may be derived externally by Phase lock loops, one shots, or counter techniques. In addition, a Read Gate Signal is provided as an output (Pin 25) on 1791/92/93/94 which can be used to inform phase lock loops when to acquire synchronization. When reading from the media in FM. RG is made true when 2 bytes of zeroes are detected. The FD179X must find an address mark within the next 10 bytes; otherwise RG is reset and the search for 2 bytes of zeroes begins all over again. If an address mark is found within 10 bytes, RG remains true as long as the FD179X is deriving any useful information from the data stream. Similarly for MFM, RG is made active when 4 bytes of "00" or "FF" are detected. The FD179X must find an address mark within the next 16 bytes, otherwise RG is reset and search resumes.

During read operations (WG = 0), the $\overline{VFOE}$ (Pin 33) is provided for phase lock loop synchronization. $\overline{VFOE}$ will go active low when:

a) Both HLT and HLD are True
b) Settling Time, if programmed, has expired
c) The 179X is inspecting data off the disk

If $\overline{WF}/\overline{VFOE}$ is not used, leave open or tie to a 10K resistor to +5.

GENERAL DISK WRITE OPERATION

When writing is to take place on the diskette the Write Gate (WG) output is activated, allowing current to flow into the Read/Write head. As a precaution to erroneous writing the first data byte must be loaded into the Data Register in response to a Data Request from the FD179X before the Write Gate signal can be activated.

Writing is inhibited when the $\overline{Write\ Protect}$ input is a logic low, in which case any Write command is immediately terminated, an interrupt is generated and the Write Protect status bit is set. The Write Fault input, when activated, signifies a writing fault condition detected in disk drive electronics such as failure to detect write current flow when the Write Gate is activated. On detection of this fault the FD179X terminates the current command, and sets the $\overline{Write\ Fault}$ bit (bit 5) in the Status Word. The $\overline{Write\ Fault}$ input should be made inactive when the Write Gate output becomes inactive.

For write operations, the FD179X provides Write Gate (Pin 30) and Write Data (Pin 31) outputs. Write data consists of a series of 500 ns pulses in FM ($\overline{DDEN}$ = 1) and 200 ns pulses in MFM ($\overline{DDEN}$ = 0). Write Data provides the unique address marks in both formats.

Also during write, two additional signals are provided for write precompensation. These are EARLY (Pin 17) and LATE (Pin 18). EARLY is active true when the WD pulse appearing on (Pin 30) is to be written EARLY. LATE is active true when the WD pulse is to be written LATE. If both EARLY and LATE are low when the WD pulse is present, the WD pulse is to be written at nominal. Since write precompensation values vary from disk manufacturer to disk manufacturer, the actual value is determined by several one shots or delay lines which are located external to the FD179X. The write precompensation signals EARLY and LATE are valid for the duration of WD in both FM and MFM formats.

READY

Whenever a Read or Write command (Type II or III) is received the FD179X samples the Ready input. If this input is logic low the command is not executed and an interrupt is generated. All Type I commands are performed regardless of the state of the Ready input. Also, whenever a Type II or III command is received, the TG43 signal output is updated.

COMMAND DESCRIPTION

The FD179X will accept eleven commands. Command words should only be loaded in the Command Register when the Busy status bit is off (Status bit 0). The one exception is the Force Interrupt command. Whenever a command is being executed, the Busy status bit is set. When a command is completed, an interrupt is generated and the Busy status bit is reset. The Status Register indicates whether the completed command encountered an error or was fault free. For ease of discussion, commands are divided into four types. Commands and types are summarized in Table 1.

TABLE 1. COMMAND SUMMARY

A. Commands for Models: 1791, 1792, 1793, 1794

Type	Command	Bits 7	6	5	4	3	2	1	0
I	Restore	0	0	0	0	h	V	r_1	r_0
I	Seek	0	0	0	1	h	V	r_1	r_0
I	Step	0	0	1	T	h	V	r_1	r_0
I	Step-in	0	1	0	T	h	V	r_1	r_0
I	Step-out	0	1	1	T	h	V	r_1	r_0
II	Read Sector	1	0	0	m	S	E	C	0
II	Write Sector	1	0	1	m	S	E	C	a_0
III	Read Address	1	1	0	0	0	E	0	0
III	Read Track	1	1	1	0	0	E	0	0
III	Write Track	1	1	1	1	0	E	0	0
IV	Force Interrupt	1	1	0	I_1	I_3	I_2	I_1	I_0

B. Commands for Models: 1795, 1797

Type	Command	Bits 7	6	5	4	3	2	1	0
I	Restore	0	0	0	0	h	V	r_1	r_0
I	Seek	0	0	0	1	h	V	r_1	r_0
I	Step	0	0	1	T	h	V	r_1	r_0
I	Step-in	0	1	0	T	h	V	r_1	r_0
I	Step-out	0	1	1	T	h	V	r_1	r_0
II	Read Sector	1	0	0	m	L	E	U	0
II	Write Sector	1	0	1	m	L	E	U	a_0
III	Read Address	1	1	0	0	0	E	U	0
III	Read Track	1	1	1	0	0	E	U	0
III	Write Track	1	1	1	1	0	E	U	0
IV	Force Interrupt	1	1	0	1	I_3	I_2	I_1	I_0

TABLE 2. FLAG SUMMARY

FLAG SUMMARY

Command Type	Bit No(s)		Description
I	0, 1	r_1 r_0 = Stepping Motor Rate See Table 3 for Rate Summary	
I	2	V = Track Number Verify Flag	V = 0, No verify V = 1, Verify on destination track
I	3	h = Head Load Flag	h = 0, Load head at beginning h = 1, Unload head at beginning
I	4	T = Track Update Flag	T = 0, No update T = 1, Update track register
II & III	0	a_0 = Data Address Mark	a_0 = 0, FB (DAM) a_0 = 1, F8 (deleted DAM)
II	1	C = Side Compare Flag	C = 0, Disable side compare C = 1, Enable side compare
II & III	1	U = Update SSO	U = 0, Update SSO to 0 U = 1, Update SSO to 1
II & III	2	E = 15 MS Delay	E = 0, No 15 MS delay E = 1, 15 MS delay
II	3	S = Side Compare Flag	S = 0, Compare for side 0 S = 1, Compare for side 1
II	3	L = Sector Length Flag	
II	4	m = Multiple Record Flag	m = 0, Single record m = 1, Multiple records
IV	0-3	I_x = Interrupt Condition Flags I_0 = 1 Not Ready To Ready Transition I_1 = 1 Ready To Not Ready Transition I_2 = 1 Index Pulse I_3 = 1 Immediate Interrupt, Requires A Reset I_3-I_1 = 0 Terminate With No Interrupt (INTRQ)	

	LSB's Sector Length in ID Field 00	01	10	11
L = 0	256	512	1024	128
L = 1	128	256	512	1024

*NOTE: See Type IV Command Description for further information.

TYPE I COMMANDS

The Type I Commands include the Restore, Seek, Step, Step-In, and Step-Out commands. Each of the Type I Commands contains a rate field (r0 r1), which determines the stepping motor rate as defined in Table 3.

A 2 μs (MFM) or 4 μs (FM) pulse is provided as an output to the drive. For every step pulse issued, the drive moves one track location in a direction determined by the direction output. The chip will step the drive in the same direction it last stepped unless the command changes the direction.

The Direction signal is active high when stepping in and low when stepping out. The Direction signal is valid 12 μs before the first stepping pulse is generated.

The rates (shown in Table 3) can be applied to a Step-Direction Motor through the device interface.

TABLE 3. STEPPING RATES

CLK	2 MHz	2 MHz	1 MHz	1 MHz	2 MHz	1 MHz
$\overline{DDEN}$	0	1	0	1	x	x
R1 R0	$\overline{TEST}$-1	$\overline{TEST}$-1	$\overline{TEST}$-1	$\overline{TEST}$=1	$\overline{TEST}$=0	$\overline{TEST}$-0
0 0	3 ms	3 ms	6 ms	6 ms	184μs	368μs
0 1	6 ms	6 ms	12 ms	12 ms	190μs	380μs
1 0	10 ms	10 ms	20 ms	20 ms	198μs	396μs
1 1	15 ms	15 ms	30 ms	30 ms	208μs	416μs

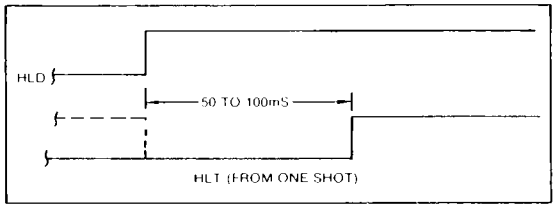
After the last directional step an additional 15 milliseconds of head settling time takes place if the Verify flag is set in Type I commands. Note that this time doubles to 30 ms for a 1 MHz clock. If $\overline{TEST}$ = 0, there is zero settling time. There is also a 15 ms head settling time if the E flag is set in any Type II or III command.

When a Seek, Step or Restore command is executed an optional verification of Read-Write head position can be performed by settling bit 2 (V = 1) in the command word to a logic 1. The verification operation begins at the end of the 15 millisecond settling time after the head is loaded against the media. The track number from the first encountered ID Field is compared against the contents of the Track Register. If the track numbers compare and the ID Field Cyclic Redundancy Check (CRC) is correct, the verify operation is complete and an INTRQ is generated with no errors. If there is a match but not a valid CRC, the CRC error status bit is set (Status bit 3), and the next encountered ID field is read from the disk for the verification operation.

The FD179X must find an ID field with correct track number and correct CRC within 5 revolutions of the media; otherwise the seek error is set and an INTRQ is generated. If V = 0, no verification is performed.

The Head Load (HLD) output controls the movement of the read/write head against the media. HLD is activated at the beginning of a Type I command if the h flag is set (h = 1), at the end of the Type I command if the verify flag (V = 1), or upon receipt of any Type II or III command. Once HLD is active it remains active until either a Type I command is received with (h = 0 and V = 0); or if the FD179X is in an idle state (non-busy) and 15 index pulses have occurred.

Head Load timing (HLT) is an input to the FD179X which is used for the head engage time. When HLT = 1, the FD179X assumes the head is completely engaged. The head engage time is typically 30 to 100 ms depending on drive. The low to high transition on HLD is typically used to fire a one shot. The output of the one shot is then used for HLT and supplied as an input to the FD179X.



HEAD LOAD TIMING

When both HLD and HLT are true, the FD179X will then read from or write to the media. The "and" of HLD and HLT appears as status Bit 5 in Type I status.

In summary for the Type I commands: if h = 0 and V = 0, HLD is reset. If h = 1 and V = 0, HLD is set at the beginning of the command and HLT is not sampled nor is there an internal 15 ms delay. If h = 0 and V = 1, HLD is set near the end of the command, an internal 15 ms occurs, and the FD179X waits for HLT to be true. If h = 1 and V = 1, HLD is set at the beginning of the command. Near the end of the command, after all the steps have been issued, an internal 15 ms delay occurs and the FD179X then waits for HLT to occur.

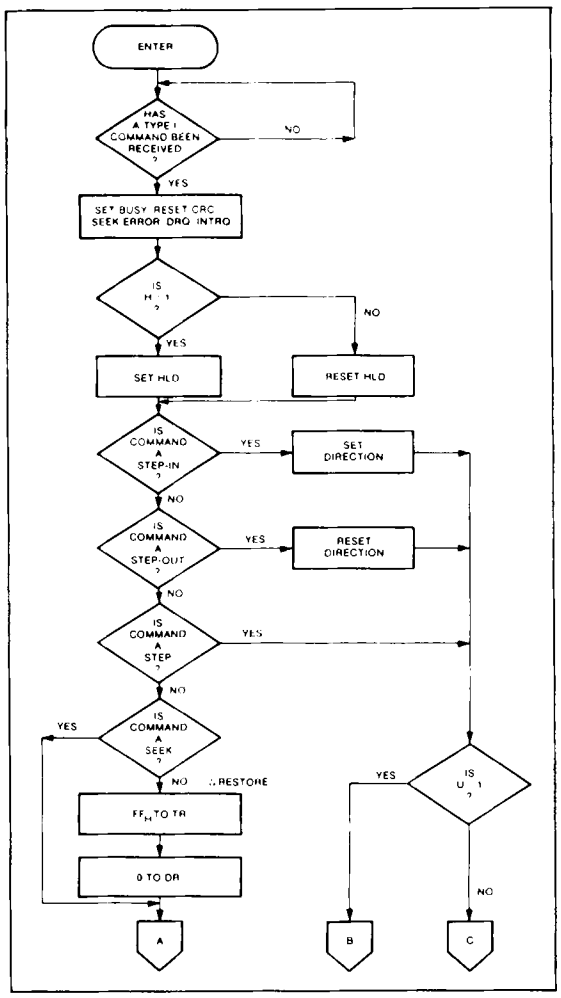
For Type II and III commands with E flag off, HLD is made active and HLT is sampled until true. With E flag on, HLD is made active, an internal 15 ms delay occurs and then HLT is sampled until true.

RESTORE (SEEK TRACK 0)

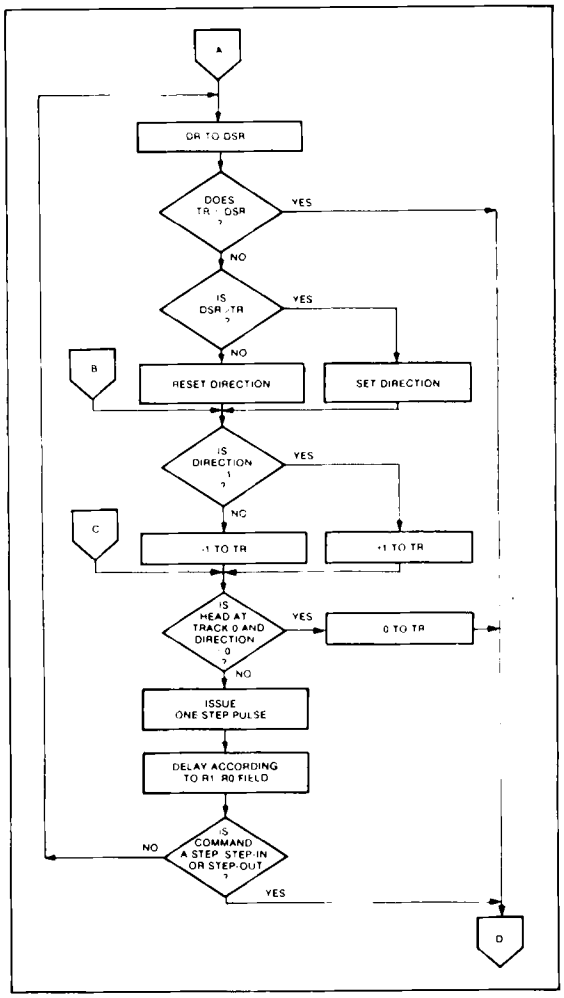
Upon receipt of this command the Track 00 ($\overline{TR00}$) input is sampled. If $\overline{TR00}$ is active low indicating the Read-Write head is positioned over track 0, the Track Register is loaded with zeroes and an interrupt is generated. If $\overline{TR00}$ is not active low, stepping pulses (pins 15 to 16) at a rate specified by the r1 r0 field are issued until the $\overline{TR00}$ input is activated. At this time the Track Register is loaded with zeroes and an interrupt is generated. If the $\overline{TR00}$ input does not go active low after 255 stepping pulses, the FD179X terminates operation, interrupts, and sets the Seek error status bit. A verification operation takes place if the V flag is set. The h bit allows the head to be loaded at the start of command. Note that the Restore command is executed when $\overline{MR}$ goes from an active to an inactive state and that the DRQ pin stays low.

SEEK

This command assumes that the Track Register contains the track number of the current position of the Read-Write head and the Data Register contains the desired track number. The FD179X will update the Track register and issue stepping pulses in the appropriate direction until the contents of the Track register are equal to the contents of



TYPE I COMMAND FLOW



TYPE I COMMAND FLOW

the Data Register (the desired track location). A verification operation takes place if the V flag is on. The h bit allows the head to be loaded at the start of the command. An interrupt is generated at the completion of the command. Note: When using multiple drives, the track register must be updated for the drive selected before seeks are issued.

STEP

Upon receipt of this command, the FD179X issues one stepping pulse to the disk drive. The stepping motor direction is the same as in the previous step command. After a delay determined by the r1r0 field, a verification takes place if the V flag is on. If the U flag is on, the Track Register is updated. The h bit allows the head to be loaded at the start of the command. An interrupt is generated at the completion of the command.

STEP-IN

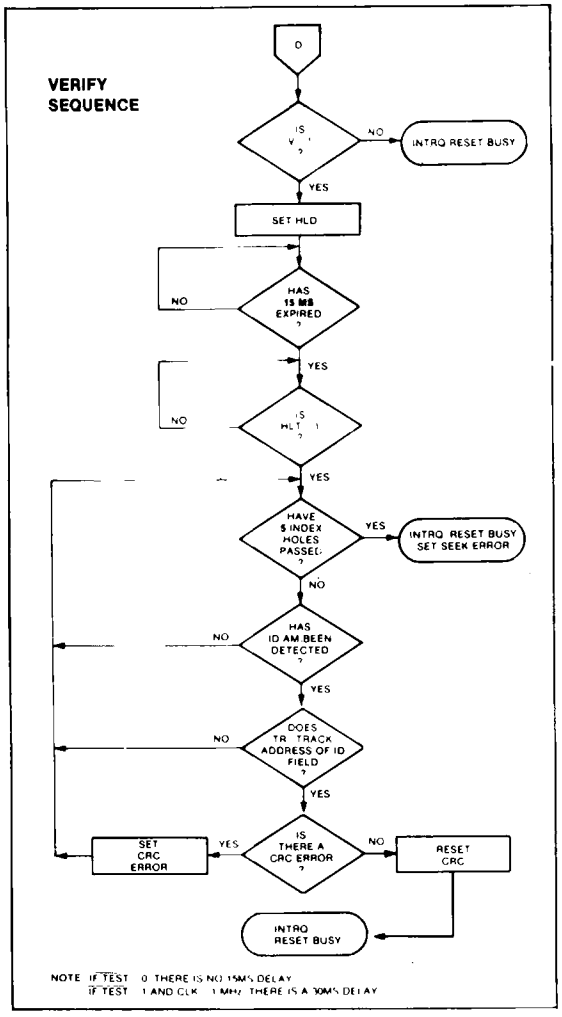
Upon receipt of this command, the FD179X issues one stepping pulse in the direction towards track 76. If the U flag is on, the Track Register is incremented by one. After a delay determined by the r1r0 field, a verification takes place if the V flag is on. The h bit allows the head to be loaded at the start of the command. An interrupt is generated at the completion of the command.

STEP-OUT

Upon receipt of this command, the FD179X issues one stepping pulse in the direction towards track 0. If the U flag is on, the Track Register is decremented by one. After a delay determined by the r1r0 field, a verification takes place if the V flag is on. The h bit allows the head to be loaded at the start of the command. An interrupt is generated at the completion of the command.

EXCEPTIONS

On the 1795/7 devices, the SSO output is not affected during Type 1 commands, and an internal side compare does not take place when the (V) Verify Flag is on.

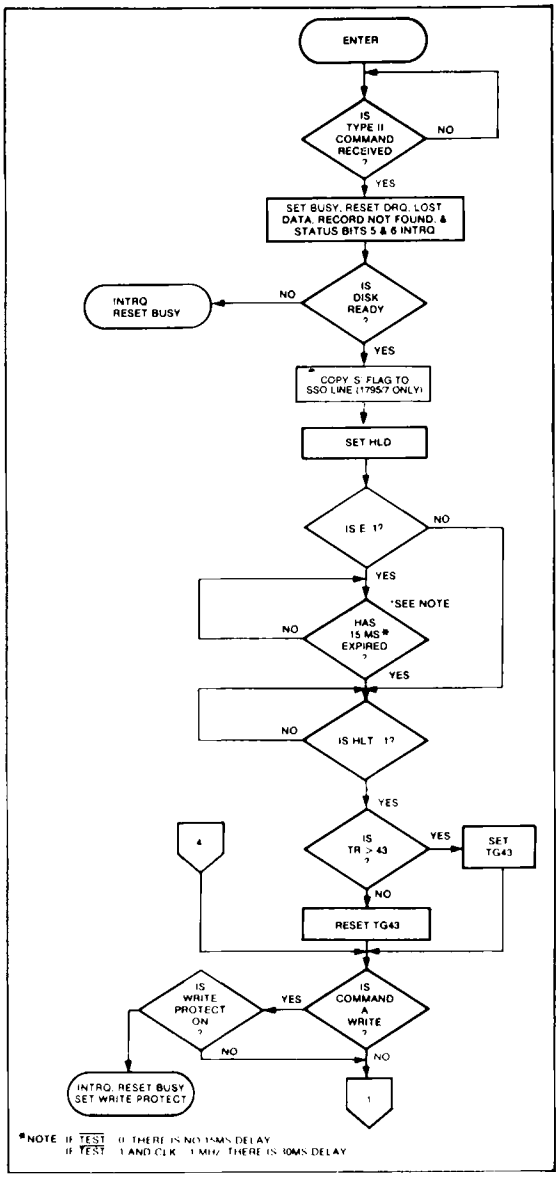


TYPE I COMMAND FLOW

TYPE II COMMANDS

The Type II Commands are the Read Sector and Write Sector commands. Prior to loading the Type II Command into the Command Register, the computer must load the Sector Register with the desired sector number. Upon receipt of the Type II command, the busy status Bit is set. If the E flag = 1 (this is the normal case) HLD is made active and HLT is sampled after a 15 msec delay. If the E flag is 0, the head is loaded and HLT sampled with no 15 msec delay. The ID field and Data Field format are shown on page 13.

When an ID field is located on the disk, the FD179X compares the Track Number on the ID field with the Track Register. If there is not a match, the next encountered ID field is read and a comparison is again made. If there was a match, the Sector Number of the ID field is compared with the Sector Register. If there is not a Sector match, the next encountered ID field is read off the disk and comparisons again made. If the ID field CRC is correct, the data field is then located and will be either written into, or read from depending upon the command. The FD179X must find an ID field with a Track number, Sector number, side number, and CRC within four revolutions of the disk; otherwise, the Record not found status bit is set (Status bit 3) and the command is terminated with an interrupt.



TYPE II COMMAND

Each of the Type II Commands contains an (m) flag which determines if multiple records (sectors) are to be read or written, depending upon the command. If m = 0, a single sector is read or written and an interrupt is generated at the

completion of the command. If m = 1, multiple records are read or written with the sector register internally updated so that an address verification can occur on the next record. The FD179X will continue to read or write multiple records and update the sector register in numerical ascending sequence until the sector register exceeds the number of sectors on the track or until the Force Interrupt command is loaded into the Command Register, which terminates the command and generates an interrupt.

For example: If the FD179X is instructed to read sector 27 and there are only 26 on the track, the sector register exceeds the number available. The FD179X will search for 5 disk revolutions, interrupt out, reset busy, and set the record not found status bit.

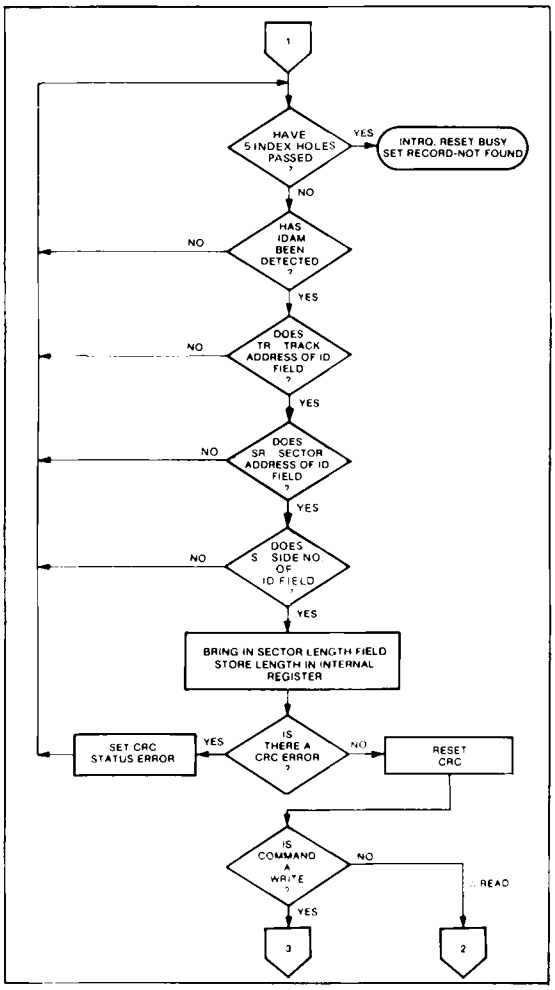
The Type II commands for 1791-94 also contain side select compare flags. When C = 0 (Bit 1) no side comparison is made. When C = 1, the LSB of the side number is read off the ID Field of the disk and compared with the contents of the (S) flag (Bit 3). If the S flag compares with the side number recorded in the ID field, the FD179X continues with the ID search. If a comparison is not made within 5 index pulses, the interrupt line is made active and the Record-Not-Found status bit is set.

The Type II and III commands for the 1795-97 contain a side select flag (Bit 1). When U = 0, SSO is updated to 0. Similarly, U = 1 updates SSO to 1. The chip compares the SSO to the ID field. If they do not compare within 5 revolutions the interrupt line is made active and the RNF status bit is set.

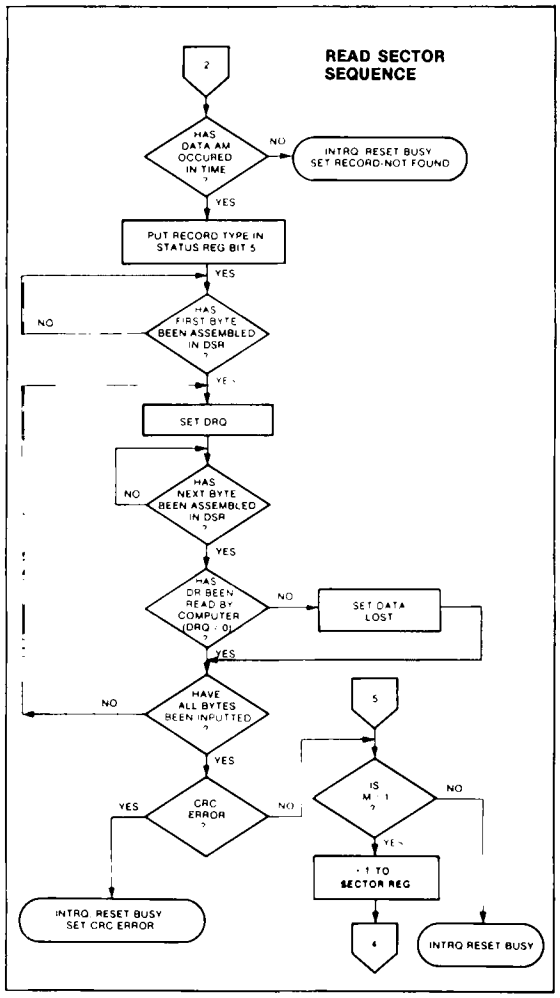
The 1795/7 READ SECTOR and WRITE SECTOR commands include a 'L' flag. The 'L' flag, in conjunction with the sector length byte of the ID Field, allows different byte lengths to be implemented in each sector. For IBM compatability, the 'L' flag should be set to a one.

READ SECTOR

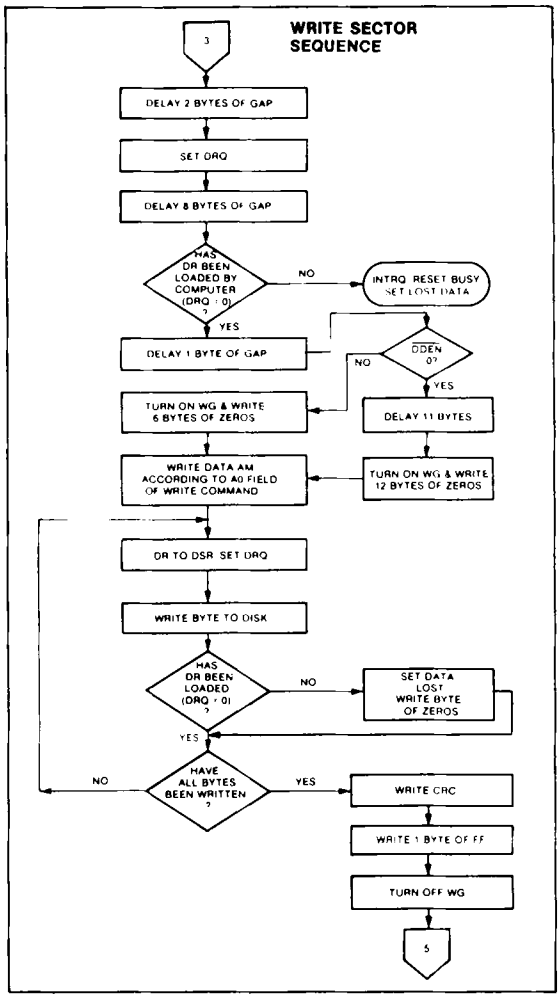
Upon receipt of the Read Sector command, the head is loaded, the Busy status bit set, and when an ID field is encountered that has the correct track number, correct sector number, correct side number, and correct CRC, the data field is presented to the computer. The Data Address



TYPE II COMMAND



TYPE II COMMAND



TYPE II COMMAND

Mark of the data field must be found within 30 bytes in single density and 43 bytes in double density of the last ID field CRC byte; if not, the Record Not Found status bit is set and the operation is terminated.

When the first character or byte of the data field has been shifted through the DSR, it is transferred to the DR, and DRQ is generated. When the next byte is accumulated in the DSR, it is transferred to the DR and another DRQ is generated. If the Computer has not read the previous contents of the DR before a new character is transferred that character is lost and the Lost Data Status bit is set. This sequence continues until the complete data field has been inputted to the computer. If there is a CRC error at the end of the data field, the CRC error status bit is set, and the command is terminated (even if it is a multiple record command).

At the end of the Read operation, the type of Data Address Mark encountered in the data field is recorded in the Status Register (Bit 5) as shown :

STATUS BIT 5	
1	Deleted Data Mark
0	Data Mark

WRITE SECTOR

Upon receipt of the Write Sector command, the head is loaded (HLD active) and the Busy status bit is set. When an ID field is encountered that has the correct track number, correct sector number, correct side number, and correct CRC, a DRQ is generated. The FD179X counts off 11 bytes in single density and 22 bytes in double density from the CRC field and the Write Gate (WG) output is made active if the DRQ is serviced (i.e., the DR has been loaded by the computer). If DRQ has not been serviced, the command is terminated and the Lost Data status bit is set. If the DRQ has been serviced, the WG is made active and six bytes of zeroes in single density and 12 bytes in double density are then written on the disk. At this time the Data Address Mark is then written on the disk as determined by the a_0 field of the command as shown below:

a_0	Data Address Mark (Bit 0)
1	Deleted Data Mark
0	Data Mark

The FD179X then writes the data field and generates DRQ's to the computer. If the DRQ is not serviced in time for continuous writing the Lost Data Status Bit is set and a byte of zeroes is written on the disk. The command is not terminated. After the last data byte has been written on the disk, the two-byte CRC is computed internally and written on the disk followed by one byte of logic ones in FM or in MFM. The WG output is then deactivated. For a 2 MHz clock the INTRQ will set 8 to 12 μsec after the last CRC byte is written. For partial sector writing, the proper method is to write the data and fill the balance with zeroes. By letting the chip fill the zeroes, errors may be masked by the lost data status and improper CRC Bytes.

TYPE III COMMANDS

READ ADDRESS

Upon receipt of the Read Address command, the head is loaded and the Busy Status Bit is set. The next encountered ID field is then read in from the disk, and the six data bytes of the ID field are assembled and transferred to the DR, and a DRQ is generated for each byte. The six bytes of the ID field are shown below:

TRACK ADDR	SIDE NUMBER	SECTOR ADDRESS	SECTOR LENGTH	CRC 1	CRC 2
1	2	3	4	5	6

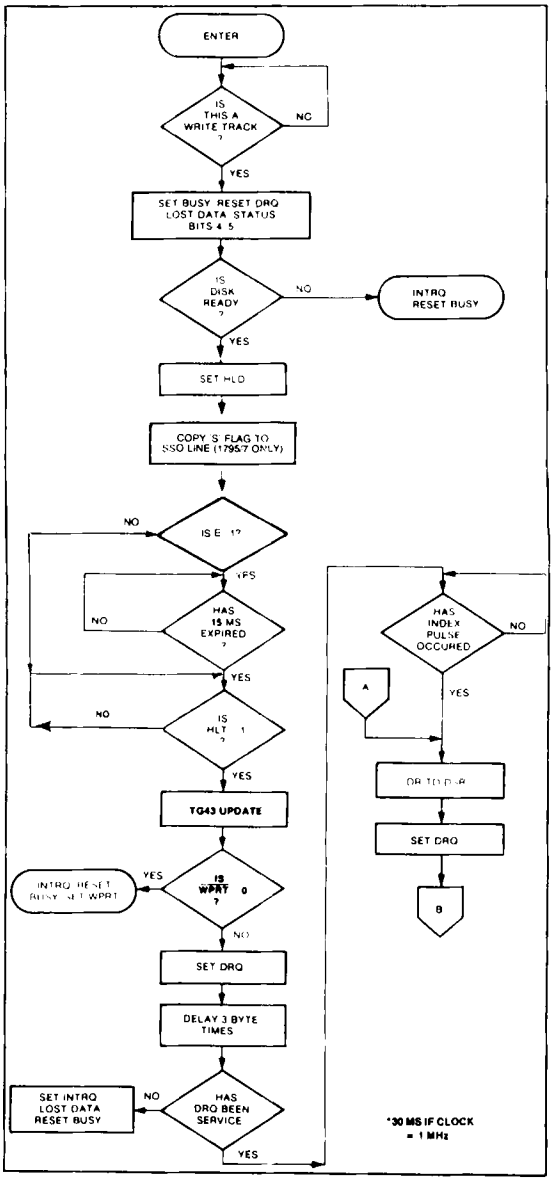
Although the CRC characters are transferred to the computer, the FD179X checks for validity and the CRC error status bit is set if there is a CRC error. The Track Address of the ID field is written into the sector register so that a comparison can be made by the user. At the end of the operation an interrupt is generated and the Busy Status is reset.

READ TRACK

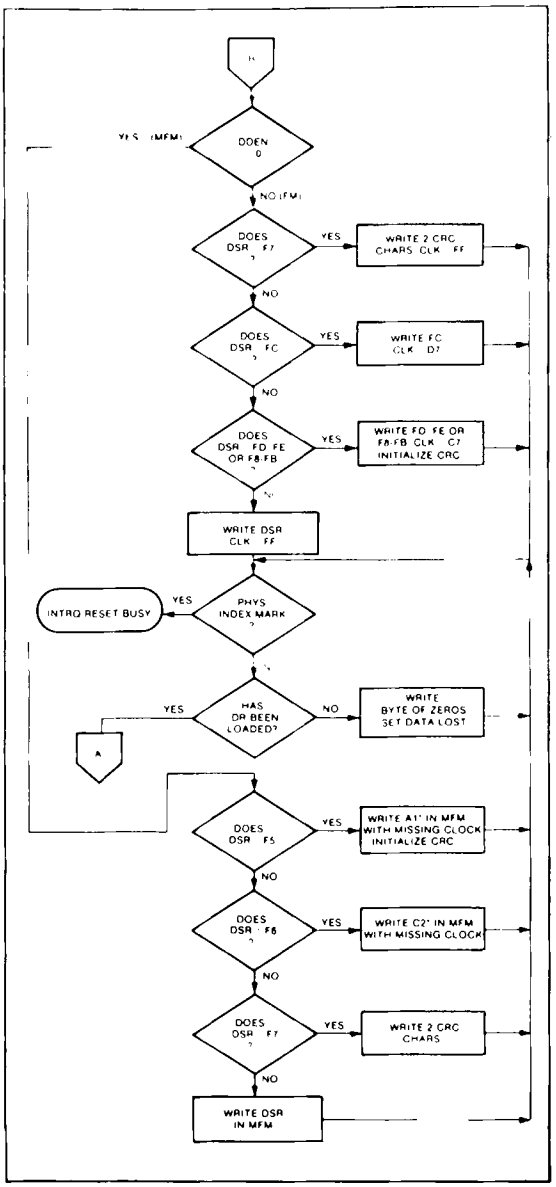
Upon receipt of the READ track command, the head is loaded, and the Busy Status bit is set. Reading starts with the leading edge of the first encountered index pulse and continues until the next index pulse. All Gap, Header, and data bytes are assembled and transferred to the data register and DRQ's are generated for each byte. The accumulation of bytes is synchronized to each address mark encountered. An interrupt is generated at the completion of the command.

This command has several characteristics which make it suitable for diagnostic purposes. They are: the Read Gate is not activated during the command; no CRC checking is performed; gap information is included in the data stream; the internal side compare is not performed; and the address mark detector is on for the duration of the command. Because the A.M. detector is always on, write splices or noise may cause the chip to look for an A.M. If an address mark does not appear on schedule the Lost Data status flag is set.

The ID A.M., ID field, ID CRC bytes, DAM, Data, and Data CRC Bytes for each sector will be correct. The Gap Bytes may be read incorrectly during write-splice time because of synchronization.



TYPE III COMMAND WRITE TRACK



TYPE III COMMAND WRITE TRACK

CONTROL BYTES FOR INITIALIZATION

DATA PATTERN IN DR (HEX)	FD179X INTERPRETATION IN FM ($\overline{DDEN}$ = 1)	FD1791/3 INTERPRETATION IN MFM ($\overline{DDEN}$ = 0)
00 thru F4	Write 00 thru F4 with CLK = FF	Write 00 thru F4, in MFM
F5	Not Allowed	Write A1* in MFM, Preset CRC
F6	Not Allowed	Write C2** in MFM
F7	Generate 2 CRC bytes	Generate 2 CRC bytes
F8 thru FB	Write F8 thru FB, Clk = C7, Preset CRC	Write F8 thru FB, in MFM
FC	Write FC with Clk = D7	Write FC in MFM
FD	Write FD with Clk = FF	Write FD in MFM
FE	Write FE, Clk = C7, Preset CRC	Write FE in MFM
FF	Write FF with Clk = FF	Write FF in MFM

*Missing clock transition between bits 4 and 5

**Missing clock transition between bits 3 & 4

WRITE TRACK FORMATTING THE DISK

(Refer to section on Type III commands for flow diagrams.)

Formatting the disk is a relatively simple task when operating programmed I/O or when operating under DMA with a large amount of memory. Data and gap information must be provided at the computer interface. Formatting the disk is accomplished by positioning the R/W head over the desired track number and issuing the Write Track command.

Upon receipt of the Write Track command, the head is loaded and the Busy Status bit is set. Writing starts with the leading edge of the first encountered index pulse and continues until the next index pulse, at which time the interrupt is activated. The Data Request is activated immediately upon receiving the command, but writing will not start until after the first byte has been loaded into the Data Register. If the DR has not been loaded by the time the index pulse is encountered the operation is terminated making the device Not Busy, the Lost Data Status Bit is set, and the Interrupt is activated. If a byte is not present in the DR when needed, a byte of zeroes is substituted.

This sequence continues from one index mark to the next index mark. Normally, whatever data pattern appears in the data register is written on the disk with a normal clock pattern. However, if the FD179X detects a data pattern of F5 thru FE in the data register, this is interpreted as data address marks with missing clocks or CRC generation.

The CRC generator is initialized when any data byte from F8 to FE is about to be transferred from the DR to the DSR in FM or by receipt of F5 in MFM. An F7 pattern will generate two CRC characters in FM or MFM. As a consequence, the patterns F5 thru FE must not appear in the gaps, data fields, or ID fields. Also, CRC's must be generated by an F7 pattern.

Disks may be formatted in IBM 3740 or System 34 formats with sector lengths of 128, 256, 512, or 1024 bytes.

TYPE IV COMMANDS

The Forced Interrupt command is generally used to terminate a multiple sector read or write command or to insure Type I status in the status register. This command can be loaded into the command register at any time. If there is a current command under execution (busy status bit set) the command will be terminated and the busy status bit reset.

The lower four bits of the command determine the conditional interrupt as follows:

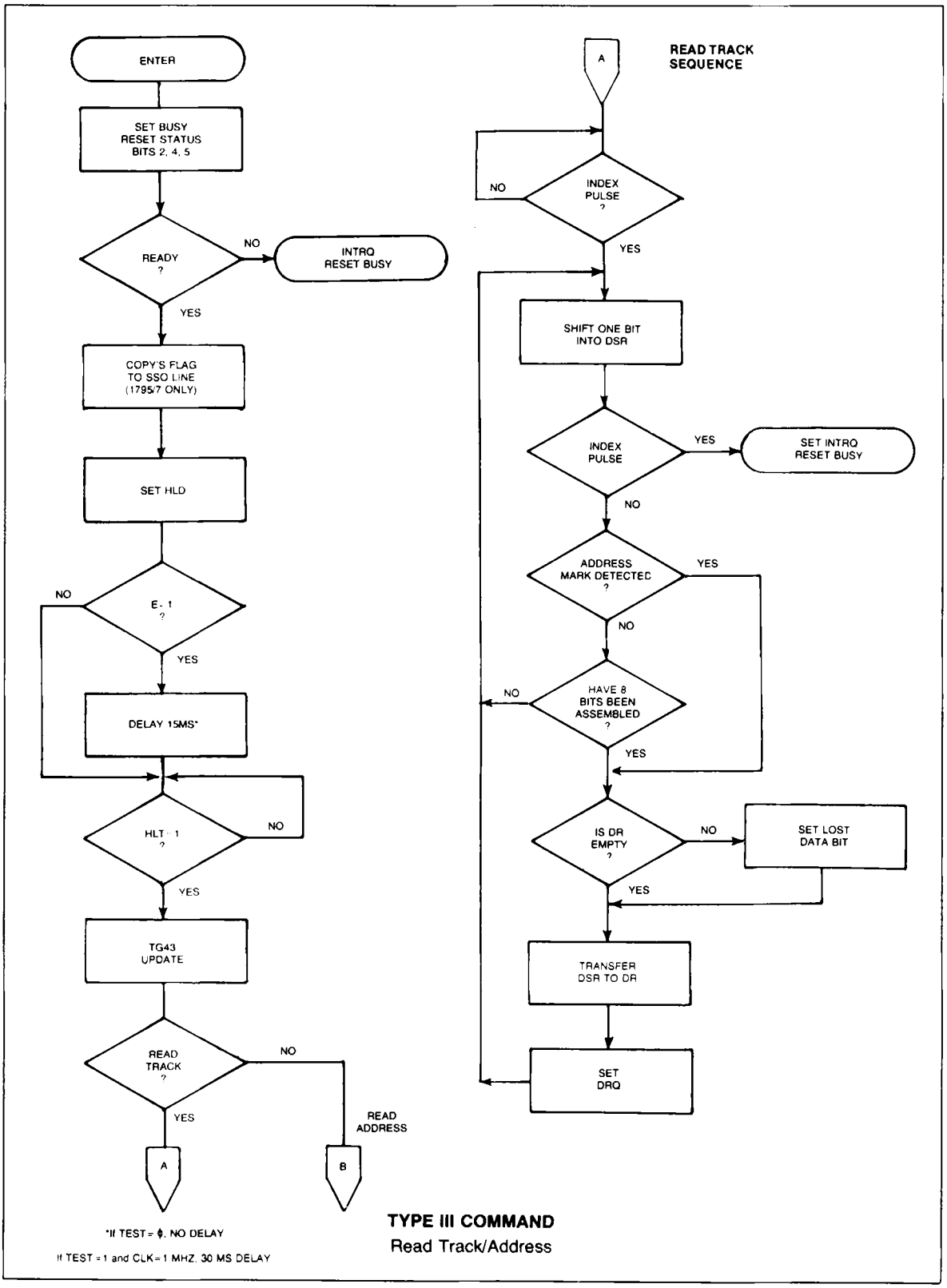
I_0 = Not-Ready to Ready Transition
I_1 = Ready to Not-Ready Transition
I_2 = Every Index Pulse
I_3 = Immediate Interrupt

The conditional interrupt is enabled when the corresponding bit positions of the command (I_3 - I_0) are set to a 1. Then, when the condition for interrupt is met, the INTRQ line will go high signifying that the condition specified has occurred. If I_3 - I_0 are all set to zero (HEX D0), no interrupt will occur but any command presently under execution will be immediately terminated. When using the immediate interrupt condition (I_3 = 1) an interrupt will be immediately generated and the current command terminated. Reading the status or writing to the command register will not automatically clear the interrupt. The HEX D0 is the only command that will enable the immediate interrupt (HEX D8) to clear on a subsequent load command register or read status register operation. Follow a HEX D8 with D0 command.

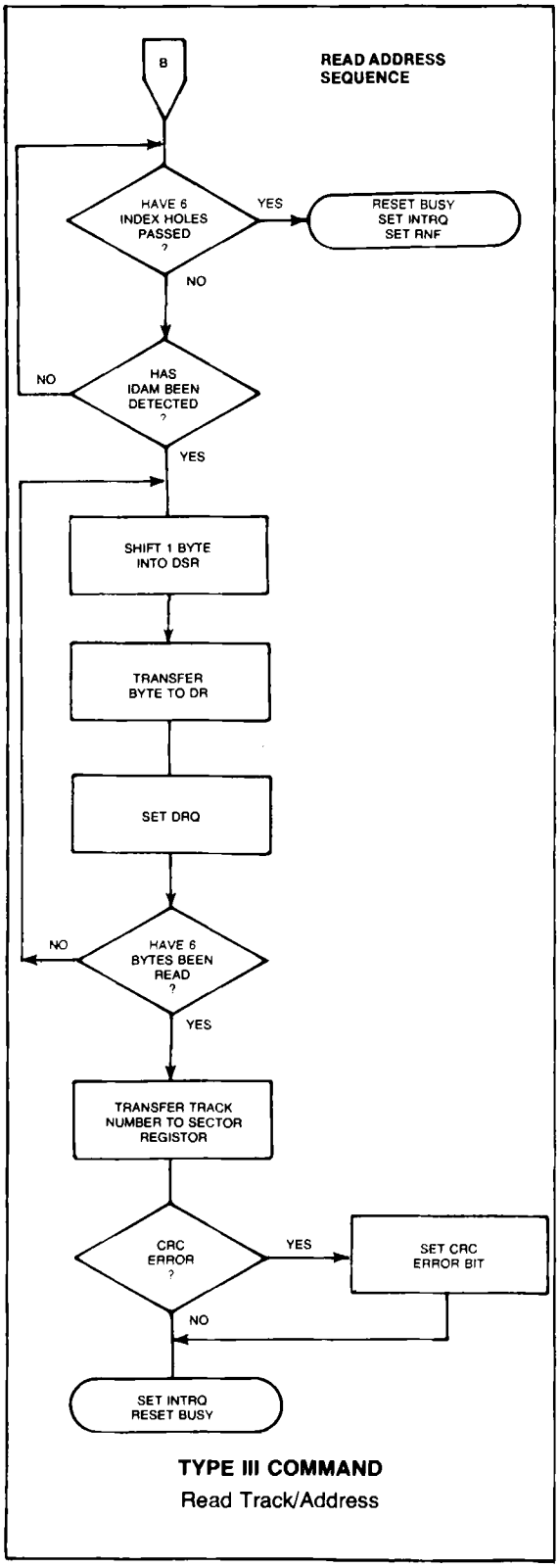
Wait 8 micro sec (double density) or 16 micro sec (single density before issuing a new command after issuing a forced interrupt (times double when clock = 1 MHz). Loading a new command sooner than this will nullify the forced interrupt.

Forced interrupt stops any command at the end of an internal micro-instruction and generates INTRQ when the specified condition is met. Forced interrupt will wait until ALU operations in progress are complete (CRC calculations, compares, etc.).

More than one condition may be set at a time. If for example, the READY TO NOT-READY condition (I_1 = 1) and the Every Index Pulse (I_2 = 1) are both set, the resultant command would be HEX "DA". The "OR" function is performed so that either a READY TO NOT- READY or the next Index Pulse will cause an interrupt condition.



TYPE III COMMAND
Read Track/Address



TYPE III COMMAND
Read Track/Address

STATUS REGISTER

Upon receipt of any command, except the Force Interrupt command, the Busy Status bit is set and the rest of the status bits are updated or cleared for the new command. If the Force Interrupt Command is received when there is a current command under execution, the Busy status bit is reset, and the rest of the status bits are unchanged. If the Force Interrupt command is received when there is not a current command under execution, the Busy Status bit is reset and the rest of the status bits are updated or cleared. In this case, Status reflects the Type I commands.

The user has the option of reading the status register through program control or using the DRQ line with DMA or interrupt methods. When the Data register is read the DRQ bit in the status register and the DRQ line are automatically reset. A write to the Data register also causes both DRQ's to reset.

The busy bit in the status may be monitored with a user program to determine when a command is complete, in lieu of using the INTRQ line. When using the INTRQ, a busy status check is not recommended because a read of the status register to determine the condition of busy will reset the INTRQ line.

The format of the Status Register is shown below:

(BITS)							
7	6	5	4	3	2	1	0
S7	S6	S5	S4	S3	S2	S1	S0

Status varies according to the type of command executed as shown in Table 4.

Because of internal sync cycles, certain time delays must be observed when operating under programmed I/O. They are: (times double when clock = 1 MHz)

Operation	Next Operation	Delay Req'd. FM	MFM
Write to Command Reg.	Read Busy Bit (Status Bit 0)	12 μs	6 μs
Write to Command Reg.	Read Status Bits 1-7	28 μs	14 μs
Write Any Register	Read From Diff. Register	0	0

IBM 3740 FORMAT — 128 BYTES/SECTOR

Shown below is the IBM single-density format with 128 bytes/sector. In order to format a diskette, the user must issue the Write Track command, and load the data register with the following values. For every byte to be written, there is one Data Request.

NUMBER OF BYTES	HEX VALUE OF BYTE WRITTEN
40	FF (or 00)'
6	00
1	FC (Index Mark)
* 26	FF (or 00)'
6	00
1	FE (ID Address Mark)
1	Track Number
1	Side Number (00 or 01)
1	Sector Number (1 thru 1A)
1	00 (Sector Length)
1	F7 (2 CRC's written)
11	FF (or 00)'
6	00
1	FB (Data Address Mark)
128	Data (IBM uses E5)
1	F7 (2 CRC's written)
27	FF (or 00)'
247**	FF (or 00)'

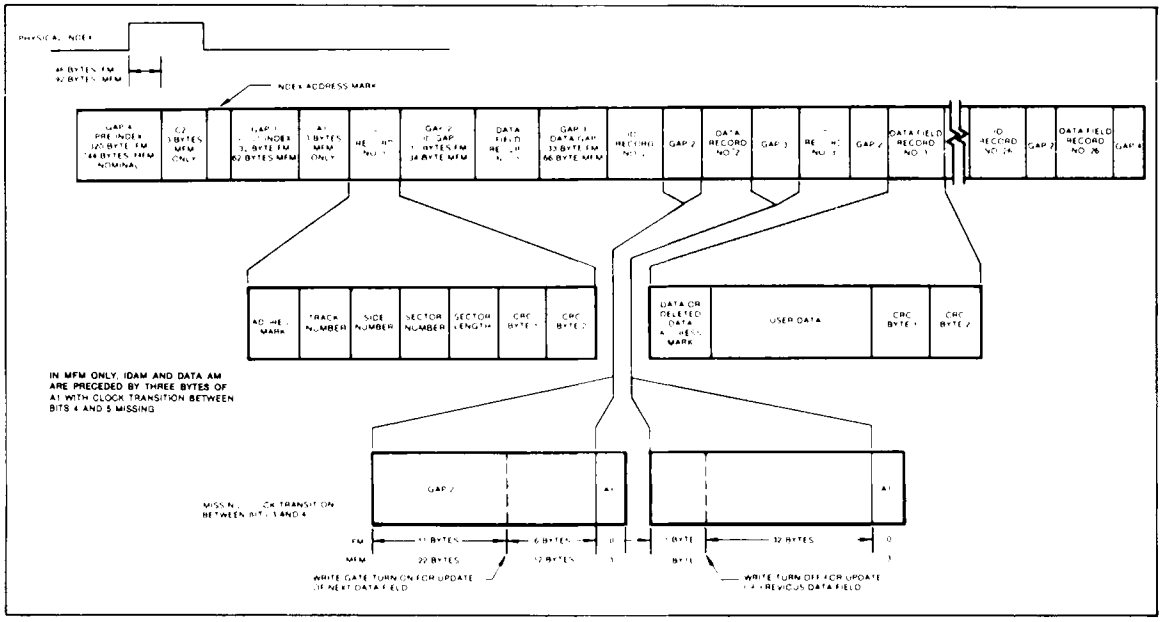
*Write bracketed field 26 times
**Continue writing until FD179X interrupts out.
Approx. 247 bytes.
1-Optional '00' on 1795/7 only.

IBM SYSTEM 34 FORMAT-
256 BYTES/SECTOR

Shown below is the IBM dual-density format with 256 bytes/sector. In order to format a diskette the user must issue the Write Track command and load the data register with the following values. For every byte to be written, there is one data request.

NUMBER OF BYTES	HEX VALUE OF BYTE WRITTEN
80	4E
12	00
3	F6 (Writes C2)
1	FC (Index Mark)
* 50	4E
12	00
3	F5 (Writes A1)
1	FE (ID Address Mark)
1	Track Number (0 thru 4C)
1	Side Number (0 or 1)
1	Sector Number (1 thru 1A)
1	01 (Sector Length)
1	F7 (2 CRCs written)
22	4E
12	00
3	F5 (Writes A1)
1	FB (Data Address Mark)
256	DATA
1	F7 (2 CRCs written)
54	4E
598**	4E

*Write bracketed field 26 times
**Continue writing until FD179X interrupts out.
Approx. 598 bytes.



IBM TRACK FORMAT

1. NON-IBM FORMATS

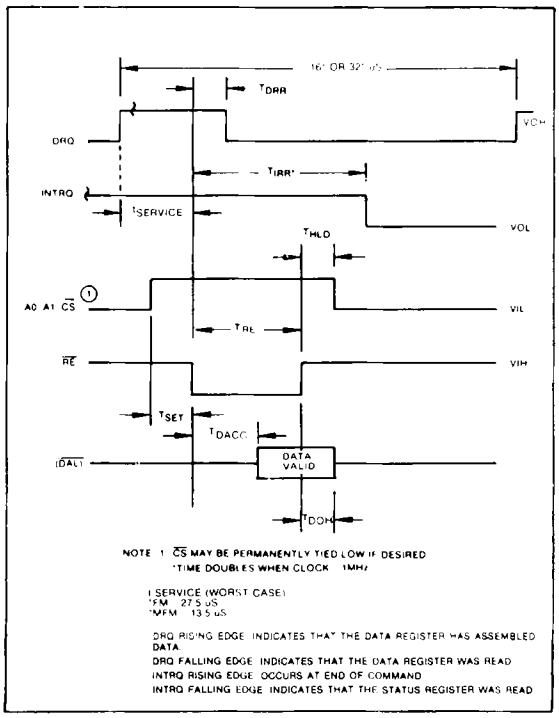
Variations in the IBM formats are possible to a limited extent if the following requirements are met:

1) Sector size must be 128, 256, 512 of 1024 bytes.
2) Gap 2 cannot be varied from the IBM format.
3) 3 bytes of A1 must be used in MFM.

In addition, the Index Address Mark is not required for operation by the FD179X. Gap 1, 3, and 4 lengths can be as short as 2 bytes for FD179X operation, however PLL lock up time, motor speed variation, write-splice area, etc. will add more bytes to each gap to achieve proper operation. It is recommended that the IBM format be used for highest system reliability.

	FM	MFM
Gap I	16 bytes FF	32 bytes 4E
Gap II	11 bytes FF	22 bytes 4E
*	6 bytes 00	12 bytes 00
*		3 bytes A1
Gap III**	10 bytes FF	24 bytes 4E
	4 bytes 00	8 bytes 00
		3 bytes A1
Gap IV	16 bytes FF	16 bytes 4E

*Byte counts must be exact.
**Byte counts are minimum, except exactly 3 bytes of A1 must be written.



READ ENABLE TIMING

TIMING CHARACTERISTICS

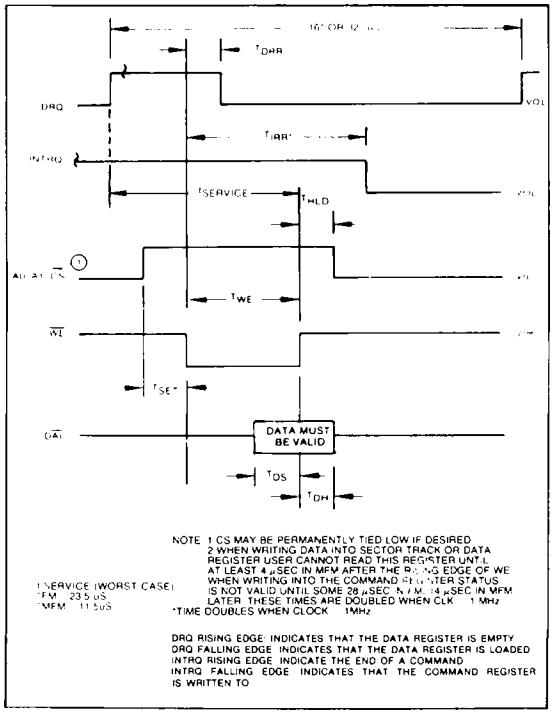
T_A = 0°C to 70°C, V_{DD} = + 12V ± .6V, V_{SS} = 0V, V_{CC} = +5V ± .25V

READ ENABLE TIMING (See Note 6, Page 21)

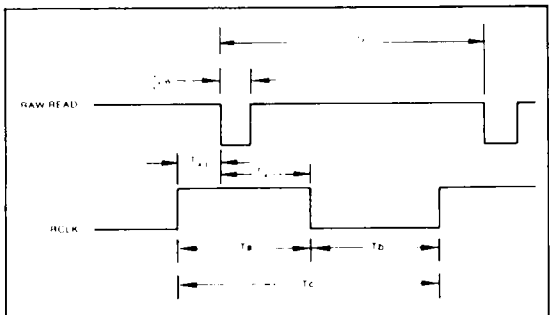
SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNITS	CONDITIONS
TSET	Setup ADDR & CS to $\overline{RE}$	50			nsec	
THLD	Hold ADDR & CS from $\overline{RE}$	10			nsec	
TRE	$\overline{RE}$ Pulse Width	400			nsec	C_L = 50.pf
TDRR	DRQ Reset from $\overline{RE}$		400	500	nsec	
TIRR	INTRQ Reset from $\overline{RE}$		500	3000	nsec	See Note 5
TDACC	Data Access from $\overline{RE}$				nsec	C_L = 50 pf
TDOH	Data Hold From $\overline{RE}$	50		150	nsec	C_L = 50 pf

WRITE ENABLE TIMING (See Note 6, Page 21)

SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNITS	CONDITIONS
TSET	Setup ADDR & CS to $\overline{WE}$	50			nsec	
THLD	Hold ADDR & CS from $\overline{WE}$	10			nsec	
TWE	$\overline{WE}$ Pulse Width	350			nsec	
TDRR	DRQ Reset from $\overline{WE}$		400	500	nsec	
TIRR	INTRQ Reset from $\overline{WE}$		500	3000	nsec	See Note 5
TDS	Data Setup to $\overline{WE}$	250			nsec	
TDH	Data Hold from $\overline{WE}$	70			nsec	



WRITE ENABLE TIMING



				NOMINAL		
DISKETTE	MODE	$\overline{DDEN}$	CLK	T_a	T_b	T_c
8"	MFM	0	2 MHz	1 μs	1 μs	2 μs
8"	FM	1	2 MHz	2 μs	2μs	4 μs
5"	MFM	0	1 MHz	2 μs	2μs	4 μs
5"	FM	1	1 MHz	4 μs	4 μs	8 μs

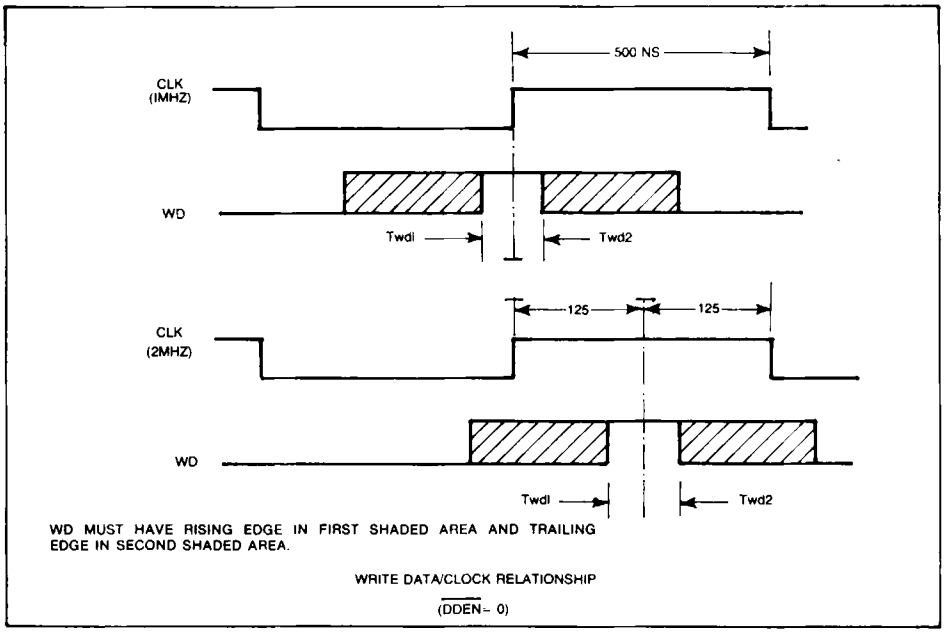
INPUT DATA TIMING

INPUT DATA TIMING:

SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNITS	CONDITIONS
Tpw	$\overline{\text{Raw Read}}$ Pulse Width	100	200		nsec	See Note 1
tbc	$\overline{\text{Raw Read}}$ Cycle Time	1500	2000		nsec	1800 ns @ 70°C
Tc	RCLK Cycle Time	1500	2000		nsec	1800 ns @ 70°C
Tx_1	RCLK hold to $\overline{\text{Raw Read}}$	40			nsec	See Note 1
Tx_2	$\overline{\text{Raw Read}}$ hold to RCLK	40			nsec	See Note 1

WRITE DATA TIMING: (ALL TIMES DOUBLE WHEN CLK = 1 MHz) (See Note 6, Page 21)

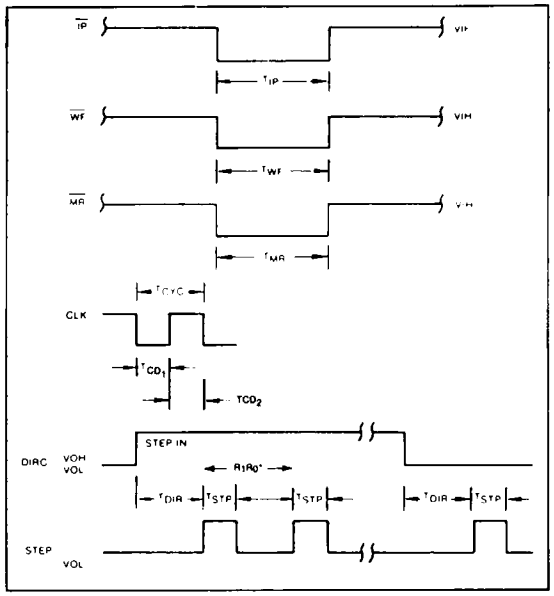
SYMBOL	CHARACTERISTICS	MIN.	TYP.	MAX.	UNITS	CONDITIONS
Twp	Write Data Pulse Width	450	500	550	nsec	FM
		150	200	250	nsec	MFM
Twg	Write Gate to Write Data		2		μsec	FM
			1		μsec	MFM
Tbc	Write data cycle Time		2,3, or 4		μsec	±CLK Error
Ts	Early (Late) to Write Data	125			nsec	MFM
Th	Early (Late) From Write Data	125			nsec	MFM
Twf	Write Gate off from WD		2		μsec	FM
			1		μsec	MFM
Twdl	WD Valid to Clk	100			nsec	CLK=1 MHZ
		50			nsec	CLK=2 MHZ
Twd2	WD Valid after CLK	100			nsec	CLK=1 MHZ
		30			nsec	CLK=2 MHZ



WRITE DATA TIMING

MISCELLANEOUS TIMING: (Times Double When Clock = 1 MHz) (See Note 6, Page 21)

SYMBOL	CHARACTERISTIC	MIN.	TYP.	MAX.	UNITS	CONDITIONS
TCD_1	Clock Duty (low)	230	250	20000	nsec	
TCD_2	Clock Duty (high)	200	250	20000	nsec	
TSTP	Step Pulse Output	2 or 4			μsec	See Note 5 ± CLK ERROR
TDIR	Dir Setup to Step		12		μsec	
TMR	Master Reset Pulse Width	50			μsec	
TIP	Index Pulse Width	10			μsec	See Note 5
TWF	Write Fault Pulse Width	10			μsec	



MISCELLANEOUS TIMING

*FROM STEP RATE TABLE

NOTES:

1. Pulse width on RAW READ (Pin 27) is normally 100-300 ns. However, pulse may be any width if pulse is entirely within window. If pulse occurs in both windows, then pulse width must be less than 300 ns for MFM at CLK = 2 MHz and 600 ns for FM at 2 MHz. Times double for 1 MHz.
2. A PPL Data Separator is recommended for 8" MFM.
3. tbc should be 2 μs, nominal in MFM and 4 μs nominal in FM. Times double when CLK = 1 MHz.
4. RCLK may be high or low during $\overline{\text{RAW READ}}$ (Polarity is unimportant).
5. Times double when clock = 1 MHz.
6. Output timing readings are at V_{OL} = 0.8v and V_{OH} = 2.0v.

Table 4. STATUS REGISTER SUMMARY

BIT	ALL TYPE I COMMANDS	READ ADDRESS	READ SECTOR	READ TRACK	WRITE SECTOR	WRITE TRACK
S7	NOT READY	NOT READY	NOT READY	NOT READY	NOT READY	NOT READY
S6	WRITE PROTECT	0	0	0	WRITE PROTECT	WRITE PROTECT
S5	HEAD LOADED	0	RECORD TYPE	0	WRITE FAULT	WRITE FAULT
S4	SEEK ERROR	RNF	RNF	0	RNF	0
S3	CRC ERROR	CRC ERROR	CRC ERROR	0	CRC ERROR	0
S2	TRACK 0	LOST DATA	LOST DATA	LOST DATA	LOST DATA	LOST DATA
S1	INDEX PULSE	DRQ	DRQ	DRQ	DRQ	DRQ
S0	BUSY	BUSY	BUSY	BUSY	BUSY	BUSY

STATUS FOR TYPE I COMMANDS

BIT NAME	MEANING
S7 NOT READY	This bit when set indicates the drive is not ready. When reset it indicates that the drive is ready. This bit is an inverted copy of the Ready input and logically 'ored' with MR.
S6 PROTECTED	When set, indicates Write Protect is activated. This bit is an inverted copy of $\overline{\text{WRPT}}$ input.
S5 HEAD LOADED	When set, it indicates the head is loaded and engaged. This bit is a logical "and" of HLD and HLT signals.
S4 SEEK ERROR	When set, the desired track was not verified. This bit is reset to 0 when updated.
S3 CRC ERROR	CRC encountered in ID field.
S2 TRACK 00	When set, indicates Read/Write head is positioned to Track 0. This bit is an inverted copy of the $\overline{\text{TROO}}$ input.
S1 INDEX	When set, indicates index mark detected from drive. This bit is an inverted copy of the $\overline{\text{IP}}$ input.
S0 BUSY	When set command is in progress. When reset no command is in progress.

STATUS FOR TYPE II AND III COMMANDS

BIT NAME	MEANING
S7 NOT READY	This bit when set indicates the drive is not ready. When reset, it indicates that the drive is ready. This bit is an inverted copy of the Ready input and 'ored' with MR. The Type II and III Commands will not execute unless the drive is ready.
S6 WRITE PROTECT	On Read Record: Not Used. On Read Track: Not Used. On any Write: It indicates a Write Protect. This bit is reset when updated.
S5 RECORD TYPE/ WRITE FAULT	On Read Record: It indicates the record-type code from data field address mark. 1 = Deleted Data Mark. 0 = Data Mark. On any Write: It indicates a Write Fault. This bit is reset when updated.
S4 RECORD NOT FOUND (RNF)	When set, it indicates that the desired track, sector, or side were not found. This bit is reset when updated.
S3 CRC ERROR	If S4 is set, an error is found in one or more ID fields; otherwise it indicates error in data field. This bit is reset when updated.
S2 LOST DATA	When set, it indicates the computer did not respond to DRQ in one byte time. This bit is reset to zero when updated.
S1 DATA REQUEST	This bit is a copy of the DRQ output. When set, it indicates the DR is full on a Read Operation or the DR is empty on a Write operation. This bit is reset to zero when updated.
S0 BUSY	When set, command is under execution. When reset, no command is under execution.

ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

V_{DD} with repect to V_{SS} (ground): + 15 to − 0.3V

Voltage to any input with respect to V_{SS} = + 15 to − 0.3V

I_{CC} = 60 MA (35 MA nominal)

I_{DD} = 15 MA (10 MA nominal)

Dissipation = 0.6 W

C_{IN} & C_{OUT} = 15 pF max with all pins grounded except one under test.

Operating temperature = 0°C to 70°C

Storage temperature = −55°C to + 125°C

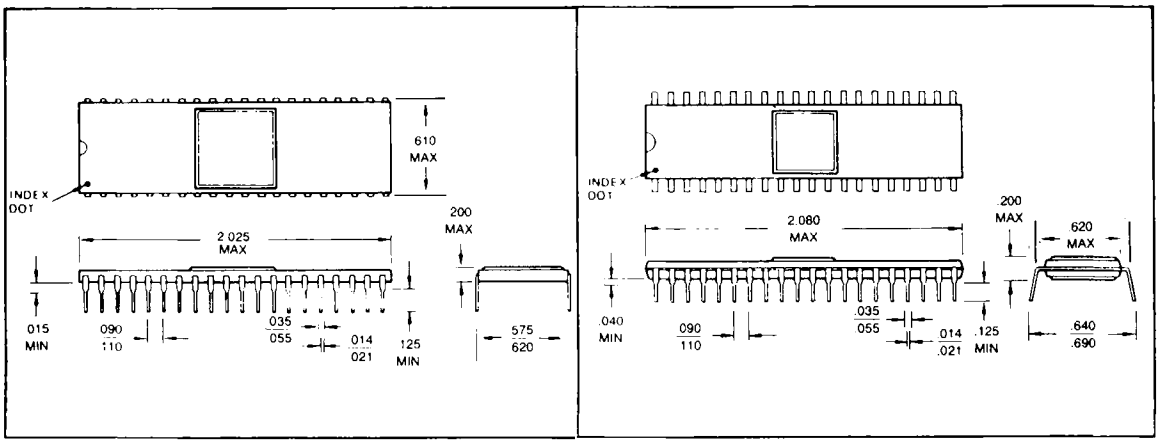
OPERATING CHARACTERISTICS (DC)

TA = 0°C to 70°C, V_{DD} = + 12V ± .6V, V_{SS} = 0V, V_{CC} = + 5V ± .25V

SYMBOL	CHARACTERISTIC	MIN.	MAX.	UNITS	CONDITIONS
I_{IL}	Input Leakage		10	μA	$V_{IN} = V_{DD}$**
I_{OL}	Output Leakage		10	μA	$V_{OUT} = V_{DD}$
V_{IH}	Input High Voltage	2.6		V	
V_{IL}	Input Low Voltage		0.8	V	
V_{OH}	Output High Voltage	2.8		V	I_O = −100 μA
V_{OL}	Output Low Voltage		0.45	V	I_O = 1.6 mA*
P_D	Power Dissipation		0.6	W	

*1792 and 1794 I_O = 1.0 mA

**Leakage conditions are for input pins without internal pull-up resistors.



FD179XA-02 CERAMIC PACKAGE **FD179XB-02 PLASTIC PACKAGE**

WESTERN DIGITAL CORPORATION | 2445 McCABE WAY
IRVINE, CA 92714 (714) 557-3550, TWX 910-595-1139

WESTERN DIGITAL
CORPORATION

WD1691 FLOPPY SUPPORT LOGIC (F.S.L.)

October, 1980

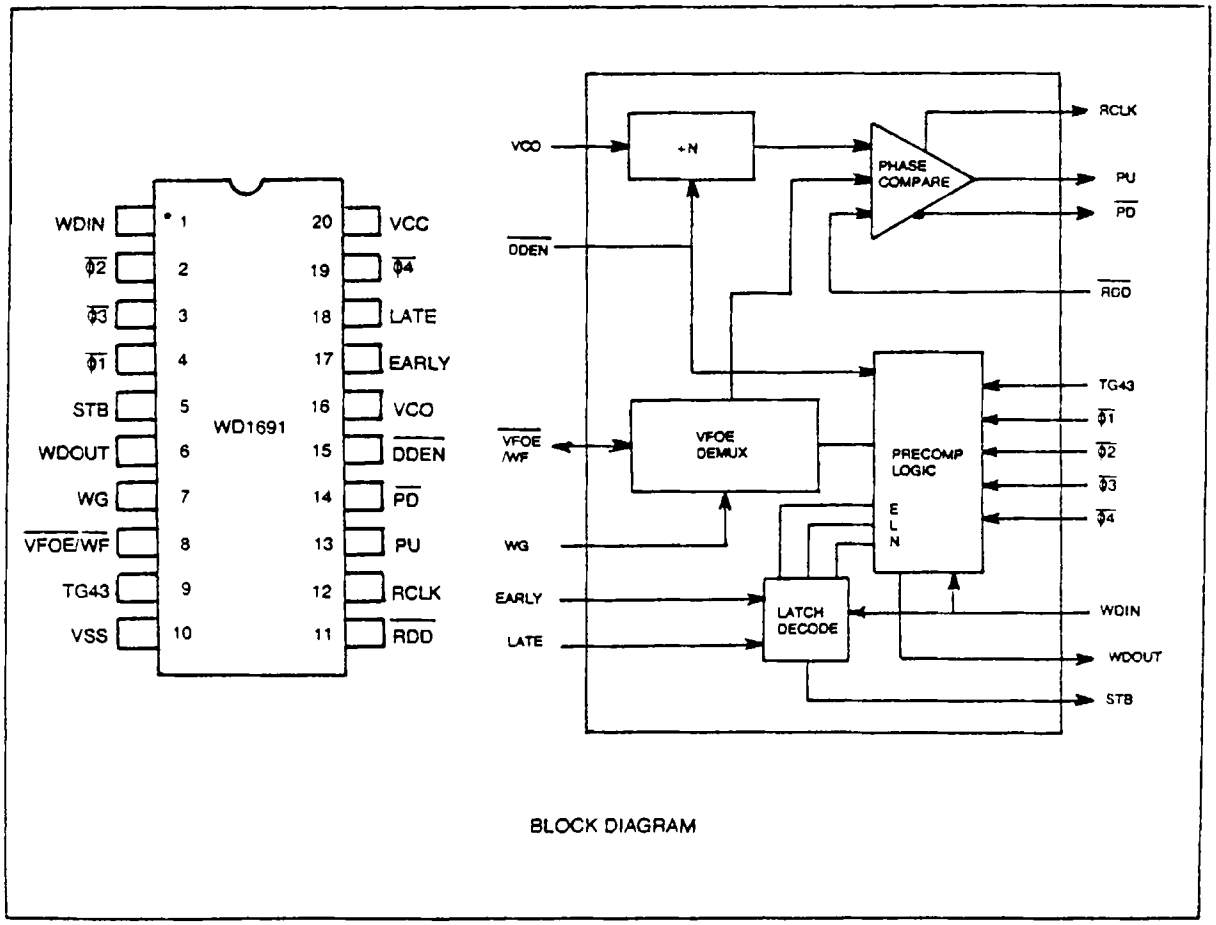
FEATURES

- Direct interface to the FD179X
- Eliminates external FDC Logic
- Data Separation/RCLK GENERATION
- Write Precompensation Signals
- VFOE/WF Demultiplexing
- Programmable Density
- 8" or 5.25" Drive Compatible
- All inputs and outputs TTL Compatible
- Single +5V Supply

GENERAL DESCRIPTION

The WD1691 F.S.L. has been designed to minimize the external logic required to interface the 179X Family of Floppy Disk Controllers to a drive. With the use of an external VCO, the WD 1691 will generate the RCLK signal for the WD179X, while providing an adjustment pulse (PUMP) to control the VCO frequency. VFOE/WF de-multiplexing is also accomplished and Write Precompensation signals have been included to interface directly with the WD2143 Clock Generator.

The WD1691 is implemented in N-MOS silicon gate technology and is available in a plastic or ceramic 20 pin dual-in-line package.



BLOCK DIAGRAM

PIN	NAME	SYMBOL	FUNCTION
1	WRITE DATA INPUT	WDIN	Ties directly to the FD179X WD pin.
2, 3, 4, 19	PHASE 2, 3, 1, 4	$\overline{\phi 2}$ $\overline{\phi 3}$ $\overline{\phi 1}$ $\overline{\phi 4}$	4 Phase inputs to generate a desired Write Precompensation delay. These signals tie directly to the WD2143 Clock Generator.
5	STROBE	STB	Strobe output from the 1691. Strobe will latch at a high level on the leading edge of WDIN and reset to a low level on the leading edge of 04.
6	WRITE DATA OUTPUT	WDOUT	Serial, pre-compensated Write data stream to be sent to the disk drive's WD line.
7	WRITE GATE	WG	Ties directly to the FD179X WG pin.
8	VFO ENABLE/ WRITE FAULT	$\overline{\text{VFOE}}/\overline{\text{WF}}$	Ties directly to the FD179X $\overline{\text{VFOE}}/\overline{\text{WF}}$ pin.
9	TRACK 43	TG43	Ties directly to the FD179X TG43 pin, If Write Precompensation is required on TRACKS 44-76.
10	V_{ss}	V_{ss}	Ground
11	READ DATA	$\overline{\text{RDD}}$	Composite clock and data stream input from the drive.
12	READ CLOCK	RCLK	RCLK signal generated by the WD1691, to be tied to the FD179X RCLK pin.
13	PUMP UP	PU	Tri-state output that will be forced high when the WD1691 requires an increase in VCO frequency.
14	PUMP DOWN	$\overline{\text{PD}}$	Tri-state output that will be forced low when the WD1691 required a decrease in VCO frequency.
15	Double Density Enable	$\overline{\text{DDEN}}$	Double Density Select input. When Inactive (High), the VCO frequency is internally divided by two.
16	Voltage Controlled Oscillator	VCO	A nominal 4.0MHz (8" drive) or 2.0MHz (5.25" drive) master clock input.
17, 18	EARLY LATE	EARLY LATE	EARLY and LATE signals from the FD179X, used to determine Write Precompensation.
20	V_{cc}	V_{cc}	+ 5V ± 10% power supply

DEVICE DESCRIPTION

The WD1691 is divided into two sections:

1) Data Recovery Circuit
2) Write precompensation Circuit

The Data Separator or Recovery Circuit has four inputs: $\overline{DDEN}$, VCO, $\overline{RDD}$, and $\overline{VFOE/WF}$; and three outputs: PU, $\overline{PD}$ and RCLK. The $\overline{VFOE/WF}$ input is used in conjunction with the Write Gate signal to enable the Data recovery circuit. When Write Gate is high, a write operation is taking place, and the data recovery circuits are disabled, regardless of the state on any other inputs.

When $\overline{VFOE/WF}$ and WRITE GATE are low, the data recovery circuit is enabled. When the $\overline{RDD}$ line goes Active Low, the PU or $\overline{PD}$ signals will become active. If the $\overline{RDD}$ line has made its transition in the beginning of the RCLK window, PU will go from a HI-Z state to a Logic I, requesting an *increase* in VCO frequency. If the $\overline{RDD}$ line has made its transition at the end of the RCLK window, PU will remain in a HI-Z state while $\overline{PD}$ will go to a logic zero, requesting a *decrease* in VCO frequency. When the leading edge of $\overline{RDD}$ occurs in the center of the RCLK window, both PU and $\overline{PD}$ will remain tri-stated, indicating that no adjustment of the VCO frequency is needed. The RCLK signal is a divide-by-16 (DDEN=1) or a divide-by-8 (DDEN=0) of the VCO frequency.

WG	VFOE/WF	RDD	PU+PD
1	X	X	HI-Z
0	1	X	HI-Z
0	0	1	HI-Z
0	0	0	Enable

The Write Precompensation circuit has been designed to be used with the WD2143-01 clock generator. When the WD1691 is operated in a "single density only" mode, write precompensation as well as the WD2143-01 is not needed. In this case, $\overline{\phi 1}$, $\overline{\phi 2}$, $\overline{\phi 3}$, $\overline{\phi 4}$, and STB should be tied together, $\overline{DDEN}$ left open, and TG43 tied to ground.

In the double-density mode ($\overline{DDEN}$=0), the signals Early and Late are used to select a phase input ($\overline{\phi 1}$ – $\overline{\phi 4}$) on the leading edge of WDIN. The STB line is latched high when this occurs, causing the WD2143-01 to start its pulse generation. $\overline{\phi 2}$ is used as the write data pulse on nominal (Early=Late=$\overline{\phi}$), $\overline{\phi 2}$ is used for early, and $\overline{\phi 3}$ is used for late. The leading edge of $\overline{\phi 4}$ resets the STB line in anticipation of the next write data pulse. When TG43=0 or $\overline{DDEN}$=1, Precompensation is disabled and any transitions on the WDIN line will appear on the WDout line. If write precompensation is desired on all tracks, leave TG43 open (an internal pull-up will force a Logic I) while $\overline{DDEN}$=0.

The signals, $\overline{DDEN}$, TG43, and $\overline{RDD}$ have internal pull-up resistors and may be left open if a logic I is desired on any of these lines.

The minimum Voh level on PU is specified at 2.4V, sourcing 200ua. During PUMP UP time, this output will "drift" from a tri-state to .4V minimum. By tying PU and PD together, a PUMP signal is created that will be forced low for a decrease in VCO frequency and forced high for an increase in VCO frequency. To speed up rise times and stabilize the output voltage, a resistor divider can be used to set the tri-state level to approximately 1.4V. This yields a worst case swing of ± 1V; acceptable for most VCO chips with a linear voltage-to-frequency characteristic.

Both PU and $\overline{PD}$ signals are affected by the width of the RAW READ ($\overline{RDD}$) pulse. The wider the RAW READ pulse, the longer the PU or $\overline{PD}$ signal (depending upon the phase relationship to RCLK) will remain active. If the RAW READ pulse exceeds 250ns, (VCO = 4MHz, DDEN = 0) or 500ns. (VCO = 4MHz, DDEN = 1), then both a PU and PD will occur in the same window. This is undesirable and reduces the accuracy of the external integrator or low-pass filter to convert the PUMP signals into a slow moving D.C. correction voltage.

Eventually, the PUMP signals will have corrected the VCO input to exactly the same frequency multiple as the RAW READ signal. The leading edge of the RAW READ pulse will then occur in the exact center of the RCLK window, and ideal condition for the FD179X internal recovery circuits.

SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS

Ambient Temperature under Bias ..... −25° to 70°C
Voltage on any pin with respect to Ground (vss) ..... −0.2 to +7V
Power Dissipation 1W

Storage Temp.—Ceramic—65°C to +150°C
Plastic—55°C to +125°C

NOTE: Maximum limits indicate where permanent device damage occurs. Continuous operation at these limits is not intended and should be limited to those conditions specified in the DC Electrical characteristics.

DC ELECTRICAL CHARACTERISTICS

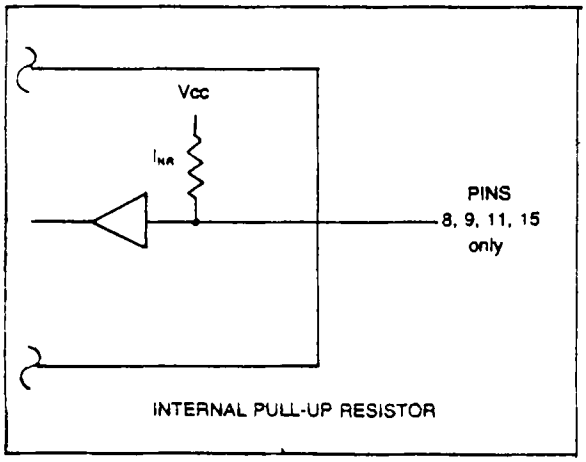
T_A = 0° to 70°C; V_{CC} = 5.0V±10%; V_{ss}=OV

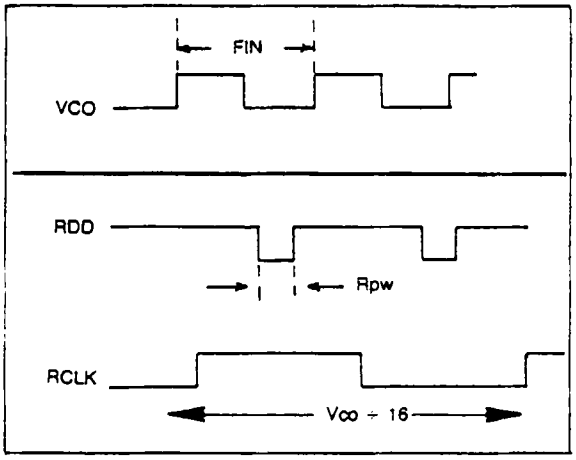
SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT	TEST CONDITIONS
V_{IL}	Input Low Voltage	−0.2		+0.8	V	
V_{IH}	Input High Voltage	2.0			V	
V_{OL}	Output Low Voltage			0.45	V	I_{OL}=3.2MA
V_{OH}	High Level Output Voltage	2.4			V	I_{OH}=−200μa
V_{CC}	Supply Voltage	4.5	5.0	5.5	V	
I_{CC}	Supply Current		40	100	MA	All outputs open

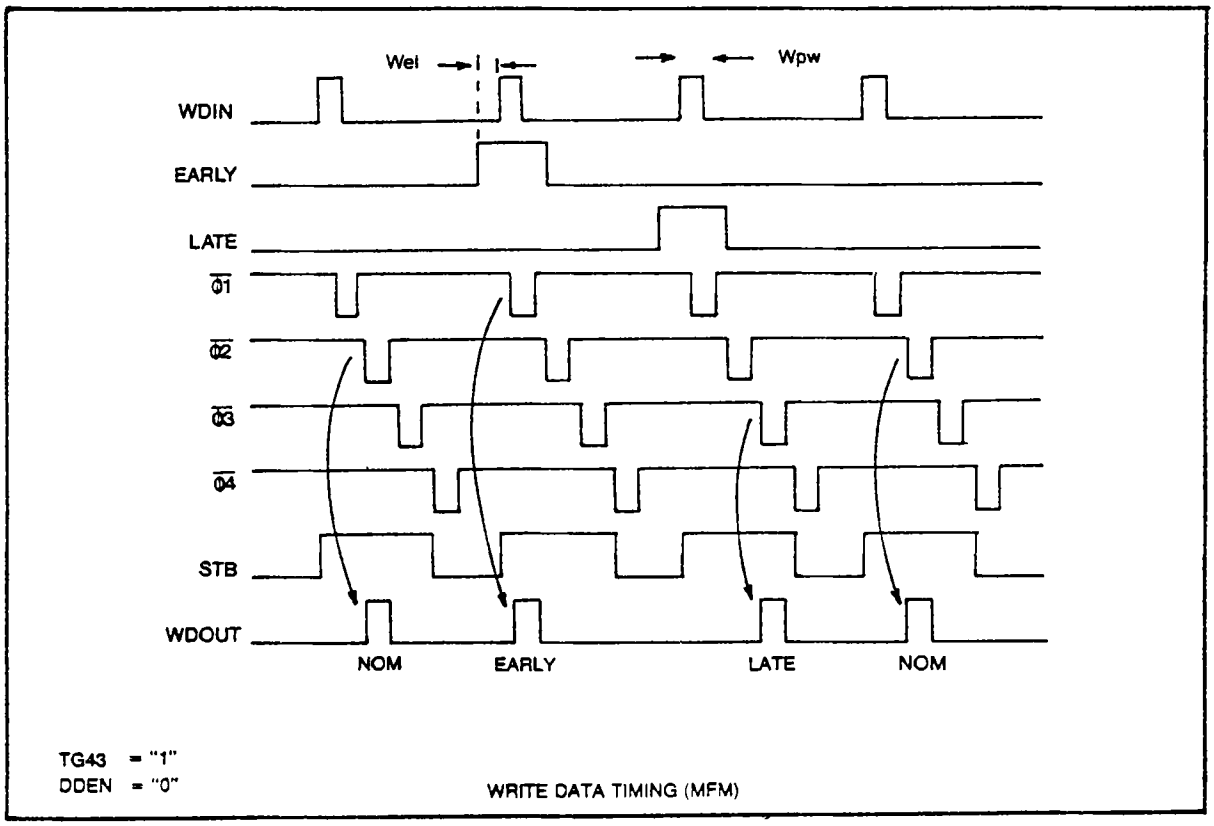
AC ELECTRICAL CHARACTERISTCS

T_A = 0° to 70°C; V_{cc} = 5V± 10%; Vss = OV

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT	TEST CONDITIONS
FIN	VCO Input Frequency	.5	4	6	MHz	$\overline{DDEN}$=0
		.5	2	6	MHz	$\overline{DDEN}$=1
R_{pw}	$\overline{RDD}$ Pulse Width	100	200		ns.	
W_{el}	EARLY (LATE) to WDIN	100			ns.	
P_{on}	PUMP UP/DN Time	0		250	ns.	
W_{pi}	WDIN to WDOUT			80	ns.	$\overline{DDEN}$=1
I_{NR}	Internal Pull-up Resistor	4.0	6.5	10	KΩ	

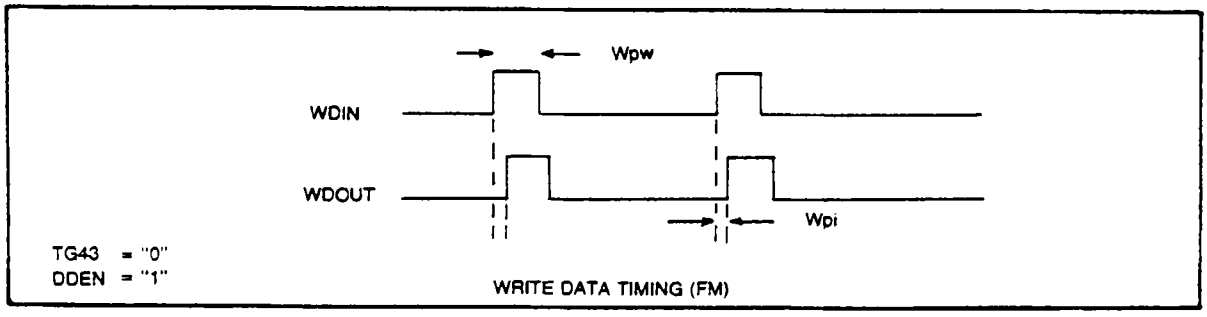






TG43 = "1"
DDEN = "0"

WRITE DATA TIMING (MFM)



TG43 = "0"
DDEN = "1"

WRITE DATA TIMING (FM)

TYPICAL APPLICATIONS

Figure 1 illustrates the 1691 to FD1771-01 floppy disk controller. The RCLK signal is used to gate the RAW data pulses which are inverted by the 74LS04 inverter. Since RCLK will be high during data and low during clock a 74LS08 is used to switch the proper clock or data pulse to the FD1771.

Shown in Figure 2 is a Phase-Lock Loop data separator and the support logic for a single and double-density 8" drive. The raw data (Both clock and data bits) are fed to the WD1691 and FD179X. The WD1691 outputs its PU or PD signal, which is integrated by the .33uf capacitor and 33ohm resistor to form a control voltage for the 74S124 VCO device. The 4.0MHZ nominal output of the VCO then feeds back to the WD1691 completing the loop. The WD2143-01 is also used, providing write precompensation when in double-density, from tracks 44-77. The $\overline{\text{DDEN}}$ line can either be controlled by a toggle switch or a logic level from the host system.

To adjust write precompensation, issue a command to the FD179X so that write data pulses are present. This can be done with a 'WRITE TRACK' command and the $\overline{\text{IP}}$ line open, or a continuous 'WRITE SECTOR' operation. With a scope on pin 4 of the WD1691, adjust the precomp pot for the desired value. This will range from 100 to 300 ns typically. The pulse width set on pin 4 (ϕ1) will be the desired precomp delay from nominal.

The data separator must be adjusted with the $\overline{\text{RDD}}$ or $\overline{\text{VFOE}}$/$\overline{\text{WF}}$ line at a Logic I. Adjust the bias voltage potentiometer for 1.4V on pin 2 of the 74S124. Then adjust the range control to yield 4.0MHZ on pin 7 of the 74S124.

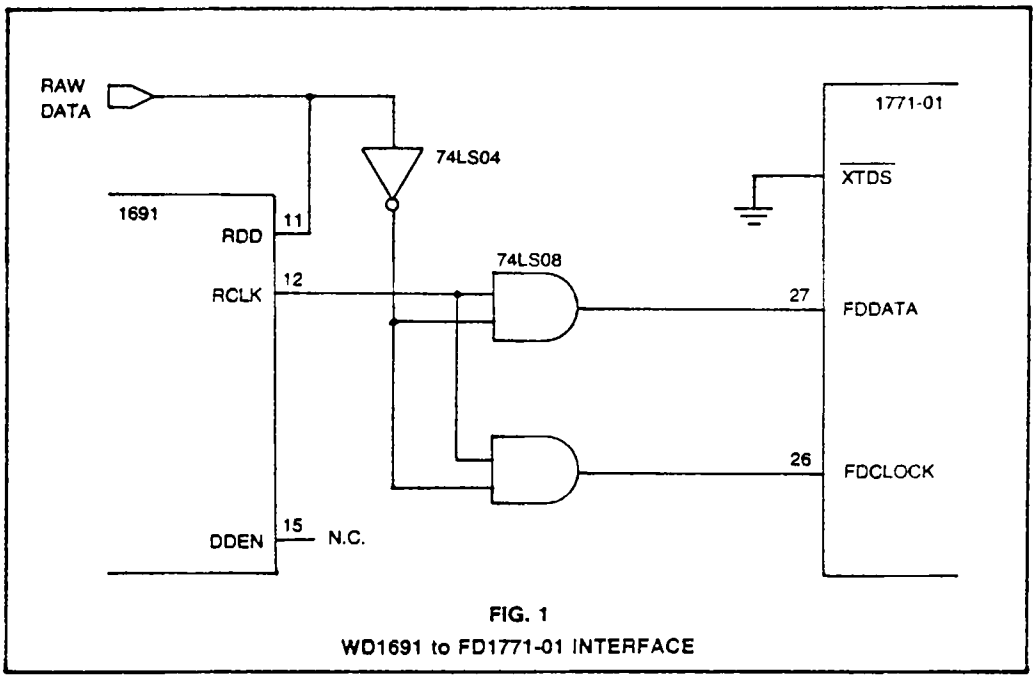


FIG. 1
WD1691 to FD1771-01 INTERFACE

SUBSTITUTING VCO's

There are other VCO circuits available that may be substituted for the 74S124. The specifications required are:

1) The VCO must free run at 4.0MHz with a 1.4V control signal. The WD1691 will force this voltage 1 Volt in either direction (i.e., .4V = decrease frequency, 2.4V = increase frequency). If a ± 15% capture range is desired, then a 1 Volt change on the VCO input should change the frequency by 15%. Capture range should be limited to about ± 25%, to prevent the VCO from breaking into oscillation and/or losing lock because of noise spikes (causing abnormally quick adjustments of the VCO frequency). Jitter in the VCO output frequency may further be reduced by increasing the integration capacitor/resistor, but this will also decrease the final capture range and lock-up time.

2) The sink output current of the WD1691 is 3.2ma minimum. The source output current is −200ua. Therefore, source current is the limiting factor. Insure that the input circuitry of the VCO does not require source current in excess of −200ua.

Another alternative is to use a voltage follower/level shifter circuit to match the input requirements of the VCO chosen. A more complex filter can be used to convert the PUMP UP/PUMP DOWN pulses to the varying DC voltage signal required by the VCO, achieving an optimum condition between lock-up time and high frequency rejection.

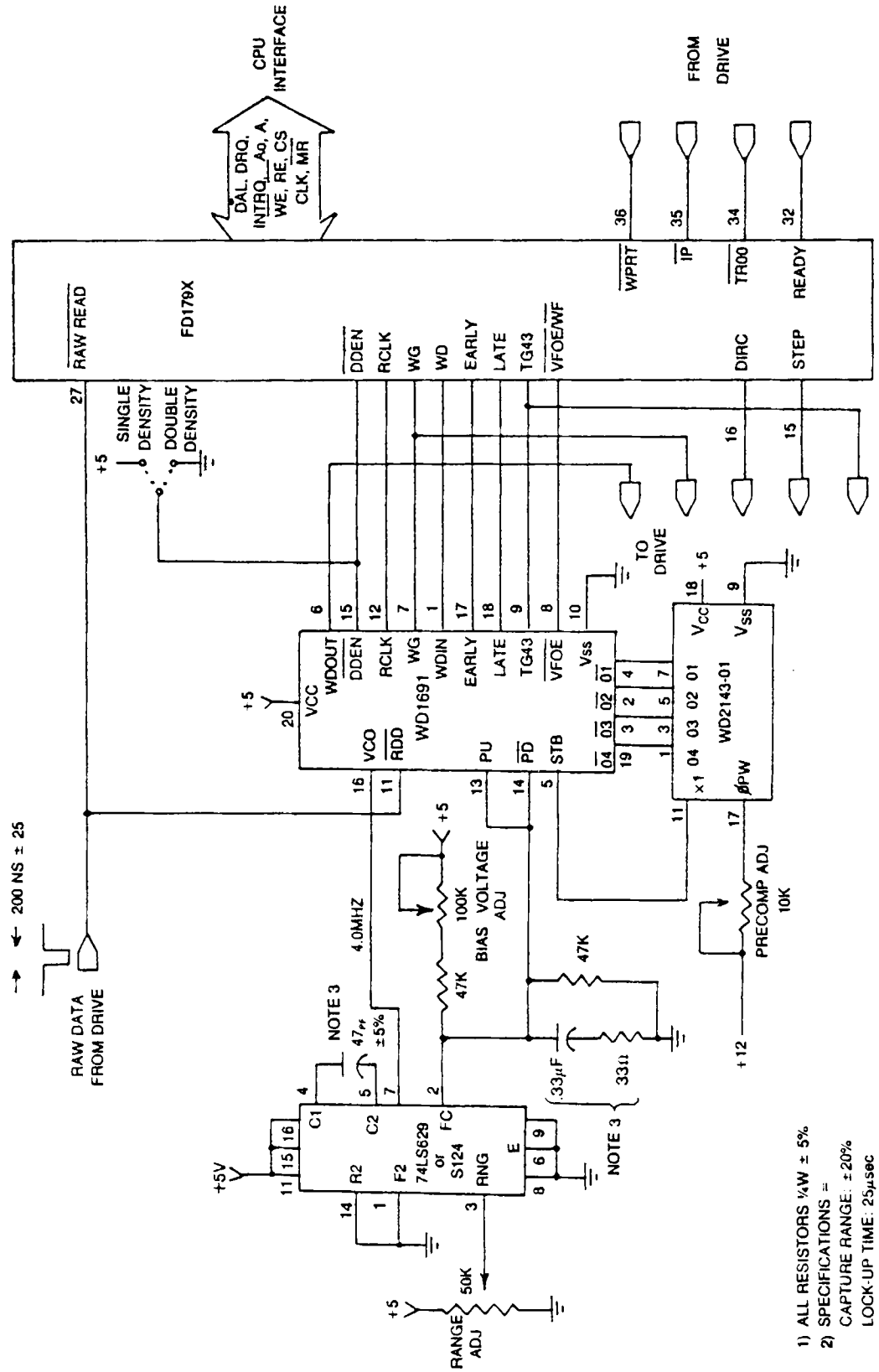
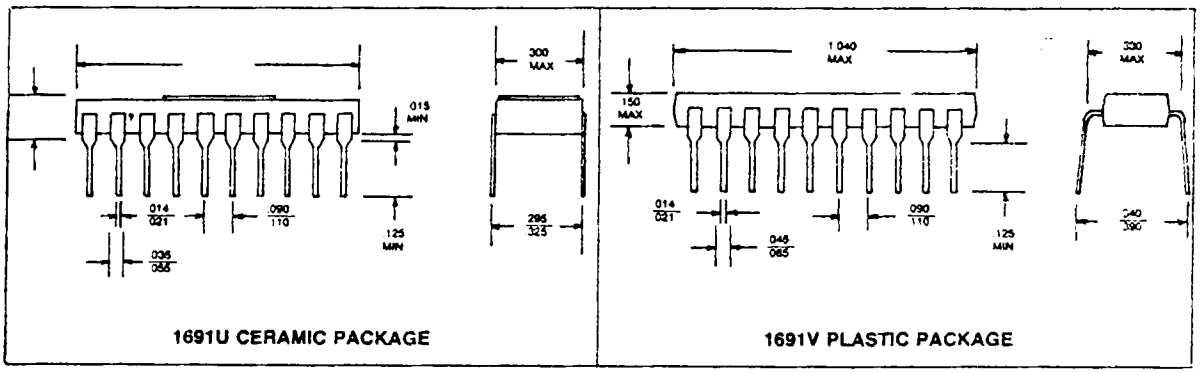


FIG. 2
8" SINGLE/DOUBLE DENSITY FLOPPY INTERFACE

1) ALL RESISTORS ¼W ± 5%
2) SPECIFICATIONS =
CAPTURE RANGE: ± 20%
LOCK-UP TIME: 25μsec
(ALL ONE'S PATTERN, MFM)
3) FOR 5 1/4" 8"
68μf 33μf
681Ω 331Ω
80PI 47PI



This is a preliminary specification with tentative device parameters and may be subject to change after final product characterization is completed.

WESTERN DIGITAL CORPORATION
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WESTERN DIGITAL
CORPORATION

WD2143-03 Four Phase Clock Generator

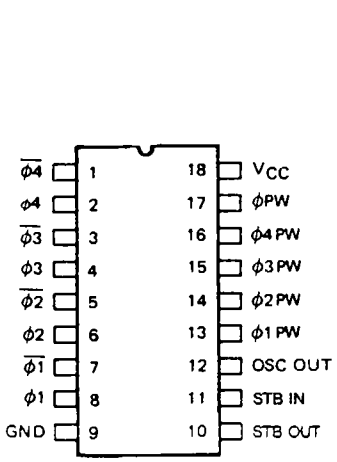
SEPTEMBER, 1981

FEATURES

- IMPROVED VERSION OF WD2143-01
- TRUE AND INVERTED OUTPUTS
- SINGLE 5 VOLT SUPPLY
- TTL COMPATABLE
- ON CHIP OSCILLATOR
- TTL CLOCK INPUTS
- TTL CLOCK OUTPUT
- PROGRAMMABLE PULSE WIDTHS
- PROGRAMMABLE PHASE WIDTHS
- NO EXTERNAL CAPACITOR

GENERAL DESCRIPTION

The WD2143-03 Four-Phase Clock Generator is a MOS/LSI device capable of generating four phase clocks. The output pulse widths are controlled by tying an external resistor to the proper control inputs. All pulse widths may be set to the same width by tying the ϕPW line through an external resistor. Each pulse width can also be individually programmed by tying a resistor through the appropriate ϕ1PW—ϕ4PW control inputs.



PIN CONNECTIONS

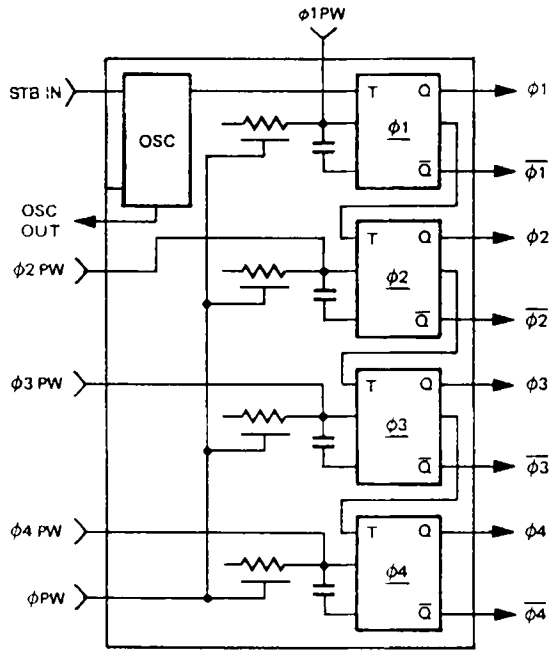


Figure 1 WD2143-03 PIN CONNECTIONS AND BLOCK DIAGRAM

DEVICE OPERATION

Each of the phase outputs can be controlled individually by typing an external resistor from ϕ1PW-ϕ4PW to a +5V supply. When it is desired to have ϕ1 through ϕ4 outputs the same width, the ϕ1PW-ϕ4PW inputs should be left open and an external resistor tied from the ϕPW (Pin 17) input to +12V.

STROBE IN (pin 11) is driven by a TTL square wave with STROBE OUT (pin 10) left open. Each of the four phase outputs provide both true and inverted signals, capable of driving 1 TTL load each.

PIN NUMBER	SYMBOL	DESCRIPTION
1, 3, 5, 7	$\overline{\phi 1}$—$\overline{\phi 4}$	Four phase clock outputs. These outputs are inverted (active low).
2, 4, 6, 8	$\phi 1$-$\phi 4$	Four Phase clock outputs. These outputs are true (active high).
9	GND	Ground
10	STB OUT	This pin is left unconnected.
11	STB IN	Input signal to initiate four-phase clock outputs.
12	N.C.	No connection
13-16	ϕ1PW-ϕ4PW	External resistor inputs to control the individual pulse widths of each output. These pins can be left open if ϕPW is used.
17	ϕPW	External resistor input to control all phase outputs to the same pulse widths.
18	V_{cc}	+5V ± 5% power supply input

Table 1 PIN DESCRIPTIONS

TYPICAL APPLICATIONS

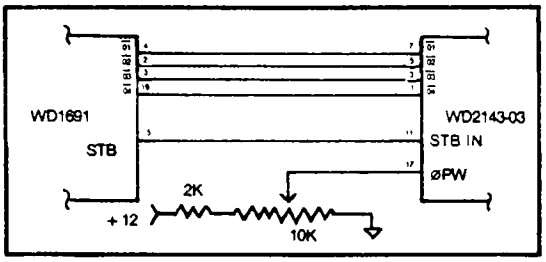


Figure 2 WRITE PRECOMP OPERATION WITH F.S.L. WD1691

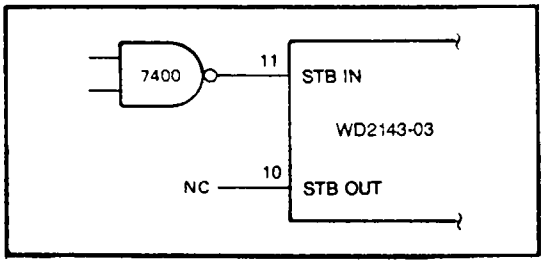


Figure 3 TTL SQUARE WAVE OPERATION

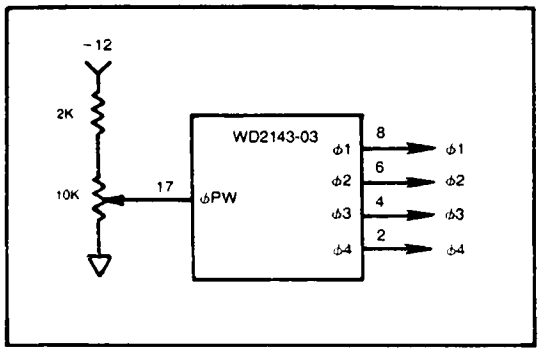


Figure 4 EQUAL PULSE WIDTH OUTPUTS

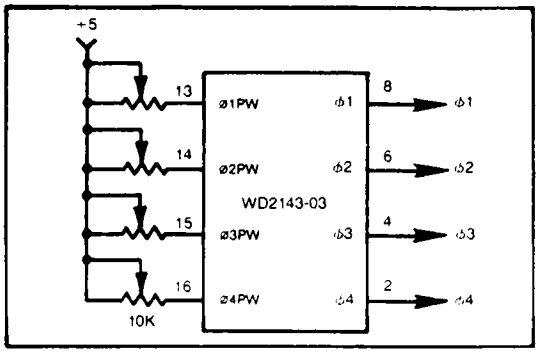


Figure 5 INDIVIDUAL PULSE WIDTH OUTPUTS

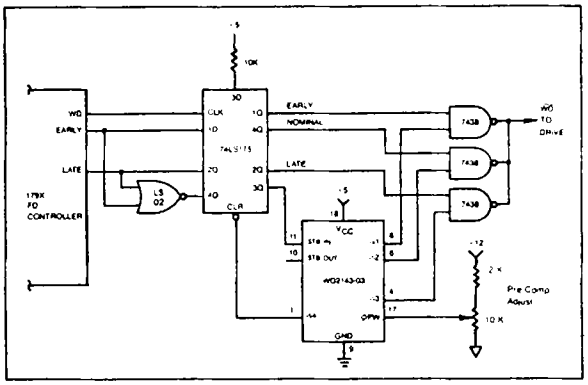


Figure 6 WRITE PRECOMP FOR FLOPPY DISK

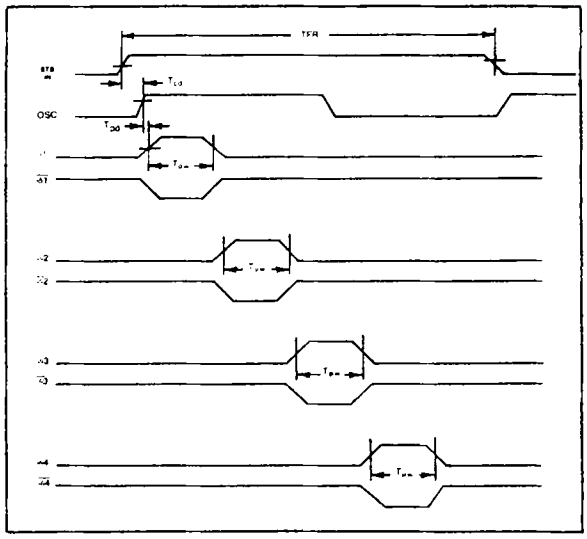


Figure 7 WD2143-03 TIMING DIAGRAM

SPECIFICATIONS

Absolute Maximum Ratings		
Operating Temperature		0° to +70° C
Voltage on any pin with respect to Ground*		−0.5 to +7V
Power Dissipation		1 Watt
Storage Temperature	plastic	−55° to +125° C
	ceramic	−65° to +150°C

Note: Maximum ratings indicate limits beyond which permanent damage may occur. Continuous operation at these limits is not intended and should be limited to the DC electrical characteristics specified.

*Pin 17 = −0.5V to +12V. Increasing voltage on Pin 17 will decrease T_{pw}.

DC ELECTRICAL CHARACTERISTICS

V_{cc} = 5V ±5%, GND = OV, T_A = 0° to 70°C.

SYMBOL	PARAMETER	MIN.	MAX.	UNITS	CONDITIONS
V_{ol}	TTL low level output		0.4	V	I_{ol} = 1.6 ma.
V_{oh}	TTL high level output	2.4		V	I_{oh} = −100 ua.
V_{il}	STB in low voltage		0.8	V	
V_{ih}	STB in high voltage	2.4		V	
I_{cc}	Supply Current		80	ma	All outputs open

Table 2 DC ELECTRICAL CHARACTERISTICS

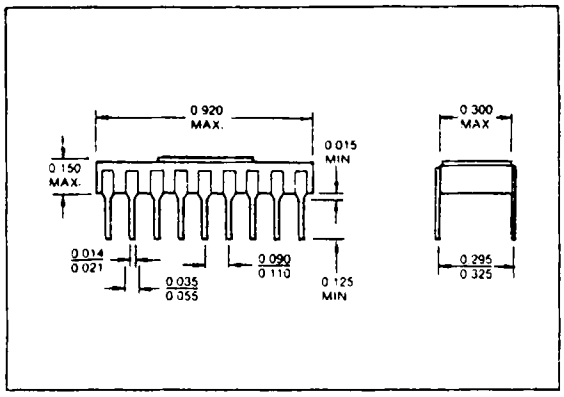
SWITCHING CHARACTERISTICS

V_{CC} =5V ± 5%, GND = 0V T_A = 0° to 70° C

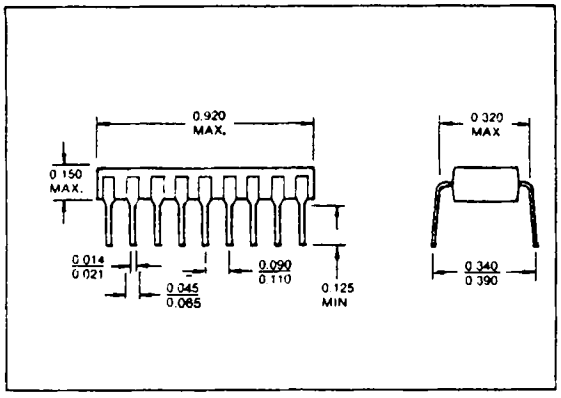
SYMBOL	PARAMETER	MIN.	MAX.	UNITS	CONDITIONS
T_{cd}	STB IN to OSC out (↑)		70	NS	
T_{pd}	STB OUT to ϕ1		70	NS	
T_{pw}	Pulse Width (any output)	100	300	NS	CL = 30pf
T_{pr}	Rise Time (any output)		30	NS	CL = 30 pf
T_{pf}	Fall Time (any output)		25	NS	CL = 30 pf
TFR	STROBE Frequency		2.5	MHz	combined Tpw = 400 NS.
T_{dpw}	Pulse Width Differential		10	%	100–300 NS.

Table 3 SWITCHING CHARACTERISTICS

NOTE: T_{pw} measured at 50% V_{OH} Point; V_{OL} = 0.8V, V_{OH} = 2.0V.



WD2143L-03 CERAMIC PACKAGE



WD2143M-03 PLASTIC PACKAGE

This is a preliminary specification with tentative device parameters and may be subject to change after final product characterization is completed.

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MOTOROLA

MCM6633

32,768-BIT DYNAMIC RAM

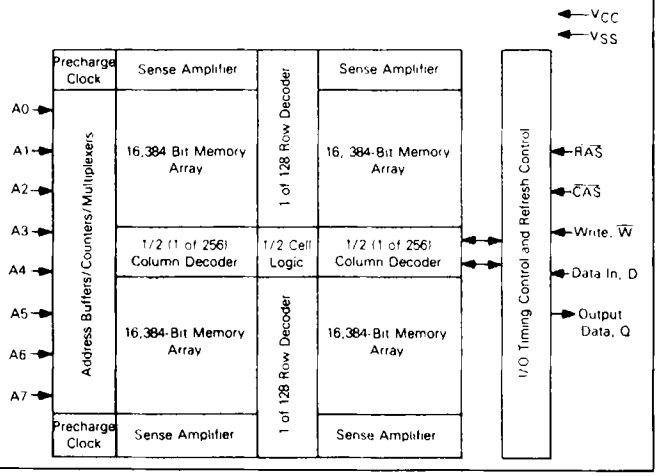
The MCM6633 is a 32,768 bit, high-speed, dynamic Random-Access Memory. Organized as 32,768 one-bit words and fabricated using HMOS high-performance N-channel silicon-gate technology. This new breed of 5-volt only dynamic RAM combines high performance with low cost and improved reliability.

By multiplexing row- and column-address inputs, the MCM6633 requires only eight address lines and permits packaging in standard 16-pin dual-in-line packages. Complete address decoding is done on chip with address latches incorporated. Data out is controlled by $\overline{CAS}$ allowing for greater system flexibility.

All inputs and outputs, including clocks, are fully TTL compatible. The MCM6633 incorporates a one-transistor cell design and dynamic storage techniques.

- Organized as 32,768 Words of 1 Bit
- Single +5 V Operation
- Fast 150 ns Operation
- Low Power Dissipation
  - 275 mW Maximum (Active)
  - 30 mW Maximum (Standby)
- Three-State Data Output
- Internal Latches for Address and Data Input
- Early-Write Output Capability
- 16K Compatible 128-Cycle, 2 ms Refresh
- $\overline{RAS}$-only Refresh Mode
- $\overline{CAS}$ Controlled Output
- Upward Pin Compatible from the 16K RAM (MCM4116, MCM4516, MCM4517)
- One Half of the 64K RAM MCM6665
- The Operating Half of the MCM6633 is Indicated by Device Marking:
  - MCM66330 Tie A7 $\overline{CAS}$ (A15) Low "0"
  - MCM66331 Tie A7 $\overline{CAS}$ (A15) High "1"

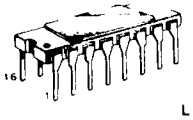
BLOCK DIAGRAM



MOS

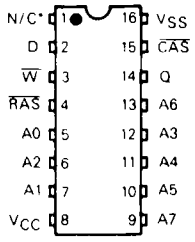
(N-CHANNEL, SILICON-GATE)

32,768-BIT DYNAMIC RANDOM ACCESS MEMORY



L SUFFIX
CERAMIC PACKAGE
CASE 690

PIN ASSIGNMENT



*For maximum compatibility with MCM6632 and MCM6664, a V_{CC} trace should go to pin #1.

PIN NAMES	
A0-A7	Address Input
D	Data In
Q	Data Out
$\overline{W}$	Read/Write Input
$\overline{RAS}$	Row Address Strobe
$\overline{CAS}$	Column Address Strobe
V_{CC}	Power (+5 V)
V_{SS}	Ground

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

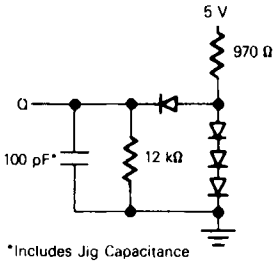
MCM6633

ABSOLUTE MAXIMUM RATINGS (See Note)

Rating	Symbol	Value	Unit
Voltage on Any Pin Relative to V_{SS} (Except V_{CC})	V_{in}, V_{out}	−2 to +7	V
Voltage on V_{CC} Supply Relative to V_{SS}	V_{in}, V_{out}	−1 to +7	V
Operating Temperature Range	T_A	0 to +70	°C
Storage Temperature Range	T_{stg}	−65 to +150	°C
Power Dissipation	P_D	1	W
Data Out Current	I_{out}	50	mA

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

FIGURE 1 – OUTPUT LOAD



*Includes Jig Capacitance

DC OPERATING CONDITIONS AND CHARACTERISTICS

(Full operating voltage and temperature range unless otherwise noted.)

RECOMMENDED OPERATING CONDITIONS

Parameter		Symbol	Min	Typ	Max	Unit	Notes
Supply Voltage	MCM6633L15/MCM6633L20	V_{CC}	4.5	5.0	5.5	Vdc	1
	MCM6633L15-5/MCM6633L20-5	V_{CC}	4.75	5.0	5.25		
		V_{SS}	0	0	0		
Logic 1 Voltage, All Inputs		V_{IH}	2.4	–	7.0	Vdc	1
Logic 0 Voltage		V_{IL}	−2.0	–	0.8	Vdc	1

DC CHARACTERISTICS

Characteristic	Symbol	Min	Max	Units	Notes
V_{CC} Power Supply Current (t_{RC} min.)	I_{CC1}	–	50	mA	4
Standby V_{CC} Power Supply Current	I_{CC2}	–	5	mA	5
V_{CC} Power Supply Current During $\overline{RAS}$ Only Refresh Cycles	I_{CC3}	–	40	mA	–
Input Leakage Current (any input) ($0 \le V_{in} \le 5.5$) (Except Pin 1)	$I_{I(L)}$	–	10	μA	–
Output Leakage Current ($0 \le V_{out} \le 5.5$) ($\overline{CAS}$ at Logic 1)	$I_{O(L)}$	–	10	μA	–
Output Logic 1 Voltage @ $I_{out} = -4$ mA	V_{OH}	2.4	–	V	–
Output Logic 0 Voltage @ $I_{out} = 4$ mA	V_{OL}	–	0.4	V	–

AC OPERATING CONDITIONS AND CHARACTERISTICS

(See Notes 2, 3, 6, and Figure 1)
(Read, Write, and Read-Modify-Write Cycles)
(Full Operating Voltage and Temperature Range Unless Otherwise Noted)

Parameter	Symbol	MCM6633-15		MCM6633-20		Units	Notes
		Min	Max	Min	Max		
Random Read or Write Cycle Time	t_{RC}	300	–	350	–	ns	8, 9
Read Write Cycle Time	t_{RWC}	300	–	350	–	ns	8, 9
Access Time from Row Address Strobe	t_{RAC}	–	150	–	200	ns	10, 12
Access Time from Column Address Strobe	t_{CAC}	–	75	–	110	ns	11, 12
Output Buffer and Turn-Off Delay	t_{OFF}	0	30	0	40	ns	17
Row Address Strobe Precharge Time	t_{RP}	120	–	140	–	ns	–
Row Address Strobe Pulse Width	t_{RAS}	150	10000	200	10000	ns	–
Column Address Strobe Pulse Width	t_{CAS}	75	10000	110	10000	ns	–
Row to Column Strobe Lead Time	t_{RCD}	30	75	35	90	ns	13
Row Address Setup Time	t_{ASR}	0	–	0	–	ns	–
Row Address Hold Time	t_{RAH}	25	–	30	–	ns	–
Column Address Setup Time	t_{ASC}	0	–	0	–	ns	–
Column Address Hold Time	t_{CAH}	45	–	55	–	ns	–
Column Address Hold Time Referenced to $\overline{RAS}$	t_{AR}	120	–	155	–	ns	–
Transition Time (Rise and Fall)	t_T	3	50	3	50	ns	6

AC OPERATING CONDITIONS AND CHARACTERISTICS

(See Notes 2, 3, 6, and Figure 1)
(Read, Write, and Read-Modify-Write Cycles)
(Full Operating Voltage and Temperature Range Unless Otherwise Noted)

Parameter	Symbol	MCM6633-15		MCM6633-20		Units	Notes
		Min	Max	Min	Max		
Read Command Setup Time	t_{RCS}	0	–	0	–	ns	–
Read Command Hold time	t_{RCH}	10	–	10	–	ns	14
Read Command Hold Time Referenced to $\overline{RAS}$	t_{RRH}	30	–	35	–	ns	14
Write Command Hold Time	t_{WCH}	45	–	55	–	ns	–
Write Command Hold Time Referenced to $\overline{RAS}$	t_{WCR}	120	–	155	–	ns	–
Write Command Pulse Width	t_{WP}	45	–	55	–	ns	–
Write Command to Row Strobe Lead Time	t_{RWL}	45	–	55	–	ns	–
Write Command to Column Strobe Lead Time	t_{CWL}	45	–	55	–	ns	–
Data in Setup Time	t_{DS}	0	–	0	–	ns	15
Data in Hold Time	t_{DH}	45	–	55	–	ns	15
Data in Hold Time Referenced to $\overline{RAS}$	t_{DHR}	120	–	155	–	ns	–
Column to Row Strobe Precharge Time	t_{CRP}	−10	–	−10	–	ns	–
$\overline{RAS}$ Hold Time	t_{RSH}	75	–	110	–	ns	–
Refresh Period	t_{RFSH}	–	2.0	–	2.0	ms	–
$\overline{WRITE}$ Command Setup Time	t_{WCS}	−10	–	−10	–	ns	16
$\overline{CAS}$ to $\overline{WRITE}$ Delay	t_{CWD}	45	–	55	–	ns	16
$\overline{RAS}$ to $\overline{WRITE}$ Delay	t_{RWD}	125	–	160	–	ns	16
$\overline{CAS}$ Hold Time	t_{CSH}	150	–	200	–	ns	–

CAPACITANCE (f = 1.0 MHz, T_A = 25°C, V_{CC} = 5 V Periodically Sampled Rather Than 100% Tested)

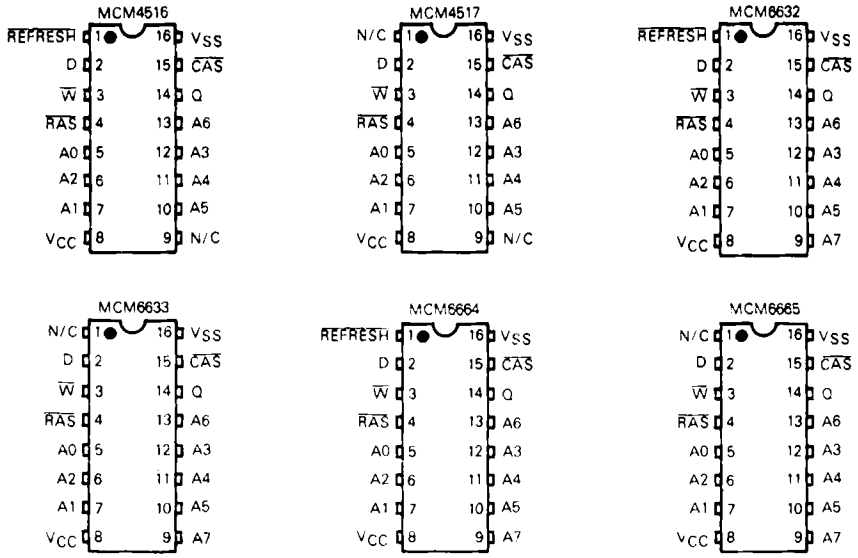
Parameter	Symbol	Typ	Max	Units	Notes
Input Capacitance (A0-A7), D	C_{I1}	4	5	pF	7
Input Capacitance $\overline{RAS}$, $\overline{CAS}$, $\overline{WRITE}$	C_{I2}	8	10	pF	7
Output Capacitance (Q) ($\overline{CAS}$ = V_{IH} to disable output)	C_O	5	7	pF	7

NOTES:

1. All voltages referenced to V_{SS}.
2. V_{IH} min and V_{IL} max are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} and V_{IL}.
3. An initial pause of 100 µs is required after power-up followed by any 8 $\overline{RAS}$ cycles before proper device operation guaranteed.
4. Current is a function of cycle rate and output loading; maximum current is measured at the fastest cycle rate with the output open.
5. Output is disabled (open-circuit) and $\overline{RAS}$ and $\overline{CAS}$ are both at a logic 1.
6. The transition time specification applies for all input signals. In addition to meeting the transition rate specification, all input signals must transmit between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) in a monotonic manner.
7. Capacitance measured with a Boonton Meter or effective capacitance calculated from the equation: $C = \frac{I\Delta_t}{\Delta V}$
8. The specifications for t_{RC} (min), and t_{RWC} (min) are used only to indicate cycle time at which proper operation over the full temperature range (0°C ≤ T_A ≤ 70°C) is assured.
9. AC measurements assume t_T = 5.0 ns.
10. Assumes that $t_{RCD} \leq t_{RCD}$ (max).
11. Assumes that $t_{RCD} \geq t_{RCD}$ (max).
12. Measured with a current load equivalent to 2 TTL loads (+200 µA, −4 mA) and 100 pF (V_{OH} = 2.0 V, V_{OL} = −0.8 V)
13. Operation within the t_{RCD} (max) limit ensures that t_{RAC} (max) can be met. t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
14. Either t_{RRH} or t_{RCH} must be satisfied for a read cycle.
15. These parameters are referenced to $\overline{CAS}$ leading edge in random write cycles and to $\overline{WRITE}$ leading edge in delayed write or read-modify-write cycles.
16. t_{WCS}, t_{CWD}, and t_{RWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only: if $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{CWD} \geq t_{CWD}$ (min) and $t_{RWD} \geq t_{RWD}$ (min), the cycle is a read-write cycle and the data out will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
17. t_{off} (max) defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.

MCM6633

PIN ASSIGNMENT COMPARISON



PIN VARIATIONS

Pin Number	MCM4116	MCM4516	MCM4517	MCM6632	MCM6663	MCM6664	MCM6665
1	V_{BB} (−5 V)	$\overline{\text{REFRESH}}$	N/C	$\overline{\text{REFRESH}}$	N/C	$\overline{\text{REFRESH}}$	N/C
8	V_{DD} (+12 V)	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
9	V_{CC} (+5 V)	N/C	N/C	A7	A7	A7	A7

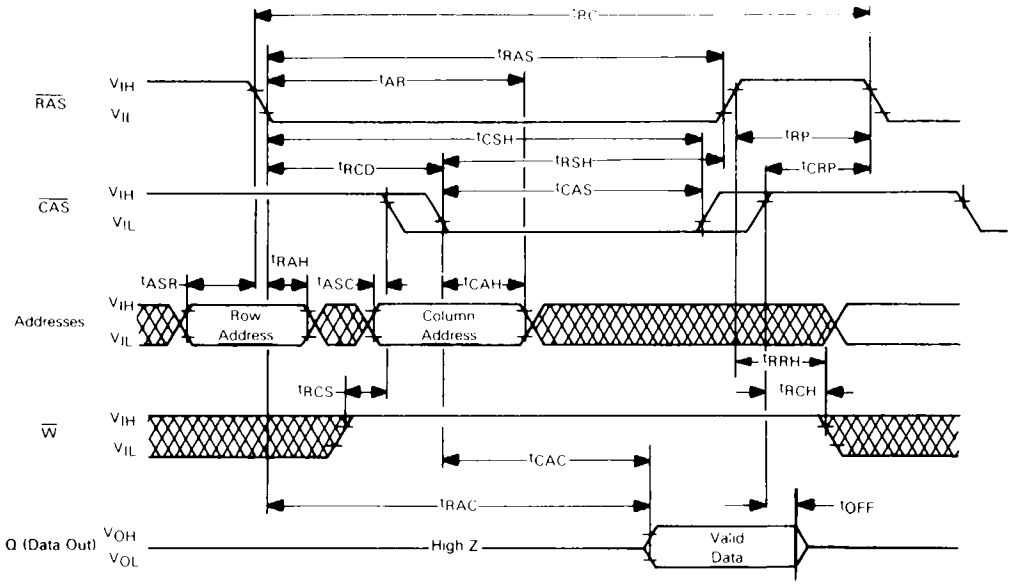
ORDERING INSTRUCTIONS

PART NUMBER	DESCRIPTION	SPEED	MARKING*
MCM6633L15	32K RAM Sidebraze Package "L"	150	66330L15/66331L15
MCM66330L15		150	66330L15
MCM66331L15		150	66331L15
MCM6633L20		200	66330L20/66331L20
MCM66330L20		200	66330L20
MCM66331L20		200	66331L20

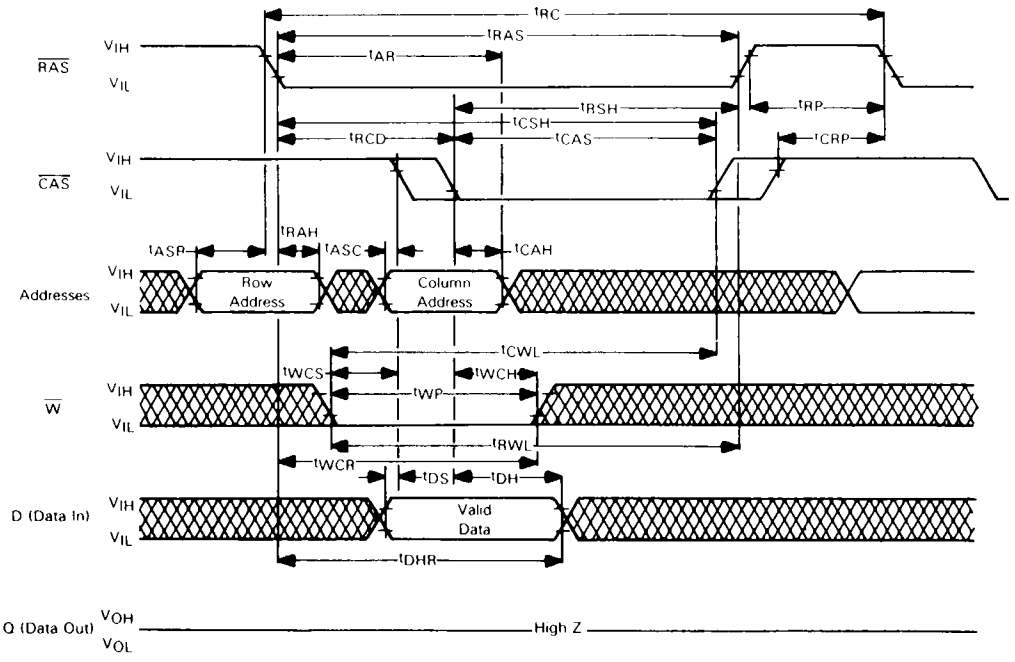
*MCM66330L20 = Tie A7 $\overline{\text{CAS}}$ (A15) Low "0"
MCM66331L20 = Tie A7 $\overline{\text{CAS}}$ (A15) High "1"

MCM6633

READ CYCLE TIMING

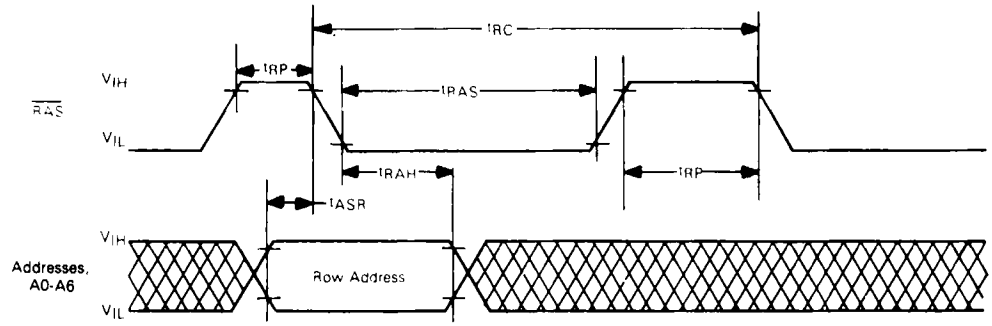


WRITE CYCLE TIMING

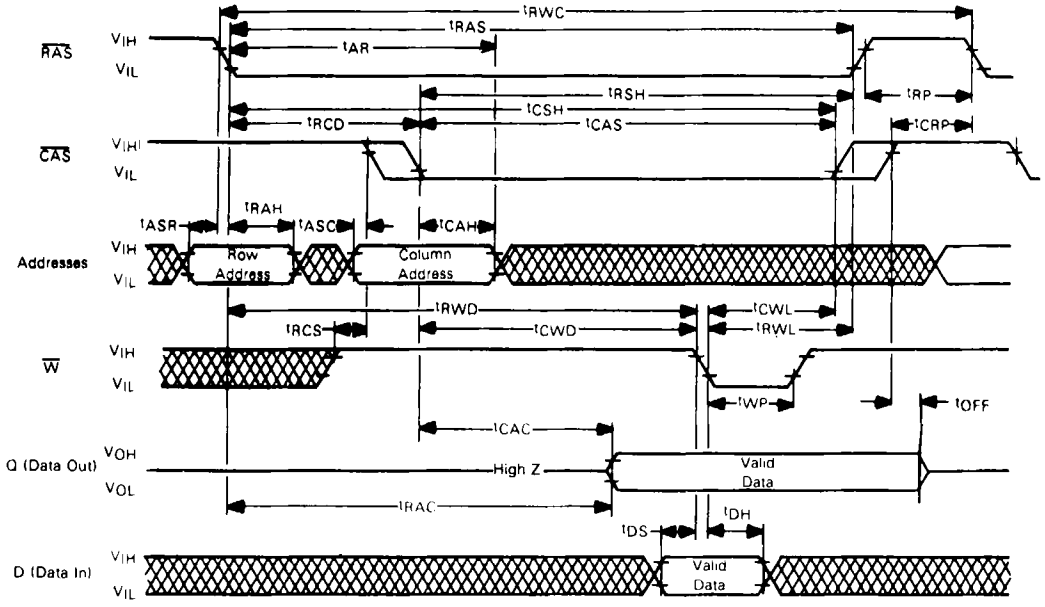


MCM6633

RAS-ONLY REFRESH CYCLE
(Data-in and Write are Don't Care, $\overline{CAS}$ is HIGH)

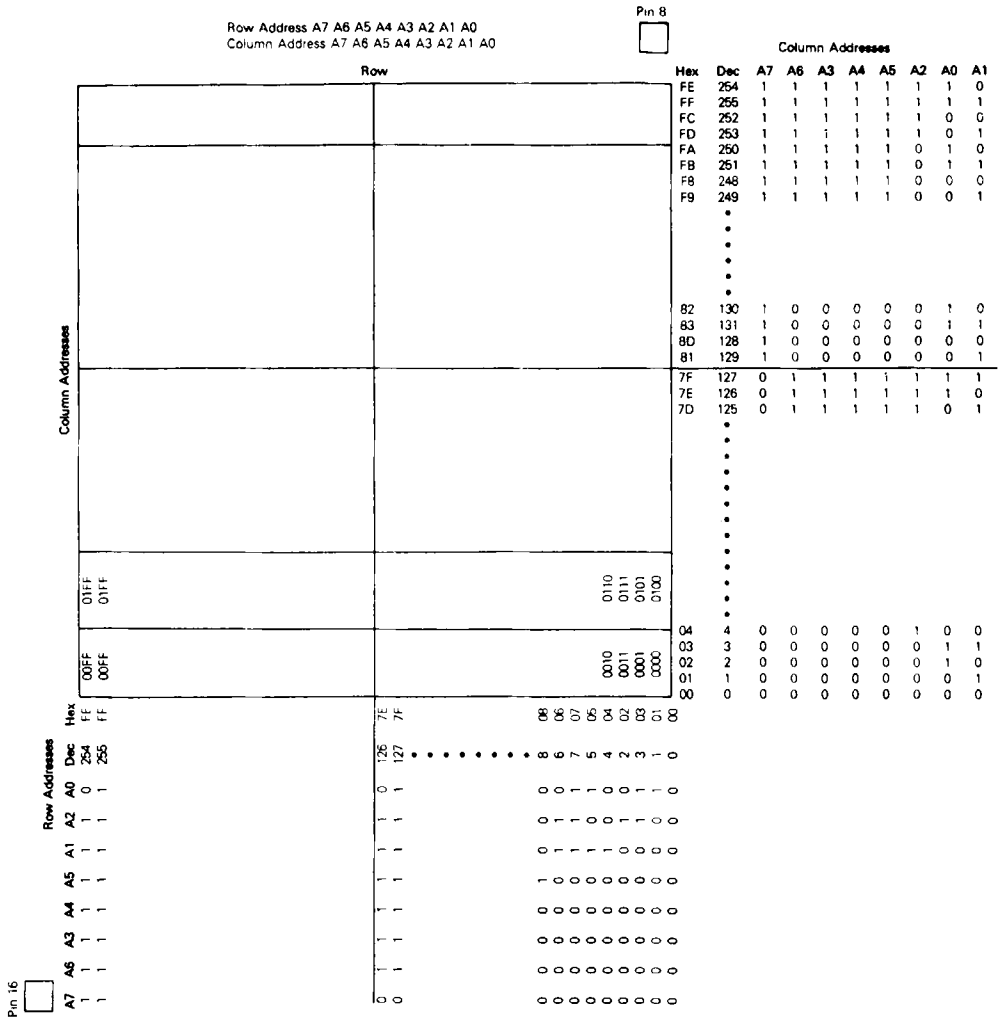


READ-WRITE/READ-MODIFY-WRITE CYCLE



MCM6633

MCM6665 BIT ADDRESS MAP



Hex	Dec	A7	A6	A3	A4	A5	A2	A0	A1
FE	254	1	1	1	1	1	1	1	0
FF	255	1	1	1	1	1	1	1	1
FC	252	1	1	1	1	1	1	0	0
FD	253	1	1	1	1	1	1	0	1
FA	250	1	1	1	1	1	0	1	0
FB	251	1	1	1	1	1	0	1	1
F8	248	1	1	1	1	1	0	0	0
F9	249	1	1	1	1	1	0	0	1
•	•								
•	•								
•	•								
•	•								
•	•								
•	•								
82	130	1	0	0	0	0	0	1	0
83	131	1	0	0	0	0	0	1	1
80	128	1	0	0	0	0	0	0	0
81	129	1	0	0	0	0	0	0	1
7F	127	0	1	1	1	1	1	1	1
7E	126	0	1	1	1	1	1	1	0
7D	125	0	1	1	1	1	1	0	1
•	•								
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•	•								
•	•								
•	•								
•	•								
04	4	0	0	0	0	0	1	0	0
03	3	0	0	0	0	0	0	1	1
02	2	0	0	0	0	0	0	1	0
01	1	0	0	0	0	0	0	0	1
00	0	0	0	0	0	0	0	0	0

$\overline{\text{Data Stored}} = D_{in} \bullet A_{0X} \bullet A_{1Y}$

Column Address A1	Row Address A0	Data Stored
0	0	Inverted
0	1	True
1	0	True
1	1	Inverted